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The revision list can be viewed directly by clicking the title page.

The revision list summarizes the locations of revisions and additions. Details should always be checked by referring to the relevant text.

H8/3048 Group, H8/3048 F-ZTAT™ Hardware Manual

Renesas 16-Bit Single-Chip Microcomputer H8 Family/H8/300H Series

H8/3048	HD6473048,
	HD6433048
H8/3047	HD6433047
H8/3045	HD6433045
H8/3044	HD6433044
H8/3048F	HD64F3048

Rev. 7.00 Revision Date: Sep 21, 2005

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Preface

The H8/3048 Group is a series of high-performance microcontrollers that integrate system supporting functions together with an H8/300H CPU core.

The H8/300H CPU has a 32-bit internal architecture with sixteen 16-bit general registers, and a concise, optimized instruction set designed for speed. It can address a 16-Mbyte linear address space.

The on-chip supporting functions include ROM, RAM, a 16-bit integrated timer unit (ITU), a programmable timing pattern controller (TPC), a watchdog timer (WDT), a serial communication interface (SCI), an A/D converter, a D/A converter, I/O ports, a direct memory access controller (DMAC), a refresh controller, and other facilities. Of the two SCI channels, one has been expanded to support the ISO/IEC7816-3 smart card interface. Functions have also been added to reduce power consumption in battery-powered applications: individual modules can be placed in standby, and the frequency of the system clock supplied to the chip can be divided down under software control.

The address space is divided into eight areas. The data bus width and access cycle length can be selected independently in each area, simplifying the connection of different types of memory. Seven operating modes (modes 1 to 7) are provided, offering a choice of data bus width and address space size.

With these features, the H8/3048 Group can be used to implement compact, high-performance systems easily.

In addition to its mask ROM versions, the H8/3048 Group has a ZTAT^{TM*1} version with userprogrammable on-chip PROM and an F-ZTAT^{TM*2} version with on-chip flash memory that can be programmed on-board. These versions enable users to respond quickly and flexibly to changing application specifications.

The on-chip emulator (E10T) is installed on the H8/3048F-ONE in the H8/3048 Group microcomputer. Refer to the H8/3048F-ONE Hardware Manual for details.

This manual describes the H8/3048 Group hardware. For details of the instruction set, refer to the H8/300H Series Programming Manual.

Notes: 1. ZTAT[™] (Zero Turn-Around-Time) is a trademark of Renesas Technology, Corp.
2. F-ZTAT[™] (Flexible ZTAT) is a trademark of Renesas Technology, Corp.

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Comparison of H8/3048 Group Product Specifications

There are seven members of the H8/3048 Group; the H8/3048F-ZTAT (H8/3048F^{*1}, H8/3048F-ONE^{*2}), H8/3048ZTAT, H8/3048 mask ROM version, H8/3047 mask ROM version, H8/3045 mask ROM version, and H8/3044 mask ROM version.

The specifications of each model is compared below.

- Notes: 1. H8/3048F has dual power supply with flash memory installed.
 - 2. H8/3048F-ONE has single power supply with flash memory and E10T installed. Refer to the H8/3048F-ONE Hardware Manual (revision 1) for details.

Hardware Manual		H8/3048 Group		H8/3048F-ONE
ROM Type	ZTAT	Mask ROM	F	ZTAT
Model Type	H8/3048	H8/3048 mask ROM version H8/3047 mask ROM version H8/3045 mask ROM version H8/3044 mask ROM version		H8/3048F-ONE
Model Spec	PROM model	Mask ROM model	Dual power supply, flash memory is installed	Single power supply, flash memory installed, internal step-down, high-speed operation model
			Refer to 1.4, Differences between H8/3048F and H8/3048F-ONE.	Refer to 1.4.3, Differences between H8/3048F and H8/3048F-ONE.
Model Type No.	HD6473048	HD6433048 HD6433047 HD6433045 HD6433044	HD64F3048	HD64F3048B
Pin Assignment	Mask ROM Vers ROM Version, H	1.2, Pin Arrangement of H8/30 sion, H8/3047 Mask ROM Vers 18/3044 Mask ROM Version, a P-100B, Top View), in section	sion, H8/3045 Mask and H8/3048F	
				Refer to figure 1.3, H8/3048F-ONE Pin Arrangement (FP-100B or TFP-100B, Top View), in section 1.
RAM Capacity	4 kbytes	H8/3048: 4 kbytes H8/3047: 4 kbytes H8/3045: 2 kbytes H8/3044: 2 kbytes	4 kbytes	4 kbytes

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Hardware Manual		H8/3048 Group		H8/3048F-ONE
ROM Type	ZTAT	Mask ROM	F	-ZTAT
ROM Capacity	128 kbytes	H8/3048: 128 kbytes H8/3047: 96 kbytes H8/3045: 64 kbytes H8/3044: 32 kbytes	128 kbytes	128 kbytes
Flash Memory	_	_	Refer to section 19, ROM (H8/3048F).	Refer to section 18, Flash Memory (H8/3048F-ONE Single Power Supply).
Clock Pulse Generator	Refer to section	20, Clock Pulse Generator.		Refer to section 19, Clock Pulse Generator.
Power-Down State	Refer to section	21, Power-Down State.		Refer to section 20, Power-Down State.
	Clock oscillator	settling time: Waiting time of	up to 131072 states	Clock oscillator settling time: Waiting time of up to 262144 states
Electrical Characteristics (Clock Rate)	Refer to table 2 Products, in sec	2.1, Electrical Characteristics tion 22.	of H8/3048 Group	Refer to table 21.1, Electrical Characteristics of H8/3048 Group Products, in section 21.
	1 to 18 MHz		1 to 16 MHz	5 V operation models: 2 to 25 MHz, 3 V operation models: 2 to 25 MHz.
List of Registers	Refer to table B appendix B.	.1, Comparison of H8/3048 G	roup Internal I/O Regis	ter Specifications, in
	Refer to append	lix B.1, Addresses.		
Notes on Usage	_	_	-	Refer to section 1.4, Notes on H8/3048F- ONE (Single Power Supply).
On-chip Emulator (E10T)	—	—		On-chip emulator (E10T)



Main Revisions for this Edition

Item	Page	Revision (See Manual for Details)
All	_	All references to Hitachi, Hitachi, Ltd., Hitachi Semiconductors, and other Hitachi brand names changed to Renesas Technology Corp.
		Designation for categories changed from "series" to "group"
13.2.6 Serial Register (SCI	0011101 101	Table amended
Bit 6-Receive		Bit 6: RIE Description
Interrupt Ena (RIE)	ble	0 Receive-data-full (RXI) and receive-error (ERI) interrupt requests are disabled* (Initial value)
		1 Receive-data-full (RXI) and receive-error (ERI) interrupt requests are enabled
19.5.3 Progra Flowchart and Sample Prog	d	Figure amended
Flowchart for Programming Byte Figure 19.9 Programming	One	Enable watchdog timer*2 Notes: 1. Write the data to be programmed using a byte transfer instruction. Select program mode (P bit = 1 in FLMCR) Select programmed using a byte transfer instruction. Wait (x) µs Step transfer instruction. Clear P bit Programming ends Disable watchdog timer X to 10 µs Disable watchdog timer Notes: 1. Write the data to be programmed using a byte transfer instruction. Notes: 1. Write the data to be programmed using a byte transfer instruction. Set the watchdog timer transfer instruction. Notes: 1. Write the data to be programmed using a byte transfer instruction. Read to verify data from the memory using a byte transfer instruction. Using Disable watchdog timer Notes: 1. Write the data to be programmed using a byte transfer instruction. Notes: 1. Write the data to be programmed using a byte transfer instruction. Notes: 1. Write the data to be programmed using a byte transfer instruction. Notes: 1. Write the data to be programming time does not exceed 1 ms) Notes: 1. Write the data to be programming time does not exceed 1 ms)
Flowchart		Select program-verify mode (PV bit = 1 in FLMCR) Wait (l _{VS1}) µs ^{rdd} Difference (PV bit = 1 in FLMCR) Wait (l _{VS1}) µs ^{rdd} Difference (PV bit = 1 in FLMCR) Difference (PV bit = 1 in FLMCR) Differ

Verify (read memory)*3

Clear PV bit

Clear erase block register

(clear bit of programmed block to 0)

Clear V_{PP}E bit

End (1-byte data programmed)

No good

Clear PV bit

n≥N?

Clear erase block register

(clear bit of block to be

programmed to 0)

Clear V_{PP}E bit Programming error

Yes

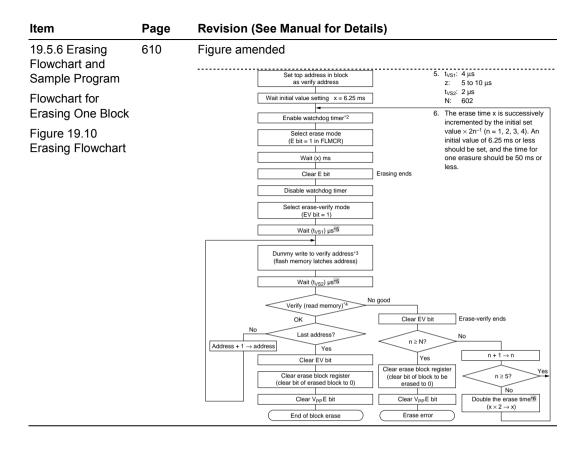
Verify ends

 $n + 1 \rightarrow n$

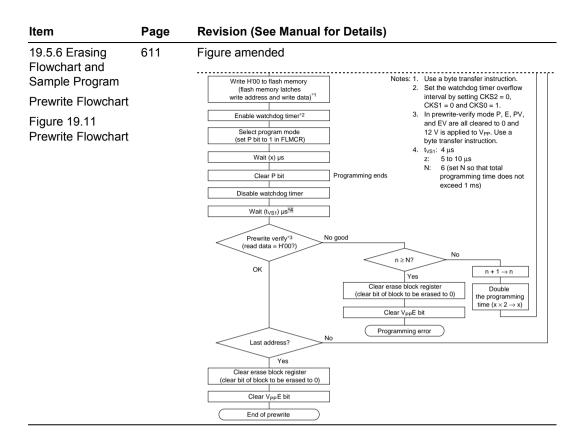
Double the programming

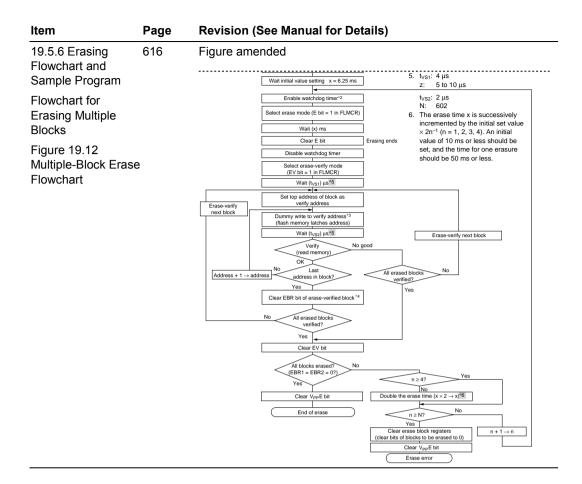
time $(x\times 2 \to x)^{*5}$

No











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Section 1 Overview

1.1 Overview

The H8/3048 Group is a series of microcontrollers (MCUs) that integrate system supporting functions together with an H8/300H CPU core having an original Renesas Technology architecture.

The H8/300H CPU has a 32-bit internal architecture with sixteen 16-bit general registers, and a concise, optimized instruction set designed for speed. It can address a 16-Mbyte linear address space. Its instruction set is upward-compatible at the object-code level with the H8/300 CPU, enabling easy porting of software from the H8/300 Series.

The on-chip system supporting functions include ROM, RAM, a 16-bit integrated timer unit (ITU), a programmable timing pattern controller (TPC), a watchdog timer (WDT), a serial communication interface (SCI), an A/D converter, a D/A converter, I/O ports, a direct memory access controller (DMAC), a refresh controller, and other facilities.

The four members of the H8/3048 Group are the H8/3048, the H8/3047, H8/3045, and the H8/3044. The H8/3048 has 128 kbytes of ROM and 4 kbytes of RAM. The H8/3047 has 96 kbytes of ROM and 4 kbytes of RAM. The H8/3045 has 64 kbytes of ROM and 2 kbytes of RAM. The H8/3044 has 32 kbytes of ROM and 2 kbytes of RAM.

Seven MCU operating modes offer a choice of data bus width and address space size. The modes (modes 1 to 7) include one single-chip mode and six expanded modes.

In addition to the mask ROM versions of the H8/3048 Group, the H8/3048 has a ZTAT^{TM*1} version with user-programmable on-chip PROM and an F-ZTAT^{TM*2} version with on-chip flash memory that can be programmed on-board. These versions enable users to respond quickly and flexibly to changing application specifications, growing production volumes, and other conditions. The F-ZTATTM version H8/3048F-ONE includes the on-chip emulator E10T.

Table 1.1 summarizes the features of the H8/3048 Group.

Notes: 1. ZTAT (Zero Turn-Around Time) is a trademark of Renesas Technology Corp.

2. F-ZTAT (Flexible ZTAT) is a trademark of Renesas Technology Corp.

Renesas

Section 1 Overview

Table 1.1	Features
Feature	Description
CPU	Upward-compatible with the H8/300 CPU at the object-code level
	General-register machine
	— Sixteen 16-bit general registers
	(also usable as sixteen 8-bit registers + eight 16-bit registers or eight 32- bit registers)
	High-speed operation (flash memory version)
	H8/3048F
	— Maximum clock rate: 16 MHz
	— Add/subtract: 125 ns
	— Multiply/divide: 875 ns
	 High-speed operation (mask ROM and PROM versions)
	— Maximum clock rate: 18 MHz
	— Add/subtract: 111 ns
	— Multiply/divide: 778 ns
	16-Mbyte address space
	Instruction features
	 — 8/16/32-bit data transfer, arithmetic, and logic instructions
	 — Signed and unsigned multiply instructions (8 bits × 8 bits, 16 bits × 16 bits)
	 — Signed and unsigned divide instructions (16 bits ÷ 8 bits, 32 bits ÷ 16 bits)
	— Bit accumulator function
	 Bit manipulation instructions with register-indirect specification of bit positions



Feature	Description
Memory	• H8/3048, H8/3048F
	— ROM: 128 kbytes
	— RAM: 4 kbytes
	• H8/3047
	— ROM: 96 kbytes
	— RAM: 4 kbytes
	• H8/3045
	— ROM: 64 kbytes
	— RAM: 2 kbytes
	• H8/3044
	— ROM: 32 kbytes
	— RAM: 2 kbytes
Interrupt	Seven external interrupt pins: NMI, IRQ0 to IRQ5
controller	30 internal interrupts
	Three selectable interrupt priority levels
Bus controller	Address space can be partitioned into eight areas, with independent bus
	specifications in each area
	Chip select output available for areas 0 to 7
	8-bit access or 16-bit access selectable for each area
	Two-state or three-state access selectable for each area
	Selection of four wait modes
	Bus arbitration function
Refresh	DRAM refresh
controller	 Directly connectable to 16-bit-wide DRAM
	— CAS-before-RAS refresh
	— Self-refresh mode selectable
	Pseudo-static RAM refresh
	— Self-refresh mode selectable
	Usable as an interval timer

Section 1 Overview

Feature	Description
DMA controller	Short address mode
(DMAC)	 Maximum four channels available
	 — Selection of I/O mode, idle mode, or repeat mode
	 Can be activated by compare match/input capture A interrupts from ITU channels 0 to 3, transmit-data-empty and receive-data-full interrupts from SCI channel 0, or external requests
	Full address mode
	— Maximum two channels available
	 Selection of normal mode or block transfer mode
	 Can be activated by compare match/input capture A interrupts from ITU channels 0 to 3, external requests, or auto-request
16-bit integrated timer unit (ITU)	• Five 16-bit timer channels, capable of processing up to 12 pulse outputs or 10 pulse inputs
	• 16-bit timer counter (channels 0 to 4)
	Two multiplexed output compare/input capture pins (channels 0 to 4)
	Operation can be synchronized (channels 0 to 4)
	PWM mode available (channels 0 to 4)
	Phase counting mode available (channel 2)
	Buffering available (channels 3 and 4)
	Reset-synchronized PWM mode available (channels 3 and 4)
	Complementary PWM mode available (channels 3 and 4)
	 DMAC can be activated by compare match/input capture A interrupts (channels 0 to 3)
Programmable	Maximum 16-bit pulse output, using ITU as time base
timing pattern controller (TPC)	 Up to four 4-bit pulse output groups (or one 16-bit group, or two 8-bit groups) Non-overlap mode available
	 Output data can be transferred by DMAC
Watchdog timer	Reset signal can be generated by overflow
(WDT),	Reset signal can be output externally
1 channel	Usable as an interval timer

Feature	Descript	ion					
Serial	Select	tion of asynchron	ous or synchrond	ous mode			
communication	 Full oublex: can transmit and receive simultaneously 						
interface (SCI), 2 channels	On-ch	nip baud-rate gen	erator				
	• Smar	t card interface fu	nctions added (S	SCI0 only)			
A/D converter	Reso	lution: 10 bits					
		channels, with se	lection of single	or scan mode			
		ble analog conver					
		ble-and-hold funct	0	ye			
	-	onversion can be		red			
			externally trigger	ieu			
D/A converter		lution: 8 bits					
	• Two c	channels					
	 D/A o 	utputs can be sus	stained in softwar	re standby mode			
I/O ports	 70 inp 	out/output pins					
	8 input-only pins						
Operating	Seven MCU operating modes						
modes	Mode	Address Space	Address Pins	Initial Bus Width	Max. Bus Width		
	Mode 1	1 Mbyte	A_{19} to A_0	8 bits	16 bits		
	Mode 2	1 Mbyte	A ₁₉ to A ₀	16 bits	16 bits		
	Mode 3	16 Mbytes	A_{23} to A_0	8 bits	16 bits		
	Mode 4	16 Mbytes	A_{23} to A_0	16 bits	16 bits		
	Mode 5	1 Mbyte	A ₁₉ to A ₀	8 bits	16 bits		
	Mode 6	16 Mbytes	A ₂₃ to A ₀	8 bits	16 bits		
	Mode 7	1 Mbyte	_		—		
	On-ch	nip ROM is disabl	ed in modes 1 to	4			
Power-down	Sleep mode						
state	Software standby mode						
	Hardware standby mode						
		le standby functio					
	 Module standby function Programmable system clock frequency division 						

Feature	Description					
Other features	On-chip clock pulse generator					
Product lineup	Model (5 V)	Model (3 V)	Package	ROM		
	HD64F3048TF	HD64F3048VTF	100-pin TQFP (TFP-100B)	Flash memory		
	HD64F3048F	HD64F3048VF	100-pin QFP (FP-100B)			
	HD6473048TF	HD6473048VTF	100-pin TQFP (TFP-100B)	PROM		
	HD6473048F	HD6473048VF	100-pin QFP (FP-100B)			
	HD6433048TF	HD6433048VTF	100-pin TQFP (TFP-100B)	Mask ROM		
	HD6433048F	HD6433048VF	100-pin QFP (FP-100B)			
	HD6433047TF	HD6433047VTF	100-pin TQFP (TFP-100B)	Mask ROM		
	HD6433047F	HD6433047VF	100-pin QFP (FP-100B)			
	HD6433045TF	HD6433045VTF	100-pin TQFP (TFP-100B)	Mask ROM		
	HD6433045F	HD6433045VF	100-pin QFP (FP-100B)			
	HD6433044TF	HD6433044VTF	100-pin TQFP (TFP-100B)	Mask ROM		
	HD6433044F	HD6433044VF	100-pin QFP (FP-100B)			



1.2 Block Diagram

Figure 1.1 shows an internal block diagram.

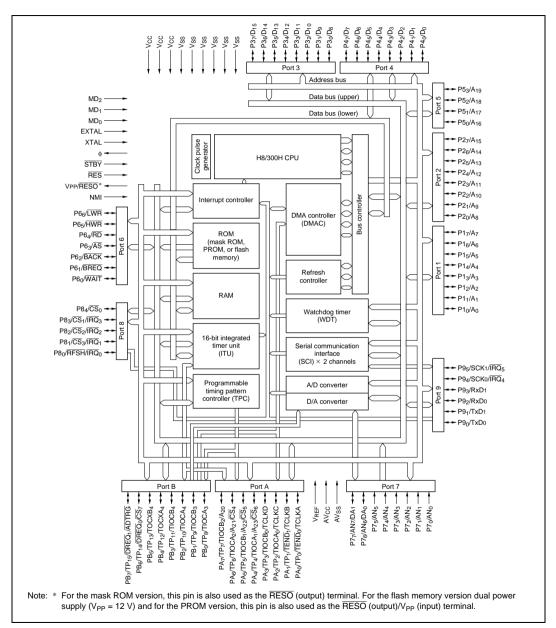


Figure 1.1 Block Diagram

1.3 Pin Description

1.3.1 Pin Arrangement

Figure 1.2 shows the pin arrangement of the H8/3048 Group.

The pin arrangement of the H8/3048 Group is shown in figure 1.2. Differences in the H8/3048 Group pin arrangements are shown in table 1.2. Except for the differences shown in table 1.2, the pin arrangements are the same.

 Table 1.2
 Comparison of H8/3048 Group Pin Arrangements

Package	Pin Number	H8/3048 ZTAT	H8/3048 Mask ROM Version	H8/3047 Mask ROM Version	H8/3045 Mask ROM Version	H8/3044 Mask ROM Version	H8/3048F
FP-100B	1	V_{CC}	V _{CC}	V _{CC}	V _{CC}	V _{CC}	V _{cc}
(TFP-100B)	10	V_{PP}/\overline{RESO}	RESO	RESO	RESO	RESO	V_{PP}/\overline{RESO}



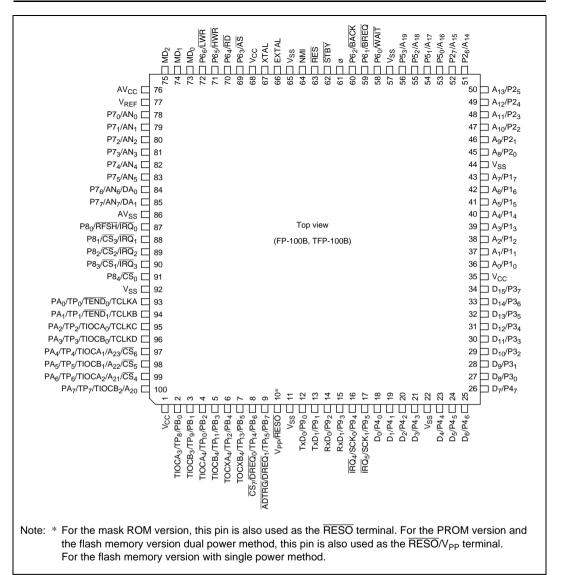


Figure 1.2 Pin Arrangement of H8/3048ZTAT, H8/3048 Mask ROM Version, H8/3047 Mask ROM Version, H8/3045 Mask ROM Version, H8/3044 Mask ROM Version, and H8/3048F (FP-100B or TFP-100B, Top View)

1.3.2 Pin Assignments in Each Mode

Table 1.3 lists the pin assignments in each mode.

Table 1.3 Pin Assignments in Each Mode (FP-100B or TFP-100B)

	Pin Name									
Pin								PROM	Mode	-
No.	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7	EPROM	Flash	Remarks
1* ³	V _{cc}	Vcc	Vcc	Vcc	Vcc	Vcc	Vcc	Vcc	V _{cc}	Mask ROM version, PROM version and flash memory version with dual power supply.
2	PB ₀ /TP ₈ / TIOCA ₃	B ₀ /TP ₈ / TIOCA ₃	B ₀ /TP ₈ / TIOCA ₃	B ₀ /TP ₈ / TIOCA ₃	B ₀ /TP ₈ / TIOCA ₃	B ₀ /TP ₈ / TIOCA ₃	B ₀ /TP ₈ / TIOCA ₃	NC	NC	
3	PB ₁ /TP ₉ / TIOCB ₃	PB ₁ /TP ₉ / TIOCB ₃	PB ₁ /TP ₉ / TIOCB ₃	PB ₁ /TP ₉ / TIOCB ₃	PB ₁ /TP ₉ / TIOCB ₃	PB ₁ /TP ₉ / TIOCB ₃	PB ₁ /TP ₉ / TIOCB ₃	NC	NC	
4	PB ₂ /TP ₁₀ / TIOCA ₄	PB ₂ /TP ₁₀ / TIOCA ₄	PB ₂ /TP ₁₀ / TIOCA ₄	PB ₂ /TP ₁₀ / TIOCA ₄	PB ₂ /TP ₁₀ / TIOCA ₄	PB ₂ /TP ₁₀ / TIOCA ₄	PB ₂ /TP ₁₀ / TIOCA ₄	NC	NC	
5	PB ₃ /TP ₁₁ / TIOCB ₄	PB ₃ /TP ₁₁ / TIOCB ₄	PB ₃ /TP ₁₁ / TIOCB ₄	PB ₃ /TP ₁₁ / TIOCB ₄	PB ₃ /TP ₁₁ / TIOCB ₄	PB ₃ /TP ₁₁ / TIOCB ₄	PB ₃ /TP ₁₁ / TIOCB ₄	NC	NC	
6	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / TOCXA ₄	PB ₄ /TP ₁₂ / TOCXA ₄	NC	NC	
7	PB ₅ /TP ₁₃ / TOCXB ₄	PB ₅ /TP ₁₃ / TOCXB ₄	PB ₅ /TP ₁₃ / TOCXB ₄	PB ₅ /TP ₁₃ / TOCXB ₄	PB ₅ /TP ₁₃ / TOCXB ₄	PB ₅ /TP ₁₃ / TOCXB ₄	PB ₅ /TP ₁₃ / TOCXB ₄	NC	NC	
8	$\frac{PB_6/TP_{14}}{\overline{DREQ}_0}/$	$\frac{PB_6/TP_{14}}{\frac{DREQ_0}{CS_7}}$	$\frac{PB_6/TP_{14}}{\frac{DREQ_0}{CS_7}}$	$\frac{PB_6/TP_{14}}{\frac{DREQ_0}{CS_7}}$	$\frac{PB_6/TP_{14}}{\overline{DREQ}_0}/$	$\frac{PB_6/TP_{14}}{\frac{DREQ_0}{CS_7}}$	$\frac{PB_6/TP_{14}}{DREQ_0}$	NC	NC	
9	PB ₇ /TP ₁₅ / DREQ ₁ / ADTRG	$\frac{PB_7/TP_{15}}{\frac{DREQ_1}{ADTRG}}$	$\frac{PB_7/TP_{15}}{\frac{DREQ_1}{ADTRG}}$	$\frac{PB_7/TP_{15}}{\frac{DREQ_1}{ADTRG}}$	$\frac{PB_7/TP_{15}}{\frac{DREQ_1}{ADTRG}}$	$\frac{PB_7/TP_{15}}{\frac{DREQ_1}{ADTRG}}$	$\frac{PB_7/TP_{15}}{\frac{DREQ_1}{ADTRG}}$	NC	NC	

- n:.

Section 1 Overview

	Pin Name									
Pin								PROM	Mode	-
No.	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7	EPROM	Flash	Remarks
10*4	RESO	RESO	RESO	RESO	RESO	RESO	RESO	Vpp	V _{PP}	Mask ROM version, PROM version and flash memory version with dual power supply.
11	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	
12	P9 ₀ /TxD ₀	$P9_0/TxD_0$	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	P9 ₀ /TxD ₀	NC	NC	
13	P9 ₁ /TxD ₁	$P9_1/TxD_1$	P9 ₁ /TxD ₁	P9 ₁ /TxD ₁	$P9_1/TxD_1$	$P9_1/TxD_1$	$P9_1/TxD_1$	NC	NC	
14	$P9_2/RxD_0$	$P9_2/RxD_0$	$P9_2/RxD_0$	$P9_2/RxD_0$	$P9_2/RxD_0$	$P9_2/RxD_0$	$P9_2/RxD_0$	NC	NC	
15	$P9_3/RxD_1$	$P9_3/RxD_1$	$P9_3/RxD_1$	$P9_3/RxD_1$	P9 ₃ /RxD ₁	$P9_3/RxD_1$	$P9_3/RxD_1$	NC	NC	
16		P9 ₄ /SCK ₀	P9 ₄ /SCK ₀	P9 ₄ /SCK ₀	P9 ₄ /SCK ₀	P9 ₄ /SCK ₀	P9 ₄ /SCK ₀	NC	NC	
	/ ĪRQ₄	/ IRQ₄	/ IRQ₄	/ IRQ₄	/ IRQ₄	/ IRQ₄	/ IRQ₄			
17	$\frac{P9_{5}/SCK_{1}}{IRQ_{5}}$	$\frac{P9_{5}/SCK_{1}}{IRQ_{5}}$	P9 ₅ /SCK ₁ / IRQ ₅	$\frac{P9_5/SCK_1}{IRQ_5}$	P95/SCK1 / IRQ5	$\frac{P9_5/SCK_1}{IRQ_5}$	P9 ₅ /SCK ₁ / IRQ ₅	NC	NC	
18	$P4_0/D_0^{*1}$	P4 ₀ /D ₀ * ²	P4 ₀ /D ₀ * ¹	P4 ₀ /D ₀ * ²	P4 ₀ /D ₀ * ¹	P4 ₀ /D ₀ * ¹	P4 ₀	NC	NC	
19	P4 ₁ /D ₁ * ¹	P4 ₁ /D ₁ * ²	P4 ₁ /D ₁ * ¹	P4 ₁ /D ₁ * ²	P4 ₁ /D ₁ * ¹	P4 ₁ /D ₁ * ¹	P41	NC	NC	
20	P4 ₂ /D ₂ * ¹	P4 ₂ /D ₂ * ²	P4 ₂ /D ₂ * ¹	P4 ₂ /D ₂ * ²	P4 ₂ /D ₂ * ¹	P4 ₂ /D ₂ * ¹	P4 ₂	NC	NC	
21	P4 ₃ /D ₃ * ¹	P4 ₃ /D ₃ * ²	P4 ₃ /D ₃ * ¹	P4 ₃ /D ₃ * ²	P4 ₃ /D ₃ * ¹	P4 ₃ /D ₃ * ¹	P4 ₃	NC	NC	
22	V _{SS}	V _{SS}	V _{SS}	V _{ss}	V _{SS}	V _{ss}	V _{ss}	V _{ss}	V_{SS}	
23	P4 ₄ /D ₄ * ¹	P4 ₄ /D ₄ * ²	P4 ₄ /D ₄ * ¹	P4 ₄ /D ₄ * ²	P4 ₄ /D ₄ * ¹	P4 ₄ /D ₄ * ¹	P4 ₄	NC	NC	
24	P4 ₅ /D ₅ *1	P4 ₅ /D ₅ * ²	P4 ₅ /D ₅ *1	P45/D5*2	P4 ₅ /D ₅ *1	P4 ₅ /D ₅ *1	P45	NC	NC	
25	P4 ₆ /D ₆ *1	P4 ₆ /D ₆ * ²	P4 ₆ /D ₆ *1	P4 ₆ /D ₆ * ²	P4 ₆ /D ₆ *1	P4 ₆ /D ₆ *1	P4 ₆	NC	NC	
26	P47/D7*1	P47/D7*2	P47/D7*1	P47/D7*2	P47/D7*1	P47/D7*1	P47	NC	NC	
27	D ₈	D ₈	D ₈	D ₈	D ₈	D ₈	P3 ₀	EO ₀	I/O ₀	
28	D ₉	D ₉	D ₉	D ₉	D ₉	D ₉	P3 ₁	EO1	I/O ₁	
29	D ₁₀	D ₁₀	D ₁₀	D ₁₀	D ₁₀	D ₁₀	P3 ₂	EO ₂	I/O ₂	
30	D ₁₁	D ₁₁	D ₁₁	D ₁₁	D ₁₁	D ₁₁	P3 ₃	EO ₃	I/O ₃	
31	D ₁₂	D ₁₂	D ₁₂	D ₁₂	D ₁₂	D ₁₂	P34	EO ₄	I/O ₄	
32	D ₁₃	D ₁₃	D ₁₃	D ₁₃	D ₁₃	D ₁₃	P35	EO ₅	I/O ₅	
33	D ₁₄	D ₁₄	D ₁₄	D ₁₄	D ₁₄	D ₁₄	P3 ₆	EO ₆	I/O ₆	

	Pin Name									
Pin								PROM Mode		-
No.	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7	EPROM	Flash	Remarks
34	D ₁₅	D ₁₅	P37	EO7	I/O7					
35	V _{cc}	V _{cc}	V _{CC}	Vcc	V _{cc}					
36	A ₀	A ₀	A ₀	A ₀	P1 ₀ /A ₀	P1 ₀ /A ₀	P10	EA ₀	A ₀	
37	A ₁	A ₁	A ₁	A ₁	P1 ₁ /A ₁	P1 ₁ /A ₁	P11	EA ₁	A ₁	
38	A ₂	A ₂	A ₂	A ₂	P1 ₂ /A ₂	P1 ₂ /A ₂	P12	EA ₂	A ₂	
39	A ₃	A ₃	A ₃	A ₃	P1 ₃ /A ₃	P1 ₃ /A ₃	P1 ₃	EA ₃	A ₃	
40	A ₄	A_4	A ₄	A_4	P14/A4	P14/A4	P1₄	EA_4	A ₄	
41	A ₅	A ₅	A ₅	A ₅	P15/A5	P15/A5	P1₅	EA ₅	A ₅	
42	A ₆	A ₆	A ₆	A ₆	P1 ₆ /A ₆	P1 ₆ /A ₆	P16	EA ₆	A ₆	
43	A ₇	A ₇	A ₇	A ₇	P17/A7	P17/A7	P17	EA ₇	A ₇	
44	V _{SS}	V_{SS}	V_{SS}	V_{SS}	V _{SS}	V _{SS}	V_{SS}	V_{SS}	V_{SS}	
56	A ₁₉	A ₁₉	A ₁₉	A ₁₉	P5 ₃ /A ₁₉	P5 ₃ /A ₁₉	P53	NC	NC	
57	V _{SS}	V_{SS}	V_{SS}	V_{SS}	V _{SS}	V _{SS}	V_{SS}	V_{SS}	V_{SS}	
58	P6 ₀ / WAIT	P6₀/ WAIT	P6₀/ WAIT	P6₀/ WAIT	P6 ₀ / WAIT	P6 ₀ / WAIT	P6 ₀	EA ₁₅	A ₁₅	
59	P6 ₁ / BREQ	P6 ₁ / BREQ	P61	NC	NC					
60	P6 ₂ / BACK	P6 ₂ / BACK	P6 ₂	NC	NC					
61	¢	¢	¢	¢	φ	φ	φ	NC	NC	
62	STBY	STBY	STBY	STBY	STBY	STBY	STBY	V _{SS}	V_{CC}	
63	RES	RES	RES	RES	RES	RES	RES	NC	RES	
64	NMI	NMI	NMI	NMI	NMI	NMI	NMI	EA ₉	A ₉	
65	Vss	V _{SS}	V _{SS}	Vss	Vss	Vss	V _{SS}	Vss	V_{SS}	
66	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL	EXTAL	NC	EXTAL	
67	XTAL	XTAL	XTAL	XTAL	XTAL	XTAL	XTAL	NC	XTAL	
68	Vcc	V _{cc}	V _{CC}	V _{cc}	Vcc	Vcc	Vcc	Vcc	Vcc	
69	ĀS	ĀS	ĀS	ĀS	ĀS	ĀS	P63	NC	A ₁₆	
70	RD	RD	RD	RD	RD	RD	P64	NC	NC	
71	HWR	HWR	HWR	HWR	HWR	HWR	P65	NC	V _{CC}	
72	LWR	LWR	LWR	LWR	LWR	LWR	P66	NC	NC	
73	MD ₀	MD ₀	MD ₀	V _{SS}	V_{SS}					
74	MD ₁	MD ₁	MD ₁	V _{SS}	V_{SS}					
75	MD_2	MD_2	MD_2	MD_2	MD_2	MD_2	MD_2	V _{SS}	V_{SS}	

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				F	Pin Name					
Pin								PROM	Mode	-
No.	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7	EPROM	Flash	Remarks
76	AV _{CC}	AV _{CC}	AV _{CC}	AV _{CC}	AV_{CC}	AV _{CC}	AV_{CC}	V _{CC}	Vcc	
77	V_{REF}	Vcc	Vcc							
78	P7 ₀ /AN ₀	NC	NC							
79	P71/AN1	P7 ₁ /AN ₁	P7 ₁ /AN ₁	P7 ₁ /AN ₁	$P7_1/AN_1$	P7 ₁ /AN ₁	$P7_1/AN_1$	NC	NC	
80	P72/AN2	$P7_2/AN_2$	$P7_2/AN_2$	$P7_2/AN_2$	$P7_2/AN_2$	$P7_2/AN_2$	$P7_2/AN_2$	NC	NC	
81	P7 ₃ /AN ₃	NC	NC							
82	P74/AN4	P74/AN4	P7 ₄ /AN ₄	P74/AN4	P74/AN4	P74/AN4	P74/AN4	NC	NC	
83	P75/AN5	NC	NC							
84	P7 ₆ /AN ₆ / DA ₀	NC	NC							
85	P7 ₇ /AN ₇ / DA ₁	NC	NC							
86	AV_{SS}	V_{SS}	V_{SS}							
87	P8₀/ RFSH/ IRQ₀	P8₀/ RFSH/ IRQ₀	P8₀/ RFSH/ IRQ₀	P8₀/ RFSH/ IRQ₀	P8₀/ RFSH/ IRQ₀	P8₀/ RFSH/ IRQ₀	P8 ₀ /IRQ ₀	EA ₁₆	NC	
88	$\frac{P8_1}{\overline{IRQ}_1}$	$\frac{P8_1}{IRQ_1}$	$\frac{P8_1}{\overline{IRQ}_1}$	$\frac{P8_1}{IRQ_1} \frac{P8_1}{IRQ_1}$	$\frac{P8_1}{IRQ_1} \frac{P8_1}{IRQ_1}$	$\frac{P8_1}{IRQ_1}/\frac{CS_3}{IRQ_1}/$	P8 ₁ /IRQ ₁	PGM	NC	
89	$\frac{P8_2}{IRQ_2}/$	$\frac{P8_2}{\overline{IRQ}_2}$	$\frac{P8_2}{\overline{IRQ}_2}$	$\frac{P8_2}{IRQ_2}/$	$\frac{P8_2}{IRQ_2}/$	$\frac{P8_2}{IRQ_2}/$	P8 ₂ /IRQ ₂	NC	V_{CC}	
90	$\frac{P8_3}{IRQ_3}$	$\frac{P8_3}{\overline{CS}_1}/$	$\frac{P8_3}{IRQ_3}$	$\frac{P8_3}{\overline{IRQ}_3}/\overline{CS}_1/$	$\frac{P8_3}{\overline{CS}_1}/$	$\frac{P8_3}{\overline{IRQ}_3}/\overline{CS}_1/$	P8 ₃ /IRQ ₃	NC	WE	
91	$P8_4/\overline{CS}_0$	$P8_4/\overline{CS}_0$	$P8_4/\overline{CS}_0$	$P8_4/\overline{CS}_0$	$P8_4/\overline{CS}_0$	$P8_4/\overline{CS}_0$	P84	NC	NC	
92	V _{ss}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	
93	PA ₀ /TP ₀ / TEND ₀ / TCLKA	NC	NC							
94	PA ₁ /TP ₁ / TEND ₁ / TCLKB	PA1/TP1/ TEND1/ TCLKB	NC	NC						
95	PA ₂ /TP ₂ / TIOCA ₀ / TCLKC	NC	NC							
96	PA ₃ /TP ₃ / TIOCB ₀ / TCLKD	NC	NC							

	Pin Name									
Pin								PROM	Mode	-
No.	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7	EPROM	Flash	Remarks
97	$\frac{PA_4/TP_4}{TIOCA_1}/\frac{CS_6}{CS_6}$	$\frac{PA_4/TP_4/}{TIOCA_1/}$	$\frac{PA_4/TP_4}{TIOCA_1}/\frac{CS_6}{CS_6}$	$\frac{PA_4/TP_4}{TIOCA_1}/\frac{CS_6}{CS_6}$	$\frac{PA_4/TP_4}{TIOCA_1}/\frac{CS_6}{CS_6}$	PA4/TP4/ TIOCA1/ A23/ CS 6	PA₄/TP₄/ TIOCA1	NC	NC	
98	$\begin{array}{c} PA_{5}/TP_{5}/\\ TIOCB_{1}/\\ \overline{CS}_{5} \end{array}$	$\begin{array}{c} PA_{5}/TP_{5}/\\ TIOCB_{1}/\\ \overline{CS}_{5} \end{array}$	$\frac{PA_5/TP_5}{TIOCB_1}/\frac{TIOCB_1}{CS_5}$	$\frac{PA_5/TP_5}{TIOCB_1}/\frac{TIOCB_1}{CS_5}$	$\frac{PA_5/TP_5}{TIOCB_1}/\frac{TIOCB_1}{CS_5}$	$\begin{array}{l} PA_5/TP_5/\\ TIOCB_1/\\ A_{22}/\overline{CS}_5 \end{array}$	PA₅/TP₅/ TIOCB1	NC	NC	
99	$\frac{PA_6/TP_6/}{TIOCA_2/}$	$\frac{PA_6/TP_6/}{TIOCA_2/}$	$\frac{PA_6/TP_6/}{TIOCA_2/}$	$\frac{PA_6/TP_6/}{TIOCA_2/}$	$\frac{PA_6/TP_6/}{TIOCA_2/}$	PA ₆ /TP ₆ / TIOCA ₂ / A ₂₁ / CS ₄	PA ₆ /TP ₆ / TIOCA ₂	NC	NC	
100	PA ₇ /TP ₇ / TIOCB ₂	PA ₇ /TP ₇ / TIOCB ₂	A ₂₀	A ₂₀	PA ₇ /TP ₇ / TIOCB ₂	A ₂₀	PA ₇ /TP ₇ / TIOCB ₂	NC	NC	

Notes: 1. In modes 1, 3, 5, and 6 the P4₀ to P4₇ functions of pins P4₀/D₀ to P4₇/D₇ are selected after a reset, but they can be changed by software.

2. In modes 2 and 4 the D_0 to D_7 functions of pins $P4_0/D_0$ to $P4_7/D_7$ are selected after a reset, but they can be changed by software.

3. For the H8/3048 ZTAT version, H8/3048F version, H8/3048 mask ROM version, H8/3047 mask ROM version, H8/3045 mask ROM version, and H8/3044 mask ROM version, this pin is also used as the V_{CC} terminal.

 For the H8/3048 ZTAT version, H8/3048F version, H8/3048 mask ROM version, H8/3047 mask ROM version, H8/3045 mask ROM version, and H8/3044 mask ROM version, this pin is used as the RESO terminal.



1.3.3 Pin Functions

Table 1.4 summarizes the pin functions.

Туре	Symbol	Pin No.	I/O	Name	and Fund	tion		
Power	Vcc	1, 35, 68	Input	Power: For connection to the power supply. Connect all V_{CC} pins to the system power supply.				
	V _{SS}	11, 22, 44, 57, 65, 92	Input		ct all V _{SS}		to ground (0 V). e 0-V system	
Clock	XTAL	67	Input	For exa externa	amples of	crystal re put, see s	al resonator. esonator and section 20, Clock	
	EXTAL	66	Input	For connection to a crystal resonator or input of an external clock signal. For examples of crystal resonator and extern clock input, see section 20, Clock Pulse Generator.			signal. For ator and external	
	φ	61	Output	System clock: Supplies the system clock to external devices.				
Operating mode control	MD ₂ to MD ₀	75 to 73	Input	operati	ng mode,	as follow	etting the vs. Inputs at these d during operation.	
				MD_2	MD ₁	MD ₀	Operating Mode	
				0	0	0		
				0	0	1	Mode 1	
				0	1	0	Mode 2	
				0	1	1	Mode 3	
				1	0	0	Mode 4	
				1	0	1	Mode 5	
				1	1	0	Mode 6	
				1	1	1	Mode 7	

Table 1.4Pin Functions

Туре	Symbol	Pin No.	I/O	Name and Function
System control	RES	63	Input	Reset input: When driven low, this pin resets the chip
	RESO	10 Output		Reset output: For the mask ROM version, outputs a reset signal to external devices
	$(\overline{\text{RESO}}/V_{PP})$			Also used as a power supply for on-board programming of the flash memory version with dual power supply.
	STBY	62	Input	Standby: When driven low, this pin forces a transition to hardware standby mode
	BREQ	59	Input	Bus request: Used by an external bus master to request the bus right
	BACK	60	Output	Bus request acknowledge: Indicates that the bus has been granted to an external bus master
Interrupts	NMI	64	Input	Nonmaskable interrupt: Requests a nonmaskable interrupt
	IRQ₅ to IRQ₀	17, 16, 90 to 87	Input	Interrupt request 5 to 0: Maskable interrupt request pins
Address bus	A ₂₃ to A ₀	97 to 100, 56 to 45, 43 to 36	Output	Address bus: Outputs address signals
Data bus	D_{15} to D_0	34 to 23, 21 to 18	Input/ output	Data bus: Bidirectional data bus
Bus control	\overline{CS}_7 to \overline{CS}_0	8, 97 to 99, 88 to 91	Output	Chip select: Select signals for areas 7 to 0
	ĀS	69	Output	Address strobe: Goes low to indicate valid address output on the address bus
	RD	70	Output	Read: Goes low to indicate reading from the external address space
	HWR	71	Output	High write: Goes low to indicate writing to the external address space; indicates valid data on the upper data bus (D_{15} to D_8).
	LWR	72	Output	Low write: Goes low to indicate writing to the external address space; indicates valid data on the lower data bus $(D_7 \text{ to } D_0)$.
	WAIT	58	Input	Wait: Requests insertion of wait states in bus cycles during access to the external address space

Section 1 Overview

Туре	Symbol	Pin No.	I/O	Name and Function
Refresh	RFSH	87	Output	Refresh: Indicates a refresh cycle
controller	\overline{CS}_3	88	Output	Row address strobe RAS : Row address strobe signal for DRAM connected to area 3
	RD	70	Output	Column address strobe CAS : Column address strobe signal for DRAM connected to area 3; used with 2WE DRAM.
				Write enable \overline{WE} : Write enable signal for DRAM connected to area 3; used with 2 \overline{CAS} DRAM.
	HWR	71	Output	Upper write \overline{UW} : Write enable signal for DRAM connected to area 3; used with $2\overline{WE}$ DRAM.
				Upper column address strobe UCAS: Column address strobe signal for DRAM connected to area 3; used with 2CAS DRAM.
	LWR	72	Output	Lower write \overline{LW} : Write enable signal for DRAM connected to area 3; used with $2\overline{WE}$ DRAM.
				Lower column address strobe LCAS: Column address strobe signal for DRAM connected to area 3; used with 2CAS DRAM.
DMA controller (DMAC)	$\overline{\text{DREQ}}_{1}, \\ \overline{\text{DREQ}}_{0}$	9, 8	Input	DMA request 1 and 0: DMAC activation requests
	$\frac{\overline{TEND}_1}{\overline{TEND}_0}$	94, 93	Output	Transfer end 1 and 0: These signals indicate that the DMAC has ended a data transfer
16-bit integrated timer unit (ITU)	TCLKD to TCLKA	96 to 93	Input	Clock input D to A: External clock inputs
	TIOCA ₄ to TIOCA ₀	4, 2, 99, 97, 95	Input/ output	Input capture/output compare A4 to A0: GRA4 to GRA0 output compare or input capture, or PWM output
	TIOCB ₄ to TIOCB ₀	5, 3, 100, 98, 96	Input/ output	Input capture/output compare B4 to B0: GRB4 to GRB0 output compare or input capture
	TOCXA ₄	6	Output	Output compare XA4: PWM output
	TOCXB ₄	7	Output	Output compare XB4: PWM output

Туре	Symbol	Pin No.	I/O	Name and Function
Programmable timing pattern controller (TPC)	TP ₁₅ to TP ₀	9 to 2, 100 to 93	Output	TPC output 15 to 0: Pulse output
Serial communication	TxD ₁ , TxD ₀	13, 12	Output	Transmit data (channels 0 and 1): SCI data output
interface (SCI)	RxD ₁ , RxD ₀	15, 14	Input	Receive data (channels 0 and 1): SCI data input
	SCK ₁ , SCK ₀	17, 16	Input/ output	Serial clock (channels 0 and 1): SCI clock input/output
A/D converter	AN_7 to AN_0	85 to 78	Input	Analog 7 to 0: Analog input pins
	ADTRG	9	Input	A/D trigger: External trigger input for starting A/D conversion
D/A converter	DA ₁ , DA ₀	85, 84	Output	Analog output: Analog output from the D/A converter
A/D and D/A converters	AV _{CC}	76	Input	Power supply pin for the A/D and D/A converters. Connect to the system power supply (V_{CC}) when not using the A/D and D/A converters.
	AV _{SS}	86	Input	Ground pin for the A/D and D/A converters. Connect to system ground (V_{SS}).
	V _{REF}	77	Input	Reference voltage input pin for the A/D and D/A converters. Connect to the system power supply (V_{CC}) when not using the A/D and D/A converters.
I/O ports	P17 to P10	43 to 36	Input/ output	Port 1: Eight input/output pins. The direction of each pin can be selected in the port 1 data direction register (P1DDR).
	P27 to P20	52 to 45	Input/ output	Port 2: Eight input/output pins. The direction of each pin can be selected in the port 2 data direction register (P2DDR).
	P37 to P30	34 to 27	Input/ output	Port 3: Eight input/output pins. The direction of each pin can be selected in the port 3 data direction register (P3DDR).
	P4 ₇ to P4 ₀	26 to 23, 21 to 18	Input/ output	Port 4: Eight input/output pins. The direction of each pin can be selected in the port 4 data direction register (P4DDR).
	$P5_3$ to $P5_0$	56 to 53	Input/ output	Port 5: Four input/output pins. The direction of each pin can be selected in the port 5 data direction register (P5DDR).

Section 1 Overview

Туре	Symbol	Pin No.	I/O	Name and Function
I/O ports	P6 ₆ to P6 ₀	72 to 69, 60 to 58	Input/ output	Port 6: Seven input/output pins. The direction of each pin can be selected in the port 6 data direction register (P6DDR).
	P77 to P70	85 to 78	Input	Port 7: Eight input pins
	P84 to P80	91 to 87	Input/ output	Port 8: Five input/output pins. The direction of each pin can be selected in the port 8 data direction register (P8DDR).
	P9 ₅ to P9 ₀	17 to 12	Input/ output	Port 9: Six input/output pins. The direction of each pin can be selected in the port 9 data direction register (P9DDR).
	PA ₇ to PA ₀	100 to 93	Input/ output	Port A: Eight input/output pins. The direction of each pin can be selected in the port A data direction register (PADDR).
	PB_7 to PB_0	PB ₇ to PB ₀ 9 to 2 In or		Port B: Eight input/output pins. The direction of each pin can be selected in the port B data direction register (PBDDR).

Section 1 Overview

1.4 Differences between H8/3048F and H8/3048F-ONE

Table 1.5 shows the differences between the H8/3048F (dual power supply model) and H8/3048F-ONE (single power supply model).

ltem	Models with Dual Power Supply: H8/3048F	Models with Single Power Supply: H8/3048F-ONE*				
Pin specifications	Pin 1: V _{CC}	Pin 1: V _{CL} (when a model which operates at 5 V is used)				
		Connected to V_{SS} with 0.1 μ F externally applied. Pin 1 becomes V_{CC} when a model which operates at 3 V is used.				
	Pin 10: V _{PP} /RESO	Pin 10: FWE				
ROM/RAM	128-kbyte flash memory with dual power supply, RAM: 4 kbytes	128-kbyte flash memory with single power supply, RAM: 4 kbytes				
Units of on- board writing	Writing in 1-byte units	Writing in 128-byte units				
Write/erase voltage	12 V is externally applied from V_{PP} pin	Application of 12 V is not required. V_{CC} single power supply				
V _{PP} pin functions	Multiplexes with RESO	FWE function only (no RESO function)				
Boot mode settings	MD2 MD1 MD0 Mode 5 12 V 0 1 Mode 6 12 V 1 0 Mode 7 12 V 1 1 Cancelled by reset	MD2 MD1 MD0 Mode 5 0 0 1 Mode 6 0 1 0 Mode 7 0 1 1 Set to mode 1 in mode 5 Set to mode 2 in mode 6 Set to mode 3 in mode 7 Cancelled by reset				
Settings for user program mode	MD2 MD1 MD0 Mode 5 1 0 1 Mode 6 1 1 0 Mode 7 1 1 1	MDE MD1 MD0 Mode 5 1 0 1 Mode 6 1 1 0 Mode 7 1 1 1 Cancelled by reset X X X				
Prewrite processing	Necessary before erasing	Not necessary				
Erasing blocks	More than one block can be erased at the same time (verifies in block units and erases only the unerased blocks)	Erases in one block units. More than one block cannot be erased at the same time (the erasing flow is different)				

Table 1.5 Differences between H8/3048F and H8/3048F-ONE

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Item	Models with Dual Power Supply: H8/3048F	Models with Single Power Supply: H8/3048F-ONE*				
Write processing	Before writing, sets the block with the address to be written to EBR1/EBR2	No setting				
FLMCR	FLMCR (H'FF40)	FLMCR1 (H'FF40)				
	V _{PP} V _{PP} E — — EV PV E P	FWE SWE ESU PSU EV PV E P				
		FLMCR2 (H'FF41)				
		FLER — — — — — — —				
EBR	EBR1 (H'FF42)	EBR (H'FF42)				
	LB7 LB6 LB5 LB4 LB3 LB2 LB1 LB0	EB7 EB6 EB5 EB4 EB3 EB2 EB1 EB0				
	EBR2 (H'FF43)	Only one block can be selected(setting				
	SB7 SB6 SB5 SB4 SB3 SB2 SB1 SB0	for erasing)				
	More than one block can be selected (setting for writing/erasing)	-				
RAMCR	RAMCR (H'FF48)	RAMCR (H'FF47)				
	FLER RAMS RAM2 RAM1 RAM0	RAMS RAM2 RAM1 _				
Division of	Division in 16 blocks	Division in 8 blocks				
flash memory	16 kbytes \times 7: LB0 to LB6	1 kbyte \times 4: EB0 to EB3				
block	12 kbytes \times 1: LB7	28 kbytes \times 1: EB4				
	512 kbytes \times 8: SB0 to SB7	32 kbytes \times 3: EB5 to EB7				
	Flash memory	Flash memory				
	LB0 (16 kbytes)	H'00000 EB0 (1 kbyte)				
	LB1 (16 kbytes)	EB1 (1 kbyte)				
	LB2 (16 kbytes)	EB2 (1 kbyte)				
	LB3 (16 kbytes)	EB3 (1 kbyte)				
	LB4 (16 kbytes)	EB4 (28 kbytes)				
	LB5 (16 kbytes)	EB5 (32 kbytes)				
	LB6 (16 kbytes)	EB6 (32 kbytes)				
	LB7 (12 kbytes)	EB7 (32 kbytes)				
	SB0 (512 bytes)	H'1FFFF				
	SB1 (512 bytes)					
	SB2 (512 bytes)					
	SB3 (512 bytes)					
	SB4 (512 bytes)					
	SB5 (512 bytes)					
	SB6 (512 bytes)					
	SB7 (512 bytes) H'1FFFF					

Item	Models with Dual H8/3048F	Power Supply:	Models with Single Power Supply: H8/3048F-ONE*			
Division of RAM emulation block			On-chip RAM Flash memory			
	H'EF10 H'F000 H'F1FF	H'00000 H'1EFFF H'1F000 H'1F200 H'1F400 H'1F600 H'1F600 H'1F800 H'1FC00 H'1FC00 H'1FFFF	H'EF10 H'F000 H'F3FF H'FF0F	H'00000 H'00400 H'00800 H'00C00 H'01000 H'11FFFF		
Reset during operation	at least 6 system c	ust be kept low during lock (6 ϕ) cycles. RESW = min. 6.0 t _{cyc})	at least 20 system	ust be kept low during clock (20ϕ) cycles. _{RESW} = min. 20 t _{cyc})		
A/D ADCR	ADCR (H'FFE9)		ADCR (H'FFE9)			
	Initial value: H'7F		Initial value: H'7E			
	Only bit 7 can be re	ead or written.	Only bit 7 can be r	ead or written.		
	Other bits are rese as 1; writing to the	rved and always read se bits is invalid.	Bit 0 is reserved an 1.	nd must not be set to		
			Other bits are rese as 1; writing to the	rved and always read se bits is invalid.		
WDT RSTCSR	RSTCSR (H'FFAB)	RSTCSR (H'FFAB)		
	Initial value: H'3F		Initial value: H'3F			
	Only bits 7 and 6 c	an be read or written.	Only bit 7 can be r	ead or written.		
	Other bits are rese as 1; writing to the	rved and always read se bits is invalid.	Bit 6 is reserved an 1.	nd must not be set to		
			Other bits are rese as 1; writing to the	rved and always read se bits is invalid.		

ltem	Model H8/304		Dual P	ower Supply:	Models with Single Power Supply: H8/3048F-ONE*			
Clock oscillator settling time (SYSCR STS2–	bits 2 t		ndby tir	mer select	Setting of standby timer select bits 2 to 0			
(313CK 3132- STS0)	STS2	STS1	STS0	Description	STS2	STS1	STS0	Description
0100)	0	0	0	8,192 states	0 0	0	0	8,192 states
			1	16,384 states			1	16,384 states
		1	0	32,768 states		1	0	32,768 states
			1	65,536 states			1	65,536 states
	1	0	0	131,072 states	1	0	0	131,072 states
			1	1,024 states			1	262,144 states
		1		Illegal setting		1	0	1,024 states
		1					1	Illegal setting
Details on flash memory				Flash Memory ver Supply).	Refer to section 18, Flash Memory (H8/3048F-ONE, Single Power Supply)			
Electrical	Clock r	Hz	Clock rate: 2 to 25 MHz					
characteristics (clock rate)		Table 22.1 stics of H8/3048	Refer to section 21, Table 21.1 Electrical Characteristics of H8/3048 Group Products.					
List of registers		arison c	of H8/30	Table B.1 048 Group Internal ation	Refer to appendix B, Table B.1 Comparison of H8/3048 Group Internal I/O Register Specification			
Refer to appendix B.1, Addresses (For H8/3048F, H8/3048ZTAT, H8/3048 mask-ROM, H8/3047 mask- ROM, H8/3045 mask-ROM, and H8/3044 mask-ROM Versions)			Refer to appendix B.1, Addresses (For H8/3048F-ONE)					
On-chip emulator	—				On-chi	p emul	ator (E ⁻	10T)
	o the "Ha		-ONE,	H8/3048F-ZTAT™	' Hardwa	re Mar	iual" foi	r information about

H8/3048F-ONE.



Section 2 CPU

2.1 Overview

The H8/300H CPU is a high-speed central processing unit with an internal 32-bit architecture that is upward-compatible with the H8/300 CPU. The H8/300H CPU has sixteen 16-bit general registers, can address a 16-Mbyte linear address space, and is ideal for realtime control.

2.1.1 Features

The H8/300H CPU has the following features.

Upward compatibility with H8/300 CPU Can execute H8/300 Series object programs

General-register architecture Sixteen 16-bit general registers (also usable as sixteen 8-bit registers or eight 32-bit registers)

Sixty-two basic instructions

- 8/16/32-bit data transfer and arithmetic and logic instructions
- Multiply and divide instructions
- Powerful bit-manipulation instructions

Eight addressing modes

- Register direct [Rn]
- Register indirect [@ERn]
- Register indirect with displacement [@(d:16, ERn) or @(d:24, ERn)]
- Register indirect with post-increment or pre-decrement [@ERn+ or @-ERn]
- Absolute address [@aa:8, @aa:16, or @aa:24]
- Immediate [#xx:8, #xx:16, or #xx:32]
- Program-counter relative [@(d:8, PC) or @(d:16, PC)]
- Memory indirect [@@aa:8]

16-Mbyte linear address space

High-speed operation

- All frequently-used instructions execute in two to four states
- Maximum clock frequency:

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18 MHz (H8/3048ZTAT, H8/3048 mask ROM, H8/3047 mask ROM, H8/3045 mask ROM, H8/3044 mask ROM)

- 16 MHz (H8/3048F)
- 8/16/32-bit register-register add/subtract: 111 ns @ 18 MHz/125 ns @ 16 MHz
- 8 × 8-bit register-register multiply:
- $-16 \div 8$ -bit register-register divide:
- 16×16 -bit register-register multiply:
- $-32 \div 16$ -bit register-register divide:

Two CPU operating modes

- 778 ns @ 18 MHz/875 ns @ 16 MHz
- 1,221 ns @ 18 MHz/1,375 ns @ 16 MHz
 - 1,221 ns @ 18 MHz/1,375 ns @ 16 MHz

778 ns @ 18 MHz/875 ns @ 16 MHz

- Normal mode (not available in the H8/3048 Group)

- Advanced mode

Low-power mode

Transition to power-down state by SLEEP instruction

2.1.2 Differences from H8/300 CPU

In comparison to the H8/300 CPU, the H8/300H has the following enhancements.

• More general registers

Eight 16-bit registers have been added.

- Expanded address space
 - Advanced mode supports a maximum 16-Mbyte address space.
 - Normal mode supports the same 64-kbyte address space as the H8/300 CPU. (Normal mode is not available in the H8/3048 Group.)
- Enhanced addressing

The addressing modes have been enhanced to make effective use of the 16-Mbyte address space.

- Enhanced instructions
 - Data transfer, arithmetic, and logic instructions can operate on 32-bit data.
 - Signed multiply/divide instructions and other instructions have been added.



2.2 CPU Operating Modes

The H8/300H CPU has two operating modes: normal and advanced. Normal mode supports a maximum 64-kbyte address space. Advanced mode supports up to 16 Mbytes. See figure 2.1.

The H8/3048 Group can be used only in advanced mode. (Information from this point on will apply to advanced mode unless otherwise stated.)

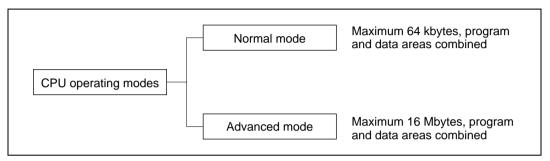


Figure 2.1 CPU Operating Modes

2.3 Address Space

The maximum address space of the H8/300H CPU is 16 Mbytes. The H8/3048 Group has various operating modes (MCU modes), some providing a 1-Mbyte address space, the others supporting the full 16 Mbytes.

Figure 2.2 shows the address ranges of the H8/3048 Group. For further details see section 3.6, Memory Map in Each Operating Mode.

The 1-Mbyte operating modes use 20-bit addressing. The upper 4 bits of effective addresses are ignored.

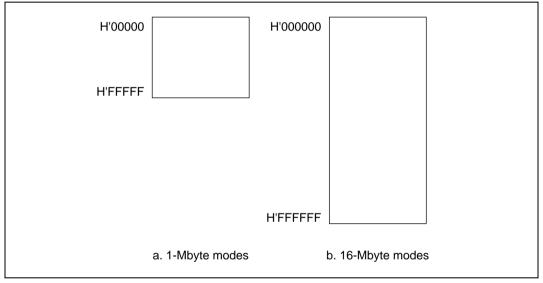
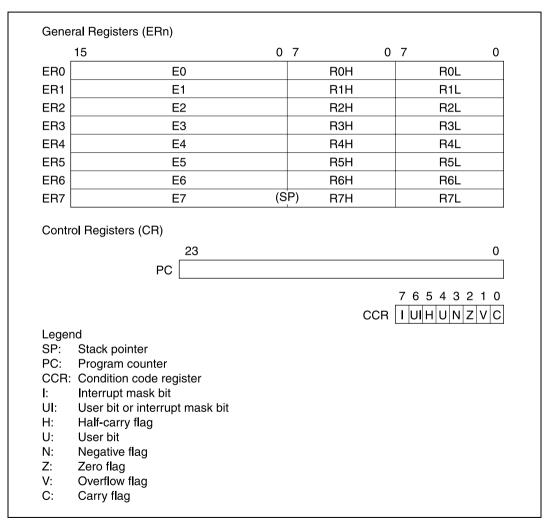


Figure 2.2 Memory Map

2.4 Register Configuration

2.4.1 Overview

The H8/300H CPU has the internal registers shown in figure 2.3. There are two types of registers: general registers and control registers.





2.4.2 General Registers

The H8/300H CPU has eight 32-bit general registers. These general registers are all functionally alike and can be used without distinction between data registers and address registers. When a general register is used as a data register, it can be accessed as a 32-bit, 16-bit, or 8-bit register. When the general registers are used as 32-bit registers or as address registers, they are designated by the letters ER (ER0 to ER7).

The ER registers divide into 16-bit general registers designated by the letters E (E0 to E7) and R (R0 to R7). These registers are functionally equivalent, providing a maximum sixteen 16-bit registers. The E registers (E0 to E7) are also referred to as extended registers.

The R registers divide into 8-bit general registers designated by the letters RH (R0H to R7H) and RL (R0L to R7L). These registers are functionally equivalent, providing a maximum sixteen 8-bit registers.

Figure 2.4 illustrates the usage of the general registers. The usage of each register can be selected independently.

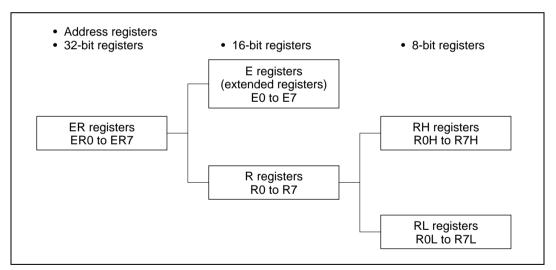


Figure 2.4 Usage of General Registers

General register ER7 has the function of stack pointer (SP) in addition to its general-register function, and is used implicitly in exception handling and subroutine calls. Figure 2.5 shows the stack.

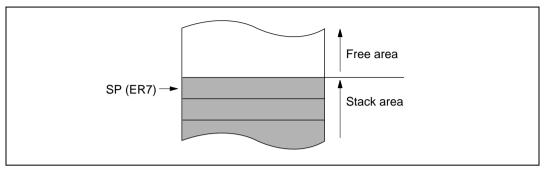


Figure 2.5 Stack

2.4.3 Control Registers

The control registers are the 24-bit program counter (PC) and the 8-bit condition code register (CCR).

Program Counter (PC): This 24-bit counter indicates the address of the next instruction the CPU will execute. The length of all CPU instructions is 2 bytes (one word) or a multiple of 2 bytes, so the least significant PC bit is ignored. When an instruction is fetched, the least significant PC bit is regarded as 0.

Condition Code Register (CCR): This 8-bit register contains internal CPU status information, including the interrupt mask bit (I) and half-carry (H), negative (N), zero (Z), overflow (V), and carry (C) flags.

- Bit 7—Interrupt Mask Bit (I): Masks interrupts other than NMI when set to 1. NMI is accepted regardless of the I bit setting. The I bit is set to 1 at the start of an exception-handling sequence.
- Bit 6—User Bit or Interrupt Mask Bit (UI): Can be written and read by software using the LDC, STC, ANDC, ORC, and XORC instructions. This bit can also be used as an interrupt mask bit. For details see section 5, Interrupt Controller.
- Bit 5—Half-Carry Flag (H): When the ADD.B, ADDX.B, SUB.B, SUBX.B, CMP.B, or NEG.B instruction is executed, this flag is set to 1 if there is a carry or borrow at bit 3, and cleared to 0 otherwise. When the ADD.W, SUB.W, CMP.W, or NEG.W instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 11, and cleared to 0 otherwise.

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When the ADD.L, SUB.L, CMP.L, or NEG.L instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 27, and cleared to 0 otherwise.

- Bit 4—User Bit (U): Can be written and read by software using the LDC, STC, ANDC, ORC, and XORC instructions.
- Bit 3—Negative Flag (N): Indicates the most significant bit (sign bit) of data.
- Bit 2—Zero Flag (Z): Set to 1 to indicate zero data, and cleared to 0 to indicate non-zero data.
- Bit 1—Overflow Flag (V): Set to 1 when an arithmetic overflow occurs, and cleared to 0 at other times.
- Bit 0—Carry Flag (C): Set to 1 when a carry occurs, and cleared to 0 otherwise. Used by:
 - Add instructions, to indicate a carry
 - Subtract instructions, to indicate a borrow
 - Shift and rotate instructions, to store the value shifted out of the end bit

The carry flag is also used as a bit accumulator by bit manipulation instructions.

Some instructions leave flag bits unchanged. Operations can be performed on CCR by the LDC, STC, ANDC, ORC, and XORC instructions. The N, Z, V, and C flags are used by conditional branch (Bcc) instructions.

For the action of each instruction on the flag bits, see appendix A.1, Instruction List. For the I and UI bits, see section 5, Interrupt Controller.

2.4.4 Initial CPU Register Values

In reset exception handling, PC is initialized to a value loaded from the vector table, and the I bit in CCR is set to 1. The other CCR bits and the general registers are not initialized. In particular, the stack pointer (ER7) is not initialized. The stack pointer must therefore be initialized by an MOV.L instruction executed immediately after a reset.



2.5 Data Formats

The H8/300H CPU can process 1-bit, 4-bit (BCD), 8-bit (byte), 16-bit (word), and 32-bit (longword) data. Bit-manipulation instructions operate on 1-bit data by accessing bit n (n = 0, 1, 2, ..., 7) of byte operand data. The DAA and DAS decimal-adjust instructions treat byte data as two digits of 4-bit BCD data.

2.5.1 General Register Data Formats

Figures 2.6 and 2.7 show the data formats in general registers.

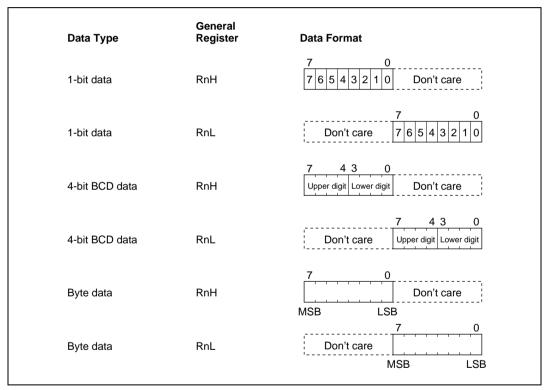


Figure 2.6 General Register Data Formats (1)

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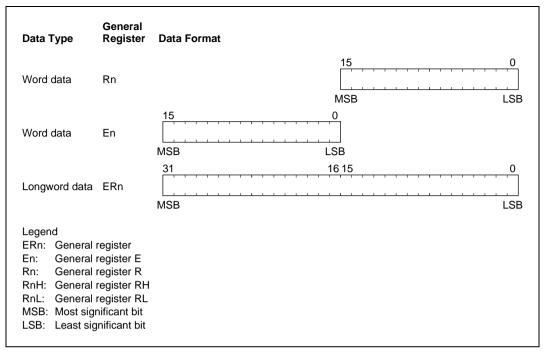


Figure 2.7 General Register Data Formats (2)



2.5.2 Memory Data Formats

Figure 2.8 shows the data formats on memory. The H8/300H CPU can access word data and longword data on memory, but word or longword data must begin at an even address. If an attempt is made to access word or longword data at an odd address, no address error occurs but the least significant bit of the address is regarded as 0, so the access starts at the preceding address. This also applies to instruction fetches.

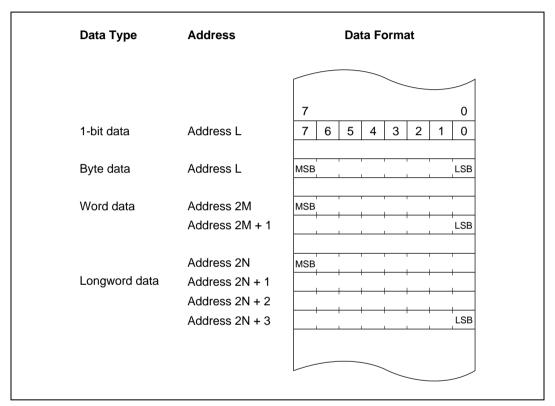


Figure 2.8 Memory Data Formats

When ER7 (SP) is used as an address register to access the stack, the operand size should be word size or longword size.

Renesas

2.6 Instruction Set

2.6.1 Instruction Set Overview

The H8/300H CPU has 62 types of instructions, which are classified in table 2.1.

Function	Instruction	Types
Data transfer	MOV, PUSH ^{*1} , POP ^{*1} , MOVTPE ^{*2} , MOVFPE ^{*2}	3
Arithmetic operatiozns	ADD, SUB, ADDX, SUBX, INC, DEC, ADDS, SUBS, DAA, DAS, MULXU, MULXS, DIVXU, DIVXS, CMP, NEG, EXTS, EXTU	18
Logic operations	AND, OR, XOR, NOT	4
Shift operations	SHAL, SHAR, SHLL, SHLR, ROTL, ROTR, ROTXL, ROTXR	8
Bit manipulation	BSET, BCLR, BNOT, BTST, BAND, BIAND, BOR, BIOR, BXOR, BIXOR, BLD, BILD, BST, BIST	14
Branch	Bcc* ³ , JMP, BSR, JSR, RTS	5
System control	TRAPA, RTE, SLEEP, LDC, STC, ANDC, ORC, XORC, NOP	9
Block data transfer	EEPMOV	1

Table 2.1Instruction Classification

Total 62 types

- Notes: 1. POP.W Rn is identical to MOV.W @SP+, Rn. PUSH.W Rn is identical to MOV.W Rn, @–SP. POP.L ERn is identical to MOV.L @SP+, Rn. PUSH.L ERn is identical to MOV.L Rn, @–SP.
 - 2. Not available in the H8/3048 Group.
 - 3. Bcc is a generic branching instruction.



2.6.2 Instructions and Addressing Modes

Table 2.2 indicates the instructions available in the H8/300H CPU.

 Table 2.2
 Instructions and Addressing Modes

							Addre	ssing	Modes					
Function	Instruction	XX#	Rn	@ERn	@ (d:16,ERn)	@ (d:24,ERn)	@ERn+/@-ERn	@ aa:8	@aa:16	@ aa:24	@ (d:8,PC)	@ (d:16,PC)	@ @ aa:8	I
Data	MOV	BWL	BWL	BWL	BWL	BWL	BWL	В	BWL	BWL		—	—	—
transfer	POP, PUSH	_	_	_	_	_	—		—	—		_	_	WL
	MOVFPE*, MOVTPE*	—	—	—	—	—	_		В	—		—	—	—
Arithmetic	ADD, CMP	BWL	BWL	—	—	—	—	-	_	—		—	—	—
operations	SUB	WL	BWL	—	—	—	—		—	—		—	—	—
	ADDX, SUBX	В	В	—	_	_	—	_	_	_		_	_	—
	ADDS, SUBS	_	L	—	_	_	—	_	_	_		_	_	—
	INC, DEC	_	BWL	—	_	—	_		_	—		—	—	—
	DAA, DAS	_	В	—	_	—	_		_	—		—	—	—
	MULXU, MULXS, DIVXU, DIVXS	-	BW	-	—	—	-		_	-		—	—	—
	NEG	_	BWL	—	—	—	—	-	_	—		—	—	—
	EXTU, EXTS	—	WL	—	—	—	—		—	—		—	—	—
Logic	AND, OR, XOR	BWL	BWL	—	_	—	_		_	—		—	—	—
operations	NOT	_	BWL	—	_	—	_		_	—		—	—	—
Shift instruc	tions	_	BWL	—	_	—	_		_	—		—	—	—
Bit manipula	ation	_	В	В	_	—	_	В	_	_	_	—	_	—
Branch	Bcc, BSR	_	_	—	_	—	_		_	—	0	0	—	—
	JMP, JSR	_	_	0	_	—	_		_	0		—	0	—
	RTS	_	_	_	_	_	_		—	_		_	_	0
System	TRAPA	_	_	—	_	—	_	_	_	_	_	—	_	0
control	RTE	_	_	—	_	—	_		_	—		—	—	0
	SLEEP	-	—	—	_	_	—	—	—	—	—	_	_	0
	LDC	В	В	W	W	W	W		W	W	_	_	_	_
	STC	—	В	W	W	W	W		W	W		—	—	—
	ANDC, ORC, XORC	В	-	-	—	-	-	_	-	-	—	-	-	-
	NOP	_	—	—	—	—	—	_	—	—	_	—	—	0
Block data t	ransfer	—	—	—	—	—	—	—	—	—		—	—	BW

Legend

B: Byte

W: Word

L: Longword

Note: * Not availabe in the H8/3048 Group.

2.6.3 Tables of Instructions Classified by Function

Tables 2.3 to 2.10 summarize the instructions in each functional category. The operation notation used in these tables is defined next.

Operation Notation

Rd	General register (destination)*
Rs	General register (source)*
Rn	General register*
ERn	General register (32-bit register or address register)
(EAd)	Destination operand
(EAs)	Source operand
CCR	Condition code register
Ν	N (negative) flag of CCR
Z	Z (zero) flag of CCR
V	V (overflow) flag of CCR
С	C (carry) flag of CCR
PC	Program counter
SP	Stack pointer
#IMM	Immediate data
disp	Displacement
+	Addition
-	Subtraction
×	Multiplication
÷	Division
^	AND logical
V	OR logical
\oplus	Exclusive OR logical
\rightarrow	Move
	NOT (logical complement)
:3/:8/:16/:24	3-, 8-, 16-, or 24-bit length

Note: * General registers include 8-bit registers (R0H to R7H, R0L to R7L), 16-bit registers (R0 to R7, E0 to E7), and 32-bit data or address registers (ER0 to ER7).

Instruction	Size*	Function
MOV	B/W/L	$(EAs) \to Rd, Rs \to (EAd)$
		Moves data between two general registers or between a general register and memory, or moves immediate data to a general register.
MOVFPE	В	$(EAs) \to Rd$
		Cannot be used in the H8/3048 Group.
MOVTPE	В	$Rs \rightarrow (EAs)$
		Cannot be used in the H8/3048 Group.
POP	W/L	$@SP+ \rightarrow Rn$
		Pops a general register from the stack. POP.W Rn is identical to MOV.W @SP+, Rn. Similarly, POP.L ERn is identical to MOV.L @SP+, ERn.
PUSH	W/L	$Rn \rightarrow @-SP$
		Pushes a general register onto the stack. PUSH.W Rn is identical to MOV.W Rn, @–SP. Similarly, PUSH.L ERn is identical to MOV.L ERn, @–SP.

Table 2.3Data Transfer Instructions

Note: * Size refers to the operand size.

B: Byte

W: Word

L: Longword

Table 2.4 Arithmetic Operation Instructions

Instruction	Size*	Function
ADD, SUB	B/W/L	$Rd \pm Rs \to Rd, Rd \pm \#IMM \to Rd$
		Performs addition or subtraction on data in two general registers, or on immediate data and data in a general register. (Immediate byte data cannot be subtracted from data in a general register. Use the SUBX or ADD instruction.)
ADDX, SUBX	В	$Rd \pm Rs \pm C \to Rd, Rd \pm \#IMM \pm C \to Rd$
		Performs addition or subtraction with carry or borrow on data in two general registers, or on immediate data and data in a general register.
INC, DEC	B/W/L	$Rd \pm 1 \to Rd, Rd \pm 2 \to Rd$
		Increments or decrements a general register by 1 or 2. (Byte operands can be incremented or decremented by 1 only.)
ADDS, SUBS	L	$Rd \pm 1 \to Rd, Rd \pm 2 \to Rd, Rd \pm 4 \to Rd$
		Adds or subtracts the value 1, 2, or 4 to or from data in a 32-bit register.
DAA, DAS	В	Rd decimal adjust \rightarrow Rd
		Decimal-adjusts an addition or subtraction result in a general register by referring to CCR to produce 4-bit BCD data.
MULXU	B/W	$Rd \times Rs \to Rd$
		Performs unsigned multiplication on data in two general registers: either 8 bits \times 8 bits \rightarrow 16 bits or 16 bits \times 16 bits \rightarrow 32 bits.
MULXS	B/W	$Rd \times Rs \to Rd$
		Performs signed multiplication on data in two general registers: either 8 bits \times 8 bits \rightarrow 16 bits or 16 bits \times 16 bits \rightarrow 32 bits.
Note: * Size ref	ers to the or	

Note: * Size refers to the operand size.

- B: Byte
- W: Word
- L: Longword

Instruction	Size*	Function
DIVXU	B/W	$Rd \div Rs \to Rd$
		Performs unsigned division on data in two general registers: either 16 bits \div 8 bits \rightarrow 8-bit quotient and 8-bit remainder or 32 bits \div 16 bits \rightarrow 16-bit quotient and 16-bit remainder.
DIVXS	B/W	$Rd \div Rs \to Rd$
		Performs signed division on data in two general registers: either 16 bits \div 8 bits \rightarrow 8-bit quotient and 8-bit remainder, or 32 bits \div 16 bits \rightarrow 16-bit quotient and 16-bit remainder.
CMP	B/W/L	Rd – Rs, Rd – #IMM
		Compares data in a general register with data in another general register or with immediate data, and sets CCR according to the result.
NEG	B/W/L	$0 - Rd \rightarrow Rd$
		Takes the two's complement (arithmetic complement) of data in a general register.
EXTS	W/L	Rd (sign extension) \rightarrow Rd
		Extends byte data in the lower 8 bits of a 16-bit register to word data, or extends word data in the lower 16 bits of a 32-bit register to longword data, by extending the sign bit.
EXTU	W/L	Rd (zero extension) \rightarrow Rd
		Extends byte data in the lower 8 bits of a 16-bit register to word data, or extends word data in the lower 16 bits of a 32-bit register to longword data, by padding with zeros.
Note: * Size re	fers to the o	perand size.

B: Byte

W: Word

L: Longword

Instruction	Size*	Function
AND	B/W/L	$Rd \land Rs \to Rd, Rd \land \#IMM \to Rd$
		Performs a logical AND operation on a general register and another general register or immediate data.
OR	B/W/L	$Rd \lor Rs \to Rd, Rd \lor \#IMM \to Rd$
		Performs a logical OR operation on a general register and another general register or immediate data.
XOR	B/W/L	$Rd \oplus Rs \to Rd, Rd \oplus \#IMM \to Rd$
		Performs a logical exclusive OR operation on a general register and another general register or immediate data.
NOT	B/W/L	$\neg Rd \to Rd$
		Takes the one's complement of general register contents.
Note [.] * Size re	fers to the or	nerand size

Note: * Size refers to the operand size.

- B: Byte
- W: Word
- L: Longword

Table 2.6 Shift Instructions

Instruction	Size*	Function
SHAL,	B/W/L	$Rd\ (shift) \to Rd$
SHAR		Performs an arithmetic shift on general register contents.
SHLL,	B/W/L	$Rd (shift) \to Rd$
SHLR		Performs a logical shift on general register contents.
ROTL,	B/W/L	$Rd \text{ (rotate)} \rightarrow Rd$
ROTR		Rotates general register contents.
ROTXL,	B/W/L	$Rd \text{ (rotate)} \rightarrow Rd$
ROTXR		Rotates general register contents through the carry bit.

Note: * Size refers to the operand size.

B: Byte

W: Word

L: Longword

Instruction	Size*	Function
BSET	В	$1 \rightarrow (\text{ of })$
		Sets a specified bit in a general register or memory operand to 1. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BCLR	В	$0 \rightarrow (\text{ of })$
		Clears a specified bit in a general register or memory operand to 0. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BNOT	В	¬ (<bit-no.> of <ead>) → (<bit-no.> of <ead>)</ead></bit-no.></ead></bit-no.>
		Inverts a specified bit in a general register or memory operand. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BTST	В	¬ (<bit-no.> of <ead>) → Z</ead></bit-no.>
		Tests a specified bit in a general register or memory operand and sets or clears the Z flag accordingly. The bit number is specified by 3-bit immediate data or the lower 3 bits of a general register.
BAND	В	$C \land (<\!bit-\!No.\!> of <\!\mathsf{EAd\!\!>}) \to C$
		ANDs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIAND	В	$C \land [\neg (of)] \to C$
		ANDs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag.
		The bit number is specified by 3-bit immediate data.

Table 2.7 Bit Manipulation Instructions

Note: * Size refers to the operand size.

B: Byte

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Instruction	Size*	Function
BOR	В	$C \lor (<\!bit\!-\!No.\!> of <\!\mathsf{EAd\!\!>}) \to C$
		ORs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIOR	В	$C \lor [\neg (<\!bit-\!No.\!> of <\!\mathsf{EAd\!>})] \to C$
		ORs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag.
		The bit number is specified by 3-bit immediate data.
BXOR	В	$C \oplus (<\!bit-No.\!> of <\!EAd\!>) \to C$
		Exclusive-ORs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIXOR	В	$C \oplus [\neg (of)] \to C$
		Exclusive-ORs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag.
		The bit number is specified by 3-bit immediate data.
BLD	В	(<bit-no.> of <ead>) \rightarrow C</ead></bit-no.>
		Transfers a specified bit in a general register or memory operand to the carry flag.
BILD	В	\neg (<bit-no.> of <ead>) \rightarrow C</ead></bit-no.>
		Transfers the inverse of a specified bit in a general register or memory operand to the carry flag.
		The bit number is specified by 3-bit immediate data.
BST	В	$C \rightarrow (\text{ of })$
		Transfers the carry flag value to a specified bit in a general register or memory operand.
BIST	В	$C \rightarrow \neg$ (<bit-no.> of <ead>)</ead></bit-no.>
		Transfers the inverse of the carry flag value to a specified bit in a general register or memory operand.
		The bit number is specified by 3-bit immediate data.

Note: * Size refers to the operand size.

B: Byte



Table 2.8	Branching Instructions	5
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Instruction	Size	Function					
Bcc	—		Branches to a specified address if a specified condition is true. The branching conditions are listed below.				
		Mnemonic	Description	Condition			
		BRA (BT)	Always (true)	Always			
		BRN (BF)	Never (false)	Never			
		BHI	High	C ∨ Z = 0			
		BLS	Low or same	C ∨ Z = 1			
		Bcc (BHS)	Carry clear (high or same)	C = 0			
		BCS (BLO)	Carry set (low)	C = 1			
		BNE	Not equal	Z = 0			
		BEQ	Equal	Z = 1			
		BVC	Overflow clear	V = 0			
		BVS	Overflow set	V = 1			
		BPL	Plus	N = 0			
		BMI	Minus	N = 1			
		BGE	Greater or equal	N ⊕ V = 0			
		BLT	Less than	N ⊕ V = 1			
		BGT	Greater than	$Z \lor (N \oplus V) = 0$			
		BLE	Less or equal	$Z \lor (N \oplus V) = 1$			
JMP	_	Branches unco	onditionally to a specified addres	SS			
BSR	—	Branches to a	subroutine at a specified addres	ŝs			
JSR	_	Branches to a	subroutine at a specified addres	ŝs			
RTS	_	Returns from a	subroutine				

Instruction	Size*	Function		
TRAPA	_	Starts trap-instruction exception handling		
RTE	_	Returns from an exception-handling routine		
SLEEP	_	Causes a transition to the power-down state		
LDC	B/W	$(EAs) \rightarrow CCR$		
		Moves the source operand contents to the condition code register. The condition code register size is one byte, but in transfer from memory, data is read by word access.		
STC	B/W	$CCR \to (EAd)$		
		Transfers the CCR contents to a destination location. The condition code register size is one byte, but in transfer to memory, data is written by word access.		
ANDC	В	$CCR \land \#IMM \to CCR$		
		Logically ANDs the condition code register with immediate data.		
ORC	В	$CCR \lor \#IMM \to CCR$		
		Logically ORs the condition code register with immediate data.		
XORC	В	$CCR \oplus \#IMM \to CCR$		
		Logically exclusive-ORs the condition code register with immediate data.		
NOP	_	$PC + 2 \rightarrow PC$		
		Only increments the program counter.		
Note: * Size refers to the operand size.				

Table 2.9 System Control Instructions

B: Byte W: Word



Instruction	Size	Function	
EEPMOV.B	—	if R4L ≠ 0 then	
		repeat until	@ER5+ \rightarrow @ER6+, R4L – 1 \rightarrow R4L R4L = 0
		else next;	
EEPMOV.W	_	if R4 \neq 0 then	
		repeat until	@ER5+ \rightarrow @ER6+, R4 – 1 \rightarrow R4 R4 = 0
		else next;	
			a block according to parameters set in general r R4, ER5, and ER6.
		ER5: Sta	e of block (bytes) arting source address arting destination address
		Execution of the completed.	e next instruction begins as soon as the transfer is

Table 2.10 Block Transfer Instruction

2.6.4 Basic Instruction Formats

The H8/300H instructions consist of 2-byte (1-word) units. An instruction consists of an operation field (OP field), a register field (r field), an effective address extension (EA field), and a condition field (cc).

Operation Field: Indicates the function of the instruction, the addressing mode, and the operation to be carried out on the operand. The operation field always includes the first 4 bits of the instruction. Some instructions have two operation fields.

Register Field: Specifies a general register. Address registers are specified by 3 bits, data registers by 3 bits or 4 bits. Some instructions have two register fields. Some have no register field.

Effective Address Extension: Eight, 16, or 32 bits specifying immediate data, an absolute address, or a displacement. A 24-bit address or displacement is treated as 32-bit data in which the first 8 bits are 0 (H'00).

Condition Field: Specifies the branching condition of Bcc instructions.

Renesas

Figure 2.9 shows examples of instruction formats.

	NOP, RTS, etc.			
Operation field a	nd register fields			
	ор	rn	rm	ADD.B Rn, Rm, etc.
	L			
Dperation field, r	egister fields, and op	effective address	s extension rm	
Operation field, r	•	rn		MOV.B @(d:16, Rn), Rn
· · · · ·	ор	rn disp)	rm	MOV.B @(d:16, Rn), Rn

Figure 2.9 Instruction Formats

2.6.5 Notes on Use of Bit Manipulation Instructions

The BSET, BCLR, BNOT, BST, and BIST instructions read a byte of data, modify a bit in the byte, then write the byte back. Care is required when these instructions are used to access registers with write-only bits, or to access ports.

The BCLR instruction can be used to clear flags in the internal I/O registers. In an interrupthandling routine, for example, if it is known that the flag is set to 1, it is not necessary to read the flag ahead of time.

Step		Description
1	Read	Read data (byte unit) at the specified address
2	Bit manipulation	Modify the specified bit in the read data
3	Write	Write the modified data (byte unit) to the specified address

In the following example, a BCLR instruction is executed on the data direction register (DDR) of port 4.

P47 and P46 are set as input pins, and are inputting low-level and high-level signals, respectively.

P45 to P40 are set as output pins, and are in the low-level output state.

In this example, the BCLR instruction is used to make P4₀ an input port.

	P4 7	P46	P4 ₅	P44	P43	P42	P4 1	P40
Input/output	Input	Input	Output	Output	Output	Output	Output	Output
DDR	0	0	1	1	1	1	1	1
DR	1	0	0	0	0	0	0	0

Before Execution of BCLR Instruction

Execution of BCLR Instruction

BCLR #0, @P4DDR ; Execute BCLR instruction on DDR

After Execution of BCLR Instruction

	P47	P4 ₆	P45	P44	P43	P4 ₂	P4 1	P40
Input/output	Output	Output	Output	Output	Output	Output	Output	Input
DDR	1	1	1	1	1	1	1	0
DR	1	0	0	0	0	0	0	0

Explanation of BCLR Instruction

To execute the BCLR instruction, the CPU begins by reading P4DDR. Since P4DDR is a writeonly register, it is read as H'FF, even though its true value is H'3F.

Next the CPU clears bit 0 of the read data, changing the value to H'FE.

Finally, the CPU writes this value (H'FE) back to DDR to complete the BCLR instruction.

As a result, $P4_0DDR$ is cleared to 0, making $P4_0$ an input pin. In addition, $P4_7DDR$ and $P4_6DDR$ are set to 1, making $P4_7$ and $P4_6$ output pins.

The BCLR instruction can be used to clear flags in the internal I/O registers to 0. In an interrupthandling routine, for example, if it is known that the flag is set to 1, it is not necessary to read the flag ahead of time.

2.7 Addressing Modes and Effective Address Calculation

2.7.1 Addressing Modes

The H8/300H CPU supports the eight addressing modes listed in table 2.11. Each instruction uses a subset of these addressing modes. Arithmetic and logic instructions can use the register direct and immediate modes. Data transfer instructions can use all addressing modes except program-counter relative and memory indirect. Bit manipulation instructions use register direct, register indirect, or absolute (@aa:8) addressing mode to specify an operand, and register direct (BSET, BCLR, BNOT, and BTST instructions) or immediate (3-bit) addressing mode to specify a bit number in the operand.

No.	Addressing Mode	Symbol
1	Register direct	Rn
2	Register indirect	@ERn
3	Register indirect with displacement	@(d:16, ERn)/@(d:24, ERn)
4	Register indirect with post-increment	@ERn+
	Register indirect with pre-decrement	@-ERn
5	Absolute address	@aa:8/@aa:16/@aa:24
6	Immediate	#xx:8/#xx:16/#xx:32
7	Program-counter relative	@(d:8, PC)/@(d:16, PC)
8	Memory indirect	@@aa:8

Table 2.11 Addressing Modes

1 Register Direct—Rn: The register field of the instruction code specifies an 8-, 16-, or 32-bit register containing the operand. R0H to R7H and R0L to R7L can be specified as 8-bit registers. R0 to R7 and E0 to E7 can be specified as 16-bit registers. ER0 to ER7 can be specified as 32-bit registers.

2 Register Indirect—@ERn: The register field of the instruction code specifies an address register (ERn), the lower 24 bits of which contain the address of the operand.

3 Register Indirect with Displacement—@(d:16, ERn) or @(d:24, ERn): A 16-bit or 24-bit displacement contained in the instruction code is added to the contents of an address register (ERn) specified by the register field of the instruction, and the lower 24 bits of the sum specify the address of a memory operand. A 16-bit displacement is sign-extended when added.

4 Register Indirect with Post-Increment or Pre-Decrement—@ERn+ or @-ERn:

• Register indirect with post-increment—@ERn+

The register field of the instruction code specifies an address register (ERn) the lower 24 bits of which contain the address of a memory operand. After the operand is accessed, 1, 2, or 4 is added to the address register contents (32 bits) and the sum is stored in the address register. The value added is 1 for byte access, 2 for word access, or 4 for longword access. For word or longword access, the register value should be even.

• Register indirect with pre-decrement—@-ERn

The value 1, 2, or 4 is subtracted from an address register (ERn) specified by the register field in the instruction code, and the lower 24 bits of the result become the address of a memory operand. The result is also stored in the address register. The value subtracted is 1 for byte access, 2 for word access, or 4 for longword access. For word or longword access, the resulting register value should be even.

5 Absolute Address—@aa:8, @aa:16, or @aa:24: The instruction code contains the absolute address of a memory operand. The absolute address may be 8 bits long (@aa:8), 16 bits long (@aa:16), or 24 bits long (@aa:24). For an 8-bit absolute address, the upper 16 bits are all assumed to be 1 (H'FFFF). For a 16-bit absolute address the upper 8 bits are a sign extension. A 24-bit absolute address can access the entire address space. Table 2.12 indicates the accessible address ranges.

Absolute Address	1-Mbyte Modes	16-Mbyte Modes
8 bits (@aa:8)	H'FFF00 to H'FFFFF (1048320 to 1048575)	H'FFFF00 to H'FFFFFF (16776960 to 16777215)
16 bits (@aa:16)	H'00000 to H'07FFF, H'F8000 to H'FFFFF (0 to 32767, 1015808 to 1048575)	H'000000 to H'007FFF, H'FF8000 to H'FFFFFF (0 to 32767, 16744448 to 16777215)
24 bits (@aa:24)	H'00000 to H'FFFFF (0 to 1048575)	H'000000 to H'FFFFFF (0 to 16777215)

Table 2.12 Absolute Address Access Ranges

6 Immediate—#xx:8, #xx:16, or #xx:32: The instruction code contains 8-bit (#xx:8), 16-bit (#xx:16), or 32-bit (#xx:32) immediate data as an operand.

The instruction codes of the ADDS, SUBS, INC, and DEC instructions contain immediate data implicitly. The instruction codes of some bit manipulation instructions contain 3-bit immediate data specifying a bit number. The TRAPA instruction code contains 2-bit immediate data specifying a vector address.

7 **Program-Counter Relative**—@(d:8, PC) or @(d:16, PC): This mode is used in the Bcc and BSR instructions. An 8-bit or 16-bit displacement contained in the instruction code is sign-extended to 24 bits and added to the 24-bit PC contents to generate a 24-bit branch address. The PC value to which the displacement is added is the address of the first byte of the next instruction, so the possible branching range is -126 to +128 bytes (-63 to +64 words) or -32766 to +32768 bytes (-16383 to +16384 words) from the branch instruction. The resulting value should be an even number.

8 Memory Indirect—@@aa:8: This mode can be used by the JMP and JSR instructions. The instruction code contains an 8-bit absolute address specifying a memory operand. This memory operand contains a branch address. The memory operand is accessed by longword access. The first byte of the memory operand is ignored, generating a 24-bit branch address. See figure 2.10. The upper bits of the 8-bit absolute address are assumed to be 0 (H'0000), so the address range is 0 to 255 (H'000000 to H'0000FF). Note that the first part of this range is also the exception vector area. For further details see section 5, Interrupt Controller.

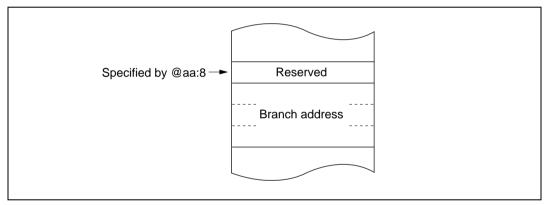
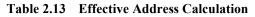


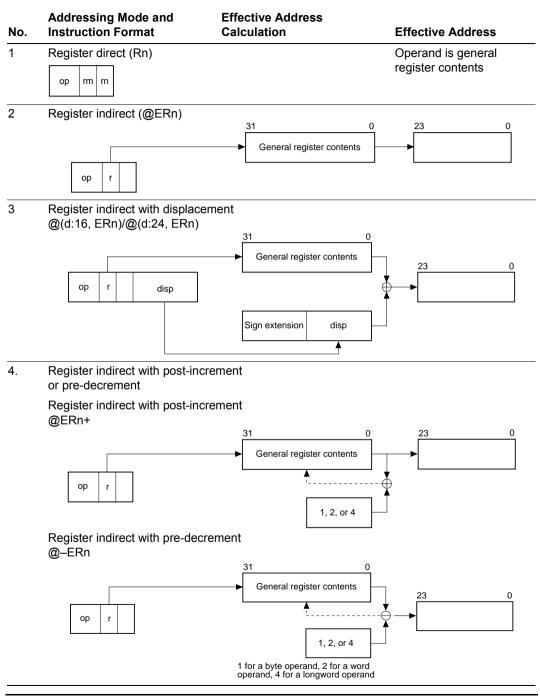
Figure 2.10 Memory-Indirect Branch Address Specification

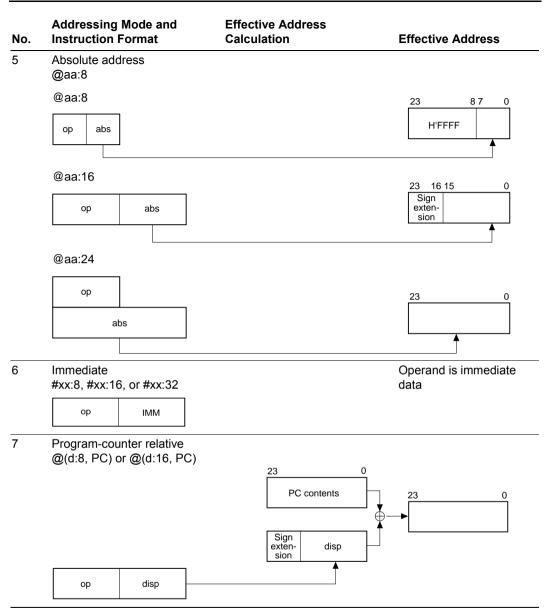
When a word-size or longword-size memory operand is specified, or when a branch address is specified, if the specified memory address is odd, the least significant bit is regarded as 0. The accessed data or instruction code therefore begins at the preceding address. See section 2.5.2, Memory Data Formats.

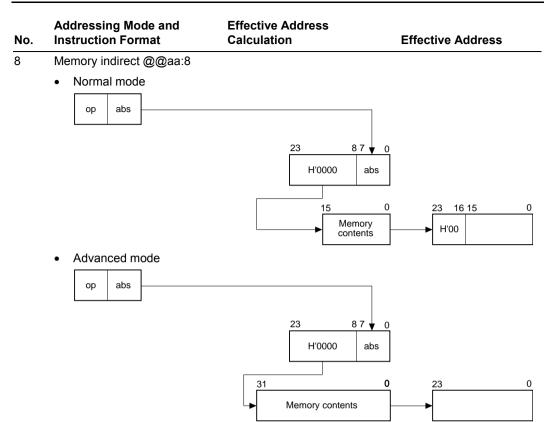
2.7.2 Effective Address Calculation

Table 2.13 explains how an effective address is calculated in each addressing mode. In the 1-Mbyte operating modes the upper 4 bits of the calculated address are ignored in order to generate a 20-bit effective address.









Legend:

- r, rm, rn: Register field
- op: Operation field
- disp: Displacement
- IMM: Immediate data
- abs: Absolute address

2.8 **Processing States**

2.8.1 Overview

The H8/300H CPU has five processing states: the program execution state, exception-handling state, power-down state, reset state, and bus-released state. The power-down state includes sleep mode, software standby mode, and hardware standby mode. Figure 2.11 classifies the processing states. Figure 2.13 indicates the state transitions.

Processing states	Program execution state
	The CPU executes program instructions in sequence
-	Exception-handling state
	A transient state in which the CPU executes a hardware sequence (saving PC and CCR, fetching a vector, etc.) in response to a reset, interrupt, or other exception
-	Bus-released state
	The external bus has been released in response to a bus request signal from a bus master other than the CPU
-	- Reset state
	The CPU and all on-chip supporting modules are initialized and halted
	Power-down state Sleep mode
	The CPU is halted to conserve power
	Software standby mode
	Hardware standby mode

Figure 2.11 Processing States

2.8.2 Program Execution State

In this state the CPU executes program instructions in normal sequence.

2.8.3 Exception-Handling State

The exception-handling state is a transient state that occurs when the CPU alters the normal program flow due to a reset, interrupt, or trap instruction. The CPU fetches a starting address from the exception vector table and branches to that address. In interrupt and trap exception handling the CPU references the stack pointer (ER7) and saves the program counter and condition code register.

Types of Exception Handling and Their Priority: Exception handling is performed for resets, interrupts, and trap instructions. Table 2.14 indicates the types of exception handling and their priority. Trap instruction exceptions are accepted at all times in the program execution state.

Priority	Type of Exception	Detection Timing	Start of Exception Handling
High ↑	Reset	Synchronized with clock	Exception handling starts immediately when RES changes from low to high
	Interrupt	End of instruction execution or end of exception handling*	When an interrupt is requested, exception handling starts at the end of the current instruction or current exception-handling sequence
 Low	Trap instruction	When TRAPA instruction is executed	Exception handling starts when a trap (TRAPA) instruction is executed

Table 2.14 Exception Handling Types and Priority

Note: * Interrupts are not detected at the end of the ANDC, ORC, XORC, and LDC instructions, or immediately after reset exception handling.

Figure 2.12 classifies the exception sources. For further details about exception sources, vector numbers, and vector addresses, see section 4, Exception Handling, and section 5, Interrupt Controller.

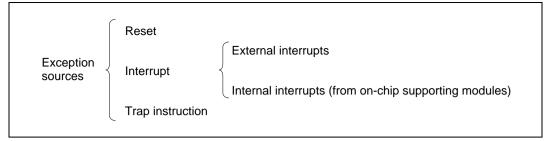


Figure 2.12 Classification of Exception Sources

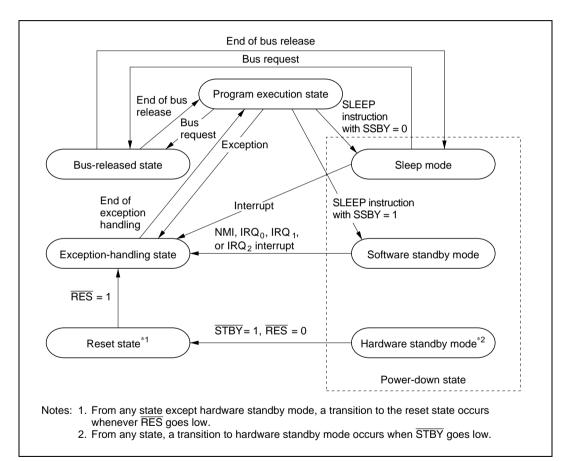


Figure 2.13 State Transitions

2.8.4 Exception-Handling Sequences

Reset Exception Handling: Reset exception handling has the highest priority. The reset state is entered when the $\overline{\text{RES}}$ signal goes low. Reset exception handling starts after that, when $\overline{\text{RES}}$ changes from low to high. When reset exception handling starts the CPU fetches a start address from the exception vector table and starts program execution from that address. All interrupts, including NMI, are disabled during the reset exception-handling sequence and immediately after it ends.

Interrupt Exception Handling and Trap Instruction Exception Handling: When these exception-handling sequences begin, the CPU references the stack pointer (ER7) and pushes the program counter and condition code register on the stack. Next, if the UE bit in the system control register (SYSCR) is set to 1, the CPU sets the I bit in the condition code register to 1. If the UE bit is cleared to 0, the CPU sets both the I bit and the UI bit in the condition code register to 1. Then the CPU fetches a start address from the exception vector table and execution branches to that address.

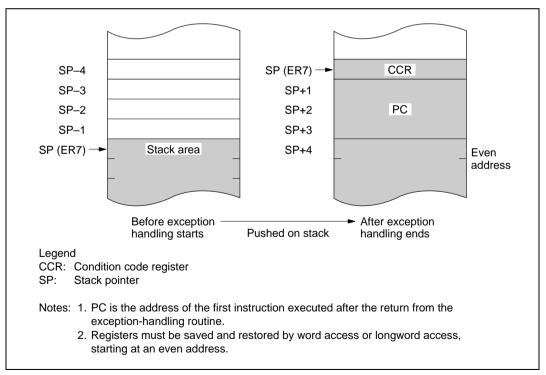


Figure 2.14 shows the stack after the exception-handling sequence.

Figure 2.14 Stack Structure after Exception Handling

2.8.5 Bus-Released State

In this state the bus is released to a bus master other than the CPU, in response to a bus request. The bus masters other than the CPU are the DMA controller, the refresh controller, and an external bus master. While the bus is released, the CPU halts except for internal operations. Interrupt requests are not accepted. For details see section 6.3.7, Bus Arbiter Operation.

2.8.6 Reset State

When the $\overline{\text{RES}}$ input goes low all current processing stops and the CPU enters the reset state. The I bit in the condition code register is set to 1 by a reset. All interrupts are masked in the reset state. Reset exception handling starts when the $\overline{\text{RES}}$ signal changes from low to high.

The reset state can also be entered by a watchdog timer overflow. For details see section 12, Watchdog Timer.

2.8.7 Power-Down State

In the power-down state the CPU stops operating to conserve power. There are three modes: sleep mode, software standby mode, and hardware standby mode.

Sleep Mode: A transition to sleep mode is made if the SLEEP instruction is executed while the SSBY bit is cleared to 0 in the system control register (SYSCR). CPU operations stop immediately after execution of the SLEEP instruction, but the contents of CPU registers are retained.

Software Standby Mode: A transition to software standby mode is made if the SLEEP instruction is executed while the SSBY bit is set to 1 in SYSCR. The CPU and clock halt and all on-chip supporting modules stop operating. The on-chip supporting modules are reset, but as long as a specified voltage is supplied the contents of CPU registers and on-chip RAM are retained. The I/O ports also remain in their existing states.

Hardware Standby Mode: A transition to hardware standby mode is made when the **STBY** input goes low. As in software standby mode, the CPU and all clocks halt and the on-chip supporting modules are reset, but as long as a specified voltage is supplied, on-chip RAM contents are retained.

For further information see section 21, Power-Down State.



2.9 Basic Operational Timing

2.9.1 Overview

The H8/300H CPU operates according to the system clock (ϕ). The interval from one rise of the system clock to the next rise is referred to as a "state." A memory cycle or bus cycle consists of two or three states. The CPU uses different methods to access on-chip memory, the on-chip supporting modules, and the external address space. Access to the external address space can be controlled by the bus controller.

2.9.2 On-Chip Memory Access Timing

On-chip memory is accessed in two states. The data bus is 16 bits wide, permitting both byte and word access. Figure 2.15 shows the on-chip memory access cycle. Figure 2.16 indicates the pin states.

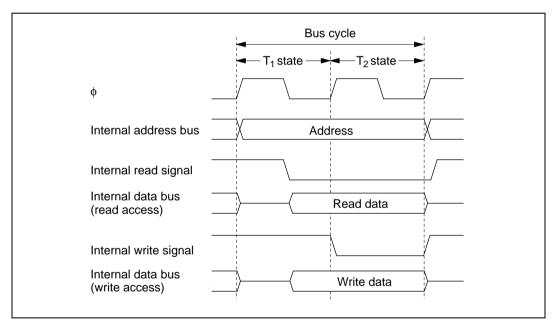
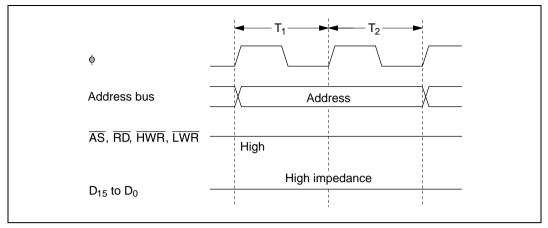
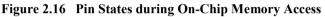


Figure 2.15 On-Chip Memory Access Cycle





2.9.3 On-Chip Supporting Module Access Timing

The on-chip supporting modules are accessed in three states. The data bus is 8 or 16 bits wide, depending on the register being accessed. Figure 2.17 shows the on-chip supporting module access timing. Figure 2.18 indicates the pin states.

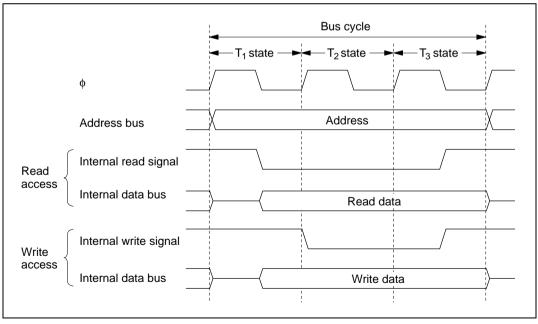
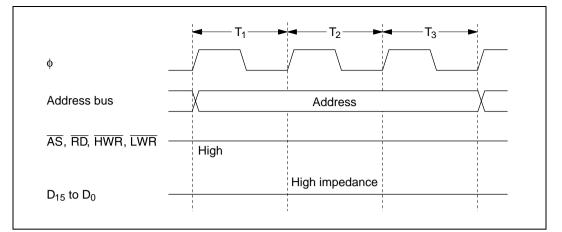
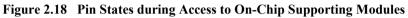


Figure 2.17 Access Cycle for On-Chip Supporting Modules





2.9.4 Access to External Address Space

The external address space is divided into eight areas (areas 0 to 7). Bus-controller settings determine whether each area is accessed via an 8-bit or 16-bit bus, and whether it is accessed in two or three states. For details see section 6, Bus Controller.



Section 3 MCU Operating Modes

3.1 Overview

3.1.1 Operating Mode Selection

The H8/3048 Group has seven operating modes (modes 1 to 7) that are selected by the mode pins $(MD_2 \text{ to } MD_0)$ as indicated in table 3.1. The input at these pins determines the size of the address space and the initial bus mode.

Mode Pins			ins	Description			
Operating Mode	MD ₂	MD ₁	MD₀	Address Space	Initial Bus Mode*1	On-Chip ROM	On-Chip RAM
_	0	0	0	_	_	_	
Mode 1	0	0	1	Expanded mode	8 bits	Disabled	Enabled*2
Mode 2	0	1	0	Expanded mode	16 bits	Disabled	Enabled*2
Mode 3	0	1	1	Expanded mode	8 bits	Disabled	Enabled*2
Mode 4	1	0	0	Expanded mode	16 bits	Disabled	Enabled*2
Mode 5	1	0	1	Expanded mode	8 bits	Enabled	Enabled*2
Mode 6	1	1	0	Expanded mode	8 bits	Enabled	Enabled*2
Mode 7	1	1	1	Single-chip advanced mode	_	Enabled	Enabled

Table 3.1 Operating Mode Selection

Notes: 1. In modes 1 to 6, an 8-bit or 16-bit data bus can be selected on a per-area basis by settings made in the area bus width control register (ABWCR). For details see section 6, Bus Controller.

2. If the RAME bit in SYSCR is cleared to 0, these addresses become external addresses.

For the address space size there are two choices: 1 Mbyte or 16 Mbytes. The external data bus is either 8 or 16 bits wide depending on ABWCR settings. If 8-bit access is selected for all areas, the external data bus is 8 bits wide. For details see section 6, Bus Controller.

Modes 1 to 4 are externally expanded modes that enable access to external memory and peripheral devices and disable access to the on-chip ROM. Modes 1 and 2 support a maximum address space of 1 Mbyte. Modes 3 and 4 support a maximum address space of 16 Mbytes.

Modes 5 and 6 are externally expanded modes that enable access to external memory and peripheral devices and also enable access to the on-chip ROM. Mode 5 supports a maximum address space of 1 Mbyte. Mode 6 supports a maximum address space of 16 Mbytes.

Mode 7 is a single-chip mode that operates using the on-chip ROM, RAM, and internal I/O registers, and makes all I/O ports available. Mode 7 supports a 1-Mbyte address space.

The H8/3048 Group can be used only in modes 1 to 7. The inputs at the mode pins must select one of these seven modes. The inputs at the mode pins must not be changed during operation.

3.1.2 Register Configuration

The H8/3048 Group has a mode control register (MDCR) that indicates the inputs at the mode pins (MD₂ to MD₀), and a system control register (SYSCR). Table 3.2 summarizes these registers.

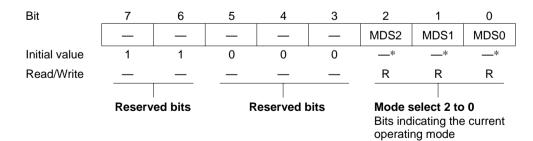
Table 3.2 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFF1	Mode control register	MDCR	R	Undetermined
H'FFF2	System control register	SYSCR	R/W	H'0B

Note: * The lower 16 bits of the address are indicated.

3.2 Mode Control Register (MDCR)

MDCR is an 8-bit read-only register that indicates the current operating mode of the H8/3048 Group.



Note: * Determined by pins MD₂ to MD₀.

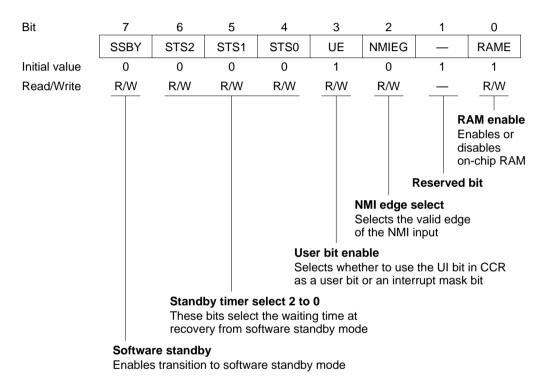
Bits 7 and 6—Reserved: Read-only bits, always read as 1.

Bits 5 to 3—Reserved: Read-only bits, always read as 0.

Bits 2 to 0—Mode Select 2 to 0 (MDS2 to MDS0): These bits indicate the logic levels at pins MD_2 to MD_0 (the current operating mode). MDS2 to MDS0 correspond to MD_2 to MD_0 . MDS2 to MDS0 are read-only bits. The mode pin (MD_2 to MD_0) levels are latched into these bits when MDCR is read.

3.3 System Control Register (SYSCR)

SYSCR is an 8-bit register that controls the operation of the H8/3048 Group.



Bit 7—Software Standby (SSBY): Enables transition to software standby mode. (For further information about software standby mode see section 21, Power-Down State.)

When software standby mode is exited by an external interrupt, this bit remains set to 1. To clear this bit, write 0.

Bit 7: SSBY	Description	
0	SLEEP instruction causes transition to sleep mode	(Initial value)
1	SLEEP instruction causes transition to software standby mode	

Bits 6 to 4—Standby Timer Select (STS2 to STS0): These bits select the length of time the CPU and on-chip supporting modules wait for the internal clock oscillator to settle when software standby mode is exited by an external interrupt. When using a crystal oscillator, set these bits so that the waiting time will be at least 7 ms at the system clock rate. For further information about waiting time selection, see section 21.4.3, Selection of Waiting Time for Exit from Software Standby Mode.

Bit 6: STS2	Bit 5: STS1	Bit 4: STS0	Description	
0	0	0	Waiting time = 8,192 states	(Initial value)
		1	Waiting time = 16,384 states	
	1	0	Waiting time = 32,768 states	
		1	Waiting time = 65,536 states	
1	0	0	Waiting time = 131,072 states	
		1	Waiting time = 1,024 states	
	1		Illegal setting	

Bit 3—User Bit Enable (UE): Selects whether to use the UI bit in the condition code register as a user bit or an interrupt mask bit.

Bit 3: UE	Description	
0	UI bit in CCR is used as an interrupt mask bit	
1	UI bit in CCR is used as a user bit	(Initial value)

Bit 2-NMI Edge Select (NMIEG): Selects the valid edge of the NMI input.

Bit 2: NMIEG	Description	
0	An interrupt is requested at the falling edge of NMI	(Initial value)
1	An interrupt is requested at the rising edge of NMI	

Bit 1—Reserved: Read-only bit, always read as 1.

Bit 0—RAM Enable (RAME): Enables or disables the on-chip RAM. The RAME bit is initialized by the rising edge of the $\overline{\text{RES}}$ signal. It is not initialized in software standby mode.

Bit 0: RAME	Description	
0	On-chip RAM is disabled	
1	On-chip RAM is enabled	(Initial value)

3.4 Operating Mode Descriptions

3.4.1 Mode 1

Ports 1, 2, and 5 function as address pins A_{19} to A_0 , permitting access to a maximum 1-Mbyte address space. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits.

3.4.2 Mode 2

Ports 1, 2, and 5 function as address pins A_{19} to A_0 , permitting access to a maximum 1-Mbyte address space. The initial bus mode after a reset is 16 bits, with 16-bit access to all areas. If all areas are designated for 8-bit access in ABWCR, the bus mode switches to 8 bits.

3.4.3 Mode 3

Ports 1, 2, and 5 and part of port A function as address pins A_{23} to A_0 , permitting access to a maximum 16-Mbyte address space. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits. A_{23} to A_{21} are valid when 0 is written in bits 7 to 5 of the bus release control register (BRCR). (In this mode A_{20} is always used for address output.)

3.4.4 Mode 4

Ports 1, 2, and 5 and part of port A function as address pins A_{23} to A_0 , permitting access to a maximum 16-Mbyte address space. The initial bus mode after a reset is 16 bits, with 16-bit access to all areas. If all areas are designated for 8-bit access in ABWCR, the bus mode switches to 8 bits. A_{23} to A_{21} are valid when 0 is written in bits 7 to 5 of BRCR. (In this mode A_{20} is always used for address output.)

3.4.5 Mode 5

Ports 1, 2, and 5 can function as address pins A_{19} to A_0 , permitting access to a maximum 1-Mbyte address space, but following a reset they are input ports. To use ports 1, 2, and 5 as an address bus, the corresponding bits in their data direction registers (P1DDR, P2DDR, and P5DDR) must be set to 1. The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits.

3.4.6 Mode 6

Ports 1, 2, and 5 and part of port A function as address pins A_{23} to A_0 , permitting access to a maximum 16-Mbyte address space, but following a reset they are input ports. To use ports 1, 2, and 5 as an address bus, the corresponding bits in their data direction registers (P1DDR, P2DDR, and P5DDR) must be set to 1. For A_{23} to A_{21} output, clear bits 7 to 5 of BRCR to 0. (In this mode A_{20} is always used for address output.)

The initial bus mode after a reset is 8 bits, with 8-bit access to all areas. If at least one area is designated for 16-bit access in ABWCR, the bus mode switches to 16 bits.

3.4.7 Mode 7

This mode operates using the on-chip ROM, RAM, and internal I/O registers. All I/O ports are available. Mode 7 supports a 1-Mbyte address space.

3.5 Pin Functions in Each Operating Mode

The pin functions of ports 1 to 5 and port A vary depending on the operating mode. Table 3.3 indicates their functions in each operating mode.

Port	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
Port 1	A_7 to A_0	A_7 to A_0	A_7 to A_0	A ₇ to A ₀	P1_7 to P1_{0}^{*2}	$P1_7$ to $P1_0^{*2}$	P17 to P10
Port 2	A_{15} to A_8	A_{15} to A_8	A_{15} to A_8	A_{15} to A_8	P27 to P20*2	P27 to P20*2	P27 to P20
Port 3	D_{15} to D_8	D_{15} to D_8	D_{15} to D_8	D_{15} to D_8	D_{15} to D_8	D_{15} to D_8	P37 to P30
Port 4	P47 to P40*1	D_7 to D_0^{*1}	P47 to P40*1	D_7 to D_0^{*1}	P47 to P40*1	P47 to P40*1	P47 to P40
Port 5	A_{19} to A_{16}	A_{19} to A_{16}	A_{19} to A_{16}	A_{19} to A_{16}	$P5_3$ to $P5_0^{*2}$	$P5_3$ to $P5_0^{*2}$	$P5_3$ to $P5_0$
Port A	PA_7 to PA_4	PA_7 to PA_4	PA_7 to PA_5^{*3} , A_{20}	PA_7 to PA_5^{*3} , A_{20}	PA_7 to PA_4	PA_7 to PA_5 , A_{20}^{*3}	PA_7 to PA_4

Table 3.3Pin Functions in Each Mode

Notes: 1. Initial state. The bus mode can be switched by settings in ABWCR. These pins function as $P4_7$ to $P4_0$ in 8-bit bus mode, and as D_7 to D_0 in 16-bit bus mode.

2. Initial state. These pins become address output pins when the corresponding bits in the data direction registers (P1DDR, P2DDR, P5DDR) are set to 1.

3. Initial state. A_{20} is always an address output pin. PA_7 to PA_5 are switched over to A_{23} to A_{21} output by writing 0 in bits 7 to 5 of BRCR.

3.6 Memory Map in Each Operating Mode

Figure 3.1 shows a memory map of the H8/3048. Figure 3.2 shows a memory map of the H8/3047. Figure 3.3 shows a memory map of the H8/3044. Figure 3.4 shows a memory map of the H8/3045. The address space is divided into eight areas.

The initial bus mode differs between modes 1 and 2, and also between modes 3 and 4.

The address locations of the on-chip RAM and internal I/O registers differ between the 1-Mbyte modes (modes 1, 2, 5, and 7) and 16-Mbyte modes (modes 3, 4, and 6). The address range specifiable by the CPU in the 8- and 16-bit absolute addressing modes (@aa:8 and @aa:16) also differs.

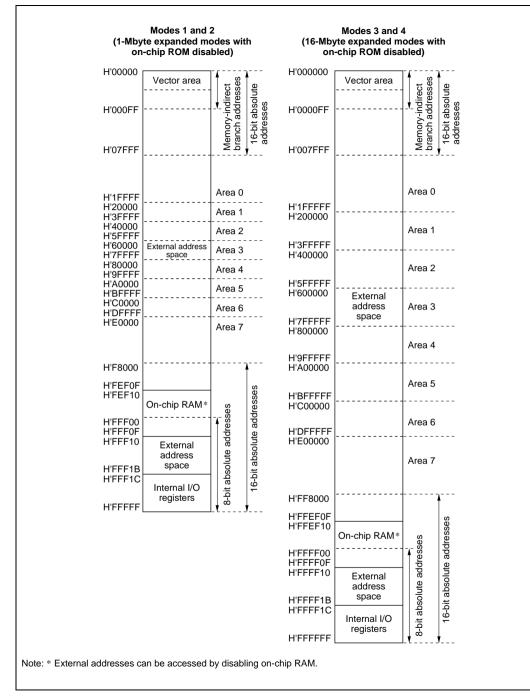


Figure 3.1 H8/3048 Memory Map in Each Operating Mode

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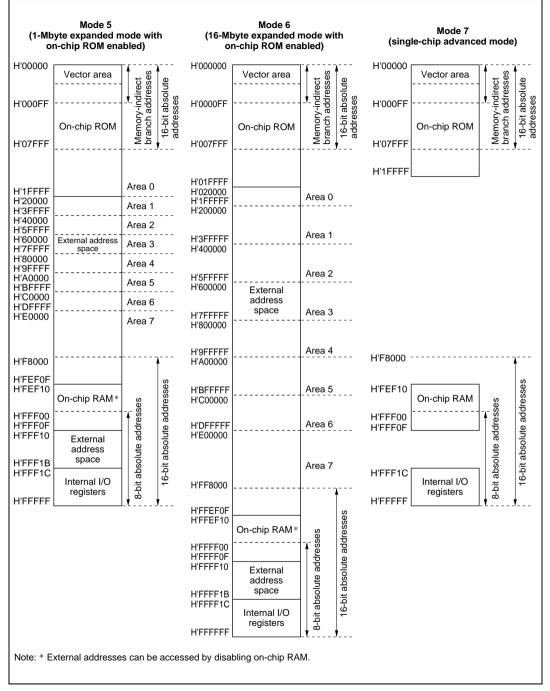


Figure 3.1 H8/3048 Memory Map in Each Operating Mode (cont)

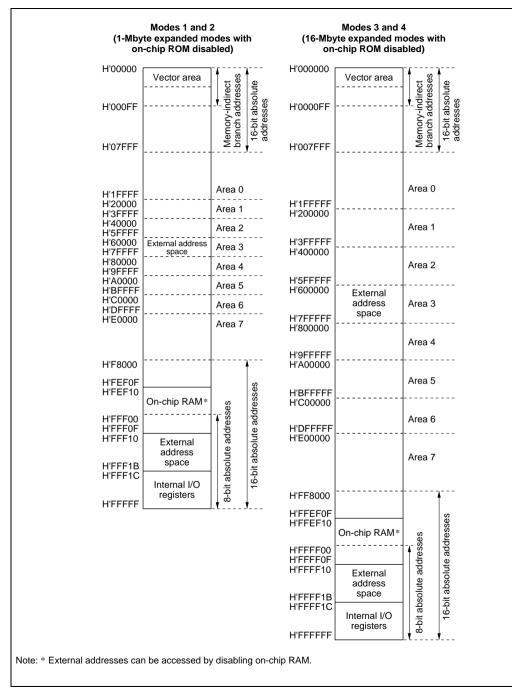


Figure 3.2 H8/3047 Memory Map in Each Operating Mode

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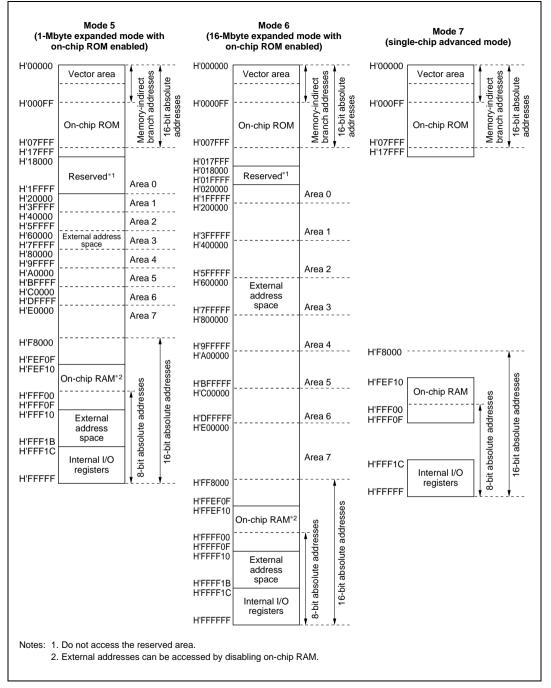


Figure 3.2 H8/3047 Memory Map in Each Operating Mode (cont)

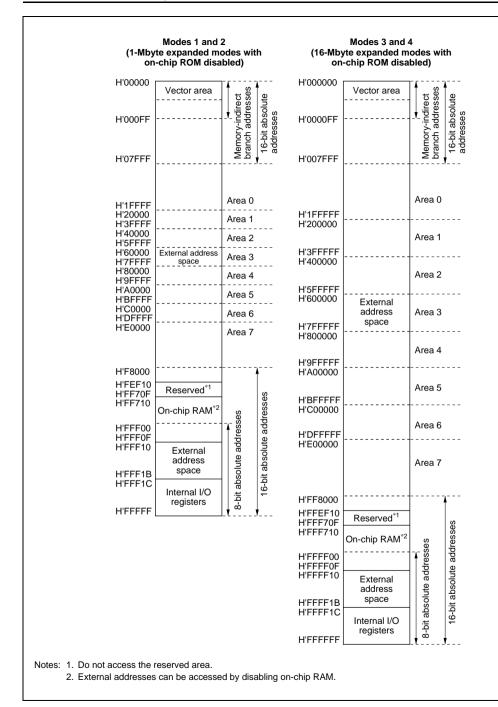


Figure 3.3 H8/3044 Memory Map in Each Operating Mode

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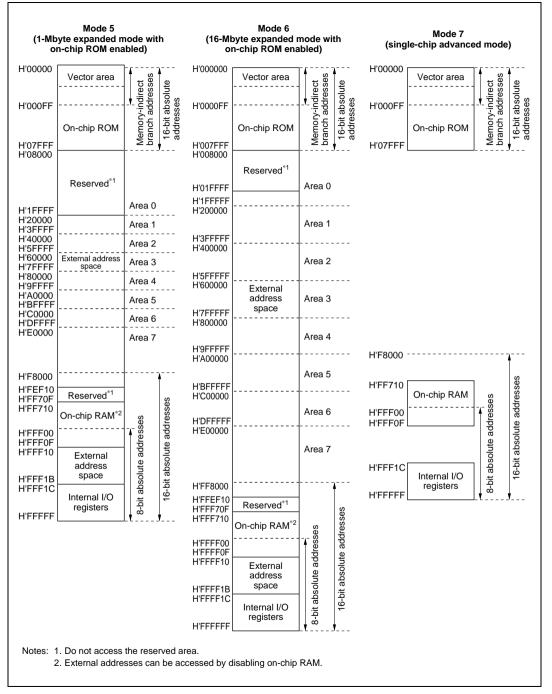


Figure 3.3 H8/3044 Memory Map in Each Operating Mode (cont)

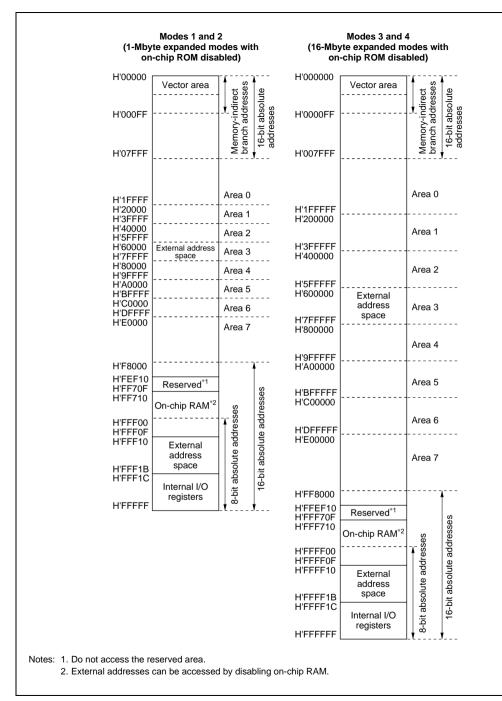


Figure 3.4 H8/3045 Memory Map in Each Operating Mode

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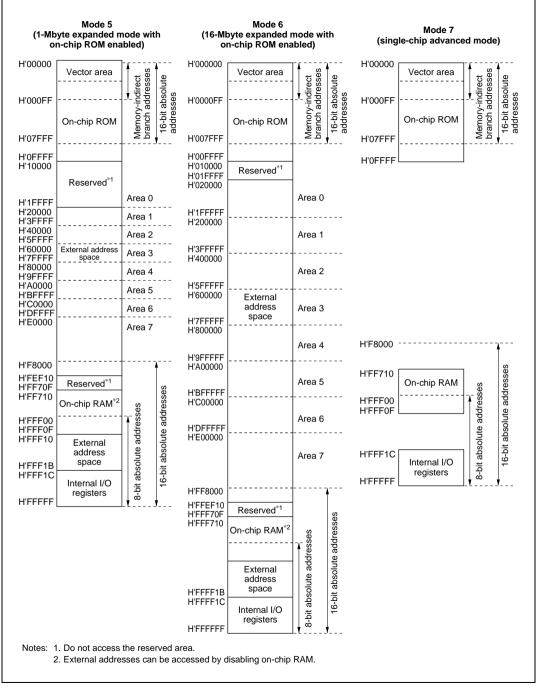


Figure 3.4 H8/3045 Memory Map in Each Operating Mode (cont)



Section 4 Exception Handling

4.1 Overview

4.1.1 Exception Handling Types and Priority

As table 4.1 indicates, exception handling may be caused by a reset, trap instruction, or interrupt. Exception handling is prioritized as shown in table 4.1. If two or more exceptions occur simultaneously, they are accepted and processed in priority order. Trap instruction exceptions are accepted at all times in the program execution state.

Table 4.1	Exception	Types an	d Priority
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Priority	Exception Type	Start of Exception Handling	
High ↑	Reset	Starts immediately after a low-to-high transition at the $\overline{\text{RES}}$ pin	
	Interrupt	Interrupt requests are handled when execution of the current instruction or handling of the current exception is completed	
Low	Trap instruction (TRAPA)	Started by execution of a trap instruction (TRAPA)	

4.1.2 Exception Handling Operation

Exceptions originate from various sources. Trap instructions and interrupts are handled as follows.

- 1. The program counter (PC) and condition code register (CCR) are pushed onto the stack.
- 2. The CCR interrupt mask bit is set to 1.
- 3. A vector address corresponding to the exception source is generated, and program execution starts from the address indicated in that address.

Note: For a reset exception, steps 2 and 3 above are carried out.

4.1.3 Exception Vector Table

The exception sources are classified as shown in figure 4.1. Different vectors are assigned to different exception sources. Table 4.2 lists the exception sources and their vector addresses.

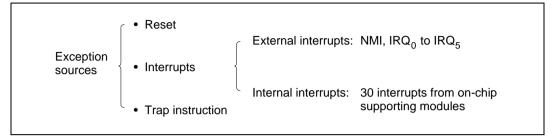


Figure 4.1 Exception Sources



Exception Source	Vector Number	Vector Address*1
Reset	0	H'0000 to H'0003
Reserved for system use	1	H'0004 to H'0007
	2	H'0008 to H'000B
	3	H'000C to H'000F
	4	H'0010 to H'0013
	5	H'0014 to H'0017
	6	H'0018 to H'001B
External interrupt (NMI)	7	H'001C to H'001F
Trap instruction (4 sources)	8	H'0020 to H'0023
	9	H'0024 to H'0027
	10	H'0028 to H'002B
	11	H'002C to H'002F
External interrupt IRQ0	12	H'0030 to H'0033
External interrupt IRQ1	13	H'0034 to H'0037
External interrupt IRQ ₂	14	H'0038 to H'003B
External interrupt IRQ ₃	15	H'003C to H'003F
External interrupt IRQ ₄	16	H'0040 to H'0043
External interrupt IRQ5	17	H'0044 to H'0047
Reserved for system use	18	H'0048 to H'004B
	19	H'004C to H'004F
Internal interrupts*2	20	H'0050 to H'0053
	to 60	to H'00F0 to H'00F3

Table 4.2Exception Vector Table

Notes: 1. Lower 16 bits of the address.

2. For the internal interrupt vectors, see section 5.3.3, Interrupt Vector Table.

4.2 Reset

4.2.1 Overview

A reset is the highest-priority exception. When the $\overline{\text{RES}}$ pin goes low, all processing halts and the chip enters the reset state. A reset initializes the internal state of the CPU and the registers of the on-chip supporting modules. Reset exception handling begins when the $\overline{\text{RES}}$ pin changes from low to high.

The chip can also be reset by overflow of the watchdog timer. For details see section 12, Watchdog Timer.

4.2.2 Reset Sequence

The chip enters the reset state when the $\overline{\text{RES}}$ pin goes low.

To ensure that the chip is reset, hold the $\overline{\text{RES}}$ pin low for at least 20 ms at power-up. To reset the chip during operation, hold the $\overline{\text{RES}}$ pin low for at least 10 system clock (ϕ) cycles. See appendix D.2, Pin States at Reset, for the states of the pins in the reset state.

When the $\overline{\text{RES}}$ pin goes high after being held low for the necessary time, the chip starts reset exception handling as follows.

- The internal state of the CPU and the registers of the on-chip supporting modules are initialized, and the I bit is set to 1 in CCR.
- The contents of the reset vector address (H'0000 to H'0003) are read, and program execution starts from the address indicated in the vector address.

Figure 4.2 shows the reset sequence in modes 1 and 3. Figure 4.3 shows the reset sequence in modes 2 and 4. Figure 4.4 shows the reset sequence in modes 5, 6 and 7.



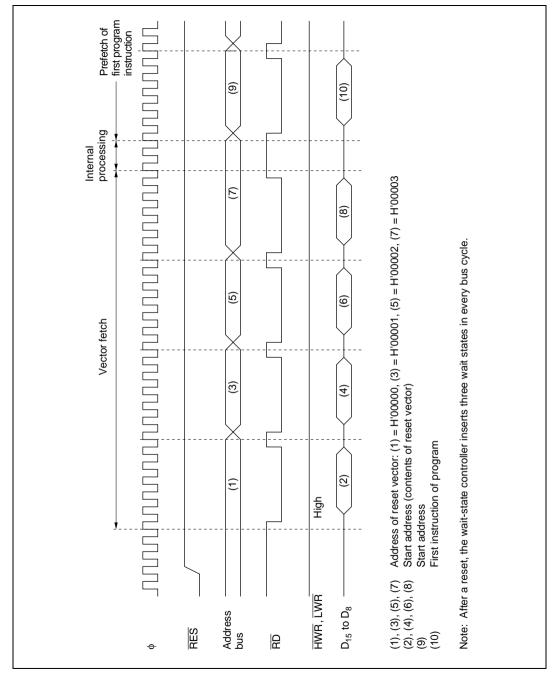


Figure 4.2 Reset Sequence (Modes 1 and 3)

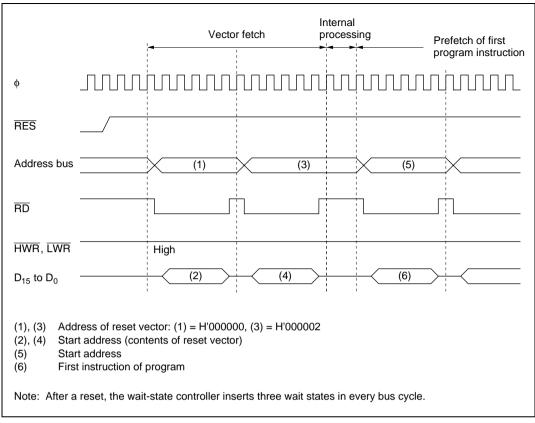


Figure 4.3 Reset Sequence (Modes 2 and 4)



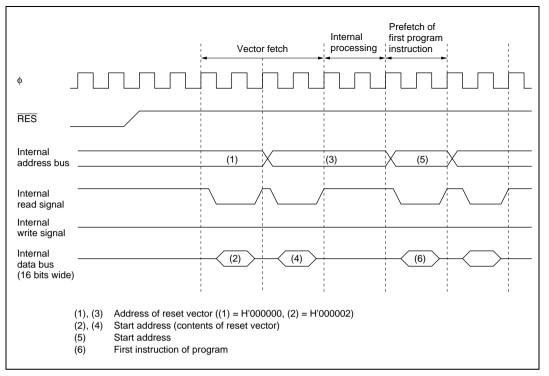


Figure 4.4 Reset Sequence (Modes 5, 6, and 7)

4.2.3 Interrupts after Reset

If an interrupt is accepted after a reset but before the stack pointer (SP) is initialized, PC and CCR will not be saved correctly, leading to a program crash. To prevent this, all interrupt requests, including NMI, are disabled immediately after a reset. The first instruction of the program is always executed immediately after the reset state ends. This instruction should initialize the stack pointer (example: MOV.L #xx:32, SP).

4.3 Interrupts

Interrupt exception handling can be requested by seven external sources (NMI, IRQ_0 to IRQ_5) and 30 internal sources in the on-chip supporting modules. Figure 4.5 classifies the interrupt sources and indicates the number of interrupts of each type.

The on-chip supporting modules that can request interrupts are the watchdog timer (WDT), refresh controller, 16-bit integrated timer unit (ITU), DMA controller (DMAC), serial communication interface (SCI), and A/D converter. Each interrupt source has a separate vector address.

NMI is the highest-priority interrupt and is always accepted. Interrupts are controlled by the interrupt controller. The interrupt controller can assign interrupts other than NMI to two priority levels, and arbitrate between simultaneous interrupts. Interrupt priorities are assigned in interrupt priority registers A and B (IPRA and IPRB) in the interrupt controller.

For details on interrupts see section 5, Interrupt Controller.

	External interrupts	$\begin{cases} NMI (1) \\ IRQ_0 \text{ to } IRQ_5 (6) \end{cases}$
Interrupts	Internal interrupts	WDT ^{*1} (1) Refresh controller ^{*2} (1) ITU (15) DMAC (4) SCI (8) A/D converter (1)
1. When the w request at e 2. When the re	atchdog timer is used every counter overflow	mber of interrupt sources. I as an interval timer, it generates an interrupt 7. ed as an interval timer, it generates an interrupt

Figure 4.5 Interrupt Sources and Number of Interrupts



4.4 Trap Instruction

Trap instruction exception handling starts when a TRAPA instruction is executed. If the UE bit is set to 1 in the system control register (SYSCR), the exception handling sequence sets the I bit to 1 in CCR. If the UE bit is 0, the I and UI bits are both set to 1. The TRAPA instruction fetches a start address from a vector table entry corresponding to a vector number from 0 to 3, which is specified in the instruction code.

4.5 Stack Status after Exception Handling

Figure 4.6 shows the stack after completion of trap instruction exception handling and interrupt exception handling.

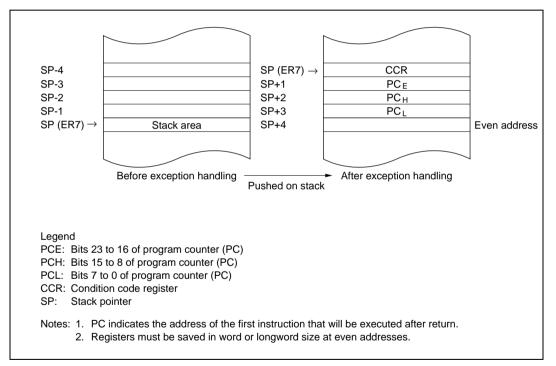


Figure 4.6 Stack after Completion of Exception Handling

4.6 Notes on Stack Usage

When accessing word data or longword data, the H8/3048 Group regards the lowest address bit as 0. The stack should always be accessed by word access or longword access, and the value of the stack pointer (SP:ER7) should always be kept even. Use the following instructions to save registers:

PUSH.W Rn (or MOV.W Rn, @–SP) PUSH.L ERn (or MOV.L ERn, @–SP)

Use the following instructions to restore registers:

POP.W Rn (or MOV.W @SP+, Rn) POP.L ERn (or MOV.L @SP+, ERn)

Setting SP to an odd value may lead to a malfunction. Figure 4.7 shows an example of what happens when the SP value is odd.

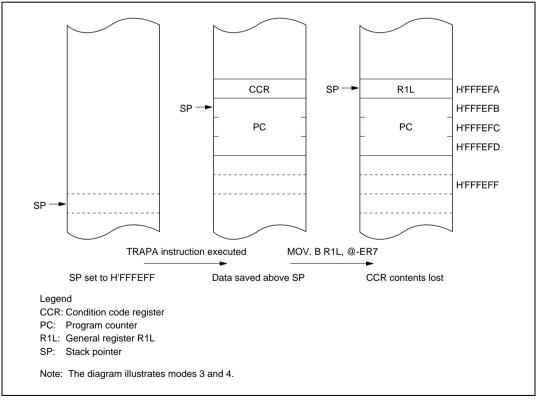


Figure 4.7 Operation when SP Value is Odd

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Section 5 Interrupt Controller

5.1 Overview

5.1.1 Features

The interrupt controller has the following features:

- Interrupt priority registers (IPRs) for setting interrupt priorities Interrupts other than NMI can be assigned to two priority levels on a module-by-module basis in interrupt priority registers A and B (IPRA and IPRB).
- Three-level masking by the I and UI bits in the CPU condition code register (CCR)
- Independent vector addresses All interrupts are independently vectored; the interrupt service routine does not have to identify the interrupt source.
- Seven external interrupt pins

NMI has the highest priority and is always accepted; either the rising or falling edge can be selected. For each of IRQ_0 to IRQ_5 , sensing of the falling edge or level sensing can be selected independently.

5.1.2 Block Diagram



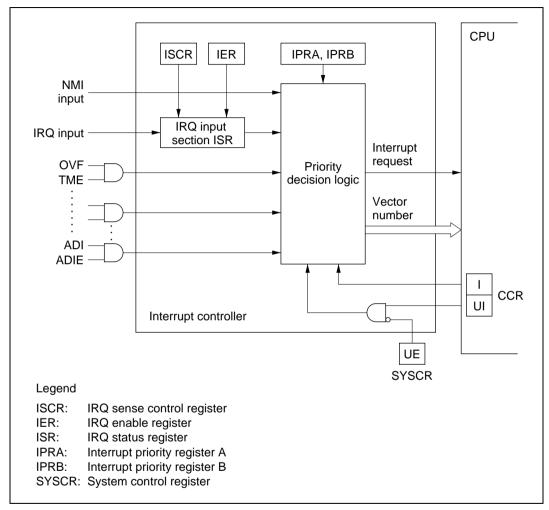


Figure 5.1 Interrupt Controller Block Diagram



5.1.3 Pin Configuration

Table 5.1 lists the interrupt pins.

Table 5.1Interrupt Pins

Name	Abbreviation	I/O	Function
Nonmaskable interrupt	NMI	Input	Nonmaskable interrupt, rising edge or falling edge selectable
External interrupt request 5 to 0	\overline{IRQ}_5 to \overline{IRQ}_0	Input	Maskable interrupts, falling edge or level sensing selectable

5.1.4 Register Configuration

Table 5.2 lists the registers of the interrupt controller.

Table 5.2 Interrupt Controller Registers

Address* ¹	Name	Abbreviation	R/W	Initial Value
H'FFF2	System control register	SYSCR	R/W	H'0B
H'FFF4	IRQ sense control register	ISCR	R/W	H'00
H'FFF5	IRQ enable register	IER	R/W	H'00
H'FFF6	IRQ status register	ISR	R/(W)* ²	H'00
H'FFF8	Interrupt priority register A	IPRA	R/W	H'00
H'FFF9	Interrupt priority register B	IPRB	R/W	H'00

Notes: 1. Lower 16 bits of the address.

2. Only 0 can be written, to clear flags.

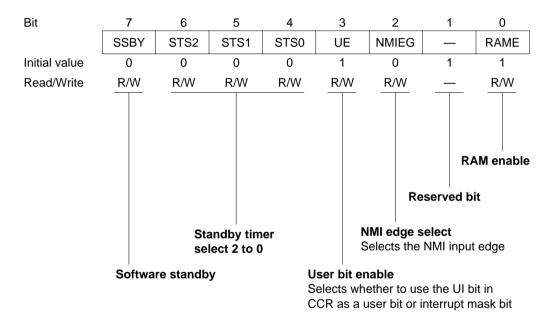
5.2 **Register Descriptions**

5.2.1 System Control Register (SYSCR)

SYSCR is an 8-bit readable/writable register that controls software standby mode, selects the action of the UI bit in CCR, selects the NMI edge, and enables or disables the on-chip RAM.

Only bits 3 and 2 are described here. For the other bits, see section 3.3, System Control Register (SYSCR).

SYSCR is initialized to H'0B by a reset and in hardware standby mode. It is not initialized in software standby mode.





Bit 3—User Bit Enable (UE): Selects whether to use the UI bit in CCR as a user bit or an interrupt mask bit.

Bit 3: UE	Description	
0	UI bit in CCR is used as interrupt mask bit	
1	UI bit in CCR is used as user bit	(Initial value)

Bit 2—NMI Edge Select (NMIEG): Selects the NMI input edge.

Bit 2: NMIEG	Description	
0	Interrupt is requested at falling edge of NMI input	(Initial value)
1	Interrupt is requested at rising edge of NMI input	

5.2.2 Interrupt Priority Registers A and B (IPRA, IPRB)

IPRA and IPRB are 8-bit readable/writable registers that control interrupt priority.

Interrupt Priority Register A (IPRA): IPRA is an 8-bit readable/writable register in which interrupt priority levels can be set.

Bit	7	6	5	4	3	2	1	0
	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
					Priority Selects t refresh c	Priority lev Selects the TU channe	P le S p o c riority leve elects the p ITU chann terrupt req el A2 priority lev I 0 interrup	oriority level nel 1 uests el of ot requests DT and
				Priority le Selects th interrupt r	e priority	level of IR	Q_4 and IR	Q_5
			 Priority le	evel A5	•	RQ ₂ and IR	Q ₃ interru	ot requests
		Priority le Selects th		evel of IR	Q ₁ interre	upt requests	8	
	Priority le Selects the	e vel A7 e priority le	evel of IRC	Q ₀ interrup	ot reques	ts		

IPRA is initialized to H'00 by a reset and in hardware standby mode.



Bit 7—Priority Level A7 (IPRA7): Selects the priority level of IRQ₀ interrupt requests.

Bit 7: IPRA7	Description	
0	IRQ ₀ interrupt requests have priority level 0 (low priority)	(Initial value)
1	IRQ ₀ interrupt requests have priority level 1 (high priority)	

Bit 6—Priority Level A6 (IPRA6): Selects the priority level of IRQ₁ interrupt requests.

Bit 6: IPRA6	Description	
0	IRQ ₁ interrupt requests have priority level 0 (low priority)	(Initial value)
1	IRQ ₁ interrupt requests have priority level 1 (high priority)	

Bit 5—Priority Level A5 (IPRA5): Selects the priority level of IRQ₂ and IRQ₃ interrupt requests.

Bit 5: IPRA5	Description
0	IRQ ₂ and IRQ ₃ interrupt requests have priority level 0 (low priority)
	(Initial value)
1	IRQ_2 and IRQ_3 interrupt requests have priority level 1 (high priority)

Bit 4—Priority Level A4 (IPRA4): Selects the priority level of IRQ₄ and IRQ₅ interrupt requests.

Bit 4: IPRA4	Description
0	IRQ_4 and IRQ_5 interrupt requests have priority level 0 (low priority)
	(Initial value)
1	IRQ_4 and IRQ_5 interrupt requests have priority level 1 (high priority)

Bit 3—Priority Level A3 (IPRA3): Selects the priority level of WDT and refresh controller interrupt requests.

Bit 3: IPRA3	Description
0	WDT and refresh controller interrupt requests have priority level 0 (low priority) (Initial value)
1	WDT and refresh controller interrupt requests have priority level 1 (high priority)

Bit 2—Priority Level A2 (IPRA2): Selects the priority level of ITU channel 0 interrupt requests.

Bit 2: IPRA2	Description
0	ITU channel 0 interrupt requests have priority level 0 (low priority) (Initial value)
1	ITU channel 0 interrupt requests have priority level 1 (high priority)

Bit 1—Priority Level A1 (IPRA1): Selects the priority level of ITU channel 1 interrupt requests.

Bit 1: IPRA1	Description
0	ITU channel 1 interrupt requests have priority level 0 (low priority) (Initial value)
1	ITU channel 1 interrupt requests have priority level 1 (high priority)

Bit 0—Priority Level A0 (IPRA0): Selects the priority level of ITU channel 2 interrupt requests.

Bit 0: IPRA0	Description
0	ITU channel 2 interrupt requests have priority level 0 (low priority) (Initial value)
1	ITU channel 2 interrupt requests have priority level 1 (high priority)



Interrupt Priority Register B (IPRB): IPRB is an 8-bit readable/writable register in which interrupt priority levels can be set.

Bit	7	6	5	4	3	2	1	0		
	IPRB7	IPRB6	IPRB5	—	IPRB3	IPRB2	IPRB1	—		
Initial value	0	0	0	0	0	0	0	0		
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		
							Po	served bit		
							NC.			
							iority leve			
							lects the p A/D conve	riority level		
							errupt requ			
						riority lev elects the		vel of		
							• •	ot requests		
						the priorit	v level of 9	SCI		
						l 0 interrup				
				Reserv	/ed bit					
	Priority level B5 Selects the priority level of DMAC									
		interrupt requests (channels 0 and 1)								
	Priority level B6 Selects the priority level of ITU channel 4 interrupt requests						ts			
			-	-			•			
		r level B7 the priorit	y level of I	TU chann	el 3 interru	upt reques	ts			

IPRB is initialized to H'00 by a reset and in hardware standby mode.

Bit 7—Priority Level B7 (IPRB7): Selects the priority level of ITU channel 3 interrupt requests.

Bit 7: IPRB7	Description
0	ITU channel 3 interrupt requests have priority level 0 (low priority) (Initial value)
1	ITU channel 3 interrupt requests have priority level 1 (high priority)

Bit 6—Priority Level B6 (IPRB6): Selects the priority level of ITU channel 4 interrupt requests.

Bit 6: IPRB6	Description
0	ITU channel 4 interrupt requests have priority level 0 (low priority) (Initial value)
1	ITU channel 4 interrupt requests have priority level 1 (high priority)

Bit 5—Priority Level B5 (IPRB5): Selects the priority level of DMAC interrupt requests (channels 0 and 1).

Bit 5: IPRB5	Description
0	DMAC interrupt requests (channels 0 and 1) have priority level 0 (low priority) (Initial value)
1	DMAC interrupt requests (channels 0 and 1) have priority level 1 (high priority)

Bit 4—Reserved: This bit can be written and read, but it does not affect interrupt priority.



Bit 3—Priority Level B3 (IPRB3): Selects the priority level of SCI channel 0 interrupt requests.

Bit 3: IPRB3	Description	
0	SCI0 interrupt requests have priority level 0 (low priority)	(Initial value)
1	SCI0 interrupt requests have priority level 1 (high priority)	

Bit 2—Priority Level B2 (IPRB2): Selects the priority level of SCI channel 1 interrupt requests.

Bit 2: IPRB2	Description	
0	SCI1 interrupt requests have priority level 0 (low priority)	(Initial value)
1	SCI1 interrupt requests have priority level 1 (high priority)	

Bit 1—Priority Level B1 (IPRB1): Selects the priority level of A/D converter interrupt requests.

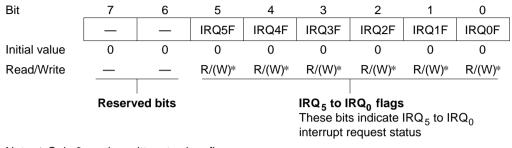
Bit 1: IPRB1	Description
0	A/D converter interrupt requests have priority level 0 (low priority) (Initial value)
1	A/D converter interrupt requests have priority level 1 (high priority)

Bit 0-Reserved: This bit can be written and read, but it does not affect interrupt priority.



5.2.3 IRQ Status Register (ISR)

ISR is an 8-bit readable/writable register that indicates the status of IRQ_0 to IRQ_5 interrupt requests.



Note: * Only 0 can be written, to clear flags.

ISR is initialized to H'00 by a reset and in hardware standby mode.

Bits 7 and 6—Reserved: Read-only bits, always read as 0.

Bits 5 to 0—IRQ₅ to IRQ₀ Flags (IRQ5F to IRQ0F): These bits indicate the status of IRQ_5 to IRQ_0 interrupt requests.

Bits 5 to 0:		
IRQ5F to IRQ0F	Description	
0	[Clearing conditions]	(Initial value)
	0 is written in IRQnF after reading the IRQnF flag when	IRQnF = 1.
	IRQnSC = 0, IRQn input is high, and interrupt exception	handling is carried out.
	IRQnSC = 1 and IRQn interrupt exception handling is ca	arried out.
1	[Setting conditions]	
	IRQnSC = 0 and \overline{IRQn} input is low.	
	IRQnSC = 1 and \overline{IRQn} input changes from high to low.	

Note: n = 5 to 0



5.2.4 IRQ Enable Register (IER)

Bit	7	6	5	4	3	2	1	0
	—	—	IRQ5E	IRQ4E	IRQ3E	IRQ2E	IRQ1E	IRQ0E
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Reserv	ed bits			RQ₀ enab s enable o		RQ ₅ to IR	Q ₀ interrup

IER is an 8-bit readable/writable register that enables or disables IRQ₀ to IRQ₅ interrupt requests.

IER is initialized to H'00 by a reset and in hardware standby mode.

Bits 7 and 6—Reserved: These bits can be written and read, but they do not enable or disable interrupts.

Bits 5 to 0—IRQ₅ to IRQ₀ Enable (IRQ5E to IRQ0E): These bits enable or disable IRQ₅ to IRQ₀ interrupts.

Bits 5 to 0: IRQ5E to IRQ0E	Description	
0	IRQ_5 to IRQ_0 interrupts are disabled	(Initial value)
1	IRQ_5 to IRQ_0 interrupts are enabled	

5.2.5 IRQ Sense Control Register (ISCR)

ISCR is an 8-bit readable/writable register that selects level sensing or falling-edge sensing of the inputs at pins \overline{IRQ}_5 to \overline{IRQ}_0 .

Bit	7	6	5	4	3	2	1	0
	_	_	IRQ5SC	IRQ4SC	IRQ3SC	IRQ2SC	IRQ1SC	IRQ0SC
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Reserv	ed bits	IRQ ₅ to IRQ ₀ sense control These bits select level sensing or falling-e sensing for IRQ ₅ to IRQ ₀ interrupts					lling-edge

ISCR is initialized to H'00 by a reset and in hardware standby mode.

Bits 7 and 6—Reserved: These bits can be written and read, but they do not select level or falling-edge sensing.

Bits 5 to 0—IRQ₅ to IRQ₀ Sense Control (IRQ5SC to IRQ0SC): These bits select whether interrupts IRQ₅ to IRQ₀ are requested by level sensing of pins $\overline{IRQ_5}$ to $\overline{IRQ_0}$, or by falling-edge sensing.

Bits 5 to 0: IRQ5SC to IRQ0SC	Description	
0	Interrupts are requested when \overline{IRQ}_5 to \overline{IRQ}_0 inputs are low	(Initial value)
1	Interrupts are requested by falling-edge input at \overline{IRQ}_5 to \overline{IRQ}	$\overline{\mathbf{\lambda}}_{0}$



5.3 Interrupt Sources

The interrupt sources include external interrupts (NMI, IRQ₀ to IRQ₅) and 30 internal interrupts.

5.3.1 External Interrupts

There are seven external interrupts: NMI, and IRQ_0 to IRQ_5 . Of these, NMI, IRQ_0 , IRQ_1 , and IRQ_2 can be used to exit software standby mode.

NMI: NMI is the highest-priority interrupt and is always accepted, regardless of the states of the I and UI bits in CCR. The NMIEG bit in SYSCR selects whether an interrupt is requested by the rising or falling edge of the input at the NMI pin. NMI interrupt exception handling has vector number 7.

IRQ₀ to **IRQ**₅ **Interrupts:** These interrupts are requested by input signals at pins $\overline{\text{IRQ}}_0$ to $\overline{\text{IRQ}}_5$. The IRQ₀ to IRQ₅ interrupts have the following features.

- ISCR settings can select whether an interrupt is requested by the low level of the input at pins \overline{IRQ}_0 to \overline{IRQ}_5 , or by the falling edge.
- IER settings can enable or disable the IRQ₀ to IRQ₅ interrupts. Interrupt priority levels can be assigned by four bits in IPRA (IPRA7 to IPRA4).
- The status of IRQ₀ to IRQ₅ interrupt requests is indicated in ISR. The ISR flags can be cleared to 0 by software.

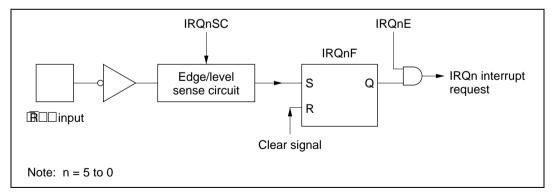


Figure 5.2 shows a block diagram of interrupts IRQ₀ to IRQ₅.

Figure 5.2 Block Diagram of Interrupts IRQ₀ to IRQ₅

Figure 5.3 shows the timing of the setting of the interrupt flags (IRQnF).

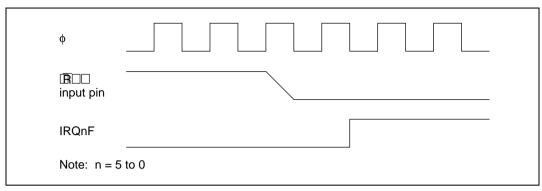


Figure 5.3 Timing of Setting of IRQnF

Interrupts IRQ_0 to IRQ_5 have vector numbers 12 to 17. These interrupts are detected regardless of whether the corresponding pin is set for input or output. When using a pin for external interrupt input, clear its DDR bit to 0 and do not use the pin for chip select output, refresh output, or SCI input or output.

5.3.2 Internal Interrupts

Thirty internal interrupts are requested from the on-chip supporting modules.

- Each on-chip supporting module has status flags for indicating interrupt status, and enable bits for enabling or disabling interrupts.
- Interrupt priority levels can be assigned in IPRA and IPRB.
- ITU and SCI interrupt requests can activate the DMAC, in which case no interrupt request is sent to the interrupt controller, and the I and UI bits are disregarded.

5.3.3 Interrupt Vector Table

Table 5.3 lists the interrupt sources, their vector addresses, and their default priority order. In the default priority order, smaller vector numbers have higher priority. The priority of interrupts other than NMI can be changed in IPRA and IPRB. The priority order after a reset is the default order shown in table 5.3.



Interrupt Source	Origin	Vector Number	Vector Address*	IPR	Priority
NMI	External pins	7	H'001C to H'001F	_	High
IRQ₀		12	H'0030 to H'0033	IPRA7	_ ↑
IRQ ₁		13	H'0034 to H0037	IPRA6	_
IRQ ₂		14	H'0038 to H'003B	IPRA5	_
IRQ ₃		15	H'003C to H'003F		
IRQ ₄		16	H'0040 to H'0043	IPRA4	
IRQ ₅		17	H'0044 to H'0047		
Reserved	—	18	H'0048 to H'004B		
		19	H'004C to H'004F		
WOVI (interval timer)	Watchdog timer	20	H'0050 to H'0053	IPRA3	
CMI (compare match)	Refresh controller	21	H'0054 to H'0057		
Reserved	_	22	H'0058 to H'005B		
		23	H'005C to H'005F		
IMIA0 (compare match/ input capture A0)	ITU channel 0	24	H'0060 to H'0063	IPRA2	
IMIB0 (compare match/ input capture B0)		25	H'0064 to H'0067		
OVI0 (overflow 0)		26	H'0068 to H'006B		
Reserved	_	27	H'006C to H'006F		
IMIA1 (compare match/ input capture A1)	ITU channel 1	28	H'0070 to H'0073	IPRA1	
IMIB1 (compare match/ input capture B1)		29	H'0074 to H'0077		
OVI1 (overflow 1)		30	H'0078 to H'007B		
Reserved	_	31	H'007C to H'007F		 Low

 Table 5.3
 Interrupt Sources, Vector Addresses, and Priority

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Interrupt Source	Origin	Vector Number	Vector Address*	IPR	Priority
IMIA2 (compare match/ input capture A2)	ITU channel 2	32	H'0080 to H'0083	IPRA0	High
IMIB2 (compare match/ input capture B2)		33	H'0084 to H'0087		
OVI2 (overflow 2)		34	H'0088 to H'008B		
Reserved	_	35	H'008C to H'008F		
IMIA3 (compare match/ input capture A3)	ITU channel 3	36	H'0090 to H'0093	IPRB7	
IMIB3 (compare match/ input capture B3)		37	H'0094 to H'0097		
OVI3 (overflow 3)		38	H'0098 to H'009B		
Reserved	_	39	H'009C to H'009F		
IMIA4 (compare match/ input capture A4)	ITU channel 4	40	H'00A0 to H'00A3	IPRB6	
IMIB4 (compare match/ input capture B4)		41	H'00A4 to H'00A7		
OVI4 (overflow 4)		42	H'00A8 to H'00AB		
Reserved	_	43	H'00AC to H'00AF		
DEND0A	DMAC	44	H'00B0 to H'00B3	IPRB5	
DEND0B		45	H'00B4 to H'00B7		
DEND1A		46	H'00B8 to H'00BB		
DEND1B		47	H'00BC to H'00BF		
Reserved		48	H'00C0 to H'00C3	_	_
		49	H'00C4 to H'00C7		
		50	H'00C8 to H'00CB		
		51	H'00CC to H'00CF		
					Low

Interrupt Source	Origin	Vector Number	Vector Address*	IPR	Priority
ERI0 (receive error 0)	SCI channel 0	52	H'00D0 to H'00D3	IPRB3	High ↑
RXI0 (receive data full 0)	_	53	H'00D4 to H'00D7		
TXI0 (transmit data empty 0)	_	54	H'00D8 to H'00DB		
TEI0 (transmit end 0)	_	55	H'00DC to H'00DF		
ERI1 (receive error 1)	SCI channel 1	56	H'00E0 to H'00E3	IPRB2	_
RXI1 (receive data full 1)	_	57	H'00E4 to H'00E7		
TXI1 (transmit data empty 1)	_	58	H'00E8 to H'00EB		
TEI1 (transmit end 1)	_	59	H'00EC to H'00EF		
ADI (A/D end)	A/D	60	H'00F0 to H'00F3	IPRB1	Low

Note: * Lower 16 bits of the address.

5.4 Interrupt Operation

5.4.1 Interrupt Handling Process

The H8/3048 Group handles interrupts differently depending on the setting of the UE bit. When UE = 1, interrupts are controlled by the I bit. When UE = 0, interrupts are controlled by the I and UI bits. Table 5.4 indicates how interrupts are handled for all setting combinations of the UE, I, and UI bits.

NMI interrupts are always accepted except in the reset and hardware standby states. IRQ interrupts and interrupts from the on-chip supporting modules have their own enable bits. Interrupt requests are ignored when the enable bits are cleared to 0.

SYSCR		CCR	
UE	I	UI	Description
1	0	_	All interrupts are accepted. Interrupts with priority level 1 have higher priority.
	1	_	No interrupts are accepted except NMI.
0	0	—	All interrupts are accepted. Interrupts with priority level 1 have higher priority.
-	1	0	NMI and interrupts with priority level 1 are accepted.
		1	No interrupts are accepted except NMI.

Table 5.4 UE, I, and UI Bit Settings and Interrupt Handling

UE = 1: Interrupts IRQ₀ to IRQ₅ and interrupts from the on-chip supporting modules can all be masked by the I bit in the CPU's CCR. Interrupts are masked when the I bit is set to 1, and unmasked when the I bit is cleared to 0. Interrupts with priority level 1 have higher priority. Figure 5.4 is a flowchart showing how interrupts are accepted when UE = 1.

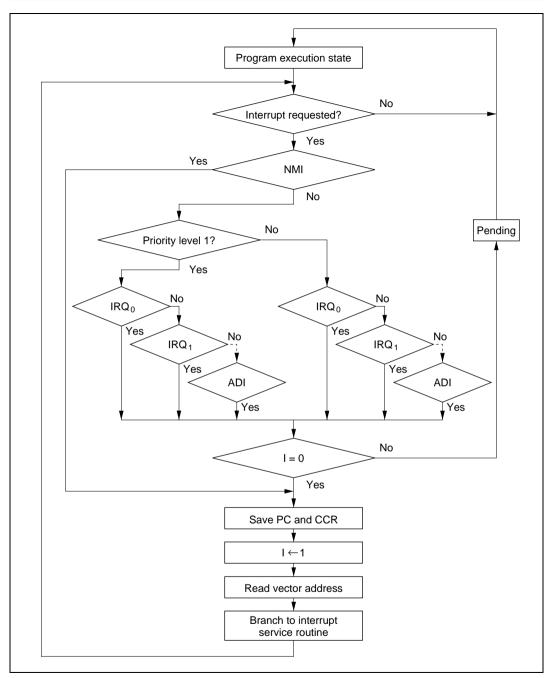


Figure 5.4 Process Up to Interrupt Acceptance when UE = 1

- If an interrupt condition occurs and the corresponding interrupt enable bit is set to 1, an interrupt request is sent to the interrupt controller.
- When the interrupt controller receives one or more interrupt requests, it selects the highestpriority request, following the IPR interrupt priority settings, and holds other requests pending. If two or more interrupts with the same IPR setting are requested simultaneously, the interrupt controller follows the priority order shown in table 5.3.
- The interrupt controller checks the I bit. If the I bit is cleared to 0, the selected interrupt request is accepted. If the I bit is set to 1, only NMI is accepted; other interrupt requests are held pending.
- When an interrupt request is accepted, interrupt exception handling starts after execution of the current instruction has been completed.
- In interrupt exception handling, PC and CCR are saved to the stack area. The PC value that is saved indicates the address of the first instruction that will be executed after the return from the interrupt service routine.
- Next the I bit is set to 1 in CCR, masking all interrupts except NMI.
- The vector address of the accepted interrupt is generated, and the interrupt service routine starts executing from the address indicated by the contents of the vector address.

UE = 0: The I and UI bits in the CPU's CCR and the IPR bits enable three-level masking of IRQ₀ to IRQ₅ interrupts and interrupts from the on-chip supporting modules.

- Interrupt requests with priority level 0 are masked when the I bit is set to 1, and are unmasked when the I bit is cleared to 0.
- Interrupt requests with priority level 1 are masked when the I and UI bits are both set to 1, and are unmasked when either the I bit or the UI bit is cleared to 0.

For example, if the interrupt enable bits of all interrupt requests are set to 1, IPRA is set to H'20, and IPRB is set to H'00 (giving IRQ_2 and IRQ_3 interrupt requests priority over other interrupts), interrupts are masked as follows:

- a. If I = 0, all interrupts are unmasked (priority order: $NMI > IRQ_2 > IRQ_3 > IRQ_0 \dots$).
- b. If I = 1 and UI = 0, only NMI, IRQ_2 , and IRQ_3 are unmasked.
- c. If I = 1 and UI = 1, all interrupts are masked except NMI.

Figure 5.5 shows the transitions among the above states.



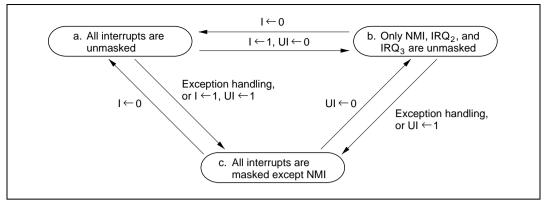


Figure 5.5 Interrupt Masking State Transitions (Example)

Figure 5.6 is a flowchart showing how interrupts are accepted when UE = 0.

- If an interrupt condition occurs and the corresponding interrupt enable bit is set to 1, an interrupt request is sent to the interrupt controller.
- When the interrupt controller receives one or more interrupt requests, it selects the highestpriority request, following the IPR interrupt priority settings, and holds other requests pending. If two or more interrupts with the same IPR setting are requested simultaneously, the interrupt controller follows the priority order shown in table 5.3.
- The interrupt controller checks the I bit. If the I bit is cleared to 0, the selected interrupt request is accepted regardless of its IPR setting, and regardless of the UI bit. If the I bit is set to 1 and the UI bit is cleared to 0, only NMI and interrupts with priority level 1 are accepted; interrupt requests with priority level 0 are held pending. If the I bit and UI bit are both set to 1, only NMI is accepted; all other interrupt requests are held pending.
- When an interrupt request is accepted, interrupt exception handling starts after execution of the current instruction has been completed.
- In interrupt exception handling, PC and CCR are saved to the stack area. The PC value that is saved indicates the address of the first instruction that will be executed after the return from the interrupt service routine.
- The I and UI bits are set to 1 in CCR, masking all interrupts except NMI.
- The vector address of the accepted interrupt is generated, and the interrupt service routine starts executing from the address indicated by the contents of the vector address.

Section 5 Interrupt Controller

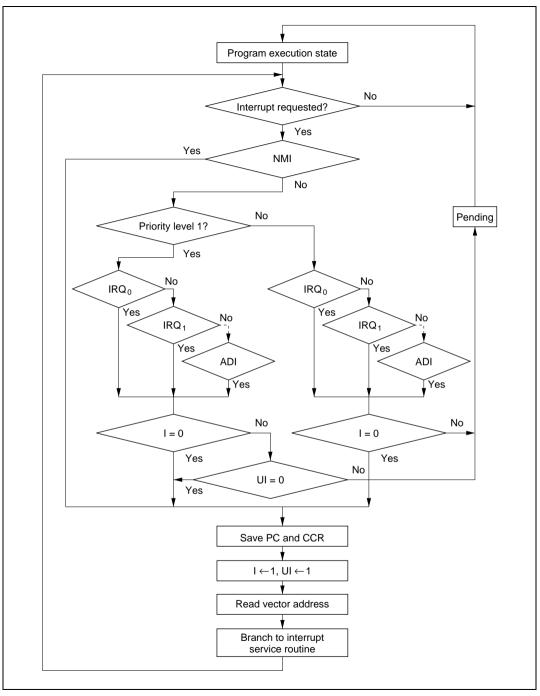


Figure 5.6 Process Up to Interrupt Acceptance when UE = 0

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5.4.2 Interrupt Sequence

Figure 5.7 shows the interrupt sequence in mode 2 when the program code and stack are in an external memory area accessed in two states via a 16-bit bus.

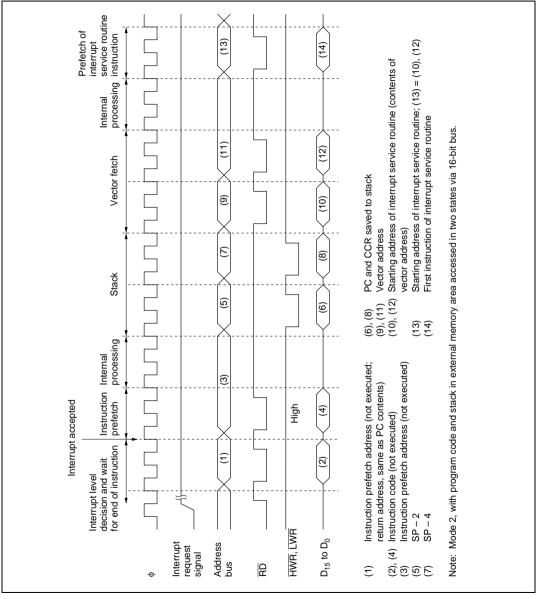


Figure 5.7 Interrupt Sequence (Mode 2, Two-State Access, Stack in External Memory)

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5.4.3 Interrupt Response Time

Table 5.5 indicates the interrupt response time from the occurrence of an interrupt request until the first instruction of the interrupt service routine is executed.

Table 5.5Interrupt Response Time

			External Memory				
		On-Chip	8-B	it Bus	16-Bit Bus		
No.	Item	Memory	2 States	3 States	2 States	3 States	
1	Interrupt priority decision	2* ¹	2* ¹	2* ¹	2* ¹	2* ¹	
2	Maximum number of states until end of current instruction	1 to 23	1 to 27	1 to 31* ⁴	1 to 23	1 to 25* ⁴	
3	Saving PC and CCR to stack	4	8	12 ^{*4}	4	6* ⁴	
4	Vector fetch	4	8	12 ^{*4}	4	6* ⁴	
5	Instruction prefetch*2	4	8	12* ⁴	4	6* ⁴	
6	Internal processing*3	4	4	4	4	4	
Total		19 to 41	31 to 57	43 to 73	19 to 41	25 to 49	

Notes: 1. 1 state for internal interrupts.

2. Prefetch after the interrupt is accepted and prefetch of the first instruction in the interrupt service routine.

3. Internal processing after the interrupt is accepted and internal processing after prefetch.

4. The number of states increases if wait states are inserted in external memory access.



5.5 Usage Notes

5.5.1 Contention between Interrupt and Interrupt-Disabling Instruction

When an instruction clears an interrupt enable bit to 0 to disable the interrupt, the interrupt is not disabled until after execution of the instruction is completed. If an interrupt occurs while a BCLR, MOV, or other instruction is being executed to clear its interrupt enable bit to 0, at the instant when execution of the instruction ends the interrupt is still enabled, so its interrupt exception handling is carried out. If a higher-priority interrupt is also requested, however, interrupt exception handling for the higher-priority interrupt is carried out, and the lower-priority interrupt is ignored. This also applies to the clearing of an interrupt flag.

Figure 5.8 shows an example in which an IMIEA bit is cleared to 0 in TIER of the ITU.

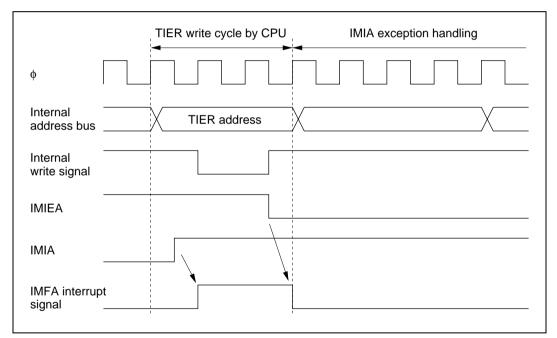


Figure 5.8 Contention between Interrupt and Interrupt-Disabling Instruction

This type of contention will not occur if the interrupt is masked when the interrupt enable bit or flag is cleared to 0.

5.5.2 Instructions that Inhibit Interrupts

The LDC, ANDC, ORC, and XORC instructions inhibit interrupts. When an interrupt occurs, after determining the interrupt priority, the interrupt controller requests a CPU interrupt. If the CPU is currently executing one of these interrupt-inhibiting instructions, however, when the instruction is completed the CPU always continues by executing the next instruction.

5.5.3 Interrupts during EEPMOV Instruction Execution

The EEPMOV.B and EEPMOV.W instructions differ in their reaction to interrupt requests.

When the EEPMOV.B instruction is executing a transfer, no interrupts are accepted until the transfer is completed, not even NMI.

When the EEPMOV.W instruction is executing a transfer, interrupt requests other than NMI are not accepted until the transfer is completed. If NMI is requested, NMI exception handling starts at a transfer cycle boundary. The PC value saved on the stack is the address of the next instruction. Programs should be coded as follows to allow for NMI interrupts during EEPMOV.W execution:

L1: EEPMOV.W MOV.W R4,R4 BNE L1

5.5.4 Usage Notes on External Interrupts

The IRQnF flag specification calls for the flag to be cleared by writing 0 to it after it has been read while set to 1. However, it is possible for the IRQnF flag to be cleared by mistake simply by writing 0 to it, irrespective of whether it has been read while set to 1, with the result that interrupt exception handling is not executed. This occurs when the following conditions are fulfilled.

- Setting conditions
- 1. Multiple external interrupts (IRQa, IRQb) are being used.
- 2. Different clearing methods are being used: clearing by writing 0 for the IRQaF flag, and clearing by hardware for the IRQbF flag.
- 3. A bit manipulation instruction is used on the IRQ status register to clear the IRQaF flag, or else ISR is read as a byte unit, the IRQaF flag bit is cleared, and the values read in the other bits are written as a byte unit.

- Occurrence conditions
- 1. When IRQaF = 1, for the IRQaF flag to clear, ISR register read is executed. Thereafter interrupt processing is carried out and IRQbF flag clears.
- IRQaF flag clear and IRQbF flag generation compete (IRQaF flag setting). (The ISR read needed for IRQaF flag clear was at IRQbF = 0 but in the time taken for ISR write, IRQbF = 1 was reached.)

In all of the setting conditions 1 to 3 and occurrence conditions 1 and 2 are generated, IRQbF clears in error during ISR write for occurrence condition 2 and interrupt processing is not carried out. However, if IRQbF flag reaches 0 between occurrence conditions 1 and 2, IRQbF flag does not clear in error.

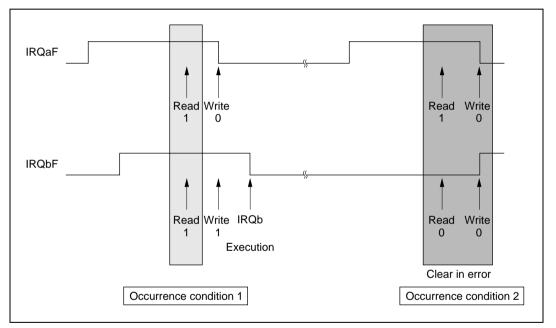


Figure 5.9 IRQnF Flag When Interrupt Processing Is Not Conducted

In this situation, conduct one of the following countermeasures.

Countermeasure 1: When clears IRQaF flag, do not use the bit manipulation instruction, read the ISR in bytes. Then write a value in bytes which sets IRQnF flag to 0 and other bits to 1.

For example, if a = 0

MOV.B @ISR,R0L MOV.B #HFE,R0L MOV.B R0L,@ISR

Countermeasure 2: During IRQb interrupt exception processing, carry out IRQbF flag clear dummy processing.

For example, if b = 1

```
IRQB MOV.B #HFD,ROL
MOV.B ROL,@ISR
```

5.5.5 Notes on Non-Maskable Interrupts (NMI)

NMI is an exception processing that can be executed by the interrupt controller and CPU when the chip internal circuits are operating normally under a specified electrical characteristics. If an NMI is executed when the circuits are not operating normally due to some factors such as software or abnormal interrupt of input to the pins (runaway execution), the operation will not be guaranteed.

Incorrect NMI Operation Factors: Software

- When an interrupt exception processing is executed in an H8/300H CPU, it is assumed that the stack pointer (SP(ER7)) has already been set by software, and that the stack pointer (SP(ER7)) points to the stack area set in a system such as RAM. If the program is in a runaway execution, the stack pointer may be overflowed and updated illegally. Therefore, normal operation will not be guaranteed.
- Requests for NMIs can be accepted on the rising or falling edge of a pin. Acceptance of the rising or falling edge depends on the setting of the bit NMIEG in the system control register (SYSCR). It is necessary for the customer to set the bit according to the designated system. When the program is in a runaway execution, this bit may be rewritten illegally. Therefore, the system may not operate as expected.
- 3. This chip has a break function to implement on-board emulation for specific customers. To use this break function, execute the BRK instruction (H'5770). Note that the BRK instruction is

usually undefined. Therefore, if the CPU accidentally executes the instruction, the chip will perform exceptional processing and will enter the break mode. In the break mode, interrupts including the NMI are inhibited and the count of the watch dog timer will be stopped. Then by executing the RTB (H'56F0) instruction, the break mode will be cancelled, and usual program execution will resume. When the execution is reset during break mode, the CPU enters the reset state and the break mode is cancelled. Once the reset has been cancelled, normal program execution will resume after the reset exception processing has been executed.

Incorrect NMI Operation Factors: Abnormal Interrupts Input to the Chip Pins

If an abnormal interrupt which was not specified in the electrical characteristics is input to a pin during a chip operation, the chip may be destroyed. In this case, the operation of the chip will not be guaranteed.

When an abnormal interrupt has been input to a pin, the chip may not be destroyed; however, the internal circuits of the chip may partially or wholly malfunction, and the CPU may enter an unimagined undefined state when the CPU was designed. If this occurs, it will be impossible to control the operation of the chip by external pins other than the external reset and standby pins, and the operation of the NMI will not be guaranteed. In this case, after some specified signals have been input to the pins, input an external reset so that the chip can enter the normal program execution state again.



Section 6 Bus Controller

6.1 Overview

The H8/3048 Group has an on-chip bus controller that divides the address space into eight areas and can assign different bus specifications to each. This enables different types of memory to be connected easily.

A bus arbitration function of the bus controller controls the operation of the DMA controller (DMAC) and refresh controller. The bus controller can also release the bus to an external device.

6.1.1 Features

Features of the bus controller are listed below.

- Independent settings for address areas 7 to 0
 - 128-kbyte areas in 1-Mbyte modes; 2-Mbyte areas in 16-Mbyte modes.
 - Chip select signals (CS7 to CS0) can be output for areas 7 to 0.
 - Areas can be designated for 8-bit or 16-bit access.
 - Areas can be designated for two-state or three-state access.
- Four wait modes
 - Programmable wait mode, pin auto-wait mode, and pin wait modes 0 and 1 can be selected.
 - Zero to three wait states can be inserted automatically.
- Bus arbitration function
 - A built-in bus arbitrates the bus right to the CPU, DMAC, refresh controller, or an external bus master.

6.1.2 Block Diagram

Figure 6.1 shows a block diagram of the bus controller.

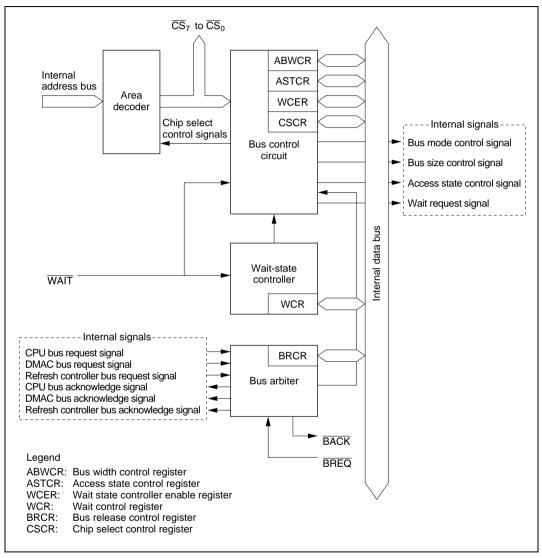


Figure 6.1 Block Diagram of Bus Controller

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6.1.3 Input/Output Pins

Table 6.1 summarizes the bus controller's input/output pins.

Table 6.1Bus Controller Pins

Name	Abbreviation	I/O	Function
Chip select 7 to 0	\overline{CS}_7 to \overline{CS}_0	Output	Strobe signals selecting areas 7 to 0
Address strobe	ĀS	Output	Strobe signal indicating valid address output on the address bus
Read	RD	Output	Strobe signal indicating reading from the external address space
High write	HWR	Output	Strobe signal indicating writing to the external address space, with valid data on the upper data bus $(D_{15} \text{ to } D_8)$
Low write	LWR	Output	Strobe signal indicating writing to the external address space, with valid data on the lower data bus (D_7 to D_0)
Wait	WAIT	Input	Wait request signal for access to external three-state-access areas
Bus request	BREQ	Input	Request signal for releasing the bus to an external device
Bus acknowledge	BACK	Output	Acknowledge signal indicating the bus is released to an external device

6.1.4 Register Configuration

Table 6.2 summarizes the bus controller's registers.

Table 6.2Bus Controller Registers

				Initia	al Value
Address*	Name	Abbreviation	R/W	Modes 1, 3, 5, 6	Modes 2, 4, 7
H'FFEC	Bus width control register	ABWCR	R/W	H'FF	H'00
H'FFED	Access state control register	ASTCR	R/W	H'FF	H'FF
H'FFEE	Wait control register	WCR	R/W	H'F3	H'F3
H'FFEF	Wait state controller enable register	WCER	R/W	H'FF	H'FF
H'FFF3	Bus release control register	BRCR	R/W	H'FE	H'FE
H'FF5F	Chip select control register	CSCR	R/W	H'0F	H'0F

Note: * Lower 16 bits of the address.

6.2 **Register Descriptions**

6.2.1 Bus Width Control Register (ABWCR)

ABWCR is an 8-bit readable/writable register that selects 8-bit or 16-bit access for each area.

_	7	6	5	4	3	2	1	0
	ABW7	ABW6	ABW5	ABW4	ABW3	ABW2	ABW1	ABW0
, 3, 5, 6	6 1	1	1	1	1	1	1	1
2, 4, 7	0	0	0	0	0	0	0	0
	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	1, 3, 5, 6 2, 4, 7	1, 3, 5, 6 1 2, 4, 7 0	ABW7 ABW6 1, 3, 5, 6 1 1 2, 4, 7 0 0	ABW7 ABW6 ABW5 1, 3, 5, 6 1 1 1 2, 4, 7 0 0 0	ABW7 ABW6 ABW5 ABW4 1, 3, 5, 6 1 1 1 1 2, 4, 7 0 0 0 0	ABW7 ABW6 ABW5 ABW4 ABW3 1, 3, 5, 6 1 1 1 1 1 2, 4, 7 0 0 0 0 0	ABW7 ABW6 ABW5 ABW4 ABW3 ABW2 1, 3, 5, 6 1 1 1 1 1 1 2, 4, 7 0 0 0 0 0 0	ABW7 ABW6 ABW5 ABW4 ABW3 ABW2 ABW1 1, 3, 5, 6 1 1 1 1 1 1 1 2, 4, 7 0 0 0 0 0 0 0

Bits selecting bus width for each area

When ABWCR contains H'FF (selecting 8-bit access for all areas), the chip operates in 8-bit bus mode: the upper data bus (D_{15} to D_8) is valid, and port 4 is an input/output port. When at least one bit is cleared to 0 in ABWCR, the chip operates in 16-bit bus mode with a 16-bit data bus (D_{15} to D_0). In modes 1, 3, 5, and 6 ABWCR is initialized to H'FF by a reset and in hardware standby mode. In modes 2, 4, and 7 ABWCR is initialized to H'00 by a reset and in hardware standby mode. ABWCR is not initialized in software standby mode.

Bits 7 to 0—Areas 7 to 0 Bus Width Control (ABW7 to ABW0): These bits select 8-bit access or 16-bit access to the corresponding address areas.

Bits 7 to 0: ABW7 to ABW0	Description
0	Areas 7 to 0 are 16-bit access areas
1	Areas 7 to 0 are 8-bit access areas

ABWCR specifies the bus width of external memory areas. The bus width of on-chip memory and internal I/O registers is fixed and does not depend on ABWCR settings. These settings are therefore meaningless in single-chip mode (mode 7).

6.2.2 Access State Control Register (ASTCR)

ASTCR is an 8-bit readable/writable register that selects whether each area is accessed in two states or three states.

Bit	7	6	5	4	3	2	1	0
	AST7	AST6	AST5	AST4	AST3	AST2	AST1	AST0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

Bits selecting number of states for access to each area

ASTCR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

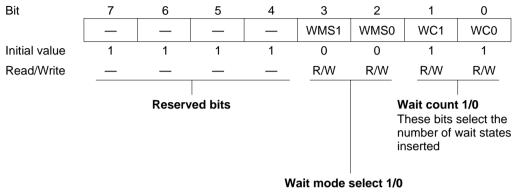
Bits 7 to 0—Areas 7 to 0 Access State Control (AST7 to AST0): These bits select whether the corresponding area is accessed in two or three states.

Bits 7 to 0: AST7 to AST0	Description	
0	Areas 7 to 0 are accessed in two states	
1	Areas 7 to 0 are accessed in three states	(Initial value)

ASTCR specifies the number of states in which external areas are accessed. On-chip memory and internal I/O registers are accessed in a fixed number of states that does not depend on ASTCR settings. These settings are therefore meaningless in single-chip mode (mode 7).

6.2.3 Wait Control Register (WCR)

WCR is an 8-bit readable/writable register that selects the wait mode for the wait-state controller (WSC) and specifies the number of wait states.



These bits select the wait mode

WCR is initialized to H'F3 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 4—Reserved: Read-only bits, always read as 1.

Bits 3 and 2—Wait Mode Select 1 and 0 (WMS1/0): These bits select the wait mode.

Bit 3: WMS1	Bit 2: WMS0	Description
0	0	Programmable wait mode (Initial value)
	1	No wait states inserted by wait-state controller
1	0	Pin wait mode 1
	1	Pin auto-wait mode

Bits 1 and 0—Wait Count 1 and 0 (WC1/0): These bits select the number of wait states inserted in access to external three-state-access areas.

Bit 1: WC1	Bit 0: WC0	Description					
0	0	No wait states inserted by wait-state controller					
	1	1 state inserted					
1	0	2 states inserted					
	1	3 states inserted	(Initial value)				

6.2.4 Wait State Controller Enable Register (WCER)

WCER is an 8-bit readable/writable register that enables or disables wait-state control of external three-state-access areas by the wait-state controller.

7	6	5	4	3	2	1	0
NCE7	WCE6	WCE5	WCE4	WCE3	WCE2	WCE1	WCE0
1	1	1	1	1	1	1	1
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	1	1 1	1 1 1	VCE7 WCE6 WCE5 WCE4 1 1 1 1 1	VCE7 WCE6 WCE5 WCE4 WCE3 1 1 1 1 1 1	VCE7 WCE6 WCE5 WCE4 WCE3 WCE2 1 1 1 1 1 1 1	VCE7 WCE6 WCE5 WCE4 WCE3 WCE2 WCE1 1 1 1 1 1 1 1 1

Wait-state controller enable 7 to 0

These bits enable or disable wait-state control

WCER is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 0—Wait-State Controller Enable 7 to 0 (WCE7 to WCE0): These bits enable or disable wait-state control of external three-state-access areas.

Bits 7 to 0: WCE7 to WCE0	Description	
0	Wait-state control disabled (pin wait mode 0)	
1	Wait-state control enabled	(Initial value)

Since WCER enables or disables wait-state control of external three-state-access areas, these settings are meaningless in single-chip mode (mode 7).

6.2.5 Bus Release Control Register (BRCR)

BRCR is an 8-bit readable/writable register that enables address output on bus lines A_{23} to A_{21} and enables or disables release of the bus to an external device.

Bit	7	6	5	4	3	2	1	0	
	A23E	A22E	A21E	—	—	—	_	BRLE	
Initial value	1	1	1	1	1	1	1	0	
Read/ Mode 1, 2, 5,	7 —	—	—	—	—	—	—	R/W	
Write Mode 3, 4, 6	R/W	R/W	R/W	_	—	—	_	R/W	
Address 23 to 21 enable				Rese	rved bits		Bus release enable		
These bits enable PA ₆ to							Enables o	r disables	
PA_4 to be used for A_{23} to							release of		
	A ₂₁ add	ress outpu	It				an externa	al device	

BRCR is initialized to H'FE by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bit 7—Address 23 Enable (A23E): Enables PA_4 to be used as the A_{23} address output pin. Writing 0 in this bit enables A_{23} address output from PA_4 . In modes other than 3, 4, and 6 this bit cannot be modified and PA_4 has its ordinary input/output functions.

Bit 7: A23E	Description	
0	PA ₄ is the A ₂₃ address output pin	
1	PA_4 is the $PA_4/TP_4/TIOCA_1$ input/output pin	(Initial value)

Bit 6—Address 22 Enable (A22E): Enables PA_5 to be used as the A_{22} address output pin. Writing 0 in this bit enables A_{22} address output from PA_5 . In modes other than 3, 4, and 6 this bit cannot be modified and PA_5 has its ordinary input/output functions.

Bit 6: A22E	Description	
0	PA_5 is the A_{22} address output pin	
1	PA_5 is the $PA_5/TP_5/TIOCB_1$ input/output pin	(Initial value)

Bit 5—Address 21 Enable (A21E): Enables PA_6 to be used as the A_{21} address output pin. Writing 0 in this bit enables A_{21} address output from PA_6 . In modes other than 3, 4, and 6 this bit cannot be modified and PA_6 has its ordinary input/output functions.

Bit 5: A21E	Description	
0	PA_6 is the A_{21} address output pin	
1	PA_6 is the $PA_6/TP_6/TIOCA_2$ input/output pin	(Initial value)

Bits 4 to 1—Reserved: Read-only bits, always read as 1.

Bit 0—Bus Release Enable (BRLE): Enables or disables release of the bus to an external device.

Bit 0: BRLE	Description	
0	The bus cannot be released to an external device; BREQ a used as input/output pins	nd BACK can be (Initial value)
1	The bus can be released to an external device	

6.2.6 Chip Select Control Register (CSCR)

CSCR is an 8-bit readable/writable register that enables or disables output of chip select signals $(\overline{CS}_7 \text{ to } \overline{CS}_4)$.

If a chip select signal $(\overline{CS}_7 \text{ to } \overline{CS}_4)$ output is selected in this register, the corresponding pin functions as a chip select signal $(\overline{CS}_7 \text{ to } \overline{CS}_4)$ output, this function taking priority over other functions. CSCR cannot be modified in single-chip mode.

Bit	7	6	5	4	3	2	1	0
	CS7E	CS6E	CS5E	CS4E	—	_		_
Initial value	0	0	0	0	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	_	—	_	
	Chip select 7 to 4 enable These bits enable or disable chip select signal output						ved bits	

CSCR is initialized to H'0F by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 4—Chip Select 7 to 4 Enable (CS7E to CS4E): These bits enable or disable output of the corresponding chip select signal.

Bit n: CSnE	Description	
0	Output of chip select signal CS _n is disabled	(Initial value)
1	Output of chip select signal CS _n is enabled	
Note: n = 7 to 4		

Bits 3 to 0—Reserved: Read-only bits, always read as 1.



6.3 Operation

6.3.1 Area Division

The external address space is divided into areas 0 to 7. Each area has a size of 128 kbytes in the 1-Mbyte modes, or 2 Mbytes in the 16-Mbyte modes. Figure 6.2 shows a general view of the memory map.

H'00000		H'000000		H'00000	On-chip ROM *1	H'000000	On-chip ROM *1
H'1FFFF	Area 0 (128 kbytes)	H'1FFFFF	Area 0 (2 Mbytes)	H'1FFFF	Area 0 (128 kbytes)	H'1FFFFF	Area 0 (2 Mbytes)
H'20000		H'200000		H'20000		H'200000	
	Area 1 (128 kbytes)		Area 1 (2 Mbytes)		Area 1 (128 kbytes)		Area 1 (2 Mbytes)
H'3FFFF H'40000		H'3FFFFF		H'3FFFF H'40000		H'3FFFFF H'400000	
H 40000	Area 2 (128 kbytes)	H'400000	Area 2 (2 Mbytes)	H 40000	Area 2 (128 kbytes)	H 400000	Area 2 (2 Mbytes)
H'5FFFF	Alea 2 (120 KDyles)	H'5FFFFF	Alea 2 (2 Mbyles)	H'5FFFF	Alea 2 (120 KDyles)	H'5FFFFF	Alea 2 (2 Mbytes)
H'60000		H'600000		H'60000		H'600000	
	Area 3 (128 kbytes)		Area 3 (2 Mbytes)		Area 3 (128 kbytes)		Area 3 (2 Mbytes)
H'7FFFF H'80000		H'7FFFFF H'800000		H'7FFFF H'80000		H'7FFFFF H'800000	
П 00000	Area 4 (128 kbytes)		Area 4 (2 Mbytes)	П 00000	Area 4 (128 kbytes)	П 000000	Area 4 (2 Mbytes)
H'9FFFF	/ 120 hby(00)	H'9FFFFF	/ 100 4 (2 Mby105)	H'9FFFF	/ 120 hby (00)	H'9FFFFF	/ lou + (2 libytoo)
H'A0000		H'A00000		H'A0000		H'A00000	
	Area 5 (128 kbytes)		Area 5 (2 Mbytes)		Area 5 (128 kbytes)		Area 5 (2 Mbytes)
H'BFFFF H'C0000		H'BFFFFF H'C00000		H'BFFFF H'C0000		H'BFFFFF H'C00000	
	Area 6 (128 kbytes)	11000000	Area 6 (2 Mbytes)	1100000	Area 6 (128 kbytes)	11000000	Area 6 (2 Mbytes)
-I'DFFFF		H'DFFFFF		H'DFFFF		H'DFFFFF	
H'E0000	Area 7 (128 kbytes)	H'E00000	Area 7 (2 Mbytes)	H'E0000	Area 7 (128 kbytes)	H'E00000	Area 7 (2 Mbytes)
	On-chip RAM*1 *2		On-chip RAM*1 *2		On-chip RAM*1 *2		On-chip RAM*1 *2
	External address space ^{*3}		External address space ^{*3}		External address space*3		External address space*
H'FFFFF	Internal I/O registers*1	H'FFFFFF	Internal I/O registers*1	H'FFFFF	Internal I/O registers*1	H'FFFFFF	Internal I/O registers*1
	a. 1-Mbyte modes with on-chip ROM disabled (modes 1 and 2)		 b. 16-Mbyte modes with on-chip ROM disabled (modes 3 and 4) 		c. 1-Mbyte mode with on-chip ROM enabled (mode 5)		d. 16-Mbyte mode with on-chip ROM enabled (mode 6)

Figure 6.2 Access Area Map for Modes 1 to 6

Chip select signals (\overline{CS}_7 to \overline{CS}_0) can be output for areas 7 to 0. The bus specifications for each area can be selected in ABWCR, ASTCR, WCER, and WCR as shown in table 6.3.

ABWCR	ASTCR	WCER	WCR		Bus Specifications		
ABWn	ASTn	WCEn	WMS1	WMS0	Bus Width	Access States	Wait Mode
0	0	_	_	_	16	2	Disabled
	1	0	_	_	16	3	Pin wait mode 0
		1	0	0	16	3	Programmable wait mode
				1	16	3	Disabled
			1	0	16	3	Pin wait mode 1
				1	16	3	Pin auto-wait mode
1	0	_	_	_	8	2	Disabled
	1	0	_	_	8	3	Pin wait mode 0
		1	0	0	8	3	Programmable wait mode
				1	8	3	Disabled
			1	0	8	3	Pin wait mode 1
				1	8	3	Pin auto-wait mode

Table 6.3	Bus Specifications
-----------	---------------------------

Note: n = 0 to 7

6.3.2 Chip Select Signals

For each of areas 7 to 0, the H8/3048 Group can output a chip select signal (\overline{CS}_7 to \overline{CS}_0) that goes low to indicate when the area is selected. Figure 6.3 shows the output timing of a \overline{CS}_n signal (n = 0 to 7).

Output of \overline{CS}_3 to \overline{CS}_0: Output of \overline{CS}_3 to \overline{CS}_0 is enabled or disabled in the data direction register (DDR) of the corresponding port.

In the expanded modes with on-chip ROM disabled, a reset leaves pin \overline{CS}_0 in the output state and pins \overline{CS}_3 to \overline{CS}_1 in the input state. To output chip select signals \overline{CS}_3 to \overline{CS}_1 , the corresponding DDR bits must be set to 1. In the expanded modes with on-chip ROM enabled, a reset leaves pins \overline{CS}_3 to \overline{CS}_0 in the input state. To output chip select signals \overline{CS}_3 to \overline{CS}_0 , the corresponding DDR bits must be set to 1. For details see section 9, I/O Ports.

Output of \overline{CS}_7 to \overline{CS}_4: Output of \overline{CS}_7 to \overline{CS}_4 is enabled or disabled in the chip select control register (CSCR). A reset leaves pins \overline{CS}_7 to \overline{CS}_4 in the input state. To output chip select signals \overline{CS}_7 to \overline{CS}_4 , the corresponding CSCR bits must be set to 1. For details see section 9, I/O Ports.

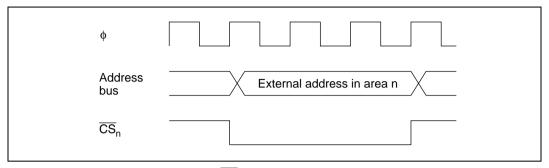


Figure 6.3 \overline{CS}_n Output Timing (n = 7 to 0)

When the on-chip ROM, on-chip RAM, and internal I/O registers are accessed, \overline{CS}_7 and \overline{CS}_0 remain high. The \overline{CS}_n signals are decoded from the address signals. They can be used as chip select signals for SRAM and other devices.

6.3.3 Data Bus

The H8/3048 Group allows either 8-bit access or 16-bit access to be designated for each of areas 7 to 0. An 8-bit-access area uses the upper data bus (D_{15} to D_8). A 16-bit-access area uses both the upper data bus (D_{15} to D_8) and lower data bus (D_7 to D_0).

In read access the $\overline{\text{RD}}$ signal applies without distinction to both the upper and lower data bus. In write access the $\overline{\text{HWR}}$ signal applies to the upper data bus, and the $\overline{\text{LWR}}$ signal applies to the lower data bus.

Table 6.4 indicates how the two parts of the data bus are used under different access conditions.

Area	Access Size	Read/W rite	Address	Valid Strobe	Upper Data Bus (D ₁₅ to D ₈)	Lower Data Bus (D ₇ to D ₀)
8-bit-access	—	Read	—	RD	Valid	Invalid
area		Write		HWR	_	Undetermined data
16-bit-access	Byte	Read	Even	RD	Valid	Invalid
area			Odd	_	Invalid	Valid
		Write	Even	HWR	Valid	Undetermined data
			Odd	LWR	Undetermined data	Valid
	Word	Read	_	RD	Valid	Valid
		Write	—	HWR, LWR	Valid	Valid

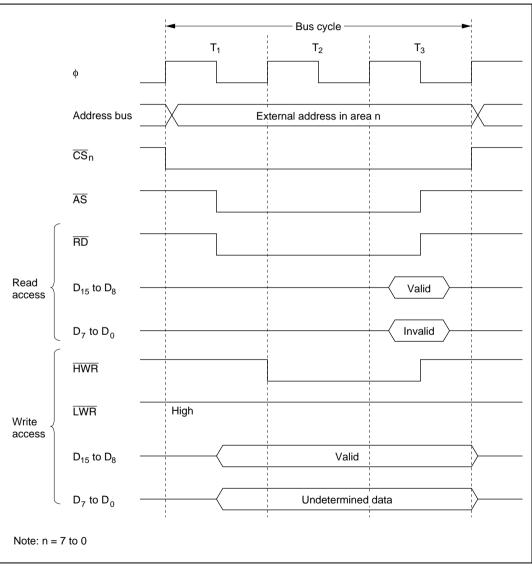
 Table 6.4
 Access Conditions and Data Bus Usage

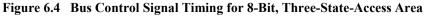
Note: Undetermined data means that unpredictable data is output. Invalid means that the bus is in the input state and the input is ignored.



6.3.4 Bus Control Signal Timing

8-Bit, Three-State-Access Areas: Figure 6.4 shows the timing of bus control signals for an 8-bit, three-state-access area. The upper address bus (D_{15} to D_8) is used to access these areas. The \overline{LWR} pin is always high. Wait states can be inserted.





8-Bit, Two-State-Access Areas: Figure 6.5 shows the timing of bus control signals for an 8-bit, two-state-access area. The upper address bus (D_{15} to D_8) is used to access these areas. The \overline{LWR} pin is always high. Wait states cannot be inserted.

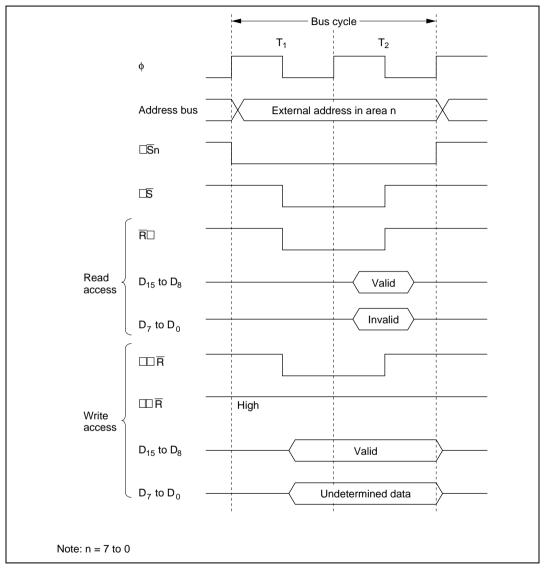
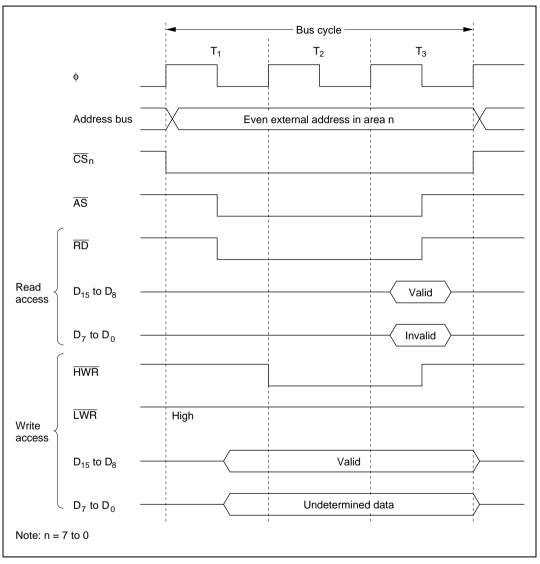
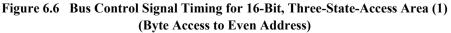
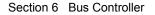


Figure 6.5 Bus Control Signal Timing for 8-Bit, Two-State-Access Area

16-Bit, Three-State-Access Areas: Figures 6.6 to 6.8 show the timing of bus control signals for a 16-bit, three-state-access area. In these areas, the upper address bus $(D_{15} \text{ to } D_8)$ is used to access even addresses and the lower address bus $(D_7 \text{ to } D_0)$ is used to access odd addresses. Wait states can be inserted.







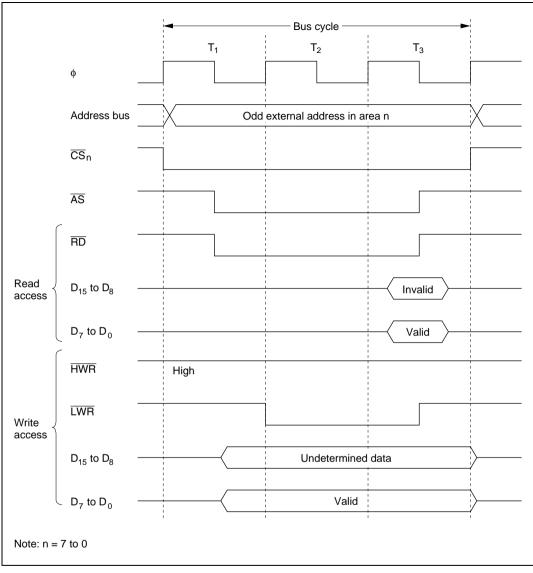


Figure 6.7 Bus Control Signal Timing for 16-Bit, Three-State-Access Area (2) (Byte Access to Odd Address)

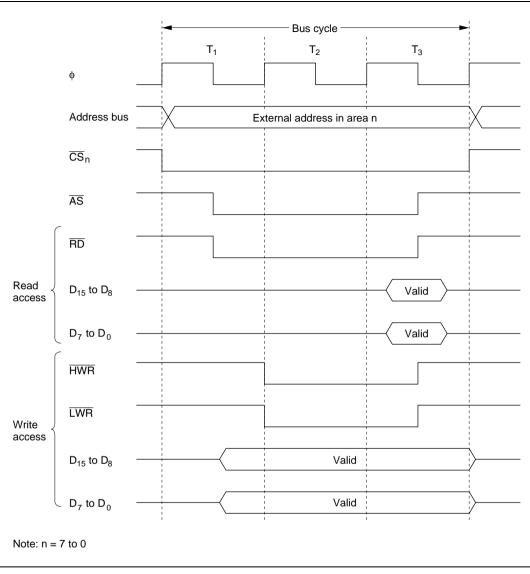
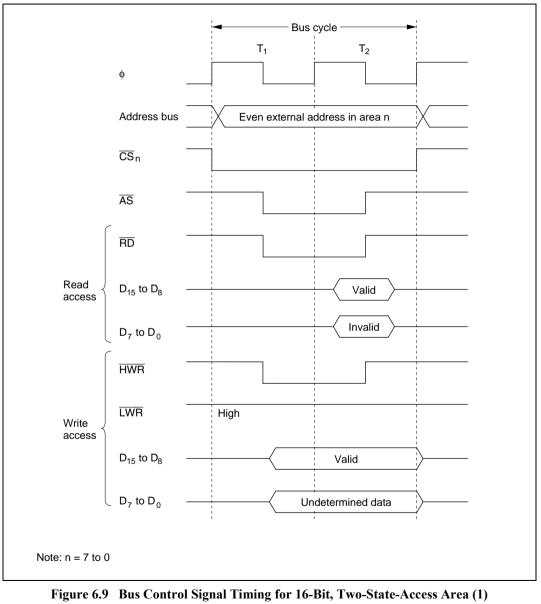


Figure 6.8 Bus Control Signal Timing for 16-Bit, Three-State-Access Area (3) (Word Access)

16-Bit, Two-State-Access Areas: Figures 6.9 to 6.11 show the timing of bus control signals for a 16-bit, two-state-access area. In these areas, the upper address bus (D_{15} to D_8) is used to access even addresses and the lower address bus (D_7 to D_0) is used to access odd addresses. Wait states cannot be inserted.



(Byte Access to Even Address)

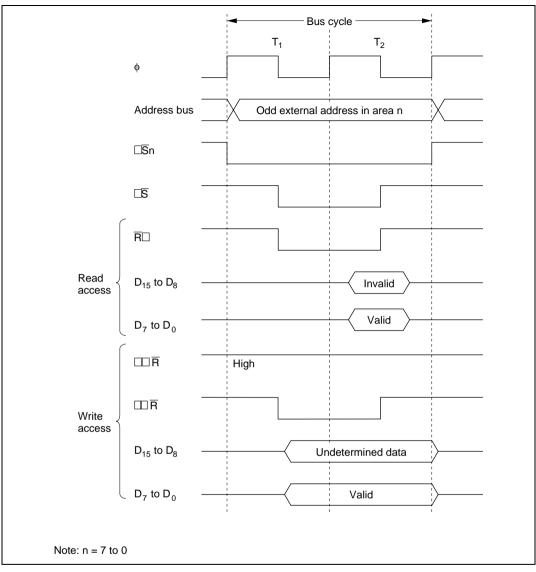
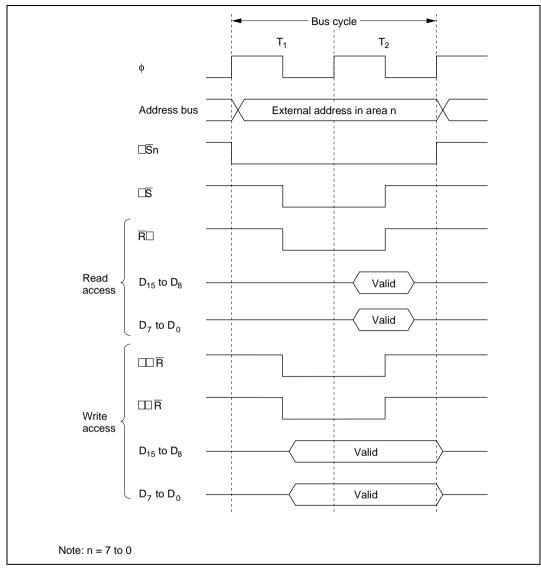
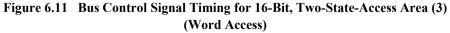


Figure 6.10 Bus Control Signal Timing for 16-Bit, Two-State-Access Area (2) (Byte Access to Odd Address)

Section 6 Bus Controller





6.3.5 Wait Modes

Four wait modes can be selected as shown in table 6.5.

Table 6.5	Wait Mode Selection
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ASTCR	WCER	WCR		WCR			
ASTn Bit	WCEn Bit	WMS1 Bit	WMS0 Bit	WSC Control	Wait Mode		
0		_	_	Disabled	No wait states		
1	0	_	_	Disabled	Pin wait mode 0		
	1	0	0	Enabled	Programmable wait mode		
			1	Enabled	No wait states		
		1	0	Enabled	Pin wait mode 1		
			1	Enabled	Pin auto-wait mode		

Note: n = 7 to 0

Wait Mode in Areas Where Wait-State Controller is Disabled

External three-state access areas in which the wait-state controller is disabled (ASTn = 1, WCEn = 0) operate in pin wait mode 0. The other wait modes are unavailable. The settings of bits WMS1 and WMS0 are ignored in these areas.

Pin Wait Mode 0: Wait states can only be inserted by \overline{WAIT} pin control. During access to an external three-state-access area, if the \overline{WAIT} pin is low at the fall of the system clock (ϕ) in the T₂ state, a wait state (T_W) is inserted. If the \overline{WAIT} pin remains low, wait states continue to be inserted until the \overline{WAIT} signal goes high. Figure 6.12 shows the timing.

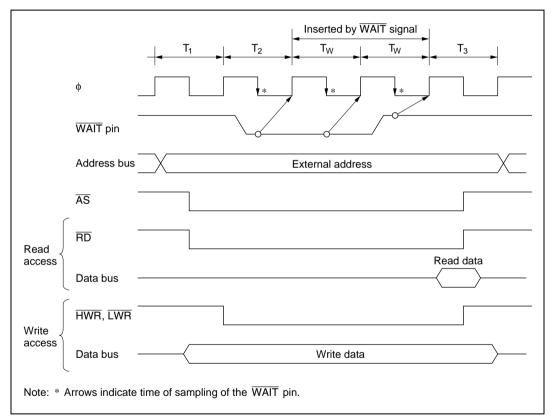


Figure 6.12 Pin Wait Mode 0

Wait Modes in Areas Where Wait-State Controller is Enabled

External three-state access areas in which the wait-state controller is enabled (ASTn = 1, WCEn = 1) can operate in pin wait mode 1, pin auto-wait mode, or programmable wait mode, as selected by bits WMS1 and WMS0. Bits WMS1 and WMS0 apply to all areas, so all areas in which the wait-state controller is enabled operate in the same wait mode.

Pin Wait Mode 1: In all accesses to external three-state-access areas, the number of wait states (T_W) selected by bits WC1 and WC0 are inserted. If the WAIT pin is low at the fall of the system clock (ϕ) in the last of these wait states, an additional wait state is inserted. If the WAIT pin remains low, wait states continue to be inserted until the WAIT signal goes high.

Pin wait mode 1 is useful for inserting four or more wait states, or for inserting different numbers of wait states for different external devices.

If the wait count is 0, this mode operates in the same way as pin wait mode 0.

Figure 6.13 shows the timing when the wait count is 1 (WC1 = 0, WC0 = 1) and one additional wait state is inserted by \overline{WAIT} input.

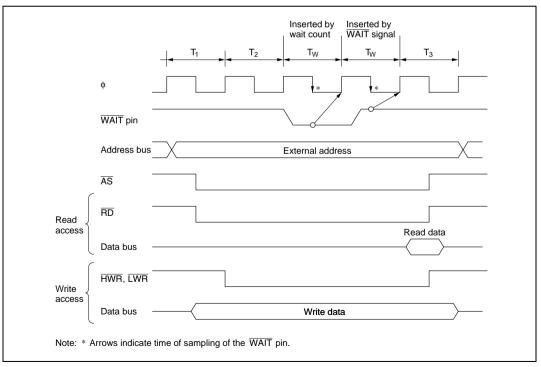


Figure 6.13 Pin Wait Mode 1

Pin Auto-Wait Mode: If the \overline{WAIT} pin is low, the number of wait states (T_W) selected by bits WC1 and WC0 are inserted.

In pin auto-wait mode, if the \overline{WAIT} pin is low at the fall of the system clock (ϕ) in the T₂ state, the number of wait states (T_W) selected by bits WC1 and WC0 are inserted. No additional wait states are inserted even if the \overline{WAIT} pin remains low. Pin auto-wait mode can be used for an easy interface to low-speed memory, simply by routing the chip select signal to the \overline{WAIT} pin.

Figure 6.14 shows the timing when the wait count is 1.

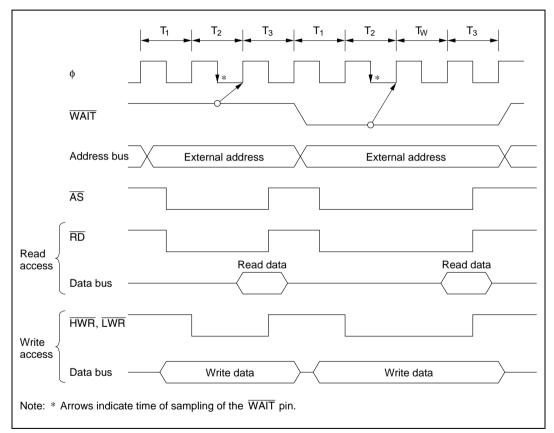


Figure 6.14 Pin Auto-Wait Mode



Programmable Wait Mode: The number of wait states (T_W) selected by bits WC1 and WC0 are inserted in all accesses to external three-state-access areas. Figure 6.15 shows the timing when the wait count is 1 (WC1 = 0, WC0 = 1).

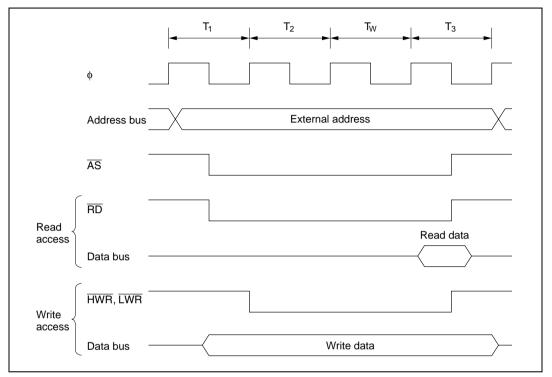


Figure 6.15 Programmable Wait Mode

Example of Wait State Control Settings: A reset initializes ASTCR and WCER to H'FF and WCR to H'F3, selecting programmable wait mode and three wait states for all areas. Software can select other wait modes for individual areas by modifying the ASTCR, WCER, and WCR settings. Figure 6.16 shows an example of wait mode settings.

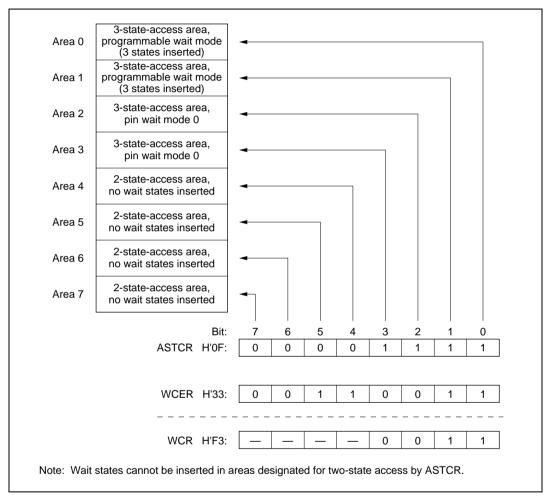


Figure 6.16 Wait Mode Settings (Example)

6.3.6 Interconnections with Memory (Example)

For each area, the bus controller can select two- or three-state access and an 8- or 16-bit data bus width. In three-state-access areas, wait states can be inserted in a variety of modes, simplifying the connection of both high-speed and low-speed devices.

Figure 6.18 shows an example of interconnections between the H8/3048 Group and memory. Figure 6.17 shows a memory map for this example.

A 256-kword \times 16-bit EPROM is connected to area 0. This device is accessed in three states via a 16-bit bus.

Two 32-kword \times 8-bit SRAM devices (SRAM1 and SRAM2) are connected to area 1. These devices are accessed in two states via a 16-bit bus.

One 32-kword \times 8-bit SRAM (SRAM3) is connected to area 2. This device is accessed via an 8-bit bus, using three-state access with an additional wait state inserted in pin auto-wait mode.

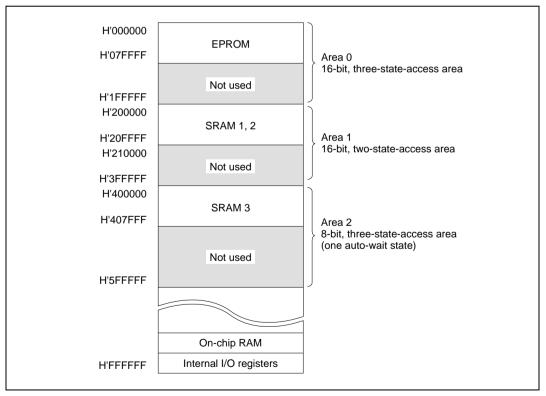


Figure 6.17 Memory Map (Example)

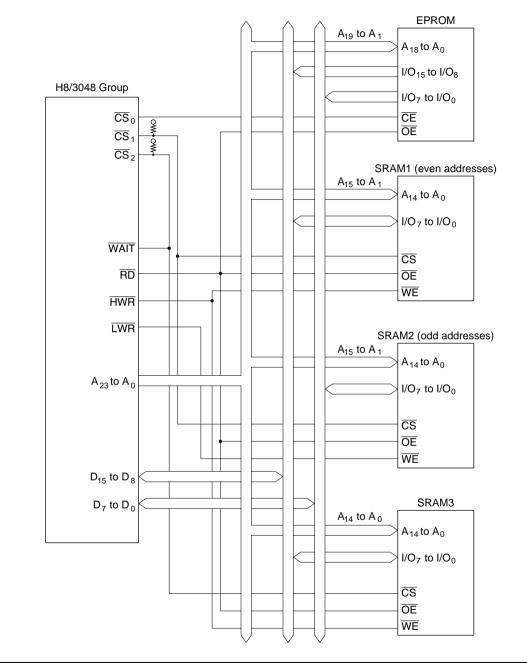


Figure 6.18 Interconnections with Memory (Example)

6.3.7 Bus Arbiter Operation

The bus controller has a built-in bus arbiter that arbitrates between different bus masters. There are four bus masters: the CPU, DMA controller (DMAC), refresh controller, and an external bus master. When a bus master has the bus right it can carry out read, write, or refresh access. Each bus master uses a bus request signal to request the bus right. At fixed times the bus arbiter determines priority and uses a bus acknowledge signal to grant the bus to a bus master, which can then operate using the bus.

The bus arbiter checks whether the bus request signal from a bus master is active or inactive, and returns an acknowledge signal to the bus master if the bus request signal is active. When two or more bus masters request the bus, the highest-priority bus master receives an acknowledge signal. The bus master that receives an acknowledge signal can continue to use the bus until the acknowledge signal is deactivated.

The bus master priority order is:

(High) External bus master > refresh controller > DMAC > CPU (Low)

The bus arbiter samples the bus request signals and determines priority at all times, but it does not always grant the bus immediately, even when it receives a bus request from a bus master with higher priority than the current bus master. Each bus master has certain times at which it can release the bus to a higher-priority bus master.

CPU: The CPU is the lowest-priority bus master. If the DMAC, refresh controller, or an external bus master requests the bus while the CPU has the bus right, the bus arbiter transfers the bus right to the bus master that requested it. The bus right is transferred at the following times:

- The bus right is transferred at the boundary of a bus cycle. If word data is accessed by two consecutive byte accesses, however, the bus right is not transferred between the two byte accesses.
- If another bus master requests the bus while the CPU is performing internal operations, such as executing a multiply or divide instruction, the bus right is transferred immediately. The CPU continues its internal operations.
- If another bus master requests the bus while the CPU is in sleep mode, the bus right is transferred immediately.

DMAC: When the DMAC receives an activation request, it requests the bus right from the bus arbiter. If the DMAC is bus master and the refresh controller or an external bus master requests the bus, the bus arbiter transfers the bus right from the DMAC to the bus master that requested the bus. The bus right is transferred at the following times.

The bus right is transferred when the DMAC finishes transferring 1 byte or 1 word. A DMAC transfer cycle consists of a read cycle and a write cycle. The bus right is not transferred between the read cycle and the write cycle.

There is a priority order among the DMAC channels. For details see section 8.4.9, DMAC Multiple-Channel Operation.

Refresh Controller: When a refresh cycle is requested, the refresh controller requests the bus right from the bus arbiter. When the refresh cycle is completed, the refresh controller releases the bus. For details see section 7, Refresh Controller.

External Bus Master: When the BRLE bit is set to 1 in BRCR, the bus can be released to an external bus master. The external bus master has highest priority, and requests the bus right from the bus arbiter by driving the BREQ signal low. Once the external bus master gets the bus, it keeps the bus right until the BREQ signal goes high. While the bus is released to an external bus master, the H8/3048 Group holds the address bus and data bus control signals (\overline{AS} , \overline{RD} , \overline{HWR} , and \overline{LWR}) in the high-impedance state, holds the chip select signals high (\overline{CS}_n : n = 7 to 0), and holds the BACK pin in the low output state.

The bus arbiter samples the \overline{BREQ} pin at the rise of the system clock (ϕ). If \overline{BREQ} is low, the bus is released to the external bus master at the appropriate opportunity. The \overline{BREQ} signal should be held low until the \overline{BACK} signal goes low.

When the \overline{BREQ} pin is high in two consecutive samples, the \overline{BACK} signal is driven high to end the bus-release cycle.



Figure 6.19 shows the timing when the bus right is requested by an external bus master during a read cycle in a two-state-access area. There is a minimum interval of two states from when the BREQ signal goes low until the bus is released.

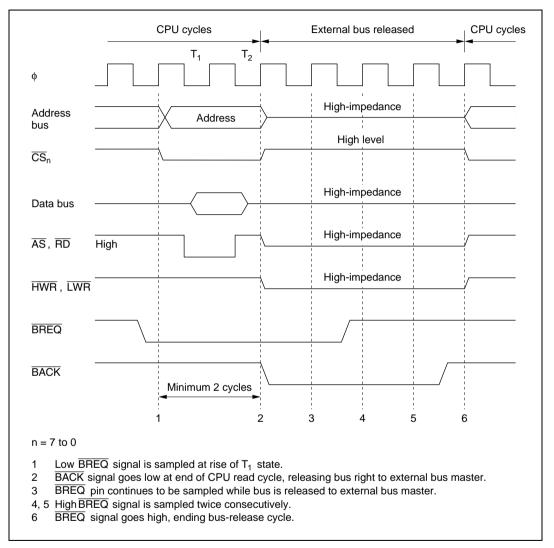


Figure 6.19 External-Bus-Released State (Two-State-Access Area, During Read Cycle)

6.4 Usage Notes

6.4.1 Connection to Dynamic RAM and Pseudo-Static RAM

A different bus control signal timing applies when dynamic RAM or pseudo-static RAM is connected to area 3. For details see section 7, Refresh Controller.

6.4.2 Register Write Timing

ABWCR, ASTCR, and WCER Write Timing: Data written to ABWCR, ASTCR, or WCER takes effect starting from the next bus cycle. Figure 6.20 shows the timing when an instruction fetched from area 0 changes area 0 from three-state access to two-state access.

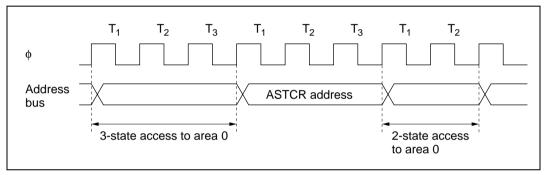


Figure 6.20 ASTCR Write Timing



DDR Write Timing: Data written to a data direction register (DDR) to change a \overline{CS}_n pin from \overline{CS}_n output to generic input, or vice versa, takes effect starting from the T₃ state of the DDR write cycle. Figure 6.21 shows the timing when the \overline{CS}_1 pin is changed from generic input to \overline{CS}_1 output.

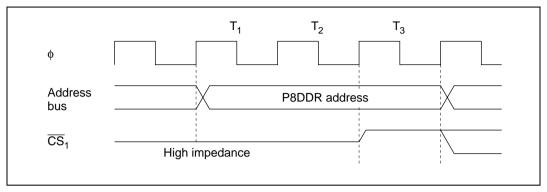


Figure 6.21 DDR Write Timing

BRCR Write Timing: Data written to switch between A_{23} , A_{22} , or A_{21} output and generic input or output takes effect starting from the T_3 state of the BRCR write cycle. Figure 6.22 shows the timing when a pin is changed from generic input to A_{23} , A_{22} , or A_{21} output.

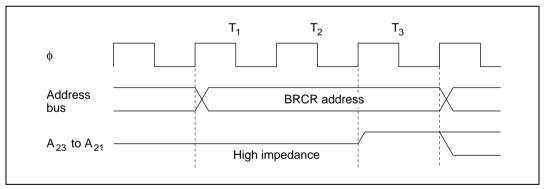


Figure 6.22 BRCR Write Timing

6.4.3 **BREQ** Input Timing

After driving the \overline{BREQ} pin low, hold it low until \overline{BACK} goes low. If \overline{BREQ} returns to the high level before \overline{BACK} goes low, the bus arbiter may operate incorrectly.

To terminate the external-bus-released state, hold the \overline{BREQ} signal high for at least three states. If \overline{BREQ} is high for too short an interval, the bus arbiter may operate incorrectly.

6.4.4 Transition To Software Standby Mode

If contention occurs between a transition to software standby mode and a bus request from an external bus master, the bus may be released for one state just before the transition to software standby mode (see figure 6.23). When using software standby mode, clear the BRLE bit to 0 in BRCR before executing the SLEEP instruction.

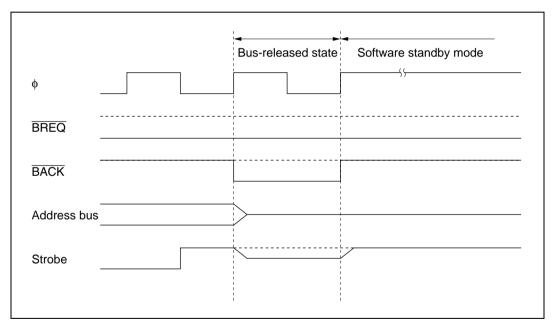


Figure 6.23 Contention between Bus-Released State and Software Standby Mode



Section 7 Refresh Controller

7.1 Overview

The H8/3048 Group has an on-chip refresh controller that enables direct connection of 16-bit-wide DRAM or pseudo-static RAM (PSRAM).

DRAM or pseudo-static RAM can be directly connected to area 3 of the external address space.

A maximum 128 kbytes can be connected in modes 1, 2, and 5 (1-Mbyte modes). A maximum

2 Mbytes can be connected in modes 3, 4, and 6 (16-Mbyte modes).

Systems that do not need to refresh DRAM or pseudo-static RAM can use the refresh controller as an 8-bit interval timer.

When the refresh controller is not used, it can be independently halted to conserve power. For details see section 21.6, Module Standby Function.

7.1.1 Features

The refresh controller can be used for one of three functions: DRAM refresh control, pseudo-static RAM refresh control, or 8-bit interval timing. Features of the refresh controller are listed below.

Features as a DRAM Refresh Controller

- Enables direct connection of 16-bit-wide DRAM
- Selection of $2\overline{CAS}$ or $2\overline{WE}$ mode
- Selection of 8-bit or 9-bit column address multiplexing for DRAM address input Examples:
 - 1-Mbit DRAM: 8-bit row address × 8-bit column address
 - 4-Mbit DRAM: 9-bit row address × 9-bit column address
 - 4-Mbit DRAM: 10-bit row address × 8-bit column address
- \overline{CAS} -before- \overline{RAS} refresh control
- Software-selectable refresh interval
- Software-selectable self-refresh mode
- Wait states can be inserted

Features as a Pseudo-Static RAM Refresh Controller

- $\overline{\text{RFSH}}$ signal output for refresh control
- Software-selectable refresh interval
- Software-selectable self-refresh mode
- Wait states can be inserted

Features as an Interval Timer

- Refresh timer counter (RTCNT) can be used as an 8-bit up-counter
- Selection of seven counter clock sources: φ/2, φ/8, φ/32, φ/128, φ/512, φ/2048, φ/4096
- Interrupts can be generated by compare match between RTCNT and the refresh time constant register (RTCOR)

7.1.2 Block Diagram

Figure 7.1 shows a block diagram of the refresh controller.

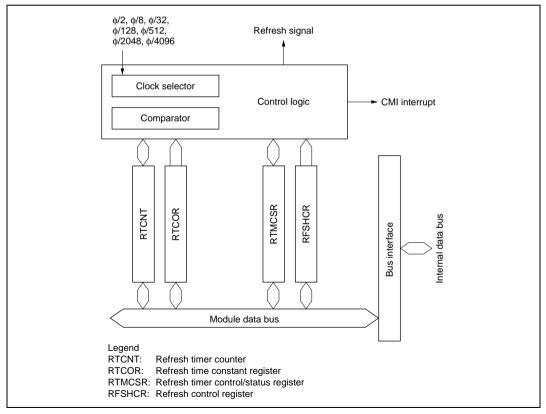


Figure 7.1 Block Diagram of Refresh Controller

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7.1.3 Input/Output Pins

Table 7.1 summarizes the refresh controller's input/output pins.

Table 7.1Refresh Controller Pins

	Signal				
Pin	Name	Abbr.	I/O	Function	
RFSH	Refresh	RFSH	Output	Goes low during refresh cycles; used to refresh DRAM and PSRAM	
HWR	Upper write/upper column address strobe	UW/UCAS	Output	Connects to the UW pin of 2WE DRAM or UCAS pin of 2CAS DRAM	
LWR	Lower write/lower column address strobe	LW/LCAS	Output	Connects to the LW pin of 2WE DRAM or LCAS pin of 2CAS DRAM	
RD	Column address strobe/ write enable	CAS/WE	Output	Connects to the CAS pin of 2WE DRAM or WE pin of 2CAS DRAM	
$\overline{\text{CS}}_3$	Row address strobe	RAS	Output	Connects to the \overline{RAS} pin of DRAM	

7.1.4 Register Configuration

Table 7.2 summarizes the refresh controller's registers.

Table 7.2 Refresh Controller Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFAC	Refresh control register	RFSHCR	R/W	H'02
H'FFAD	Refresh timer control/status register	RTMCSR	R/W	H'07
H'FFAE	Refresh timer counter	RTCNT	R/W	H'00
H'FFAF	Refresh time constant register	RTCOR	R/W	H'FF

Note: * Lower 16 bits of the address.

7.2 **Register Descriptions**

7.2.1 Refresh Control Register (RFSHCR)

RFSHCR is an 8-bit readable/writable register that selects the operating mode of the refresh controller.

Bit	7	6	5	4	3	2	1	0
	SRFMD	PSRAME	DRAME	CAS/WE	M9/M8	RFSHE	_	RCYCE
Initial value	0	0	0	0	0	0	1	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	_	R/W
							ena Ena disa inse	resh cycle ble bles or bles ertion of esh cycles
							Reserved	d bit
						Refresh pin enable Enables refresh signal output from the refresh pin		nal output
						ultiplex m number of		:t ddress bits
				trobe mod elects 2CA		E strobing	of DRAM	
			enable and DRAM enable s enable or disable connection of pseudo-static RAM and DRAM				and DRAM	
S	Self-refresh mode							

Selects self-refresh mode

RFSHCR is initialized to H'02 by a reset and in hardware standby mode.

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Bit 7—Self-Refresh Mode (SRFMD): Specifies DRAM or pseudo-static RAM self-refresh during software standby mode. When PSRAME = 1 and DRAME = 0, after the SRFMD bit is set to 1, pseudo-static RAM can be self-refreshed when the H8/3048 Group enters software standby mode. When PSRAME = 0 and DRAME = 1, after the SRFMD bit is set to 1, DRAM can be self-refreshed when the H8/3048 Group enters software standby mode. In either case, the normal access state resumes on exit from software standby mode.

Bit 7: SRFMD	Description
0	DRAM or PSRAM self-refresh is disabled in software standby mode
	(Initial value)
1	DRAM or PSRAM self-refresh is enabled in software standby mode

Bit 6—PSRAM Enable (PSRAME) and

Bit 5—DRAM Enable (DRAME): These bits enable or disable connection of pseudo-static RAM and DRAM to area 3 of the external address space.

When DRAM or pseudo-static RAM is connected, the bus cycle and refresh cycle of area 3 consist of three states, regardless of the setting in the access state control register (ASTCR). If AST3 = 0 in ASTCR, wait states cannot be inserted.

When the PSRAME or DRAME bit is set to 1, bits 0, 2, 3, and 4 in RFSHCR and registers RTMCSR, RTCNT, and RTCOR are write-disabled, except that the CMF flag in RTMCSR can be cleared by writing 0.

Bit 6: PSRAME	Bit 5: DRAME	Description
0	0	Can be used as an interval timer (Initial value)
		(DRAM and PSRAM cannot be directly connected)
	1	DRAM can be directly connected
1 0 PSRAM can be directly connected		PSRAM can be directly connected
	1	Illegal setting

Bit 4—Strobe Mode Select (CAS/WE): Selects $2\overline{CAS}$ or $2\overline{WE}$ mode. The setting of this bit is valid when PSRAME = 0 and DRAME = 1. This bit is write-disabled when the PSRAME or DRAME bit is set to 1.

Bit 4: CAS/WE	Description	
0	2WE mode	(Initial value)
1	2CAS mode	

Bit 3—Address Multiplex Mode Select (M9/M8): Selects 8-bit or 9-bit column addressing.

The setting of this bit is valid when PSRAME = 0 and DRAME = 1. This bit is write-disabled when the PSRAME or DRAME bit is set to 1.

Bit 3: M9/M8	Description	
0	8-bit column address mode	(Initial value)
1	9-bit column address mode	

Bit 2—Refresh Pin Enable (RFSHE): Enables or disables refresh signal output from the $\overline{\text{RFSH}}$ pin. This bit is write-disabled when the PSRAME or DRAME bit is set to 1.

Bit 2: RFSHE	Description	
0	Refresh signal output at the $\overline{\text{RFSH}}$ pin is disabled (the $\overline{\text{RF}}$ as a generic input/output port)	SH pin can be used (Initial value)
1	Refresh signal output at the RFSH pin is enabled	

Bit 1—Reserved: Read-only bit, always read as 1.

Bit 0-Refresh Cycle Enable (RCYCE): Enables or disables insertion of refresh cycles.

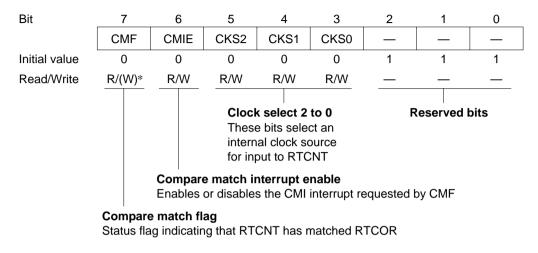
The setting of this bit is valid when PSRAME = 1 or DRAME = 1. When PSRAME = 0 and DRAME = 0, refresh cycles are not inserted regardless of the setting of this bit.

Bit 0: RCYCE	Description	
0	Refresh cycles are disabled	(Initial value)
1	Refresh cycles are enabled for area 3	



7.2.2 Refresh Timer Control/Status Register (RTMCSR)

RTMCSR is an 8-bit readable/writable register that selects the clock source for RTCNT. It also enables or disables interrupt requests when the refresh controller is used as an interval timer.



Note: * Only 0 can be written, to clear the flag.

Bits 7 and 6 are initialized by a reset and in standby mode. Bits 5 to 3 are initialized by a reset and in hardware standby mode, but retain their previous values on transition to software standby mode.

Bit 7—Compare Match Flag (CMF): This status flag indicates that the RTCNT and RTCOR values have matched.

Bit 7: CMF	Description
0	[Clearing condition]
	Cleared by reading CMF when CMF = 1, then writing 0 in CMF
1	[Setting condition]
	When RTCNT = RTCOR

Bit 6—Compare Match Interrupt Enable (CMIE): Enables or disables the CMI interrupt requested when the CMF flag is set to 1 in RTMCSR. The CMIE bit is always cleared to 0 when PSRAME = 1 or DRAME = 1.

Bit 6: CMIE	Description	
0	The CMI interrupt requested by CMF is disabled	(Initial value)
1	The CMI interrupt requested by CMF is enabled	

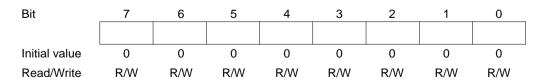
Bits 5 to 3—Clock Select 2 to 0 (CKS2 to CKS0): These bits select an internal clock source for input to RTCNT. When used for refresh control, the refresh controller outputs a refresh request at periodic intervals determined by compare match between RTCNT and RTCOR. When used as an interval timer, the refresh controller generates CMI interrupts at periodic intervals determined by compare match. These bits are write-disabled when the PSRAME bit or DRAME bit is set to 1.

Bit 5: CKS2	Bit 4: CKS1	Bit 3: CKS0	Description		
0	0	0	Clock input is disabled (Initial v		
		1	φ/2 clock source		
	1	0	ø/8 clock source		
		1	φ/32 clock source		
1	0	0	φ/128 clock source		
		1	φ/512 clock source		
	1	0	φ/2048 clock source		
		1	\$\phi\$/4096 clock source \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$		

Bits 2 to 0—Reserved: Read-only bits, always read as 1.

7.2.3 Refresh Timer Counter (RTCNT)

RTCNT is an 8-bit readable/writable up-counter.

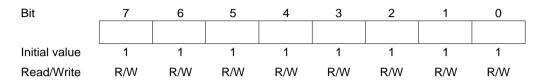


RTCNT is an up-counter that is incremented by an internal clock selected by bits CKS2 to CKS0 in RTMCSR. When RTCNT matches RTCOR (compare match), the CMF flag is set to 1 and RTCNT is cleared to H'00.

RTCNT is write-disabled when the PSRAME bit or DRAME bit is set to 1. RTCNT is initialized to H'00 by a reset and in standby mode.

7.2.4 Refresh Time Constant Register (RTCOR)

RTCOR is an 8-bit readable/writable register that determines the interval at which RTCNT is compare matched.



RTCOR and RTCNT are constantly compared. When their values match, the CMF flag is set to 1 in RTMCSR, and RTCNT is simultaneously cleared to H'00.

RTCOR is write-disabled when the PSRAME bit or DRAME bit is set to 1. RTCOR is initialized to H'FF by a reset and in hardware standby mode. In software standby mode it retains its previous value.

7.3 Operation

7.3.1 Overview

One of three functions can be selected for the H8/3048 Group refresh controller: interfacing to DRAM connected to area 3, interfacing to pseudo-static RAM connected to area 3, or interval timing. Table 7.3 summarizes the register settings when these three functions are used.

interrupt requests				Usage	
Intervention Intervention Intervention Intervention Intervention PSRAME Cleared to 0 Set to 1 Cleared to 0 DRAME Set to 1 Cleared to 0 Cleared to 0 DRAME Set to 1 Cleared to 0 Cleared to 0 CAS/WE Selects 2CAS or 2WE mode - - M9/M8 Selects column addressing mode - - RFSHE Selects column output - - RCYCE Selects insertion of refresh cycles Selects insertion of refresh cycles Cleared to 0 RTCOR Refresh interval setting Refresh interval setting Interrupt interval setting RTMCSR CKS2 to CKS0 Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interrupt requests	Register Settings		DRAM Interface	PSRAM Interface	Interval Timer
DRAME Set to 1 Cleared to 0 Cleared to 0 DRAME Set to 1 Cleared to 0 Cleared to 0 CAS/WE Selects 2CAS or 2WE mode - - M9/M8 Selects column addressing mode - - RFSHE Selects RFSH signal output Selects RFSH signal output Cleared to 0 RCYCE Selects insertion of refresh cycles Selects insertion of refresh cycles Cleared to 0 RTCOR Refresh interval setting Refresh interval setting Interrupt interval setting Interrupt interval setting RTMCSR CKS2 to CKS0 Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interrupt requests	RFSHCR SRFMD				
CAS/WE Selects 2CAS or 2WE mode - - - M9/M8 Selects column addressing mode - - - RFSHE Selects RFSH signal output Selects RFSH signal output Cleared to 0 - RCYCE Selects insertion of refresh cycles Selects insertion of refresh cycles Selects insertion of refresh cycles - RTCOR Refresh interval setting Refresh interval setting Refresh interval setting Interrupt interval setting RTMCSR CKS2 to CKS0 Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interval setting		PSRAME	Cleared to 0	Set to 1	Cleared to 0
2WE mode M9/M8 Selects column addressing mode — — RFSHE Selects RFSH signal output Selects RFSH signal output Cleared to 0 RCYCE Selects insertion of refresh cycles Selects insertion of refresh cycles Selects insertion of refresh cycles RTCOR Refresh interval setting Refresh interval setting Refresh interval setting Interrupt interval setting RTMCSR CKS2 to CKS0 Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interval requests		DRAME	Set to 1	Cleared to 0	Cleared to 0
addressing mode RFSHE Selects RFSH signal output Selects RFSH signal output Cleared to 0 RCYCE Selects insertion of refresh cycles Selects insertion of refresh cycles RTCOR Refresh interval setting Refresh interval setting Interrupt interval setting RTMCSR CKS2 to CKS0 Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interrupt requests		CAS/WE		_	
RTCOR Refresh interval setting Refresh interval setting Refresh interval setting Refresh interval setting RTMCSR CKS2 to CKS0 Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interval setting		M9/M8		—	_
RTCOR Refresh interval setting Refresh interval setting Refresh interval setting Interrupt interval setting RTMCSR CKS2 to CKS0 Set to 1 when RTCNT = RTCOR Refresh interval setting Interrupt interval setting CMF Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interrupt requests		RFSHE	•	•	Cleared to 0
RTMCSR CKS2 to CKS0 setting setting setting CMF Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interrupt requests		RCYCE			_
CKS0 Set to 1 when RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interrupt requests	RTCOR				
RTCNT = RTCOR RTCNT = RTCOR RTCNT = RTCOR CMIE Cleared to 0 Cleared to 0 Enables or disables interrupt requests	RTMCSR	0	setting	setting	setting
interrupt requests		CMF			
P8DDR P81DDR Set to 1 (\overline{CS}_3 output) Set to 1 (\overline{CS}_3 output) Set to 0 or 1		CMIE	Cleared to 0	Cleared to 0	Enables or disables interrupt requests
	P8DDR	P8₁DDR	Set to 1 (\overline{CS}_3 output)	Set to 1 (\overline{CS}_3 output)	Set to 0 or 1
ABWCR ABW3 Cleared to 0 — —	ABWCR	ABW3	Cleared to 0	_	—

Table 7.3 Refresh Controller Settings

DRAM Interface: To set up area 3 for connection to 16-bit-wide DRAM, initialize RTCOR, RTMCSR, and RFSHCR in that order, clearing bit PSRAME to 0 and setting bit DRAME to 1. Set bit P8₁DDR to 1 in the port 8 data direction register (P8DDR) to enable \overline{CS}_3 output. In ABWCR, make area 3 a 16-bit-access area.

Pseudo-Static RAM Interface: To set up area 3 for connection to pseudo-static RAM, initialize RTCOR, RTMCSR, and RFSHCR in that order, setting bit PSRAME to 1 and clearing bit DRAME to 0. Set bit P8₁DDR to 1 in P8DDR to enable \overline{CS}_3 output.

Interval Timer: When PSRAME = 0 and DRAME = 0, the refresh controller operates as an interval timer. After setting RTCOR, select an input clock in RTMCSR and set the CMIE bit to 1. CMI interrupts will be requested at compare match intervals determined by RTCOR and bits CKS2 to CKS0 in RTMCSR.

When setting RTCOR, RTMCSR, and RFSHCR, make sure that PSRAME = 0 and DRAME = 0. Writing is disabled when either of these bits is set to 1.

7.3.2 DRAM Refresh Control

Refresh Request Interval and Refresh Cycle Execution: The refresh request interval is determined by the settings of RTCOR and bits CKS2 to CKS0 in RTMCSR. Figure 7.2 illustrates the refresh request interval.

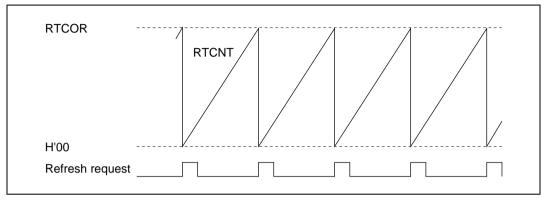


Figure 7.2 Refresh Request Interval (RCYCE = 1)

Refresh requests are generated at regular intervals as shown in figure 7.2, but the refresh cycle is not actually executed until the refresh controller gets the bus right.

Table 7.4 summarizes the relationship among area 3 settings, DRAM read/write cycles, and refresh cycles.

Area 3 Settings	Read/Write Cycle by CPU or DMAC	Refresh Cycle		
2-state-access area	3 states	3 states		
(AST3 = 0)	Wait states cannot be inserted	Wait states cannot be inserted		
3-state-access area	3 states	3 states		
(AST3 = 1)	Wait states can be inserted	Wait states can be inserted		

Table 7.4	Area 3 Settings, DRAM Access Cycles, and Refresh Cycles
-----------	---

To insert refresh cycles, set the RCYCE bit to 1 in RFSHCR. Figure 7.3 shows the state transitions for execution of refresh cycles.

When the first refresh request occurs after exit from the reset state or standby mode, the refresh controller does not execute a refresh cycle, but goes into the refresh request pending state. Note this point when using a DRAM that requires a refresh cycle for initialization.

When a refresh request occurs in the refresh request pending state, the refresh controller acquires the bus right, then executes a refresh cycle. If another refresh request occurs during execution of the refresh cycle, it is ignored.

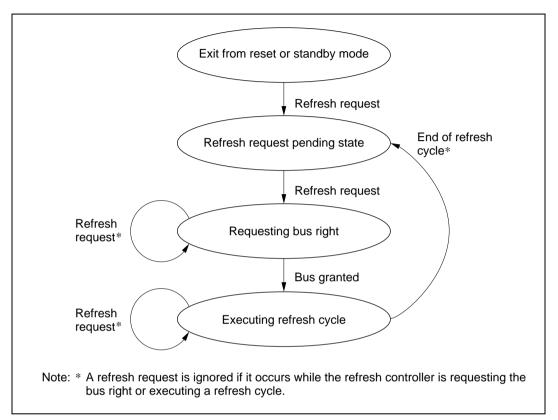


Figure 7.3 State Transitions for Refresh Cycle Execution

Address Multiplexing: Address multiplexing depends on the setting of the M9/ $\overline{M8}$ bit in RFSHCR, as described in table 7.5. Figure 7.4 shows the address output timing. Address output is multiplexed only in area 3.

Table 7.5 Address Multiplexing

Address Pins Address signals during row address output		A ₂₃ to A ₁₀	A ₉	A ₈	A 7 A7	A 6	A 5 A5	A 4 A4	A 3 A3	A ₂ A ₂	A 1 A1	A ₀
		A ₂₃ to A ₁₀		A ₈								A ₀
Address signals during column	M9/ <u>M8</u> = 0	A ₂₃ to A ₁₀	A ₉	A ₉	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	A ₁₁	A ₁₀	A ₀
address output	M9/M8 = 1	A ₂₃ to A ₁₀	A ₁₈	A ₁₇	A ₁₆	A ₁₅	A ₁₄	A ₁₃	A ₁₂	A ₁₁	A ₁₀	A ₀

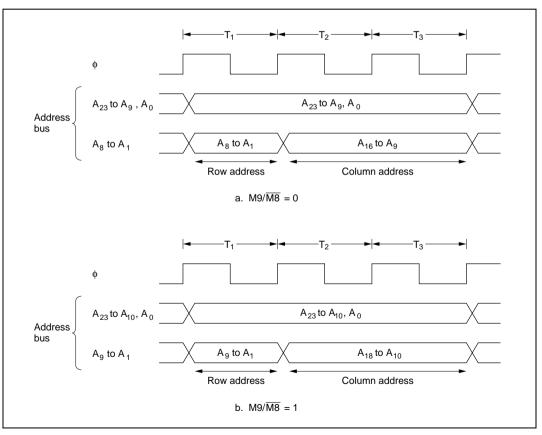


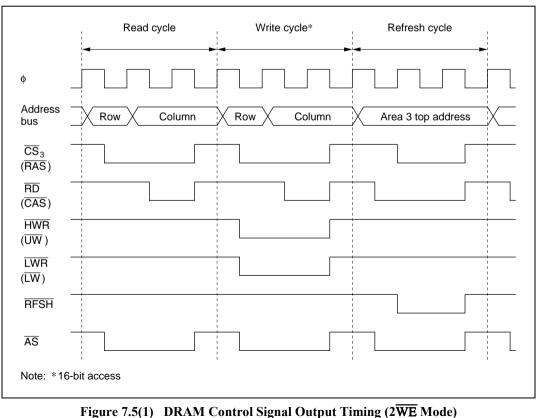
Figure 7.4 Multiplexed Address Output (Example without Wait States)

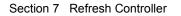
2CAS and **2WE Modes:** The CAS/WE bit in RFSHCR can select two control modes for 16-bitwide DRAM: one using UCAS and LCAS; the other using UW and LW. These DRAM pins correspond to H8/3048 Group pins as shown in table 7.6.

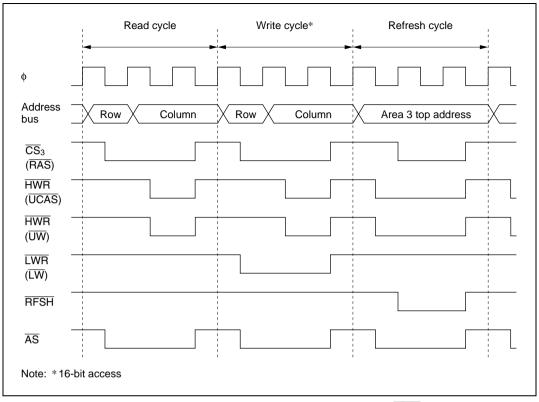
Table 7.6	DRAM Pins and H8/3048 Group Pins
-----------	----------------------------------

	DRAM Pin					
H8/3048 Group Pin	CAS/WE = 0 (2WE Mode)	CAS/WE = 1 (2CAS Mode)				
HWR	UW	UCAS				
LWR	LW	LCAS				
RD	CAS	WE				
\overline{CS}_3	RAS	RAS				

Figure 7.5 (1) shows the interface timing for $2\overline{WE}$ DRAM. Figure 7.5 (2) shows the interface timing for $2\overline{CAS}$ DRAM.









Refresh Cycle Priority Order: When there are simultaneous bus requests, the priority order is:

(High) External bus master > refresh controller > DMA controller > CPU (Low)

For details see section 6.3.7, Bus Arbiter Operation.

Wait State Insertion: When bit AST3 is set to 1 in ASTCR, bus controller settings can cause wait states to be inserted into bus cycles and refresh cycles. For details see section 6.3.5, Wait Modes.

Self-Refresh Mode: Some DRAM devices have a self-refresh function. After the SRFMD bit is set to 1 in RFSHCR, when a transition to software standby mode occurs, the \overline{CAS} and \overline{RAS} outputs go low in that order so that the DRAM self-refresh function can be used. On exit from software standby mode, the \overline{CAS} and \overline{RAS} outputs both go high.

Table 7.7 shows the pin states in software standby mode. Figure 7.6 shows the signal output timing.

	Software Standby Mode						
	SRI	FMD = 0	SRFMD = 1 (self-refresh mode)				
Signal	CAS/WE = 0	CAS/WE = 1	CAS/WE = 0	CAS/WE = 1			
HWR	High-impedance	High-impedance	High	Low			
LWR	High-impedance	High-impedance	High	Low			
RD	High-impedance	High-impedance	Low	High			
\overline{CS}_3	High	High	Low	Low			
RFSH	High	High	Low	Low			

Table 7.7	Pin States in Software Standby	Mode (1) (PSRAME = 0, DRAME = 1)

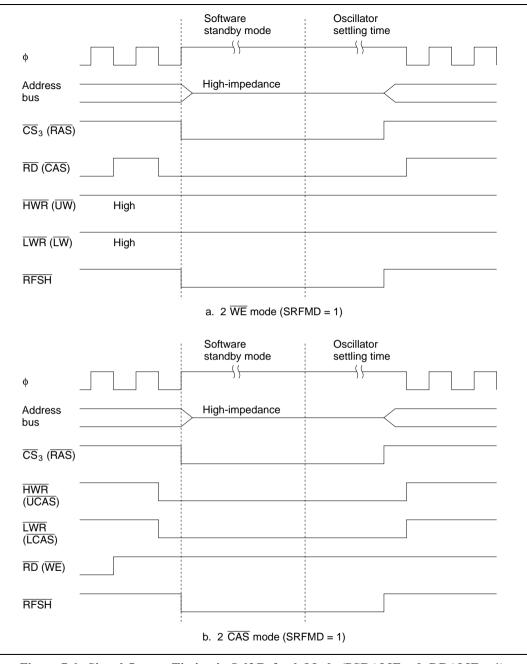


Figure 7.6 Signal Output Timing in Self-Refresh Mode (PSRAME = 0, DRAME = 1)

Operation in Power-Down State: The refresh controller operates in sleep mode. It does not operate in hardware standby mode. In software standby mode RTCNT is initialized, but RFSHCR, RTMCSR bits 5 to 3, and RTCOR retain their settings prior to the transition to software standby mode.

Example 1: Connection to 2\overline{WE} 1-Mbit DRAM (1-Mbyte Mode): Figure 7.7 shows typical interconnections to a $2\overline{WE}$ 1-Mbit DRAM, and the corresponding address map. Figure 7.8 shows a setup procedure to be followed by a program for this example. After power-up the DRAM must be refreshed to initialize its internal state. Initialization takes a certain length of time, which can be measured by using an interrupt from another timer module, or by counting the number of times RTMCSR bit 7 (CMF) is set. Note that no refresh cycle is executed for the first refresh request after exit from the reset state or standby mode (the first time the CMF flag is set; see figure 7.3). When using this example, check the DRAM device characteristics carefully and use a procedure that fits them.

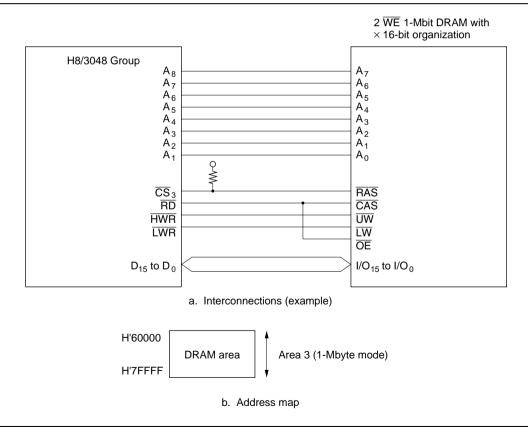


Figure 7.7 Interconnections and Address Map for 2WE 1-Mbit DRAM (Example)

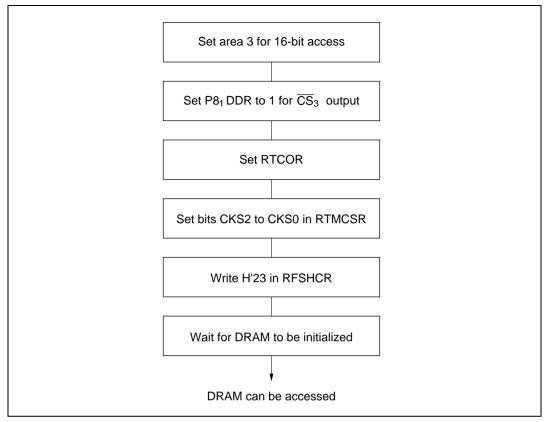
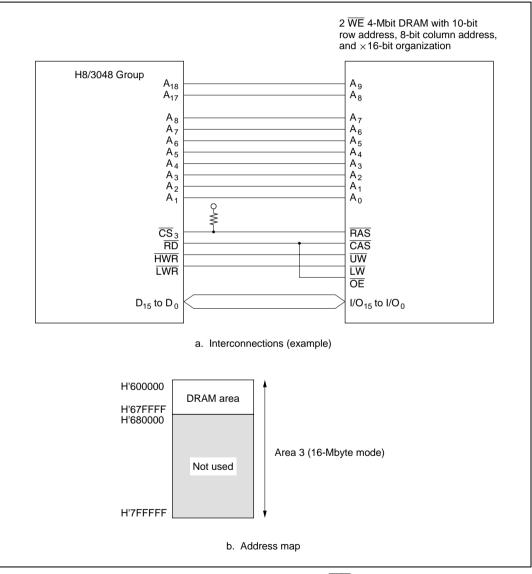


Figure 7.8 Setup Procedure for 2WE 1-Mbit DRAM (1-Mbyte Mode)



Example 2: Connection to 2 \overline{WE} **4-Mbit DRAM (16-Mbyte Mode):** Figure 7.9 shows typical interconnections to a single 2 \overline{WE} 4-Mbit DRAM, and the corresponding address map. Figure 7.10 shows a setup procedure to be followed by a program for this example.

The DRAM in this example has 10-bit row addresses and 8-bit column addresses. Its address area is H'600000 to H'67FFFF.





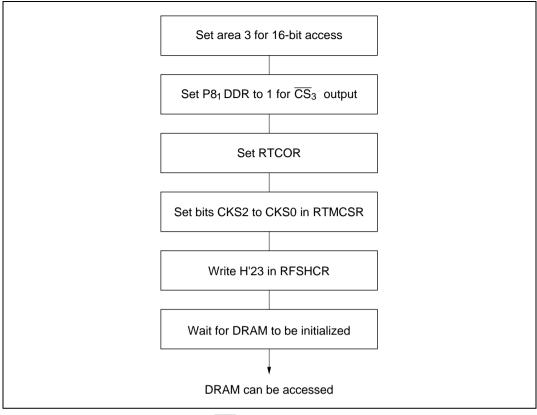


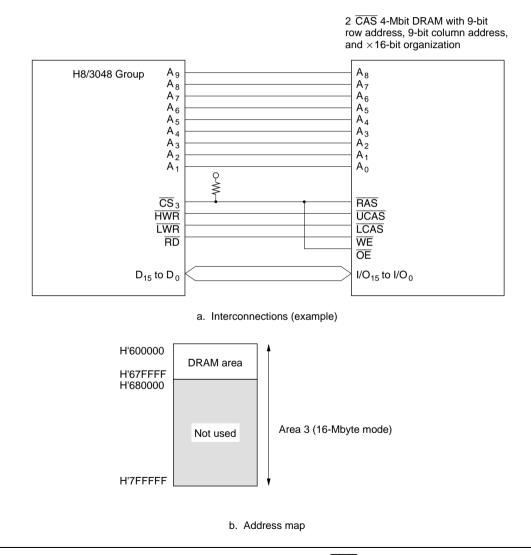
Figure 7.10 Setup Procedure for 2WE 4-Mbit DRAM with 10-Bit Row Address and 8-Bit Column Address (16-Mbyte Mode)

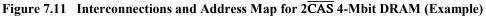


Example 3: Connection to 2\overline{CAS} 4-Mbit DRAM (16-Mbyte Mode): Figure 7.11 shows typical interconnections to a single $2\overline{CAS}$ 4-Mbit DRAM, and the corresponding address map.

Figure 7.12 shows a setup procedure to be followed by a program for this example.

The DRAM in this example has 9-bit row addresses and 9-bit column addresses. Its address area is H'600000 to H'67FFFF.





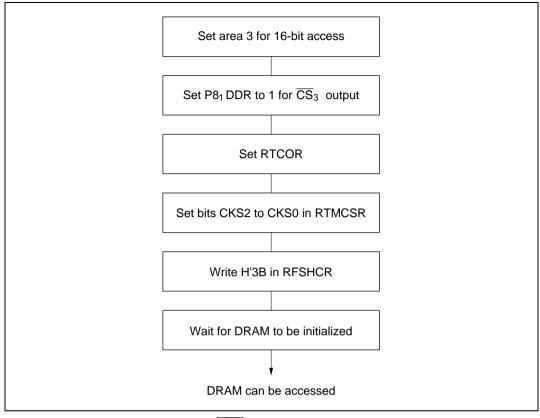
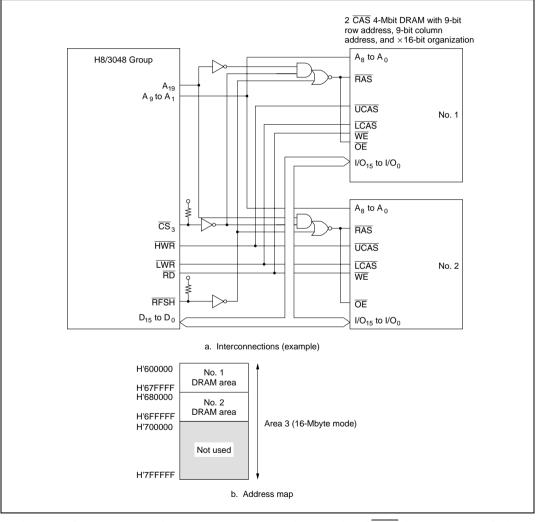


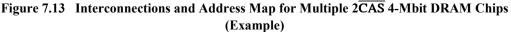
Figure 7.12 Setup Procedure for 2CAS 4-Mbit DRAM with 9-Bit Row Address and 9-Bit Column Address (16-Mbyte Mode)



Example 4: Connection to Multiple 4-Mbit DRAM Chips (16-Mbyte Mode): Figure 7.13 shows an example of interconnections to two $2\overline{CAS}$ 4-Mbit DRAM chips, and the corresponding address map. Up to four DRAM chips can be connected to area 3 by decoding upper address bits A₁₉ and A₂₀.

Figure 7.14 shows a setup procedure to be followed by a program for this example. The DRAM in this example has 9-bit row addresses and 9-bit column addresses. Both chips must be refreshed simultaneously, so the **RFSH** pin must be used.





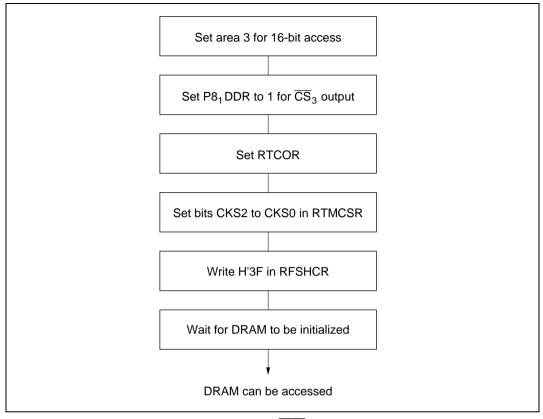


Figure 7.14 Setup Procedure for Multiple 2CAS 4-Mbit DRAM Chips with 9-Bit Row Address and 9-Bit Column Address (16-Mbyte Mode)



7.3.3 Pseudo-Static RAM Refresh Control

Refresh Request Interval and Refresh Cycle Execution: The refresh request interval is determined as in a DRAM interface, by the settings of RTCOR and bits CKS2 to CKS0 in RTMCSR. The numbers of states required for pseudo-static RAM read/write cycles and refresh cycles are the same as for DRAM (see table 7.4). The state transitions are as shown in figure 7.3.

Pseudo-Static RAM Control Signals: Figure 7.15 shows the control signals for pseudo-static RAM read, write, and refresh cycles.

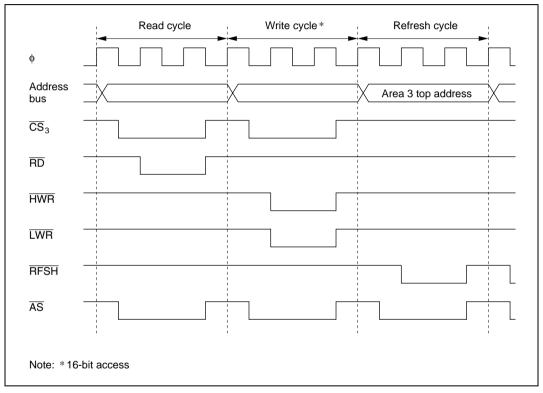


Figure 7.15 Pseudo-Static RAM Control Signal Output Timing

Refresh Cycle Priority Order: When there are simultaneous bus requests, the priority order is:

(High) External bus master > refresh controller > DMA controller > CPU (Low)

For details see section 6.3.7, Bus Arbiter Operation.

Wait State Insertion: When bit AST3 is set to 1 in ASTCR, the wait state controller (WSC) can insert wait states into bus cycles and refresh cycles. For details see section 6.3.5, Wait Modes.

Self-Refresh Mode: Some pseudo-static RAM devices have a self-refresh function. After the SRFMD bit is set to 1 in RFSHCR, when a transition to software standby mode occurs, the H8/3048 Group' \overline{CS}_3 output goes high and its \overline{RFSH} output goes low so that the pseudo-static RAM self-refresh function can be used. On exit from software standby mode, the \overline{RFSH} output goes high.

Table 7.8 shows the pin states in software standby mode. Figure 7.16 shows the signal output timing.

	Software Standby Mode				
Signal	SRFMD = 0	SRFMD = 1 (Self-Refresh Mode)			
\overline{CS}_3	High	High			
RD	High-impedance	High-impedance			
HWR	High-impedance	High-impedance			
LWR	High-impedance	High-impedance			
RFSH	High	Low			

Table 7.8Pin States in Software Standby Mode (2) (PSRAME = 1, DRAME = 0)



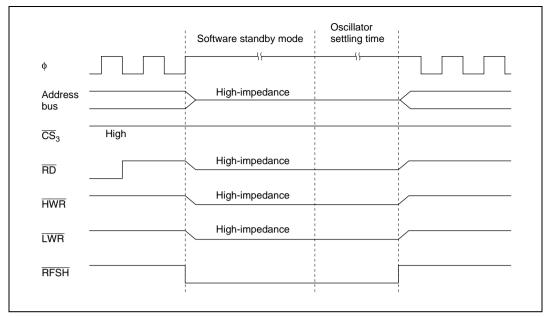


Figure 7.16 Signal Output Timing in Self-Refresh Mode (PSRAME = 1, DRAME = 0)

Operation in Power-Down State: The refresh controller operates in sleep mode. It does not operate in hardware standby mode. In software standby mode RTCNT is initialized, but RFSHCR, RTMCSR bits 5 to 3, and RTCOR retain their settings prior to the transition to software standby mode.

Example: Pseudo-static RAM may have separate \overline{OE} and \overline{RFSH} pins, or these may be combined into a single $\overline{OE}/\overline{RFSH}$ pin. Figure 7.17 shows an example of a circuit for generating an $\overline{OE}/\overline{RFSH}$ signal. Check the device characteristics carefully, and design a circuit that fits them. Figure 7.18 shows a setup procedure to be followed by a program.

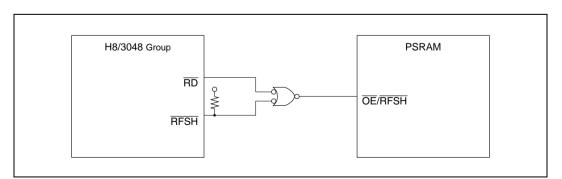


Figure 7.17 Interconnection to Pseudo-Static RAM with OE/RFSH Signal (Example)

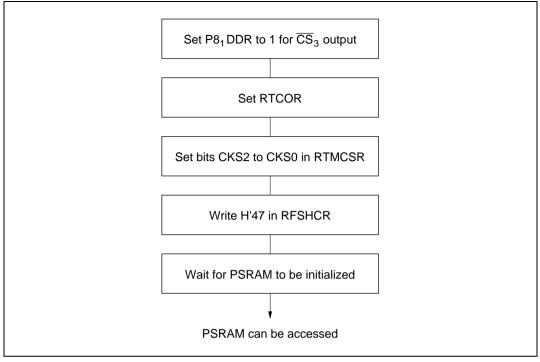


Figure 7.18 Setup Procedure for Pseudo-Static RAM



7.3.4 Interval Timer

To use the refresh controller as an interval timer, clear the PSRAME and DRAME both to 0. After setting RTCOR, select a clock source with bits CKS2 to CKS0 in RTMCSR, and set the CMIE bit to 1.

Timing of Setting of Compare Match Flag and Clearing by Compare Match: The CMF flag in RTCSR is set to 1 by a compare match signal output when the RTCOR and RTCNT values match. The compare match signal is generated in the last state in which the values match (when RTCNT is updated from the matching value to a new value). Accordingly, when RTCNT and RTCOR match, the compare match signal is not generated until the next counter clock pulse. Figure 7.19 shows the timing.

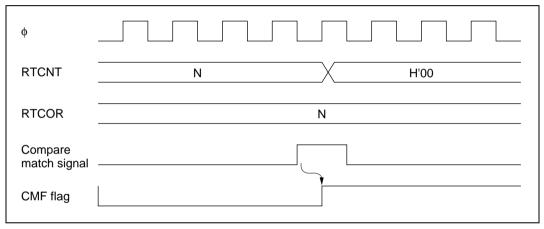


Figure 7.19 Timing of Setting of CMF Flag

Operation in Power-Down State: The interval timer function operates in sleep mode. It does not operate in hardware standby mode. In software standby mode RTCNT and RTMCSR bits 7 and 6 are initialized, but RTMCSR bits 5 to 3 and RTCOR retain their settings prior to the transition to software standby mode.

Contention between RTCNT Write and Counter Clear: If a counter clear signal occurs in the T_3 state of an RTCNT write cycle, clearing of the counter takes priority and the write is not performed. See figure 7.20.

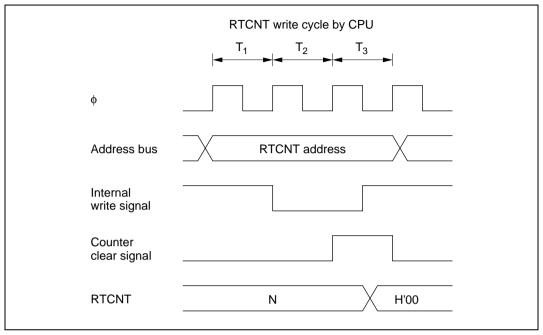
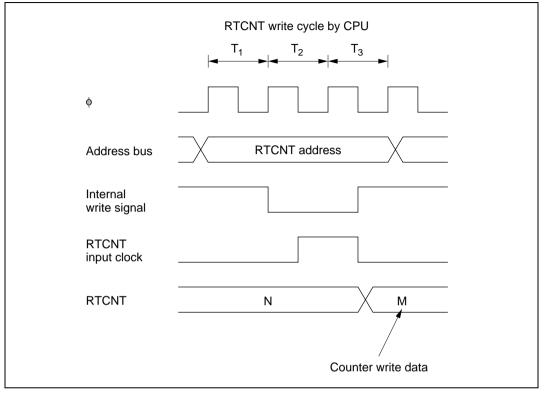


Figure 7.20 Contention between RTCNT Write and Clear





Contention between RTCNT Write and Increment: If an increment pulse occurs in the T₃ state of an RTCNT write cycle, writing takes priority and RTCNT is not incremented. See figure 7.21.

Figure 7.21 Contention between RTCNT Write and Increment

Contention between RTCOR Write and Compare Match: If a compare match occurs in the T_3 state of an RTCOR write cycle, writing takes priority and the compare match signal is inhibited. See figure 7.22.

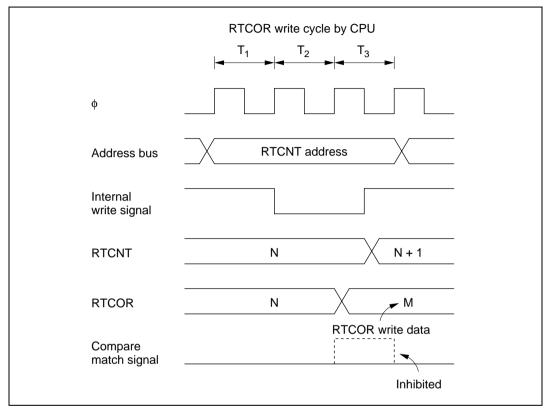


Figure 7.22 Contention between RTCOR Write and Compare Match

RTCNT Operation at Internal Clock Source Switchover: Switching internal clock sources may cause RTCNT to increment, depending on the switchover timing. Table 7.9 shows the relation between the time of the switchover (by writing to bits CKS2 to CKS0) and the operation of RTCNT.

The RTCNT input clock is generated from the internal clock source by detecting the falling edge of the internal clock. If a switchover is made from a high clock source to a low clock source, as in case No. 3 in table 7.9, the switchover will be regarded as a falling edge, an RTCNT clock pulse will be generated, and RTCNT will be incremented.

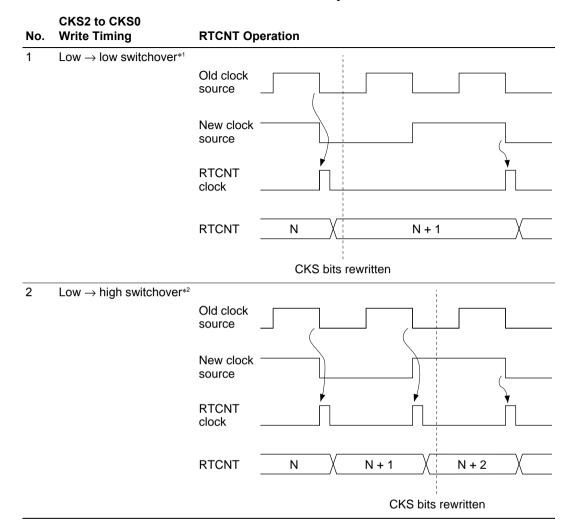
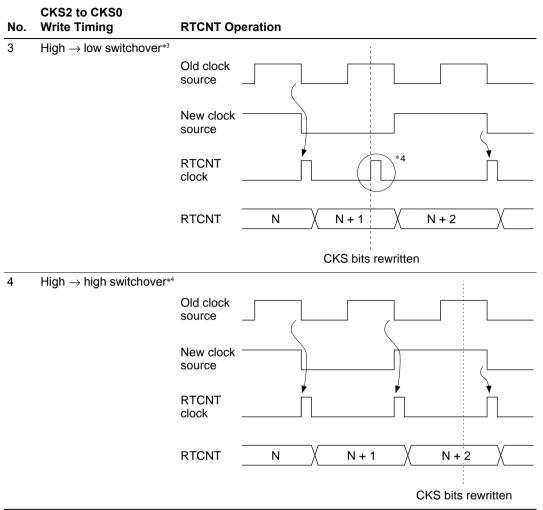


Table 7.9 Internal Clock Switchover and RTCNT Operation



- Notes: 1. Including switchovers from a low clock source to the halted state, and from the halted state to a low clock source.
 - 2. Including switchover from the halted state to a high clock source.
 - 3. Including switchover from a high clock source to the halted state.
 - 4. The switchover is regarded as a falling edge, causing RTCNT to increment.



7.4 Interrupt Source

Compare match interrupts (CMI) can be generated when the refresh controller is used as an interval timer. Compare match interrupt requests are masked/unmasked with the CMIE bit of RTMCSR.

7.5 Usage Notes

When using the DRAM or pseudo-static RAM refresh function, note the following points:

- With the refresh controller, if directly connected DRAM or PSRAM is disconnected*, the P8₀/RFSH/IRQ₀ pin and the P8₁/CS₃/IRQ₁ pin may both become low-level outputs simultaneously.
- Note: * When the DRAM enable bit (DRAME) or PSRAM enable bit (PSRAME) in the refresh control register (RFSHCR) is cleared to 0 after being set to 1.

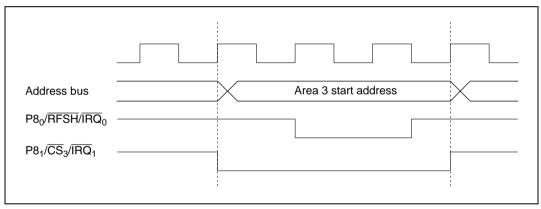


Figure 7.23 Operation when DRAM/PSRAM Connection is Switched

- Refresh cycles are not executed while the bus is released, during software standby mode, and when a bus cycle is greatly prolonged by insertion of wait states. When these conditions occur, other means of refreshing are required.
- If refresh requests occur while the bus is released, the first request is held and one refresh cycle is executed after the bus-released state ends. Figure 7.24 shows the bus cycles in this case.

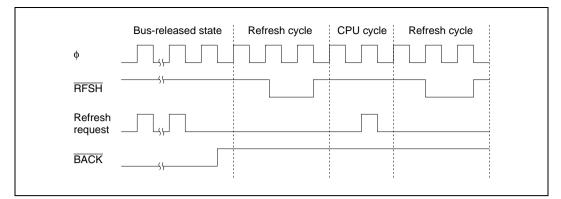


Figure 7.24 Refresh Cycles when Bus is Released

- If a bus cycle is prolonged by insertion of wait states, the first refresh request is held, as in the bus-released state.
- If there is contention with a bus request from an external bus master when making a transition to software standby mode, a one-state bus-released state may occur immediately before the transition to software standby mode (see figure 7.25).

When using software standby mode, clear the BRLE bit to 0 in BRCR before executing the SLEEP instruction.

When making a transition to self-refresh mode, the strobe waveform output may not be guaranteed due to the same kind of contention. This, too, can be prevented by clearing the BRLE bit to 0 in BRCR.

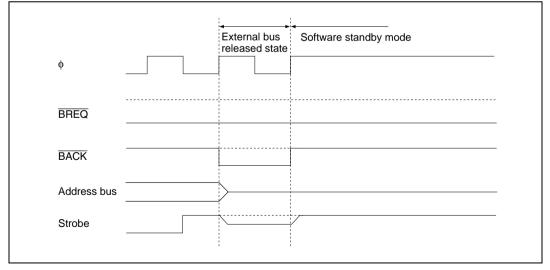


Figure 7.25 Contention between Bus-Released State and Software Standby Mode



Section 8 DMA Controller

8.1 Overview

The H8/3048 Group has an on-chip DMA controller (DMAC) that can transfer data on up to four channels.

When the DMA controller is not used, it can be independently halted to conserve power. For details see section 21.6, Module Standby Function.

8.1.1 Features

DMAC features are listed below.

- Selection of short address mode or full address mode Short address mode
 - 8-bit source address and 24-bit destination address, or vice versa
 - Maximum four channels available
 - Selection of I/O mode, idle mode, or repeat mode

Full address mode

- 24-bit source and destination addresses
- Maximum two channels available
- Selection of normal mode or block transfer mode
- Directly addressable 16-Mbyte address space
- Selection of byte or word transfer
- Activation by internal interrupts, external requests, or auto-request (depending on transfer mode)
 - 16-bit integrated timer unit (ITU) compare match/input capture interrupts (four)
 - Serial communication interface (SCI channel 0) transmit-data-empty/receive-data-full interrupts
 - External requests
 - Auto-request

8.1.2 Block Diagram

Figure 8.1 shows a DMAC block diagram.

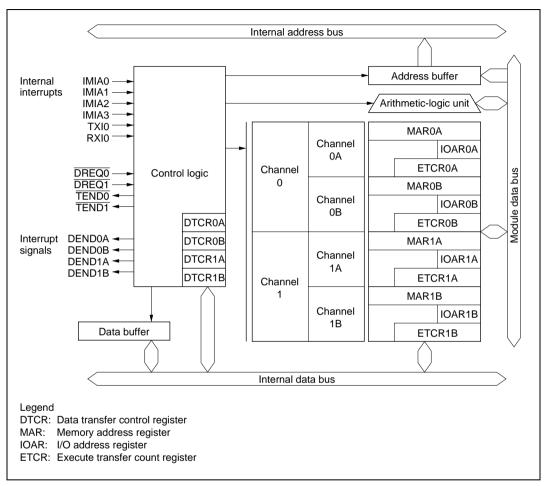


Figure 8.1 Block Diagram of DMAC



8.1.3 Functional Overview

Table 8.1 gives an overview of the DMAC functions.

Table 8.1DMAC Functional Overview

				ddress . Length
Transfer	Mode	Activation	Source	Destination
Short address mode	 I/O mode Transfers one byte or one word per request Increments or decrements the memory address by 1 or 2 Executes 1 to 65,536 transfers 	 Compare match/ input capture A interrupts from ITU channels 0 to 3 Transmit-data-empty interrupt from SCI channel 0 	24	8
	Idle modeTransfers one byte or one word per request	Receive-data-full interrupt from SCI channel 0	8	24
	Holds the memory address fixedExecutes 1 to 65,536 transfers	External request	24	8
	Repeat mode			
	Transfers one byte or one word per request			
	 Increments or decrements the memory address by 1 or 2 			
	• Executes a specified number (1 to 255) of transfers, then returns to the initial state and continues			

				ddress J. Length
Transfer Mode		Activation	Source	Destination
Transfer Full address mode	 Normal mode Auto-request Retains the transfer request internally Executes a specified number (1 to 65,536) of transfers continuously Selection of burst mode or cycle-steal mode External request Transfers one byte or one word per request Executes 1 to 65,536 transfers 	Auto-requestExternal request	24	24
	 Block transfer Transfers one block of a specified size per request Executes 1 to 65,536 transfers Allows either the source or destination to be a fixed block area Block size can be 1 to 255 bytes or words 	 Compare match/ input capture A interrupts from ITU channels 0 to 3 External request 	24	24



8.1.4 Input/Output Pins

Table 8.2 lists the DMAC pins.

Table 8.2 DMAC Pins

Channel	Name	Abbre- viation	Input/ Output	Function
0	DMA request 0	DREQ ₀	Input	External request for DMAC channel 0
	Transfer end 0	TEND ₀	Output	Transfer end on DMAC channel 0
1	DMA request 1	DREQ ₁	Input	External request for DMAC channel 1
	Transfer end 1	TEND ₁	Output	Transfer end on DMAC channel 1

Note: External requests cannot be made to channel A in short address mode.

8.1.5 Register Configuration

Table 8.3 lists the DMAC registers.

Table 8.3DMAC Registers

Channel	Address*	Name	Abbreviation	R/W	Initial Value	
0	H'FF20	Memory address register 0AR	MAR0AR	R/W	Undetermined	
	H'FF21	Memory address register 0AE	MAR0AE	R/W	Undetermined	
	H'FF22	Memory address register 0AH	MAR0AH	R/W	Undetermined	
	H'FF23	Memory address register 0AL	MAR0AL	R/W	Undetermined	
	H'FF26	I/O address register 0A	IOAR0A	R/W	Undetermined	
	H'FF24	Execute transfer count register 0AH	ETCR0AH	R/W	Undetermined	
	H'FF25	Execute transfer count register 0AL	ETCR0AL	R/W	Undetermined	
	H'FF27	Data transfer control register 0A	DTCR0A	R/W	H'00	
	H'FF28	Memory address register 0BR	MAR0BR	R/W	Undetermined	
	H'FF29	Memory address register 0BE	MAR0BE	R/W	Undetermined	
	H'FF2A	Memory address register 0BH	MAR0BH	R/W	Undetermined	
	H'FF2B	Memory address register 0BL	MAR0BL	R/W	Undetermined	
	H'FF2E	I/O address register 0B	IOAR0B	R/W	Undetermined	
	H'FF2C	Execute transfer count register 0BH	ETCR0BH	R/W	Undetermined	
	H'FF2D	Execute transfer count register 0BL	ETCR0BL	R/W	Undetermined	
	H'FF2F	Data transfer control register 0B	DTCR0B	R/W	H'00	
1	H'FF30	Memory address register 1AR	MAR1AR	R/W	Undetermined	
	H'FF31	Memory address register 1AE	MAR1AE	R/W	Undetermined	
	H'FF32	Memory address register 1AH	MAR1AH	R/W	Undetermined	
	H'FF33	Memory address register 1AL	MAR1AL	R/W	Undetermined	
	H'FF36	I/O address register 1A	IOAR1A	R/W	Undetermined	
	H'FF34	Execute transfer count register 1AH	ETCR1AH	R/W	Undetermined	
	H'FF35	Execute transfer count register 1AL	ETCR1AL	R/W	Undetermined	
	H'FF37	Data transfer control register 1A	DTCR1A	R/W	H'00	
	H'FF38	Memory address register 1BR	MAR1BR	R/W	Undetermined	
	H'FF39	Memory address register 1BE	MAR1BE	R/W	Undetermined	
	H'FF3A	Memory address register 1BH	MAR1BH	R/W	Undetermined	
	H'FF3B	Memory address register 1BL	MAR1BL	R/W	Undetermined	
	H'FF3E	I/O address register 1B	IOAR1B	R/W	Undetermined	
	H'FF3C	Execute transfer count register 1BH	ETCR1BH	R/W	Undetermined	
	H'FF3D	Execute transfer count register 1BL		R/W	Undetermined	
	H'FF3F	Data transfer control register 1B	DTCR1B	R/W	H'00	
Note: * Th	ote: * The lower 16 bits of the address are indicated					

Note: * The lower 16 bits of the address are indicated.

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8.2 Register Descriptions (Short Address Mode)

In short address mode, transfers can be carried out independently on channels A and B. Short address mode is selected by bits DTS2A and DTS1A in data transfer control register A (DTCRA) as indicated in table 8.4.

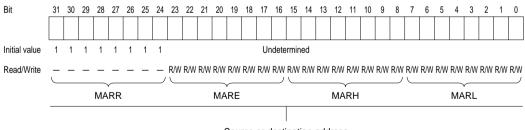
Channel	Bit 2: DTS2A	Bit 1: DTS1A	Description
0	1	1	DMAC channel 0 operates as one channel in full address mode
	Other than	above	DMAC channels 0A and 0B operate as two independent channels in short address mode
1	1	1	DMAC channel 1 operates as one channel in full address mode
	Other than	above	DMAC channels 1A and 1B operate as two independent channels in short address mode

Table 8.4 Selection of Short and Full Address Modes

8.2.1 Memory Address Registers (MAR)

A memory address register (MAR) is a 32-bit readable/writable register that specifies a source or destination address. The transfer direction is determined automatically from the activation source.

An MAR consists of four 8-bit registers designated MARR, MARE, MARH, and MARL. All bits of MARR are reserved: they cannot be modified and are always read as 1.



Source or destination address

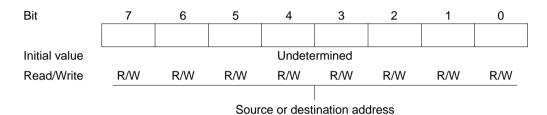
An MAR functions as a source or destination address register depending on how the DMAC is activated: as a destination address register if activation is by a receive-data-full interrupt from the serial communication interface (SCI) (channel 0), and as a source address register otherwise.

The MAR value is incremented or decremented each time one byte or word is transferred, automatically updating the source or destination memory address. For details, see section 8.2.4, Data Transfer Control Registers (DTCR).

The MARs are not initialized by a reset or in standby mode.

8.2.2 I/O Address Registers (IOAR)

An I/O address register (IOAR) is an 8-bit readable/writable register that specifies a source or destination address. The IOAR value is the lower 8 bits of the address. The upper 16 address bits are all 1 (H'FFFF).



An IOAR functions as a source or destination address register depending on how the DMAC is activated: as a source address register if activation is by a receive-data-full interrupt from the SCI (channel 0), and as a destination address register otherwise.

The IOAR value is held fixed. It is not incremented or decremented when a transfer is executed.

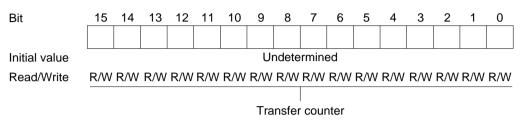
The IOARs are not initialized by a reset or in standby mode.



8.2.3 Execute Transfer Count Registers (ETCR)

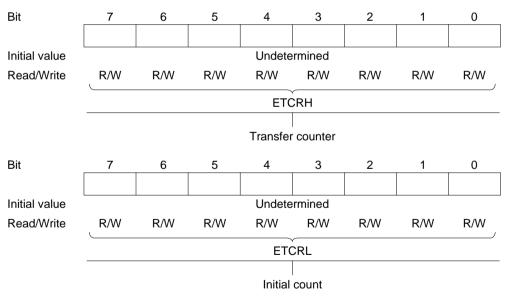
An execute transfer count register (ETCR) is a 16-bit readable/writable register that specifies the number of transfers to be executed. These registers function in one way in I/O mode and idle mode, and another way in repeat mode.

• I/O mode and idle mode



In I/O mode and idle mode, ETCR functions as a 16-bit counter. The count is decremented by 1 each time one transfer is executed. The transfer ends when the count reaches H'0000.

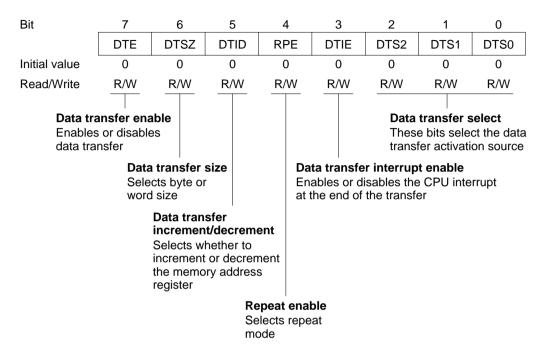
Repeat mode



In repeat mode, ETCRH functions as an 8-bit transfer counter and ETCRL holds the initial transfer count. ETCRH is decremented by 1 each time one transfer is executed. When ETCRH reaches H'00, the value in ETCRL is reloaded into ETCRH and the same operation is repeated. The ETCRs are not initialized by a reset or in standby mode.

8.2.4 Data Transfer Control Registers (DTCR)

A data transfer control register (DTCR) is an 8-bit readable/writable register that controls the operation of one DMAC channel.



The DTCRs are initialized to H'00 by a reset and in standby mode.

Bit 7—Data Transfer Enable (DTE): Enables or disables data transfer on a channel. When the DTE bit is set to 1, the channel waits for a transfer to be requested, and executes the transfer when activated as specified by bits DTS2 to DTS0. When DTE is 0, the channel is disabled and does not accept transfer requests. DTE is set to 1 by reading the register when DTE is 0, then writing 1.

Bit 7: DTE	Description	
0	Data transfer is disabled. In I/O mode or idle mode, DTE is cleared to 0 wh the specified number of transfers have been completed. (Initial va	
1	Data transfer is enabled	

If DTIE is set to 1, a CPU interrupt is requested when DTE is cleared to 0.

Bit 6—Data Transfer Size (DTSZ): Selects the data size of each transfer.

Bit 6: DTSZ	Description	
0	Byte-size transfer	(Initial value)
1	Word-size transfer	

Bit 5—Data Transfer Increment/Decrement (DTID): Selects whether to increment or decrement the memory address register (MAR) after a data transfer in I/O mode or repeat mode.

Bit 5: DTID	Description
0	MAR is incremented after each data transfer
	 If DTSZ = 0, MAR is incremented by 1 after each transfer
	• If DTSZ = 1, MAR is incremented by 2 after each transfer
1	MAR is decremented after each data transfer
	 If DTSZ = 0, MAR is decremented by 1 after each transfer
	• If DTSZ = 1, MAR is decremented by 2 after each transfer

MAR is not incremented or decremented in idle mode.

Bit 4—Repeat Enable (RPE): Selects whether to transfer data in I/O mode, idle mode, or repeat mode.

Bit 4: RPE	Bit 3: DTIE	Description	
0	0	I/O mode	(Initial value)
	1		
1	0	Repeat mode	
	1	Idle mode	

Operations in these modes are described in sections 8.4.2, I/O Mode, 8.4.3, Idle Mode, and 8.4.4, Repeat Mode.

Bit 3—Data Transfer Interrupt Enable (DTIE): Enables or disables the CPU interrupt (DEND) requested when the DTE bit is cleared to 0.

Bit 3: DTIE	Description	
0	The DEND interrupt requested by DTE is disabled	(Initial value)
1	The DEND interrupt requested by DTE is enabled	

Bits 2 to 0—Data Transfer Select (DTS2, DTS1, DTS0): These bits select the data transfer activation source. Some of the selectable sources differ between channels A and B.*

Note: * Refer to section 8.3.4, Data Transfer Control Registers (DTCR).

Bit 2: DTS2	Bit 1: DTS1	Bit 0: DTS0	Description
0	0	0	Compare match/input capture A interrupt from ITU channel 0 (Initial value)
		1	Compare match/input capture A interrupt from ITU channel 1
1 0		0	Compare match/input capture A interrupt from ITU channel 2
		1	Compare match/input capture A interrupt from ITU channel 3
1	0	0	Transmit-data-empty interrupt from SCI channel 0
		1	Receive-data-full interrupt from SCI channel 0
	1	0	Falling edge of DREQ input (channel B)
			Transfer in full address mode (channel A)
		1	Low level of DREQ input (channel B)
			Transfer in full address mode (channel A)

The same internal interrupt can be selected as an activation source for two or more channels at once. In that case the channels are activated in a priority order, highest-priority channel first. For the priority order, see section 8.4.9, DMAC Multiple-Channel Operation.

When a channel is enabled (DTE = 1), its selected DMAC activation source cannot generate a CPU interrupt.



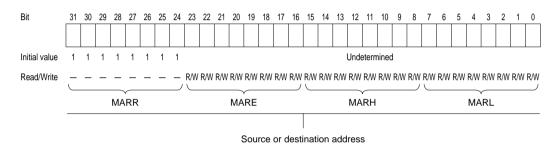
8.3 **Register Descriptions (Full Address Mode)**

In full address mode the A and B channels operate together. Full address mode is selected as indicated in table 8.4.

8.3.1 Memory Address Registers (MAR)

A memory address register (MAR) is a 32-bit readable/writable register. MARA functions as the source address register of the transfer, and MARB as the destination address register.

An MAR consists of four 8-bit registers designated MARR, MARE, MARH, and MARL. All bits of MARR are reserved: they cannot be modified and are always read as 1.



The MAR value is incremented or decremented each time one byte or word is transferred, automatically updating the source or destination memory address. For details, see section 8.3.4, Data Transfer Control Registers (DTCR).

The MARs are not initialized by a reset or in standby mode.

8.3.2 I/O Address Registers (IOAR)

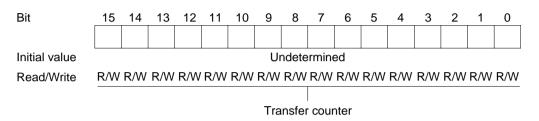
The I/O address registers (IOARs) are not used in full address mode.

8.3.3 Execute Transfer Count Registers (ETCR)

An execute transfer count register (ETCR) is a 16-bit readable/writable register that specifies the number of transfers to be executed. The functions of these registers differ between normal mode and block transfer mode.

• Normal mode

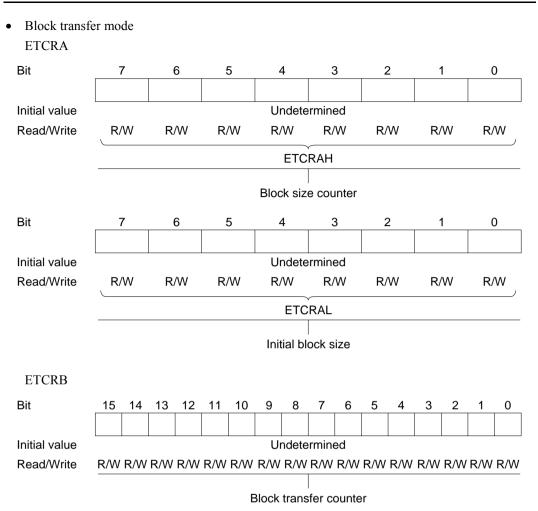




ETCRB: Is not used in normal mode.

In normal mode ETCRA functions as a 16-bit transfer counter. The count is decremented by 1 each time one transfer is executed. The transfer ends when the count reaches H'0000. ETCRB is not used.





In block transfer mode, ETCRAH functions as an 8-bit block size counter. ETCRAL holds the initial block size. ETCRAH is decremented by 1 each time one byte or word is transferred. When the count reaches H'00, ETCRAH is reloaded from ETCRAL. Blocks consisting of an arbitrary number of bytes or words can be transferred repeatedly by setting the same initial block size value in ETCRAH and ETCRAL.

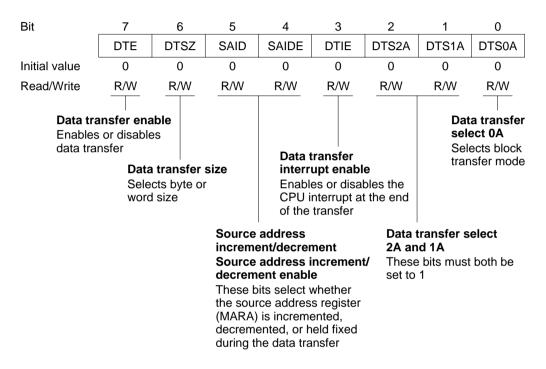
In block transfer mode ETCRB functions as a 16-bit block transfer counter. ETCRB is decremented by 1 each time one block is transferred. The transfer ends when the count reaches H'0000.

The ETCRs are not initialized by a reset or in standby mode.

8.3.4 Data Transfer Control Registers (DTCR)

The data transfer control registers (DTCRs) are 8-bit readable/writable registers that control the operation of the DMAC channels. A channel operates in full address mode when bits DTS2A and DTS1A are both set to 1 in DTCRA. DTCRA and DTCRB have different functions in full address mode.

DTCRA



DTCRA is initialized to H'00 by a reset and in standby mode.



Bit 7—Data Transfer Enable (DTE): Together with the DTME bit in DTCRB, this bit enables or disables data transfer on the channel. When the DTME and DTE bits are both set to 1, the channel is enabled. If auto-request is specified, data transfer begins immediately. Otherwise, the channel waits for transfers to be requested. When the specified number of transfers have been completed, the DTE bit is automatically cleared to 0. When DTE is 0, the channel is disabled and does not accept transfer requests. DTE is set to 1 by reading the register when DTE is 0, then writing 1.

Bit 7: DTE	Description
0	Data transfer is disabled (DTE is cleared to 0 when the specified number of transfers have been completed) (Initial value)
1	Data transfer is enabled

If DTIE is set to 1, a CPU interrupt is requested when DTE is cleared to 0.

Bit 6: DTSZ	Description	
0	Byte-size transfer	(Initial value)
1	Word-size transfer	

Bit 5—Source Address Increment/Decrement (SAID) and

Bit 4—Source Address Increment/Decrement Enable (SAIDE): These bits select whether the source address register (MARA) is incremented, decremented, or held fixed during the data transfer.

Bit 5: SAID	Bit 4: SAIDE	Description		
0	0	MARA is held fixed	(Initial value)	
	1	MARA is incremented after each data	transfer	
		• If DTSZ = 0, MARA is incremented	by 1 after each transfer	
		• If DTSZ = 1, MARA is incremented	by 2 after each transfer	
1	0	MARA is held fixed		
1 MARA is decremented after each data tr		transfer		
		 If DTSZ = 0, MARA is decremented transfer 	d by 1 after each	
		 If DTSZ = 1, MARA is decremented transfer 	d by 2 after each	

Bit 3—Data Transfer Interrupt Enable (DTIE): Enables or disables the CPU interrupt (DEND) requested when the DTE bit is cleared to 0.

Bit 3: DTIE	Description	
0	The DEND interrupt requested by DTE is disabled	(Initial value)
1	The DEND interrupt requested by DTE is enabled	

Bits 2 and 1—Data Transfer Select 2A and 1A (DTS2A, DTS1A): A channel operates in full address mode when DTS2A and DTS1A are both set to 1.

Bit 0—Data Transfer Select 0A (DTS0A): Selects normal mode or block transfer mode.

Bit 0: DTS0A	Description	
0	Normal mode	(Initial value)
1	Block transfer mode	

Operations in these modes are described in sections 8.4.5, Normal Mode, and 8.4.6, Block Transfer Mode.



DTCRB

Bit	7	6	5	4	3	2	1	0
	DTME	—	DAID	DAIDE	TMS	DTS2B	DTS1B	DTS0B
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Data transfer Enables or dist transfer, togeth the DTE bit, ar to 0 by an inter	R/W R/W R/W master enable sables data her with nd is cleared errupt Reserved bit Destination increment/ Destination increment/ Destination increment/ These bits s the destination increment/		Select block a or des transfe n address /decremen select whe tion addre	nt ent enable ether ss cremented fixed	Data block Data 2B to Thes trans	e bits sele	select ct the data ion source	

DTCRB is initialized to H'00 by a reset and in standby mode.

Bit 7—Data Transfer Master Enable (DTME): Together with the DTE bit in DTCRA, this bit enables or disables data transfer. When the DTME and DTE bits are both set to 1, the channel is enabled. When an NMI interrupt occurs DTME is cleared to 0, suspending the transfer so that the CPU can use the bus. The suspended transfer resumes when DTME is set to 1 again. For further information on operation in block transfer mode, see section 8.6.6, NMI Interrupts and Block Transfer Mode.

DTME is set to 1 by reading the register while DTME = 0, then writing 1.

Bit 7: DTME	Description
0	Data transfer is disabled (DTME is cleared to 0 when an NMI interrupt occurs) (Initial value)
1	Data transfer is enabled

Bit 6—Reserved: Although reserved, this bit can be written and read.

Bit 5—Destination Address Increment/Decrement (DAID) and

Bit 4—Destination Address Increment/Decrement Enable (DAIDE): These bits select whether the destination address register (MARB) is incremented, decremented, or held fixed during the data transfer.

Bit 5: DAID	Bit 4: DAIDE	Description
0	0	MARB is held fixed (Initial value)
	1	MARB is incremented after each data transfer
		 If DTSZ = 0, MARB is incremented by 1 after each data transfer
		 If DTSZ = 1, MARB is incremented by 2 after each data transfe
1	0	MARB is held fixed
	1	MARB is decremented after each data transfer
		 If DTSZ = 0, MARB is decremented by 1 after each data transfer
		 If DTSZ = 1, MARB is decremented by 2 after each data transfer

Bit 3—Transfer Mode Select (TMS): Selects whether the source or destination is the block area in block transfer mode.

Bit 3: TMS	Description	
0	Destination is the block area in block transfer mode	(Initial value)
1	Source is the block area in block transfer mode	



Bits 2 to 0—Data Transfer Select 2B to 0B (DTS2B, DTS1B, DTS0B): These bits select the data transfer activation source. The selectable activation sources differ between normal mode and block transfer mode.

• Normal mode

Bit 2: DTS2B	Bit 1: DTS1B	Bit 0: DTS0B	Description	
0	0	0	Auto-request (burst mode)	(Initial value)
		1	Cannot be used	
	1	0	Auto-request (cycle-steal mode)	
		1	Cannot be used	
1 0 Cannot be used 1 Cannot be used 1 Cannot be used 1 0				
		1	Cannot be used	
		0	Falling edge of DREQ	
		1	Low level input at DREQ	

• Block transfer mode

Bit 2: DTS2B	Bit 1: DTS1B	Bit 0: DTS0B	Description
0	0	0	Compare match/input capture A interrupt from ITU channel 0 (Initial value)
channel 1		Compare match/input capture A interrupt from ITU channel 1	
		0	Compare match/input capture A interrupt from ITU channel 2
		1	Compare match/input capture A interrupt from ITU channel 3
1	0	0	Cannot be used
		1	Cannot be used
	1	0	Falling edge of DREQ
		1	Cannot be used

The same internal interrupt can be selected to activate two or more channels. The channels are activated in a priority order, highest priority first. For the priority order, see section 8.4.9, DMAC Multiple-Channel Operation.

8.4 **Operation**

8.4.1 Overview

Table 8.5 summarizes the DMAC modes.

Table 8.5 DMAC Modes

Transfer Mode		Activation	Notes
Short address mode	I/O mode Idle mode Repeat mode	Compare match/input capture A interrupt from ITU channels 0 to 3 Transmit-data-empty and	 Up to four channels can operate independently Only the B channels support external requests
		receive-data-full interrupts from SCI channel 0	
		External request	
Full address	Normal mode Block transfer mode	Auto-request	A and B channels are
mode		External request	paired; up to two channels
		Compare match/input capture A interrupt from ITU channels 0 to 3	 are available Burst mode or cycle-steal mode can be selected for
		External request	auto-requests

A summary of operations in these modes follows.

I/O Mode: One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. One 24-bit address and one 8-bit address are specified. The transfer direction is determined automatically from the activation source.

Idle Mode: One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. One 24-bit address and one 8-bit address are specified. The addresses are held fixed. The transfer direction is determined automatically from the activation source.

Repeat Mode: One byte or word is transferred per request. A designated number of these transfers are executed. When the designated number of transfers are completed, the initial address and counter value are restored and operation continues. No CPU interrupt is requested. One 24-bit address and one 8-bit address are specified. The transfer direction is determined automatically from the activation source.

Normal Mode

• Auto-request

The DMAC is activated by register setup alone, and continues executing transfers until the designated number of transfers have been completed. A CPU interrupt can be requested at completion of the transfers. Both addresses are 24-bit addresses.

- Cycle-steal mode

The bus is released to another bus master after each byte or word is transferred.

- Burst mode

Unless requested by a higher-priority bus master, the bus is not released until the designated number of transfers have been completed.

• External request

One byte or word is transferred per request. A designated number of these transfers are executed. A CPU interrupt can be requested at completion of the designated number of transfers. Both addresses are 24-bit addresses.

Block Transfer Mode: One block of a specified size is transferred per request. A designated number of block transfers are executed. At the end of each block transfer, one address is restored to its initial value. When the designated number of blocks have been transferred, a CPU interrupt can be requested. Both addresses are 24-bit addresses.

8.4.2 I/O Mode

I/O mode can be selected independently for each channel.

One byte or word is transferred at each transfer request in I/O mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 8.6 indicates the register functions in I/O mode.

	Function			
Register	Activated by SCI 0 Receive- Data-Full Interrupt	Other Activation	- Initial Setting	Operation
23 0 MAR	Destination address register	Source address register	Destination or source address	Incremented or decremented once per transfer
23 7 0 All 1s IOAR	Source address register	Destination address register	Source or destination address	Held fixed
15 0 ETCR	Transfer counter	Transfer counter	Number of transfers	Decremented once per transfer until H'0000 is reached and transfer ends

Table 8.6 Register Functions in I/O Mode

Legend

MAR: Memory address register

IOAR: I/O address register

ETCR: Execute transfer count register

MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address, which is incremented or decremented as each byte or word is transferred. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. IOAR is not incremented or decremented.

Figure 8.2 illustrates how I/O mode operates.

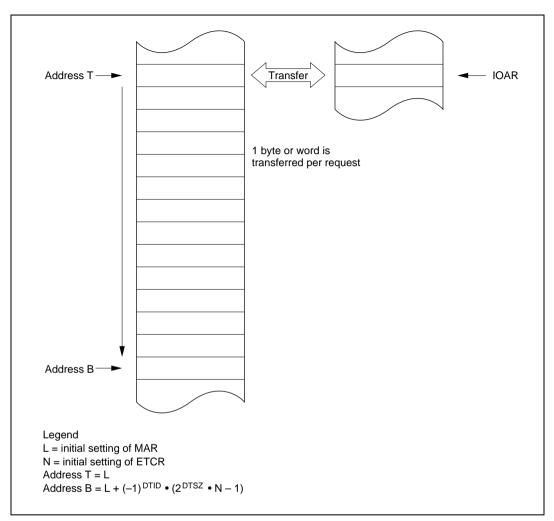


Figure 8.2 Operation in I/O Mode

The transfer count is specified as a 16-bit value in ETCR. The ETCR value is decremented by 1 at each transfer. When the ETCR value reaches H'0000, the DTE bit is cleared and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time. The maximum transfer count is 65,536, obtained by setting ETCR to H'0000.

Transfers can be requested (activated) by compare match/input capture A interrupts from ITU channels 0 to 3, transmit-data-empty and receive-data-full interrupts from SCI channel 0, and external request signals.

For the detailed settings see section 8.2.4, Data Transfer Control Registers (DTCR).

Figure 8.3 shows a sample setup procedure for I/O mode.

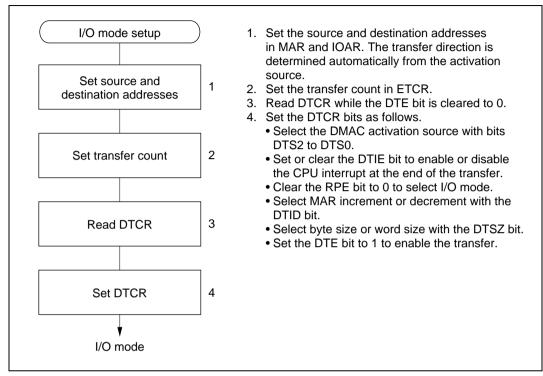


Figure 8.3 I/O Mode Setup Procedure (Example)

8.4.3 Idle Mode

Idle mode can be selected independently for each channel.

One byte or word is transferred at each transfer request in idle mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 8.7 indicates the register functions in idle mode.

	Function			
Register	Activated by SCI 0 Receive- Data-Full Interrupt	Other Activation	Initial Setting	Operation
23 0 MAR	Destination address register	Source address register	Destination or source address	Held fixed
23 7 0 All 1s IOAR	Source address register	Destination address register	Source or destination address	Held fixed
15 0 ETCR	Transfer counter	Transfer counter	Number of transfers	Decremented once per transfer until H'0000 is reached and transfer ends

Table 8.7 Register Functions in Idle Mode

Legend

MAR: Memory address register

IOAR: I/O address register

ETCR: Execute transfer count register

MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. MAR and IOAR are not incremented or decremented.

Figure 8.4 illustrates how idle mode operates.

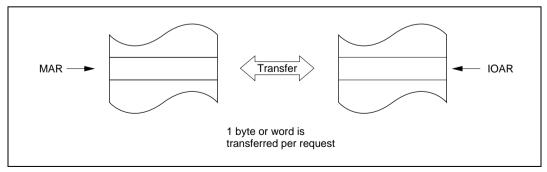


Figure 8.4 Operation in Idle Mode

The transfer count is specified as a 16-bit value in ETCR. The ETCR value is decremented by 1 at each transfer. When the ETCR value reaches H'0000, the DTE bit is cleared, the transfer ends, and a CPU interrupt is requested. The maximum transfer count is 65,536, obtained by setting ETCR to H'0000.

Transfers can be requested (activated) by compare match/input capture A interrupts from ITU channels 0 to 3, transmit-data-empty and receive-data-full interrupts from SCI channel 0, and external request signals.

For the detailed settings see section 8.2.4, Data Transfer Control Registers (DTCR).

Figure 8.5 shows a sample setup procedure for idle mode.

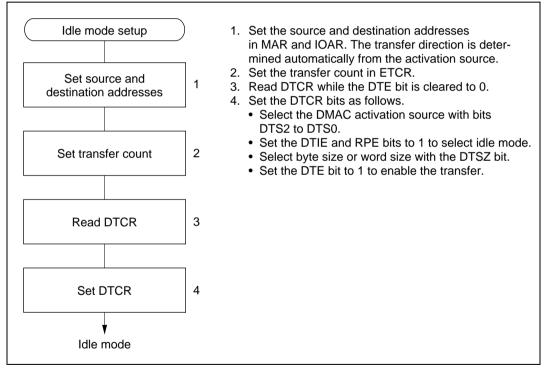


Figure 8.5 Idle Mode Setup Procedure (Example)

8.4.4 Repeat Mode

Repeat mode is useful for cyclically transferring a bit pattern from a table to the programmable timing pattern controller (TPC) in synchronization, for example, with ITU compare match. Repeat mode can be selected for each channel independently.

One byte or word is transferred per request in repeat mode, as in I/O mode. A designated number of these transfers are executed. One address is specified in the memory address register (MAR), the other in the I/O address register (IOAR). At the end of the designated number of transfers, MAR and ETCR are restored to their original values and operation continues. The direction of transfer is determined automatically from the activation source. The transfer is from the address specified in IOAR to the address specified in MAR if activated by an SCI channel 0 receive-data-full interrupt, and from the address specified in MAR to the address specified in IOAR otherwise.

Table 8.8 indicates the register functions in repeat mode.

	Function			
Register	Activated by SCI 0 Receive- Data-Full Interrupt	Other Activation	Initial Setting	Operation
23 0 MAR	Destination address register	Source address register	Destination or source address	Incremented or decremented at each transfer until H'0000, then restored to initial value
23 7 0 All 1s IOAR	Source address register	Destination address register	Source or destination address	Held fixed
7 0 ETCRH	Transfer counter	Transfer counter	Number of transfers	Decremented once per transfer until H'0000 is reached, then reloaded from ETCRL
7 0 ETCRL	Initial transfer count	Initial transfer count	Number of transfers	Held fixed

Legend

MAR: Memory address register

IOAR: I/O address register

ETCR: Execute transfer count register

In repeat mode ETCRH is used as the transfer counter while ETCRL holds the initial transfer count. ETCRH is decremented by 1 at each transfer until it reaches H'00, then is reloaded from ETCRL. MAR is also restored to its initial value, which is calculated from the DTSZ and DTID bits in DTCR. Specifically, MAR is restored as follows:

 $MAR \leftarrow MAR - (-1)^{DTID} \cdot 2^{DTSZ} \cdot ETCRL$

ETCRH and ETCRL should be initially set to the same value.

In repeat mode transfers continue until the CPU clears the DTE bit to 0. After DTE is cleared to 0, if the CPU sets DTE to 1 again, transfers resume from the state at which DTE was cleared. No CPU interrupt is requested.

As in I/O mode, MAR and IOAR specify the source and destination addresses. MAR specifies a 24-bit source or destination address. IOAR specifies the lower 8 bits of a fixed address. The upper 16 bits are all 1s. IOAR is not incremented or decremented.

Figure 8.6 illustrates how repeat mode operates.

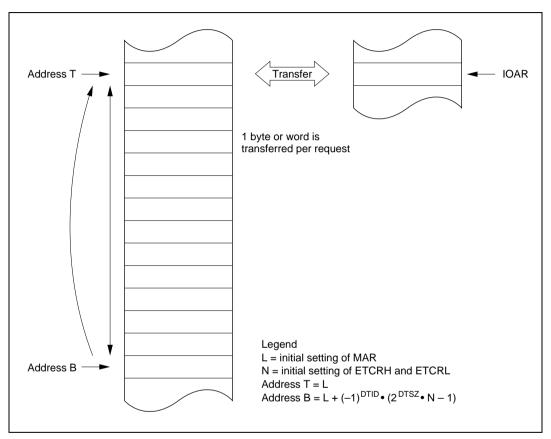


Figure 8.6 Operation in Repeat Mode

The transfer count is specified as an 8-bit value in ETCRH and ETCRL. The maximum transfer count is 255, obtained by setting both ETCRH and ETCRL to H'FF.

Transfers can be requested (activated) by compare match/input capture A interrupts from ITU channels 0 to 3, transmit-data-empty and receive-data-full interrupts from SCI channel 0, and external request signals.

For the detailed settings see section 8.2.4, Data Transfer Control Registers (DTCR).

Figure 8.7 shows a sample setup procedure for repeat mode.

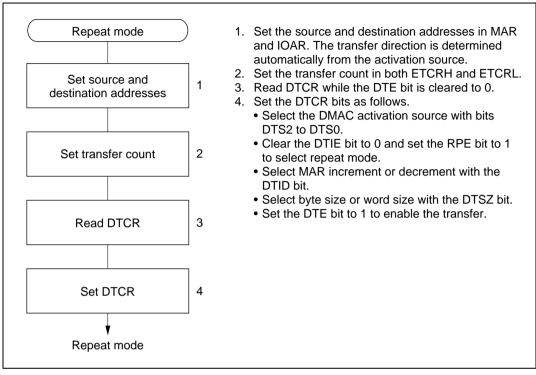


Figure 8.7 Repeat Mode Setup Procedure (Example)



8.4.5 Normal Mode

In normal mode the A and B channels are combined. One byte or word is transferred per request. A designated number of these transfers are executed. Addresses are specified in MARA and MARB. Table 8.9 indicates the register functions in I/O mode.

Register		Function	Initial Setting	Operation
23 MARA	0	Source address register	Source address	Incremented or decremented once per transfer, or held fixed
23 MARB	0	Destination address register	Destination address	Incremented or decremented once per transfer, or held fixed
15 ETCRA	0	Transfer counter	Number of transfers	Decremented once per transfer

Table 8.9 Register Functions in Normal Mode

Legend

MARA: Memory address register A

MARB: Memory address register B

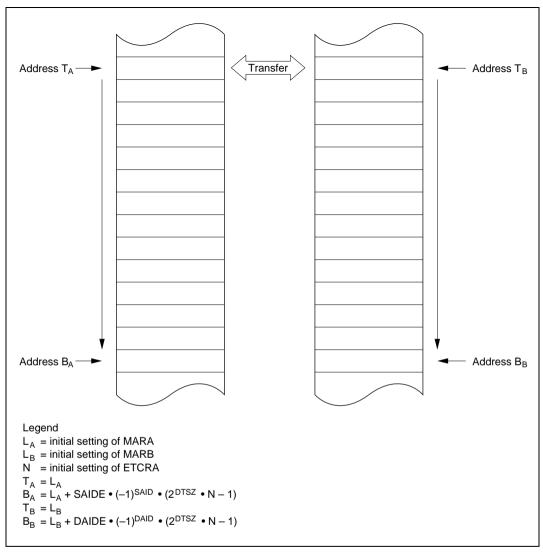
ETCRA: Execute transfer count register A

The source and destination addresses are both 24-bit addresses. MARA specifies the source address. MARB specifies the destination address. MARA and MARB can be independently incremented, decremented, or held fixed as data is transferred.

The transfer count is specified as a 16-bit value in ETCRA. The ETCRA value is decremented by 1 at each transfer. When the ETCRA value reaches H'0000, the DTE bit is cleared and the transfer ends. If the DTIE bit is set, a CPU interrupt is requested at this time. The maximum transfer count is 65,536, obtained by setting ETCRA to H'0000.

Figure 8.8 illustrates how normal mode operates.







Transfers can be requested (activated) by an external request or auto-request. An auto-requested transfer is activated by the register settings alone. The designated number of transfers are executed automatically. Either cycle-steal or burst mode can be selected. In cycle-steal mode the DMAC releases the bus temporarily after each transfer. In burst mode the DMAC keeps the bus until the transfers are completed, unless there is a bus request from a higher-priority bus master.

For the detailed settings see section 8.3.4, Data Transfer Control Registers (DTCR).

Figure 8.9 shows a sample setup procedure for normal mode.

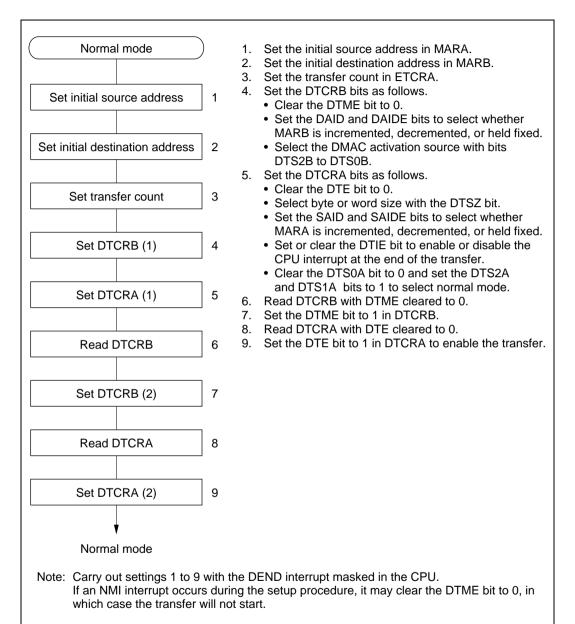


Figure 8.9 Normal Mode Setup Procedure (Example)

8.4.6 Block Transfer Mode

In block transfer mode the A and B channels are combined. One block of a specified size is transferred per request. A designated number of block transfers are executed. Addresses are specified in MARA and MARB. The block area address can be either held fixed or cycled.

Table 8.10 indicates the register functions in block transfer mode.

Table 8.10	Register Functions in Block Transfer Mode
-------------------	--

Register	Function	Initial Setting	Operation
23 0 MARA	Source address register	Source address	Incremented or decremented once per transfer, or held fixed
23 0 MARB	Destination address register	Destination address	Incremented or decremented once per transfer, or held fixed
7 0 ETCRAH	Block size counter	Block size	Decremented once per transfer until H'00 is reached, then reloaded from ETCRAL
7 0 ETCRAL	Initial block size	Block size	Held fixed
15 0 ETCRB	Block transfer counter	Number of block transfers	Decremented once per block transfer until H'0000 is reached and the transfer ends

Legend

MARA: Memory address register A

MARB: Memory address register B

ETCRA: Execute transfer count register A

ETCRB: Execute transfer count register B

The source and destination addresses are both 24-bit addresses. MARA specifies the source address. MARB specifies the destination address. MARA and MARB can be independently incremented, decremented, or held fixed as data is transferred. One of these registers operates as a block area register: even if it is incremented or decremented, it is restored to its initial value at the end of each block transfer. The TMS bit in DTCRB selects whether the block area is the source or destination.

If M (1 to 255) is the size of the block transferred at each request and N (1 to 65,536) is the number of blocks to be transferred, then ETCRAH and ETCRAL should initially be set to M and ETCRB should initially be set to N.

Figure 8.10 illustrates how block transfer mode operates. In this figure, bit TMS is cleared to 0, meaning the block area is the destination.

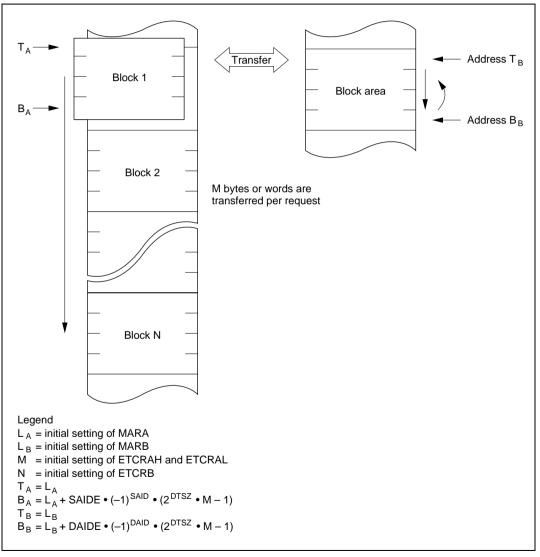


Figure 8.10 Operation in Block Transfer Mode

When activated by a transfer request, the DMAC executes a burst transfer. During the transfer MARA and MARB are updated according to the DTCR settings, and ETCRAH is decremented. When ETCRAH reaches H'00, it is reloaded from ETCRAL to restore the initial value. The memory address register of the block area is also restored to its initial value, and ETCRB is decremented. If ETCRB is not H'0000, the DMAC then waits for the next transfer request. ETCRAH and ETCRAL should be initially set to the same value.

The above operation is repeated until ETCRB reaches H'0000, at which point the DTE bit is cleared to 0 and the transfer ends. If the DTIE bit is set to 1, a CPU interrupt is requested at this time.

Figure 8.11 shows examples of a block transfer with byte data size when the block area is the destination. In (a) the block area address is cycled. In (b) the block area address is held fixed.

Transfers can be requested (activated) by compare match/input capture A interrupts from ITU channels 0 to 3, and by external request signals.

For the detailed settings see section 8.3.4, Data Transfer Control Registers (DTCR).



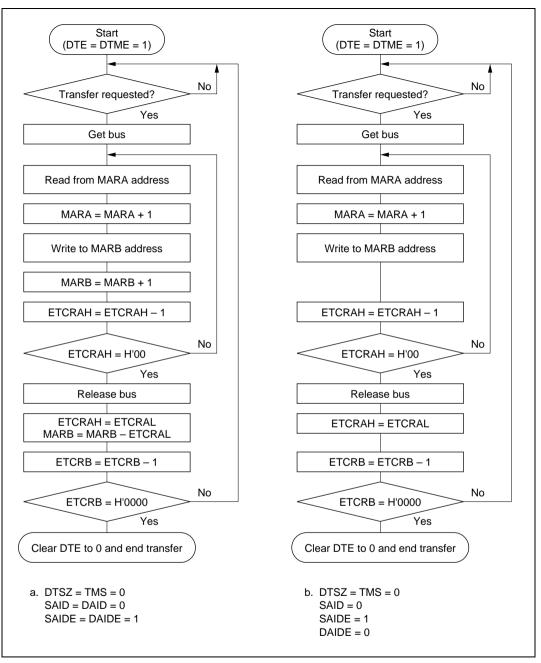


Figure 8.11 Block Transfer Mode Flowcharts (Examples)

Figure 8.12 shows a sample setup procedure for block transfer mode.

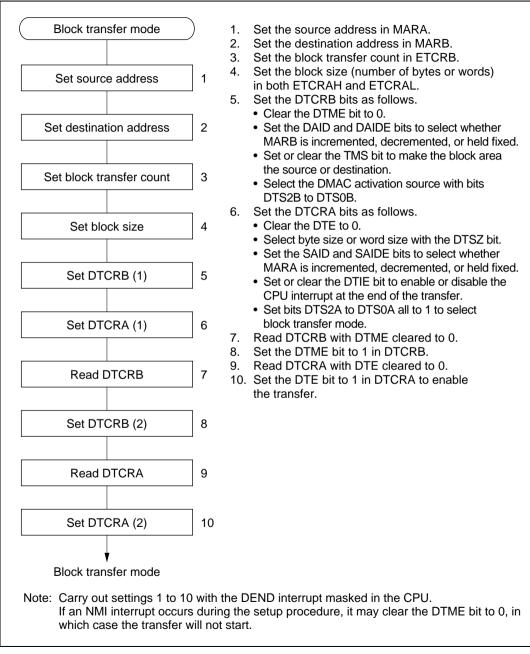


Figure 8.12 Block Transfer Mode Setup Procedure (Example)

8.4.7 DMAC Activation

The DMAC can be activated by an internal interrupt, external request, or auto-request. The available activation sources differ depending on the transfer mode and channel as indicated in table 8.11.

		Short A	ddress Mode	Full Addre	ss Mode
Activation Source		Channels 0A and 1A	Channels 0B and 1B	Normal	Block
Internal	IMIA0	Yes	Yes	No	Yes
interrupts	IMIA1	Yes	Yes	No	Yes
	IMIA2	Yes	Yes	No	Yes
	IMIA3	Yes	Yes	No	Yes
	TXI0	Yes	Yes	No	No
	RXI0	Yes	Yes	No	No
External requests	Falling edge of DREQ	No	Yes	Yes	Yes
	Low input at DREQ	No	Yes	Yes	No
Auto-request		No	No	Yes	No

Table 8.11 DMAC Activation Sources

Activation by Internal Interrupts: When an interrupt request is selected as a DMAC activation source and the DTE bit is set to 1, that interrupt request is not sent to the CPU. It is not possible for an interrupt request to activate the DMAC and simultaneously generate a CPU interrupt.

When the DMAC is activated by an interrupt request, the interrupt request flag is cleared automatically. If the same interrupt is selected to activate two or more channels, the interrupt request flag is cleared when the highest-priority channel is activated, but the transfer request is held pending on the other channels in the DMAC, which are activated in their priority order.

Activation by External Request: If an external request (\overline{DREQ} pin) is selected as an activation source, the \overline{DREQ} pin becomes an input pin and the corresponding \overline{TEND} pin becomes an output pin, regardless of the port data direction register (DDR) settings. The \overline{DREQ} input can be level-sensitive or edge-sensitive.

In short address mode and normal mode, an external request operates as follows. If edge sensing is selected, one byte or word is transferred each time a high-to-low transition of the \overline{DREQ} input is detected. If the next edge is input before the transfer is completed, the next transfer may not be executed. If level sensing is selected, the transfer continues while \overline{DREQ} is low, until the transfer is completed. The bus is released temporarily after each byte or word has been transferred, however. If the \overline{DREQ} input goes high during a transfer, the transfer is suspended after the current byte or word has been transferred. When \overline{DREQ} goes low, the request is held internally until one byte or word has been transferred. The \overline{TEND} signal goes low during the last write cycle.

In block transfer mode, an external request operates as follows. Only edge-sensitive transfer requests are possible in block transfer mode. Each time a high-to-low transition of the \overline{DREQ} input is detected, a block of the specified size is transferred. The \overline{TEND} signal goes low during the last write cycle in each block.

Activation by Auto-Request: The transfer starts as soon as enabled by register setup, and continues until completed. Cycle-steal mode or burst mode can be selected.

In cycle-steal mode the DMAC releases the bus temporarily after transferring each byte or word. Normally, DMAC cycles alternate with CPU cycles.

In burst mode the DMAC keeps the bus until the transfer is completed, unless there is a higherpriority bus request. If there is a higher-priority bus request, the bus is released after the current byte or word has been transferred.



8.4.8 DMAC Bus Cycle

Figure 8.13 shows an example of the timing of the basic DMAC bus cycle. This example shows a word-size transfer from a 16-bit two-state access area to an 8-bit three-state access area. When the DMAC gets the bus from the CPU, after one dead cycle (T_d) , it reads from the source address and writes to the destination address. During these read and write operations the bus is not released even if there is another bus request. DMAC cycles comply with bus controller settings in the same way as CPU cycles.

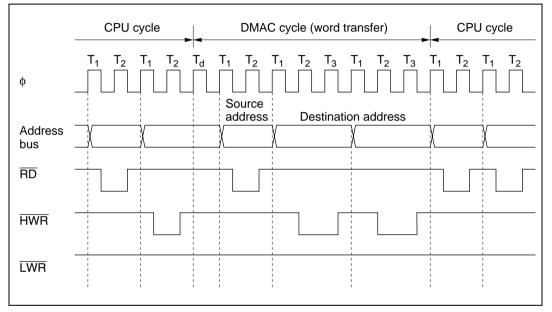


Figure 8.13 DMA Transfer Bus Timing (Example)

Figure 8.14 shows the timing when the DMAC is activated by low input at a $\overline{\text{DREQ}}$ pin. This example shows a word-size transfer from a 16-bit two-state access area to another 16-bit two-state access area. The DMAC continues the transfer while the $\overline{\text{DREQ}}$ pin is held low.

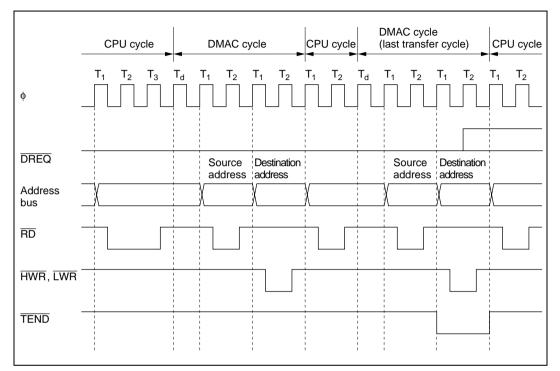


Figure 8.14 Bus Timing of DMA Transfer Requested by Low DREQ Input



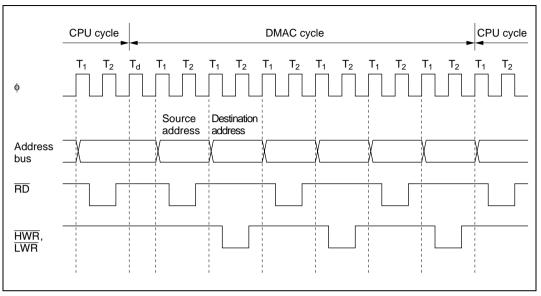


Figure 8.15 shows an auto-requested burst-mode transfer. This example shows a transfer of three words from a 16-bit two-state access area to another 16-bit two-state access area.

Figure 8.15 Bus Timing of Burst Mode DMA Transfer

When the DMAC is activated from a $\overline{\text{DREQ}}$ pin there is a minimum interval of four states from when the transfer is requested until the DMAC starts operating. The $\overline{\text{DREQ}}$ pin is not sampled during the time between the transfer request and the start of the transfer. In short address mode and normal mode, the pin is next sampled at the end of the read cycle. In block transfer mode, the pin is next sampled at the end of the read cycle.

Figure 8.16 shows the timing when the DMAC is activated by the falling edge of $\overline{\text{DREQ}}$ in normal mode.

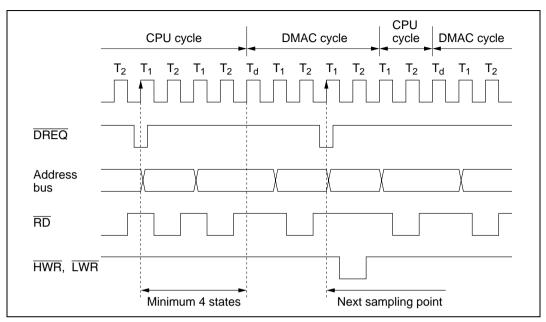


Figure 8.16 Timing of DMAC Activation by Falling Edge of DREQ in Normal Mode



Figure 8.17 shows the timing when the DMAC is activated by level-sensitive low $\overline{\text{DREQ}}$ input in normal mode.

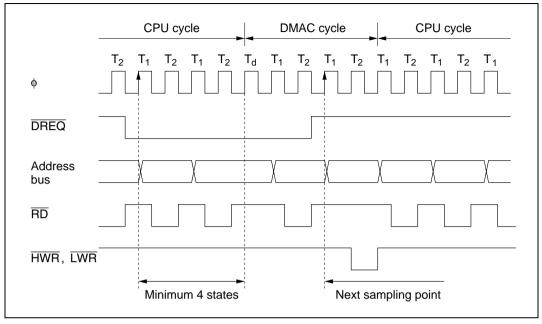


Figure 8.17 Timing of DMAC Activation by Low DREQ Level in Normal Mode

Figure 8.18 shows the timing when the DMAC is activated by the falling edge of $\overline{\text{DREQ}}$ in block transfer mode.

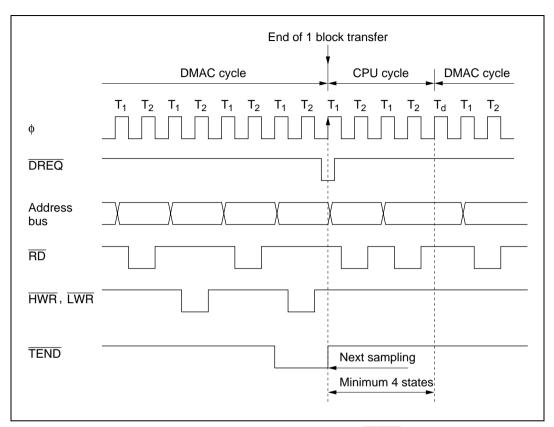


Figure 8.18 Timing of DMAC Activation by Falling Edge of DREQ in Block Transfer Mode



8.4.9 DMAC Multiple-Channel Operation

The DMAC channel priority order is: channel 0 > channel 1 and channel A > channel B.

Table 8.12 shows the complete priority order.

 Table 8.12
 Channel Priority Order

Short Address Mode	Full Address Mode	Priority
Channel 0A	Channel 0	High
Channel 0B		\uparrow
Channel 1A	Channel 1	
Channel 1B		Low

If transfers are requested on two or more channels simultaneously, or if a transfer on one channel is requested during a transfer on another channel, the DMAC operates as follows.

- 1. When a transfer is requested, the DMAC requests the bus right. When it gets the bus right, it starts a transfer on the highest-priority channel at that time.
- 2. Once a transfer starts on one channel, requests to other channels are held pending until that channel releases the bus.
- 3. After each transfer in short address mode, and each externally-requested or cycle-steal transfer in normal mode, the DMAC releases the bus and returns to step 1. After releasing the bus, if there is a transfer request for another channel, the DMAC requests the bus again.
- 4. After completion of a burst-mode transfer, or after transfer of one block in block transfer mode, the DMAC releases the bus and returns to step 1. If there is a transfer request for a higher-priority channel or a bus request from a higher-priority bus master, however, the DMAC releases the bus after completing the transfer of the current byte or word. After releasing the bus, if there is a transfer request for another channel, the DMAC requests the bus again.

Figure 8.19 shows the timing when channel 0A is set up for I/O mode and channel 1 for burst mode, and a transfer request for channel 0A is received while channel 1 is active.

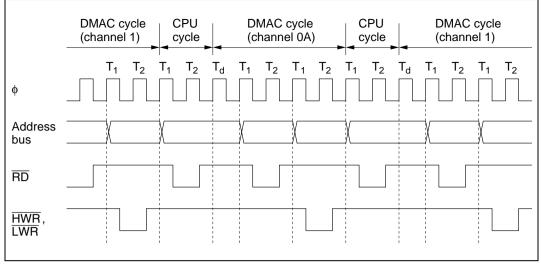


Figure 8.19 Timing of Multiple-Channel Operations

8.4.10 External Bus Requests, Refresh Controller, and DMAC

During a DMA transfer, if the bus right is requested by an external bus request signal (\overline{BREQ}) or by the refresh controller, the DMAC releases the bus after completing the transfer of the current byte or word. If there is a transfer request at this point, the DMAC requests the bus right again. Figure 8.20 shows an example of the timing of insertion of a refresh cycle during a burst transfer on channel 0.

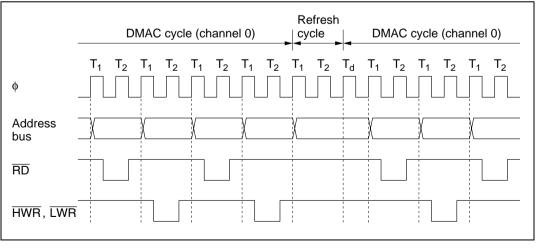


Figure 8.20 Bus Timing of Refresh Controller and DMAC

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8.4.11 NMI Interrupts and DMAC

NMI interrupts do not affect DMAC operations in short address mode.

If an NMI interrupt occurs during a transfer in full address mode, the DMAC suspends operations. In full address mode, a channel is enabled when its DTE and DTME bits are both set to 1. NMI input clears the DTME bit to 0. After transferring the current byte or word, the DMAC releases the bus to the CPU. In normal mode, the suspended transfer resumes when the CPU sets the DTME bit to 1 again. Check that the DTE bit is set to 1 and the DTME bit is cleared to 0 before setting the DTME bit to 1.

Figure 8.21 shows the procedure for resuming a DMA transfer in normal mode on channel 0 after the transfer was halted by NMI input.

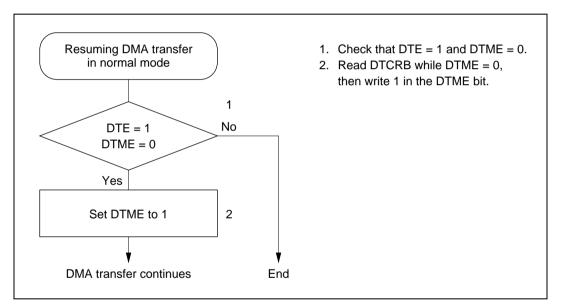


Figure 8.21 Procedure for Resuming a DMA Transfer Halted by NMI (Example)

For information about NMI interrupts in block transfer mode, see section 8.6.6, NMI Interrupts and Block Transfer Mode.

8.4.12 Aborting a DMA Transfer

When the DTE bit in an active channel is cleared to 0, the DMAC halts after transferring the current byte or word. The DMAC starts again when the DTE bit is set to 1. In full address mode, the DTME bit can be used for the same purpose. Figure 8.22 shows the procedure for aborting a DMA transfer by software.

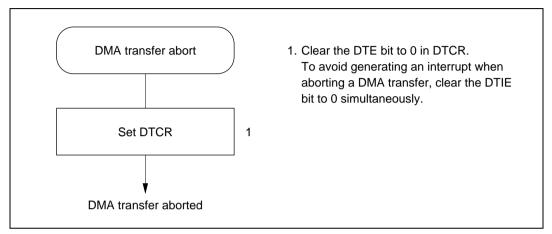


Figure 8.22 Procedure for Aborting a DMA Transfer



8.4.13 Exiting Full Address Mode

Figure 8.23 shows the procedure for exiting full address mode and initializing the pair of channels. To set the channels up in another mode after exiting full address mode, follow the setup procedure for the relevant mode.

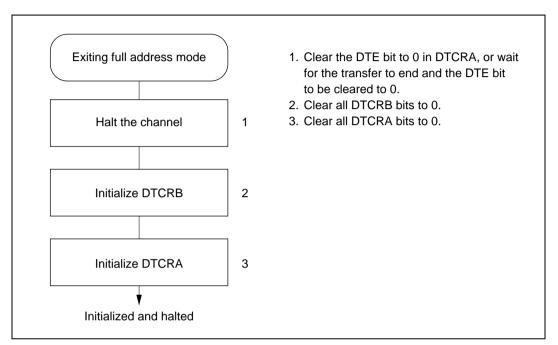


Figure 8.23 Procedure for Exiting Full Address Mode (Example)

8.4.14 DMAC States in Reset State, Standby Modes, and Sleep Mode

When the chip is reset or enters hardware or software standby mode, the DMAC is initialized and halts. DMAC operations continue in sleep mode. Figure 8.24 shows the timing of a cycle-steal transfer in sleep mode.

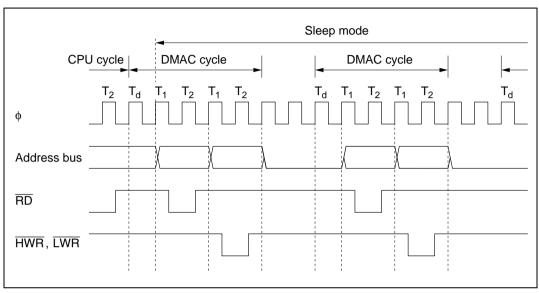


Figure 8.24 Timing of Cycle-Steal Transfer in Sleep Mode



8.5 Interrupts

The DMAC generates only DMA-end interrupts. Table 8.13 lists the interrupts and their priority.

Table 8.13DMAC Interrupts

	Des	Interrupt	
Interrupt	Short Address Mode	Priority	
DEND0A	End of transfer on channel 0A	End of transfer on channel 0	High
DEND0B	End of transfer on channel 0B	—	_ ↑
DEND1A	End of transfer on channel 1A	End of transfer on channel 1	
DEND1B	End of transfer on channel 1B	_	Low

Each interrupt is enabled or disabled by the DTIE bit in the corresponding data transfer control register (DTCR). Separate interrupt signals are sent to the interrupt controller.

The interrupt priority order among channels is channel 0 > channel 1 and channel A > channel B.

Figure 8.25 shows the DMA-end interrupt logic. An interrupt is requested whenever DTE = 0 and DTIE = 1.

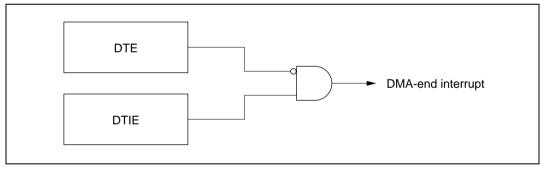


Figure 8.25 DMA-End Interrupt Logic

The DMA-end interrupt for the B channels (DENDB) is unavailable in full address mode. The DTME bit does not affect interrupt operations.

8.6 Usage Notes

8.6.1 Note on Word Data Transfer

Word data cannot be accessed starting at an odd address. When word-size transfer is selected, set even values in the memory and I/O address registers (MAR and IOAR).

8.6.2 DMAC Self-Access

The DMAC itself cannot be accessed during a DMAC cycle. DMAC registers cannot be specified as source or destination addresses.

8.6.3 Longword Access to Memory Address Registers

A memory address register can be accessed as longword data at the MARR address.

Example

MOV.L #LBL, ER0 MOV.L ER0, @MARR

Four byte accesses are performed. Note that the CPU may release the bus between the second byte (MARE) and third byte (MARH).

Memory address registers should be written and read only when the DMAC is halted.

8.6.4 Note on Full Address Mode Setup

Full address mode is controlled by two registers: DTCRA and DTCRB. Care must be taken to prevent the B channel from operating in short address mode during the register setup. The enable bits (DTE and DTME) should not be set to 1 until the end of the setup procedure.

8.6.5 Note on Activating DMAC by Internal Interrupts

When using an internal interrupt to activate the DMAC, make sure that the interrupt selected as the activating source does not occur during the interval after it has been selected but before the DMAC has been enabled. The on-chip supporting module that will generate the interrupt should not be activated until the DMAC has been enabled. If the DMAC must be enabled while the on-chip supporting module is active, follow the procedure in figure 8.26.

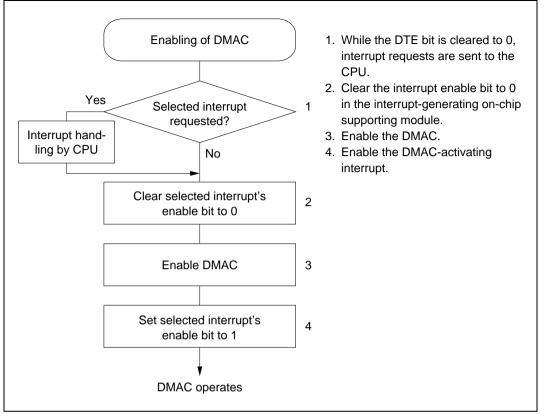


Figure 8.26 Procedure for Enabling DMAC while On-Chip Supporting Module is Operating (Example)

If the DTE bit is set to 1 but the DTME bit is cleared to 0, the DMAC is halted and the selected activating source cannot generate a CPU interrupt. If the DMAC is halted by an NMI interrupt, for example, the selected activating source cannot generate CPU interrupts. To terminate DMAC operations in this state, clear the DTE bit to 0 to allow CPU interrupts to be requested. To continue DMAC operations, carry out steps 2 and 4 in figure 8.26 before and after setting the DTME bit to 1.

When an ITU interrupt activates the DMAC, make sure the next interrupt does not occur before the DMA transfer ends. If one ITU interrupt activates two or more channels, make sure the next interrupt does not occur before the DMA transfers end on all the activated channels. If the next interrupt occurs before a transfer ends, the channel or channels for which that interrupt was selected may fail to accept further activation requests.

8.6.6 NMI Interrupts and Block Transfer Mode

If an NMI interrupt occurs in block transfer mode, the DMAC operates as follows.

- When the NMI interrupt occurs, the DMAC finishes transferring the current byte or word, then clears the DTME bit to 0 and halts. The halt may occur in the middle of a block.
 It is possible to find whether a transfer was halted in the middle of a block by checking the block size counter. If the block size counter does not have its initial value, the transfer was halted in the middle of a block.
- If the transfer is halted in the middle of a block, the activating interrupt flag is cleared to 0. The activation request is not held pending.
- While the DTE bit is set to 1 and the DTME bit is cleared to 0, the DMAC is halted and does not accept activating interrupt requests. If an activating interrupt occurs in this state, the DMAC does not operate and does not hold the transfer request pending internally. Neither is a CPU interrupt requested.

For this reason, before setting the DTME bit to 1, first clear the enable bit of the activating interrupt to 0. Then, after setting the DTME bit to 1, set the interrupt enable bit to 1 again. See section 8.6.5, Note on Activating DMAC by Internal Interrupts.

• When the DTME bit is set to 1, the DMAC waits for the next transfer request. If it was halted in the middle of a block transfer, the rest of the block is transferred when the next transfer request occurs. Otherwise, the next block is transferred when the next transfer request occurs.

8.6.7 Memory and I/O Address Register Values

Table 8.14 indicates the address ranges that can be specified in the memory and I/O address registers (MAR and IOAR).

Table 8.14 Address Ranges Specifiable in MAR and IOAR

	1-Mbyte Mode	16-Mbyte Mode
MAR	H'00000 to H'FFFFF (0 to 1048575)	H'000000 to H'FFFFF (0 to 16777215)
IOAR	H'FFF00 to H'FFFFF (1048320 to 1048575)	H'FFFF00 to H'FFFFFF (16776960 to 16777215)

MAR bits 23 to 20 are ignored in 1-Mbyte mode.



8.6.8 Bus Cycle when Transfer is Aborted

When a transfer is aborted by clearing the DTE bit or suspended by an NMI that clears the DTME bit, if this halts a channel for which the DMAC has a transfer request pending internally, a dead cycle may occur. This dead cycle does not update the halted channel's address register or counter value. Figure 8.27 shows an example in which an auto-requested transfer in cycle-steal mode on channel 0 is aborted by clearing the DTE bit in channel 0.

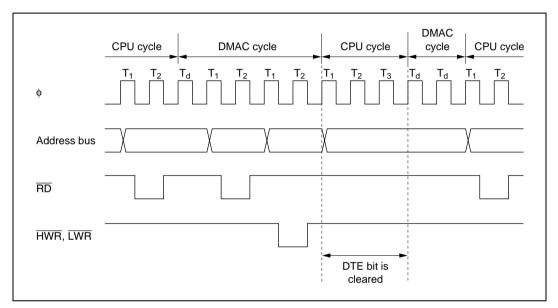


Figure 8.27 Bus Timing at Abort of DMA Transfer in Cycle-Steal Mode



Section 9 I/O Ports

9.1 Overview

The H8/3048 Group has 10 input/output ports (ports 1, 2, 3, 4, 5, 6, 8, 9, A, and B) and one input port (port 7). Table 9.1 summarizes the port functions. The pins in each port are multiplexed as shown in table 9.1.

Each port has a data direction register (DDR) for selecting input or output, and a data register (DR) for storing output data. In addition to these registers, ports 2, 4, and 5 have an input pull-up MOS control register (PCR) for switching input pull-up MOS transistors on and off.

Ports 1 to 6 and port 8 can drive one TTL load and a 90-pF capacitive load. Ports 9, A, and B can drive one TTL load and a 30-pF capacitive load. Ports 1 to 6 and 8 to B can drive a darlington pair. Ports 1, 2, 5, and B can drive LEDs (with 10-mA current sink). Pins P8₂ to P8₀, PA₇ to PA₀, and PB₃ to PB₀ have Schmitt-trigger input circuits.

For block diagrams of the ports see appendix C, I/O Port Block Diagrams.

Table 9.1Port Functions

Port	Description	Pins	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
Port 1	 8-bit I/O port Can drive LEDs 	$P1_7$ to $P1_0/A_7$ to A_0	Address o	utput pins	$(A_7 \text{ to } A_0)$		Address o to A₀) and input	• • •	Generic input/ output
							DDR = 0: input	generic	
							DDR = 1: output	address	
Port 2	• 8-bit I/O port		Address o	utput pins	(A ₁₅ to A ₈)		Address o	• •	Generic
	 Input pull-up MOS 	A_{15} to A_8					to A ₈) and input	generic	input/ output
	 Can drive LEDs 						DDR = 0: input	generic	
							DDR = 1: output	address	
Port 3	• 8-bit I/O port	P3 ₇ to P3 ₀ / D ₁₅ to D ₈	Data input	/output (D₁	₅ to D ₈)				Generic input/ output
Port 4	• 8-bit I/O port	P47 to P40/	Data input	/output (D	to D ₀) and	d 8-bit ger	neric input/	output	Generic
	 Input pull-up 	D ₇ to D ₀	8-bit bus n	node: gene	eric input/o	utput			input/ output
	MOS		16-bit bus	mode: dat	a input/out	put			ouipui
Port 5	• 4-bit I/O port		Address o	utput (A ₁₉ 1	o A ₁₆)		Address o		Generic
	Input pull-up MOS	A ₁₉ to A ₁₆					to A ₁₆) and generic in		input/ output
	• Can drive LEDs						DDR = 0: input	generic	
							DDR = 1: output	address	
Port 6	• 7-bit I/O port	P6 ₆ / <u>LWR,</u> P6₅/ IWR, P6₄/RD, P6₃/AS	Bus contro	ol signal ou	tput (LWR	, HWR, RI	D, AS)		Generic input/ output
		P6 ₂ / BACK , P6 ₁ /BREQ, P6 ₀ /WAIT	Bus contro bit generic			(BACK, BF	REQ, WAIT) and 3-	
Port 7	• 8-bit I/O port	P7 ₇ /AN ₇ /DA ₁ , P7 ₆ /AN ₆ /DA ₀	Analog inp D/A conve	out (AN ₇ , A erter, and g	.,		analog ou	tput (DA ₁ ,	DA ₀) from
		P7₅ to P7₀/ AN₅ to AN₀	Analog inp	out (AN₅ to	AN ₀) to A/	D converte	er, and gen	eric input	

Port	Description	Pins	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
Port 8	 5-bit I/O port P8₂ to P8₀ have Schmitt 		DDR = 0: generic input DDR = 1 (after reset): \overline{CS}_0 output						Generic input/ output
	inputs	P83/CS1/IRQ3, P82/CS2/IRQ2, P81/CS3/IRQ1 P80/RFSH/IRQ0	DDR = 0 (DDR = 1:	after reset \overline{CS}_1 to \overline{CS}		nput	-	input	IRQ₃ to IRQ₀ input and generic input/
Port 9	• 6-bit I/O port		communic		CK ₁ , SCK ₀ , faces 1 and out				
Port A	 8-bit I/O port Schmitt inputs 	PA7/TP7/ TIOCB2/A20	Output (TI programm timing pat controller input or ou (TIOCB ₂) integrated (ITU), and input/outp	hable tern (TPC), utput for 16-bit timer unit I generic	Address o (A ₂₀)	utput	TPC output (TP7), ITU input or output (TIOCB2), and generic input/ output	Address output (A ₂₀)	TPC output (TP7), ITU input or output (TIOCB2), and generic input/ output
		PA ₆ /TP ₆ / TIOCA ₂ /A ₂₁ /CS ₄ PA ₅ /TP ₅ / TIOCB ₁ /A ₂₂ /CS ₅ PA ₄ /TP ₄ / TIOCA ₁ /A ₂₃ /CS ₆	output (TI TIOCB ₁ , T CS₄ to CS	input and OCA ₂ , TOCA ₁), \overline{S}_6 output,	TPC outpu TP4), ITU i output (TIC TIOCB1, T address or to A21), CS output, an- input/outpu	input and DCA_2 , $IOCA_1$), $utput (A_{23})$ \overline{S}_4 to \overline{CS}_6 d generic	TPC output (TP ₆ to TP ₄), ITU input and output (TIOCA ₂ , TIOCA ₁), \overline{CS}_4 to \overline{CS}_6 output, and generic input/ output	TPC output (TP ₆ to TP ₄), ITU input and output (TIOCA ₂ , TIOCB ₁ , TIOCA ₁), address output (A ₂₃ to A ₂₁), \overline{CS}_4 to \overline{CS}_6 output, and generic input/out put	input and output (TIOCA ₂ , TIOCB ₁ , TIOCA ₁), and generic input/

Port	Description	Pins	Mode 1	Mode 2	Mode 3	Mode 4	Mode 5	Mode 6	Mode 7
Port A	 8-bit I/O port Schmitt inputs 	$\begin{array}{l} PA_3/TP_3/\\ TIOCB_0/\\ TCLKD,\\ PA_2/TP_2/\\ TIOCA_0/\\ TCLKC,\\ PA_1/TP_1/\\ TEND_1/TCLKB,\\ PA_0/TP_0/\\ TEND_0/TCLKA \end{array}$	(DMAC), I	TÙ input a	TP ₀), outpu Ind output (Ind generic	TCLKD, T	CLKC, TC		
Port B	 8-bit I/O port Can drive LEDs 	PB7/TP15/ DREQ1/ADTR G	TPC output (TP ₁₅), DMAC input (\overline{DREQ}_1), trigger input (\overline{ADTRG}) to A converter, and generic input/output					3) to A/D	
	 PB₃ to PB₀ have Schmitt inputs 	PB ₆ /TP ₁₄ / DREQ ₀ /CS ₇	TPC output (TP ₁₄), DMAC input (\overline{DREQ}_0), \overline{CS}_7 output, and generic input/output				ıt, and	TPC output (TP ₁₄), DMAC input (DREQ ₀), and generic input/ output	
		PB ₅ /TP ₁₃ / TOCXB ₄ , PB ₄ /TP ₁₂ / TOCXA ₄ , PB ₃ /TP ₁₁ / TIOCB ₄ , PB ₂ /TP ₁₀ / TIOCA ₄ , PB ₁ /TP ₉ / TIOCB ₃ , PB ₀ /TP ₈ / TIOCA ₃		(··-	TPଃ), ITU i OCB₃, TIO		• •	.,	XA4,



9.2 Port 1

9.2.1 Overview

Port 1 is an 8-bit input/output port with the pin configuration shown in figure 9.1. The pin functions differ between the expanded modes with on-chip ROM disabled, expanded modes with on-chip ROM enabled, and single-chip mode. In modes 1 to 4 (expanded modes with on-chip ROM disabled), they are address bus output pins (A_7 to A_0).

In modes 5 and 6 (expanded modes with on-chip ROM enabled), settings in the port 1 data direction register (P1DDR) can designate pins for address bus output (A_7 to A_0) or generic input. In mode 7 (single-chip mode), port 1 is a generic input/output port.

When DRAM is connected to area 3, A_7 to A_0 output row and column addresses in read and write cycles. For details see section 7, Refresh Controller.

Pins in port 1 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

	Port 1 pins	Modes 1 to 4	Modes 5 and 6	Mode 7
	 ➡ P1₇/A₇ 	A ₇ (output)	P1 ₇ (input)/A ₇ (output)	P17 (input/output)
	← P1 ₆ /A ₆	A ₆ (output)	P1 ₆ (input)/A ₆ (output)	P1 ₆ (input/output)
	← P1 ₅ /A ₅	A ₅ (output)	P1 ₅ (input)/A ₅ (output)	P1 ₅ (input/output)
Dort 1	→ P1 ₄ /A ₄	A ₄ (output)	P1 ₄ (input)/A ₄ (output)	P1 ₄ (input/output)
Port 1	 ► P1₃/A₃ 	A ₃ (output)	P1 ₃ (input)/A ₃ (output)	P1 ₃ (input/output)
	 ► P1₂/A₂ 	A ₂ (output)	P1 ₂ (input)/A ₂ (output)	P1 ₂ (input/output)
	 ► P1₁/A₁ 	A ₁ (output)	P1 ₁ (input)/A ₁ (output)	P1 ₁ (input/output)
	← P1 ₀ /A ₀	A ₀ (output)	P1 ₀ (input)/A ₀ (output)	P1 ₀ (input/output)

Figure 9.1 Port 1 Pin Configuration

9.2.2 Register Descriptions

Table 9.2 summarizes the registers of port 1.

Table 9.2 Port 1 Registers

				Initial Value			
Address*	Name	Abbreviation	R/W	Modes 1 to 4	Modes 5 to 7		
H'FFC0	Port 1 data direction register	P1DDR	W	H'FF	H'00		
H'FFC2	Port 1 data register	P1DR	R/W	H'00	H'00		

Note: * Lower 16 bits of the address.

Port 1 Data Direction Register (P1DDR)

P1DDR is an 8-bit write-only register that can select input or output for each pin in port 1.

Bit	7	6	5	4	3	2	1	0
	P17DDR	P1 ₆ DDR	P1₅DDR	P1 ₄ DDR	P1 ₃ DDR	P1 ₂ DDR	P1 ₁ DDR	P1 ₀ DDR
Modes∫Initial valu	ie 1	1	1	1	1	1	1	1
1 to 4 Read/Writ	te —	—	—	—	—	—	—	—
Modes∫Initial valu	ie 0	0	0	0	0	0	0	0
5 to 7 Read/Writ	te W	W	W	W	W	W	W	W

Port 1 data direction 7 to 0 These bits select input or output for port 1 pins

Modes 1 to 4 (Expanded Modes with On-Chip ROM Disabled): P1DDR values are fixed at 1 and cannot be modified. Port 1 functions as an address bus.

Modes 5 and 6 (Expanded Modes with On-Chip ROM Enabled): A pin in port 1 becomes an address output pin if the corresponding P1DDR bit is set to 1, and a generic input pin if this bit is cleared to 0.

Mode 7 (Single-Chip Mode): Port 1 functions as an input/output port. A pin in port 1 becomes an output pin if the corresponding P1DDR bit is set to 1, and an input pin if this bit is cleared to 0.

In modes 5 to 7, P1DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P1DDR is initialized to H'FF in modes 1 to 4 and H'00 in modes 5 to 7 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. If a P1DDR bit is set to 1, the corresponding pin maintains its output state in software standby mode.

Port 1 Data Register (P1DR)

P1DR is an 8-bit readable/writable register that stores port 1 output data. While port 1 acts as an output port, the value of this register is output. When this register is read, the pin logic level of a pin is read for bits for which the P1DDR setting is 0, and the P1DR value is read for bits for which the P1DDR setting is 1.

Bit	7	6	5	4	3	2	1	0
	P1 ₇	P1 ₆	P1 ₅	P1 ₄	P1 ₃	P1 ₂	P1 ₁	P10
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Port 1 data 7 to 0 These bits store data for port 1 pins							

P1DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

9.3 Port 2

9.3.1 Overview

Port 2 is an 8-bit input/output port with the pin configuration shown in figure 9.2. The pin functions differ according to the operating mode.

In modes 1 to 4 (expanded modes with on-chip ROM disabled), port 2 consists of address bus output pins (A_{15} to A_8). In modes 5 and 6 (expanded modes with on-chip ROM enabled), settings in the port 2 data direction register (P2DDR) can designate pins for address bus output (A_{15} to A_8) or generic input. In mode 7 (single-chip mode), port 2 is a generic input/output port.

When DRAM is connected to area 3, A_9 and A_8 output row and column addresses in read and write cycles. For details see section 7, Refresh Controller.

Port 2 has software-programmable built-in pull-up MOS. Pins in port 2 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

	Port 2 p	ins Modes 1 to 4	Modes 5 and 6	Mode 7
	← P2 ₇ /A	15 A ₁₅ (output)	P27 (input)/A15 (output)	P2 ₇ (input/output)
	← P2 ₆ /A	A ₁₄ A ₁₄ (output)	P2 ₆ (input)/A ₁₄ (output)	P2 ₆ (input/output)
	← P2 ₅ /A	13 A ₁₃ (output)	P2 ₅ (input)/A ₁₃ (output)	P2 ₅ (input/output)
David O	← ► P2 ₄ /A	12 A ₁₂ (output)	P2 ₄ (input)/A ₁₂ (output)	P2 ₄ (input/output)
Port 2	← ► P2 ₃ /A	11 A ₁₁ (output)	P2 ₃ (input)/A ₁₁ (output)	P2 ₃ (input/output)
	← P2 ₂ /A	10 A ₁₀ (output)	P2 ₂ (input)/A ₁₀ (output)	P2 ₂ (input/output)
	← ► P2 ₁ /A	₉ A ₉ (output)	P2 ₁ (input)/A ₉ (output)	P2 ₁ (input/output)
	← P2 ₀ /A	₈ A ₈ (output)	P2 ₀ (input)/A ₈ (output)	P2 ₀ (input/output)

Figure 9.2 Port 2 Pin Configuration

9.3.2 Register Descriptions

Table 9.3 summarizes the registers of port 2.

Table 9.3 Port 2 Registers

				Initial Value			
Address*	Name	Abbreviation	R/W	Modes 1 to 4	Modes 5 to 7		
H'FFC1	Port 2 data direction register	P2DDR	W	H'FF	H'00		
H'FFC3	Port 2 data register	P2DR	R/W	H'00	H'00		
H'FFD8	Port 2 input pull-up MOS control register	P2PCR	R/W	H'00	H'00		

Note: * Lower 16 bits of the address.

Port 2 Data Direction Register (P2DDR)

P2DDR is an 8-bit write-only register that can select input or output for each pin in port 2.

Bit	_	7	6	5	4	3	2	1	0	
		P27DDR	P2 ₆ DDR	$P2_5DDR$	P2 ₄ DDR	P2 ₃ DDR	P2 ₂ DDR	P21DDR	P20DDR	
Modes∫	Initial value	e 1	1	1	1	1	1	1	1	
1 to 4	Read/Write	e —	—	—	—	—	—	—	—	
Modes∫	Initial value	e 0	0	0	0	0	0	0	0	
5 to 7 Re	Read/Write	e W W W W W W								
				_						
	Port 2 data direction 7 to 0 These bits select input or									

output for port 2 pins

Modes 1 to 4 (Expanded Modes with On-Chip ROM Disabled): P2DDR values are fixed at 1 and cannot be modified. Port 2 functions as an address bus.

Modes 5 and 6 (Expanded Modes with On-Chip ROM Enabled): Following a reset, port 2 is an input port. A pin in port 2 becomes an address output pin if the corresponding P2DDR bit is set to 1, and a generic input port if this bit is cleared to 0.

Mode 7 (Single-Chip Mode): Port 2 functions as an input/output port. A pin in port 2 becomes an output port if the corresponding P2DDR bit is set to 1, and an input port if this bit is cleared to 0.

In modes 1 to 4, P2DDR always returns 1 when read. No value can be written to.

In modes 5 to 7, P2DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P2DDR is initialized to H'FF in modes 1 to 4 and H'00 in modes 5 to 7 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. If a P2DDR bit is set to 1, the corresponding pin maintains its output state in software standby mode.

Port 2 Data Register (P2DR)

P2DR is an 8-bit readable/writable register that stores output data for pins $P2_7$ to $P2_0$. While port 2 acts as an output port, the value of this register is output. When a bit in P2DDR is set to 1, if port 2 is read the value of the corresponding P2DR bit is returned. When a bit in P2DDR is cleared to 0, if port 2 is read the corresponding pin level is read.

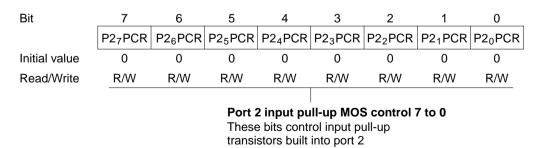
Bit	7	6	5	4	3	2	1	0	
	P27	P2 ₆	P2 ₅	P2 ₄	P2 ₃	P2 ₂	P2 ₁	P2 ₀	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Port 2 data 7 to 0									

These bits store data for port 2 pins

P2DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Port 2 Input Pull-Up MOS Control Register (P2PCR)

P2PCR is an 8-bit readable/writable register that controls the MOS input pull-up transistors in port 2.



In modes 5 to 7, when a P2DDR bit is cleared to 0 (selecting generic input), if the corresponding bit from $P2_7PCR$ to $P2_0PCR$ is set to 1, the input pull-up MOS is turned on.

P2PCR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 9.4 summarizes the states of the input pull-up transistors.

Mode	Reset	Hardware Standby Mode	Software Standby Mode	Other Modes
1	Off	Off	Off	Off
2				
3				
4				
5	Off	Off	On/off	On/off
6				
7				

Table 9.4 Input Pull-Up MOS States (Port 2)

Legend

Off: The input pull-up MOS is always off.

On/off: The input pull-up MOS is on if P2PCR = 1 and P2DDR = 0. Otherwise, it is off.

9.4 Port 3

9.4.1 Overview

Port 3 is an 8-bit input/output port with the pin configuration shown in figure 9.3. Port 3 is a data bus in modes 1 to 6 (expanded modes) and a generic input/output port in mode 7 (single-chip mode).

Pins in port 3 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

	Port 3 pins	Modes 1 to 6	Mode 7
	→ P3 ₇ /D ₁₅	D ₁₅ (input/output)	P3 ₇ (input/output)
	← P3 ₆ /D ₁₄	D ₁₄ (input/output)	P3 ₆ (input/output)
	← P3 ₅ /D ₁₃	D ₁₃ (input/output)	P3 ₅ (input/output)
	← P3 ₄ /D ₁₂	D ₁₂ (input/output)	P3 ₄ (input/output)
Port 3	← P3 ₃ /D ₁₁	D ₁₁ (input/output)	P3 ₃ (input/output)
	← P3 ₂ /D ₁₀	D ₁₀ (input/output)	P3 ₂ (input/output)
	← P3 ₁ /D ₉	D ₉ (input/output)	P3 ₁ (input/output)
	← P3 ₀ /D ₈	D ₈ (input/output)	P3 ₀ (input/output)

Figure 9.3 Port 3 Pin Configuration

9.4.2 Register Descriptions

Table 9.5 summarizes the registers of port 3.

Table 9.5Port 3 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFC4	Port 3 data direction register	P3DDR	W	H'00
H'FFC6	Port 3 data register	P3DR	R/W	H'00

Note: * Lower 16 bits of the address.



Port 3 Data Direction Register (P3DDR)

Bit	7	6	5	4	3	2	1	0	
	P37DDR	P3 ₆ DDR	$P3_5DDR$	P3 ₄ DDR	P3 ₃ DDR	P3 ₂ DDR	P31DDR	P30DDR	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	W	W	W	W	W	W	W	W	
Port 3 data direction 7 to 0									

P3DDR is an 8-bit write-only register that can select input or output for each pin in port 3.

These bits select input or output for port 3 pins

Modes 1 to 6 (Expanded Modes): Port 3 functions as a data bus. P3DDR is ignored.

Mode 7 (Single-Chip Mode): Port 3 functions as an input/output port. A pin in port 3 becomes an output port if the corresponding P3DDR bit is set to 1, and an input port if this bit is cleared to 0.

P3DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P3DDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. If a P3DDR bit is set to 1, the corresponding pin maintains its output state in software standby mode.

Port 3 Data Register (P3DR)

P3DR is an 8-bit readable/writable register that stores output data for pins P3₇ to P3₀. While port 3 acts as an output port, the value of this register is output. When a bit in P3DDR is set to 1, if port 3 is read the value of the corresponding P3DR bit is returned. When a bit in P3DDR is cleared to 0, if port 3 is read the corresponding pin level is read.

Bit	7	6	5	4	3	2	1	0	
	P3 ₇	P3 ₆	P3 ₅	P3 ₄	P3 ₃	P3 ₂	P3 ₁	P3 ₀	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	R/W								
Port 3 data 7 to 0									

These bits store data for port 3 pins

P3DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

9.5 Port 4

9.5.1 Overview

Port 4 is an 8-bit input/output port with the pin configuration shown in figure 9.4. The pin functions differ according to the operating mode.

In modes 1 to 6 (expanded modes), when the bus width control register (ABWCR) designates areas 0 to 7 all as 8-bit-access areas, the chip operates in 8-bit bus mode and port 4 is a generic input/output port. When at least one of areas 0 to 7 is designated as a 16-bit-access area, the chip operates in 16-bit bus mode and port 4 becomes part of the data bus. In mode 7 (single-chip mode), port 4 is a generic input/output port.

Port 4 has software-programmable built-in pull-up MOS.

Pins in port 4 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

	7	Port 4 pins	Modes 1 to 6	Mode 7
	• •	P4 ₇ /D ₇	P47 (input/output)/D7 (input/output)	P47 (input/output)
		P4 ₆ /D ₆	P4 ₆ (input/output)/D ₆ (input/output)	P4 ₆ (input/output)
	• •	P4 ₅ /D ₅	P4 ₅ (input/output)/D ₅ (input/output)	P4 ₅ (input/output)
Port 4		P4 ₄ /D ₄	P4 ₄ (input/output)/D ₄ (input/output)	P4 ₄ (input/output)
FUIL4		P4 ₃ /D ₃	P43 (input/output)/D3 (input/output)	P4 ₃ (input/output)
		P4 ₂ /D ₂	P4 ₂ (input/output)/D ₂ (input/output)	P4 ₂ (input/output)
		P4 ₁ /D ₁	P4 ₁ (input/output)/D ₁ (input/output)	P4 ₁ (input/output)
		P4 ₀ /D ₀	P4 ₀ (input/output)/D ₀ (input/output)	P4 ₀ (input/output)
L				

Figure 9.4 Port 4 Pin Configuration

9.5.2 Register Descriptions

Table 9.6 summarizes the registers of port 4.

Table 9.6Port 4 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFC5	Port 4 data direction register	P4DDR	W	H'00
H'FFC7	Port 4 data register	P4DR	R/W	H'00
H'FFDA	Port 4 input pull-up MOS control register	P4PCR	R/W	H'00

Note: * Lower 16 bits of the address.

Port 4 Data Direction Register (P4DDR)

P4DDR is an 8-bit write-only register that can select input or output for each pin in port 4.

Bit	7	6	5	4	3	2	1	0	
	P47DDR	P4 ₆ DDR	P45DDR	P4 ₄ DDR	P4 ₃ DDR	P4 ₂ DDR	P4 ₁ DDR	P40DDR	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	W	W	W	W	W	W	W	W	
Port 4 data direction 7 to 0									

These bits select input or output for port 4 pins

Modes 1 to 6 (Expanded Modes): When all areas are designated as 8-bit-access areas using the bus width control register (ABWCR) of the bus controller, selecting 8-bit bus mode, port 4 functions as a generic input/output port. A pin in port 4 becomes an output port if the corresponding P4DDR bit is set to 1, and an input port if this bit is cleared to 0.

When at least one area is designated as a 16-bit-access area, selecting 16-bit bus mode, port 4 functions as part of the data bus regardless of the value in P4DDR.

Mode 7 (Single-Chip Mode): Port 4 functions as an input/output port. A pin in port 4 becomes an output port if the corresponding P4DDR bit is set to 1, and an input port if this bit is cleared to 0.

P4DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P4DDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

ABWCR and P4DDR are not initialized in software standby mode. When port 4 functions as a generic input/output port, if a P4DDR bit is set to 1, the corresponding pin maintains its output state in software standby mode.

Port 4 Data Register (P4DR)

P4DR is an 8-bit readable/writable register that stores output data for pins $P4_7$ to $P4_0$. While port 4 acts as an output port, the value of this register is output. When a bit in P4DDR is set to 1, if port 4 is read the value of the corresponding P4DR bit is returned. When a bit in P4DDR is cleared to 0, if port 4 is read the corresponding pin level is read.

Bit	7	6	5	4	3	2	1	0	
	P47	P4 ₆	P4 ₅	P4 ₄	P43	P4 ₂	P4 ₁	P4 ₀	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
	Port 4 data 7 to 0								

These bits store data for port 4 pins

P4DR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Port 4 Input Pull-Up MOS Control Register (P4PCR)

P4PCR is an 8-bit readable/writable register that controls the MOS input pull-up transistors in port 4.

7	6	5	4	3	2	1	0
P47PCR	P4 ₆ PCR	$P4_5PCR$	P4 ₄ PCR	P4 ₃ PCR	P4 ₂ PCR	P41PCR	P4 ₀ PCR
0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	0	0 0	0 0 0 R/W R/W R/W	0 0 0 0 R/W R/W R/W R/W	0 0 0 0 0 R/W R/W R/W R/W	0 0 0 0 0 0 R/W R/W R/W R/W R/W	7 6 5 4 3 2 1 P47PCR P46PCR P45PCR P44PCR P43PCR P42PCR P41PCR 0 0 0 0 0 0 0 R/W R/W R/W R/W R/W R/W R/W

Port 4 input pull-up MOS control 7 to 0 These bits control input pull-up MOS transistors built into port 4

In mode 7 (single-chip mode), and in 8-bit bus mode in modes 1 to 6 (expanded modes), when a P4DDR bit is cleared to 0 (selecting generic input), if the corresponding P4PCR bit is set to 1, the input pull-up MOS transistor is turned on.

P4PCR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 9.7 summarizes the states of the input pull-ups MOS in the 8-bit and 16-bit bus modes.

Table 9.7	Input Pull-Up MOS Transistor States (Port 4)
-----------	--

Mode		Reset	Hardware Standby Mode	Software Standby Mode	Other Modes
1 to 6	8-bit bus mode	Off	Off	On/off	On/off
	16-bit bus mode			Off	Off
7				On/off	On/off

Legend

Off: The input pull-up MOS transistor is always off.

On/off: The input pull-up MOS transistor is on if P4PCR = 1 and P4DDR = 0. Otherwise, it is off.

9.6 Port 5

9.6.1 Overview

Port 5 is a 4-bit input/output port with the pin configuration shown in figure 9.5. The pin functions differ depending on the operating mode.

In modes 1 to 4 (expanded modes with on-chip ROM disabled), port 5 consists of address output pins (A_{19} to A_{16}). In modes 5 and 6 (expanded modes with on-chip ROM enabled), settings in the port 5 data direction register (P5DDR) designate pins for address bus output (A_{19} to A_{16}) or generic input. In mode 7 (single-chip mode), port 5 is a generic input/output port.

Port 5 has software-programmable built-in pull-up MOS transistors.

Pins in port 5 can drive one TTL load and a 90-pF capacitive load. They can also drive an LED or a darlington transistor pair.

[7	Port 5 pins	Modes 1 to 4	Modes 5 and 6	Mode 7
	• •	P5 ₃ /A ₁₉	A ₁₉ (output)	P53 (input)/A19 (output)	P53 (input/output)
Port 5	• •	P5 ₂ /A ₁₈	A ₁₈ (output)	P5 ₂ (input)/A ₁₈ (output)	P5 ₂ (input/output)
FUILD	• •	P5 ₁ /A ₁₇	A ₁₇ (output)	P5 ₁ (input)/A ₁₇ (output)	P5 ₁ (input/output)
		P5 ₀ /A ₁₆	A ₁₆ (output)	P5 ₀ (input)/A ₁₆ (output)	P5 ₀ (input/output)
L					

Figure 9.5 Port 5 Pin Configuration



9.6.2 **Register Descriptions**

Table 9.8 summarizes the registers of port 5.

Table 9.8 Port 5 Registers

				Initia	I Value
Address*	Name	Abbreviation	R/W	Modes 1 to 4	Modes 5 to 7
H'FFC8	Port 5 data direction register	P5DDR	W	H'FF	H'F0
H'FFCA	Port 5 data register	P5DR	R/W	H'F0	H'F0
H'FFDB	Port 5 input pull-up MOS control register	P5PCR	R/W	H'F0	H'F0

Note: * Lower 16 bits of the address.

Port 5 Data Direction Register (P5DDR)

P5DDR is an 8-bit write-only register that can select input or output for each pin in port 5.

Bits 7 to 4 are reserved. They cannot be modified and are always read as 1.

Bit	7	6	5	4	3	2	1	0
	—	—	_	—	P5 ₃ DDR	P5 ₂ DDR	P51DDR	P5 ₀ DDR
Modes Initial value	e 1	1	1	1	1	1	1	1
1 to 4 Read/Write	» —	—	—	_	—	—	—	_
Modes∫Initial value	e 1	1	1	1	0	0	0	0
5 to 7 Read/Write	» <u> </u>		—		W	W	W	W
Reserved bits					Th	rt 5 data d ese bits se put for pol	elect input	

Modes 1 to 4 (Expanded Modes with On-Chip ROM Disabled): P5DDR values are fixed at 1 and cannot be modified. Port 5 functions as an address bus.

Modes 5 and 6 (Expanded Modes with On-Chip ROM Enabled): Following a reset, port 5 is an input port. A pin in port 5 becomes an address output pin if the corresponding P5DDR bit is set to 1, and an input port if this bit is cleared to 0.

Mode 7 (Single-Chip Mode): Port 5 functions as an input/output port. A pin in port 5 becomes an output port if the corresponding P5DDR bit is set to 1, and an input port if this bit is cleared to 0.

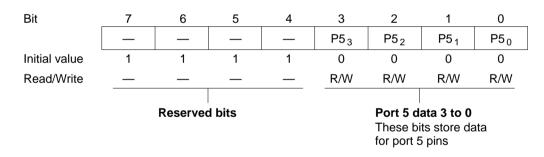
In modes 1 to 4, P5DDR always returns 1 when read. No value can be written to.

In modes 5 to 7, P5DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P5DDR is initialized to H'FF in modes 1 to 4 and H'F0 in modes 5 to 7 by a reset and in hardware standby mode. In software standby mode it retains its previous setting, so if a P5DDR bit is set to 1 while port 5 acts as an I/O port, the corresponding pin maintains its output state in software standby mode.

Port 5 Data Register (P5DR)

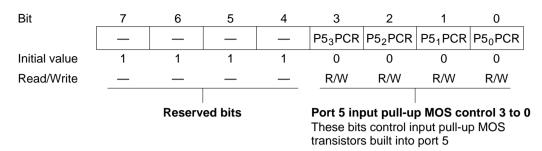
P5DR is an 8-bit readable/writable register that stores output data for pins $P5_3$ to $P5_0$. While port 5 acts as an output port, the value of this register is output. When a bit in P5DDR is set to 1, if port 5 is read the value of the corresponding P5DR bit is returned. When a bit in P5DDR is cleared to 0, if port 5 is read the corresponding pin level is read.



Bits 7 to 4 are reserved. They cannot be modified and are always read as 1.

P5DR is initialized to H'F0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.





Port 5 Input Pull-Up MOS Control Register (P5PCR)

P5PCR is an 8-bit readable/writable register that controls the MOS input pull-up MOS transistors in port 5.

Bits 7 to 4 are reserved. They cannot be modified and are always read as 1.

In modes 5 to 7, when a P5DDR bit is cleared to 0 (selecting generic input), if the corresponding bit from $P5_3PCR$ to $P5_0PCR$ is set to 1, the input pull-up MOS transistor is turned on.

P5PCR is initialized to H'F0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 9.9 summarizes the states of the input pull-ups MOS in each mode.

Table 9.9	Input Pull-Up MOS Transistor States (Port 5)
-----------	--

Mode	Reset	Hardware Standby Mode	Software Standby Mode	Other Modes
1	Off	Off	Off	Off
2				
3				
4				
5	Off	Off	On/off	On/off
6				
7				
Legend				

Off: The input pull-up MOS transistor is always off.

On/off: The input pull-up MOS transistor is on if P5PCR = 1 and P5DDR = 0. Otherwise, it is off.

9.7 Port 6

9.7.1 Overview

Port 6 is a 7-bit input/output port that is also used for input and output of bus control signals (\overline{LWR} , \overline{HWR} , \overline{RD} , \overline{AS} , \overline{BACK} , \overline{BREQ} , and \overline{WAIT}). When DRAM is connected to area 3, \overline{LWR} , HWR, and \overline{RD} also function as \overline{LW} , \overline{UW} , and \overline{CAS} , or \overline{LCAS} , \overline{UCAS} , and \overline{WE} , respectively. For details see section 7, Refresh Controller.

Figure 9.6 shows the pin configuration of port 6. In modes 1 to 6 (expanded modes) the pin functions are \overline{LWR} , \overline{HWR} , \overline{RD} , \overline{AS} , $P6_2/\overline{BACK}$, $P6_1/\overline{BREQ}$, and $P6_0/\overline{WAIT}$. See table 9.11 for the method of selecting the pin states. In mode 7 (single-chip mode) port 6 is a generic input/output port.

Pins in port 6 can drive one TTL load and a 30-pF capacitive load. They can also drive a darlington transistor pair.

		Port 6 pins	Modes 1 to 6 (expanded modes	s)		Mode 7 (single-chip mode)
	< →	$P6_6 / \overline{LWR}$		LWR	(output)	P6 ₆ (input/output)
	< →	$P6_5 / \overline{HWR}$		HWR	(output)	P6 ₅ (input/output)
	< →	$P6_4 / \overline{RD}$		RD	(output)	P6 ₄ (input/output)
Port 6	← →	$P6_3 / \overline{AS}$		AS	(output)	P63 (input/output)
	← ►	P6 ₂ / BACK	P62 (input/output)/	BACK	(output)	P6 ₂ (input/output)
	• •	$P6_1 / \overline{BREQ}$	P6 ₁ (input/output)/	BREQ	(input)	P6 ₁ (input/output)
	← ►	$P6_0 / \overline{WAIT}$	P60 (input/output)/	WAIT	(input)	P6 ₀ (input/output)

Figure 9.6 Port 6 Pin Configuration

9.7.2 Register Descriptions

Table 9.10 summarizes the registers of port 6.

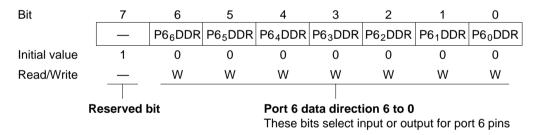
Table 9.10 Port 6 Registers

				Initial Value		
Address*	Name	Abbreviation	R/W	Mode 1 to 5	Mode 6, 7	
H'FFC9	Port 6 data direction register	P6DDR	W	H'F8	H'80	
H'FFCB	Port 6 data register	P6DR	R/W	H'80	H'80	

Note: * Lower 16 bits of the address.

Port 6 Data Direction Register (P6DDR)

P6DDR is an 8-bit write-only register that can select input or output for each pin in port 6. Bit 7 is reserved. It cannot be modified and is always read as 1.



Modes 1 to 6 (Expanded Modes): Ports P6₆ to P6₃ function as bus control output pins (\overline{LWR} , \overline{HWR} , \overline{RD} , \overline{AS}), regardless of the settings of P6₆DDR to P6₃DDR. Ports P6₂ to P6₀ function as the bus control pins (\overline{BACK} , \overline{BREQ} , \overline{WAIT}) or I/O ports. For selecting the pin function, see table 9.11. When ports P6₂ to P6₀ function as I/O ports and if P6DDR is set to 1, the corresponding pin of port 6 functions as an output port. If P6DDR is cleared to 0, the corresponding pin functions as an input port.

Mode 7 (Single-Chip Mode): Port 6 is a generic input/output port. A pin in port 6 becomes an output port if the corresponding P6DDR bit is set to 1, and an input port if this bit is cleared to 0.

P6DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P6DDR is initialized to H'80 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. If a P6DDR bit is set to 1 while port 6 acts as an I/O port, the corresponding pin maintains its output state in software standby mode.

Port 6 Data Register (P6DR)

Bit	7	6	5	4	3	2	1	0
	—	P6 ₆	P6 ₅	P64	P6 ₃	P62	P6 ₁	P6 ₀
Initial value	1	0	0	0	0	0	0	0
Read/Write	_	R/W	R/W	R/W	R/W	R/W	R/W	R/W
F	Port 6 data 6 to 0 These bits store data for port 6 pins							
				1116	26 0112 211	Jie uala iu	i port o pi	15

P6DR is an 8-bit readable/writable register that stores output data for pins P6₆ to P6₀. When this register is read, bits 6 to 0 each returns the logic level of the pin, when the corresponding bit of P6DDR is 0. When the corresponding bit of P6DDR is 1, bits 6 to 0 return the P6DR value.

Bit 7 is reserved, cannot be modified, and always read as 1.

P6DR is initialized to H'80 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Pin	Pin Functions and Selection Method						
P6 ₆ /UWR	Functions as follows re	egardless of P66DDR					
	P6 ₆ DDR	0	1				
	Pin function	LWR	utput				
P6 ₅ /HWR	Functions as follows re	egardless of P6₅DDR					
	P6₅DDR	0	1				
	Pin function HWR output						
	<u></u>						
P6 ₄ /RD	Functions as follows regardless of P6₄DDR						
	P6₄DDR	0	1				
	Pin function	RD ou	tput				
P6 ₃ /AS	Functions as follows re	egardless of P6₃DDR					
	P6 ₃ DDR	0	1				
	Pin function	AS ou	tput				
		AS ou	ιρυι				

Table 9.11 Port 6 Pin Functions in Modes 1 to 6

Pin	Pin Functions a	nd Selection M	ethod			
P6 ₂ /BACK	Bit BRLE in BRC	R and bit P62DI	OR select the pir	n function as	follows	
	BRLE		0		1	
	P6 ₂ DDR	0	1			
	Pin function	P62 input P62 output		BACK output		
				<u> </u>		
P6 ₁ /BREQ	Bit BRLE in BRC	R and bit P6 ₁ D	OR select the pir	n function as	follows	
	BRLE	0			1	
	P61DDR	0	1	1	_	
	Pin function	P6₁ input	P61 0	utput	BREQ input	
P6₀/WAIT	Bits WCE7 to W0		oit WMS1 in WC	R, and bit P6	0DDR select the	
	WCER		All 1s		Not all 1s	
	WMS1	()	1		
	P6₀DDR	0	1	0*	0*	
	Pin function	P6 ₀ input	P60 output	W	AIT input	
	Note: * Do not se	et bit P6 ₀ DDR to	1.			

9.8 Port 7

9.8.1 Overview

Port 7 is an 8-bit input port that is also used for analog input to the A/D converter and analog output from the D/A converter. The pin functions are the same in all operating modes. Figure 9.7 shows the pin configuration of port 7.

For the analog input pins of the A/D converter, see section 15, A/D Converter.

For the analog input pins of the D/A converter, see section 16, D/A Converter.

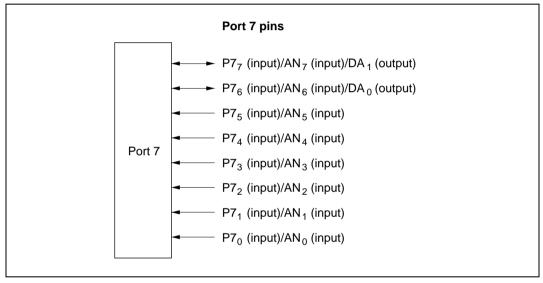


Figure 9.7 Port 7 Pin Configuration

9.8.2 Register Description

Table 9.12 summarizes the port 7 register. Port 7 is an input-only port, so it has no data direction register.

Table 9.12 Port 7 Data Register

Address*	Name	Abbreviation	R/W	Initial Value
H'FFCE	Port 7 data register	P7DR	R	Undetermined
Note: * Lowe	r 16 bits of the address.			

Port 7 Data Register (P7DR)

Bit	7	6	5	4	3	2	1	0
	P7 ₇	P7 ₆	P7 ₅	P7 ₄	P7 ₃	P7 ₂	P7 ₁	P70
Initial value	*	*	*	*	*	*	*	*
Read/Write	R	R	R	R	R	R	R	R

Note: * Determined by pins P7₇ to P7₀.

When P7DR is read, the logic level of the pin is always read. No data can be written to.

9.9 Port 8

9.9.1 Overview

Port 8 is a 5-bit input/output port that is also used for \overline{CS}_3 to \overline{CS}_0 output, \overline{RFSH} output, and \overline{IRQ}_3 to \overline{IRQ}_0 input. Figure 9.8 shows the pin configuration of port 8.

In modes 1 to 6 (expanded modes), port 8 can provide \overline{CS}_3 to \overline{CS}_0 output, RFSH output, and \overline{IRQ}_3 to \overline{IRQ}_0 input. See table 9.14 for the selection of pin functions in expanded modes.

In mode 7 (single-chip mode), port 8 can provide \overline{IRQ}_3 to \overline{IRQ}_0 input. See table 9.15 for the selection of pin functions in single-chip mode.

The \overline{IRQ}_3 to \overline{IRQ}_0 functions are selected by IER settings, regardless of whether the pin is used for input or output. For details see section 5, Interrupt Controller.

Pins in port 8 can drive one TTL load and a 90-pF capacitive load. They can also drive a darlington transistor pair.

Pins P82 to P80 have Schmitt-trigger inputs.

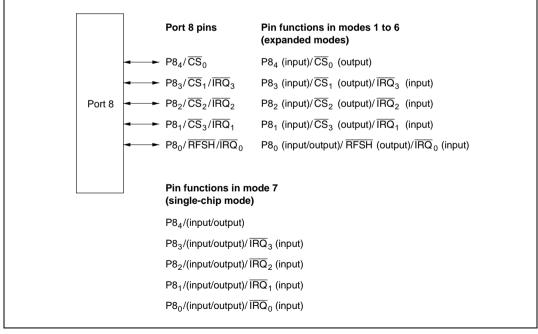


Figure 9.8 Port 8 Pin Configuration

9.9.2 Register Descriptions

Table 9.13 summarizes the registers of port 8.

Table 9.13 Port 8 Registers

				Initial Value			
Address*	Name	Abbreviation	R/W	Mode 1 to 4	Mode 5 to 7		
H'FFCD	Port 8 data direction register	P8DDR	W	H'F0	H'E0		
H'FFCF	Port 8 data register	P8DR	R/W	H'E0	H'E0		
	10111 11						

Note: * Lower 16 bits of the address.

Port 8 Data Direction Register (P8DDR)

P8DDR is an 8-bit write-only register that can select input or output for each pin in port 8.

Bits 7 to 5 are reserved. They cannot be modified and are always read as 1.

Bit	_	7	6	5	4	3	2	1	0
		_	_		P84DDR	P83DDR	P82DDR	P81DDR	P80DDR
Modes	Initial value	1	1	1	1	0	0	0	0
1 to 4	Read/Write	—	—	—	W	W	W	W	W
Modes	Initial value	1	1	1	0	0	0	0	0
5 to 7	Read/Write	—	—	—	W	W	W	W	W
		F	Reserved I	oits		These bit	ata directi s select in r port 8 pir	put or	

Modes 1 to 6 (Expanded Modes): When bits in P8DDR bit are set to 1, $P8_4$ to $P8_1$ become \overline{CS}_0 to \overline{CS}_3 output pins. When bits in P8DDR are cleared to 0, the corresponding pins become input ports. In modes 1 to 4 (expanded modes with on-chip ROM disabled), following a reset only \overline{CS}_0 is output. The other three pins are input ports. In modes 5 and 6 (expanded modes with on-chip ROM enabled), following a reset all four pins are input ports.

When the refresh controller is enabled, $P8_0$ is used unconditionally for $\overline{\text{RFSH}}$ output. When the refresh controller is disabled, $P8_0$ becomes a generic input/output port according to the P8DDR setting. For details see table 9.15.

Mode 7 (Single-Chip Mode): Port 8 is a generic input/output port. A pin in port 8 becomes an output port if the corresponding P8DDR bit is set to 1, and an input port if this bit is cleared to 0.

P8DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P8DDR is initialized to H'F0 in modes 1 to 4 and H'E0 in modes 5 to 7 by a reset and in hardware standby mode. In software standby mode it retains its previous setting, so if a P8DDR bit is set to 1 while port 8 acts as an I/O port, the corresponding pin maintains its output state in software standby mode.

Port 8 Data Register (P8DR)

P8DR is an 8-bit readable/writable register that stores output data for pins $P8_4$ to $P8_0$. While port 8 acts as an output port, the value of this register is output. When a bit in P8DDR is set to 1, if port 8 is read the value of the corresponding P8DR bit is returned. When a bit in P8DDR is cleared to 0, if port 8 is read the corresponding pin level is read.

Bits 7 to 5 are reserved. They cannot be modified and always are read as 1.

Bit	7	6	5	4	3	2	1	0	
	—	—	—	P84	P83	P82	P8 1	P8 ₀	
Initial value	1	1	1	0	0	0	0	0	
Read/Write	_	_	_	R/W	R/W	R/W	R/W	R/W	
	Reserved bits			Port 8 data 4 to 0					
						se bits stor ort 8 pins	e data		
					101 p				

P8DR is initialized to H'E0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.



Pin	Pin Functions and Selection Method						
P84/CS0	Bit P84DDR select	ts the pin function as	follows				
	P8₄DDR	0		1			
	Pin function	P8₄ input	\overline{CS}_0 output				
	<u> </u>		L				
P8 ₃ /CS ₁ /IRQ ₃	Bit P83DDR select	ts the pin function as	follows				
	P8₃DDR	0		1			
	Pin function	P83 input		CS ₁ output			
		IRQ ₃ input					
	L						
P8 ₂ /CS ₂ /IRQ ₂	Bit P82DDR select	ts the pin function as	follows				
	P8₂DDR	0		1			
	Pin function	P82 input		CS ₂ output			
			IRQ ₂ input				
P8 ₁ / CS ₃ / IRQ ₁	Bit P81DDR select	ts the pin function as	follows				
	P81DDR	0		1			
	Pin function	P81 input		\overline{CS}_3 output			
			IRQ ₁ input				
P8 ₀ /RFSH/IRQ ₀	Bit RFSHE in RFS	HCR and bit P8 ₀ DD	R select the pin fund	ction as follows			
	RFSHE	0		1			
	P8₀DDR	0	1	_			
	Pin function	P8₀ input	P80 output	RFSH output			
		L. L	IRQ ₀ input	4			

Table 9.14Port 8 Pin Functions in Modes 1 to 6

Pin	Pin Functions and	Selection Method					
P84	Bit P84DDR selects	the pin function as follows					
	P8₄DDR	0	1				
	Pin function	P8₄ input	P8₄ output				
P8 ₃ /IRQ ₃	Bit P8₂DDR selects	the pin function as follows					
	P8 ₃ DDR	0	1				
	Pin function	P83 input	P8₃ output				
		IRQ₃ input					
P8 ₂ /IRQ ₂	Bit P82DDR selects	the pin function as follows					
	P82DDR	0	1				
	Pin function	P82 input	P8 ₂ output				
		IRQ₂ input					
P8 ₁ /IRQ ₁	Bit P81DDR selects	the pin function as follows					
	P81DDR	0	1				
	Pin function	P81 input	P8₁ output				
		IRQ ₁ input					
P8 ₀ /IRQ ₀		ne pin function as follows					
	P8₀DDR	0	1				
	Pin function	P80 input	P8 ₀ output				
		IRQ ₀ input					

Table 9.15Port 8 Pin Functions in Mode 7



9.10 Port 9

9.10.1 Overview

Port 9 is a 6-bit input/output port that is also used for input and output $(TxD_0, TxD_1, RxD_0, RxD_1, SCK_0, SCK_1)$ by serial communication interface channels 0 and 1 (SCI0 and SCI1), and for $\overline{IRQ_5}$ and $\overline{IRQ_4}$ input. See table 9.17 for the selection of pin functions.

The \overline{IRQ}_5 and \overline{IRQ}_4 functions are selected by IER settings, regardless of whether the pin is used for input or output. For details see section 5, Interrupt Controller.

Port 9 has the same set of pin functions in all operating modes. Figure 9.9 shows the pin configuration of port 9.

Pins in port 9 can drive one TTL load and a 30-pF capacitive load. They can also drive a darlington transistor pair.

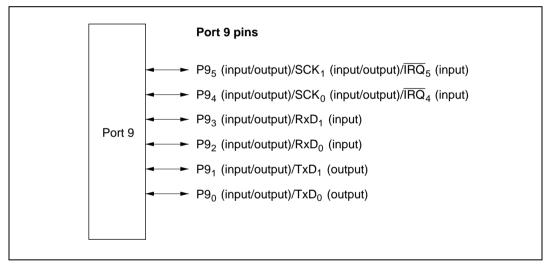


Figure 9.9 Port 9 Pin Configuration

9.10.2 Register Descriptions

Table 9.16 summarizes the registers of port 9.

Table 9.16Port 9 Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFD0	Port 9 data direction register	P9DDR	W	H'C0
H'FFD2	Port 9 data register	P9DR	R/W	H'C0
NI 1				

Note: * Lower 16 bits of the address.

Port 9 Data Direction Register (P9DDR)

P9DDR is an 8-bit write-only register that can select input or output for each pin in port 9.

Bits 7 and 6 are reserved. They cannot be modified and are always read as 1.

Bit	7	6	5	4	3	2	1	0
	PA ₇	PA_6	PA_5	PA ₄	PA ₃	PA ₂	PA ₁	PA ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Port A data 7 to 0 These bits store data for port A pins

While port 9 acts as an I/O port, a pin in port 9 becomes an output port if the corresponding P9DDR bit is set to 1, and an input port if this bit is cleared to 0. For selecting the pin function, see table 9.17.

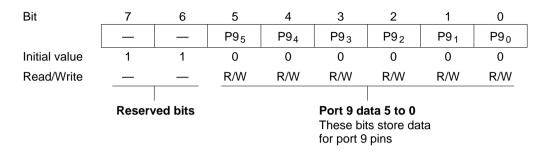
P9DDR is a write-only register. Its value cannot be read. All bits return 1 when read.

P9DDR is initialized to H'C0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. If a P9DDR bit is set to 1 while port 9 acts as an I/O port, the corresponding pin maintains its output state in software standby mode.



Port 9 Data Register (P9DR)

P9DR is an 8-bit readable/writable register that stores output data for pins $P9_5$ to $P9_0$. While port 9 acts as an output port, the value of this register is output. When a bit in P9DDR is set to 1, if port 9 is read the value of the corresponding P9DR bit is returned. When a bit in P9DDR is cleared to 0, if port 9 is read the corresponding pin level is read.



Bits 7 and 6 are reserved. They cannot be modified and are always read as 1.

P9DR is initialized to H'C0 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.

Table 9.17Port 9 Pin Functions

Pin Pin Functions and Selection Method P9₅/SCK1/IRQ₅ Bit C/A in SMR of SCI1. bits CKE0 and CKE1 in SCR of SCI1. and bit P9₅DDR

CKE1		0 1					
C/Ā		0					
CKE0	(C	1				
P9₅DDR	0	1					
Pin function	P9₅ input	P9₅ output	SCK₁ output	SCK₁ output	SCK₁ input		
		1	IRQ₅ input		1		

P9₄/SCK₀/IRQ₄ Bit C/A in SMR of SCI0, bits CKE0 and CKE1 in SCR of SCI0, and bit P9₄DDR select the pin function as follows

CKE1		0					
C/Ā		0 1					
CKE0	C)	1		-		
P9₄DDR	0	1	—		-		
Pin function	P9₄ input	P9 ₄ output	SCK₀ output	SCK₀ output	SCK₀ input		
			IRQ ₄ input				

P9₃/RxD₁ Bit RE in SCR of SCI1 and bit P9₃DDR select the pin function as follows

RE	(1	
P9₃DDR	0	1	—
Pin function	P93 input	P93 output	RxD₁ input

P9₂/RxD₀

Bit RE in SCR of SCI0, bit SMIF in SCMR, and bit P9₂DDR select the pin function as follows

SMIF		1		
RE	()	1	—
P92DDR	0	1	—	—
Pin function	P92 input	P92 output	RxD ₀ input	RxD ₀ input

Pin	Pin Functions a	Pin Functions and Selection Method										
P9 ₁ /TxD ₁	Bit TE in SCR of	Bit TE in SCR of SCI1 and bit P91DDR select the pin function as follows										
	TE			1								
	P91DDR	0		1	_							
	Pin function	P9₁ input	P91 c	output	TxD₁ output							
P9 ₀ /TxD ₀		Bit TE in SCR of SCI0, bit SMIF in SCMR, and bit P9 ₀ DDR select the pin function as follows										
	TE		<u>ן</u>	1	1							
			J	1								
	P9₀DDR	0	1	—	—							
	Pin function	tion P90 input P90		TxD ₀ output	TxD ₀ output*							
Note: * Functions as the TxD ₀ output pin, but there are two states: one the pin is driven, and another in which the pin is at high-impeda												

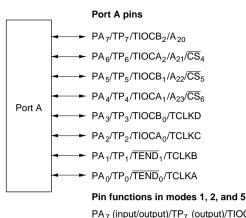
9.11 Port A

9.11.1 Overview

Port A is an 8-bit input/output port that is also used for output (TP₇ to TP₀) from the programmable timing pattern controller (TPC), input and output (TIOCB₂, TIOCA₂, TIOCB₁, TIOCA₁, TIOCB₀, TIOCA₀, TCLKD, TCLKC, TCLKB, TCLKA) by the 16-bit integrated timer unit (ITU), output (TEND₁, TEND₀) from the DMA controller (DMAC), \overline{CS}_4 to \overline{CS}_6 output, and address output (A₂₃ to A₂₀). A reset or hardware standby leaves port A as an input port, except that in modes 3, 4, and 6, one pin is always used for A₂₀ output. For selecting the pin function, see table 9.19. Usage of pins for TPC, ITU, and DMAC input and output is described in the sections on those modules. For output of address bits A₂₃ to A₂₁ in modes 3, 4, and 6, see section 6.2.5, Bus Release Control Register (BRCR). For output of \overline{CS}_4 to \overline{CS}_6 in modes 1 to 6, see section 6.3.2, Chip Select Signals. Pins not assigned to any of these functions are available for generic input/output. Figure 9.10 shows the pin configuration of port A.

Pins in port A can drive one TTL load and a 30-pF capacitive load. They can also drive a darlington transistor pair. Port A has Schmitt-trigger inputs.





PA7 (input/output)/TP7 (output)/TIOCB2 (input/output) PA_6 (input/output)/TP₆ (output)/TIOCA₂ (input/output)/ \overline{CS}_4 (output) PA₅ (input/output)/TP₅ (output)/TIOCB₁ (input/output)/CS₅(output) PA₄ (input/output)/TP₄ (output)/TIOCA₁ (input/output)/CS₆(output) PA₃ (input/output)/TP₃ (output)/TIOCB₀ (input/output)/TCLKD (input) PA2 (input/output)/TP2 (output)/TIOCA0 (input/output)/TCLKC (input) PA1 (input/output)/TP1 (output)/TEND1 (output)/TCLKB (input) PA₀ (input/output)/TP₀ (output)/TEND₀ (output)/TCLKA (input) Pin functions in modes 3, 4, and 6 A₂₀ (output) PA_{6} (input/output)/TP₆ (output)/TIOCA₂ (input/output)/A₂₁ (output)/ \overline{CS}_{4} (output) PA₅ (input/output)/TP₅ (output)/TIOCB₁ (input/output)/A₂₂ (output)/CS₅ (output) PA_4 (input/output)/TP₄ (output)/TIOCA₁ (input/output)/A₂₃ (output)/ \overline{CS}_6 (output) PA₃ (input/output)/TP₃ (output)/TIOCB₀ (input/output)/TCLKD (input) PA2 (input/output)/TP2 (output)/TIOCA0 (input/output)/TCLKC (input) PA₁ (input/output)/TP₁ (output)/TEND₁ (output)/TCLKB (input) PA₀ (input/output)/TP₀ (output)/TEND₀ (output)/TCLKA (input) Pin functions in mode 7 PA₇ (input/output)/TP₇ (output)/TIOCB₂ (input/output) PA₆ (input/output)/TP₆ (output)/TIOCA₂ (input/output) PA₅ (input/output)/TP₅ (output)/TIOCB₁ (input/output) PA_{4} (input/output)/TP₄ (output)/TIOCA₁ (input/output) PA₃ (input/output)/TP₃ (output)/TIOCB₀ (input/output)/TCLKD (input) PA₂ (input/output)/TP₂ (output)/TIOCA₀ (input/output)/TCLKC (input)

PA₁ (input/output)/TP₁ (output)/TEND₁ (output)/TCLKB (input)

PA₀ (input/output)/TP₀ (output)/TEND₀ (output)/TCLKA (input)

Figure 9.10 Port A Pin Configuration

9.11.2 Register Descriptions

Table 9.18 summarizes the registers of port A.

Table 9.18 Port A Registers

				Initial Value			
Address*	Name	Abbreviation	R/W	Modes 1, 2, 5, and 7	Modes 3, 4, and 6		
H'FFD1	Port A data direction register	PADDR	W	H'00	H'80		
H'FFD3	Port A data register	PADR	R/W	H'00	H'00		

Note: * Lower 16 bits of the address.

Port A Data Direction Register (PADDR)

PADDR is an 8-bit write-only register that can select input or output for each pin in port A. When pins are used for TPC output, the corresponding PADDR bits must also be set.

Bit		7	6	5	4	3	2	1	0
		PA7DDR	PA ₆ DDR	PA ₅ DDR	PA ₄ DDR	PA ₃ DDR	PA ₂ DDR	PA ₁ DDR	PA ₀ DDR
Modes 3, 4,	Initial valu	ue 1	0	0	0	0	0	0	0
and 6	Read/Wri	te —	W	W	W	W	W	W	W
Modes 1, 2, 5, 4	∫ Initial valu	ue O	0	0	0	0	0	0	0
and 7	Read/Wri	te W	W	W	W	W	W	W	W

Port A data direction 7 to 0

These bits select input or output for port A pins

While port A acts as an I/O port, a pin in port A becomes an output pin if the corresponding PADDR bit is set to 1, and an input pin if this bit is cleared to 0. In modes 3, 4, and 6, PA₇DDR is fixed at 1 and PA₇ functions as an address output pin.

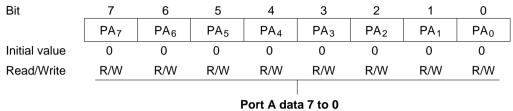
PADDR is a write-only register. Its value cannot be read. All bits return 1 when read.

PADDR is initialized to H'00 by a reset and in hardware standby mode in modes 1, 2, 5, and 7.

It is initialized to H'80 by a reset and in hardware standby mode in modes 3, 4, and 6. In software standby mode it retains its previous setting. If a PADDR bit is set to 1, the corresponding pin maintains its output state in software standby mode.

Port A Data Register (PADR)

PADR is an 8-bit readable/writable register that stores output data for pins PA₇ to PA₀. While port A acts as an output port, the value of this register is output. When a bit in PADDR is set to 1, if port A is read the value of the corresponding PADR bit is returned. When a bit in PADDR is cleared to 0, if port A is read the corresponding pin level is read.



These bits store data for port A pins

PADR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.



9.11.3 Pin Functions

Table 9.19 describes the selection of pin functions.

Table 9.19 Port A Pin Functions

Pin Pin Functions and Selection Method

PA₇/TP₇/ The mode setting, ITU channel 2 settings (bit PWM2 in TMDR and bits IOB2 to IOB0 in TIOCB₂/A₂₀ TIOR2), bit NDER7 in NDERA, and bit PA₇DDR in PADDR select the pin function as follows

Mode			3, 4, 6		
ITU channel 2 settings	(1) in table below	(2	_		
PA7DDR	_	0	1	1	_
NDER7	_	_	0	1	_
Pin function	TIOCB ₂	PA7 input	PA7 output	TP ₇ output	A ₂₀ output
	output				

Note: * TIOCB₂ input when IOB2 = 1 and PWM2 = 0.

ITU channel 2 settings	(2)	((2)	
IOB2		1		
IOB1	0	0	1	—
IOB0	0	1	—	_



Pin Pin Functions and Selection Method

PA₆/TP₆/

 $TIOCA_2/A_{21}/\overline{CS}_4$

The mode setting, bit $A_{21}E$ in BRCR, bit CS4E in CSCR, ITU channel 2 settings (bit PWM2 in TMDR and bits IOA2 to IOA0 in TIOR2), bit NDER6 in NDERA, and bit PA₆DDR in PADDR select the pin function as follows

Mode		1, 2, 5						3, 4	3, 4, 6				7		
CS4E		0			1			0			1	_			
A ₂₁ E					1 (0			_					
ITU channel 2 settings	(1) in table below) in tab below		_	(1) in (2) in table table below below				(1) in table below	table below				
PA ₆ DDR	_	0	1	1	_	_	0	1	1	I			0	1	1
NDER6	_		0	1	_	_	_	0	1	I		_	-	0	1
Pin function	TIOCA ₂ output	input	put	TP ₆ out- put	CS₄ out- put	TIOCA ₂ output	input	put	TP ₆ out- put	A ₂₁ out- put	CS₄ out- put	TIOCA ₂ output	input	PA ₆ out- put	TP ₆ out- put
		TIO	CA ₂ in	put*			TIOCA ₂ input*		TIOCA ₂ input*			TIO	CA ₂ in	put*	

Note: * TIOCA₂ input when IOA2 = 1.

ITU channel 2 settings	(2)	(*	1)	(2)	(1)			
PWM2		1						
IOA2		0						
IOA1	0	0	_	_				
IOA0	0	1	—	—	_			

Pin **Pin Functions and Selection Method**

PA₅/TP₅/ TIOCB₁/ A_{22}/\overline{CS}_5

The mode setting, bit A22E in BRCR, bit CS5E in CSCR, ITU channel 1 settings (bit PWM1 in TMDR and bits IOB2 to IOB0 in TIOR1), bit NDER5 in NDERA, and bit PA₅DDR in PADDR select the pin function as follows

Mode		1, 2, 5					3, 4, 6					7			
CS5E		0			1		0				1	_			
A ₂₂ E		_		_		1			0			_			
ITU channel 1 settings	(1) in table below	(2) in tab below	in table — elow		(1) in table below	ble below				(1) in (2) in table table below below				
PA₅DDR	_	0	1	1	_	_	0	1	1			_	0	1	1
NDER5	_	_	0	1	_	_	_	0	1			_	_	0	1
Pin function	TIOCB ₁ output	PA₅ input	put	TP₅ out- put	CS₅ out- put	TIOCB₁ output	input	put	TP₅ out- put	A ₂₂ out- put	CS₅ out- put	TIOCB ₁ output	PA₅ input	PA₅ out- put	TP₅ out- put
		TIO	CB ₁ in	put*			TIOCB ₁ input*					TIO	CB ₁ in	put*	

Note: * TIOCB₁ input when IOB2 = 1 and PWM1 = 0.

ITU channel 1 settings	(2)	(*	(2)					
IOB2		0						
IOB1	0	0	1	_				
IOB0	0	1	_	_				



PA4/TP4/

 $TIOCA_1/A_{23}/\overline{CS}_6$

The mode setting, bit $A_{23}E$ in BRCR, bit CS6E in CSCR, ITU channel 1 settings (bit PWM1 in TMDR and bits IOA2 to IOA0 in TIOR1), bit NDER4 in NDERA, and bit PA₄DDR in PADDR select the pin function as follows

Mode		1, 2, 5				3, 4, 6					7				
CS6E		0 1		1		0				1	_				
A ₂₃ E				_	1		0			_					
ITU channel 2 settings	(1) in table below) in tab below		_	(1) in (2) in table table below below		_	_	(1) in (2) in table table below below					
PA₄DDR		0	1	1	_	_	0	1	1	I		_	0	1	1
NDER4	I		0	1	_	_	_	0	1	I		_	-	0	1
Pin function	TIOCA ₁ output	input	put	TP₄ out- put	CS ₆ out- put	TIOCA ₁ output	input	put	TP₄ out- put	A ₂₃ out- put	CS ₆ out- put	TIOCA ₁ output	input	put	TP ₄ out- put
		TIO	CA ₁ in	put*			TIOCA ₁ input*					TIO	CA₁ in	put*	

Note: * TIOCA1 input when IOA2 = 1.

ITU channel 1 settings	(2)	(*	1)	(2)	(1)
PWM1		1			
IOA2		0		1	—
IOA1	0	0 0 1			_
IOA0	0	1	—	—	_

PA₃/TP₃/ITU channel 0 settings (bit PWM0 in TMDR and bits IOB2 to IOB0 in TIOR0), bitsTIOCB₀/TPSC2 to TPSC0 in TCR4 to TCR0, bit NDER3 in NDERA, and bit PA₃DDR in PADDRTCLKDselect the pin function as follows

ITU channel 0 settings	(1) in table below	(2) in table below						
PA₃DDR	—	- 0 1		1				
NDER3	_	— 0		1				
Pin function	TIOCB ₀ output	PA ₃ input PA ₃ output TP ₃ o		TP ₃ output				
		TIOCB ₀ input ^{*1}						
		TCLKD input ^{*2}						

Notes: 1. TIOCB₀ input when IOB2 = 1 and PWM0 = 0.

2. TCLKD input when TPSC2 = TPSC1 = TPSC0 = 1 in any of TCR4 to TCR0.

ITU channel 0 settings	(2)	(1)	(2)
IOB2	0			1
IOB1	0	0	1	—
IOB0	0	1	—	—



PA2/TP2/ITU channel 0 settings (bit PWM0 in TMDR and bits IOA2 to IOA0 in TIOR0), bitsTIOCA0/TPSC2 to TPSC0 in TCR4 to TCR0, bit NDER2 in NDERA, and bit PA2DDR in PADDRTCLKCselect the pin function as follows

ITU channel 0 settings	(1) in table below	(2) in table below						
PA ₂ DDR	—	0	1	1				
NDER2	_	_	0	1				
Pin function	IOCA ₀ output	PA ₂ input	PA ₂ output	TP ₂ output				
		TIOCA ₀ input ^{*1}						
	TCLKC input*2							

Notes: 1. TIOCA₀ input when IOA2 = 1.

2. TCLKC input when TPSC2 = TPSC1 = 1 and TPSC0 = 0 in any of TCR4 to TCR0.

ITU channel 0 settings	(2) (1)			(2)	(1)
PWM0		1			
IOA2		0			—
IOA1	0	0	1	—	—
IOA0	0	1			—

PA₁/TP₁/ DMAC channel 1 settings (bits DTS2/1/0A and DTS2/1/0B in DTCR1A and DTCR1B), TCLKB/ bit NDER1 in NDERA, and bit PA₁DDR in PADDR select the pin function as follows

TEND₁

DMAC channel 1 settings	(1) in table below	(2) in table below					
PA₁DDR	—	0	1	1			
NDER1	—	—	0	1			
Pin function	TEND ₁ output	PA ₁ input PA ₁ output		TP ₁ output			
	TCLKB input*						

Note: *TCLKB input when MDF = 1 in TMDR, or when TPSC2 = 1, TPSC1 = 0, and TPSC0 = 1 in any of TCR4 to TCR0.

DMAC channel 1 settings	(2) (1)			(2)	(1)	(2	(1)		
DTS2A, DTS1A	Not both 1			Both 1					
DTS0A		_		0	0	1	1	1	
DTS2B	0 1 1			0	1	0	1	1	
DTS1B	— 0 1			—	—	_	0	1	



PA₀/TP₀/ DMAC channel 0 settings (bits DTS2/1/0A and DTS2/1/0B in DTCR0A and DTCR0B), TCLKA/ bit NDER0 in NDERA, and bit PA₀DDR in PADDR select the pin function as follows

TEND0 DMAC (1) in table channel 0 below settings PA0DDR NDFR0 —

F

ootango								
PA₀DDR	_	0	1	1				
NDER0		_	0	1				
Pin function	TEND₀ output	PA ₀ input	PA ₀ output	TP ₀ output				
	TCLKA input*							

(2) in table

below

Note: * TCLKA input when MDF = 1 in TMDR, or when TPSC2 = 1 and TPSC1 = 0 in any of TCR4 to TCR0.

DMAC channel 0 settings	(2	2)	(1)	(2)	(1)	(2	2)	(1)	
DTS2A, DTS1A	Not both 1			Both 1					
DTS0A		—		0	0	1	1	1	
DTS2B	0 1 1			0	1	0	1	1	
DTS1B	— 0 1			—	—	—	0	1	

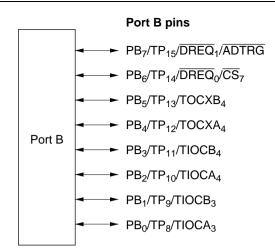
9.12 Port B

9.12.1 Overview

Port B is an 8-bit input/output port that is also used for output (TP₁₅ to TP₈) from the programmable timing pattern controller (TPC), input/output (TIOCB₄, TIOCB₃, TIOCA₄, TIOCA₃) and output (TOCXB₄, TOCXA₄) by the 16-bit integrated timer unit (ITU), input ($\overline{DREQ_1}$, $\overline{DREQ_0}$) to the DMA controller (DMAC), \overline{ADTRG} input to the A/D converter, and $\overline{CS_7}$ output. A reset or hardware standby leaves port B as an input port. For selecting the pin function, see table 9.21. Usage of pins for TPC, ITU, DMAC, and A/D converter input and output is described in the sections on those modules. For output of $\overline{CS_7}$ in modes 1 to 6, see section 6.3.2, Chip Select Signals. Pins not assigned to any of these functions are available for generic input/output. Figure 9.11 shows the pin configuration of port B.

Pins in port B can drive one TTL load and a 30-pF capacitive load. They can also drive an LED or darlington transistor pair. Pins PB_3 to PB_0 have Schmitt-trigger inputs.





Pin functions in modes 1 to 6

$$\label{eq:PB7} \begin{split} & \text{PB}_7 \ (\text{input/output})/\text{TP}_{15} \ (\text{output})/\overline{\text{DREQ}}_1 \ (\text{input})/\overline{\text{ADTRG}} \ (\text{input}) \\ & \text{PB}_6 \ (\text{input/output})/\text{TP}_{14} \ (\text{output})/\overline{\text{DREQ}}_0 \ (\text{input})/\overline{\text{CS}}_7 \ (\text{output}) \\ & \text{PB}_5 \ (\text{input/output})/\text{TP}_{13} \ (\text{output})/\text{TOCXB}_4 \ (\text{output}) \\ & \text{PB}_4 \ (\text{input/output})/\text{TP}_{12} \ (\text{output})/\text{TOCXA}_4 \ (\text{output}) \\ & \text{PB}_3 \ (\text{input/output})/\text{TP}_{11} \ (\text{output})/\text{TIOCB}_4 \ (\text{input/output}) \\ & \text{PB}_2 \ (\text{input/output})/\text{TP}_{10} \ (\text{output})/\text{TIOCA}_4 \ (\text{input/output}) \\ & \text{PB}_1 \ (\text{input/output})/\text{TP}_9 \ (\text{output})/\text{TIOCB}_3 \ (\text{input/output}) \\ & \text{PB}_0 \ (\text{input/output})/\text{TP}_8 \ (\text{output})/\text{TIOCA}_3 \ (\text{input/output}) \end{split}$$

Pin functions in mode 7

 $\label{eq:PB7} PB_7 (input/output)/TP_{15} (output)/\overline{DREQ}_1 (input)/\overline{ADTRG} (input) \\ PB_6 (input/output)/TP_{14} (output)/\overline{DREQ}_0 (input) \\ PB_5 (input/output)/TP_{13} (output)/TOCXB_4 (output) \\ PB_4 (input/output)/TP_{12} (output)/TOCXA_4 (output) \\ PB_3 (input/output)/TP_{11} (output)/TIOCB_4 (input/output) \\ PB_2 (input/output)/TP_{10} (output)/TIOCA_4 (input/output) \\ PB_1 (input/output)/TP_9 (output)/TIOCB_3 (input/output) \\ PB_0 (input/output)/TP_8 (output)/TIOCA_3 (input/output) \\ \end{tabular}$

Figure 9.11 Port B Pin Configuration

Renesas

9.12.2 Register Descriptions

Table 9.20 summarizes the registers of port B.

Table 9.20Port B Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFD4	Port B data direction register	PBDDR	W	H'00
H'FFD6	Port B data register	PBDR	R/W	H'00

Note: * Lower 16 bits of the address.

Port B Data Direction Register (PBDDR)

PBDDR is an 8-bit write-only register that can select input or output for each pin in port B. When pins are used for TPC output, the corresponding PBDDR bits must also be set.

Bit	7	6	5	4	3	2	1	0		
	PB7DDR	PB ₆ DDR	PB ₅ DDR	PB ₄ DDR	PB ₃ DDR	PB ₂ DDR	PB1 DDR	PB ₀ DDR		
Initial value	0	0	0	0	0	0	0	0		
Read/Write	W	W	W	W	W	W	W	W		

Port B data direction 7 to 0 These bits select input or output for port B pins

While port B acts as an I/O port, a pin in port B becomes an output pin if the corresponding PBDDR bit is set to 1, and an input pin if this bit is cleared to 0.

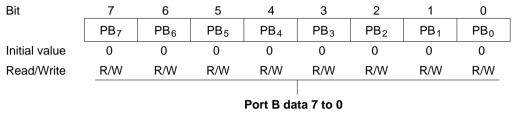
PBDDR is a write-only register. Its value cannot be read. All bits return 1 when read.

PBDDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting. If a PBDDR bit is set to 1 while port B acts as an I/O port, the corresponding pin maintains its output state in software standby mode.



Port B Data Register (PBDR)

PBDR is an 8-bit readable/writable register that stores output data for pins PB7 to PB0. While port B acts as an output port, the value of this register is output. When a bit in PBDDR is set to 1, if port B is read the value of the corresponding PBDR bit is returned. When a bit in PBDDR is cleared to 0, if port B is read the corresponding pin level is read.



These bits store data for port B pins

PBDR is initialized to H'00 by a reset and in hardware standby mode. In software standby mode it retains its previous setting.



9.12.3 Pin Functions

Table 9.21 describes the selection of pin functions.

Table 9.21Port B Pin Functions

Pin Pin Functions and Selection Method

PB7/TP15/DMAC channel 1 settings (bits DTS2/1/0A and DTS2/1/0B in DTCR1A and DTCR1B),DREQ1/bit TRGE in ADCR, bit NDER15 in NDERB, and bit PB7DDR in PBDDR select the pin
function as follows

PB7DDR	0	1	1
NDER15	—	0	1
Pin function	PB7 input	PB7 output	TP ₁₅ output
		DREQ ₁ input ^{*1}	
		ADTRG input*2	

Notes: 1. \overline{DREQ}_1 input under DMAC channel 1 settings (1) in the table below.

DMAC channel 1 settings	(2) (1)			(2)	(1)	(2	2)	(1)
DTS2A, DTS1A	Not both 1			Both 1				
DTS0A				0	0	1	1	1
DTS2B	0	0 1 1			1	0	1	1
DTS1B	_	0	1	_	_	_	0	1

2. $\overline{\text{ADTRG}}$ input when TRGE = 1.



CS₇

PB6/TP14/ Bit CS7E in CSCR. DMAC channel 0 settings (bits DTS2/1/0A and DTS2/1/0B in DTCR0A and DTCR0B), bit NDER14 in NDERB, and bit PB6DDR in PBDDR select the DREQ₀/ pin function as follows

PB ₆ DDR	0	1	1	—
CS7E	0	0	0	1
NDER14	—	0	1	—
Pin function	PB ₆ input	PB ₆ output	TP ₁₄ output	—
		DREQ ₀ input*		CS7 output

Note: * DREQ₀ input under DMAC channel 0 settings (1) in the table below.

DMAC channel 0 settings	(2	2)	(1)	(2)	(1)	(2	2)	(1)	
DTS2A, DTS1A	٢	Not both 1			Both 1				
DTS0A		_		0	0	1	1	1	
DTS2B	0	0 1 1			1	0	1	1	
DTS1B		0	1				0	1	

ITU channel 4 settings (bit CMD1 in TFCR and bit EXB4 in TOER), bit NDER13 in PB₅/TP₁₃/ NDERB, and bit PB₅DDR in PBDDR select the pin function as follows **TOCXB**₄

EXB4, CMD1		Both 1		
PB₅DDR	0	1	1	
NDER13	—	0	1	
Pin function	PB₅ input	PB ₅ output	TP ₁₃ output	TOCXB₄ output

 $PB_4/TP_{12}/$ ITU channel 4 settings (bit CMD1 in TFCR and bit EXA4 in TOER), bit NDER12 in TOCXA₄ NDERB, and bit PB4DDR in PBDDR select the pin function as follows

EXA4, CMD1		Both 1		
PB₄DDR	0	—		
NDER12	—	0	1	—
Pin function	PB₄ input	PB₄ output	TP ₁₂ output	TOCXA ₄ output

PB₃/TP₁₁/ ITU channel 4 settings (bit PWM4 in TMDR, bit CMD1 in TFCR, bit EB4 in TOER, and TIOCB₄ bits IOB2 to IOB0 in TIOR4), bit NDER11 in NDERB, and bit PB₃DDR in PBDDR select the pin function as follows

ITU channel 4 settings	(1) in table below	(2) in table below				
PB₃DDR	_	0	1	1		
NDER11	_	_	0	1		
Pin function	TIOCB ₄ output	PB ₃ input	PB ₃ output	TP ₁₁ output		
		TIOCB ₄ input*				

Note: * TIOCB₄ input when CMD1 = PWM4 = 0 and IOB2 = 1.

ITU channel 4 settings	(2)	(2)	(*	1)	(2)	(1)
EB4	0					
CMD1			0			
IOB2		0	0	0	1	—
IOB1		0	0	1	_	—
IOB0		0	1		_	—

PB2/TP10/
TIOCA4ITU channel 4 settings (bit CMD1 in TFCR, bit EA4 in TOER, bit PWM4 in TMDR, and
bits IOA2 to IOA0 in TIOR4), bit NDER10 in NDERB, and bit PB2DDR in PBDDR
select the pin function as follows

ITU channel 4 settings	(1) in table below	(2) in table below				
PB ₂ DDR	_	0	1	1		
NDER10			0	1		
Pin function	TIOCA₄ output	PB ₂ input	PB ₂ output	TP ₁₀ output		
		TIOCA₄ input*				

Note: * TIOCA₄ input when CMD1 = PWM4 = 0 and IOA2 = 1.

ITU channel 4 settings	(2)	(2)	1)						
EA4	0				1				
CMD1	_			0			1		
PWM4			()		1			
IOA2	_	0	0	0	1	_			
IOA1		0	0 0 1 — —						
IOA0		0	0 1 — — —						

PB₁/TP₉/ ITU channel 3 settings (bit PWM3 in TMDR, bit CMD1 in TFCR, bit EB3 in TOER, and TIOCB₃ bits IOB2 to IOB0 in TIOR3), bit NDER9 in NDERB, and bit PB₁DDR in PBDDR select the pin function as follows

ITU channel 3 settings	(1) in table below	(2) in table below				
PB₁DDR	_	0 1 1				
NDER9		_	0	1		
Pin function	TIOCB ₃ output	PB ₁ input	PB ₁ output	TP ₉ output		
		TIOCB ₃ input*				

Note: * TIOCB₃ input when CMD1 = PWM3 = 0 and IOB2 = 1.

ITU channel 3 settings	(2)	(2)	(*	1)	(2)	(1)
EB3	0					
CMD1				1		
IOB2	_	0	0	0	1	
IOB1		0	0	1	_	
IOB0		0	1		_	

PB_0/TP_8/ITU channel 3 settings (bit CMD1 in TFCR, bit EA3 in TOER, bit PWM3 in TMDR, and
bits IOA2 to IOA0 in TIOR3), bit NDER8 in NDERB, and bit PB_0DDR in PBDDR select
the pin function as follows

ITU channel 3 settings	(1) in table below	(2) in table below		
PB₀DDR		0	1	1
NDER8			0	1
Pin function	TIOCA ₃ output	PB ₀ input	PB ₀ output	TP ₈ output
		TIOCA ₃ input*		

Note: * TIOCA₃ input when CMD1 = PWM3 = 0 and IOA2 = 1.

ITU channel 3 settings	(2)	(2)	(*	1)	(2)	(*	1)
EA3	0		1				
CMD1	_			0			1
PWM3			0 1				
IOA2	_	0	0	0	1		
IOA1	_	0	0	1		_	
IOA0	_	0	1	—		-	—

Renesas



Section 10 16-Bit Integrated Timer Unit (ITU)

10.1 Overview

The H8/3048 Group has a built-in 16-bit integrated timer unit (ITU) with five 16-bit timer channels.

When the ITU is not used, it can be independently halted to conserve power. For details see section 21.6, Module Standby Function.

10.1.1 Features

ITU features are listed below.

- Capability to process up to 12 pulse outputs or 10 pulse inputs
- Ten general registers (GRs, two per channel) with independently-assignable output compare or input capture functions
- Selection of eight counter clock sources for each channel: Internal clocks: φ, φ/2, φ/4, φ/8 External clocks: TCLKA, TCLKB, TCLKC, TCLKD
- Five operating modes selectable in all channels:
 - Waveform output by compare match
 - Selection of 0 output, 1 output, or toggle output (only 0 or 1 output in channel 2)
 - Input capture function
 - Rising edge, falling edge, or both edges (selectable)
 - Counter clearing function
 - Counters can be cleared by compare match or input capture
 - Synchronization

Two or more timer counters (TCNTs) can be preset simultaneously, or cleared simultaneously by compare match or input capture. Counter synchronization enables synchronous register input and output.

— PWM mode

PWM output can be provided with an arbitrary duty cycle. With synchronization, up to five-phase PWM output is possible

• Phase counting mode selectable in channel 2

Two-phase encoder output can be counted automatically.

Renesas

- Three additional modes selectable in channels 3 and 4
 - Reset-synchronized PWM mode

If channels 3 and 4 are combined, three-phase PWM output is possible with three pairs of complementary waveforms.

- Complementary PWM mode

If channels 3 and 4 are combined, three-phase PWM output is possible with three pairs of non-overlapping complementary waveforms.

— Buffering

Input capture registers can be double-buffered. Output compare registers can be updated automatically.

• High-speed access via internal 16-bit bus

The 16-bit timer counters, general registers, and buffer registers can be accessed at high speed via a 16-bit bus.

• Fifteen interrupt sources

Each channel has two compare match/input capture interrupts and an overflow interrupt. All interrupts can be requested independently.

- Activation of DMA controller (DMAC) Four of the compare match/input capture interrupts from channels 0 to 3 can start the DMAC.
- Output triggering of programmable timing pattern controller (TPC) Compare match/input capture signals from channels 0 to 3 can be used as TPC output triggers.



Table 10.1 summarizes the ITU functions.

Item		Channel 0	Channel 1	Channel 2	Channel 3	Channel 4
Clock sources		Internal clocks:	þ, φ/2, φ/4, φ/8			
		External clocks:	TCLKA, TCLKB,	TCLKC, TCLKD,	, selectable indep	endently
General registers (output compare/i capture registers)	nput	GRA0, GRB0	GRA1, GRB1	GRA2, GRB2	GRA3, GRB3	GRA4, GRB4
Buffer registers		—	_	—	BRA3, BRB3	BRA4, BRB4
Input/output pins		TIOCA ₀ , TIOCB ₀	TIOCA ₁ , TIOCB ₁	TIOCA ₂ , TIOCB ₂	TIOCA ₃ , TIOCB ₃	TIOCA ₄ , TIOCB ₄
Output pins		_	_	—	_	TOCXA ₄ , TOCXB ₄
Counter clearing t	function	•		GRA2/GRB2 compare match or input capture	•	•
Compare match	0	0	0	0	0	0
output	1	0	0	0	0	0
	Toggle	0	0	_	0	0
Input capture fund	ction	0	0	0	0	0
Synchronization		0	0	0	0	0
PWM mode		0	0	0	0	0
Reset-synchroniz PWM mode	ed	_	_	_	0	0
Complementary F mode	PWM	_	_	_	0	0
Phase counting m	node	_	_	0	—	_
Buffering		_	_	_	0	0
DMAC activation		GRA0 compare match or input capture	GRA1 compare match or input capture	GRA2 compare match or input capture	GRA3 compare match or input capture	_
Interrupt sources		Three sources				
		 Compare match/input capture A0 Compare 	 Compare match/input capture A1 Compare 	 Compare match/input capture A2 Compare 	 Compare match/input capture A3 Compare 	 Compare match/input capture A4 Compare
		match/input capture B0	match/input capture B1	 Compare match/input capture B2 	•	match/input capture B4
Legend		Overflow	• Overflow	Overflow	• Overflow	• Overflow

Table 10.1 ITU Functions

Legend

o: Available

-: Not available

10.1.2 Block Diagrams

ITU Block Diagram (Overall): Figure 10.1 is a block diagram of the ITU.

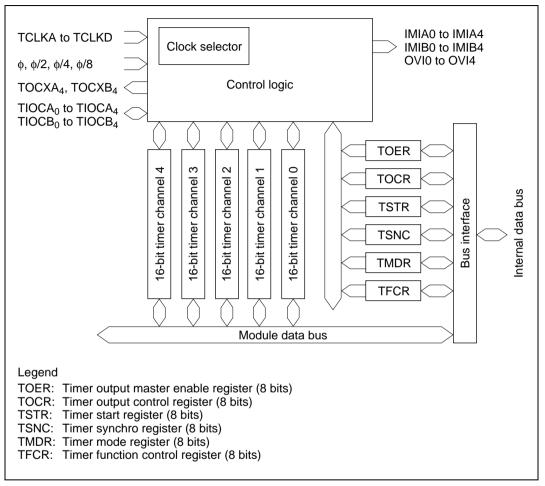


Figure 10.1 ITU Block Diagram (Overall)

Block Diagram of Channels 0 and 1: ITU channels 0 and 1 are functionally identical. Both have the structure shown in figure 10.2.

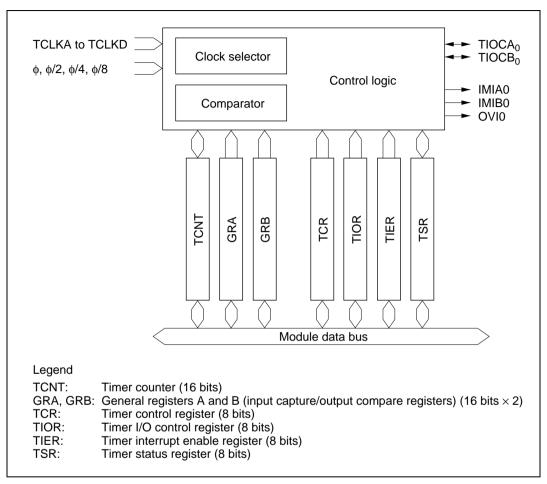


Figure 10.2 Block Diagram of Channels 0 and 1 (for Channel 0)

Block Diagram of Channel 2: Figure 10.3 is a block diagram of channel 2. This is the channel that provides only 0 output and 1 output.

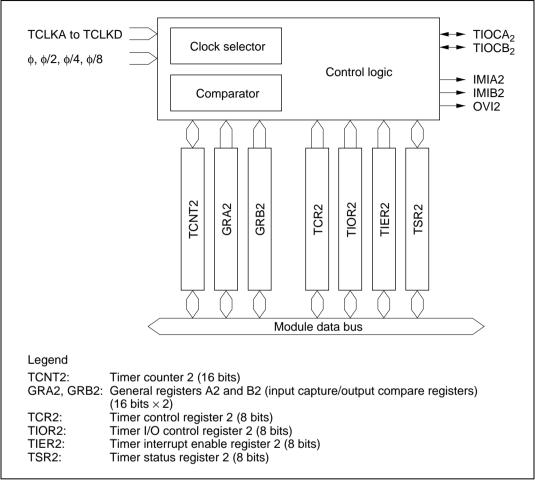


Figure 10.3 Block Diagram of Channel 2

Block Diagrams of Channels 3 and 4: Figure 10.4 is a block diagram of channel 3. Figure 10.5 is a block diagram of channel 4.

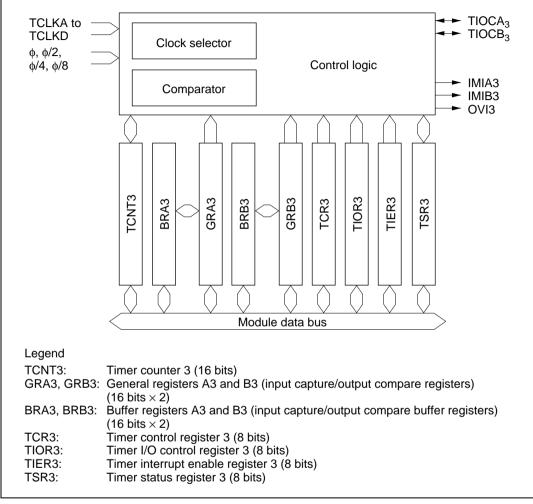


Figure 10.4 Block Diagram of Channel 3

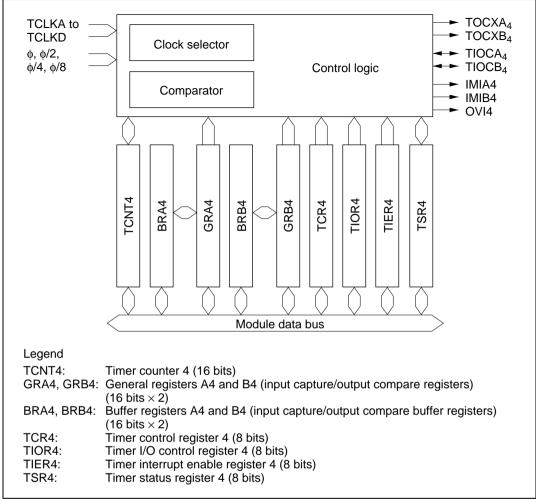


Figure 10.5 Block Diagram of Channel 4



10.1.3 Input/Output Pins

Table 10.2 summarizes the ITU pins.

Table 10.2 ITU Pins

Channel	Name	Abbre- viation	Input/ Output	Function
Common	Clock input A	TCLKA	Input	External clock A input pin (phase-A input pin in phase counting mode)
	Clock input B	TCLKB	Input	External clock B input pin (phase-B input pin in phase counting mode)
	Clock input C	TCLKC	Input	External clock C input pin
	Clock input D	TCLKD	Input	External clock D input pin
0	Input capture/output compare A0	TIOCA ₀	Input/ output	GRA0 output compare or input capture pin PWM output pin in PWM mode
	Input capture/output compare B0	TIOCB₀	Input/ output	GRB0 output compare or input capture pin
1	Input capture/output compare A1	TIOCA ₁	Input/ output	GRA1 output compare or input capture pin PWM output pin in PWM mode
	Input capture/output compare B1	TIOCB ₁	Input/ output	GRB1 output compare or input capture pin
2	Input capture/output compare A2	TIOCA ₂	Input/ output	GRA2 output compare or input capture pin PWM output pin in PWM mode
	Input capture/output compare B2	TIOCB ₂	Input/ output	GRB2 output compare or input capture pin
3	Input capture/output compare A3	TIOCA ₃	Input/ output	GRA3 output compare or input capture pin PWM output pin in PWM mode,
	Input capture/output compare B3	TIOCB ₃	Input/ output	GRB3 output compare or input capture pin PWM output pin in complementary PWM
4	Input capture/output compare A4	TIOCA ₄	Input/ output	GRA4 output compare or input capture pin PWM output pin in PWM mode,
	Input capture/output compare B4	TIOCB ₄	Input/ output	GRB4 output compare or input capture pin PWM output pin in complementary PWM
	Output compare XA4	TOCXA ₄	Output	PWM output pin in complementary PWM mode or reset-synchronized PWM mode
	Output compare XB4	TOCXB ₄	Output	PWM output pin in complementary PWM mode or reset-synchronized PWM mode

10.1.4 Register Configuration

Table 10.3 summarizes the ITU registers.

Table 10.3 ITU Registers

Channel	Address* ¹	Name	Abbre- viation	R/W	Initial Value
Common	H'FF60	Timer start register	TSTR	R/W	H'E0
	H'FF61	Timer synchro register	TSNC	R/W	H'E0
	H'FF62	Timer mode register	TMDR	R/W	H'80
	H'FF63	Timer function control register	TFCR	R/W	H'C0
	H'FF90	Timer output master enable register	TOER	R/W	H'FF
	H'FF91	Timer output control register	TOCR	R/W	H'FF
0	H'FF64	Timer control register 0	TCR0	R/W	H'80
	H'FF65	Timer I/O control register 0	TIOR0	R/W	H'88
	H'FF66	Timer interrupt enable register 0	TIER0	R/W	H'F8
	H'FF67	Timer status register 0	TSR0	R/(W)*2	H'F8
	H'FF68	Timer counter 0 (high)	TCNT0H	R/W	H'00
	H'FF69	Timer counter 0 (low)	TCNT0L	R/W	H'00
	H'FF6A	General register A0 (high)	GRA0H	R/W	H'FF
	H'FF6B	General register A0 (low)	GRA0L	R/W	H'FF
	H'FF6C	General register B0 (high)	GRB0H	R/W	H'FF
	H'FF6D	General register B0 (low)	GRB0L	R/W	H'FF
1	H'FF6E	Timer control register 1	TCR1	R/W	H'80
	H'FF6F	Timer I/O control register 1	TIOR1	R/W	H'88
	H'FF70	Timer interrupt enable register 1	TIER1	R/W	H'F8
	H'FF71	Timer status register 1	TSR1	R/(W)* ²	H'F8
	H'FF72	Timer counter 1 (high)	TCNT1H	R/W	H'00
	H'FF73	Timer counter 1 (low)	TCNT1L	R/W	H'00
	H'FF74	General register A1 (high)	GRA1H	R/W	H'FF
	H'FF75	General register A1 (low)	GRA1L	R/W	H'FF
	H'FF76	General register B1 (high)	GRB1H	R/W	H'FF
	H'FF77	General register B1 (low)	GRB1L	R/W	H'FF

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Channel	Address*1	Name	Abbre- viation	R/W	Initial Value
2	H'FF78	Timer control register 2	TCR2	R/W	H'80
	H'FF79	Timer I/O control register 2	TIOR2	R/W	H'88
	H'FF7A	Timer interrupt enable register 2	TIER2	R/W	H'F8
	H'FF7B	Timer status register 2	TSR2	R/(W)* ²	H'F8
	H'FF7C	Timer counter 2 (high)	TCNT2H	R/W	H'00
	H'FF7D	Timer counter 2 (low)	TCNT2L	R/W	H'00
	H'FF7E	General register A2 (high)	GRA2H	R/W	H'FF
	H'FF7F	General register A2 (low)	GRA2L	R/W	H'FF
	H'FF80	General register B2 (high)	GRB2H	R/W	H'FF
	H'FF81	General register B2 (low)	GRB2L	R/W	H'FF
3	H'FF82	Timer control register 3	TCR3	R/W	H'80
	H'FF83	Timer I/O control register 3	TIOR3	R/W	H'88
	H'FF84	Timer interrupt enable register 3	TIER3	R/W	H'F8
	H'FF85	Timer status register 3	TSR3	R/(W)*2	H'F8
	H'FF86	Timer counter 3 (high)	TCNT3H	R/W	H'00
	H'FF87	Timer counter 3 (low)	TCNT3L	R/W	H'00
	H'FF88	General register A3 (high)	GRA3H	R/W	H'FF
	H'FF89	General register A3 (low)	GRA3L	R/W	H'FF
	H'FF8A	General register B3 (high)	GRB3H	R/W	H'FF
	H'FF8B	General register B3 (low)	GRB3L	R/W	H'FF
	H'FF8C	Buffer register A3 (high)	BRA3H	R/W	H'FF
	H'FF8D	Buffer register A3 (low)	BRA3L	R/W	H'FF
	H'FF8E	Buffer register B3 (high)	BRB3H	R/W	H'FF
	H'FF8F	Buffer register B3 (low)	BRB3L	R/W	H'FF

Channel	Address ^{*1}	Name	Abbre- viation	R/W	Initial Value
4	H'FF92	Timer control register 4	TCR4	R/W	H'80
	H'FF93	Timer I/O control register 4	TIOR4	R/W	H'88
	H'FF94	Timer interrupt enable register 4	TIER4	R/W	H'F8
	H'FF95	Timer status register 4	TSR4	R/(W)* ²	H'F8
	H'FF96	Timer counter 4 (high)	TCNT4H	R/W	H'00
	H'FF97	Timer counter 4 (low)	TCNT4L	R/W	H'00
	H'FF98	General register A4 (high)	GRA4H	R/W	H'FF
	H'FF99	General register A4 (low)	GRA4L	R/W	H'FF
	H'FF9A	General register B4 (high)	GRB4H	R/W	H'FF
	H'FF9B	General register B4 (low)	GRB4L	R/W	H'FF
	H'FF9C	Buffer register A4 (high)	BRA4H	R/W	H'FF
	H'FF9D	Buffer register A4 (low)	BRA4L	R/W	H'FF
	H'FF9E	Buffer register B4 (high)	BRB4H	R/W	H'FF
	H'FF9F	Buffer register B4 (low)	BRB4L	R/W	H'FF

Notes: 1. Lower 16 bits of the address.

2. Only 0 can be written, to clear flags.



10.2 Register Descriptions

10.2.1 Timer Start Register (TSTR)

TSTR is an 8-bit readable/writable register that starts and stops the timer counter (TCNT) in channels 0 to 4.

Bit	7	6	5	4	3	2	1	0
	—		—	STR4	STR3	STR2	STR1	STR0
Initial value	1	1	1	0	0	0	0	0
Read/Write	—	—	—	R/W	R/W	R/W	R/W	R/W
	Reserved bits			Thes	n ter start e bits start TCNT4 to	and		

TSTR is initialized to H'E0 by a reset and in standby mode.

Bits 7 to 5—Reserved: Read-only bits, always read as 1.

Bit 4—Counter Start 4 (STR4): Starts and stops timer counter 4 (TCNT4).

Bit 4: STR4	Description	
0	TCNT4 is halted	(Initial value)
1	TCNT4 is counting	

Bit 3—Counter Start 3 (STR3): Starts and stops timer counter 3 (TCNT3).

Bit 3: STR3	Description	
0	TCNT3 is halted	(Initial value)
1	TCNT3 is counting	

Bit 2—Counter Start 2 (STR2): Starts and stops timer counter 2 (TCNT2).

Bit 2: STR2	Description	
0	TCNT2 is halted	(Initial value)
1	TCNT2 is counting	

Bit 1—Counter Start 1 (STR1): Starts and stops timer counter 1 (TCNT1).

Bit 1: STR1	Description	
0	TCNT1 is halted	(Initial value)
1	TCNT1 is counting	

Bit 0—Counter Start 0 (STR0): Starts and stops timer counter 0 (TCNT0).

Bit 0: STR0	Description	
0	TCNT0 is halted	(Initial value)
1	TCNT0 is counting	

10.2.2 Timer Synchro Register (TSNC)

TSNC is an 8-bit readable/writable register that selects whether channels 0 to 4 operate independently or synchronously. Channels are synchronized by setting the corresponding bits to 1.

Bit	7	6	5	4	3	2	1	0
	—		—	SYNC4	SYNC3	SYNC2	SYNC1	SYNC0
Initial value	1	1	1	0	0	0	0	0
Read/Write	_	_	_	R/W	R/W	R/W	R/W	R/W
	F	Reserved I	bits		Time	r sync 4 t	o 0	
					Thes	e bits synd	chronize	
					chan	nels 4 to 0		

TSNC is initialized to H'E0 by a reset and in standby mode.

Bits 7 to 5—Reserved: Read-only bits, always read as 1.

Bit 4—Timer Sync 4 (SYNC4): Selects whether channel 4 operates independently or synchronously.

Bit 4: SYNC4	Description	
0	Channel 4's timer counter (TCNT4) operates independently (Initial value	
	TCNT4 is preset and cleared independently of other channels	
1	Channel 4 operates synchronously	
	TCNT4 can be synchronously preset and cleared	

Bit 3—Timer Sync 3 (SYNC3): Selects whether channel 3 operates independently or synchronously.

Bit 3: SYNC3	Description		
0	Channel 3's timer counter (TCNT3) operates independently (Initial va		
	TCNT3 is preset and cleared independently of other channels		
1	Channel 3 operates synchronously		
	TCNT3 can be synchronously preset and cleared		

Bit 2—Timer Sync 2 (SYNC2): Selects whether channel 2 operates independently or synchronously.

Bit 2: SYNC2	Description	
0	Channel 2's timer counter (TCNT2) operates independently	(Initial value)
	TCNT2 is preset and cleared independently of other channels	
1	Channel 2 operates synchronously	
	TCNT2 can be synchronously preset and cleared	

Bit 1—Timer Sync 1 (SYNC1): Selects whether channel 1 operates independently or synchronously.

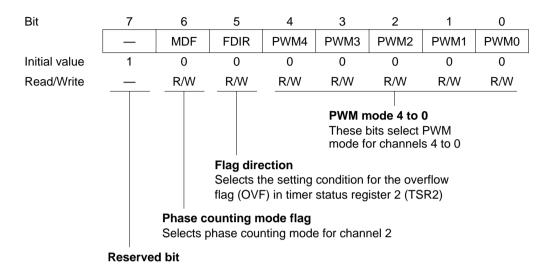
Bit 1: SYNC1	Description	
0	Channel 1's timer counter (TCNT1) operates independently (Initial value)	
	TCNT1 is preset and cleared independently of other channels	
1	Channel 1 operates synchronously	
	TCNT1 can be synchronously preset and cleared	

Bit 0—Timer Sync 0 (SYNC0): Selects whether channel 0 operates independently or synchronously.

Bit 0: Bit 0	Description				
0	Channel 0's timer counter (TCNT0) operates independently (Initial val				
	TCNT0 is preset and cleared independently of other channels				
1	Channel 0 operates synchronously				
	TCNT0 can be synchronously preset and cleared				

10.2.3 Timer Mode Register (TMDR)

TMDR is an 8-bit readable/writable register that selects PWM mode for channels 0 to 4. It also selects phase counting mode and the overflow flag (OVF) setting conditions for channel 2.



TMDR is initialized to H'80 by a reset and in standby mode.

Bit 7—Reserved: Read-only bit, always read as 1.

Bit 6—Phase Counting Mode Flag (MDF): Selects whether channel 2 operates normally or in phase counting mode.

Bit 6: MDF	Description	
0	Channel 2 operates normally	(Initial value)
1	Channel 2 operates in phase counting mode	



When MDF is set to 1 to select phase counting mode, TCNT2 operates as an up/down-counter and pins TCLKA and TCLKB become counter clock input pins. TCNT2 counts both rising and falling edges of TCLKA and TCLKB, and counts up or down as follows.

Counting Direction	Down-	Counting	I		Up-Co	unting		
TCLKA pin	Ŷ	High	\downarrow	Low	Ŷ	Low	\downarrow	High
TCLKB pin	Low	\uparrow	High	\downarrow	High	\downarrow	Low	\downarrow

In phase counting mode channel 2 operates as above regardless of the external clock edges selected by bits CKEG1 and CKEG0 and the clock source selected by bits TPSC2 to TPSC0 in TCR2. Phase counting mode takes precedence over these settings.

The counter clearing condition selected by the CCLR1 and CCLR0 bits in TCR2 and the compare match/input capture settings and interrupt functions of TIOR2, TIER2, and TSR2 remain effective in phase counting mode.

Bit 5—Flag Direction (FDIR): Designates the setting condition for the OVF flag in TSR2. The FDIR designation is valid in all modes in channel 2.

Bit 5: FDIR	Description	
0	OVF is set to 1 in TSR2 when TCNT2 overflows or underflows	(Initial value)
1	OVF is set to 1 in TSR2 when TCNT2 overflows	

Bit 4—PWM Mode 4 (PWM4): Selects whether channel 4 operates normally or in PWM mode.

Bit 4: PWM4	Description	
0	Channel 4 operates normally	(Initial value)
1	Channel 4 operates in PWM mode	

When bit PWM4 is set to 1 to select PWM mode, pin TIOCA₄ becomes a PWM output pin. The output goes to 1 at compare match with GRA4, and to 0 at compare match with GRB4.

If complementary PWM mode or reset-synchronized PWM mode is selected by bits CMD1 and CMD0 in TFCR, the CMD1 and CMD0 setting takes precedence and the PWM4 setting is ignored.

Renesas

Bit 3—PWM Mode 3 (PWM3): Selects whether channel 3 operates normally or in PWM mode.

Bit 3: PWM3	Description	
0	Channel 3 operates normally	(Initial value)
1	Channel 3 operates in PWM mode	

When bit PWM3 is set to 1 to select PWM mode, pin TIOCA₃ becomes a PWM output pin. The output goes to 1 at compare match with GRA3, and to 0 at compare match with GRB3.

If complementary PWM mode or reset-synchronized PWM mode is selected by bits CMD1 and CMD0 in TFCR, the CMD1 and CMD0 setting takes precedence and the PWM3 setting is ignored.

Bit 2—PWM Mode 2 (PWM2): Selects whether channel 2 operates normally or in PWM mode.

Bit 2: PWM2	Description	
0	Channel 2 operates normally	(Initial value)
1	Channel 2 operates in PWM mode	

When bit PWM2 is set to 1 to select PWM mode, pin $TIOCA_2$ becomes a PWM output pin. The output goes to 1 at compare match with GRA2, and to 0 at compare match with GRB2.

Bit 1—PWM Mode 1 (PWM1): Selects whether channel 1 operates normally or in PWM mode.

Bit 1: PWM1	Description	
0	Channel 1 operates normally	(Initial value)
1	Channel 1 operates in PWM mode	

When bit PWM1 is set to 1 to select PWM mode, pin TIOCA₁ becomes a PWM output pin. The output goes to 1 at compare match with GRA1, and to 0 at compare match with GRB1.

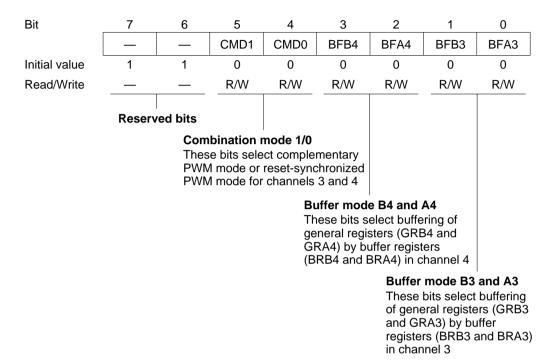
Bit 0—PWM Mode 0 (PWM0): Selects whether channel 0 operates normally or in PWM mode.

Bit 0: PWM0	Description	
0	Channel 0 operates normally	(Initial value)
1	Channel 0 operates in PWM mode	

When bit PWM0 is set to 1 to select PWM mode, pin $TIOCA_0$ becomes a PWM output pin. The output goes to 1 at compare match with GRA0, and to 0 at compare match with GRB0.

10.2.4 Timer Function Control Register (TFCR)

TFCR is an 8-bit readable/writable register that selects complementary PWM mode, resetsynchronized PWM mode, and buffering for channels 3 and 4.



TFCR is initialized to H'C0 by a reset and in standby mode.

Bits 7 and 6—Reserved: Read-only bits, always read as 1.

Bits 5 and 4—Combination Mode 1 and 0 (CMD1, CMD0): These bits select whether channels 3 and 4 operate in normal mode, complementary PWM mode, or reset-synchronized PWM mode.

Bit 5: CMD1	Bit 4: CMD0	Description	
0	0	Channels 3 and 4 operate normally	(Initial value)
	1		
1	0	Channels 3 and 4 operate together in co PWM mode	mplementary
	1	Channels 3 and 4 operate together in re- PWM mode	set-synchronized

Renesas

Before selecting reset-synchronized PWM mode or complementary PWM mode, halt the timer counter or counters that will be used in these modes.

When these bits select complementary PWM mode or reset-synchronized PWM mode, they take precedence over the setting of the PWM mode bits (PWM4 and PWM3) in TMDR. Settings of complementary PWM mode or reset-synchronized PWM mode and settings of timer sync bits SYNC4 and SYNC3 in TSNC are valid simultaneously, however, when complementary PWM mode is selected, channels 3 and 4 must not be synchronized (do not set bits SYNC3 and SYNC4 both to 1 in TSNC).

Bit 3—Buffer Mode B4 (BFB4): Selects whether GRB4 operates normally in channel 4, or whether GRB4 is buffered by BRB4.

Bit 3: BFB4	Description	
0	GRB4 operates normally	(Initial value)
1	GRB4 is buffered by BRB4	

Bit 2—Buffer Mode A4 (BFA4): Selects whether GRA4 operates normally in channel 4, or whether GRA4 is buffered by BRA4.

Bit 2: BFA4	Description	
0	GRA4 operates normally	(Initial value)
1	GRA4 is buffered by BRA4	

Bit 1—Buffer Mode B3 (BFB3): Selects whether GRB3 operates normally in channel 3, or whether GRB3 is buffered by BRB3.

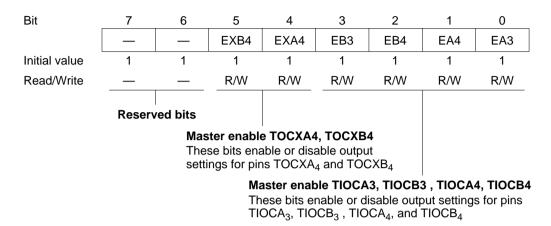
Bit 1: BFB3	Description	
0	GRB3 operates normally	(Initial value)
1	GRB3 is buffered by BRB3	

Bit 0—Buffer Mode A3 (BFA3): Selects whether GRA3 operates normally in channel 3, or whether GRA3 is buffered by BRA3.

Bit 0: BFA3	Description	
0	GRA3 operates normally	(Initial value)
1	GRA3 is buffered by BRA3	

10.2.5 Timer Output Master Enable Register (TOER)

TOER is an 8-bit readable/writable register that enables or disables output settings for channels 3 and 4.



TOER is initialized to H'FF by a reset and in standby mode.

Bits 7 and 6—Reserved: Read-only bits, always read as 1.

Bit 5-Master Enable TOCXB4 (EXB4): Enables or disables ITU output at pin TOCXB4.

Bit 5: EXB4	Description	
0	TOCXB ₄ output is disabled regardless of TFCR settings (TOCXB ₄ operates as a generic input/output pin).	
	If XTGD = 0, EXB4 is cleared to 0 when input capture A occurs in	n channel 1.
1	TOCXB ₄ is enabled for output according to TFCR settings	(Initial value)

Bit 4-Master Enable TOCXA4 (EXA4): Enables or disables ITU output at pin TOCXA4.

Bit 4: EXA4	Description	
0	TOCXA ₄ output is disabled regardless of TFCR settings (TOCXA ₄ operates as a generic input/output pin).	
	If XTGD = 0, EXA4 is cleared to 0 when input capture A occurs in	n channel 1.
1	TOCXA ₄ is enabled for output according to TFCR settings	(Initial value)

Renesas

Bit 3—Master Enable TIOCB3 (EB3): Enables or disables ITU output at pin TIOCB₃.

Bit 3: EB3	Description	
0	TIOCB ₃ output is disabled regardless of TIOR3 and TFCR settings (TIOCB ₃ operates as a generic input/output pin).	
	If XTGD = 0, EB3 is cleared to 0 when input capture A occurs in channel 1.	
1	TIOCB ₃ is enabled for output according to TIOR3 and TFCR settings (Initial value)	

Bit 2-Master Enable TIOCB4 (EB4): Enables or disables ITU output at pin TIOCB4.

Description
TIOCB ₄ output is disabled regardless of TIOR4 and TFCR settings (TIOCB ₄ operates as a generic input/output pin).
If XTGD = 0, EB4 is cleared to 0 when input capture A occurs in channel 1.
TIOCB ₄ is enabled for output according to TIOR4 and TFCR settings (Initial value)

Bit 1-Master Enable TIOCA4 (EA4): Enables or disables ITU output at pin TIOCA4.

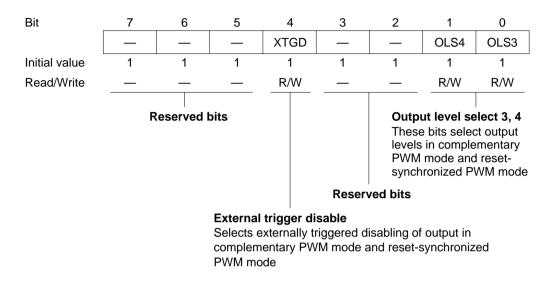
Bit 1: EA4	Description
0	TIOCA ₄ output is disabled regardless of TIOR4, TMDR, and TFCR settings (TIOCA ₄ operates as a generic input/output pin).
	If XTGD = 0, EA4 is cleared to 0 when input capture A occurs in channel 1.
1	TIOCA ₄ is enabled for output according to TIOR4, TMDR, and TFCR settings (Initial value)

Bit 0-Master Enable TIOCA3 (EA3): Enables or disables ITU output at pin TIOCA3.

Bit 0: EA3	Description
0	TIOCA ₃ output is disabled regardless of TIOR3, TMDR, and TFCR settings (TIOCA ₃ operates as a generic input/output pin).
	If XTGD = 0, EA3 is cleared to 0 when input capture A occurs in channel 1.
1	TIOCA ₃ is enabled for output according to TIOR3, TMDR, and TFCR settings (Initial value)

10.2.6 Timer Output Control Register (TOCR)

TOCR is an 8-bit readable/writable register that selects externally triggered disabling of output in complementary PWM mode and reset-synchronized PWM mode, and inverts the output levels.



The settings of the XTGD, OLS4, and OLS3 bits are valid only in complementary PWM mode and reset-synchronized PWM mode. These settings do not affect other modes.

TOCR is initialized to H'FF by a reset and in standby mode.

Bits 7 to 5—Reserved: Read-only bits, always read as 1.

Bit 4—External Trigger Disable (XTGD): Selects externally triggered disabling of ITU output in complementary PWM mode and reset-synchronized PWM mode.

Bit 4: XTGD	Description						
0		Input capture A in channel 1 is used as an external trigger signal in complementary PWM mode and reset-synchronized PWM mode.					
	When an external trigger occurs, bits 5 to 0 in TOER are clear ITU output.	red to 0, disabling					
1	External triggering is disabled	(Initial value)					

Bits 3 and 2—Reserved: Read-only bits, always read as 1.

Bit 1—Output Level Select 4 (OLS4): Selects output levels in complementary PWM mode and reset-synchronized PWM mode.

Bit 1: OLS4	Description	
0	TIOCA ₃ , TIOCA ₄ , and TIOCB ₄ outputs are inverted	
1	TIOCA ₃ , TIOCA ₄ , and TIOCB ₄ outputs are not inverted	(Initial value)

Bit 0—Output Level Select 3 (OLS3): Selects output levels in complementary PWM mode and reset-synchronized PWM mode.

Bit 0: OLS3	Description	
0	TIOCB ₃ , TOCXA ₄ , and TOCXB ₄ outputs are inverted	
1	TIOCB ₃ , TOCXA ₄ , and TOCXB ₄ outputs are not inverted	(Initial value)

10.2.7 Timer Counters (TCNT)

Channel	Abbreviation	Function
0	TCNT0	Up-counter
1	TCNT1	
2	TCNT2	Phase counting mode: up/down-counter
		Other modes: up-counter
3	TCNT3	Complementary PWM mode: up/down-counter
4	TCNT4	Other modes: up-counter

TCNT is a 16-bit counter. The ITU has five TCNTs, one for each channel.

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W															

Each TCNT is a 16-bit readable/writable register that counts pulse inputs from a clock source. The clock source is selected by bits TPSC2 to TPSC0 in TCR.

TCNT0 and TCNT1 are up-counters. TCNT2 is an up/down-counter in phase counting mode and an up-counter in other modes. TCNT3 and TCNT4 are up/down-counters in complementary PWM mode and up-counters in other modes.

TCNT can be cleared to H'0000 by compare match with GRA or GRB or by input capture to GRA or GRB (counter clearing function) in the same channel.

When TCNT overflows (changes from H'FFFF to H'0000), the OVF flag is set to 1 in TSR of the corresponding channel.

When TCNT underflows (changes from H'0000 to H'FFFF), the OVF flag is set to 1 in TSR of the corresponding channel.

The TCNTs are linked to the CPU by an internal 16-bit bus and can be written or read by either word access or byte access.

Each TCNT is initialized to H'0000 by a reset and in standby mode.

10.2.8 General Registers (GRA, GRB)

The general registers are 16-bit registers. The ITU has 10 general registers, two in each channel.

Channel	Abbreviation	Function
0	GRA0, GRB0	Output compare/input capture register
1	GRA1, GRB1	
2	GRA2, GRB2	
3	GRA3, GRB3	Output compare/input capture register; can be buffered by
4	GRA4, GRB4	buffer registers BRA and BRB

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W															

A general register is a 16-bit readable/writable register that can function as either an output compare register or an input capture register. The function is selected by settings in TIOR.

When a general register is used as an output compare register, its value is constantly compared with the TCNT value. When the two values match (compare match), the IMFA or IMFB flag is set to 1 in TSR. Compare match output can be selected in TIOR.

When a general register is used as an input capture register, rising edges, falling edges, or both edges of an external input capture signal are detected and the current TCNT value is stored in the

general register. The corresponding IMFA or IMFB flag in TSR is set to 1 at the same time. The valid edge or edges of the input capture signal are selected in TIOR.

TIOR settings are ignored in PWM mode, complementary PWM mode, and reset-synchronized PWM mode.

General registers are linked to the CPU by an internal 16-bit bus and can be written or read by either word access or byte access.

General registers are initialized to the output compare function (with no output signal) by a reset and in standby mode. The initial value is H'FFFF.

10.2.9 Buffer Registers (BRA, BRB)

The buffer registers are 16-bit registers. The ITU has four buffer registers, two each in channels 3 and 4.

Channel	Abbreviation	Function
3	BRA3, BRB3	Used for buffering
4	BRA4, BRB4	 When the corresponding GRA or GRB functions as an output compare register, BRA or BRB can function as an output compare buffer register: the BRA or BRB value is automatically transferred to GRA or GRB at compare match When the corresponding GRA or GRB functions as an input capture register, BRA or BRB can function as an input capture buffer register: the GRA or GRB value is automatically transferred to BRA or BRB can function as an input capture buffer register.

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W															

A buffer register is a 16-bit readable/writable register that is used when buffering is selected. Buffering can be selected independently by bits BFB4, BFA4, BFB3, and BFA3 in TFCR.

The buffer register and general register operate as a pair. When the general register functions as an output compare register, the buffer register functions as an output compare buffer register. When the general register functions as an input capture register, the buffer register functions as an input capture buffer register functions as an input capture buffer register.

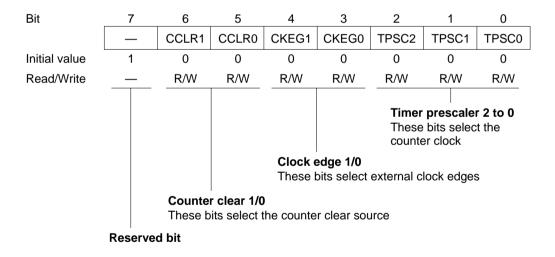
The buffer registers are linked to the CPU by an internal 16-bit bus and can be written or read by either word or byte access.

Buffer registers are initialized to H'FFFF by a reset and in standby mode.

10.2.10 Timer Control Registers (TCR)

TCR is an 8-bit register. The ITU has five TCRs, one in each channel.

Channel	Abbreviation	Function
0	TCR0	TCR controls the timer counter. The TCRs in all channels are
1	TCR1	functionally identical. When phase counting mode is selected in channel 2, the settings of bits CKEG1 and CKEG0 and TPSC2
2	TCR2	to TPSC0 in TCR2 are ignored.
3	TCR3	
4	TCR4	



Each TCR is an 8-bit readable/writable register that selects the timer counter clock source, selects the edge or edges of external clock sources, and selects how the counter is cleared.

TCR is initialized to H'80 by a reset and in standby mode.

Bit 7—Reserved: Read-only bit, always read as 1.

Bits 6 and 5—Counter Clear 1/0 (CCLR1, CCLR0): These bits select how TCNT is cleared.

Bit 6: CCLR1	Bit 5: CCLR0	Description
0	0	TCNT is not cleared (Initial value
	1	TCNT is cleared by GRA compare match or input capture ^{*1}
1	0	TCNT is cleared by GRB compare match or input capture* ¹
	1	Synchronous clear: TCNT is cleared in synchronization with other synchronized timers ^{*2}

Notes: 1. TCNT is cleared by compare match when the general register functions as an output compare register, and by input capture when the general register functions as an input capture register.

2. Selected in TSNC.

Bits 4 and 3—Clock Edge 1/0 (CKEG1, CKEG0): These bits select external clock input edges when an external clock source is used.

Bit 4: CKEG1	Bit 3: CKEG0	Description	
0	0	Count rising edges	(Initial value)
	1	Count falling edges	
1	_	Count both edges	

When channel 2 is set to phase counting mode, bits CKEG1 and CKEG0 in TCR2 are ignored. Phase counting takes precedence.

Bits 2 to 0—Timer Prescaler 2 to 0 (TPSC2 to TPSC0): These bits select the counter clock source.

Bit 2: TPSC2	Bit 1: TPSC1	Bit 0: TPSC0	Description
0	0	0	Internal clock: (Initial value)
		1	Internal clock: ø/2
	1	0	Internal clock: ø/4
		1	Internal clock: ø/8
1	0	0	External clock A: TCLKA input
		1	External clock B: TCLKB input
	1	0	External clock C: TCLKC input
		1	External clock D: TCLKD input

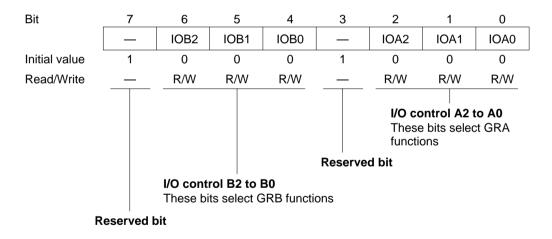
When bit TPSC2 is cleared to 0 an internal clock source is selected, and the timer counts only falling edges. When bit TPSC2 is set to 1 an external clock source is selected, and the timer counts the edge or edges selected by bits CKEG1 and CKEG0.

When channel 2 is set to phase counting mode (MDF = 1 in TMDR), the settings of bits TPSC2 to TPSC0 in TCR2 are ignored. Phase counting takes precedence.

10.2.11 Timer I/O Control Register (TIOR)

TIOR is an 8-bit register. The ITU has five TIORs, one in each channel.

Channel	Abbreviation	Function
0	TIOR0	TIOR controls the general registers. Some functions differ in
1	TIOR1	PWM mode. TIOR3 and TIOR4 settings are ignored when complementary PWM mode or reset-synchronized PWM mode
2	TIOR2	is selected in channels 3 and 4.
3	TIOR3	
4	TIOR4	



Each TIOR is an 8-bit readable/writable register that selects the output compare or input capture function for GRA and GRB, and specifies the functions of the TIOCA and TIOCB pins. If the output compare function is selected, TIOR also selects the type of output. If input capture is selected, TIOR also selects the edge or edges of the input capture signal.

TIOR is initialized to H'88 by a reset and in standby mode.

Bit 7—Reserved: Read-only bit, always read as 1.

Bit 6: IOB2	Bit 5: IOB1	Bit 4: IOB0	Description			
0	0	0	GRB is an output	No output at compare match (Initial value)		
		1	compare register	0 output at GRB compare match*1		
	1	0		1 output at GRB compare match*1		
		1		Output toggles at GRB compare match (1 output in channel 2)*1 *2		
1	0	0	GRB is an input	GRB captures rising edge of input		
		1	capture register	GRB captures falling edge of input		
	1	0		GRB captures both edges of input		
		1				

Bits 6 to 4—I/O Control B2 to B0 (IOB2 to IOB0): These bits select the GRB function.

Notes: 1. After a reset, the output is 0 until the first compare match.

2. Channel 2 output cannot be toggled by compare match. This setting selects 1 output instead.

Bit 3—Reserved: Read-only bit, always read as 1.

Bits 2 to 0—I/O Control A2 to A0 (IOA2 to IOA0): These bits select the GRA function.

Bit 2: IOA2	Bit 1: IOA1	Bit 0: IOA0	Description			
0	0	0	GRA is an output	No output at compare match (Initial value)		
		1	compare register	0 output at GRA compare match*1		
	1	0		1 output at GRA compare match*1		
		1		Output toggles at GRA compare match (1 output in channel 2)*1 *2		
1	0	0	GRA is an input	GRA captures rising edge of input		
		1	capture register	GRA captures falling edge of input		
	1	0		GRA captures both edges of input		
		1				

Notes: 1. After a reset, the output is 0 until the first compare match.

2. Channel 2 output cannot be toggled by compare match. This setting selects 1 output instead.

10.2.12 Timer Status Register (TSR)

TSR is an 8-bit register. The ITU has five TSRs, one in each channel.

Channel	Abl	breviatio	n	Function					
0	TSF	TSR0 Indicates input capture, compare match, and overflow status						w status	
1	TSF	٦1		-					
2	TSF	R2		=					
3	TSF	२३		=					
4	TSI	२ 4		_					
		_	•	_		0	0		
Bit		7	6	5	4	3	2	1	0
		_	—		_		OVF	IMFB	IMFA
Initial value		1	1	1	1	1	0	0	0
Read/Write		_	_	<u> </u>			R/(W)*	R/(W)*	R/(W)*
				Reserved b	its				
	Overflow flag Status flag indicating overflow or underflow								
			Input capture/compare match flag B Status flag indicating GRB compare match or input capture						
	Input capture/compare match flag A Status flag indicating GRA compare match or input capture								

Note: * Only 0 can be written, to clear the flag.

Each TSR is an 8-bit readable/writable register containing flags that indicate TCNT overflow or underflow and GRA or GRB compare match or input capture. These flags are interrupt sources and generate CPU interrupts if enabled by corresponding bits in TIER.

TSR is initialized to H'F8 by a reset and in standby mode.

Bits 7 to 3—Reserved: Read-only bits, always read as 1.

Bit 2—Overflow Flag (OVF): This status flag indicates TCNT overflow or underflow.

Description	
[Clearing condition]	(Initial value)
Read OVF when OVF = 1, then write 0 in OVF	
[Setting condition]	
TCNT overflowed from H'FFFF to H'0000, or underflowed H'FFFF*	from H'0000 to
	[Clearing condition] Read OVF when OVF = 1, then write 0 in OVF [Setting condition] TCNT overflowed from H'FFFF to H'0000, or underflowed

Notes: 1. Channel 2 operates in phase counting mode (MDF = 1 in TMDR)

- Channel 3 and 4 operate in complementary PWM mode (CMD1 = 1 and CMD0 = 0 in TFCR)
- * TCNT underflow occurs when TCNT operates as an up/down-counter. Underflow occurs only under the following conditions:

Bit 1—Input Capture/Compare Match Flag B (IMFB): This status flag indicates GRB

compare match or input capture events.

Bit 1: IMFB	Description	
0	[Clearing condition]	(Initial value)
	Read IMFB when IMFB = 1, then write 0 in IMFB	
1	[Setting conditions]	
	TCNT = GRB when GRB functions as an output compare re-	gister.
	TCNT value is transferred to GRB by an input capture signal functions as an input capture register.	l, when GRB

Bit 0—Input Capture/Compare Match Flag A (IMFA): This status flag indicates GRA compare match or input capture events.

Bit 0: IMFA	Description	
0	[Clearing condition]	(Initial value)
	Read IMFA when IMFA = 1, then write 0 in IMFA.	
	DMAC activated by IMIA interrupt (channels 0 to 3 only).	
1	[Setting conditions]	
	TCNT = GRA when GRA functions as an output compare reg	jister.
	TCNT value is transferred to GRA by an input capture signal, functions as an input capture register.	when GRA

10.2.13 Timer Interrupt Enable Register (TIER)

TIER is an 8-bit register. The ITU has five TIERs, one in each channel.

Channel	A	obreviatio	on	Function					
0	ΤI	TIER0 Enables or disables interrupt requests.							
1	ΤI	ER1		=					
2	ΤI	ER2		=					
3	ΤI	ER3		=					
4	ΤI	ER4		=					
Bit	Г	7	6	5	4	3	2	1	0
		—	_	_	—	_	OVIE	IMIEB	IMIEA
Initial value		1	1	1	1	1	0	0	0
Read/Write		_	_	—	—		R/W	R/W	R/W
				Reserved b	its				
	Overflow interrupt enable Enables or disables OVF interrupts								
	Input capture/compare match interrupt enable B Enables or disables IMFB interrupts								
	Input capture/compare match interrupt enable A Enables or disables IMFA interrupts								

Each TIER is an 8-bit readable/writable register that enables and disables overflow interrupt requests and general register compare match and input capture interrupt requests.

TIER is initialized to H'F8 by a reset and in standby mode.

Bits 7 to 3—Reserved: Read-only bits, always read as 1.

Bit 2—Overflow Interrupt Enable (OVIE): Enables or disables the interrupt requested by the OVF flag in TSR when OVF is set to 1.

Bit 2: OVIE	Description	
0	OVI interrupt requested by OVF is disabled	(Initial value)
1	OVI interrupt requested by OVF is enabled	

Bit 1—Input Capture/Compare Match Interrupt Enable B (IMIEB): Enables or disables the interrupt requested by the IMFB flag in TSR when IMFB is set to 1.

Bit 1: IMIEB	Description	
0	IMIB interrupt requested by IMFB is disabled	(Initial value)
1	IMIB interrupt requested by IMFB is enabled	

Bit 0—Input Capture/Compare Match Interrupt Enable A (IMIEA): Enables or disables the interrupt requested by the IMFA flag in TSR when IMFA is set to 1.

Bit 0: IMIEA	Description	
0	IMIA interrupt requested by IMFA is disabled	(Initial value)
1	IMIA interrupt requested by IMFA is enabled	



10.3 CPU Interface

10.3.1 16-Bit Accessible Registers

The timer counters (TCNTs), general registers A and B (GRAs and GRBs), and buffer registers A and B (BRAs and BRBs) are 16-bit registers, and are linked to the CPU by an internal 16-bit data bus. These registers can be written or read a word at a time, or a byte at a time.

Figures 10.6 and 10.7 show examples of word access to a timer counter (TCNT). Figures 10.8 to 10.11 show examples of byte access to TCNTH and TCNTL.

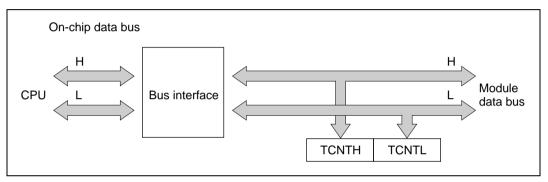


Figure 10.6 Access to Timer Counter (CPU Writes to TCNT, Word)

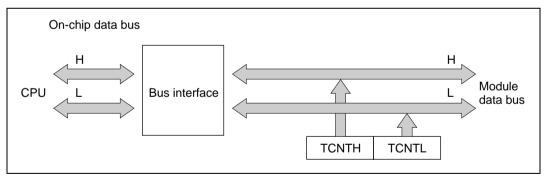


Figure 10.7 Access to Timer Counter (CPU Reads TCNT, Word)

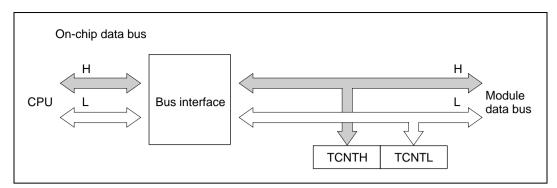


Figure 10.8 Access to Timer Counter (CPU Writes to TCNT, Upper Byte)

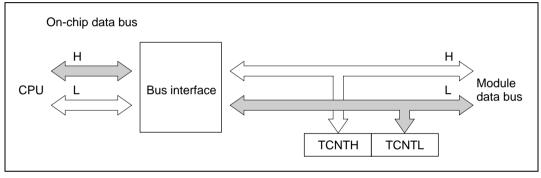


Figure 10.9 Access to Timer Counter (CPU Writes to TCNT, Lower Byte)

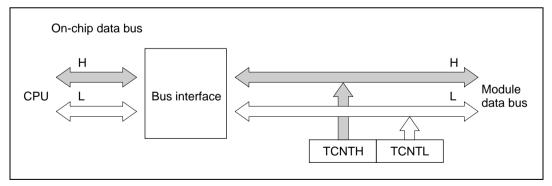


Figure 10.10 Access to Timer Counter (CPU Reads TCNT, Upper Byte)

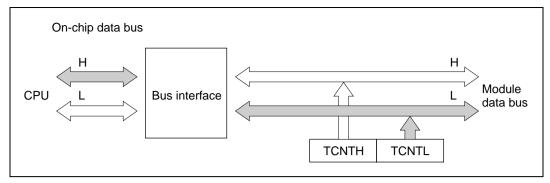


Figure 10.11 Access to Timer Counter (CPU Reads TCNT, Lower Byte)

10.3.2 8-Bit Accessible Registers

The registers other than the timer counters, general registers, and buffer registers are 8-bit registers. These registers are linked to the CPU by an internal 8-bit data bus.

Figures 10.12 and 10.13 show examples of byte read and write access to a TCR.

If a word-size data transfer instruction is executed, two byte transfers are performed.

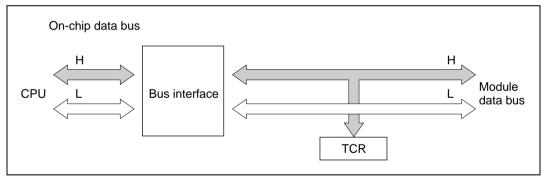


Figure 10.12 Access to Timer Counter (CPU Writes to TCR)

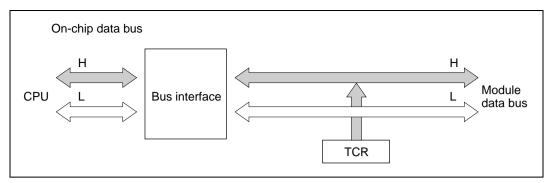


Figure 10.13 Access to Timer Counter (CPU Reads TCR)

10.4 Operation

10.4.1 Overview

A summary of operations in the various modes is given below.

Normal Operation: Each channel has a timer counter and general registers. The timer counter counts up, and can operate as a free-running counter, periodic counter, or external event counter. General registers A and B can be used for input capture or output compare.

Synchronous Operation: The timer counters in designated channels are preset synchronously. Data written to the timer counter in any one of these channels is simultaneously written to the timer counters in the other channels as well. The timer counters can also be cleared synchronously if so designated by the CCLR1 and CCLR0 bits in the TCRs.

PWM Mode: A PWM waveform is output from the TIOCA pin. The output goes to 1 at compare match A and to 0 at compare match B. The duty cycle can be varied from 0% to 100% depending on the settings of GRA and GRB. When a channel is set to PWM mode, its GRA and GRB automatically become output compare registers.

Reset-Synchronized PWM Mode: Channels 3 and 4 are paired for three-phase PWM output with complementary waveforms. (The three phases are related by having a common transition point.) When reset-synchronized PWM mode is selected GRA3, GRB3, GRA4, and GRB4 automatically function as output compare registers, TIOCA₃, TIOCB₃, TIOCA₄, TOCXA₄, TIOCB₄, and TOCXB₄ function as PWM output pins, and TCNT3 operates as an up-counter. TCNT4 operates independently, and is not compared with GRA4 or GRB4.

Complementary PWM Mode: Channels 3 and 4 are paired for three-phase PWM output with non-overlapping complementary waveforms. When complementary PWM mode is selected GRA3, GRB3, GRA4, and GRB4 automatically function as output compare registers, and TIOCA₃, TIOCB₃, TIOCA₄, TOCXA₄, TIOCB₄, and TOCXB₄ function as PWM output pins. TCNT3 and TCNT4 operate as up/down-counters.

Phase Counting Mode: The phase relationship between two clock signals input at TCLKA and TCLKB is detected and TCNT2 counts up or down accordingly. When phase counting mode is selected TCLKA and TCLKB become clock input pins and TCNT2 operates as an up/down-counter.

Buffering

- If the general register is an output compare register When compare match occurs the buffer register value is transferred to the general register.
- If the general register is an input capture register When input capture occurs the TCNT value is transferred to the general register, and the previous general register value is transferred to the buffer register.
- Complementary PWM mode

The buffer register value is transferred to the general register when TCNT3 and TCNT4 change counting direction.

• Reset-synchronized PWM mode The buffer register value is transferred to the general register at GRA3 compare match.

10.4.2 Basic Functions

Counter Operation: When one of bits STR0 to STR4 is set to 1 in the timer start register (TSTR), the timer counter (TCNT) in the corresponding channel starts counting. The counting can be free-running or periodic.

• Sample setup procedure for counter

Figure 10.14 shows a sample procedure for setting up a counter.

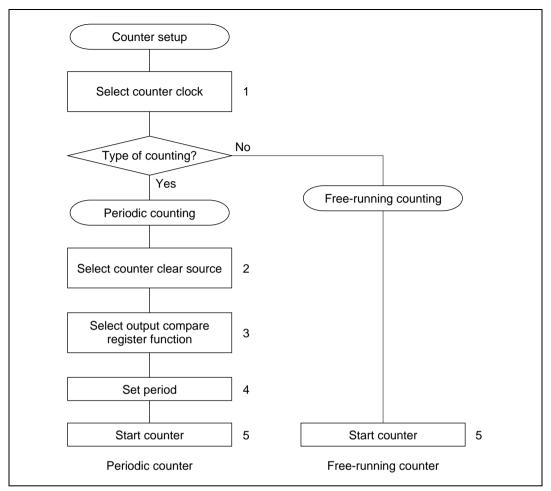
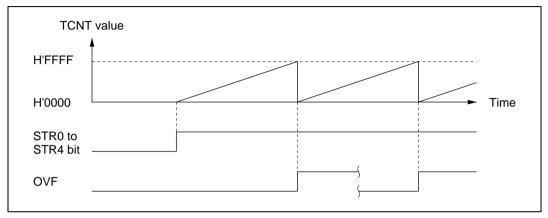


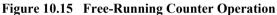
Figure 10.14 Counter Setup Procedure (Example)

- 1. Set bits TPSC2 to TPSC0 in TCR to select the counter clock source. If an external clock source is selected, set bits CKEG1 and CKEG0 in TCR to select the desired edge(s) of the external clock signal.
- 2. For periodic counting, set CCLR1 and CCLR0 in TCR to have TCNT cleared at GRA compare match or GRB compare match.
- 3. Set TIOR to select the output compare function of GRA or GRB, whichever was selected in step 2.
- 4. Write the count period in GRA or GRB, whichever was selected in step 2.
- 5. Set the STR bit to 1 in TSTR to start the timer counter.

• Free-running and periodic counter operation

A reset leaves the counters (TCNTs) in ITU channels 0 to 4 all set as free-running counters. A free-running counter starts counting up when the corresponding bit in TSTR is set to 1. When the count overflows from H'FFFF to H'0000, the OVF flag is set to 1 in TSR. If the corresponding OVIE bit is set to 1 in TIER, a CPU interrupt is requested. After the overflow, the counter continues counting up from H'0000. Figure 10.15 illustrates free-running counting.





When a channel is set to have its counter cleared by compare match, in that channel TCNT operates as a periodic counter. Select the output compare function of GRA or GRB, set bit CCLR1 or CCLR0 in TCR to have the counter cleared by compare match, and set the count period in GRA or GRB. After these settings, the counter starts counting up as a periodic counter when the corresponding bit is set to 1 in TSTR. When the count matches GRA or GRB, the IMFA or IMFB flag is set to 1 in TSR and the counter is cleared to H'0000. If the corresponding IMIEA or IMIEB bit is set to 1 in TIER, a CPU interrupt is requested at this time. After the compare match, TCNT continues counting up from H'0000. Figure 10.16 illustrates periodic counting.



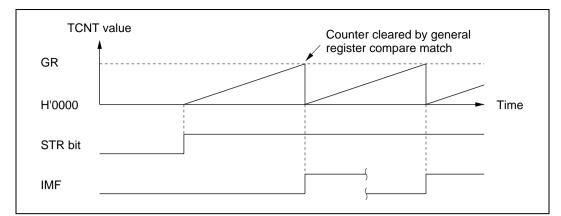


Figure 10.16 Periodic Counter Operation

- TCNT count timing
 - Internal clock source

Bits TPSC2 to TPSC0 in TCR select the system clock (ϕ) or one of three internal clock sources obtained by prescaling the system clock ($\phi/2$, $\phi/4$, $\phi/8$).

Figure 10.17 shows the timing.

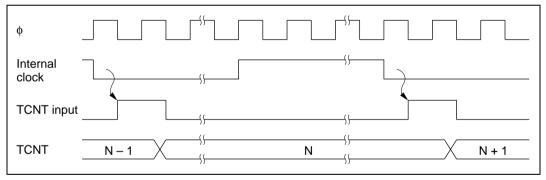


Figure 10.17 Count Timing for Internal Clock Sources

- External clock source

Bits TPSC2 to TPSC0 in TCR select an external clock input pin (TCLKA to TCLKD), and its valid edge or edges are selected by bits CKEG1 and CKEG0. The rising edge, falling edge, or both edges can be selected.

The pulse width of the external clock signal must be at least 1.5 system clocks when a single edge is selected, and at least 2.5 system clocks when both edges are selected. Shorter pulses will not be counted correctly.

Figure 10.18 shows the timing when both edges are detected.

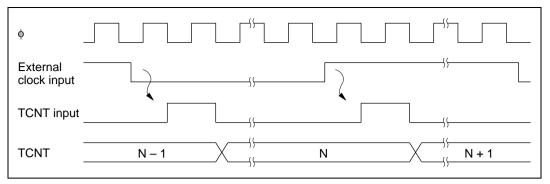
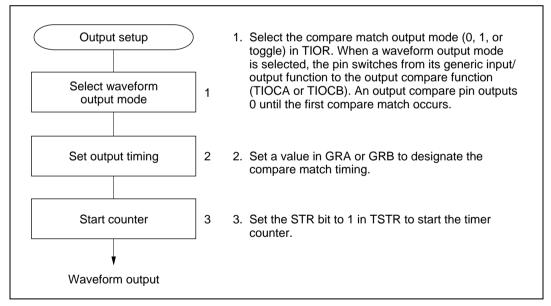


Figure 10.18 Count Timing for External Clock Sources (when Both Edges are Detected)

Waveform Output by Compare Match: In ITU channels 0, 1, 3, and 4, compare match A or B can cause the output at the TIOCA or TIOCB pin to go to 0, go to 1, or toggle. In channel 2 the output can only go to 0 or go to 1.

• Sample setup procedure for waveform output by compare match Figure 10.19 shows a sample procedure for setting up waveform output by compare match.





• Examples of waveform output

Figure 10.20 shows examples of 0 and 1 output. TCNT operates as a free-running counter, 0 output is selected for compare match A, and 1 output is selected for compare match B. When the pin is already at the selected output level, the pin level does not change.

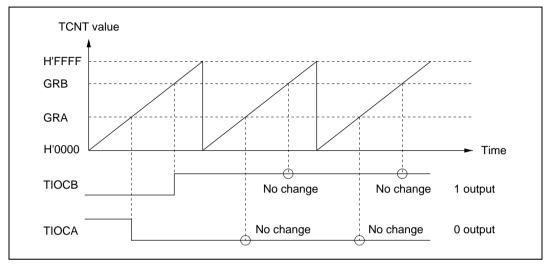


Figure 10.20 0 and 1 Output (Examples)

Figure 10.21 shows examples of toggle output. TCNT operates as a periodic counter, cleared by compare match B. Toggle output is selected for both compare match A and B.

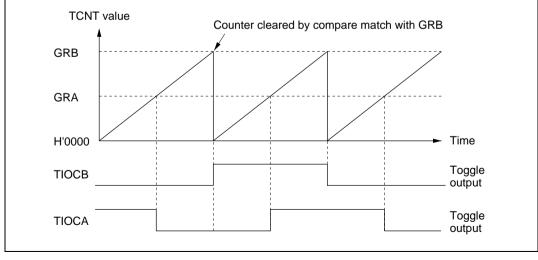


Figure 10.21 Toggle Output (Example)

• Output compare timing

The compare match signal is generated in the last state in which TCNT and the general register match (when TCNT changes from the matching value to the next value). When the compare match signal is generated, the output value selected in TIOR is output at the output compare pin (TIOCA or TIOCB). When TCNT matches a general register, the compare match signal is not generated until the next counter clock pulse.

Figure 10.22 shows the output compare timing.

φ	
TCNT input clock	
TCNT	N N + 1
GR	Ν
Compare match signal	
TIOCA, TIOCB	

Figure 10.22 Output Compare Timing

Input Capture Function: The TCNT value can be captured into a general register when a transition occurs at an input capture/output compare pin (TIOCA or TIOCB). Capture can take place on the rising edge, falling edge, or both edges. The input capture function can be used to measure pulse width or period.

• Sample setup procedure for input capture

Figure 10.23 shows a sample procedure for setting up input capture.

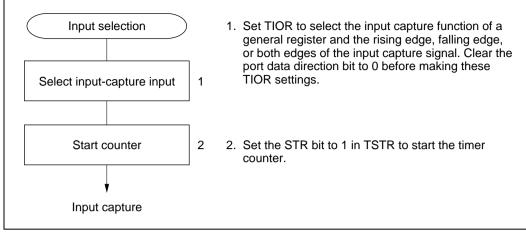


Figure 10.23 Setup Procedure for Input Capture (Example)

• Examples of input capture

Figure 10.24 illustrates input capture when the falling edge of TIOCB and both edges of TIOCA are selected as capture edges. TCNT is cleared by input capture into GRB.

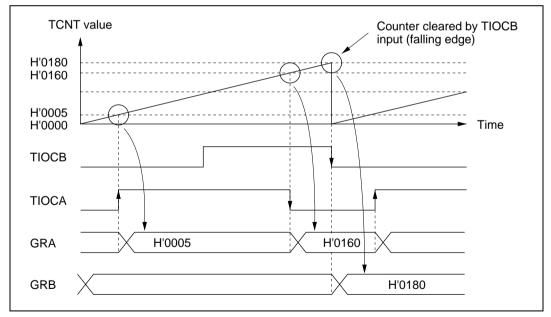


Figure 10.24 Input Capture (Example)

• Input capture signal timing Input capture on the rising edge, falling edge, or both edges can be selected by settings in TIOR. Figure 10.25 shows the timing when the rising edge is selected. The pulse width of the input capture signal must be at least 1.5 system clocks for single-edge capture, and 2.5 system clocks for capture of both edges.

φ	
Input-capture input	
Internal input capture signal	
TCNT	Ν
GRA, GRB	N

Figure 10.25 Input Capture Signal Timing



10.4.3 Synchronization

The synchronization function enables two or more timer counters to be synchronized by writing the same data to them simultaneously (synchronous preset). With appropriate TCR settings, two or more timer counters can also be cleared simultaneously (synchronous clear). Synchronization enables additional general registers to be associated with a single time base. Synchronization can be selected for all channels (0 to 4).

Sample Setup Procedure for Synchronization: Figure 10.26 shows a sample procedure for setting up synchronization.

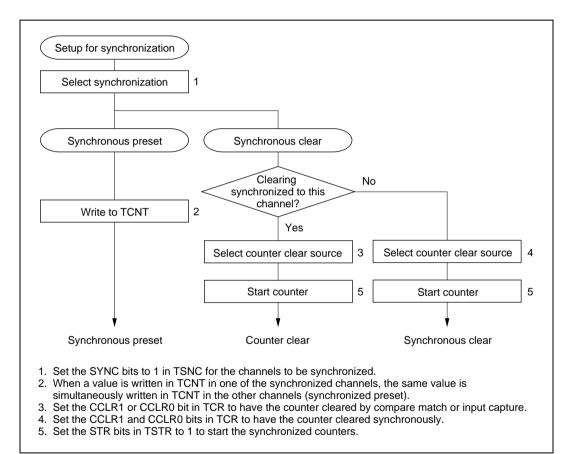


Figure 10.26 Setup Procedure for Synchronization (Example)

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Example of Synchronization: Figure 10.27 shows an example of synchronization. Channels 0, 1, and 2 are synchronized, and are set to operate in PWM mode. Channel 0 is set for counter clearing by compare match with GRB0. Channels 1 and 2 are set for synchronous counter clearing. The timer counters in channels 0, 1, and 2 are synchronously preset, and are synchronously cleared by compare match with GRB0. A three-phase PWM waveform is output from pins TIOCA₀, TIOCA₁, and TIOCA₂. For further information on PWM mode, see section 10.4.4, PWM Mode.

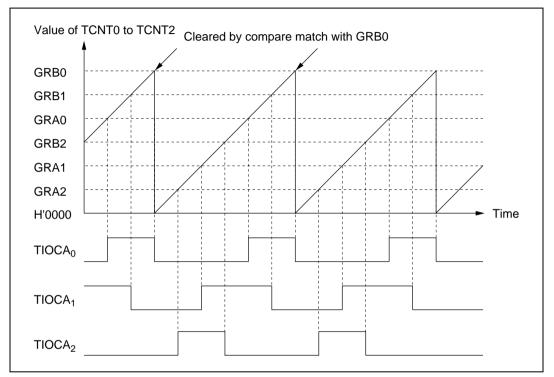


Figure 10.27 Synchronization (Example)

10.4.4 PWM Mode

In PWM mode GRA and GRB are paired and a PWM waveform is output from the TIOCA pin. GRA specifies the time at which the PWM output changes to 1. GRB specifies the time at which the PWM output changes to 0. If either GRA or GRB is selected as the counter clear source, a PWM waveform with a duty cycle from 0% to 100% is output at the TIOCA pin. PWM mode can be selected in all channels (0 to 4).

Table 10.4 summarizes the PWM output pins and corresponding registers. If the same value is set in GRA and GRB, the output does not change when compare match occurs.

Channel	Output Pin	1 Output	0 Output	
0	TIOCA ₀	GRA0	GRB0	
1	TIOCA ₁	GRA1	GRB1	
2	TIOCA ₂	GRA2	GRB2	
3	TIOCA ₃	GRA3	GRB3	
4	TIOCA ₄	GRA4	GRB4	

Table 10.4	PWM	Output 1	Pins and	Registers
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Sample Setup Procedure for PWM Mode: Figure 10.28 shows a sample procedure for setting up PWM mode.

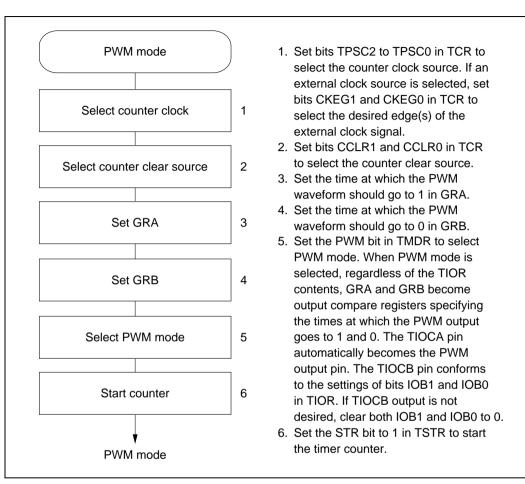


Figure 10.28 Setup Procedure for PWM Mode (Example)

Examples of PWM Mode: Figure 10.29 shows examples of operation in PWM mode. In PWM mode TIOCA becomes an output pin. The output goes to 1 at compare match with GRA, and to 0 at compare match with GRB.

In the examples shown, TCNT is cleared by compare match with GRA or GRB. Synchronized operation and free-running counting are also possible.

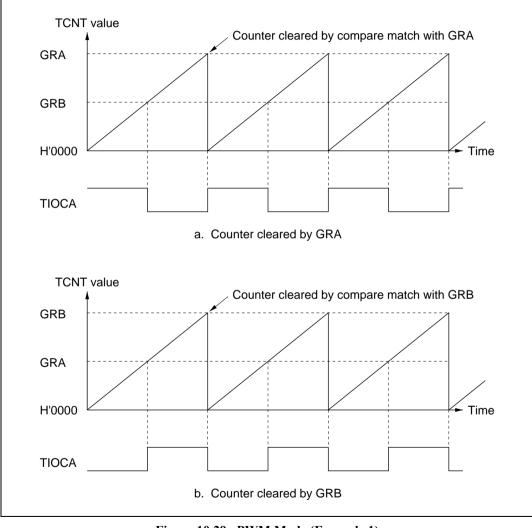
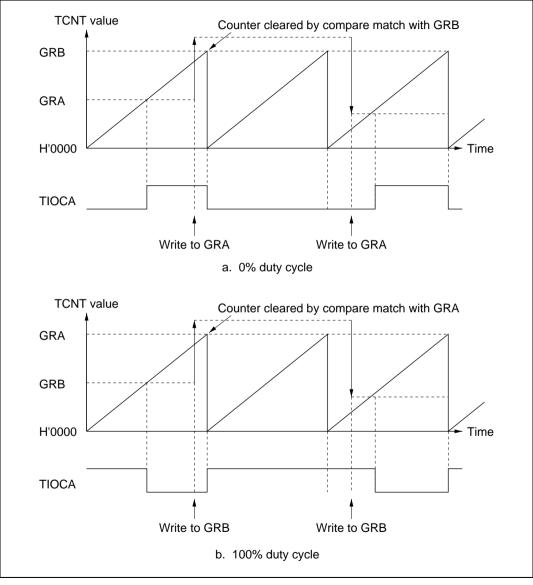


Figure 10.29 PWM Mode (Example 1)

Figure 10.30 shows examples of the output of PWM waveforms with duty cycles of 0% and 100%. If the counter is cleared by compare match with GRB, and GRA is set to a higher value than GRB, the duty cycle is 0%. If the counter is cleared by compare match with GRA, and GRB is set to a higher value than GRA, the duty cycle is 100%.





10.4.5 Reset-Synchronized PWM Mode

In reset-synchronized PWM mode channels 3 and 4 are combined to produce three pairs of complementary PWM waveforms, all having one waveform transition point in common.

When reset-synchronized PWM mode is selected TIOCA₃, TIOCB₃, TIOCA₄, TOCXA₄, TIOCB₄, and TOCXB₄ automatically become PWM output pins, and TCNT3 functions as an up-counter.

Table 10.5 lists the PWM output pins. Table 10.6 summarizes the register settings.

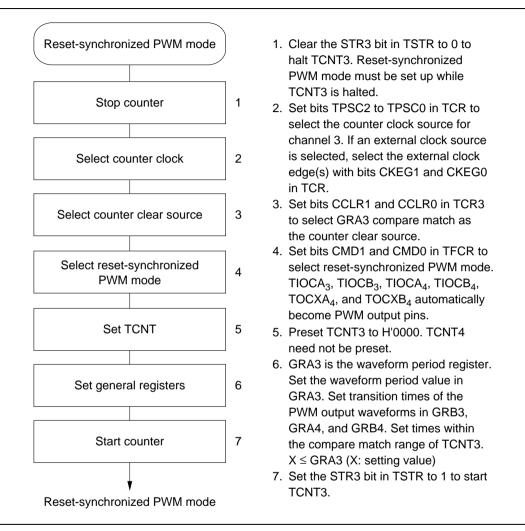
Channel	Output Pin	Description
3	TIOCA ₃	PWM output 1
	TIOCB ₃	PWM output 1' (complementary waveform to PWM output 1)
4	TIOCA ₄	PWM output 2
	TOCXA ₄	PWM output 2' (complementary waveform to PWM output 2)
	TIOCB ₄	PWM output 3
	TOCXB ₄	PWM output 3' (complementary waveform to PWM output 3)

 Table 10.5
 Output Pins in Reset-Synchronized PWM Mode

Table 10.6 Register Settings in Reset-Synchronized PWM Mode

Register	Setting
TCNT3	Initially set to H'0000
TCNT4	Not used (operates independently)
GRA3	Specifies the count period of TCNT3
GRB3	Specifies a transition point of PWM waveforms output from TIOCA ₃ and TIOCB ₃
GRA4	Specifies a transition point of PWM waveforms output from TIOCA ₄ and TOCXA ₄
GRB4	Specifies a transition point of PWM waveforms output from $TIOCB_4$ and $TOCXB_4$

Sample Setup Procedure for Reset-Synchronized PWM Mode: Figure 10.31 shows a sample procedure for setting up reset-synchronized PWM mode.





Example of Reset-Synchronized PWM Mode: Figure 10.32 shows an example of operation in reset-synchronized PWM mode. TCNT3 operates as an up-counter in this mode. TCNT4 operates independently, detached from GRA4 and GRB4. When TCNT3 matches GRA3, TCNT3 is cleared and resumes counting from H'0000. The PWM outputs toggle at compare match of TCNT3 with GRB3, GRA4, and GRB4 respectively, and all toggle when the counter is cleared.

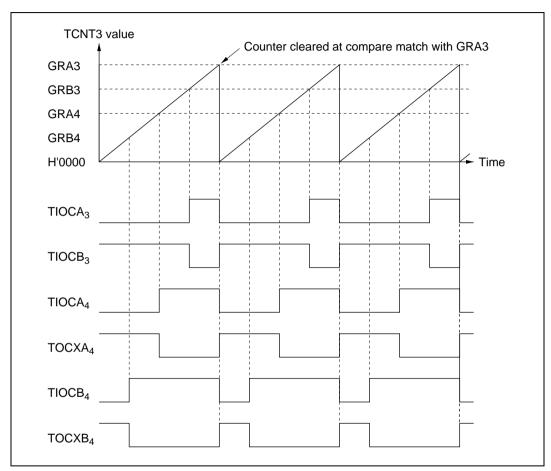


Figure 10.32 Operation in Reset-Synchronized PWM Mode (Example) (when OLS3 = OLS4 = 1)

For the settings and operation when reset-synchronized PWM mode and buffer mode are both selected, see section 10.4.8, Buffering.

10.4.6 Complementary PWM Mode

In complementary PWM mode channels 3 and 4 are combined to output three pairs of complementary, non-overlapping PWM waveforms.

When complementary PWM mode is selected TIOCA₃, TIOCB₃, TIOCA₄, TOCXA₄, TIOCB₄, and TOCXB₄ automatically become PWM output pins, and TCNT3 and TCNT4 function as up/down-counters.

Table 10.7 lists the PWM output pins. Table 10.8 summarizes the register settings.

Channel	Output Pin	Description
3	TIOCA ₃	PWM output 1
	TIOCB ₃	PWM output 1' (non-overlapping complementary waveform to PWM output 1)
4	TIOCA ₄	PWM output 2
	TOCXA ₄	PWM output 2' (non-overlapping complementary waveform to PWM output 2)
	TIOCB ₄	PWM output 3
	TOCXB ₄	PWM output 3' (non-overlapping complementary waveform to PWM output 3)

 Table 10.7
 Output Pins in Complementary PWM Mode

Table 10.8 Register Settings in Complementary PWM Mode

Register	Setting
TCNT3	Initially specifies the non-overlap margin (difference to TCNT4)
TCNT4	Initially set to H'0000
GRA3	Specifies the upper limit value of TCNT3 minus 1
GRB3	Specifies a transition point of PWM waveforms output from TIOCA ₃ and TIOCB ₃
GRA4	Specifies a transition point of PWM waveforms output from TIOCA4 and TOCXA4
GRB4	Specifies a transition point of PWM waveforms output from TIOCB ₄ and TOCXB ₄

Setup Procedure for Complementary PWM Mode: Figure 10.33 shows a sample procedure for setting up complementary PWM mode.

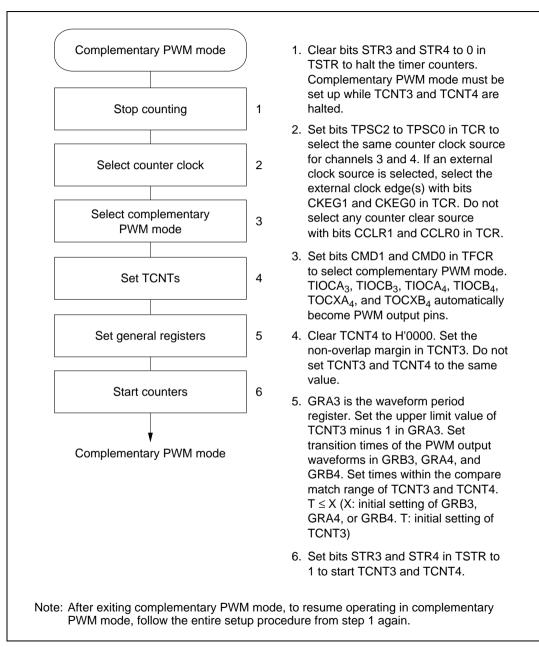


Figure 10.33 Setup Procedure for Complementary PWM Mode (Example)

Clearing Procedure for Complementary PWM Mode: Figure 10.34 shows the steps to clear complementary PWM mode.

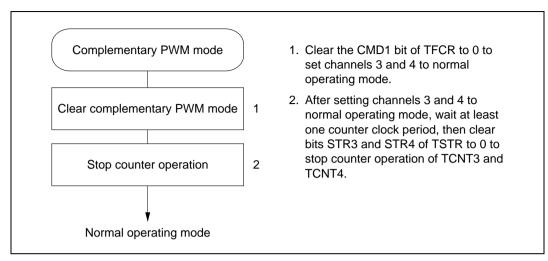


Figure 10.34 Clearing Procedure for Complementary PWM Mode

Examples of Complementary PWM Mode: Figure 10.35 shows an example of operation in complementary PWM mode. TCNT3 and TCNT4 operate as up/down-counters, counting down from compare match between TCNT3 and GRA3 and counting up from the point at which TCNT4 underflows. During each up-and-down counting cycle, PWM waveforms are generated by compare match with general registers GRB3, GRA4, and GRB4. Since TCNT3 is initially set to a higher value than TCNT4, compare match events occur in the sequence TCNT3, TCNT4, TCNT4, TCNT4, TCNT3.

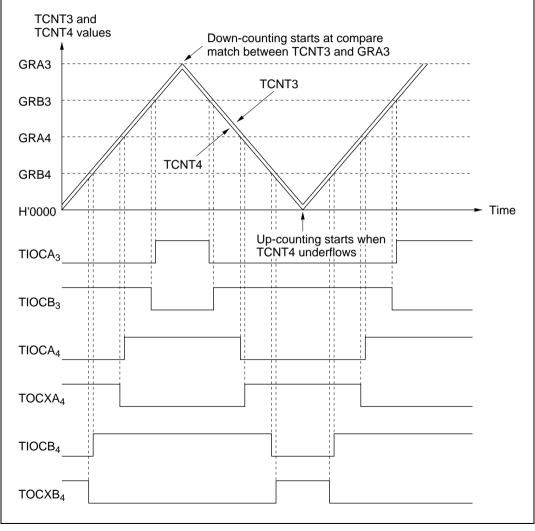
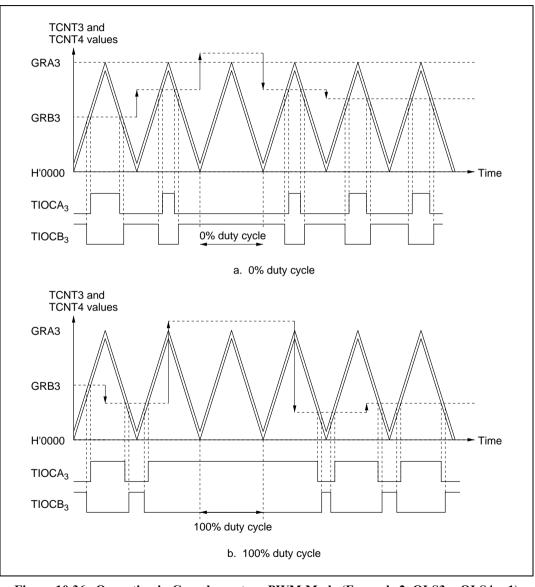


Figure 10.35 Operation in Complementary PWM Mode (Example 1, OLS3 = OLS4 = 1)

Figure 10.36 shows examples of waveforms with 0% and 100% duty cycles (in one phase) in complementary PWM mode. In this example the outputs change at compare match with GRB3, so waveforms with duty cycles of 0% or 100% can be output by setting GRB3 to a value larger than GRA3. The duty cycle can be changed easily during operation by use of the buffer registers. For further information see section 10.4.8, Buffering.





In complementary PWM mode, TCNT3 and TCNT4 overshoot and undershoot at the transitions between up-counting and down-counting. The setting conditions for the IMFA bit in channel 3 and the OVF bit in channel 4 differ from the usual conditions. In buffered operation the buffer transfer conditions also differ. Timing diagrams are shown in figures 10.37 and 10.38.

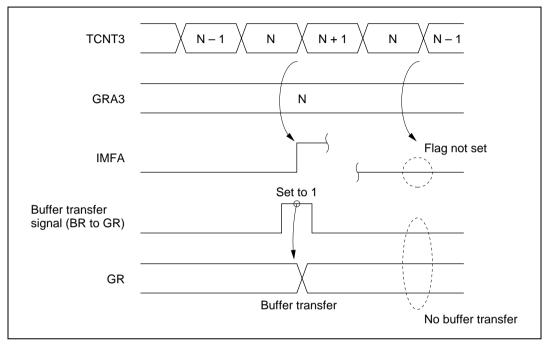


Figure 10.37 Overshoot Timing



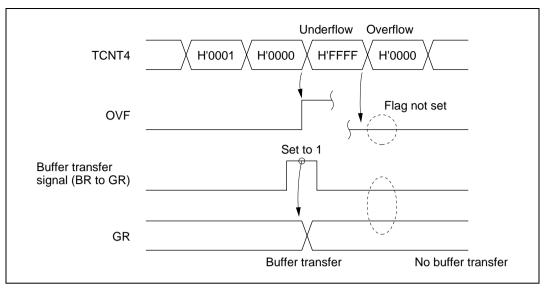


Figure 10.38 Undershoot Timing

In channel 3, IMFA is set to 1 only during up-counting. In channel 4, OVF is set to 1 only when an underflow occurs. When buffering is selected, buffer register contents are transferred to the general register at compare match A3 during up-counting, and when TCNT4 underflows.

General Register Settings in Complementary PWM Mode: When setting up general registers for complementary PWM mode or changing their settings during operation, note the following points.

Initial settings

Do not set values from H'0000 to T - 1 (where T is the initial value of TCNT3). After the counters start and the first compare match A3 event has occurred, however, settings in this range also become possible.

Changing settings

Use the buffer registers. Correct waveform output may not be obtained if a general register is written to directly.

• Cautions on changes of general register settings Figure 10.39 shows six correct examples and one incorrect example.



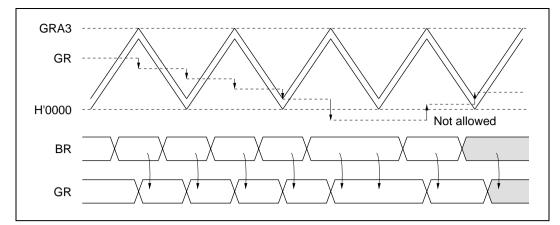


Figure 10.39 Changing a General Register Setting by Buffer Transfer (Example 1)

- Buffer transfer at transition from up-counting to down-counting

If the general register value is in the range from GRA3 - T + 1 to GRA3, do not transfer a buffer register value outside this range. Conversely, if the general register value is outside this range, do not transfer a value within this range. See figure 10.40.

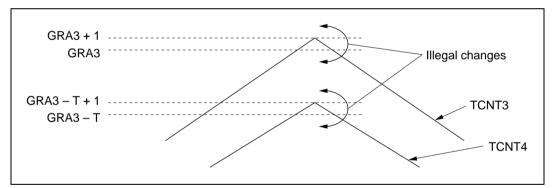


Figure 10.40 Changing a General Register Setting by Buffer Transfer (Caution 1)

- Buffer transfer at transition from down-counting to up-counting

If the general register value is in the range from H'0000 to T - 1, do not transfer a buffer register value outside this range. Conversely, when a general register value is outside this range, do not transfer a value within this range. See figure 10.41.

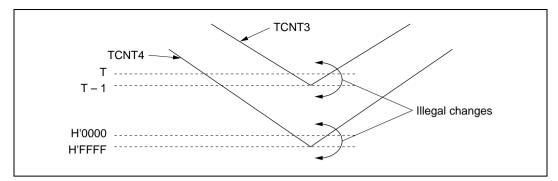


Figure 10.41 Changing a General Register Setting by Buffer Transfer (Caution 2)

— General register settings outside the counting range (H'0000 to GRA3) Waveforms with a duty cycle of 0% or 100% can be output by setting a general register to a value outside the counting range. When a buffer register is set to a value outside the counting range, then later restored to a value within the counting range, the counting direction (up or down) must be the same both times. See figure 10.42.

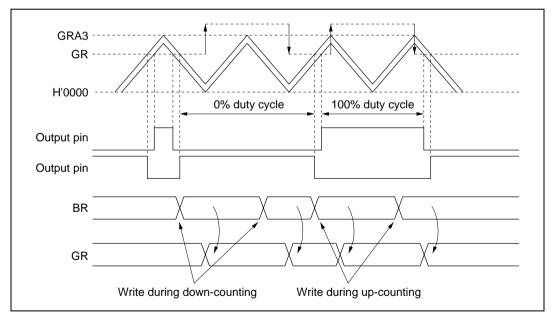


Figure 10.42 Changing a General Register Setting by Buffer Transfer (Example 2)

Settings can be made in this way by detecting GRA3 compare match or TCNT4 underflow before writing to the buffer register. They can also be made by using GRA3 compare match to activate the DMAC.

10.4.7 Phase Counting Mode

In phase counting mode the phase difference between two external clock inputs (at the TCLKA and TCLKB pins) is detected, and TCNT2 counts up or down accordingly.

In phase counting mode, the TCLKA and TCLKB pins automatically function as external clock input pins and TCNT2 becomes an up/down-counter, regardless of the settings of bits TPSC2 to TPSC0, CKEG1, and CKEG0 in TCR2. Settings of bits CCLR1, CCLR0 in TCR2, and settings in TIOR2, TIER2, TSR2, GRA2, and GRB2 are valid. The input capture and output compare functions can be used, and interrupts can be generated.

Phase counting is available only in channel 2.

Sample Setup Procedure for Phase Counting Mode: Figure 10.43 shows a sample procedure for setting up phase counting mode.

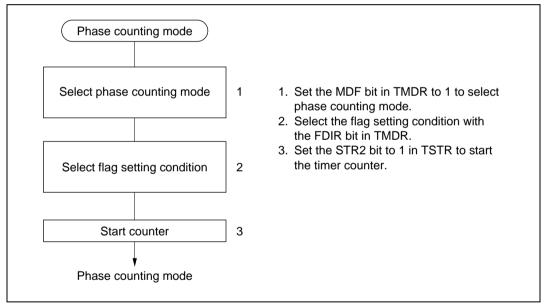


Figure 10.43 Setup Procedure for Phase Counting Mode (Example)



Example of Phase Counting Mode: Figure 10.44 shows an example of operations in phase counting mode. Table 10.9 lists the up-counting and down-counting conditions for TCNT2.

In phase counting mode both the rising and falling edges of TCLKA and TCLKB are counted. The phase difference between TCLKA and TCLKB must be at least 1.5 states, the phase overlap must also be at least 1.5 states, and the pulse width must be at least 2.5 states. See figure 10.45.

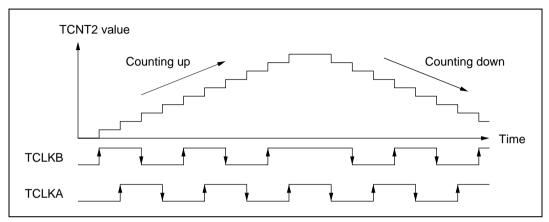


Figure 10.44 Operation in Phase Counting Mode (Example)

Table 10.9 Up/Down Counting Conditions

Counting Direction	Up-Cou	unting			Down-0	Counting		
TCLKB	\uparrow	High	\downarrow	Low	High	\downarrow	Low	\uparrow
TCLKA	Low	\uparrow	High	\downarrow	\downarrow	Low	\uparrow	High

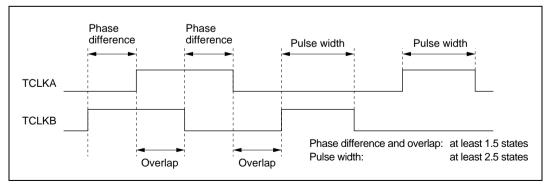


Figure 10.45 Phase Difference, Overlap, and Pulse Width in Phase Counting Mode

10.4.8 Buffering

Buffering operates differently depending on whether a general register is an output compare register or an input capture register, with further differences in reset-synchronized PWM mode and complementary PWM mode. Buffering is available only in channels 3 and 4. Buffering operations under the conditions mentioned above are described next.

• General register used for output compare

The buffer register value is transferred to the general register at compare match. See figure 10.46.

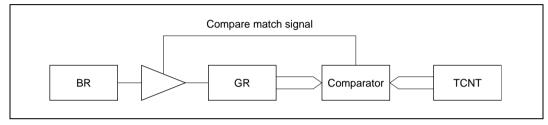


Figure 10.46 Compare Match Buffering

• General register used for input capture

The TCNT value is transferred to the general register at input capture. The previous general register value is transferred to the buffer register.

See figure 10.47.

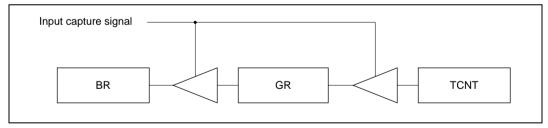


Figure 10.47 Input Capture Buffering

• Complementary PWM mode

The buffer register value is transferred to the general register when TCNT3 and TCNT4 change counting direction. This occurs at the following two times:

- When TCNT3 compare matches GRA3
- When TCNT4 underflows
- Reset-synchronized PWM mode

The buffer register value is transferred to the general register at compare match A3.

Sample Buffering Setup Procedure: Figure 10.48 shows a sample buffering setup procedure.

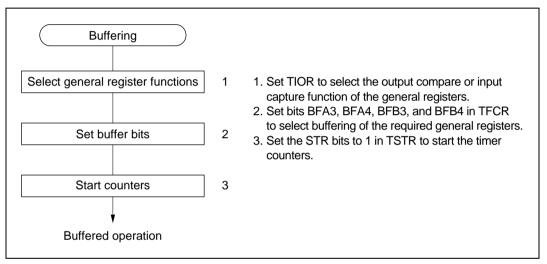


Figure 10.48 Buffering Setup Procedure (Example)

Examples of Buffering: Figure 10.49 shows an example in which GRA is set to function as an output compare register buffered by BRA, TCNT is set to operate as a periodic counter cleared by GRB compare match, and TIOCA and TIOCB are set to toggle at compare match A and B. Because of the buffer setting, when TIOCA toggles at compare match A, the BRA value is simultaneously transferred to GRA. This operation is repeated each time compare match A occurs. Figure 10.50 shows the transfer timing.

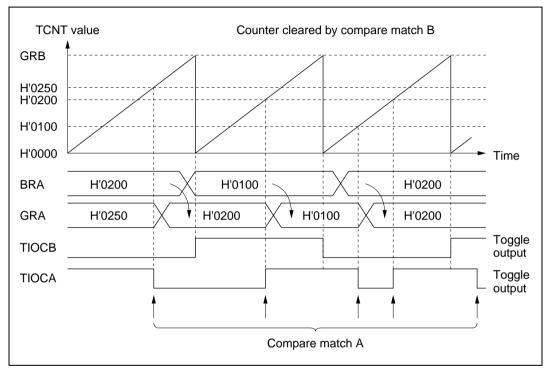


Figure 10.49 Register Buffering (Example 1: Buffering of Output Compare Register)

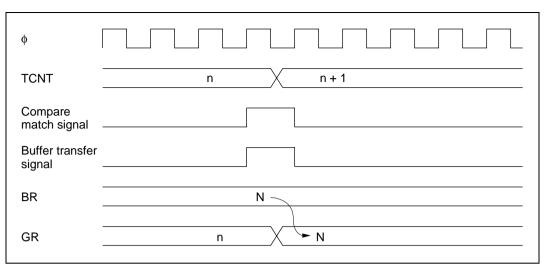


Figure 10.50 Compare Match and Buffer Transfer Timing (Example)

Figure 10.51 shows an example in which GRA is set to function as an input capture register buffered by BRA, and TCNT is cleared by input capture B. The falling edge is selected as the input capture edge at TIOCB. Both edges are selected as input capture edges at TIOCA. Because of the buffer setting, when the TCNT value is captured into GRA at input capture A, the previous GRA value is simultaneously transferred to BRA. Figure 10.52 shows the transfer timing.

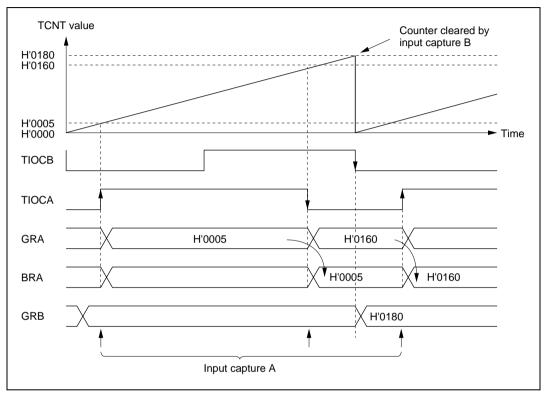


Figure 10.51 Register Buffering (Example 2: Buffering of Input Capture Register)



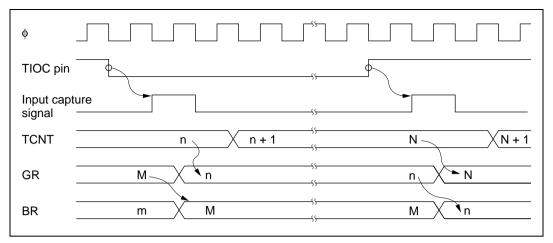


Figure 10.52 Input Capture and Buffer Transfer Timing (Example)

Figure 10.53 shows an example in which GRB3 is buffered by BRB3 in complementary PWM mode. Buffering is used to set GRB3 to a higher value than GRA3, generating a PWM waveform with 0% duty cycle. The BRB3 value is transferred to GRB3 when TCNT3 matches GRA3, and when TCNT4 underflows.

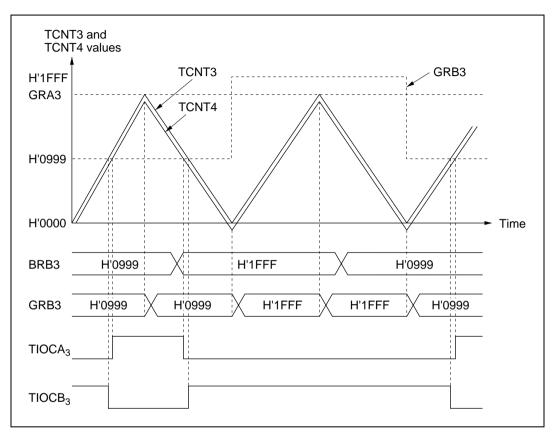


Figure 10.53 Register Buffering (Example 3: Buffering in Complementary PWM Mode)



10.4.9 ITU Output Timing

The ITU outputs from channels 3 and 4 can be disabled by bit settings in TOER or by an external trigger, or inverted by bit settings in TOCR.

Timing of Enabling and Disabling of ITU Output by TOER: In this example an ITU output is disabled by clearing a master enable bit to 0 in TOER. An arbitrary value can be output by appropriate settings of the data register (DR) and data direction register (DDR) of the corresponding input/output port. Figure 10.54 illustrates the timing of the enabling and disabling of ITU output by TOER.

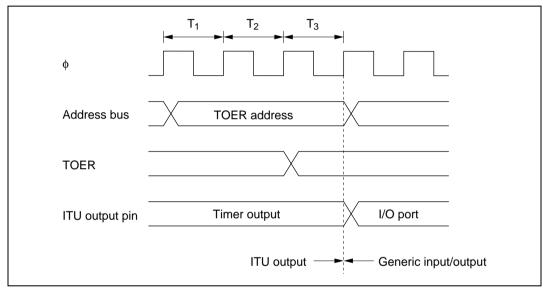


Figure 10.54 Timing of Disabling of ITU Output by Writing to TOER (Example)

Timing of Disabling of ITU Output by External Trigger: If the XTGD bit is cleared to 0 in TOCR in reset-synchronized PWM mode or complementary PWM mode, when an input capture A signal occurs in channel 1, the master enable bits are cleared to 0 in TOER, disabling ITU output. Figure 10.55 shows the timing.

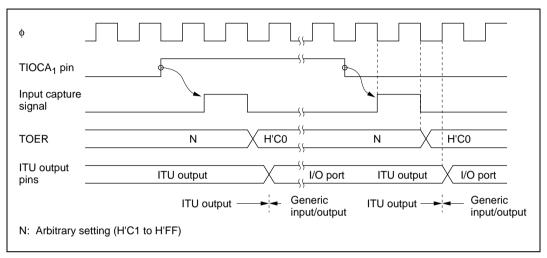


Figure 10.55 Timing of Disabling of ITU Output by External Trigger (Example)

Timing of Output Inversion by TOCR: The output levels in reset-synchronized PWM mode and complementary PWM mode can be inverted by inverting the output level select bits (OLS4 and OLS3) in TOCR. Figure 10.56 shows the timing.

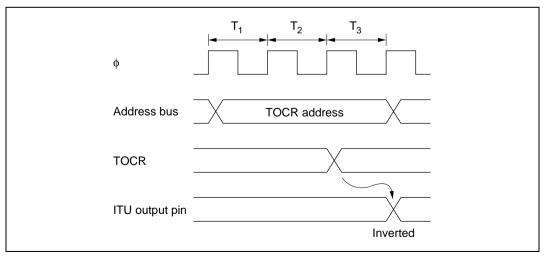


Figure 10.56 Timing of Inverting of ITU Output Level by Writing to TOCR (Example)



10.5 Interrupts

The ITU has two types of interrupts: input capture/compare match interrupts, and overflow interrupts.

10.5.1 Setting of Status Flags

Timing of Setting of IMFA and IMFB at Compare Match: IMFA and IMFB are set to 1 by a compare match signal generated when TCNT matches a general register (GR). The compare match signal is generated in the last state in which the values match (when TCNT is updated from the matching count to the next count). Therefore, when TCNT matches a general register, the compare match signal is not generated until the next timer clock input. Figure 10.57 shows the timing of the setting of IMFA and IMFB.

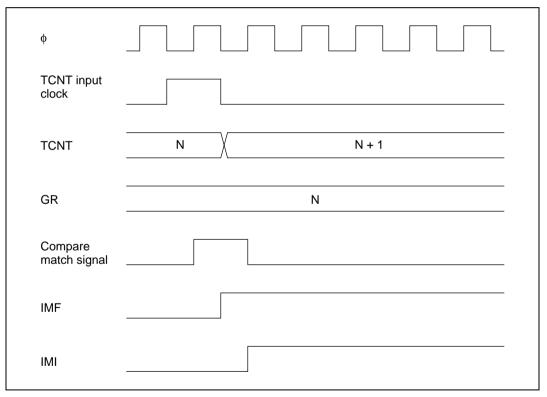


Figure 10.57 Timing of Setting of IMFA and IMFB by Compare Match

Timing of Setting of IMFA and IMFB by Input Capture: IMFA and IMFB are set to 1 by an input capture signal. The TCNT contents are simultaneously transferred to the corresponding general register. Figure 10.58 shows the timing.

ф	
Input capture signal	3
IMF	
TCNT	Ν
GR	N
IMI	

Figure 10.58 Timing of Setting of IMFA and IMFB by Input Capture



Timing of Setting of Overflow Flag (OVF): OVF is set to 1 when TCNT overflows from H'FFFF to H'0000 or underflows from H'0000 to H'FFFF. Figure 10.59 shows the timing.

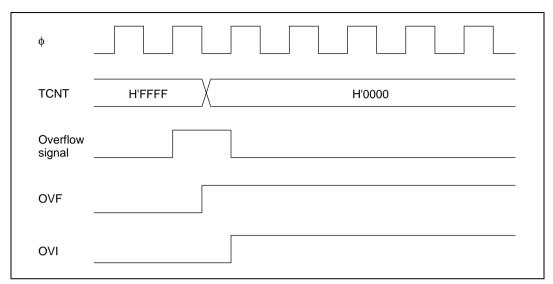


Figure 10.59 Timing of Setting of OVF

10.5.2 Clearing of Status Flags

If the CPU reads a status flag while it is set to 1, then writes 0 in the status flag, the status flag is cleared. Figure 10.60 shows the timing.

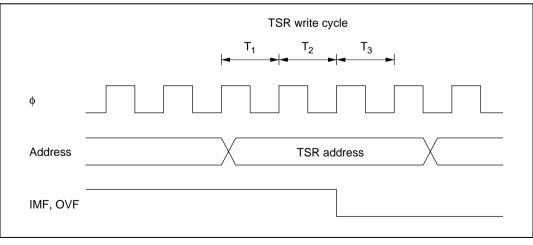


Figure 10.60 Timing of Clearing of Status Flags

10.5.3 Interrupt Sources and DMA Controller Activation

Each ITU channel can generate a compare match/input capture A interrupt, a compare match/input capture B interrupt, and an overflow interrupt. In total there are 15 interrupt sources, all independently vectored. An interrupt is requested when the interrupt request flag and interrupt enable bit are both set to 1.

The priority order of the channels can be modified in interrupt priority registers A and B (IPRA and IPRB). For details see section 5, Interrupt Controller.

Compare match/input capture A interrupts in channels 0 to 3 can activate the DMA controller (DMAC). When the DMAC is activated a CPU interrupt is not requested.

Table 10.10 lists the interrupt sources.

Table 10.10 ITU Interrupt Sources

Channel	Interrupt Source	Description	DMAC Activatable	Priority*
0	IMIA0	Compare match/input capture A0	Yes	High
	IMIB0	Compare match/input capture B0	No	_ ↑
	OVI0	Overflow 0	No	
1	IMIA1	Compare match/input capture A1	Yes	_
	IMIB1	Compare match/input capture B1	No	
	OVI1	Overflow 1	No	
2	IMIA2	Compare match/input capture A2	Yes	_
	IMIB2	Compare match/input capture B2	No	
	OVI2	Overflow 2	No	_
3	IMIA3	Compare match/input capture A3	Yes	_
	IMIB3	Compare match/input capture B3	No	
	OVI3	Overflow 3	No	_
4	IMIA4	Compare match/input capture A4	No	_
	IMIB4	Compare match/input capture B4	No	_
	OVI4	Overflow 4	No	Low

Note: * The priority immediately after a reset is indicated. Inter-channel priorities can be changed by settings in IPRA and IPRB.

10.6 Usage Notes

This section describes contention and other matters requiring special attention during ITU operations.

Contention between TCNT Write and Clear: If a counter clear signal occurs in the T₃ state of a TCNT write cycle, clearing of the counter takes priority and the write is not performed. See figure 10.61.

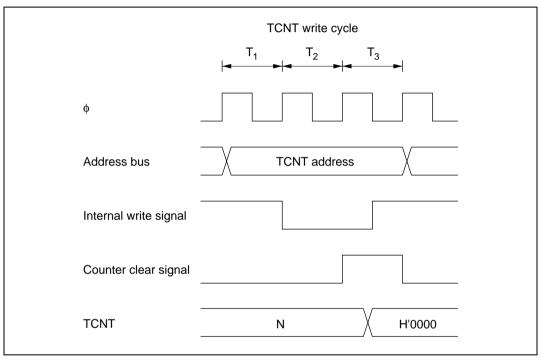


Figure 10.61 Contention between TCNT Write and Clear

Contention between TCNT Word Write and Increment: If an increment pulse occurs in the T₃ state of a TCNT word write cycle, writing takes priority and TCNT is not incremented. See figure 10.62.

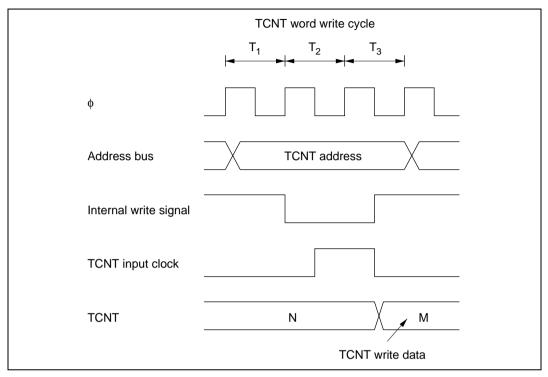


Figure 10.62 Contention between TCNT Word Write and Increment



Contention between TCNT Byte Write and Increment: If an increment pulse occurs in the T_2 or T_3 state of a TCNT byte write cycle, writing takes priority and TCNT is not incremented. The TCNT byte that was not written retains its previous value. See figure 10.63, which shows an increment pulse occurring in the T_2 state of a byte write to TCNTH.

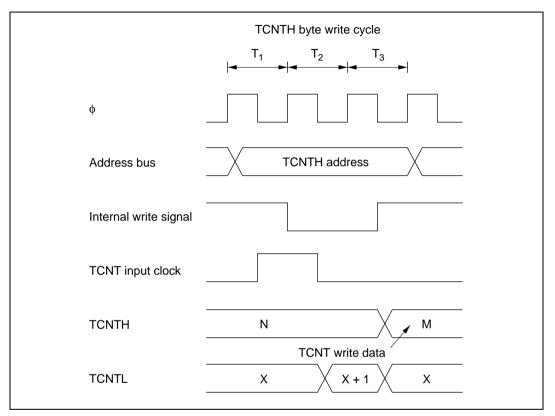


Figure 10.63 Contention between TCNT Byte Write and Increment

Contention between General Register Write and Compare Match: If a compare match occurs in the T_3 state of a general register write cycle, writing takes priority and the compare match signal is inhibited. See figure 10.64.

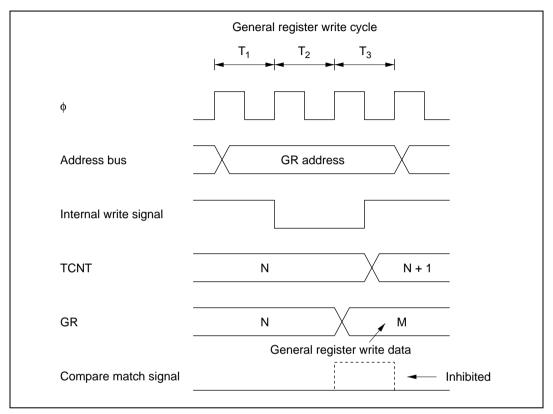


Figure 10.64 Contention between General Register Write and Compare Match



Contention between TCNT Write and Overflow or Underflow: If an overflow occurs in the T_3 state of a TCNT write cycle, writing takes priority and the counter is not incremented. OVF is set to 1. The same holds for underflow. See figure 10.65.

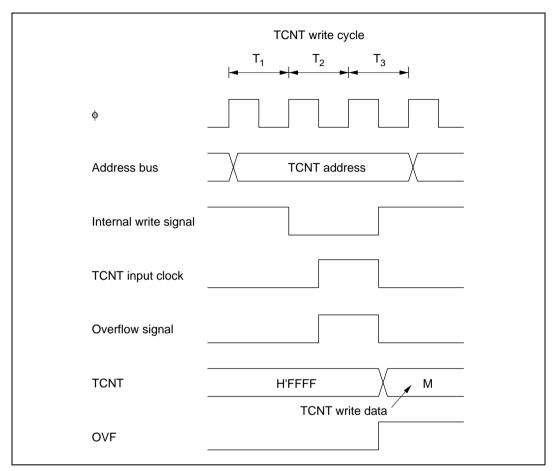


Figure 10.65 Contention between TCNT Write and Overflow

Contention between General Register Read and Input Capture: If an input capture signal occurs during the T₃ state of a general register read cycle, the value before input capture is read. See figure 10.66.

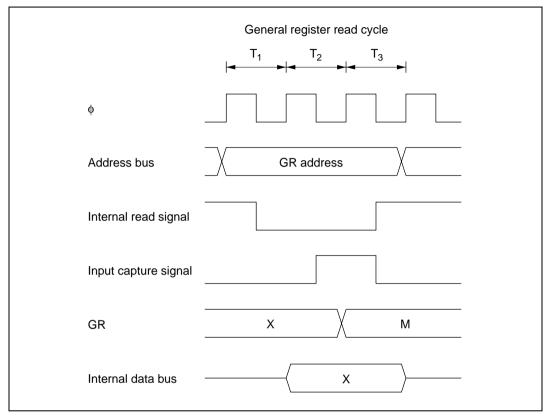


Figure 10.66 Contention between General Register Read and Input Capture



Contention between Counter Clearing by Input Capture and Counter Increment: If an input capture signal and counter increment signal occur simultaneously, the counter is cleared according to the input capture signal. The counter is not incremented by the increment signal. The value before the counter is cleared is transferred to the general register. See figure 10.67.

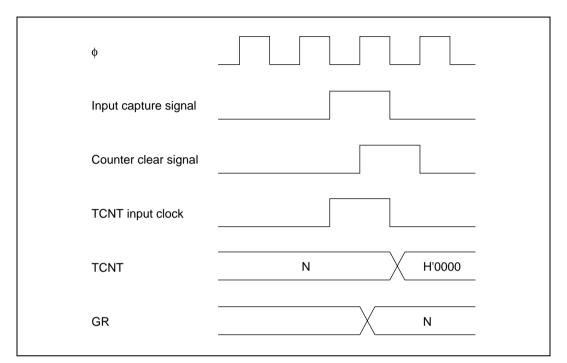


Figure 10.67 Contention between Counter Clearing by Input Capture and Counter Increment

Contention between General Register Write and Input Capture: If an input capture signal occurs in the T₃ state of a general register write cycle, input capture takes priority and the write to the general register is not performed. See figure 10.68.

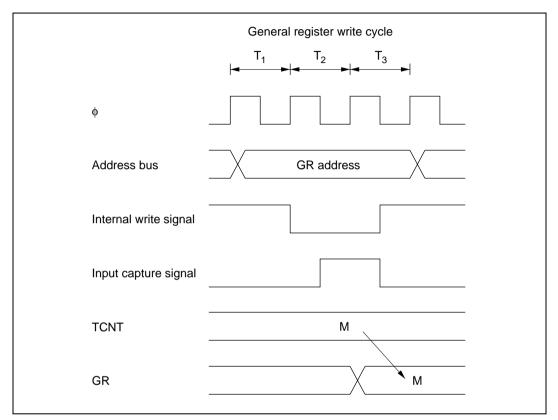


Figure 10.68 Contention between General Register Write and Input Capture

Note on Waveform Period Setting: When a counter is cleared by compare match, the counter is cleared in the last state at which the TCNT value matches the general register value, at the time when this value would normally be updated to the next count. The actual counter frequency is therefore given by the following formula:

$$f = \frac{\phi}{(N+1)}$$

(f: counter frequency. ϕ : system clock frequency. N: value set in general register.)

Contention between Buffer Register Write and Input Capture: If a buffer register is used for input capture buffering and an input capture signal occurs in the T_3 state of a write cycle, input capture takes priority and the write to the buffer register is not performed. See figure 10.69.

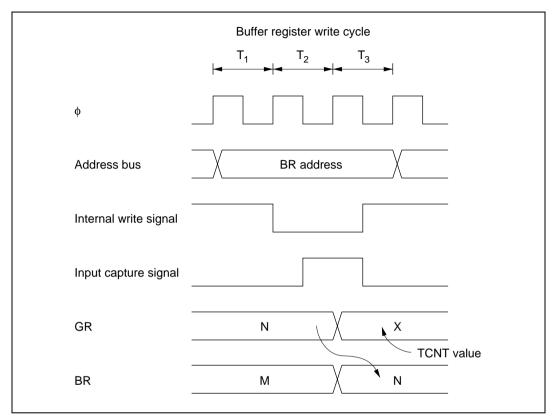


Figure 10.69 Contention between Buffer Register Write and Input Capture

Note on Synchronous Preset: When channels are synchronized, if a TCNT value is modified by byte write access, all 16 bits of all synchronized counters assume the same value as the counter that was addressed.

Example: When channels 2 and 3 are synchronized

• Byte write to channel 2 or byte write to channel 3

			Write A to upper byte			
TCNT2	W	Х	of channel 2	TCNT2	А	Х
TCNT3	Y	Z		TCNT3	A	Х
	Upper byte	Lower byte	Write A to lower byte of channel 3		Upper byte	Lower byte
				TCNT2	Y	А
				TCNT3	Y	А
					Upper byte	Lower byte
• Word v	write to char	nnel 2 or wo	rd write to channel 3			
TCNT2	W	Х	►	TCNT2	Α	В
TCNT3	Y	Z	Write AB word to	TCNT3	A	В
	Upper byte	Lower byte	channel 2 or 3		Upper byte	Lower byte

Note on Setup of Reset-Synchronized PWM Mode and Complementary PWM Mode: When setting bits CMD1 and CMD0 in TFCR, take the following precautions:

- Write to bits CMD1 and CMD0 only when TCNT3 and TCNT4 are stopped.
- Do not switch directly between reset-synchronized PWM mode and complementary PWM mode. First switch to normal mode (by clearing bit CMD1 to 0), then select reset-synchronized PWM mode or complementary PWM mode.





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								Register Settings	Settings						
		TSNC		TMDR			TFCR		TO	TOCR	TOER	TIC	TIOR0	TCR0	
Operat	Operating Mode	Synchro- nization	MDF	FDIR	MMd	Comple- mentary PWM	Reset- Synchro- Buffer- nized ing PWM	Buffer- ing	ХТСР	Output Level Select	Master Enable	YOI	IOB	Clear Select	Clock Select
Synchron	Synchronous preset	SYNC0 = 1	I	I	0	I	I	I	I	1	1	0	0	0	0
PWM mode	de	0	I	I	PWM0 = 1	I	I	I	I	1	1	I	*0	0	0
Output compare A	mpare A	0		I	PWM0 = 0	I	I		I	1	1	IOA2 = 0 Other bits unrestricted	0	0	0
Output compare B	mpare B	0	I		0	I	I	I	1	1	1	0	IOB2 = 0 Other bits unrestricted	0	0
Input capture A	ture A	0	I	I	PWM0 = 0		I	I	I	1	1	IOA2 = 1 Other bits unrestricted	0	0	0
Input capture B	ture B	0	I	I	PWM0 = 0		I	I	I	I	I	0	IOB2 = 1 Other bits unrestricted	0	0
Counter clearing	By compare match/input capture A	0	I	I	0	I	I	I	I	I	I	0	0	CCLR1 = 0 CCLR0 = 1	0
1	By compare match/input capture B	0	I	I	0	I	I		I	I	I	0	0	CCLR1 = 1 CCLR0 = 0	0
1	Syn- chronous clear	SYNC0 = 1	I		0	I	I		1	1	1	0	0	CCLR1 = 1 CCLR0 = 1	0
Legend: C	D: Setting available (valid).	Legend: O: Setting available (valid).	-												

Table 10.11 (a) ITU Operating Modes (Channel 0)

---: Setting does not affect this mode.

Note: * The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.

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							1 ^{ce}	Register Settings	Settings						
		TSNC		TMDR			TFCR		10	TOCR	TOER	TIC	TIOR1	TCR1	
Opera	Operating Mode	Synchro- nization	MDF	FDIR	MMd	Comple- mentary PWM	Reset- Synchro- Buffer- nized ing PWM	Buffer- ing		XTGD Level Select	Master Enable	IOA	IOB	Clear Select	Clock Select
Synchron	Synchronous preset	SYNC1 = 1	Ι	I	0	I	I	Ι	Ι	I	Ι	0	0	0	0
PWM mode	ode	0	I	Ι	PWM1 = 1	I	I	Ι	I	I	I	I	0*1	0	0
Output cc	Output compare A	0	I	I	PWM1 = 0	1	1	I	I	I	I	IOA2 = 0 Other bits unrestricted	0	0	0
Output cc	Output compare B	0	I	I	0	1	1	I	I	I	I	0	IOB2 = 0 Other bits unrestricted	0	0
Input capture A	oture A	0	I	1	PWM1 = 0	1	1	Ι	0*2	1	1	IOA2 = 1 Other bits unrestricted	0	0	0
Input capture B	oture B	0	I		PWM1 = 0	I	I	I	I	I	I	0	IOB2 = 1 Other bits unrestricted	0	0
Counter clearing	Counter By compare clearing match/input capture A	0			0	Ι	I		-	I	I	0	0	CCLR1 = 0 CCLR0 = 1	0
	By compare match/input capture B	0	I	I	0	I	I	I	I	I	I	0	0	CCLR1 = 1 CCLR0 = 0	0
	Syn- chronous clear	SYNC1 = 1	I		0	I	1		I	I	I	0	0	CCLR1 = 1 CCLR0 = 1	0
Legend: (Legend: O: Setting available (valid). —: Setting does not affect this mode.	tilable (valid).	is mode.												

Table 10.11 (b) ITU Operating Modes (Channel 1)

Notes: 1. The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited. 2. Valid only when channels 3 and 4 are operating in complementary PWM mode or reset-synchronized PWM mode.

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								Register Settings	Settings						
		TSNC		TMDR			TFCR		2	TOCR	TOER	TIC	TIOR2	TCR2	
Opera	Operating Mode	Synchro- nization	MDF	FDIR	PWM	Comple- mentary PWM	Reset- Synchro- Buffer- nized ing PWM	Buffer- ing	XTGD	Output Level Select	Master Enable	IOA	IOB	Clear Select	Clock Select
Synchron	Synchronous preset	SYNC2 = 1	I	1	0	I	I	I	I	1	1	0	0	0	0
PWM mode	de	0	I	1	PWM2 = 1	I	I	I	I	I	I	Ι	*0	0	0
Output cc	Output compare A	0	I	1	PWM2 = 0	I	I	ļ		1	I	IOA2 = 0 Other bits unrestricted	0	0	0
Output cc	Output compare B	0	I	I	0	I	I	I	I	I	I	0	IOB2 = 0 Other bits unrestricted	0	0
Input capture A	ture A	0	I	1	PWM2 = 0	I	I	I		1	I	IOA2 = 1 Other bits unrestricted	0	0	0
Input capture B	ture B	0	I		PWM2 = 0	Ι				l	l	0	IOB2 = 1 Other bits unrestricted	0	0
Counter clearing	By compare match/input capture A	0	I	I	0	I	I	ļ		I	I	0	0	CCLR1 = 0 CCLR0 = 1	0
	By compare match/input capture B	0	I	I	0	I	I	I	I	I	I	0	0	CCLR1 = 1 CCLR0 = 0	0
	Syn- chronous clear	SYNC2 = 1	I	I	0	Ι	Ι	I		I	I	0	0	CCLR1 = 1 CCLR0 = 1	0
Phase counting mode	ounting	0	MDF = 1	0	0	-	—	Ι	Ι	Ι	Ι	0	0	0	Ι
Legend: (Legend: O: Setting available (valid).	ilable (valid).													

Table 10.11 (c) ITU Operating Modes (Channel 2)

Note: * The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited.

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								Register Settings	ettings						
		TSNC		TMDR	L L		TFCR		Ĭ	TOCR	TOER	TIOR3	R3	TCR3	
Opera	Operating Mode	Synchro- nization	MDF	FDIR	MWd	Comple- mentary PWM	Reset- Synchro- nized PWM	Buffer- ing	XTGD	XTGD Level Select	Master Enable	POI	IOB	Clear Select	Clock Select
Synchror	Synchronous preset	SYNC3 = 1	1	1	0	0*3	0	0	1	1	0*1	0	0	0	0
PWM mode	ode	0	1	1	PWM3 = 1	CMD1 = 0	CMD1 = 0	0	1	1	0	1	0*2	0	0
Output o	Output compare A	0	1	1	PWM3 = 0 CMD1 = 0	CMD1 = 0	CMD1 = 0	0	1	1	0	IOA2 = 0 Other bits unrestricted	0	0	0
Output o	Output compare B	0	1	1	0	CMD1 = 0	CMD1 = 0	0	I	1	0	0	IOB2 = 0 Other bits unrestricted	0	0
Input capture A	oture A	0	I	I	PWM3 = 0 CMD1 = 0	CMD1 = 0	CMD1 = 0	0	I	I	EA3 ignored IOA2 = 1 Other bits Other bitt unrestricted unrestrict	IOA2 = 1 Other bits unrestricted	0	0	0
Input capture B	oture B	0		I	PWM3 = 0 CMD1 = 0	CMD1 = 0	CMD1 = 0	0	I	I	EB3 ignored Other bits unrestricted	0	IOA2 = 1 Other bits unrestricted	0	0
Counter clearing	Counter By compare clearing match/input capture A	0	1	I	0	Illegal setting: CMD1 = 1 CMD0 = 0	*4 •	0	I	I	^{*4}	0	0	CCLR1 = 0 CCLR0 = 1	0
	By compare match/input capture B	0		I	0	CMD1 = 0	CMD1 = 0	0	I	I	ž.	0	0	CCLR1 = 1 CCLR0 = 0	0
	Syn- chronous clear	SYNC3 = 1	I	I	0	Illegal setting: CMD1 = 1 CMD0 = 0	0	0	I	I	°*1	0	0	CCLR1 = 1 CCLR0 = 1	0
Complementary PWM mode	nentary ode	0*3	I	I	I	CMD1 = 1 CMD0 = 0	CMD1 = 1 $CMD0 = 0$	0	0*6	0	0	I		CCLR1 = 0 CCLR0 = 0	0*5
Reset-synch PWM mode	Reset-synchronized PWM mode	0	Ι	Ι	I	CMD1 = 1 CMD0 = 1	CMD1 = 1 CMD0 = 1	0	0*6	0	0	I		CCLR1 = 0 CCLR0 = 1	0
Buffering (BRA)	5	0		I	0	0	0	BFA3 = 1 Other bits unrestricted			0*1	0	0	0	0
Buffering (BRB)		0	I	I	0	0	0	BFA3 = 1 Other bits unrestricted	I	l	\$ 7	0	0	0	0
Legend: (Legend: O: Setting available (valid).	ailable (valid	 												

Table 10.11 (d) ITU Operating Modes (Channel 3)

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Setting does not affect this mode. Legeriu: ⊖: ⊃etting available (valid). ï

Notes:

1. Master enable bit settings are valid only during waveform output.

The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited. Do not set both channels 3 and 4 for synchronous operation when complementary PWM mode is selected. പത

The counter cannot be cleared by input capture A when reset-synchronized PWM mode is selected. . 4

In complementary PWM mode, select the same clock source for channels 3 and 4.
 Use the input capture A function in channel 1.

								Register Settings	ettings						
		TSNC		TMDR	~		TFCR		Ĕ	TOCR	TOER	TIOR4	R4	TCR4	
Opera	Operating Mode	Synchro- nization	MDF	MDF FDIR	PWM	Comple- mentary PWM	Reset- Synchro- nized PWM	Buffer- ing	ХТСD	Output Level Select	Master Enable	IOA	IOB	Clear Select	Clock Select
Synchro	Synchronous preset	SYNC4 = 1	1	1	0	0*3	0	0	I	I	0*1	0	0	0	0
PWM mode	ode	0	I		PWM4 = 1	CMD1 = 0	CMD1 = 0	0	I	1	0	1	O*2	0	0
Output o	Output compare A	0	I		PWM4 = 0 CMD1 = 0	CMD1 = 0	CMD1 = 0	0		I	0	IOA2 = 0 Other bits unrestricted	0	0	0
Output o	Output compare B	0	I	1	0	CMD1 = 0	CMD1 = 0	0	I	I	0	0	IOB2 = 0 Other bits unrestricted	0	0
Input capture A	pture A	0	I	1	PWM4 = 0 CMD1 = 0	CMD1 = 0	CMD1 = 0	0	I	I	EA4 ignored IOA2 = 1 Other bits Other bits unrestricted unrestricted	IOA2 = 1 Other bits unrestricted	0	0	0
Input capture B	pture B	0			PWM4 = 0 CMD1 = 0	CMD1 = 0	CMD1 = 0	0		Ι	EB4 ignored Other bits unrestricted	0	IOA2 = 1 Other bits unrestricted	0	0
Counter clearing	Counter By compare clearing match/input capture A	0	I	I	0	Illegal setting: CMD1 = 1 CMD0 = 0	0*4	0	Ι	I	0*1	0	0	CCLR1 = 0 CCLR0 = 1	0
	By compare match/input capture B	0		I	0	Illegal setting: CMD1 = 1 CMD0 = 0	0*4	0	_	I	0*1	0	0	CCLR1 = 1 CCLR0 = 0	0
	Syn- chronous clear	SYNC4 = 1	I	I	0	Illegal setting: CMD1 = 1 CMD0 = 0	0*4	0	I	I	0*1	0	0	CCLR1 = 1 CCLR0 = 1	0
Complementary PWM mode	nentary ode	93	I	I	Ι	CMD1 = 1 CMD0 = 0	CMD1 = 1 $CMD0 = 0$	0	0	0	0	I		CCLR1 = 0 CCLR0 = 0	0#5
Reset-synch PWM mode	Reset-synchronized PWM mode	0	I	I	I	CMD1 = 1 CMD0 = 1	CMD1 = 1 CMD0 = 1	0	0	0	0	I		9*0	9*6
Buffering (BRA)	6	0	I	I	0	0	0	BFA4 = 1 Other bits unrestricted	I	I	0*1	0	0	0	0
Buffering (BRB)		0		I	0	0	0	BFA4 = 1 Other bits unrestricted	I		0*1	0	0	0	0
Legend:	Legend: O: Setting available (valid).	 Setting available (valid). Softing does not official this mode.). thic m	940											

Table 10.11 (e) ITU Operating Modes (Channel 4)

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-: Setting does not affect this mode.

1. Master enable bit settings are valid only during waveform output. Notes:

The input capture function cannot be used in PWM mode. If compare match A and compare match B occur simultaneously, the compare match signal is inhibited. Do not set both channels 3 and 4 for synchronous operation when complementary PWM mode is selected. κi κi

When reset-synchronized PWM mode is selected, TCNT4 operates independently and the counter clearing function is available. Waveform output is not affected. 4.0.0

In complementary PWM mode, select the same clock source for channels 3 and 4.

TCR4 settings are valid in reset-synchronized PWM mode, but TCNT4 operates independently, without affecting waveform output.



Section 11 Programmable Timing Pattern Controller

11.1 Overview

The H8/3048 Group has a built-in programmable timing pattern controller (TPC) that provides pulse outputs by using the 16-bit integrated timer unit (ITU) as a time base. The TPC pulse outputs are divided into 4-bit groups (group 3 to group 0) that can operate simultaneously and independently.

11.1.1 Features

TPC features are listed below.

• 16-bit output data

Maximum 16-bit data can be output. TPC output can be enabled on a bit-by-bit basis.

• Four output groups

Output trigger signals can be selected in 4-bit groups to provide up to four different 4-bit outputs.

• Selectable output trigger signals

Output trigger signals can be selected for each group from the compare-match signals of four ITU channels.

• Non-overlap mode

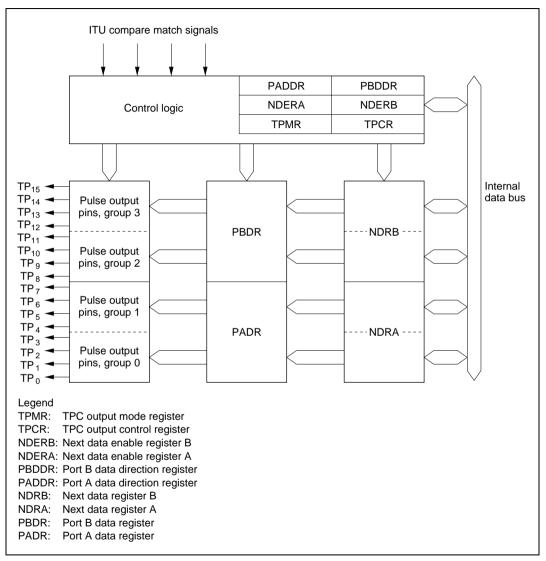
A non-overlap margin can be provided between pulse outputs.

• Can operate together with the DMA controller (DMAC)

The compare-match signals selected as trigger signals can activate the DMAC for sequential output of data without CPU intervention.

11.1.2 Block Diagram

Figure 11.1 shows a block diagram of the TPC.





11.1.3 TPC Pins

Table 11.1 summarizes the TPC output pins.

Table 11.1 TPC Pins

Name	Symbol	I/O	Function
TPC output 0	TP ₀	Output	Group 0 pulse output
TPC output 1	TP ₁	Output	_
TPC output 2	TP ₂	Output	_
TPC output 3	TP ₃	Output	_
TPC output 4	TP ₄	Output	Group 1 pulse output
TPC output 5	TP ₅	Output	_
TPC output 6	TP ₆	Output	_
TPC output 7	TP ₇	Output	_
TPC output 8	TP ₈	Output	Group 2 pulse output
TPC output 9	TP ₉	Output	_
TPC output 10	TP ₁₀	Output	_
TPC output 11	TP ₁₁	Output	_
TPC output 12	TP ₁₂	Output	Group 3 pulse output
TPC output 13	TP ₁₃	Output	_
TPC output 14	TP ₁₄	Output	_
TPC output 15	TP ₁₅	Output	-

11.1.4 Registers

Table 11.2 summarizes the TPC registers.

Table 11.2 TPC Registers

Address*1	Name	Abbreviation	R/W	Initial Value
H'FFD1	Port A data direction register	PADDR	W	H'00
H'FFD3	Port A data register	PADR	R/(W)* ²	H'00
H'FFD4	Port B data direction register	PBDDR	W	H'00
H'FFD6	Port B data register	PBDR	R/(W)*2	H'00
H'FFA0	TPC output mode register	TPMR	R/W	H'F0
H'FFA1	TPC output control register	TPCR	R/W	H'FF
H'FFA2	Next data enable register B	NDERB	R/W	H'00
H'FFA3	Next data enable register A	NDERA	R/W	H'00
H'FFA5/ H'FFA7* ³	Next data register A	NDRA	R/W	H'00
H'FFA4 H'FFA6* ³	Next data register B	NDRB	R/W	H'00

Notes: 1. Lower 16 bits of the address.

2. Bits used for TPC output cannot be written.

3. The NDRA address is H'FFA5 when the same output trigger is selected for TPC output groups 0 and 1 by settings in TPCR. When the output triggers are different, the NDRA address is H'FFA7 for group 0 and H'FFA5 for group 1. Similarly, the address of NDRB is H'FFA4 when the same output trigger is selected for TPC output groups 2 and 3 by settings in TPCR. When the output triggers are different, the NDRB address is H'FFA6 for group 2 and H'FFA4 for group 3.



11.2 Register Descriptions

11.2.1 Port A Data Direction Register (PADDR)

PADDR is an 8-bit write-only register that selects input or output for each pin in port A.

Bit	7	6	5	4	3	2	1	0
	PA7DDR	PA ₆ DDR	PA ₅ DDR	PA ₄ DDR	PA ₃ DDR	PA ₂ DDR	PA ₁ DDR	PA ₀ DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W
				These bits	t a directio s select inp port A pin	out or		

Port A is multiplexed with pins TP_7 to TP_0 . Bits corresponding to pins used for TPC output must be set to 1. For further information about PADDR, see section 9.11, Port A.

11.2.2 Port A Data Register (PADR)

PADR is an 8-bit readable/writable register that stores TPC output data for groups 0 and 1, when these TPC output groups are used.

Bit	7	6	5	4	3	2	1	0
	PA ₇	PA_6	PA_5	PA ₄	PA ₃	PA ₂	PA ₁	PA ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*
				Port A da These bits	ta 7 to 0 s store out	put data		

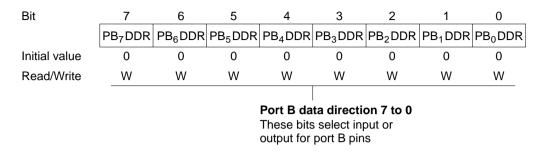
for TPC output groups 0 and 1

Note: * Bits selected for TPC output by NDERA settings become read-only bits.

For further information about PADR, see section 9.11, Port A.

11.2.3 Port B Data Direction Register (PBDDR)

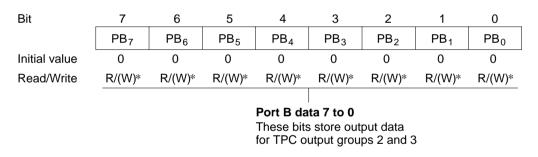
PBDDR is an 8-bit write-only register that selects input or output for each pin in port B.



Port B is multiplexed with pins TP_{15} to TP_8 . Bits corresponding to pins used for TPC output must be set to 1. For further information about PBDDR, see section 9.12, Port B.

11.2.4 Port B Data Register (PBDR)

PBDR is an 8-bit readable/writable register that stores TPC output data for groups 2 and 3, when these TPC output groups are used.



Note: * Bits selected for TPC output by NDERB settings become read-only bits.

For further information about PBDR, see section 9.12, Port B.



11.2.5 Next Data Register A (NDRA)

NDRA is an 8-bit readable/writable register that stores the next output data for TPC output groups 1 and 0 (pins TP_7 to TP_0). During TPC output, when an ITU compare match event specified in TPCR occurs, NDRA contents are transferred to the corresponding bits in PADR. The address of NDRA differs depending on whether TPC output groups 0 and 1 have the same output trigger or different output triggers.

NDRA is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

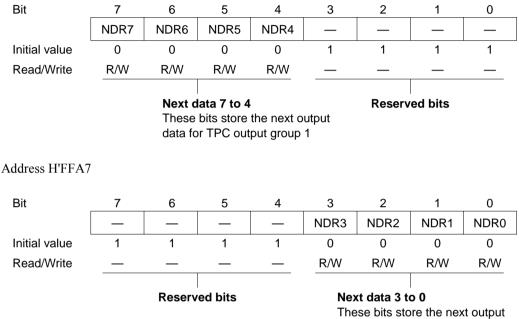
Same Trigger for TPC Output Groups 0 and 1: If TPC output groups 0 and 1 are triggered by the same compare match event, the NDRA address is H'FFA5. The upper 4 bits belong to group 1 and the lower 4 bits to group 0. Address H'FFA7 consists entirely of reserved bits that cannot be modified and are always read as 1.

Address H'FFA5

Bit	7	6	5	4	3	2	1	0
	NDR7	NDR6	NDR5	NDR4	NDR3	NDR2	NDR1	NDR0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Address H'FFA7	Th da	ext data 7 ese bits st ta for TPC	ore the ne		The	t data 3 to se bits stor for TPC o	e the next	•
Bit	7	6	5	4	3	2	1	0
	_	_	_	_				
Initial value	1	1	1	1	1	1	1	1
Read/Write		—	_	—		—	—	_
				Reserv	ed bits			

Different Triggers for TPC Output Groups 0 and 1: If TPC output groups 0 and 1 are triggered by different compare match events, the address of the upper 4 bits of NDRA (group 1) is H'FFA5 and the address of the lower 4 bits (group 0) is H'FFA7. Bits 3 to 0 of address H'FFA5 and bits 7 to 4 of address H'FFA7 are reserved bits that cannot be modified and are always read as 1.

Address H'FFA5



data for TPC output group 0



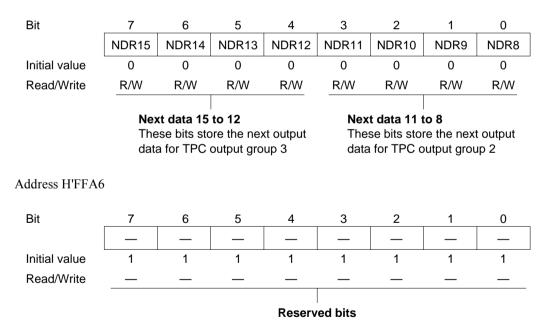
11.2.6 Next Data Register B (NDRB)

NDRB is an 8-bit readable/writable register that stores the next output data for TPC output groups 3 and 2 (pins TP_{15} to TP_8). During TPC output, when an ITU compare match event specified in TPCR occurs, NDRB contents are transferred to the corresponding bits in PBDR. The address of NDRB differs depending on whether TPC output groups 2 and 3 have the same output trigger or different output triggers.

NDRB is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

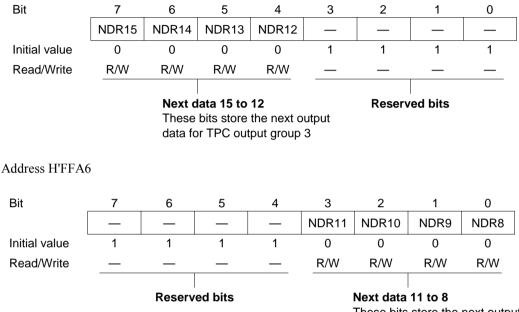
Same Trigger for TPC Output Groups 2 and 3: If TPC output groups 2 and 3 are triggered by the same compare match event, the NDRB address is H'FFA4. The upper 4 bits belong to group 3 and the lower 4 bits to group 2. Address H'FFA6 consists entirely of reserved bits that cannot be modified and are always read as 1.

Address H'FFA4



Different Triggers for TPC Output Groups 2 and 3: If TPC output groups 2 and 3 are triggered by different compare match events, the address of the upper 4 bits of NDRB (group 3) is H'FFA4 and the address of the lower 4 bits (group 2) is H'FFA6. Bits 3 to 0 of address H'FFA4 and bits 7 to 4 of address H'FFA6 are reserved bits that cannot be modified and are always read as 1.

Address H'FFA4



These bits store the next output data for TPC output group 2



11.2.7 Next Data Enable Register A (NDERA)

NDERA is an 8-bit readable/writable register that enables or disables TPC output groups 1 and 0 (TP₇ to TP₀) on a bit-by-bit basis.

Bit	7	6	5	4	3	2	1	0
	NDER7	NDER6	NDER5	NDER4	NDER3	NDER2	NDER1	NDER0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Next data enable 7 to 0 These bits enable or disable TPC output groups 1 and 0

If a bit is enabled for TPC output by NDERA, then when the ITU compare match event selected in the TPC output control register (TPCR) occurs, the NDRA value is automatically transferred to the corresponding PADR bit, updating the output value. If TPC output is disabled, the bit value is not transferred from NDRA to PADR and the output value does not change.

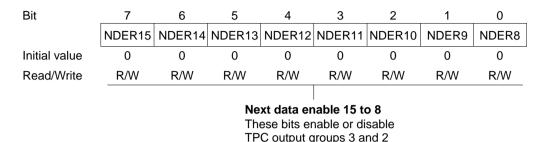
NDERA is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 0—Next Data Enable 7 to 0 (NDER7 to NDER0): These bits enable or disable TPC output groups 1 and 0 (TP_7 to TP_0) on a bit-by-bit basis.

Bits 7 to 0: NDER7 to NDER0	Description	
0	TPC outputs TP ₇ to TP ₀ are disabled (NDR7 to NDR0 are not transferred to PA ₇ to PA ₀)	(Initial value)
1	TPC outputs TP ₇ to TP ₀ are enabled (NDR7 to NDR0 are transferred to PA ₇ to PA ₀)	

11.2.8 Next Data Enable Register B (NDERB)

NDERB is an 8-bit readable/writable register that enables or disables TPC output groups 3 and 2 (TP_{15} to TP_8) on a bit-by-bit basis.



If a bit is enabled for TPC output by NDERB, then when the ITU compare match event selected in the TPC output control register (TPCR) occurs, the NDRB value is automatically transferred to the corresponding PBDR bit, updating the output value. If TPC output is disabled, the bit value is not transferred from NDRB to PBDR and the output value does not change.

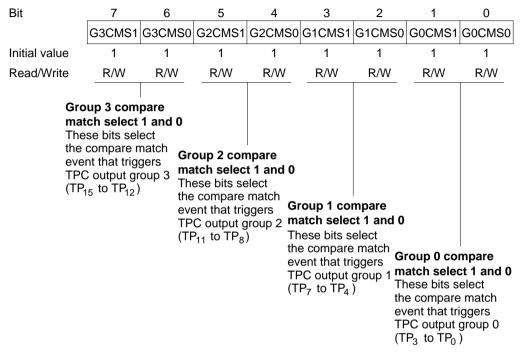
NDERB is initialized to H'00 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 0—Next Data Enable 15 to 8 (NDER15 to NDER8): These bits enable or disable TPC output groups 3 and 2 (TP_{15} to TP_8) on a bit-by-bit basis.

Bits 7 to 0: NDER15 to NDER8	Description	
0	TPC outputs TP ₁₅ to TP ₈ are disabled (NDR15 to NDR8 are not transferred to PB ₇ to PB ₀)	(Initial value)
1	TPC outputs TP ₁₅ to TP ₈ are enabled (NDR15 to NDR8 are transferred to PB ₇ to PB ₀)	

11.2.9 TPC Output Control Register (TPCR)

TPCR is an 8-bit readable/writable register that selects output trigger signals for TPC outputs on a group-by-group basis.



TPCR is initialized to H'FF by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 and 6—Group 3 Compare Match Select 1 and 0 (G3CMS1, G3CMS0): These bits select the compare match event that triggers TPC output group 3 (TP₁₅ to TP₁₂).

Bit 7: G3CMS1	Bit 6: G3CMS0	Description
0	0	TPC output group 3 (TP $_{15}$ to TP $_{12}$) is triggered by compare match in ITU channel 0
	1	TPC output group 3 (TP ₁₅ to TP ₁₂) is triggered by compare match in ITU channel 1
1	0	TPC output group 3 (TP ₁₅ to TP ₁₂) is triggered by compare match in ITU channel 2
	1	TPC output group 3 (TP15 to TP12) is triggered by comparematch in ITU channel 3(Initial value)

Bits 5 and 4—Group 2 Compare Match Select 1 and 0 (G2CMS1, G2CMS0): These bits select the compare match event that triggers TPC output group 2 (TP₁₁ to TP₈).

Bit 5: G2CMS1	Bit 4: G2CMS0	Description
0	0	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in ITU channel 0
	1	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in ITU channel 1
1	0	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in ITU channel 2
	1	TPC output group 2 (TP11 to TP8) is triggered by comparematch in ITU channel 3(Initial value)

Bits 3 and 2—Group 1 Compare Match Select 1 and 0 (G1CMS1, G1CMS0): These bits
select the compare match event that triggers TPC output group 1 (TP ₇ to TP ₄).

Bit 3: G1CMS1	Bit 2: G1CMS0	Description		
0	0	TPC output group 1 (TP ₇ to TP ₄) is triggered by compare match in ITU channel 0		
	1	TPC output group 1 (TP ₇ to TP ₄) is triggered by compare match in ITU channel 1		
1	0	TPC output group 1 (TP ₇ to TP ₄) is triggered by compar- match in ITU channel 2		
	1	TPC output group 1 (TP7 to TP4) is triggered by comparematch in ITU channel 3(Initial value)		

Bits 1 and 0—Group 0 Compare Match Select 1 and 0 (G0CMS1, G0CMS0): These bits select the compare match event that triggers TPC output group 0 (TP₃ to TP₀).

Bit 0: G0CMS0	Description
0	TPC output group 0 (TP $_3$ to TP $_0$) is triggered by compare match in ITU channel 0
1	TPC output group 0 (TP $_3$ to TP $_0$) is triggered by compare match in ITU channel 1
0	TPC output group 0 (TP $_3$ to TP $_0$) is triggered by compare match in ITU channel 2
1	TPC output group 0 (TP $_3$ to TP $_0$) is triggered by compare match in ITU channel 3 (Initial value)
	0

11.2.10 TPC Output Mode Register (TPMR)

TPMR is an 8-bit readable/writable register that selects normal or non-overlapping TPC output for each group.

Bit	7	6	5	4	3	2	1	0
			—	_	G3NOV	G2NOV	G1NOV	G0NOV
Initial value	1	1	1	1	0	0	0	0
Read/Write		—	—	_	R/W	R/W	R/W	R/W
	Reserved bits							
Group 3 I Selects no output for	on-overlap	ping TPC	, ₁₂)					
	on-overlap	ap pping TPC TP ₁₁ to TP	8 ₈)					
Group 1 I Selects no output for	on-overlap	ping TPC	,)					
Group 0		•						

Selects non-overlapping TPC output for group 0 (TP₃ to TP₀)

The output trigger period of a non-overlapping TPC output waveform is set in general register B (GRB) in the ITU channel selected for output triggering. The non-overlap margin is set in general register A (GRA). The output values change at compare match A and B. For details see section 11.3.4, Non-Overlapping TPC Output.

TPMR is initialized to H'F0 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 4—Reserved: Read-only bits, always read as 1.

Bit 3—Group 3 Non-Overlap (G3NOV): Selects normal or non-overlapping TPC output for group 3 (TP₁₅ to TP₁₂).

Bit 3: G3NOV	Description
0	Normal TPC output in group 3 (output values change at compare match A in the selected ITU channel) (Initial value)
1	Non-overlapping TPC output in group 3 (independent 1 and 0 output at compare match A and B in the selected ITU channel)

Bit 2—Group 2 Non-Overlap (G2NOV): Selects normal or non-overlapping TPC output for group 2 (TP₁₁ to TP₈).

Bit 2: G2NOV	Description	
0	Normal TPC output in group 2 (output values change at compare match A in the selected ITU channel) (Initial value)	
1	Non-overlapping TPC output in group 2 (independent 1 and 0 output at compare match A and B in the selected ITU channel)	

Bit 1—Group 1 Non-Overlap (G1NOV): Selects normal or non-overlapping TPC output for group 1 (TP₇ to TP₄).

Bit 1: G1NOV	Description	
0	Normal TPC output in group 1 (output values change at compare match A in the selected ITU channel) (Initial valu	
1	Non-overlapping TPC output in group 1 (independent 1 and 0 output at compare match A and B in the selected ITU channel)	

Bit 0—Group 0 Non-Overlap (G0NOV): Selects normal or non-overlapping TPC output for group 0 (TP₃ to TP₀).

Bit 0: G0NOV	Description	
0	Normal TPC output in group 0 (output values change at compare match A in the selected ITU channel) (Initial value)
1	Non-overlapping TPC output in group 0 (independent 1 and 0 output at compare match A and B in the selected ITU channel)	_

11.3 Operation

11.3.1 Overview

When corresponding bits in PADDR or PBDDR and NDERA or NDERB are set to 1, TPC output is enabled. The TPC output initially consists of the corresponding PADR or PBDR contents. When a compare-match event selected in TPCR occurs, the corresponding NDRA or NDRB bit contents are transferred to PADR or PBDR to update the output values.

Figure 11.2 illustrates the TPC output operation. Table 11.3 summarizes the TPC operating conditions.

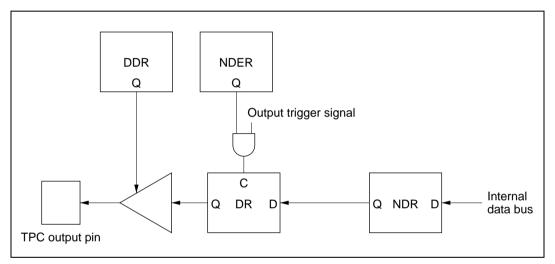


Figure 11.2 TPC Output Operation

Table 11.3 TPC Operating Conditions

NDER	DDR	Pin Function
0	0	Generic input port
	1	Generic output port
1	0	Generic input port (but the DR bit is a read-only bit, and when compare match occurs, the NDR bit value is transferred to the DR bit)
	1	TPC pulse output

Sequential output of up to 16-bit patterns is possible by writing new output data to NDRA and NDRB before the next compare match. For information on non-overlapping operation, see section 11.3.4, Non-Overlapping TPC Output.

11.3.2 Output Timing

If TPC output is enabled, NDRA/NDRB contents are transferred to PADR/PBDR and output when the selected compare match event occurs. Figure 11.3 shows the timing of these operations for the case of normal output in groups 2 and 3, triggered by compare match A.

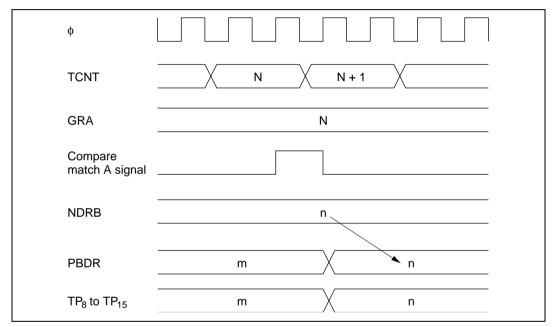


Figure 11.3 Timing of Transfer of Next Data Register Contents and Output (Example)



11.3.3 Normal TPC Output

Sample Setup Procedure for Normal TPC Output: Figure 11.4 shows a sample procedure for setting up normal TPC output.

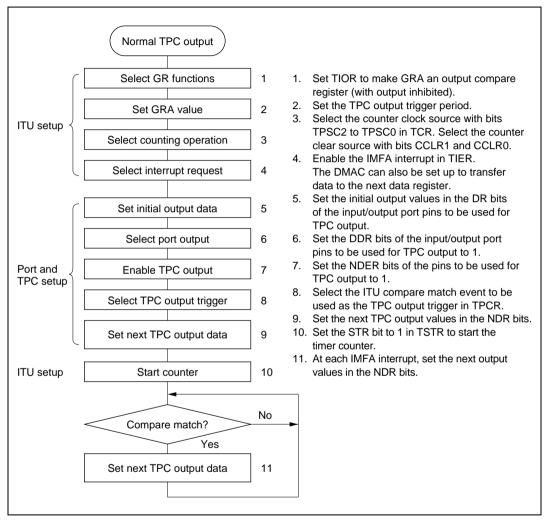
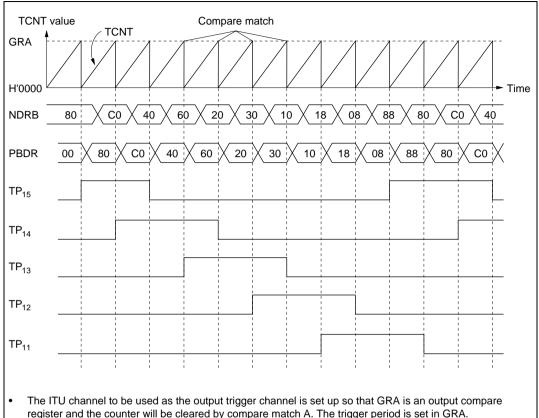


Figure 11.4 Setup Procedure for Normal TPC Output (Example)

Example of Normal TPC Output (Example of Five-Phase Pulse Output): Figure 11.5 shows an example in which the TPC is used for cyclic five-phase pulse output.



- The IMIEA bit is set to 1 in TIER to enable the compare match A interrupt.
- H'F8 is written in PBDDR and NDERB, and bits G3CMS1, G3CMS0, G2CMS1, and G2CMS0 are set in TPCR to select compare match in the ITU channel set up in step 1 as the output trigger. Output data H'80 is written in NDRB.
- The timer counter in this ITU channel is started. When compare match A occurs, the NDRB contents
 are transferred to PBDR and output. The compare match/input capture A (IMFA) interrupt service routine
 writes the next output data (H'C0) in NDRB.
- Five-phase overlapping pulse output (one or two phases active at a time) can be obtained by writing H'40, H'60, H'20, H'30, H'10, H'18, H'08, H'88... at successive IMFA interrupts. If the DMAC is set for activation by this interrupt, pulse output can be obtained without loading the CPU.

Figure 11.5 Normal TPC Output Example (Five-Phase Pulse Output)

11.3.4 Non-Overlapping TPC Output

Sample Setup Procedure for Non-Overlapping TPC Output: Figure 11.6 shows a sample procedure for setting up non-overlapping TPC output.

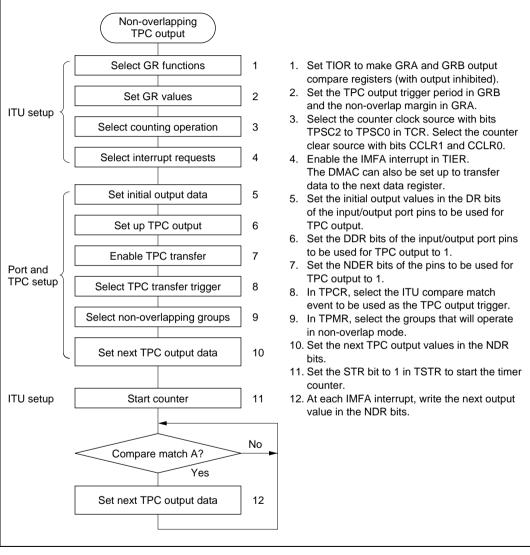


Figure 11.6 Setup Procedure for Non-Overlapping TPC Output (Example)

Example of Non-Overlapping TPC Output (Example of Four-Phase Complementary Non-Overlapping Output): Figure 11.7 shows an example of the use of TPC output for four-phase complementary non-overlapping pulse output.

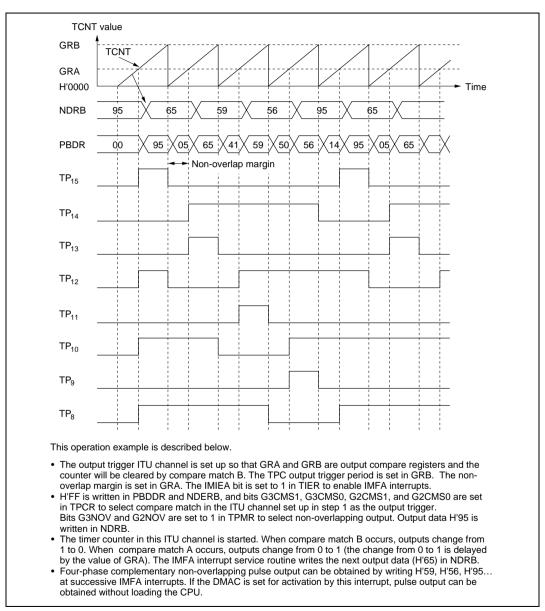


Figure 11.7 Non-Overlapping TPC Output Example (Four-Phase Complementary Non-Overlapping Pulse Output)

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11.3.5 TPC Output Triggering by Input Capture

TPC output can be triggered by ITU input capture as well as by compare match. If GRA and GRB functions as an input capture register in the ITU channel selected in TPCR, TPC output will be triggered by the input capture signal. Figure 11.8 shows the timing.

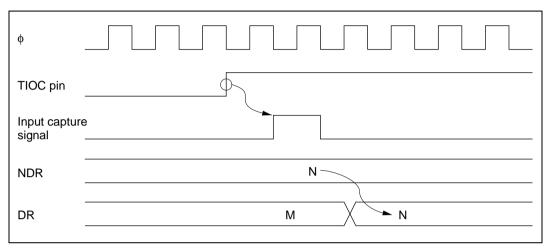


Figure 11.8 TPC Output Triggering by Input Capture (Example)

11.4 Usage Notes

11.4.1 Operation of TPC Output Pins

 TP_0 to TP_{15} are multiplexed with ITU, DMAC, address bus, and other pin functions. When ITU, DMAC, or address output is enabled, the corresponding pins cannot be used for TPC output. The data transfer from NDR bits to DR bits takes place, however, regardless of the usage of the pin.

Pin functions should be changed only under conditions in which the output trigger event will not occur.

11.4.2 Note on Non-Overlapping Output

During non-overlapping operation, the transfer of NDR bit values to DR bits takes place as follows.

- 1. NDR bits are always transferred to DR bits at compare match A.
- 2. At compare match B, NDR bits are transferred only if their value is 0. Bits are not transferred if their value is 1.

Figure 11.9 illustrates the non-overlapping TPC output operation.

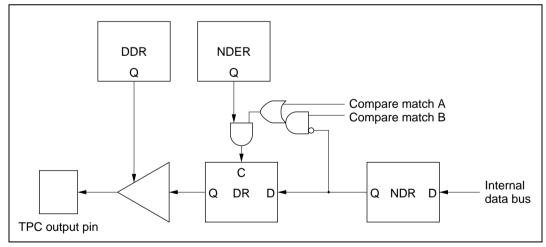


Figure 11.9 Non-Overlapping TPC Output

Therefore, 0 data can be transferred ahead of 1 data by making compare match B occur before compare match A. NDR contents should not be altered during the interval from compare match B to compare match A (the non-overlap margin).

This can be accomplished by having the IMFA interrupt service routine write the next data in NDR, or by having the IMFA interrupt activate the DMAC. The next data must be written before the next compare match B occurs.

Figure 11.10 shows the timing relationships.

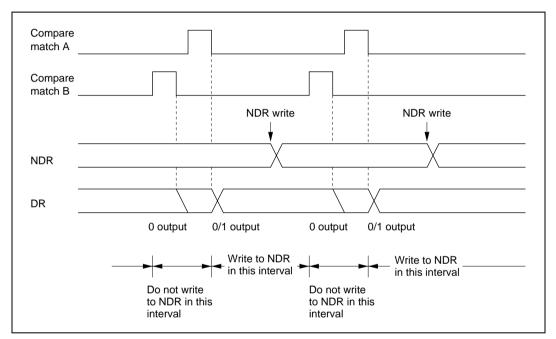


Figure 11.10 Non-Overlapping Operation and NDR Write Timing



Section 12 Watchdog Timer

12.1 Overview

The H8/3048 Group has an on-chip watchdog timer (WDT). The WDT has two selectable functions: it can operate as a watchdog timer to supervise system operation, or it can operate as an interval timer. As a watchdog timer, it generates a reset signal for the chip if a system crash allows the timer counter (TCNT) to overflow before being rewritten. In interval timer operation, an interval timer interrupt is requested at each TCNT overflow.

12.1.1 Features

WDT features are listed below.

- Selection of eight counter clock sources φ/2, φ/32, φ/64, φ/128, φ/256, φ/512, φ/2048, or φ/4096
- Interval timer option
- Timer counter overflow generates a reset signal or interrupt. The reset signal is generated in watchdog timer operation. An interval timer interrupt is generated in interval timer operation.
- Watchdog timer reset signal resets the entire chip internally, and can also be output externally. The reset signal generated by timer counter overflow during watchdog timer operation resets the entire chip internally. An external reset signal can be output from the RESO pin to reset other system devices simultaneously.

12.1.2 Block Diagram

Figure 12.1 shows a block diagram of the WDT.

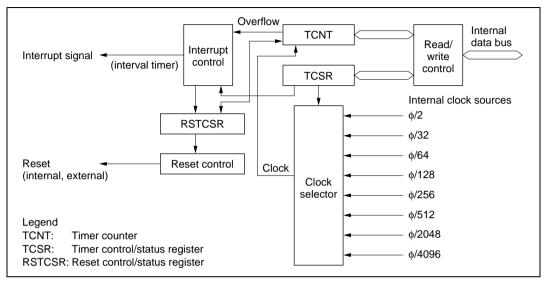


Figure 12.1 WDT Block Diagram

12.1.3 Pin Configuration

Table 12.1 describes the WDT output pin.

Table 12.1 WDT Pin

Name	Abbreviation	I/O	Function
Reset output	RESO	Output*	External output of the watchdog timer reset signal

Note: * Open-drain output.



12.1.4 Register Configuration

Table 12.2 summarizes the WDT registers.

Table 12.2 WDT Registers

lress* ¹		Abbre-		Initial
Read	Name	viation	R/W	Value
H'FFA8	Timer control/status register	TCSR	R/(W)* ³	H'18
H'FFA9	Timer counter	TCNT	R/W	H'00
H'FFAB	Reset control/status register	RSTCSR	R/(W)* ³	H'3F
	Read H'FFA8 H'FFA9	ReadNameH'FFA8Timer control/status registerH'FFA9Timer counter	ReadNameAbbre-viationH'FFA8Timer control/status registerTCSRH'FFA9Timer counterTCNT	ReadNameAbbreviationH'FFA8Timer control/status registerTCSRR/(W)*3H'FFA9Timer counterTCNTR/W

Notes: 1. Lower 16 bits of the address.

2. Write word data starting at this address.

3. Only 0 can be written in bit 7, to clear the flag.

12.2 Register Descriptions

12.2.1 Timer Counter (TCNT)

TCNT is an 8-bit readable and writable* up-counter.

Bit	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

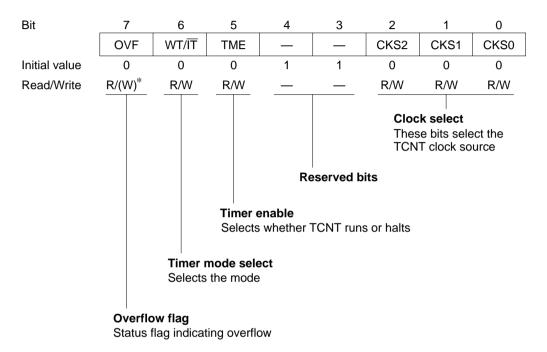
When the TME bit is set to 1 in TCSR, TCNT starts counting pulses generated from an internal clock source selected by bits CKS2 to CKS0 in TCSR. When the count overflows (changes from H'FF to H'00), the OVF bit is set to 1 in TCSR. TCNT is initialized to H'00 by a reset and when the TME bit is cleared to 0.

Note: * TCNT is write-protected by a password. For details see section 12.2.4, Notes on Register Access.

12.2.2 Timer Control/Status Register (TCSR)

TCSR is an 8-bit readable and writable* register. Its functions include selecting the timer mode and clock source.

Note: * TCSR differs from other registers in being more difficult to write. For details see section 12.2.4, Notes on Register Access.



Note: * Only 0 can be written, to clear the flag.

Bits 7 to 5 are initialized to 0 by a reset and in standby mode. Bits 2 to 0 are initialized to 0 by a reset. In software standby mode bits 2 to 0 are not initialized, but retain their previous values.

Bit 7—Overflow Flag (OVF): This status flag indicates that the timer counter has overflowed from H'FF to H'00.

Bit 7: OVF	Description	
0	[Clearing condition]	
	Cleared by reading OVF when OVF = 1, then writing 0 in OVF	(Initial value)
1	[Setting condition]	
	Set when TCNT changes from H'FF to H'00	

Bit 6—Timer Mode Select (WT/TT): Selects whether to use the WDT as a watchdog timer or interval timer. If used as an interval timer, the WDT generates an interval timer interrupt request when TCNT overflows. If used as a watchdog timer, the WDT generates a reset signal when TCNT overflows.

Bit 6: WT/IT	Description	
0	Interval timer: requests interval timer interrupts	(Initial value)
1	Watchdog timer: generates a reset signal	

Bit 5—Timer Enable (TME): Selects whether TCNT runs or is halted.

When $WT/\overline{IT} = 1$, clear the SYSCR software standby bit (SSBY) to 0, then set the TME to 1. When SSBY is set to 1, clear TME to 0.

Bit 5: TME	Description	
0	TCNT is initialized to H'00 and halted	(Initial value)
1	TCNT is counting and CPU interrupt requests are enabled	

Bits 4 and 3-Reserved: Read-only bits, always read as 1.

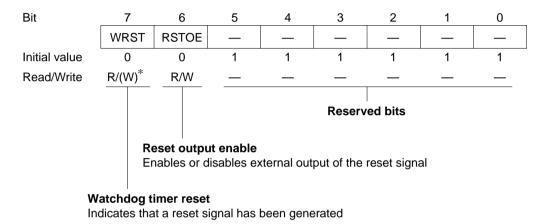
Bits 2 to 0—Clock Select 2 to 0 (CKS2/1/0): These bits select one of eight internal clock sources, obtained by prescaling the system clock (ϕ), for input to TCNT.

Bit 2: CKS2	Bit 1: CKS1	Bit 0: CKS0	Description	
0	0	0	ф/2	(Initial value)
		1	ф/32	
	1	0	ф/64	
		1	ф/128	
1	0	0	ф/256	
		1	ф/512	
	1	0	ф/2048	
		1	ф/4096	

12.2.3 Reset Control/Status Register (RSTCSR)

RSTCSR is an 8-bit readable and writable* register that indicates when a reset signal has been generated by watchdog timer overflow, and controls external output of the reset signal.

Note: * RSTCSR differs from other registers in being more difficult to write. For details see section 12.2.4, Notes on Register Access.



Note: * Only 0 can be written in bit 7, to clear the flag.

Bits 7 and 6 are initialized by input of a reset signal at the $\overline{\text{RES}}$ pin. They are not initialized by reset signals generated by watchdog timer overflow.

Bit 7—Watchdog Timer Reset (WRST): During watchdog timer operation, this bit indicates that TCNT has overflowed and generated a reset signal. This reset signal resets the entire chip internally. If bit RSTOE is set to 1, this reset signal is also output (low) at the RESO pin to initialize external system devices.

Bit 7: WRST	Description		
0	[Clearing conditions]		
	Cleared to 0 by reset signal input at RES pin	(Initial value)	
	Cleared by reading WRST when WRST = 1, then writing 0 in WRST		
1	[Setting condition]		
	Set when TCNT overflow generates a reset signal during watchdog timer operation		

Bit 6—Reset Output Enable (RSTOE): Enables or disables external output at the RESO pin of the reset signal generated if TCNT overflows during watchdog timer operation.

Bit 6: RSTOE	Description	
0	Reset signal is not output externally	(Initial value)
1	Reset signal is output externally	

Bits 5 to 0—Reserved: Read-only bits, always read as 1.

12.2.4 Notes on Register Access

The watchdog timer's TCNT, TCSR, and RSTCSR registers differ from other registers in being more difficult to write. The procedures for writing and reading these registers are given below.

Writing to TCNT and TCSR: These registers must be written by a word transfer instruction. They cannot be written by byte instructions. Figure 12.2 shows the format of data written to TCNT and TCSR. TCNT and TCSR both have the same write address. The write data must be contained in the lower byte of the written word. The upper byte must contain H'5A (password for TCNT) or H'A5 (password for TCSR). This transfers the write data from the lower byte to TCNT or TCSR.

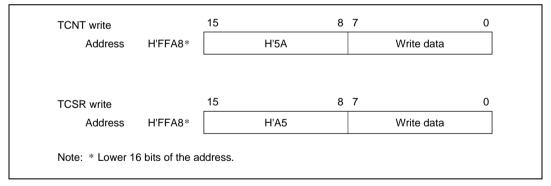
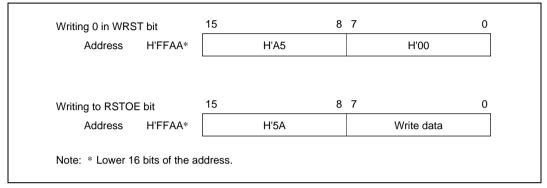


Figure 12.2 Format of Data Written to TCNT and TCSR

Section 12 Watchdog Timer

Writing to RSTCSR: RSTCSR must be written by a word transfer instruction. It cannot be written by byte transfer instructions. Figure 12.3 shows the format of data written to RSTCSR. To write 0 in the WRST bit, the write data must have H'A5 in the upper byte and H'00 in the lower byte. The H'00 in the lower byte clears the WRST bit in RSTCSR to 0. To write to the RSTOE bit, the upper byte must contain H'5A and the lower byte must contain the write data. Writing this word transfers a write data value into the RSTOE bit.





Reading TCNT, TCSR, and RSTCSR: These registers are read like other registers. Byte access instructions can be used. The read addresses are H'FFA8 for TCSR, H'FFA9 for TCNT, and H'FFAB for RSTCSR, as listed in table 12.3.

Table 12.3 Read Addresses of TCNT, TCSR, and RSTCSR

Address*	Register
H'FFA8	TCSR
H'FFA9	TCNT
H'FFAB	RSTCSR

Note: * Lower 16 bits of the address.



12.3 Operation

Operations when the WDT is used as a watchdog timer and as an interval timer are described below.

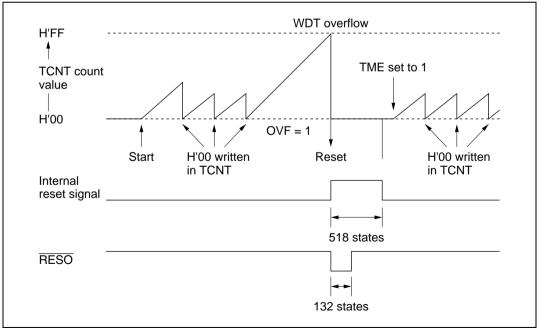
12.3.1 Watchdog Timer Operation

Figure 12.4 illustrates watchdog timer operation. To use the WDT as a watchdog timer, set the WT/\overline{IT} and TME bits to 1 in TCSR. Software must prevent TCNT overflow by rewriting the TCNT value (normally by writing H'00) before overflow occurs. If TCNT fails to be rewritten and overflows due to a system crash etc., the chip is internally reset for a duration of 518 states.

The watchdog reset signal can be externally output from the $\overline{\text{RESO}}$ pin to reset external system devices. The reset signal is output externally for 132 states. External output can be enabled or disabled by the RSTOE bit in RSTCSR.

A watchdog reset has the same vector as a reset generated by input at the $\overline{\text{RES}}$ pin. Software can distinguish a $\overline{\text{RES}}$ reset from a watchdog reset by checking the WRST bit in RSTCSR.

If a $\overline{\text{RES}}$ reset and a watchdog reset occur simultaneously, the $\overline{\text{RES}}$ reset takes priority.





12.3.2 Interval Timer Operation

Figure 12.5 illustrates interval timer operation. To use the WDT as an interval timer, clear bit WT/\overline{IT} to 0 and set bit TME to 1 in TCSR. An interval timer interrupt request is generated at each TCNT overflow. This function can be used to generate interval timer interrupts at regular intervals.

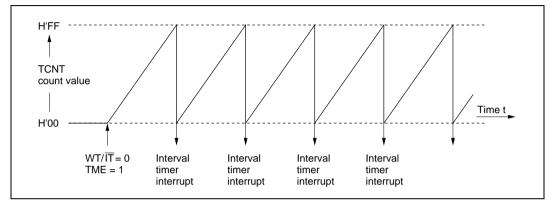


Figure 12.5 Interval Timer Operation

12.3.3 Timing of Setting of Overflow Flag (OVF)

Figure 12.6 shows the timing of setting of the OVF flag in TCSR. The OVF flag is set to 1 when TCNT overflows. At the same time, a reset signal is generated in watchdog timer operation, or an interval timer interrupt is generated in interval timer operation.

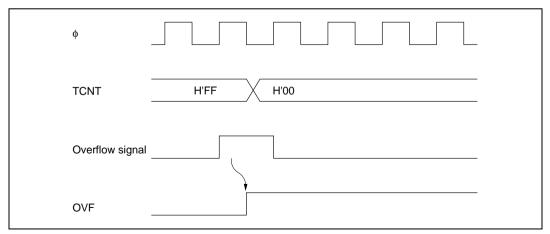


Figure 12.6 Timing of Setting of OVF

12.3.4 Timing of Setting of Watchdog Timer Reset Bit (WRST)

The WRST bit in RSTCSR is valid when bits WT/\overline{IT} and TME are both set to 1 in TCSR.

Figure 12.7 shows the timing of setting of WRST and the internal reset timing. The WRST bit is set to 1 when TCNT overflows and OVF is set to 1. At the same time an internal reset signal is generated for the entire chip. This internal reset signal clears OVF to 0, but the WRST bit remains set to 1. The reset routine must therefore clear the WRST bit.

ф	
TCNT	H'FF H'00
Overflow sig	Inal
OVF	
WDT interna reset	al
WRST	

Figure 12.7 Timing of Setting of WRST Bit and Internal Reset

12.4 Interrupts

During interval timer operation, an overflow generates an interval timer interrupt (WOVI). The interval timer interrupt is requested whenever the OVF bit is set to 1 in TCSR.

12.5 Usage Notes

Contention between TCNT Write and Increment: If a timer counter clock pulse is generated during the T_3 state of a write cycle to TCNT, the write takes priority and the timer count is not incremented. See figure 12.8.

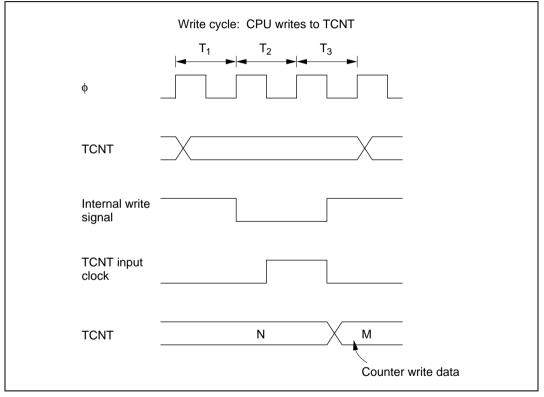


Figure 12.8 Contention between TCNT Write and Increment

Changing CKS2 to CKS0 Values: Halt TCNT by clearing the TME bit to 0 in TCSR before changing the values of bits CKS2 to CKS0.

12.6 Notes

This chip incorporates an WDT. The timer counter value of the on-chip WDT is not rewritten, even if a system crash occurs. If an overflow occurs, a reset signal is generated and the chip is reset.

However, if the following three events occur due to a CPU overrun, for example, the above operations cannot be guaranteed since the WDT and the CPU are incorporated in the same chip.

- When the internal I/O registers related to the on-chip WDT are rewritten.
- When software standby mode is incorrectly entered.
- When the break mode is incorrectly entered.

In addition, as stated in the NMI above, if an abnormal level is input into the power supply pins or the system control pins, correct operations cannot be guaranteed.

Except the above cases, the on-chip WDT functions as a device that supports recovery from a system crash. Accordingly, when a fail-safe function is required in your system, an additional circuit may be required as necessary.



Section 13 Serial Communication Interface

13.1 Overview

The H8/3048 Group has a serial communication interface (SCI) with two independent channels. The two channels are functionally identical. The SCI can communicate in asynchronous or synchronous mode. It also has a multiprocessor communication function for serial communication among two or more processors.

When the SCI is not used, it can be halted to conserve power. Each SCI channel can be halted independently. For details see section 21.6, Module Standby Function.

Channel 0 (SCI0) also has a smart card interface function conforming to the ISO/IEC7816-3 (Identification Card) standard. This function supports serial communication with a smart card. For details, see section 14, Smart Card Interface.

13.1.1 Features

SCI features are listed below.

- Selection of asynchronous or synchronous mode for serial communication
 - Asynchronous mode

Serial data communication is synchronized one character at a time. The SCI can communicate with a universal asynchronous receiver/transmitter (UART), asynchronous communication interface adapter (ACIA), or other chip that employs standard asynchronous serial communication. It can also communicate with two or more other processors using the multiprocessor communication function. There are twelve selectable serial data communication formats.

- Data length: 7 or 8 bits
- Stop bit length: 1 or 2 bits
- Parity bit: even, odd, or none
- Multiprocessor bit: 1 or 0
- Receive error detection: parity, overrun, and framing errors
- Break detection: by reading the RxD level directly when a framing error occurs
 - Synchronous mode

Serial data communication is synchronized with a clock signal. The SCI can communicate with other chips having a synchronous communication function. There is one serial data communication format.

- Data length: 8 bits
- Receive error detection: overrun errors
- Full duplex communication

The transmitting and receiving sections are independent, so the SCI can transmit and receive simultaneously. The transmitting and receiving sections are both double-buffered, so serial data can be transmitted and received continuously.

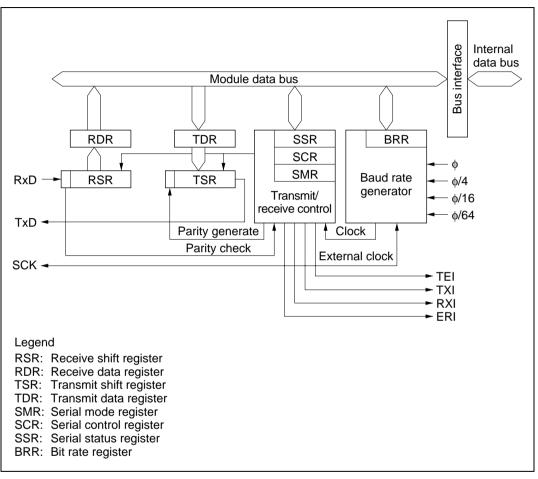
- Built-in baud rate generator with selectable bit rates
- Selectable transmit/receive clock sources: internal clock from baud rate generator, or external clock from the SCK pin.
- Four types of interrupts

Transmit-data-empty, transmit-end, receive-data-full, and receive-error interrupts are requested independently. The transmit-data-empty and receive-data-full interrupts from SCI0 can activate the DMA controller (DMAC) to transfer data.



13.1.2 Block Diagram

Figure 13.1 shows a block diagram of the SCI.





13.1.3 Input/Output Pins

The SCI has serial pins for each channel as listed in table 13.1.

Table 13.1 SCI Pins

Channel	Name	Abbreviation	I/O	Function
0	Serial clock pin	SCK ₀	Input/output	SCI0 clock input/output
	Receive data pin	RxD ₀	Input	SCI ₀ receive data input
	Transmit data pin	TxD ₀	Output	SCI ₀ transmit data output
1	Serial clock pin	SCK1	Input/output	SCI1 clock input/output
	Receive data pin	RxD ₁	Input	SCI1 receive data input
	Transmit data pin	TxD ₁	Output	SCI1 transmit data output

13.1.4 Register Configuration

The SCI has internal registers as listed in table 13.2. These registers select asynchronous or synchronous mode, specify the data format and bit rate, and control the transmitter and receiver sections.

Channel	Address* ¹	Name	Abbreviation	R/W	Initial Value
0	H'FFB0	Serial mode register	SMR	R/W	H'00
	H'FFB1	Bit rate register	BRR	R/W	H'FF
	H'FFB2	Serial control register	SCR	R/W	H'00
	H'FFB3	Transmit data register	TDR	R/W	H'FF
	H'FFB4	Serial status register	SSR	R/(W)* ²	H'84
	H'FFB5	Receive data register	RDR	R	H'00
1	H'FFB8	Serial mode register	SMR	R/W	H'00
	H'FFB9	Bit rate register	BRR	R/W	H'FF
	H'FFBA	Serial control register	SCR	R/W	H'00
	H'FFBB	Transmit data register	TDR	R/W	H'FF
	H'FFBC	Serial status register	SSR	R/(W)* ²	H'84
_	H'FFBD	Receive data register	RDR	R	H'00

Table 13.2 Registers

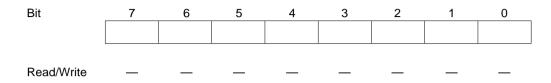
Notes: 1. Lower 16 bits of the address.

2. Only 0 can be written, to clear flags.

13.2 Register Descriptions

13.2.1 Receive Shift Register (RSR)

RSR is the register that receives serial data.



The SCI loads serial data input at the RxD pin into RSR in the order received, LSB (bit 0) first, thereby converting the data to parallel data. When 1 byte has been received, it is automatically transferred to RDR. The CPU cannot read or write RSR directly.

13.2.2 Receive Data Register (RDR)

RDR is the register that stores received serial data.

Bit	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R	R	R	R	R	R	R	R

When the SCI finishes receiving 1 byte of serial data, it transfers the received data from RSR into RDR for storage. RSR is then ready to receive the next data. This double buffering allows data to be received continuously.

RDR is a read-only register. Its contents cannot be modified by the CPU. RDR is initialized to H'00 by a reset and in standby mode.

13.2.3 Transmit Shift Register (TSR)

TSR is the register that transmits serial data.

Bit	7	6	5	4	3	2	1	0
Read/Write	_			_	_	_	_	_

The SCI loads transmit data from TDR into TSR, then transmits the data serially from the TxD pin, LSB (bit 0) first. After transmitting one data byte, the SCI automatically loads the next transmit data from TDR into TSR and starts transmitting it. If the TDRE flag is set to 1 in SSR, however, the SCI does not load the TDR contents into TSR. The CPU cannot read or write TSR directly.

13.2.4 Transmit Data Register (TDR)

TDR is an 8-bit register that stores data for serial transmission.

Bit	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

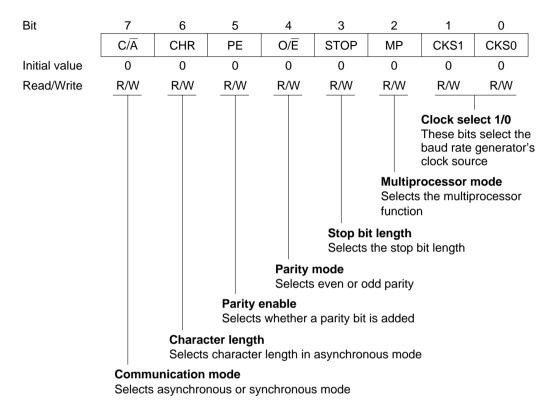
When the SCI detects that TSR is empty, it moves transmit data written in TDR from TDR into TSR and starts serial transmission. Continuous serial transmission is possible by writing the next transmit data in TDR during serial transmission from TSR.

The CPU can always read and write TDR. TDR is initialized to H'FF by a reset and in standby mode.



13.2.5 Serial Mode Register (SMR)

SMR is an 8-bit register that specifies the SCI serial communication format and selects the clock source for the baud rate generator.



The CPU can always read and write SMR. SMR is initialized to H'00 by a reset and in standby mode.

Bit 7—Communication Mode (C/\overline{A}) : Selects whether the SCI operates in asynchronous or synchronous mode.

Bit 7: C/Ā	Description	
0	Asynchronous mode	(Initial value)
1	Synchronous mode	

Bit 6—Character Length (CHR): Selects 7-bit or 8-bit data length in asynchronous mode. In synchronous mode the data length is 8 bits regardless of the CHR setting.

Bit 6: CHR	Description	
0	8-bit data	(Initial value)
1	7-bit data*	

Note: * When 7-bit data is selected, the MSB (bit 7) in TDR is not transmitted.

Bit 5—Parity Enable (PE): In asynchronous mode, this bit enables or disables the addition of a parity bit to transmit data, and the checking of the parity bit in receive data. In synchronous mode the parity bit is neither added nor checked, regardless of the PE setting.

Bit 5: PE	Description	
0	Parity bit not added or checked	(Initial value)
1	Parity bit added and checked*	

Note: *When PE is set to 1, an even or odd parity bit is added to transmit data according to the even or odd parity mode selected by the O/E bit, and the parity bit in receive data is checked to see that it matches the even or odd mode selected by the O/E bit.

Bit 4—Parity Mode (O/Ē): Selects even or odd parity. The O/Ē bit setting is valid in asynchronous mode when the PE bit is set to 1 to enable the adding and checking of a parity bit. The O/Ē setting is ignored in synchronous mode, or when parity adding and checking is disabled in asynchronous mode.

Bit 4: O/E	Description	
0	Even parity ^{*1}	(Initial value)
1	Odd parity*2	
Notes: 1.	When even parity is selected, the parity bit	added to transmit data makes an even

number of 1s in the transmitted character and parity bit combined. Receive data must have an even number of 1s in the received character and parity bit combined.

2. When odd parity is selected, the parity bit added to transmit data makes an odd number of 1s in the transmitted character and parity bit combined. Receive data must have an odd number of 1s in the received character and parity bit combined.



Bit 3—Stop Bit Length (STOP): Selects one or two stop bits in asynchronous mode. This setting is used only in asynchronous mode. In synchronous mode no stop bit is added, so the STOP bit setting is ignored.

Bit 3: STOP	Description	
0	One stop bit*1	(Initial value)
1	Two stop bits ^{*2}	

Notes: 1. One stop bit (with value 1) is added at the end of each transmitted character.

2. Two stop bits (with value 1) are added at the end of each transmitted character.

In receiving, only the first stop bit is checked, regardless of the STOP bit setting. If the second stop bit is 1 it is treated as a stop bit. If the second stop bit is 0 it is treated as the start bit of the next incoming character.

Bit 2—Multiprocessor Mode (MP): Selects a multiprocessor format. When a multiprocessor format is selected, parity settings made by the PE and O/\overline{E} bits are ignored. The MP bit setting is valid only in asynchronous mode. It is ignored in synchronous mode.

For further information on the multiprocessor communication function, see section 13.3.3, Multiprocessor Communication.

Bit 2: MP	Description	
0	Multiprocessor function disabled	(Initial value)
1	Multiprocessor format selected	

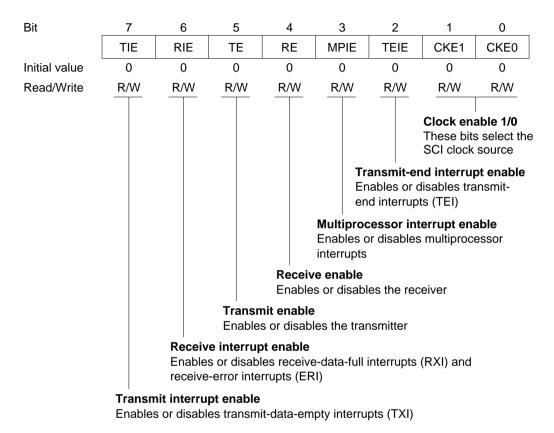
Bits 1 and 0—Clock Select 1 and 0 (CKS1/0): These bits select the clock source of the on-chip baud rate generator. Four clock sources are available: ϕ , $\phi/4$, $\phi/16$, and $\phi/64$.

For the relationship between the clock source, bit rate register setting, and baud rate, see section 13.2.8, Bit Rate Register (BRR).

Bit 1: CKS1	Bit 0: CKS0	Description	
0	0	φ	(Initial value)
	1	φ/4	
1	0	φ/16	
	1	ф/64	

13.2.6 Serial Control Register (SCR)

SCR enables the SCI transmitter and receiver, enables or disables serial clock output in asynchronous mode, enables or disables interrupts, and selects the transmit/receive clock source.



The CPU can always read and write SCR. SCR is initialized to H'00 by a reset and in standby mode.



Bit 7—Transmit Interrupt Enable (TIE): Enables or disables the transmit-data-empty interrupt (TXI) requested when the TDRE flag in SSR is set to 1 due to transfer of serial transmit data from TDR to TSR.

Bit 7: TIE Description

0	Transmit-data-empty interrupt request (TXI) is disabled*	(Initial value)
1	Transmit-data-empty interrupt request (TXI) is enabled	

Note: *TXI interrupt requests can be cleared by reading the value 1 from the TDRE flag, then clearing it to 0; or by clearing the TIE bit to 0.

Bit 6—Receive Interrupt Enable (RIE): Enables or disables the receive-data-full interrupt (RXI) requested when the RDRF flag is set to 1 in SSR due to transfer of serial receive data from RSR to RDR; also enables or disables the receive-error interrupt (ERI).

Bit 6: RIE	Description	
0	Receive-data-full (RXI) and receive-error (ERI) interrupt requests are disabled* (Initial value)	
1	Receive-data-full (RXI) and receive-error (ERI) interrupt requests are enabled	
Note: * RXI and ERI interrupt requests can be cleared by reading the value 1 from the RDRF, FER,		

PER, or ORER flag, then clearing it to 0; or by clearing the RIE bit to 0.

Bit 5—Transmit Enable (TE): Enables or disables the start of SCI serial transmitting operations.

Bit 5: TE Description

0	Transmitting disabled*1	(Initial value)
1	Transmitting enabled ^{*2}	

Notes: 1. The TDRE bit is locked at 1 in SSR.

2. In the enabled state, serial transmitting starts when the TDRE bit in SSR is cleared to 0 after writing of transmit data into TDR. Select the transmit format in SMR before setting the TE bit to 1.

Bit 4—Receive Enable (RE): Enables or disables the start of SCI serial receiving operations.

Bit 4: RE	Description		
0	Receiving disabled*1	(Initial value)	
1	Receiving enabled ^{*2}		
Notes: 1. Clearing the RE bit to 0 does not affect the RDRF, FER, PER, and ORER flags. These flags retain their previous values.			

2. In the enabled state, serial receiving starts when a start bit is detected in asynchronous mode, or serial clock input is detected in synchronous mode. Select the receive format in SMR before setting the RE bit to 1.

Bit 3—Multiprocessor Interrupt Enable (MPIE): Enables or disables multiprocessor interrupts. The MPIE setting is valid only in asynchronous mode, and only if the MP bit is set to 1 in SMR. The MPIE setting is ignored in synchronous mode or when the MP bit is cleared to 0.

Bit 3: MPIE	Description
0	Multiprocessor interrupts are disabled (normal receive operation) (Initial value)
	[Clearing conditions]
	The MPIE bit is cleared to 0.
	MPB = 1 in received data.
1	Multiprocessor interrupts are enabled*
	Receive-data-full interrupts (RXI), receive-error interrupts (ERI), and setting of the RDRF, FER, and ORER status flags in SSR are disabled until data with the multiprocessor bit set to 1 is received.
Note: * The SCI	does not transfer receive data from PSP to PDP, does not detect receive errors

Note: * The SCI does not transfer receive data from RSR to RDR, does not detect receive errors, and does not set the RDRF, FER, and ORER flags in SSR. When it receives data in which MPB = 1, the SCI sets the MPB bit to 1 in SSR, automatically clears the MPIE bit to 0, enables RXI and ERI interrupts (if the RIE bit is set to 1 in SCR), and allows the FER and ORER flags to be set.

Bit 2—Transmit-End Interrupt Enable (TEIE): Enables or disables the transmit-end interrupt (TEI) requested if TDR does not contain new transmit data when the MSB is transmitted.

Bit 2: TEIE	Description	
0	Transmit-end interrupt requests (TEI) are disabled*	(Initial value)
1	Transmit-end interrupt requests (TEI) are enabled*	

Note: * TEI interrupt requests can be cleared by reading the value 1 from the TDRE flag in SSR, then clearing the TDRE flag to 0, thereby also clearing the TEND flag to 0; or by clearing the TEIE bit to 0.

Bits 1 and 0—Clock Enable 1 and 0 (CKE1/0): These bits select the SCI clock source and enable or disable clock output from the SCK pin. Depending on the settings of CKE1 and CKE0, the SCK pin can be used for generic input/output, serial clock output, or serial clock input.

The CKE0 setting is valid only in asynchronous mode, and only when the SCI is internally clocked (CKE1 = 0). The CKE0 setting is ignored in synchronous mode, or when an external clock source is selected (CKE1 = 1). Select the SCI operating mode in SMR before setting the CKE1 and CKE0 bits. For further details on selection of the SCI clock source, see table 13.9 in section 13.3, Operation.

Bit 1: CKE1	Bit 0: CKE0	Description	
0 0 Asynchronous mode Internal clock, SCK pi input/output *1		Asynchronous mode	Internal clock, SCK pin available for generic input/output *1
		Synchronous mode	Internal clock, SCK pin used for serial clock output *1
	1	Asynchronous mode	Internal clock, SCK pin used for clock output*2
		Synchronous mode	Internal clock, SCK pin used for serial clock output
1	0	Asynchronous mode	External clock, SCK pin used for clock input *3
		Synchronous mode	External clock, SCK pin used for serial clock input
	1	Asynchronous mode	External clock, SCK pin used for clock input *3
		Synchronous mode	External clock, SCK pin used for serial clock input

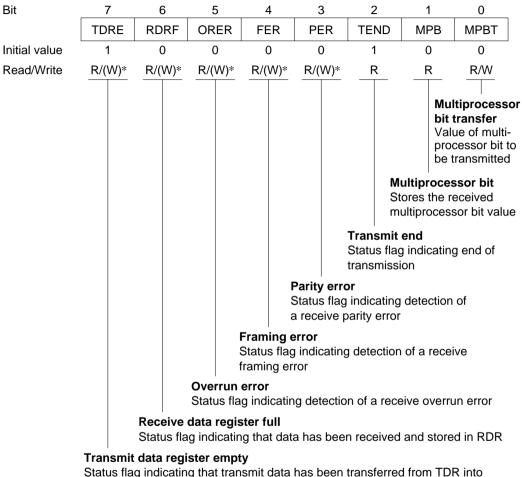
Notes: 1. Initial value

2. The output clock frequency is the same as the bit rate.

3. The input clock frequency is 16 times the bit rate.

13.2.7 Serial Status Register (SSR)

SSR is an 8-bit register containing multiprocessor bit values, and status flags that indicate SCI operating status.



TSR and new data can be written in TDR

Note: * Only 0 can be written, to clear the flag.

The CPU can always read and write SSR, but cannot write 1 in the TDRE, RDRF, ORER, PER, and FER flags. These flags can be cleared to 0 only if they have first been read while set to 1. The TEND and MPB flags are read-only bits that cannot be written.

SSR is initialized to H'84 by a reset and in standby mode.

Bit 7—Transmit Data Register Empty (TDRE): Indicates that the SCI has loaded transmit data from TDR into TSR and the next serial transmit data can be written in TDR.

Bit 7: TDRE	Description	
0	TDR contains valid transmit data	
	[Clearing conditions]	
	Software reads TDRE while it is set to 1, then writes 0.	
	The DMAC writes data in TDR.	
1	TDR does not contain valid transmit data	(Initial value)
	[Setting conditions]	
	The chip is reset or enters standby mode.	
	The TE bit in SCR is cleared to 0.	
	TDR contents are loaded into TSR, so new data can be written in TDR.	

Bit 6—Receive Data Register Full (RDRF): Indicates that RDR contains new receive data.

Bit 6: RDRF	Description	
0	RDR does not contain new receive data	(Initial value)
	[Clearing conditions]	
	The chip is reset or enters standby mode.	
	Software reads RDRF while it is set to 1, then writes 0.	
	The DMAC reads data from RDR.	
1	RDR contains new receive data	
	[Setting condition]	
	When serial data is received normally and transferred from RS	SR to RDR.

Note: The RDR contents and RDRF flag are not affected by detection of receive errors or by clearing of the RE bit to 0 in SCR. They retain their previous values. If the RDRF flag is still set to 1 when reception of the next data ends, an overrun error occurs and receive data is lost.

Bit 5—Overrun Error (ORER): Indicates that data reception ended abnormally due to an overrun error.

Bit 5: OR	ER Description
0	Receiving is in progress or has ended normally (Initial value)* ¹
	[Clearing conditions]
	The chip is reset or enters standby mode.
	Software reads ORER while it is set to 1, then writes 0.
1	A receive overrun error occurred ^{*2}
	[Setting condition]
	Reception of the next serial data ends when RDRF = 1.
Notes: 1.	Clearing the RE bit to 0 in SCR does not affect the ORER flag, which retains its previous value.
2.	RDR continues to hold the receive data before the overrun error, so subsequent receive

 RDR continues to hold the receive data before the overrun error, so subsequent receive data is lost. Serial receiving cannot continue while the ORER flag is set to 1. In synchronous mode, serial transmitting is also disabled.

Bit 4—Framing Error (FER): Indicates that data reception ended abnormally due to a framing error in asynchronous mode.

Bit 4: FER	Description	
0	Receiving is in progress or has ended normally	(Initial value)*1
	[Clearing conditions]	
	The chip is reset or enters standby mode.	
	Software reads FER while it is set to 1, then writes 0.	
1	A receive framing error occurred* ²	
	[Setting condition]	
	The stop bit at the end of receive data is checked and found	to be 0.

Notes: 1. Clearing the RE bit to 0 in SCR does not affect the FER flag, which retains its previous value.

2. When the stop bit length is 2 bits, only the first bit is checked. The second stop bit is not checked. When a framing error occurs the SCI transfers the receive data into RDR but does not set the RDRF flag. Serial receiving cannot continue while the FER flag is set to 1. In synchronous mode, serial transmitting is also disabled.



Bit 3—Parity Error (PER): Indicates that data reception ended abnormally due to a parity error in asynchronous mode.

Bit 3: PE	ER	Description	
0		Receiving is in progress or has ended normally ^{*1} (Initial	value)
		[Clearing conditions]	
		The chip is reset or enters standby mode.	
		Software reads PER while it is set to 1, then writes 0.	
1		A receive parity error occurred*2	
		[Setting condition]	
		The number of 1s in receive data, including the parity bit, does not mate even or odd parity setting of O/E in SMR.	h the
Notes:		earing the RE bit to 0 in SCR does not affect the PER flag, which retains its pr lue.	evious
2	the	hen a parity error occurs the SCI transfers the receive data into RDR but does e RDRF flag. Serial receiving cannot continue while the PER flag is set to 1. In nchronous mode, serial transmitting is also disabled.	

Bit 2—Transmit End (TEND): Indicates that when the last bit of a serial character was transmitted TDR did not contain new transmit data, so transmission has ended. The TEND flag is a read-only bit and cannot be written.

Bit 2: TEND	Description	
0	Transmission is in progress	
	[Clearing conditions]	
	Software reads TDRE while it is set to 1, then writes 0 in the TI	DRE flag.
	The DMAC writes data in TDR.	
1	End of transmission	(Initial value)
	[Setting conditions]	
	The chip is reset or enters standby mode.	
	The TE bit is cleared to 0 in SCR.	
	TDRE is 1 when the last bit of a serial character is transmitted.	

Bit 1—Multiprocessor Bit (MPB): Stores the value of the multiprocessor bit in receive data when a multiprocessor format is used in asynchronous mode. MPB is a read-only bit and cannot be written.

Bit 1: MPB Description

0	Multiprocessor bit value in receive data is 0*	(Initial value)
1	Multiprocessor bit value in receive data is 1	

Note: * If the RE bit is cleared to 0 when a multiprocessor format is selected, MPB retains its previous value.

Bit 0—Multiprocessor Bit Transfer (MPBT): Stores the value of the multiprocessor bit added to transmit data when a multiprocessor format is selected for transmitting in asynchronous mode. The MPBT setting is ignored in synchronous mode, when a multiprocessor format is not selected, or when the SCI is not transmitting.

Bit 0: MPBT	Description	
0	Multiprocessor bit value in transmit data is 0	(Initial value)
1	Multiprocessor bit value in transmit data is 1	

13.2.8 Bit Rate Register (BRR)

BRR is an 8-bit register that, together with the CKS1 and CKS0 bits in SMR that select the baud rate generator clock source, determines the serial communication bit rate.

Bit	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

The CPU can always read and write BRR. BRR is initialized to H'FF by a reset and in standby mode. The two SCI channels have independent baud rate generator control, so different values can be set in the two channels.

Table 13.3 shows examples of BRR settings in asynchronous mode. Table 13.4 shows examples of BRR settings in synchronous mode.

		φ (MHz)													
		2		2.097152			2.4576			3					
Bit Rate (bits/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)			
110	1	141	0.03	1	148	-0.04	1	174	-0.26	1	212	0.03			
150	1	103	0.16	1	108	0.21	1	127	0.00	1	155	0.16			
300	0	207	0.16	0	217	0.21	0	255	0.00	1	77	0.16			
600	0	103	0.16	0	108	0.21	0	127	0.00	0	155	0.16			
1200	0	51	0.16	0	54	-0.70	0	63	0.00	0	77	0.16			
2400	0	25	0.16	0	26	1.14	0	31	0.00	0	38	0.16			
4800	0	12	0.16	0	13	-2.48	0	15	0.00	0	19	-2.34			
9600	0	6	-6.99	0	6	-2.48	0	7	0.00	0	9	-2.34			
19200	0	2	8.51	0	2	13.78	0	3	0.00	0	4	-2.34			
31250	0	1	0.00	0	1	4.86	0	1	22.88	0	2	0.00			
38400	0	1	-18.62	0	1	-14.67	0	1	0.00	_	_				

 Table 13.3
 Examples of Bit Rates and BRR Settings in Asynchronous Mode

φ (MHz)

						Ψ (
		3.68	364		4			4.91	52	5		
Bit Rate (bits/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	2	64	0.70	2	70	0.03	2	86	0.31	2	88	-0.25
150	1	191	0.00	1	207	0.16	1	255	0.00	2	64	0.16
300	1	95	0.00	1	103	0.16	1	127	0.00	1	129	0.16
600	0	191	0.00	0	207	0.16	0	255	0.00	1	64	0.16
1200	0	95	0.00	0	103	0.16	0	127	0.00	0	129	0.16
2400	0	47	0.00	0	51	0.16	0	63	0.00	0	64	0.16
4800	0	23	0.00	0	25	0.16	0	31	0.00	0	32	-1.36
9600	0	11	0.00	0	12	0.16	0	15	0.00	0	15	1.73
19200	0	5	0.00	0	6	-6.99	0	7	0.00	0	7	1.73
31250			—	0	3	0.00	0	4	-1.70	0	4	0.00
38400	0	2	0.00	0	2	8.51	0	3	0.00	0	3	1.73

		φ (MHz)													
		6		6.144			7.3728			8					
Bit Rate (bits/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)			
110	2	106	-0.44	2	108	0.08	2	130	-0.07	2	141	0.03			
150	2	77	0.16	2	79	0.00	2	95	0.00	2	103	0.16			
300	1	155	0.16	1	159	0.00	1	191	0.00	1	207	0.16			
600	1	77	0.16	1	79	0.00	1	95	0.00	1	103	0.16			
1200	0	155	0.16	0	159	0.00	0	191	0.00	0	207	0.16			
2400	0	77	0.16	0	79	0.00	0	95	0.00	0	103	0.16			
4800	0	38	0.16	0	39	0.00	0	47	0.00	0	51	0.16			
9600	0	19	-2.34	0	19	0.00	0	23	0.00	0	25	0.16			
19200	0	9	-2.34	0	9	0.00	0	11	0.00	0	12	0.16			
31250	0	5	0.00	0	5	2.40	0	6	5.33	0	7	0.00			
38400	0	4	-2.34	0	4	0.00	0	5	0.00	0	6	-6.99			

Section 13 Serial Communication Interface

φ (MHz)

		9.8304			10)		12	2	12.288			
Bit Rate (bits/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	
110	2	174	-0.26	2	177	-0.25	2	212	0.03	2	217	0.08	
150	2	127	0.00	2	129	0.16	2	155	0.16	2	159	0.00	
300	1	255	0.00	2	64	0.16	2	77	0.16	2	79	0.00	
600	1	127	0.00	1	129	0.16	1	155	0.16	1	159	0.00	
1200	0	255	0.00	1	64	0.16	1	77	0.16	1	79	0.00	
2400	0	127	0.00	0	129	0.16	0	155	0.16	0	159	0.00	
4800	0	63	0.00	0	64	0.16	0	77	0.16	0	79	0.00	
9600	0	31	0.00	0	32	-1.36	0	38	0.16	0	39	0.00	
19200	0	15	0.00	0	15	1.73	0	19	-2.34	0	19	0.00	
31250	0	9	-1.70	0	9	0.00	0	11	0.00	0	11	2.40	
38400	0	7	0.00	0	7	1.73	0	9	-2.34	0	9	0.00	

						φ(whz)					
		1:	3		14	4		14.7	456		10	6
Bit Rate (bits/s)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)
110	2	230	-0.08	2	248	-0.17	3	64	0.70	3	70	0.03
150	2	168	0.16	2	181	0.16	2	191	0.00	2	207	0.16
300	2	84	-0.43	2	90	0.16	2	95	0.00	2	103	0.16
600	1	168	0.16	1	181	0.16	1	191	0.00	1	207	0.16
1200	1	84	-0.43	1	90	0.16	1	95	0.00	1	103	0.16
2400	0	168	0.16	0	181	0.16	0	191	0.00	0	207	0.16
4800	0	84	-0.43	0	90	0.16	0	95	0.00	0	103	0.16
9600	0	41	0.76	0	45	-0.93	0	47	0.00	0	51	0.16
19200	0	20	0.76	0	22	-0.93	0	23	0.00	0	25	0.16
31250	0	12	0.00	0	13	0.00	0	14	-1.70	0	15	0.00
38400	0	10	-3.82	0	10	3.57	0	11	0.00	0	12	0.16

φ(MHz)

φ (MHz)

		18 Error									
Bit Rate (bits/s)	n	N	Error (%)								
110	3	79	-0.12								
150	2	233	0.16								
300	2	116	0.16								
600	1	233	0.16								
1200	1	116	0.16								
2400	0	233	0.16								
4800	0	116	0.16								
9600	0	58	-0.69								
19200	0	28	1.02								
31250	0	17	0.00								
38400	0	14	-2.34								

φ (MHz)													
	2		4		8		10		13		16		18
n	Ν	n	Ν	n	Ν	n	Ν	n	Ν	n	Ν	n	Ν
3	70	_	_		_	_		_		_	_		
2	124	2	249	3	124	_		3	202	3	249	_	
1	249	2	124	2	249			3	101	3	124	3	140
1	124	1	249	2	124	_		2	202	2	249	3	69
0	199	1	99	1	199	1	249	2	80	2	99	2	112
0	99	0	199	1	99	1	124	1	162	1	199	1	224
0	49	0	99	0	199	0	249	1	80	1	99	1	112
0	19	0	39	0	79	0	99	0	129	0	159	0	179
0	9	0	19	0	39	0	49	0	64	0	79	0	89
0	4	0	9	0	19	0	24		_	0	39	0	44
0	1	0	3	0	7	0	9	0	12	0	15	0	17
0	0*	0	1	0	3	0	4	_		0	7	0	8
		0	0*	0	1					0	3	0	4
				0	0*					0	1	_	_
				_		0	0*	_		_		_	
										0	0*	_	_
	3 2 1 1 0 0 0 0 0 0 0 0 0 0 0	n N 3 70 2 124 1 249 1 124 0 199 0 99 0 49 0 19 0 9 0 49 0 1 0 1 0 1 0 1 0 1 0 1	N N 3 70 2 124 2 1 249 2 1 124 1 0 199 1 0 99 0 0 19 0 0 99 0 0 19 0 0 19 0 0 19 0 0 19 0 0 19 0 0 19 0 0 19 0 0 19 0 0 9 0 0 4 0 0 1 0 0 0* 0	N N N 3 70 2 124 2 249 1 249 2 124 1 1249 2 124 1 1249 2 124 0 199 1 99 0 99 0 199 0 49 0 99 0 19 0 39 0 9 0 19 0 19 0 39 0 9 0 19 0 19 0 39 0 4 0 9 0 1 0 3 0 1 0 3 0 0 1 0 3	N N N N 3 70 2 124 2 249 3 1 249 2 124 2 1 1249 2 124 2 0 199 1 249 2 0 199 0 199 1 0 99 0 199 1 0 49 0 99 0 0 19 0 39 0 0 19 0 39 0 0 19 0 39 0 0 44 0 9 0 0 1 0 3 0 0 0* 0 1 0 0 0* 0 1 0	n N n N n N 3 70 2 124 2 249 3 124 1 249 2 124 2 249 1 1249 2 124 2 249 1 1249 2 124 2 249 1 1249 1 249 2 124 0 199 1 99 1 199 0 99 0 199 1 99 0 49 0 99 0 199 0 19 0 39 0 199 0 9 0 19 0 39 0 4 0 9 0 19 0 1 0 3 0 7 0 0* 0 1 0 3	2 4 8 n	2 4 8 10 n N n N n N n N n N 3 70 2 124 2 249 3 124 1 249 2 124 2 249 1 124 1 249 2 124 1 124 1 249 2 124 0 199 1 99 1 199 1 249 0 199 0 199 1 124 0 199 1 99 1 194 0 199 0 199 1 124 - 0 199 0 199 0	$\begin{array}{ c c c c c c c c }\hline 2 & 4 & 8 & 10 & n \\ \hline n & N & n & N & n & N & n & N & n \\ \hline n & N & - & - & - & - & - & - & - \\ \hline 3 & 70 & - & - & - & - & - & - & - & - & - \\ \hline 2 & 124 & 2 & 249 & 3 & 124 & - & - & 3 \\ \hline 1 & 249 & 2 & 124 & 2 & 249 & - & - & 3 \\ \hline 1 & 124 & 1 & 249 & 2 & 124 & - & - & 2 \\ \hline 0 & 199 & 1 & 99 & 1 & 199 & 1 & 249 & 2 \\ \hline 0 & 99 & 0 & 199 & 1 & 999 & 1 & 124 & 1 \\ \hline 0 & 49 & 0 & 99 & 0 & 199 & 0 & 249 & 1 \\ \hline 0 & 19 & 0 & 39 & 0 & 79 & 0 & 99 & 0 \\ \hline 0 & 19 & 0 & 39 & 0 & 199 & 0 & 249 & 1 \\ \hline 0 & 19 & 0 & 39 & 0 & 199 & 0 & 249 & 1 \\ \hline 0 & 19 & 0 & 39 & 0 & 199 & 0 & 249 & - \\ \hline 0 & 11 & 0 & 3 & 0 & 77 & 0 & 9 & 0 \\ \hline 0 & 0^* & 0 & 1 & 0 & 3 & 0 & 4 & - \\ \hline 0 & 0^* & 0 & 1 & 0 & 3 & 0 & 4 & - \\ \hline 0 & 0^* & 0 & 0^* & 0 & 1 & - & - & - \\ \hline 0 & 0^* & 0 & 0^* & 0 & 1 & - & - & - \\ \hline \end{array}$	$ \begin{array}{ c c c c c c c c c c } \hline 2 & 4 & 8 & 10 & 13 \\ \hline n & N & n & N & n & N & n & N & n & N \\ \hline 3 & 70 & & & & & & &$	$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $

Note: Settings with an error of 1% or less are recommended.

Legend

Blank: No setting available

- -: Setting possible, but error occurs
- *: Continuous transmit/receive not possible



The BRR setting is calculated as follows:

Asynchronous mode:

$$\mathsf{N} = \frac{\phi}{64 \times 2^{2\mathsf{n}-1} \times \mathsf{B}} \times 10^6 - 1$$

Synchronous mode:

$$N = \frac{\phi}{8 \times 2^{2n-1} \times B} \times 10^6 - 1$$

- B: Bit rate (bits/s)
- N: BRR setting for baud rate generator ($0 \le N \le 255$)
- φ: System clock frequency (MHz)
- n: Baud rate generator clock source (n = 0, 1, 2, 3)(For the clock sources and values of n, see the following table.)

		SMR Settings						
n	Clock Source	CKS1	CKS0					
0	φ	0	0					
1	φ/4	0	1					
2	φ/16	1	0					
3	φ/64	1	1					

The bit rate error in asynchronous mode is calculated as follows.

Error (%) = $\left\{ \frac{\phi \times 10^{6}}{(N+1) \times B \times 64 \times 2^{2n-1}} - 1 \right\} \times 100$

Table 13.5 indicates the maximum bit rates in asynchronous mode for various system clock frequencies. Tables 13.6 and 13.7 indicate the maximum bit rates with external clock input.

N 0
0
0
0
0
0
0
0
0
0
0
0
0
0
0
0
0
0
0
0
0
-

φ (MHz)	External Input Clock (MHz)	Maximum Bit Rate (bits/s)
2	0.5000	31250
2.097152	0.5243	32768
2.4576	0.6144	38400
3	0.7500	46875
3.6864	0.9216	57600
4	1.0000	62500
4.9152	1.2288	76800
5	1.2500	78125
6	1.5000	93750
6.144	1.5360	96000
7.3728	1.8432	115200
8	2.0000	125000
9.8304	2.4576	153600
10	2.5000	156250
12	3.0000	187500
12.288	3.0720	192000
14	3.5000	218750
14.7456	3.6864	230400
16	4.0000	250000
17.2032	4.3008	268800
18	4.5000	281250

 Table 13.6
 Maximum Bit Rates with External Clock Input (Asynchronous Mode)

Table 13.7 Maximum Bit Rates with External Clock Input (Synchronous Mode)

φ (MHz)	External Input Clock (MHz)	Maximum Bit Rate (bits/s)
2	0.3333	333333.3
4	0.6667	666666.7
6	1.0000	100000.0
8	1.3333	133333.3
10	1.6667	1666666.7
12	2.0000	200000.0
14	2.3333	2333333.3
16	2.6667	2666666.7
18	3.0000	300000.0

13.3 Operation

13.3.1 Overview

The SCI has an asynchronous mode in which characters are synchronized individually, and a synchronous mode in which communication is synchronized with clock pulses. Serial communication is possible in either mode. Asynchronous or synchronous mode and the communication format are selected in SMR, as shown in table 13.8. The SCI clock source is selected by the C/\overline{A} bit in SMR and the CKE1 and CKE0 bits in SCR, as shown in table 13.9.

Asynchronous Mode

- Data length is selectable: 7 or 8 bits.
- Parity and multiprocessor bits are selectable. So is the stop bit length (1 or 2 bits). These selections determine the communication format and character length.
- In receiving, it is possible to detect framing errors, parity errors, overrun errors, and the break state.
- An internal or external clock can be selected as the SCI clock source.
 - When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and can output a serial clock signal with a frequency matching the bit rate.
 - When an external clock is selected, the external clock input must have a frequency 16 times the bit rate. (The on-chip baud rate generator is not used.)

Synchronous Mode

- The communication format has a fixed 8-bit data length.
- In receiving, it is possible to detect overrun errors.
- An internal or external clock can be selected as the SCI clock source.
 - When an internal clock is selected, the SCI operates using the on-chip baud rate generator, and outputs a serial clock signal to external devices.
 - When an external clock is selected, the SCI operates on the input serial clock. The on-chip baud rate generator is not used.



	SN	/IR Sett	ings			SCI Communication Format					
Bit 7: C/Ā	Bit 6: CHR	Bit 2: MP	Bit 5: PE	Bit 3: STOP	Mode	Multi- Data processor Length Bit		Parity Bit	Stop Bit Length		
0	0	0	0	0	Asynchronous	8-bit data	Absent	Absent	1 bit		
				1	mode				2 bits		
			1	0	_			Present	1 bit		
				1	_				2 bits		
	1	-	0	0		7-bit data	_	Absent	1 bit		
				1	=				2 bits		
			1	0	_			Present	1 bit		
				1	_				2 bits		
	0	1	—	0	Asynchronous	8-bit data	Present	Absent	1 bit		
				1	mode (multi- processor				2 bits		
	1	-		0	format)	7-bit data	_		1 bit		
				1					2 bits		
1					Synchronous mode	8-bit data	Absent	_	None		

Table 13.8 SMR Settings and Serial Communication Formats

Table 13.9	SMR and SCR Settings and SCI Clock Source Selection
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SMR	SCR Settin			SCI Transmit/Receive Clock					
Bit 7: C/Ā	Bit 1: CKE1	Bit 0: CKE0	 Mode	Clock Source	SCK Pin Function				
0	0	0	Asynchronous	Internal	SCI does not use the SCK pin				
		1	mode		Outputs a clock with frequency matching the bit rate				
	1	0		External	Inputs a clock with frequency 16				
		1			times the bit rate				
1	0	0	Synchronous	Internal	Outputs the serial clock				
		1	mode						
	1	0		External	Inputs the serial clock				
		1							

13.3.2 Operation in Asynchronous Mode

In asynchronous mode each transmitted or received character begins with a start bit and ends with a stop bit. Serial communication is synchronized one character at a time.

The transmitting and receiving sections of the SCI are independent, so full duplex communication is possible. The transmitter and receiver are both double buffered, so data can be written and read while transmitting and receiving are in progress, enabling continuous transmitting and receiving.

Figure 13.2 shows the general format of asynchronous serial communication. In asynchronous serial communication the communication line is normally held in the mark (high) state. The SCI monitors the line and starts serial communication when the line goes to the space (low) state, indicating a start bit. One serial character consists of a start bit (low), data (LSB first), parity bit (high or low), and stop bit (high), in that order.

When receiving in asynchronous mode, the SCI synchronizes at the falling edge of the start bit. The SCI samples each data bit on the eighth pulse of a clock with a frequency 16 times the bit rate. Receive data is latched at the center of each bit.

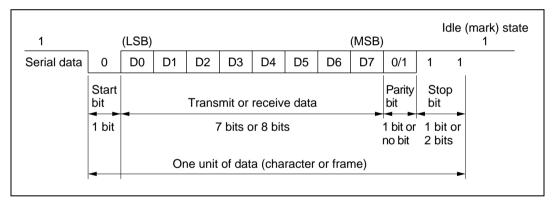


Figure 13.2 Data Format in Asynchronous Communication (Example: 8-Bit Data with Parity and 2 Stop Bits)



Communication Formats: Table 13.10 shows the 12 communication formats that can be selected in asynchronous mode. The format is selected by settings in SMR.

SMR Settings				S	erial (Comm	unica	tion F	ormat	and	Frame	e Leng	gth		
CHR	PE	MP	STOP	1	2	3	4	5	6	7	8	9	10	11	12
0	0	0	0	S			8.	-bit da	ita				STOF	-	
0	0	0	1	S			8-	-bit da	ita				STOF	STOF	- >
0	1	0	0	S			8	-bit da	ita				Ρ	STOF	-
0	1	0	1	S			8-	-bit da	ita				Ρ	STOF	STOP
1	0	0	0	S			7.	-bit da	ita			STOF			
1	0	0	1	S			7.	-bit da	ita			STOF	STOF	<u> </u>	
1	1	0	0	S			7.	-bit da	ita			Ρ	STOF	-)	
1	1	0	1	S			7.	-bit da	ita			Ρ	STOF	STOF	-
0	_	1	0	S			8	-bit da	ita				MPB	STOF	-
0	_	1	1	S			8-	-bit da	ita				MPB	STOF	STOP
1	_	1	0	S			7-	-bit da	ita			MPB	STOF)	
1	_	1	1	S			7.	-bit da	ita			MPB	STOF	STOF	,

Legend

S: Start bit

STOP: Stop bit

P: Parity bit

MPB: Multiprocessor bit

Clock: An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected as the SCI transmit/receive clock. The clock source is selected by the C/\overline{A} bit in SMR and bits CKE1 and CKE0 in SCR. See table 13.9.

When an external clock is input at the SCK pin, it must have a frequency equal to 16 times the desired bit rate.

When the SCI operates on an internal clock, it can output a clock signal at the SCK pin. The frequency of this output clock is equal to the bit rate. The phase is aligned as in figure 13.3 so that the rising edge of the clock occurs at the center of each transmit data bit.

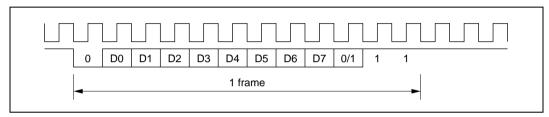


Figure 13.3 Phase Relationship between Output Clock and Serial Data (Asynchronous Mode)

Transmitting and Receiving Data

• SCI Initialization (Asynchronous Mode)

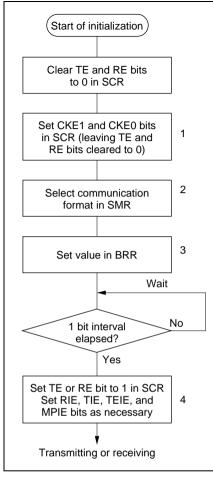
Before transmitting or receiving, clear the TE and RE bits to 0 in SCR, then initialize the SCI as follows.

When changing the communication mode or format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing TE to 0 sets the TDRE flag to 1 and initializes TSR. Clearing RE to 0, however, does not initialize the RDRF, PER, FER, and ORER flags and RDR, which retain their previous contents.

When an external clock is used, the clock should not be stopped during initialization or subsequent operation. SCI operation becomes unreliable if the clock is stopped.

Figure 13.4 is a sample flowchart for initializing the SCI.



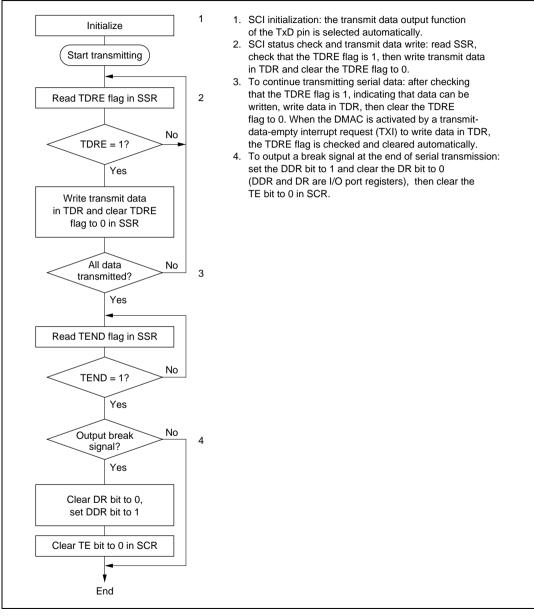


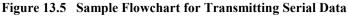
- Select the clock source in SCR. Clear the RIE, TIE, TEIE, MPIE, TE, and RE bits to 0. If clock output is selected in asynchronous mode, clock output starts immediately after the setting is made in SCR.
- 2. Select the communication format in SMR.
- 3. Write the value corresponding to the bit rate in BRR. This step is not necessary when an external clock is used.
- 4. Wait for at least the interval required to transmit or receive 1 bit, then set the TE or RE bit to 1 in SCR. Set the RIE, TIE, TEIE, and MPIE bits as necessary. Setting the TE or RE bit enables the SCI to use the TxD or RxD pin.

Figure 13.4 Sample Flowchart for SCI Initialization

• Transmitting Serial Data (Asynchronous Mode)

Figure 13.5 shows a sample flowchart for transmitting serial data and indicates the procedure to follow.





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In transmitting serial data, the SCI operates as follows.

- 1. The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0 the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- 2. After loading the data from TDR into TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

Serial transmit data is transmitted in the following order from the TxD pin:

- a. Start bit: One 0 bit is output.
- b. Transmit data: 7 or 8 bits are output, LSB first.
- c. Parity bit or multiprocessor bit: One parity bit (even or odd parity) or one multiprocessor bit is output. Formats in which neither a parity bit nor a multiprocessor bit is output can also be selected.
- d. Stop bit: One or two 1 bits (stop bits) are output.
- e. Mark state: Output of 1 bits continues until the start bit of the next transmit data.
- 3. The SCI checks the TDRE flag when it outputs the stop bit. If the TDRE flag is 0, the SCI loads new data from TDR into TSR, outputs the stop bit, then begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, outputs the stop bit, then continues output of 1 bits in the mark state. If the TEIE bit is set to 1 in SCR, a transmit-end interrupt (TEI) is requested at this time.

Figure 13.6 shows an example of SCI transmit operation in asynchronous mode.

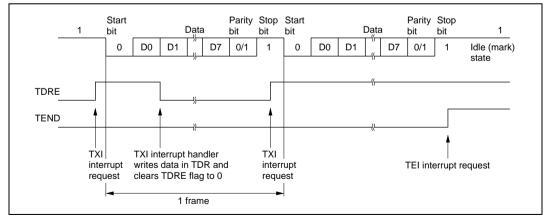


Figure 13.6 Example of SCI Transmit Operation in Asynchronous Mode (8-Bit Data with Parity and 1 Stop Bit)

• Receiving Serial Data (Asynchronous Mode)

Figure 13.7 shows a sample flowchart for receiving serial data and indicates the procedure to follow.

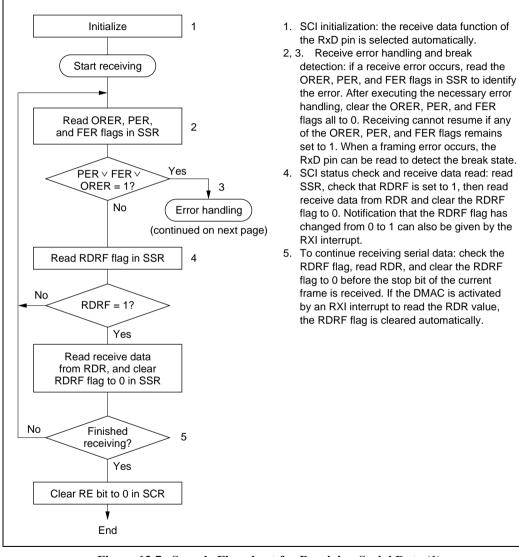


Figure 13.7 Sample Flowchart for Receiving Serial Data (1)

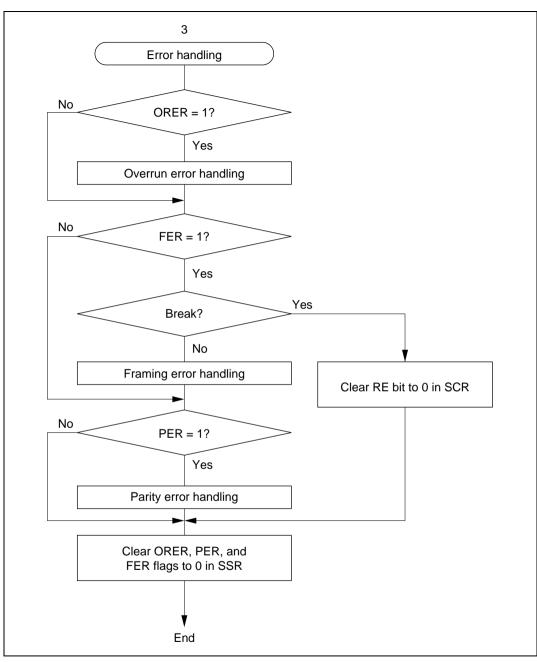


Figure 13.7 Sample Flowchart for Receiving Serial Data (2)

In receiving, the SCI operates as follows.

- 1. The SCI monitors the receive data line. When it detects a start bit, the SCI synchronizes internally and starts receiving.
- 2. Receive data is stored in RSR in order from LSB to MSB.
- 3. The parity bit and stop bit are received.

After receiving, the SCI makes the following checks:

- a. Parity check: The number of 1s in the receive data must match the even or odd parity setting of the O/\overline{E} bit in SMR.
- b. Stop bit check: The stop bit value must be 1. If there are two stop bits, only the first stop bit is checked.
- c. Status check: The RDRF flag must be 0 so that receive data can be transferred from RSR into RDR.

If these checks all pass, the RDRF flag is set to 1 and the received data is stored in RDR. If one of the checks fails (receive error), the SCI operates as indicated in table 13.11.

- Note: When a receive error occurs, further receiving is disabled. In receiving, the RDRF flag is not set to 1. Be sure to clear the error flags to 0.
 - 4. When the RDRF flag is set to 1, if the RIE bit is set to 1 in SCR, a receive-data-full interrupt (RXI) is requested. If the ORER, PER, or FER flag is set to 1 and the RIE bit in SCR is also set to 1, a receive-error interrupt (ERI) is requested.

Receive Error	Abbreviation	Condition	Data Transfer
Overrun error	ORER	Receiving of next data ends while RDRF flag is still set to 1 in SSR	Receive data not transferred from RSR to RDR
Framing error	FER	Stop bit is 0	Receive data transferred from RSR to RDR
Parity error	PER	Parity of receive data differs from even/odd parity setting in SMR	Receive data transferred from RSR to RDR

Table 13.11 Receive Error Conditions

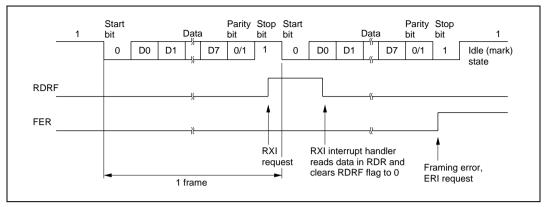


Figure 13.8 shows an example of SCI receive operation in asynchronous mode.

Figure 13.8 Example of SCI Receive Operation (8-Bit Data with Parity and One Stop Bit)

13.3.3 Multiprocessor Communication

The multiprocessor communication function enables several processors to share a single serial communication line. The processors communicate in asynchronous mode using a format with an additional multiprocessor bit (multiprocessor format).

In multiprocessor communication, each receiving processor is addressed by an ID. A serial communication cycle consists of an ID-sending cycle that identifies the receiving processor, and a data-sending cycle. The multiprocessor bit distinguishes ID-sending cycles from data-sending cycles.

The transmitting processor starts by sending the ID of the receiving processor with which it wants to communicate as data with the multiprocessor bit set to 1. Next the transmitting processor sends transmit data with the multiprocessor bit cleared to 0.

Receiving processors skip incoming data until they receive data with the multiprocessor bit set to 1. When they receive data with the multiprocessor bit set to 1, receiving processors compare the data with their IDs. The receiving processor with a matching ID continues to receive further incoming data. Processors with IDs not matching the received data skip further incoming data until they again receive data with the multiprocessor bit set to 1. Multiple processors can send and receive data in this way.

Figure 13.9 shows an example of communication among different processors using a multiprocessor format.

Communication Formats: Four formats are available. Parity-bit settings are ignored when a multiprocessor format is selected. For details see table 13.10.

Clock: See the description of asynchronous mode.

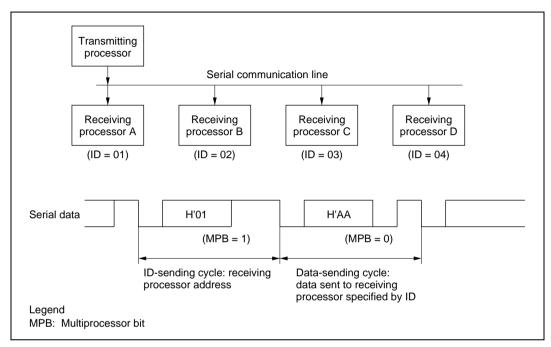


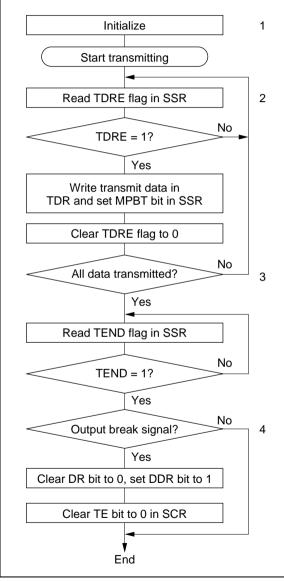
Figure 13.9 Example of Communication among Processors using Multiprocessor Format (Sending Data H'AA to Receiving Processor A)



Transmitting and Receiving Data

• Transmitting Multiprocessor Serial Data

Figure 13.10 shows a sample flowchart for transmitting multiprocessor serial data and indicates the procedure to follow.



- 1. SCI initialization: the transmit data output function of the TxD pin is selected automatically.
- 2. SCI status check and transmit data write: read SSR, check that the TDRE flag is 1, then write transmit data in TDR. Also set the MPBT flag to 0 or 1 in SSR. Finally, clear the TDRE flag to 0.
- To continue transmitting serial data: after checking that the TDRE flag is 1, indicating that data can be written, write data in TDR, then clear the TDRE flag to 0. When the DMAC is activated by a transmit-data-empty interrupt request (TXI) to write data in TDR, the TDRE flag is checked and cleared automatically.
- To output a break signal at the end of serial transmission: set the DDR bit to 1 and clear the DR bit to 0 (DDR and DR are I/O port registers), then clear the TE bit to 0 in SCR.

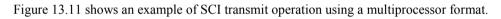
Figure 13.10 Sample Flowchart for Transmitting Multiprocessor Serial Data

In transmitting serial data, the SCI operates as follows.

- 1. The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0 the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- 2. After loading the data from TDR into TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit in SCR is set to 1, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

Serial transmit data is transmitted in the following order from the TxD pin:

- a. Start bit: One 0 bit is output.
- b. Transmit data: 7 or 8 bits are output, LSB first.
- c. Multiprocessor bit: One multiprocessor bit (MPBT value) is output.
- d. Stop bit: One or two 1 bits (stop bits) are output.
- e. Mark state: Output of 1 bits continues until the start bit of the next transmit data.
- 3. The SCI checks the TDRE flag when it outputs the stop bit. If the TDRE flag is 0, the SCI loads data from TDR into TSR, outputs the stop bit, then begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag in SSR to 1, outputs the stop bit, then continues output of 1 bits in the mark state. If the TEIE bit is set to 1 in SCR, a transmit-end interrupt (TEI) is requested at this time.



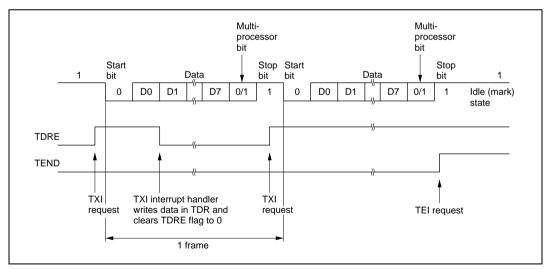


Figure 13.11 Example of SCI Transmit Operation (8-Bit Data with Multiprocessor Bit and One Stop Bit)

Receiving Multiprocessor Serial Data

Figure 13.12 shows a sample flowchart for receiving multiprocessor serial data and indicates the procedure to follow.

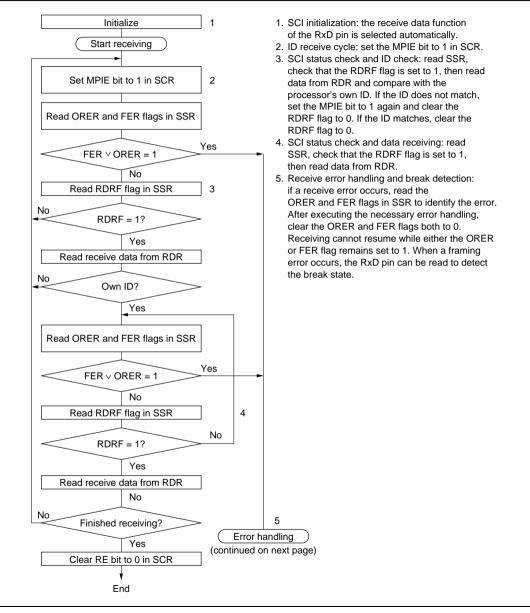


Figure 13.12 Sample Flowchart for Receiving Multiprocessor Serial Data (1)

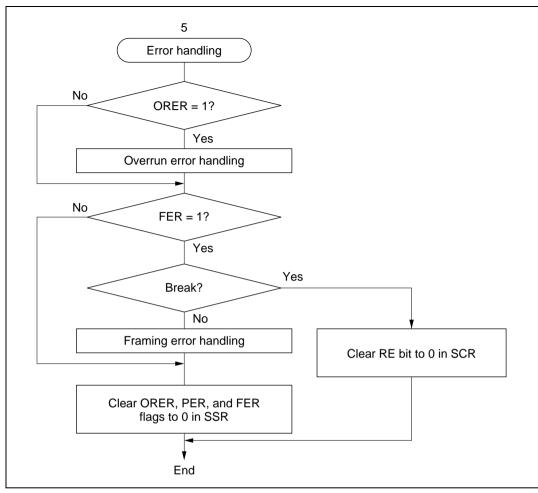


Figure 13.12 Sample Flowchart for Receiving Multiprocessor Serial Data (2)

Figure 13.13 shows an example of SCI receive operation using a multiprocessor format.



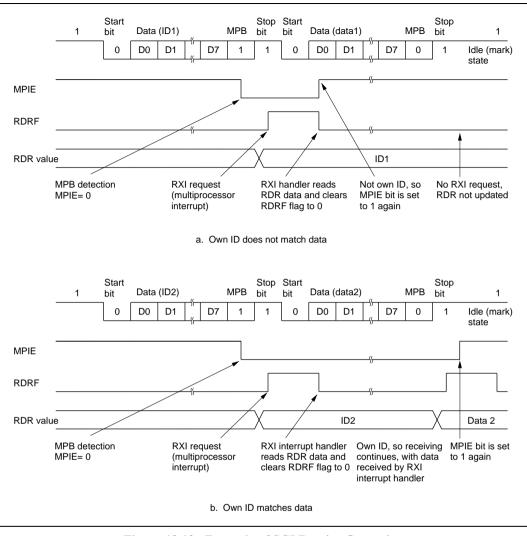


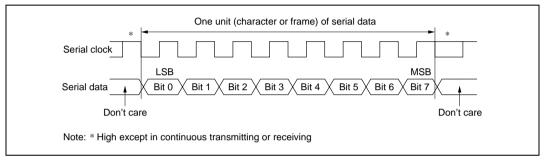
Figure 13.13 Example of SCI Receive Operation (8-Bit Data with Multiprocessor Bit and One Stop Bit)

13.3.4 Synchronous Operation

In synchronous mode, the SCI transmits and receives data in synchronization with clock pulses. This mode is suitable for high-speed serial communication.

The SCI transmitter and receiver share the same clock but are otherwise independent, so full duplex communication is possible. The transmitter and receiver are also double buffered, so continuous transmitting or receiving is possible by reading or writing data while transmitting or receiving is in progress.

Figure 13.14 shows the general format in synchronous serial communication.





In synchronous serial communication, each data bit is placed on the communication line from one falling edge of the serial clock to the next. Data is guaranteed valid at the rise of the serial clock. In each character, the serial data bits are transmitted in order from LSB (first) to MSB (last). After output of the MSB, the communication line remains in the state of the MSB. In synchronous mode the SCI receives data by synchronizing with the rise of the serial clock.

Communication Format: The data length is fixed at 8 bits. No parity bit or multiprocessor bit can be added.

Clock: An internal clock generated by the on-chip baud rate generator or an external clock input from the SCK pin can be selected by clearing or setting the CKE1 bit in SCR. See table 13.9. When the SCI operates on an internal clock, it outputs the clock signal at the SCK pin. Eight clock pulses are output per transmitted or received character.

When the SCI operates on an internal clock, the serial clock outputs the clock signal at the SCK pin. Eight clock pulses are output per transmitted or received character. When the SCI is not transmitting or receiving, the clock signal remains in the high state. However, when receiving only, overrun error may occur or the serial clock continues output until the RE bit clears at 0. When transmitting or receiving in single characters, select the external clock.

Transmitting and Receiving Data

• SCI Initialization (Synchronous Mode)

Before transmitting or receiving, clear the TE and

RE bits to 0 in SCR, then initialize the SCI as follows.

When changing the communication mode or format, always clear the TE and RE bits to 0 before following the procedure given below. Clearing the TE bit to 0 sets the TDRE flag to 1 and initializes TSR. Clearing the RE bit to 0, however, does not initialize the RDRF, PER, FER, and ORE flags and RDR, which retain their previous contents.

Figure 13.15 is a sample flowchart for initializing the SCI.

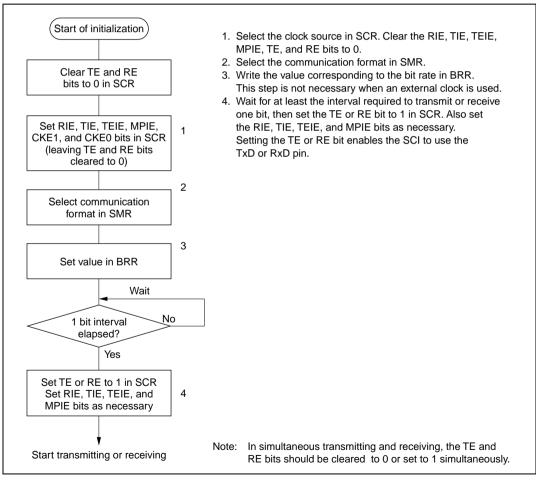
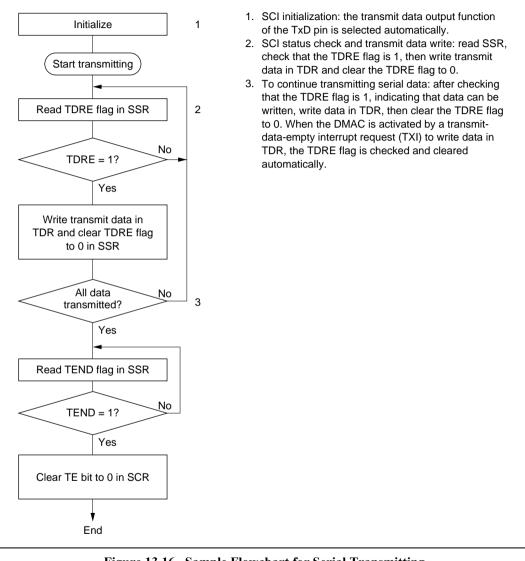


Figure 13.15 Sample Flowchart for SCI Initialization

• Transmitting Serial Data (Synchronous Mode)

Figure 13.16 shows a sample flowchart for transmitting serial data and indicates the procedure to follow.





In transmitting serial data, the SCI operates as follows.

- 1. The SCI monitors the TDRE flag in SSR. When the TDRE flag is cleared to 0 the SCI recognizes that TDR contains new data, and loads this data from TDR into TSR.
- 2. After loading the data from TDR into TSR, the SCI sets the TDRE flag to 1 and starts transmitting. If the TIE bit is set to 1 in SCR, the SCI requests a transmit-data-empty interrupt (TXI) at this time.

If clock output is selected, the SCI outputs eight serial clock pulses. If an external clock source is selected, the SCI outputs data in synchronization with the input clock. Data is output from the TxD pin in order from LSB (bit 0) to MSB (bit 7).

- 3. The SCI checks the TDRE flag when it outputs the MSB (bit 7). If the TDRE flag is 0, the SCI loads data from TDR into TSR and begins serial transmission of the next frame. If the TDRE flag is 1, the SCI sets the TEND flag to 1 in SSR, and after transmitting the MSB, holds the TxD pin in the MSB state. If the TEIE bit in SCR is set to 1, a transmit-end interrupt (TEI) is requested at this time.
- 4. After the end of serial transmission, the SCK pin is held in a constant state.

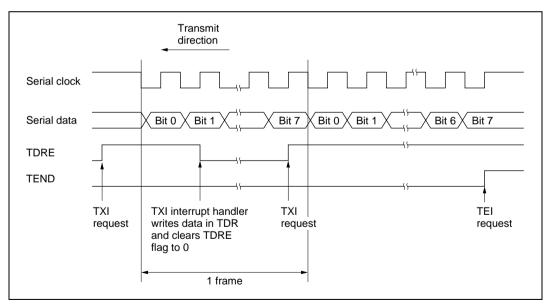
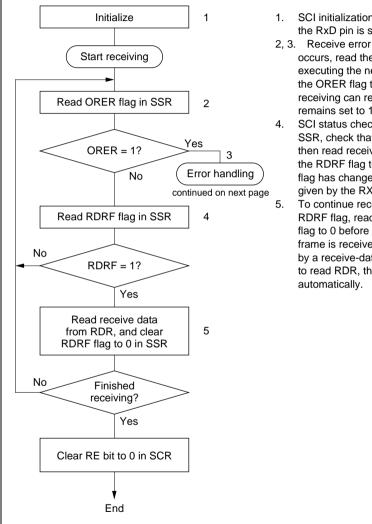


Figure 13.17 shows an example of SCI transmit operation.

Figure 13.17 Example of SCI Transmit Operation

Receiving Serial Data

Figure 13.18 shows a sample flowchart for receiving serial data and indicates the procedure to follow. When switching from asynchronous mode to synchronous mode, make sure that the ORER, PER, and FER flags are cleared to 0. If the FER or PER flag is set to 1 the RDRF flag will not be set and both transmitting and receiving will be disabled.



- 1. SCI initialization: the receive data function of the RxD pin is selected automatically.
- 2, 3. Receive error handling: if a receive error occurs, read the ORER flag in SSR, then after executing the necessary error handling, clear the ORER flag to 0. Neither transmitting nor receiving can resume while the ORER flag remains set to 1.
- 4. SCI status check and receive data read: read SSR, check that the RDRF flag is set to 1, then read receive data from RDR and clear the RDRF flag to 0. Notification that the RDRF flag has changed from 0 to 1 can also be given by the RXI interrupt.
- 5. To continue receiving serial data: check the RDRF flag, read RDR, and clear the RDRF flag to 0 before the MSB (bit 7) of the current frame is received. If the DMAC is activated by a receive-data-full interrupt request (RXI) to read RDR, the RDRF flag is cleared automatically.

Figure 13.18 Sample Flowchart for Serial Receiving (1)

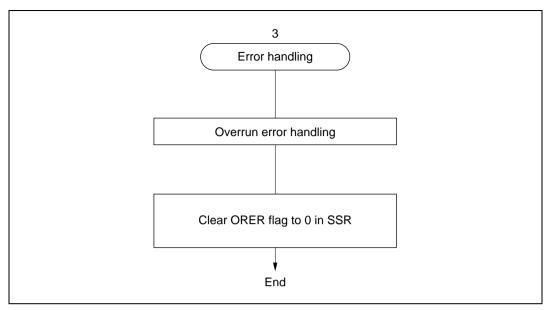


Figure 13.18 Sample Flowchart for Serial Receiving (2)

In receiving, the SCI operates as follows.

- 1. The SCI synchronizes with serial clock input or output and initializes internally.
- 2. Receive data is stored in RSR in order from LSB to MSB.

After receiving the data, the SCI checks that the RDRF flag is 0 so that receive data can be transferred from RSR to RDR. If this check passes, the RDRF flag is set to 1 and the received data is stored in RDR. If the check does not pass (receive error), the SCI operates as indicated in table 13.11.

3. After setting the RDRF flag to 1, if the RIE bit is set to 1 in SCR, the SCI requests a receive-data-full interrupt (RXI). If the ORER flag is set to 1 and the RIE bit in SCR is also set to 1, the SCI requests a receive-error interrupt (ERI).

Figure 13.19 shows an example of SCI receive operation.

Section 13 Serial Communication Interface

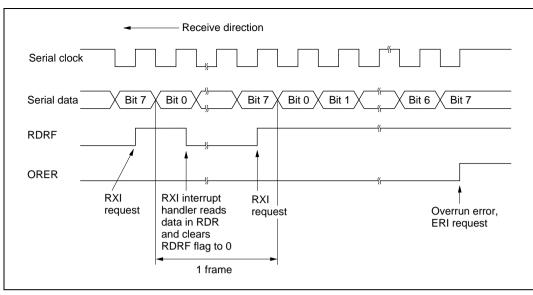
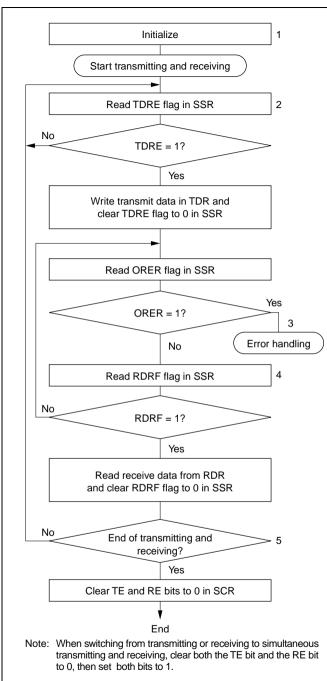


Figure 13.19 Example of SCI Receive Operation

• Transmitting and Receiving Serial Data Simultaneously (Synchronous Mode) Figure 13.20 shows a sample flowchart for transmitting and receiving serial data simultaneously and indicates the procedure to follow.





- SCI initialization: the transmit data output function of the TxD pin and receive data input function of the RxD pin are selected, enabling simultaneous transmitting and receiving.
- SCI status check and transmit data write: read SSR, check that the TDRE flag is 1, then write transmit data in TDR and clear the TDRE flag to 0. Notification that the TDRE flag has changed from 0 to 1 can also be given by the TXI interrupt.
- 3. Receive error handling: if a receive error occurs, read the ORER flag in SSR, then after executing the necessary error handling, clear the ORER flag to 0.

Neither transmitting nor receiving can resume while the ORER flag remains set to 1.

- 4. SCI status check and receive data read: read SSR, check that the RDRF flag is 1, then read receive data from RDR and clear the RDRF flag to 0. Notification that the RDRF flag has changed from 0 to 1 can also be given by the RXI interrupt.
- 5. To continue transmitting and receiving serial data: check the RDRF flag, read RDR, and clear the RDRF flag to 0 before the MSB (bit 7) of the current frame is received. Also check that the TDRE flag is set to 1, indicating that data can be written, write data in TDR, then clear the TDRE flag to 0 before the MSB (bit 7) of the current frame is transmitted. When the DMAC is activated by a transmit-data-empty interrupt request (TXI) to write data in TDR, the TDRE flag is checked and cleared automatically. When the DMAC is activated by a receivedata-full interrupt request (RXI) to read RDR, the RDRF flag is cleared automatically.



13.4 SCI Interrupts

The SCI has four interrupt request sources: TEI (transmit-end interrupt), ERI (receive-error interrupt), RXI (receive-data-full interrupt), and TXI (transmit-data-empty interrupt). Table 13.12 lists the interrupt sources and indicates their priority. These interrupts can be enabled and disabled by the TIE, TEIE, and RIE bits in SCR. Each interrupt request is sent separately to the interrupt controller.

The TXI interrupt is requested when the TDRE flag is set to 1 in SSR. The TEI interrupt is requested when the TEND flag is set to 1 in SSR. The TXI interrupt request can activate the DMAC to transfer data. Data transfer by the DMAC automatically clears the TDRE flag to 0. The TEI interrupt request cannot activate the DMAC.

The RXI interrupt is requested when the RDRF flag is set to 1 in SSR. The ERI interrupt is requested when the ORER, PER, or FER flag is set to 1 in SSR. The RXI interrupt request can activate the DMAC to transfer data. Data transfer by the DMAC automatically clears the RDRF flag to 0. The ERI interrupt request cannot activate the DMAC.

The DMAC can be activated by interrupts from SCI channel 0.

Interrupt	Description	Priority
ERI	Receive error (ORER, FER, or PER)	High
RXI	Receive data register full (RDRF)	\uparrow
TXI	Transmit data register empty (TDRE)	
TEI	Transmit end (TEND)	Low

Table 13.12 SCI Interrupt Sources



13.5 Usage Notes

Note the following points when using the SCI.

TDR Write and TDRE Flag: The TDRE flag in SSR is a status flag indicating the loading of transmit data from TDR into TSR. The SCI sets the TDRE flag to 1 when it transfers data from TDR to TSR.

Data can be written into TDR regardless of the state of the TDRE flag. If new data is written in TDR when the TDRE flag is 0, the old data stored in TDR will be lost because this data has not yet been transferred to TSR. Before writing transmit data in TDR, be sure to check that the TDRE flag is set to 1.

Simultaneous Multiple Receive Errors: Table 13.13 indicates the state of SSR status flags when multiple receive errors occur simultaneously. When an overrun error occurs the RSR contents are not transferred to RDR, so receive data is lost.

RDRF	ORER	FER	PER	Receive Data Transfer RSR → RDR	Receive Errors
1	1	0	0	×	Overrun error
0	0	1	0	0	Framing error
0	0	0	1	0	Parity error
1	1	1	0	×	Overrun error + framing error
1	1	0	1	×	Overrun error + parity error
0	0	1	1	0	Framing error + parity error
1	1	1	1	×	Overrun error + framing error + parity error

Table 13.13 SSR Status Flags and Transfer of Receive Data

Notes: O: Receive data is transferred from RSR to RDR.

×: Receive data is not transferred from RSR to RDR.

Break Detection and Processing: Break signals can be detected by reading the RxD pin directly when a framing error (FER) is detected. In the break state the input from the RxD pin consists of all 0s, so the FER flag is set and the parity error flag (PER) may also be set. In the break state the SCI receiver continues to operate, so if the FER flag is cleared to 0 it will be set to 1 again.

Sending a Break Signal: When the TE bit is cleared to 0 the TxD pin becomes an I/O port, the level and direction (input or output) of which are determined by DR and DDR bits. This feature can be used to send a break signal.

After the serial transmitter is initialized, the DR value substitutes for the mark state until the TE bit is set to 1 (the TxD pin function is not selected until the TE bit is set to 1). The DDR and DR bits should therefore both be set to 1 beforehand.

To send a break signal during serial transmission, clear the DR bit to 0, then clear the TE bit to 0. When the TE bit is cleared to 0 the transmitter is initialized, regardless of its current state, so the TxD pin becomes an output port outputting the value 0.

Receive Error Flags and Transmitter Operation (Synchronous Mode Only): When a receive error flag (ORER, PER, or FER) is set to 1 the SCI will not start transmitting, even if the TDRE flag is cleared to 0. Be sure to clear the receive error flags to 0 when starting to transmit. Note that clearing the RE bit to 0 does not clear the receive error flags to 0.

Receive Data Sampling Timing in Asynchronous Mode and Receive Margin: In asynchronous mode the SCI operates on a base clock with 16 times the bit rate frequency. In receiving, the SCI synchronizes internally with the fall of the start bit, which it samples on the base clock. Receive data is latched at the rising edge of the eighth base clock pulse. See figure 13.21.

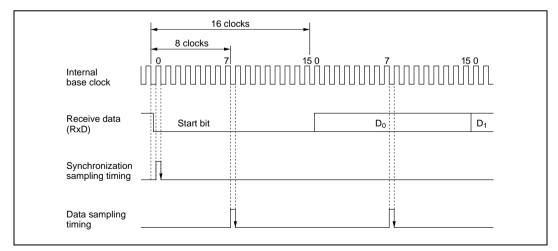


Figure 13.21 Receive Data Sampling Timing in Asynchronous Mode



The receive margin in asynchronous mode can therefore be expressed as in equation (1).

$$M = \left| (0.5 - \frac{1}{2N}) - (L - 0.5) F - \frac{|D - 0.5|}{N} (1 + F) \right| \times 100\% \dots (1)$$

M: Receive margin (%)

N: Ratio of clock frequency to bit rate (N = 16)

- D: Clock duty cycle (D = 0 to 1.0)
- L: Frame length (L = 9 to 12)
- F: Absolute deviation of clock frequency

From equation (1), if F = 0 and D = 0.5 the receive margin is 46.875%, as given by equation (2).

This is a theoretical value. A reasonable margin to allow in system designs is 20% to 30%.

Restrictions on Usage of DMAC: To have the DMAC read RDR, be sure to select the SCI receive-data-full interrupt (RXI) as the activation source with bits DTS2 to DTS0 in DTCR.

Restrictions on Usage of the Serial Clock: When transmitting data using an external clock as the serial clock, an interval of at least 5 states is necessary between clearing the TDRE bit in SSR and the start (falling edge) of the first transmit clock pulse corresponding to each frame (see figure 13.22). This condition is also needed for continuous transmission. If it is not fulfilled, operational error will occur.

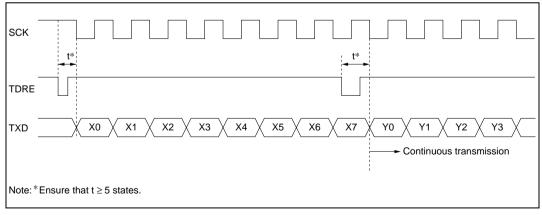


Figure 13.22 Serial Clock Transmission (Example)

Switching SCK Pin to Port Output Pin Function in Synchronous Mode: When the SCK pin is used as the serial clock output in synchronous mode, and is then switched to its output port function at the end of transmission, a low level may be output for one half-cycle. Half-cycle low-level output occurs when SCK is switched to its port function with the following settings when DDR = 1, DR = 1, $C/\overline{A} = 1$, CKE1 = 0, CKE0 = 0, and TE = 1.

- 1. End of serial data transmission
- 2. TE bit = 0
- 3. C/\overline{A} bit = 0 ... switchover to port output
- 4. Occurrence of low-level output (see figure 13.23)

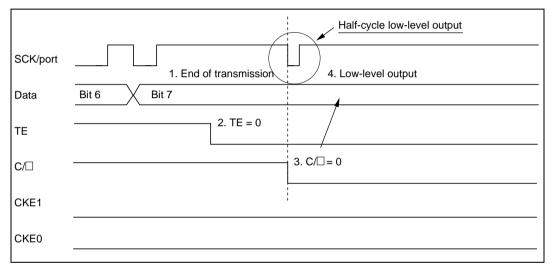


Figure 13.23 Operation when Switching from SCK Pin Function to Port Pin Function



Sample Procedure for Preventing Low-Level Output

As this sample procedure temporarily places the SCK pin in the input state, the SCK/port pin should be pulled up beforehand with an external circuit.

With DDR = 1, DR = 1, C/A = 1, CKE1 = 0, CKE0 = 0, and TE = 1, make the following settings in the order shown.

- 1. End of serial data transmission
- 2. TE bit = 0
- 3. CKE1 bit = 1
- 4. C/\overline{A} bit = 0 ... switchover to port output
- 5. CKE1 bit = 0

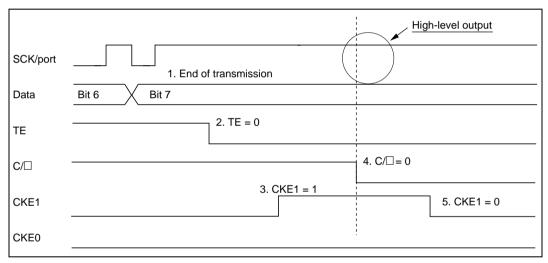


Figure 13.24 Operation when Switching from SCK Pin Function to Port Pin Function (Example of Preventing Low-Level Output)



Section 14 Smart Card Interface

14.1 Overview

As an extension of its serial communication interface functions, SCI0 supports a smart card (IC card) interface conforming to the ISO/IEC7816-3 (Identification Card) standard. Switchover between normal serial communication and the smart card interface is controlled by a register setting.

14.1.1 Features

Features of the smart-card interface supported by the H8/3048 Group are listed below.

- Asynchronous communication
 - Data length: 8 bits
 - Parity bits generated and checked
 - Error signal output in receive mode (parity error)
 - Error signal detect and automatic data retransmit in transmit mode
 - Supports both direct convention and inverse convention
- Built-in baud rate generator with selectable bit rates
- Three types of interrupts

Transmit-data-empty, receive-data-full, and receive-error interrupts are requested independently. The transmit-data-empty and receive-data-full interrupts can activate the DMA controller (DMAC) to transfer data.

14.1.2 Block Diagram

Figure 14.1 shows a block diagram of the smart card interface.

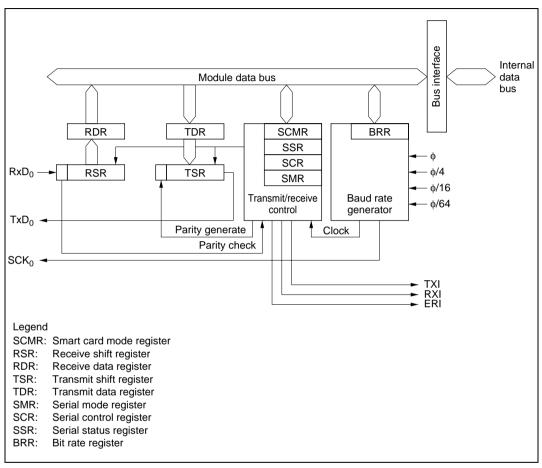


Figure 14.1 Smart Card Interface Block Diagram



14.1.3 Input/Output Pins

Table 14.1 lists the smart card interface pins.

Table 14.1 Smart Card Interface Pins

Name	Abbreviation	I/O	Function
Serial clock pin	SCK ₀	Output	Clock output
Receive data pin	RxD ₀	Input	Receive data input
Transmit data pin	TxD ₀	Output	Transmit data output

14.1.4 Register Configuration

The smart card interface has the internal registers listed in table 14.2. BRR, TDR, and RDR have their normal serial communication interface functions, as described in section 13, Serial Communication Interface.

Table 14.2 Registers

Address* ¹	Name	Abbreviation	R/W	Initial Value
H'FFB0	Serial mode register	SMR	R/W	H'00
H'FFB1	Bit rate register	BRR	R/W	H'FF
H'FFB2	Serial control register	SCR	R/W	H'00
H'FFB3	Transmit data register	TDR	R/W	H'FF
H'FFB4	Serial status register	SSR	R/(W)* ²	F'84
H'FFB5	Receive data register	RDR	R	H'00
H'FFB6	Smart card mode register	SCMR	R/W	H'F2
N. 4 1				

Notes: 1. Lower 16 bits of the address.

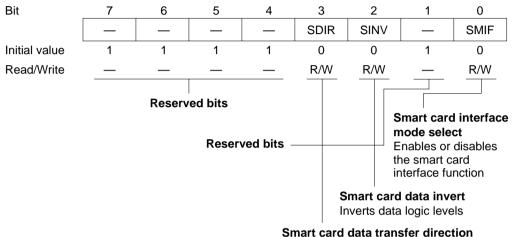
2. Only 0 can be written, to clear flags.

14.2 **Register Descriptions**

This section describes the new or modified registers and bit functions in the smart card interface.

14.2.1 Smart Card Mode Register (SCMR)

SCMR is an 8-bit readable/writable register that selects smart card interface functions.



Selects the serial/parallel conversion format

SCMR is initialized to H'F2 by a reset and in standby mode.

Bits 7 to 4—Reserved: Read-only bits, always read as 1.

Bit 3—Smart Card Data Transfer Direction (SDIR): Selects the serial/parallel conversion format.

Bit 3: SDIR	Description	
0	TDR contents are transmitted LSB-first	(Initial value)
	Received data is stored LSB-first in RDR	
1	TDR contents are transmitted MSB-first	
	Received data is stored MSB-first in RDR	

Bit 2—Smart Card Data Inverter (SINV): Inverts data logic levels. This function is used in combination with bit 3 to communicate with inverse-convention cards. SINV does not affect the logic level of the parity bit. For parity settings, see section 14.3.4, Register Settings.

Bit 2: SINV	Description	
0	Unmodified TDR contents are transmitted	(Initial value)
	Received data is stored unmodified in RDR	
1	Inverted TDR contents are transmitted	
	Received data is inverted before storage in RDR	

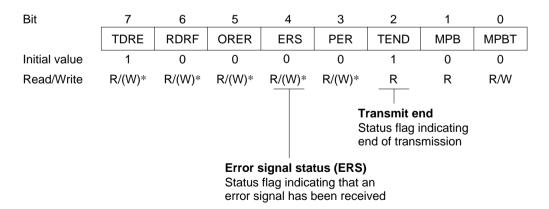
Bit 1—Reserved: Read-only bit, always read as 1.

Bit 0—Smart Card Interface Mode Select (SMIF): Enables the smart card interface function.

Bit 0: SMIF	Description	
0	Smart card interface function is disabled	(Initial value)
1	Smart card interface function is enabled	

14.2.2 Serial Status Register (SSR)

The function of SSR bit 4 is modified in the smart card interface. This change also causes a modification to the setting conditions for bit 2 (TEND).



Note: * Only 0 can be written, to clear the flag.

Bits 7 to 5: These bits operate as in normal serial communication. For details see section 13, Serial Communication Interface.

Bit 4—Error Signal Status (ERS): In smart card interface mode, this flag indicates the status of the error signal sent from the receiving device to the transmitting device. The smart card interface does not detect framing errors.

Bit 4: ERS	Description			
0	Indicates normal data transmission, with no error signal returned (Initial value)			
	[Clearing conditions]			
	The chip is reset or enters standby mode.			
	Software reads ERS while it is set to 1, then writes 0.			
1	Indicates that the receiving device sent an error signal reporting a parity error			
	[Setting condition]			
	A low error signal was sampled.			

Note: Clearing the TE bit to 0 in SCR does not affect the ERS flag, which retains its previous value.

Bits 3 to 0: These bits operate as in normal serial communication. For details see section 13, Serial Communication Interface. The setting conditions for transmit end (TEND, bit 2), however, are modified as follows.

Bit 2: TEND	Description				
0	Transmission is in progress				
	[Clearing conditions]				
	Software reads TDRE while it is set to 1, then writes 0 in the	e TDRE flag.			
	The DMAC writes data in TDR.				
1	End of transmission	(Initial value)			
	[Setting conditions]				
	The chip is reset or enters standby mode.				
	The TE bit and FER/ERS bit are both cleared to 0 in SCR.				
	TDRE is 1 and FER/ERS is 0 at a time 2.5 etu after the last serial character is transmitted (normal transmission)	bit of a 1-byte			
NI 1 1 1 1					

Note: An etu (elementary time unit) is the time needed to transmit one bit.

14.2.3 Serial Mode Register (SMR)

Bit 7 of SMR has a different function in smart card interface mode. The related serial control register (SCR) changes from bit 1 to bit 0. However, this function does not exist in the flash memory version.

Bit	7	6	5	4	3	2	1	0
	GM	CHR	PR	O/E	STOP	MP	CKS1	CKS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bit 7-GSM Mode (GM): Set at 0 when using the regular smart card interface. In GSM mode, set to 1. When transmission is complete, initially the TEND flag set timing appears followed by clock output restriction mode. Clock output restriction mode comprises serial control register bit 1 and bit 0.

Bit 7: GM	Description	
0	Using the regular smart card interface mode	
	The TEND flag is set 12.5 etu after the beginning of the start bit	(Initial value)
	Clock output on/off control only	
1	Using the GSM mode smart card interface mode	
	The TEND flag is set 11.0 etu after the beginning of the start bit	
	Clock output on/off and fixed-high/fixed-low control	

Bits 6 to 0—Operate in the same way as for the normal SCI.

For details, see section 13.2.5, Serial Mode Register (SMR).

14.2.4 Serial Control Register (SCR)

Bits 1 and 0 have different functions in smart card interface mode. However, this function does not exist in the flash memory version.

Bit	7	6	5	4	3	2	1	0
	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Bits 7 to 2—Operate in the same way as for the normal SCI.

For details, see section 13.2.6, Serial Control Register (SCR).

Bits 1 and 0—Clock Enable (CKE1, CKE0): Setting enable or disable for the SCI clock selection and clock output from the SCK pin. In smart card interface mode, it is possible to switch between enabling and disabling of the normal clock output, and specify a fixed high level or fixed low level for the clock output.

SMR	SCR		
Bit 7: GM	Bit 1: CKE1	Bit 0: CKE0	 Description
0	0	0	The internal clock/SCK0 pin functions as an I/O port (Initial value)
0	0	1	The internal clock/SCK0 pin functions as the clock output
1	0	0	The internal clock/SCK0 pin is fixed at low-level output
1	0	1	The internal clock/SCK0 pin functions as the clock output
1	1	0	The internal clock/SCK0 pin is fixed at high-level output
1	1	1	The internal clock/SCK0 pin functions as the clock output



14.3 Operation

14.3.1 Overview

The main features of the smart-card interface are as follows.

- One frame consists of eight data bits and a parity bit.
- In transmitting, a guard time of at least two elementary time units (2 etu) is provided between the end of the parity bit and the start of the next frame. (An elementary time unit is the time required to transmit one bit.)
- In receiving, if a parity error is detected, a low error signal is output for 1 etu, beginning 10.5 etu after the start bit.
- In transmitting, if an error signal is received, after at least 2 etu, the same data is automatically transmitted again.
- Only asynchronous communication is supported. There is no synchronous communication function.

14.3.2 Pin Connections

Figure 14.2 shows a pin connection diagram for the smart card interface.

In communication with a smart card, data is transmitted and received over the same signal line. The TxD_0 and RxD_0 pins should both be connected to this line. The data transmission line should be pulled up to V_{CC} through a resistor.

If the smart card uses the clock generated by the smart card interface, connect the SCK_0 output pin to the card's CLK input. If the card uses its own internal clock, this connection is unnecessary.

The reset signal should be output from one of the H8/3048 Group's generic ports.

In addition to these pin connections, power and ground connections will normally also be necessary.

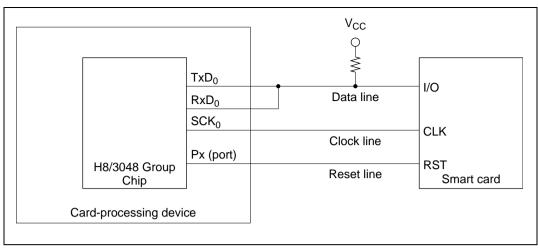


Figure 14.2 Smart Card Interface Connection Diagram

Note: A loop-back test can be performed by setting both RE and TE to 1 without connecting a smart card.



14.3.3 Data Format

Figure 14.3 shows the data format of the smart card interface. In receive mode, parity is checked once per frame. If a parity error is detected, an error signal is returned to the transmitting device to request retransmission. In transmit mode, the error signal is sampled and the same data is retransmitted if the error signal is low.

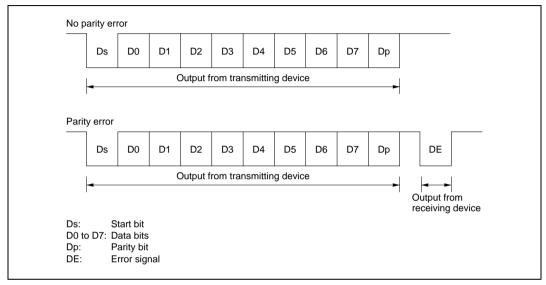


Figure 14.3 Smart Card Interface Data Format

The operating sequence is as follows.

- 1. When not in use, the data line is in the high-impedance state, and is pulled up to the high level through a resistor.
- 2. To start transmitting a frame of data, the transmitting device transmits a low start bit (Ds), followed by eight data bits (D0 to D7) and a parity bit (Dp).
- 3. Next, in the smart card interface, the transmitting device returns the data line to the highimpedance state. The data line is pulled up to the high level through a resistor.
- 4. The receiving device performs a parity check. If there is no parity error, the receiving device waits to receive the next data. If a parity error is present, the receiving device outputs a low error signal (DE) to request retransmission of the data. After outputting the error signal for a designated interval, the receiving device returns the signal line to the high-impedance state. The signal line is pulled back up to the high level through the pull-up resistor.
- 5. If the transmitting device does not receive an error signal, it proceeds to transmit the next data. If it receives an error signal, it returns to step 2 and transmits the same data again.

14.3.4 Register Settings

Table 14.3 shows a bit map of the registers used in the smart card interface. Bits indicated as 0 or 1 should always be set to the indicated value. The settings of the other bits will be described in this section.

Register	Address*1	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SMR	H'FFB0	GM	0	1	O/E	1	0	CKS1	CKS0
BRR	H'FFB1	BRR7	BRR6	BRR5	BRR4	BRR3	BRR2	BRR1	BRR0
SCR	H'FFB2	TIE	RIE	TE	RE	0	0	CKE1*2	CKE0
TDR	H'FFB3	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR1	TDR0
SSR	H'FFB4	TDRE	RDRF	ORER	ERS	PER	TEND	0	0
RDR	H'FFB5	RDR7	RDR6	RDR5	RDR4	RDR3	RDR2	RDR1	RDR0
SCMR	H'FFB6	_	_		_	SDIR	SINV	_	SMIF

 Table 14.3
 Register Settings in Smart Card Interface

Notes: — Unused bit.

1. Lower 16 bits of the address.

2. When the GM of the SMR is set at 0, be sure the CKE1 bit is 0.

Serial Mode Register (SMR) Settings: In regular smart card interface mode, set the GM bit at 0. In regular smart card mode, clear the GM bit to 0. In GSM mode, set the GM bit to 1. Clear the O/\overline{E} bit to 0 if the smart card uses the direct convention. Set the O/\overline{E} bit to 1 if the smart card uses the inverse convention. Bits CKS1 and CKS0 select the clock source of the built-in baud rate generator. See section 14.3.5, Clock.

Bit Rate Register (BRR) Settings: This register sets the bit rate. Equations for calculating the setting are given in section 14.3.5, Clock.

Serial Control Register (SCR): The TIE, RIE, TE, and RE bits have their normal serial communication functions. For details, see section 13, Serial Communication Interface. The CKE1 and CKE0 bits select clock output. When the GM bit of the SMR is cleared to 0, to disable clock output, clear this bit to 00. To enable clock output, set this bit to 01. When the GM bit of the SMR is set to 1, clock output is enabled. Clock output is fixed at high or low.

Smart Card Mode Register (SCMR): If the smart card follows the direct convention, clear the SDIR and SINV bits to 0. If the smart card follows the indirect convention, set the SDIR and SINV bits to 1. To use the smart card interface, set the SMIF bit to 1.

The register settings and examples of starting character waveforms are shown below for two smart cards, one following the direct convention and one the inverse convention.

• Direct convention (SDIR = SINV =
$$O/\overline{E} = 0$$
)

(Z)	А	Z	Z	А	Z	Z	Z	А	А	Z	(Z)	State
	Ds	D0	D1	D2	D3	D4	D5	D6	D7	Dp		

In the direct convention, state Z corresponds to logic level 1, and state A to logic level 0. Characters are transmitted and received LSB-first. In the example above the first character data is H'3B. The parity bit is 1, following the even parity rule designated for smart cards.

• Inverse convention (SDIR = SINV =
$$O/\overline{E} = 1$$
)

(Z)	А	Z	Z	А	А	А	А	А	А	Z	(Z)	State
	Ds	D7	D6	D5	D4	D3	D2	D1	D0	Dp		

In the inverse convention, state A corresponds to the logic level 1, and state Z to the logic level 0. Characters are transmitted and received MSB-first. In the example above the first character data is H'3F. Following the even parity rule designated for smart cards, the parity bit logic level is 0, corresponding to state Z.

In the H8/3048 Group, the SINV bit inverts only the data bits D7 to D0. The parity bit is not inverted, so the O/\overline{E} bit in SMR must be set to odd parity mode. This applies in both transmitting and receiving.

14.3.5 Clock

As its serial communication clock, the smart card interface can use only the internal clock generated by the on-chip baud rate generator. The bit rate can be selected by setting the bit rate register (BRR) and bits CKS1 and CKS0 in the serial mode register (SMR). The bit rate can be calculated from the equation given below. Table 14.5 lists some examples of bit rate settings.

If bit CKE0 is set to 1, a clock signal with a frequency equal to 372 times the bit rate is output from the SCK_0 pin.

$$\mathsf{B} = \frac{\varphi}{1488 \times 2^{2n-1} \times (\mathsf{N}+1)} \times 10^6$$

where, N: BRR setting $(0 \le N \le 255)$

- B: Bit rate (bits/s)
- φ: System clock frequency (MHz)*
- n: See table 14.4

Table 14.4 n-Values of CKS1 and CKS0 Settings

n	CKS1	CKS0
0	0	0
1	0	1
2	1	0
3	1	1

Note: * If the gear function is used to divide the system clock frequency, use the divided frequency to calculate the bit rate. The equation above applies directly to 1/1 frequency division.

Table 14.5 Bit Rates (bits/s) for Different BRR Settings (when n = 0)

		φ (MHz)											
Ν	7.1424	10.00	10.7136	13.00	14.2848	16.00	18.00						
0	9600.0	13440.9	14400.0	17473.1	19200.0	21505.4	24193.5						
1	4800.0	6720.4	7200.0	8736.6	9600.0	10752.7	12096.8						
2	3200.0	4480.3	4800.0	5824.4	6400.0	7168.5	8064.5						

Note: Bit rates are rounded off to one decimal place.

The following equation calculates the bit rate register (BRR) setting from the system clock frequency and bit rate. N is an integer from 0 to 255, specifying the value with the smaller error.

$$N = \frac{\phi}{1488 \times 2^{2n-1} \times B} \times 10^6 - 1$$

 Table 14.6
 BRR Settings for Typical Bit Rate (bits/s) (when n = 0)

							¢	(MHz)						
		7.1424		10.00	1	0.7136		13.00	1	4.2848		16.00		18.00
Bit/s	Ν	Error	Ν	Error	Ν	Error	Ν	Error	Ν	Error	Ν	Error	Ν	Error
9600	0	0.00	1	30.00	1	25.00	1	8.99	1	0.00	1	12.01	2	15.99

 Table 14.7
 Maximum Bit Rates for Various Frequencies (Smart Card Interface)

φ (MHz)	Maximum Bit Rate (bits/s)	Ν	n	
7.1424	9600	0	0	
10.00	13441	0	0	
10.7136	14400	0	0	
13.00	17473	0	0	
14.2848	19200	0	0	
16.00	21505	0	0	
18.00	24194	0	0	

The bit rate error is calculated from the following equation.

Error (%) =
$$\left\{ \frac{\phi}{1488 \times 2^{2n-1} \times B \times (N+1)} \times 10^6 - 1 \right\} \times 100$$

14.3.6 Transmitting and Receiving Data

Initialization: Before transmitting or receiving data, initialize the smart card interface by the procedure below. Initialization is also necessary when switching from transmit mode to receive mode or from receive mode to transmit mode.

- 1. Clear the TE and RE bits to 0 in the serial control register (SCR).
- 2. Clear the ERS, PER, and ORER error flags to 0 in the serial status register (SSR).
- 3. Set the parity mode bit (O/E) and baud rate generator clock source select bits (CKS1 and CKS0) as required in the serial mode register (SMR). At the same time, clear the C/A, CHR, and MP bits to 0, and set the STOP and PE bits to 1.
- 4. Set the SMIF, SDIR, and SINV bits as required in the smart card mode register (SMR). When the SMIF bit is set to 1, the TxD_0 and RxD_0 pins switch from their I/O port functions to their serial communication interface functions, and are placed in the high-impedance state.
- 5. Set a value corresponding to the desired bit rate in the bit rate register (BRR).
- 6. Set clock enable bit 0 (CKE0) as required in the serial control register (SCR). Write 0 in the TIE, RIE, TE, RE, MPIE, TEIE, and CKE1 bits. If bit CKE0 is set to 1, a serial clock will be output from the SCK₀ pin.
- 7. Wait for at least the interval required to transmit or receive one bit, then set the TIE, RIE, TE, and RE bits as necessary in SCR. Do not set TE and RE both to 1, except when performing a loop-back test.

Transmitting Serial Data: The transmitting procedure in smart card mode is different from the normal SCI procedure, because of the need to sample the error signal and retransmit. Figure 14.4 shows a flowchart for transmitting, and figure 14.5 shows the relation between a transmit operation and the internal registers.

- 1. Initialize the smart card interface by the procedure given above in Initialization.
- 2. Check that the ERS error flag is cleared to 0 in SSR.
- 3. Check that the TEND flag is set to 1 in SSR. Repeat steps 2 and 3 until this check passes.
- 4. Write transmit data in TDR and clear the TDRE flag to 0. The data will be transmitted and the TEND flag will be cleared to 0.
- 5. To continue transmitting data, return to step 2.
- 6. To terminate transmission, clear the TE bit to 0.

This procedure may include interrupt handling and DMA transfer.

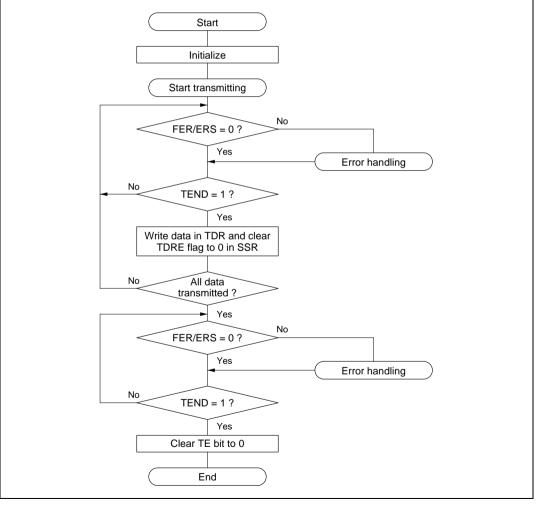
If the TIE bit is set to 1 to enable interrupt requests, when transmission is completed and the TEND flag is set to 1, a transmit-data-empty interrupt (TXI) is requested. If the RIE bit is set to 1

to enable interrupt requests, when a transmit error occurs and the ERS flag is set to 1, a transmit/receive-error interrupt (ERI) is requested.

The timing of TEND flag setting depends on the GM bit in SMR. The timing is shown in figure 14.6.

If the TXI interrupt activates the DMAC, the number of bytes designated in the DMAC can be transmitted automatically, including automatic retransmit.

For details, see Interrupt Operations and Data Transfer by DMAC in this section.





Section 14 Smart Card Interface

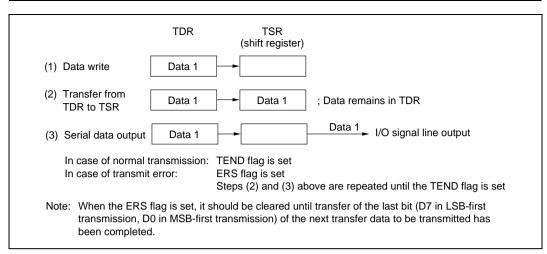


Figure 14.5 Relation Between Transmit Operation and Internal Registers

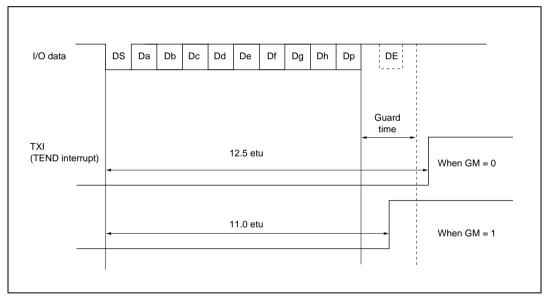


Figure 14.6 TEND Flag Occurrence Timing

Receiving Serial Data: The receiving procedure in smart card mode is the same as the normal SCI procedure. Figure 14.7 shows a flowchart for receiving.

- 1. Initialize the smart card interface by the procedure given in Initialization at the beginning of this section.
- 2. Check that the ORER and PER error flags are cleared to 0 in SSR. If either flag is set, carry out the necessary error handling, then clear both the ORER and PER flags to 0.
- 3. Check that the RDRF flag is set to 1. Repeat steps 2 and 3 until this check passes.
- 4. Read receive data from RDR.
- 5. To continue receiving data, clear the RDRF flag to 0 and return to step 2.
- 6. To terminate receiving, clear the RE bit to 0.

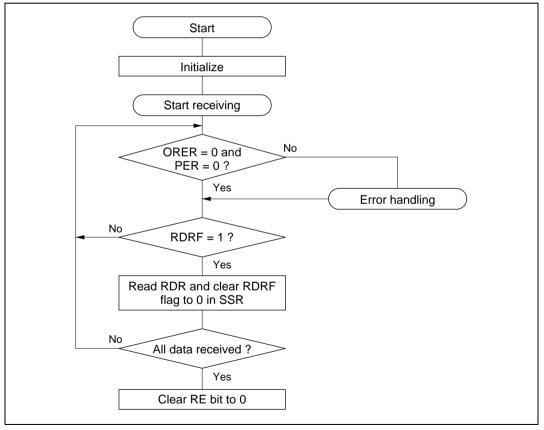


Figure 14.7 Receive Flowchart (Example)

Section 14 Smart Card Interface

This procedure may include interrupt handling and DMA transfer.

If the RIE bit is set to 1 to enable interrupt requests, when receiving is completed and the RDRF flag is set to 1, a receive-data-full interrupt (RXI) is requested. If a receive error occurs, either the ORER or PER flag is set to 1 and a transmit/receive-error interrupt (ERI) is requested.

If the RXI interrupt activates the DMAC, the number of bytes designated in the DMAC will be transferred, skipping receive data in which an error occurred.

For details, see Interrupt Operations and Data Transfer by DMAC below.

When a parity error occurs and PER is set to 1, the receive data is transferred to RDR, so the erroneous data can be read.

Switching Modes: To switch from receive mode to transmit mode, check that receiving operations have completed, then initialize the smart card interface, clearing RE to 0 and setting TE to 1. Completion of receive operations is indicated by the RDRF, PER, or ORER flag.

To switch from transmit mode to receive mode, check that transmitting operations have completed, then initialize the smart card interface, clearing TE to 0 and setting RE to 1. Completion of transmit operations can be verified from the TEND flag.

Fixing Clock Output: When the GM bit of the SMR is set to 1, clock output is fixed by CKE1 and CKE0 of SCR. In this case, the clock pulse can be set at minimum value.

Figure 14.8 shows clock output fixed timing: CKE0 is restricted with GM = 1 and CKE1 = 1.

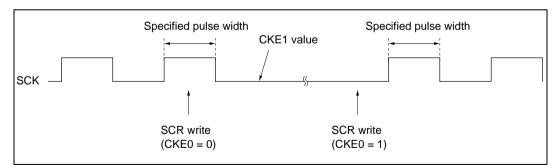


Figure 14.8 Clock Output Fixed Timing

Interrupt Operations: The smart card interface has three interrupt sources: transmit-data-empty (TXI), transmit/receive-error (ERI), and receive-data-full (RXI). The transmit-end interrupt request (TEI) is not available in smart card mode.

A TXI interrupt is requested when the TEND flag is set to 1 in SSR. An RXI interrupt is requested when the RDRF flag is set to 1 in SSR. An ERI interrupt is requested when the ORER, PER, or ERS flag is set to 1 in SSR. These relationships are shown in table 14.8.

Operating State		Flag	Mask Bit	Interrupt Source	DMAC Activation
Transmit mode	Normal operation	TEND	TIE	TXI	Available
	Error	ERS	RIE	ERI	Not available
Receive mode	Normal operation	RDRF	RIE	RXI	Available
	Error	PER, ORER	RIE	ERI	Not available

Table 14.8 Smart Card Mode Operating States and Interrupt Sources

Data Transfer by DMAC: The DMAC can be used to transmit and receive in smart card mode, as in normal SCI operations. In transmit mode, when the TEND flag is set to 1 in SSR, the TDRE flag is set simultaneously, generating a TXI interrupt. If TXI is designated in advance as a DMAC activation source, the DMAC will be activated by the TXI request and will transfer the next transmit data. This data transfer by the DMAC automatically clears the TDRE and TEND flags to 0. When an error occurs, the SCI automatically retransmits the same data, keeping TEND cleared to 0 so that the DMAC is not activated. The SCI and DMAC will therefore automatically transmit the designated number of bytes, including retransmission when an error occurs. When an error occurs the ERS flag is not cleared automatically, so the RIE bit should be set to 1 to enable the error to generate an ERI request, and the ERI interrupt handler should clear ERS.

When using the DMAC to transmit or receive, first set up and enable the DMAC, then make SCI settings. DMAC settings are described in section 8, DMA Controller.

In receive operations, when the RDRF flag is set to 1 in SSR, an RXI interrupt is requested. If RXI is designated in advance as a DMAC activation source, the DMAC will be activated by the RXI request and will transfer the received data. This data transfer by the DMAC automatically clears the RDRF flag to 0. When an error occurs, the RDRF flag is not set and an error flag is set instead. The DMAC is not activated. The ERI interrupt request is directed to the CPU. The ERI interrupt handler should clear the error flags.

Examples of Operation in GSM Mode: When switching between smart card interface mode and software standby mode, use the following procedures to maintain the clock duty cycle.

- Switching from smart card interface mode to software standby mode
 - 1. Set the P94 data register (DR) and data direction register (DDR) to the values for the fixed output state in software standby mode.
 - 2. Write 0 to the TE and RE bits in the serial control register (SCR) to stop transmit/receive operations. At the same time, set the CKE1 bit to the value for the fixed output state in software standby mode.
 - 3. Write 0 to the CKE0 bit in SCR to stop the clock.
 - 4. Wait for one serial clock cycle. During this period, the duty cycle is preserved and clock output is fixed at the specified level.
 - 5. Write H'00 to the serial mode register (SMR) and smart card mode register (SCMR).
 - 6. Make the transition to the software standby state.
- Returning from software standby mode to smart card interface mode
 - 1. Clear the software standby state.
 - 2. Set the CKE1 bit in SCR to the value for the fixed output state at the start of software standby (the current P94 pin state).
 - 3. Set smart card interface mode and output the clock. Clock signal generation is started with the normal duty cycle.

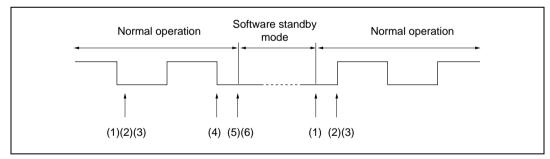


Figure 14.9 Procedure for Stopping and Restarting the Clock

Use the following procedure to secure the clock duty cycle after powering on.

- 1. The initial state is port input and high impedance. Use pull-up or pull-down resistors to fix the potential.
- 2. Fix at the output specified by the CKE1 bit in SCR.
- 3. Set SMR and SCMR, and switch to smart card interface mode operation.
- 4. Set the CKE0 bit in SCR to 1 to start clock output.



14.4 Usage Notes

When using the SCI as a smart card interface, note the following points.

Receive Data Sampling Timing in Smart Card Mode and Receive Margin: In smart card mode the SCI operates on a base clock with 372 times the bit rate frequency. In receiving, the SCI synchronizes internally with the fall of the start bit, which it samples on the base clock. Receive data is latched at the rising edge of the 186th base clock pulse. See figure 14.10.

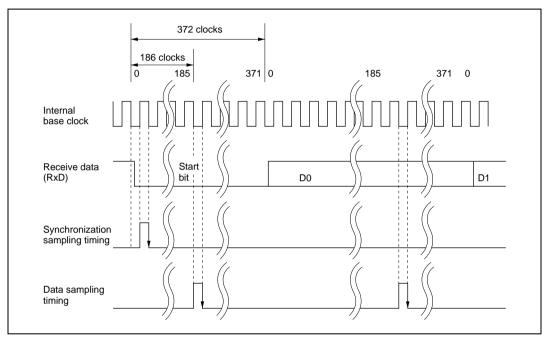


Figure 14.10 Receive Data Sampling Timing in Smart Card Mode

The receive margin can therefore be expressed as follows.

Receive margin in smart card mode:

$$M = \left| \left\{ 0.5 - \frac{1}{2N} \right\} - (L - 0.5) F - \frac{|D - 0.5|}{N} (1 + F) \right| \times 100\%$$

- M: Receive margin (%)
- N: Ratio of clock frequency to bit rate (N = 372)
- D: Clock duty cycle (D = 0 to 1.0)
- L: Frame length (L = 10)
- F: Absolute deviation of clock frequency

From this equation, if F = 0 and D = 0.5 the receive margin is as follows.

D = 0.5, F = 0 M = $\{0.5 - 1/(2 \times 372)\} \times 100\%$ = 49.866%

Retransmission: Retransmission is described below for the separate cases of transmit mode and receive mode.

- Retransmission when SCI is in Receive Mode (see figure 14.11)
- (1) The SCI checks the received parity bit. If it detects an error, it automatically sets the PER flag to 1. If the RIE bit in SCR is set to the enable state, an ERI interrupt is requested. The PER flag should be cleared to 0 in SSR before the next parity bit sampling timing.
- (2) The RDRF bit in SSR is not set to 1 for the error frame.
- (3) If an error is not detected when the parity bit is checked, the PER flag is not set in SSR.
- (4) If an error is not detected when the parity bit is checked, receiving operations are assumed to have ended normally, and the RDRF bit is automatically set to 1 in SSR. If the RIE bit in SCR is set to the enable state, an RXI interrupt is requested. If RXI is enabled as a DMA transfer activation source, the RDR contents can be read automatically. When the DMAC reads the RDR data, it automatically clears RDRF to 0.
- (5) When a normal frame is received, at the error signal transmit timing, the data pin is held in the high-impedance state.

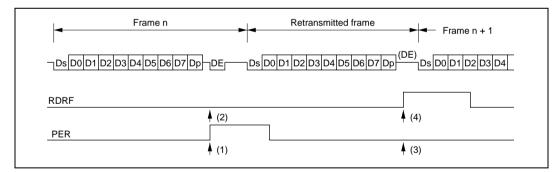


Figure 14.11 Retransmission in SCI Receive Mode

- Retransmission when SCI is in Transmit Mode (see figure 14.12)
- (6) After transmitting one frame, if the receiving device returns an error signal, the SCI sets the ERS flag to 1 in SSR. If the RIE bit in SCR is set to the enable state, an ERI interrupt is requested. The ERS flag should be cleared to 0 in SSR before the next parity bit sampling timing.
- (7) The TEND bit in SSR is not set for the frame in which the error signal was received, indicating an error.
- (8) If no error signal is returned from the receiving device, the ERS flag is not set in SSR.
- (9) If no error signal is returned from the receiving device, transmission of the frame, including retransmission, is assumed to be complete, and the TEND bit is set to 1 in SSR. If the TIE bit in SCR is set to the enable state, a TXI interrupt is requested. If TXI is enabled as a DMA transfer activation source, the next data can be written in TDR automatically. When the DMAC writes data in TDR, it automatically clears the TDRE bit to 0.

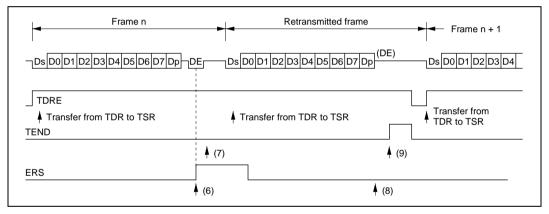


Figure 14.12 Retransmission in SCI Transmit Mode



Section 15 A/D Converter

15.1 Overview

The H8/3048 Group includes a 10-bit successive-approximations A/D converter with a selection of up to eight analog input channels.

When the A/D converter is not used, it can be halted independently to conserve power. For details see section 21.6, Module Standby Function.

15.1.1 Features

A/D converter features are listed below.

- 10-bit resolution
- Eight input channels
- Selectable analog conversion voltage range The analog voltage conversion range can be programmed by input of an analog reference voltage at the V_{REF} pin.
- High-speed conversion Conversion time: Minimum 7.45 μs per channel (with 18 MHz system clock)
- Two conversion modes

Single mode: A/D conversion of one channel

Scan mode: continuous conversion on one to four channels

• Four 16-bit data registers

A/D conversion results are transferred for storage into data registers corresponding to the channels.

- Sample-and-hold function
- A/D conversion can be externally triggered
- A/D interrupt requested at end of conversion At the end of A/D conversion, an A/D end interrupt (ADI) can be requested.

15.1.2 Block Diagram

Figure 15.1 shows a block diagram of the A/D converter.

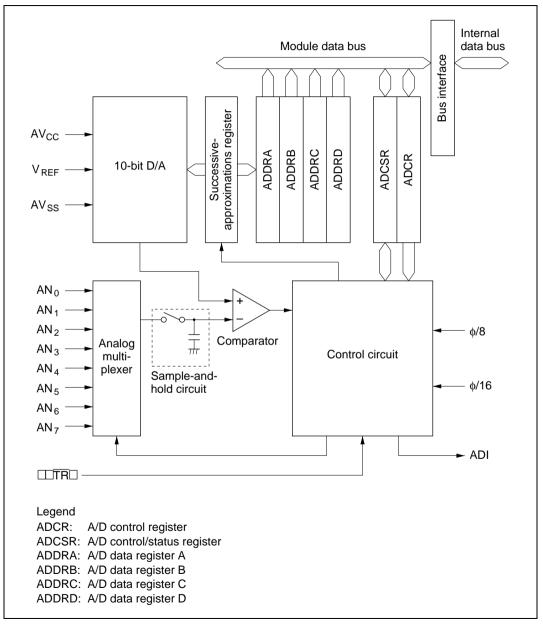


Figure 15.1 A/D Converter Block Diagram

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15.1.3 Input Pins

Table 15.1 summarizes the A/D converter's input pins. The eight analog input pins are divided into two groups: group 0 (AN₀ to AN₃), and group 1 (AN₄ to AN₇). AV_{CC} and AV_{SS} are the power supply for the analog circuits in the A/D converter. V_{REF} is the A/D conversion reference voltage.

Pin Name	Abbreviation	I/O	Function
Analog power supply pin	AV _{CC}	Input	Analog power supply
Analog ground pin	AV _{SS}	Input	Analog ground and reference voltage
Reference voltage pin	V _{REF}	Input	Analog reference voltage
Analog input pin 0	AN ₀	Input	Group 0 analog inputs
Analog input pin 1	AN ₁	Input	_
Analog input pin 2	AN ₂	Input	_
Analog input pin 3	AN ₃	Input	_
Analog input pin 4	AN ₄	Input	Group 1 analog inputs
Analog input pin 5	AN ₅	Input	_
Analog input pin 6	AN ₆	Input	_
Analog input pin 7	AN ₇	Input	_
A/D external trigger input pin	ADTRG	Input	External trigger input for starting A/D conversion

Table 15.1 A/D Converter Pins

15.1.4 Register Configuration

Table 15.2 summarizes the A/D converter's registers.

Table 15.2 A/D Converter Registers

Address* ¹	Name	Abbreviation	R/W	Initial Value
H'FFE0	A/D data register A (high)	ADDRAH	R	H'00
H'FFE1	A/D data register A (low)	ADDRAL	R	H'00
H'FFE2	A/D data register B (high)	ADDRBH	R	H'00
H'FFE3	A/D data register B (low)	ADDRBL	R	H'00
H'FFE4	A/D data register C (high)	ADDRCH	R	H'00
H'FFE5	A/D data register C (low)	ADDRCL	R	H'00
H'FFE6	A/D data register D (high)	ADDRDH	R	H'00
H'FFE7	A/D data register D (low)	ADDRDL	R	H'00
H'FFE8	A/D control/status register	ADCSR	R/(W)* ²	H'00
H'FFE9	A/D control register	ADCR	R/W	H'7F ^{*3}

Notes: 1. Lower 16 bits of the address

2. Only 0 can be written in bit 7, to clear the flag.

3. H8/3048F, H8/3048ZTAT, H8/3048 mask-ROM, H8/3047 mask-ROM, H8/3045 mask-ROM, and H8/3044 mask-ROM versions



15.2 Register Descriptions

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ADDRn	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	_	—	_		_	—
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write (n = A to D)	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R
				A/D c 10-bit A/D c	data	givir	ng an	-				Re	eserv	ed bi	its	

15.2.1 A/D Data Registers A to D (ADDRA to ADDRD)

The four A/D data registers (ADDRA to ADDRD) are 16-bit read-only registers that store the results of A/D conversion.

An A/D conversion produces 10-bit data, which is transferred for storage into the A/D data register corresponding to the selected channel. The upper 8 bits of the result are stored in the upper byte of the A/D data register. The lower 2 bits are stored in the lower byte. Bits 5 to 0 of an A/D data register are reserved bits that are always read as 0. Table 15.3 indicates the pairings of analog input channels and A/D data registers.

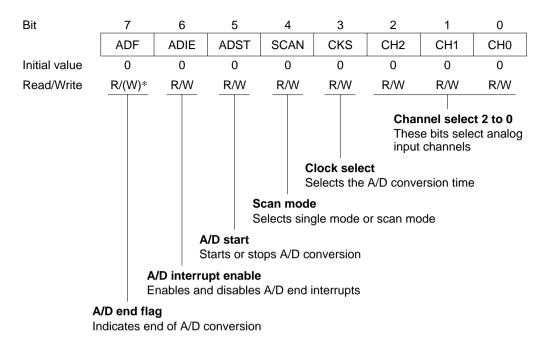
The CPU can always read and write the A/D data registers. The upper byte can be read directly, but the lower byte is read through a temporary register (TEMP). For details see section 15.3, CPU Interface.

The A/D data registers are initialized to H'0000 by a reset and in standby mode.

Table 15.3 Analog Input Channels and A/D Data Registers

Ana	alog Input Channel		
Group 0	Group 1	A/D Data Register	
AN ₀	AN ₄	ADDRA	
AN ₁	AN ₅	ADDRB	
AN ₂	AN ₆	ADDRC	
AN ₃	AN ₇	ADDRD	

15.2.2 A/D Control/Status Register (ADCSR)



Note: * Only 0 can be written, to clear the flag.

ADCSR is an 8-bit readable/writable register that selects the mode and controls the A/D converter. ADCSR is initialized to H'00 by a reset and in standby mode.

Bit 7—A/D End Flag (ADF): Indicates the end of A/D conversion.

Bit 7: ADF	Description	
0	[Clearing condition]	(Initial value)
	Cleared by reading ADF while ADF = 1, then writing 0 in ADF	
1	[Setting conditions]	
	Single mode: A/D conversion ends	
	Scan mode: A/D conversion ends in all selected channels	

Bit 6—A/D Interrupt Enable (ADIE): Enables or disables the interrupt (ADI) requested at the end of A/D conversion.

Bit 6: ADIE	Description	
0	A/D end interrupt request (ADI) is disabled	(Initial value)
1	A/D end interrupt request (ADI) is enabled	

Bit 5—A/D Start (ADST): Starts or stops A/D conversion. The ADST bit remains set to 1 during A/D conversion. It can also be set to 1 by external trigger input at the ADTRG pin.

Bit 5: ADST	Description	
0	A/D conversion is stopped	(Initial value)
1	Single mode: A/D conversion starts; ADST is automatically c conversion ends.	leared to 0 when
	Scan mode: A/D conversion starts and continues, cycling am channels, until ADST is cleared to 0 by software, by a reset, to standby mode.	-

Bit 4—Scan Mode (SCAN): Selects single mode or scan mode. For further information on operation in these modes, see section 15.4, Operation. Clear the ADST bit to 0 before switching the conversion mode.

Bit 4: SCAN	Description	
0	Single mode	(Initial value)
1	Scan mode	

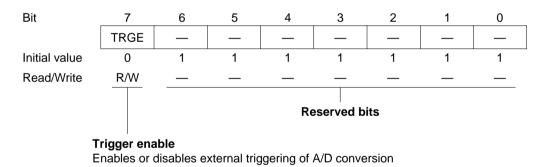
Bit 3—Clock Select (CKS): Selects the A/D conversion time. Clear the ADST bit to 0 before switching the conversion time.

Bit 3: CKS	Description	
0	Conversion time = 266 states (maximum)	(Initial value)
1	Conversion time = 134 states (maximum)	

Bits 2 to 0—Channel Select 2 to 0 (CH2 to CH0): These bits and the SCAN bit select the analog input channels. Clear the ADST bit to 0 before changing the channel selection.

Group Selection	Channel Selection		Description			
CH2	CH1	CH0	Single Mode	Scan Mode		
0	0	0	AN ₀ (Initial value)	AN ₀		
		1	AN ₁	AN ₀ , AN ₁		
	1	0	AN ₂	AN ₀ to AN ₂		
		1	AN ₃	AN ₀ to AN ₃		
1	0	0	AN ₄	AN ₄		
		1	AN ₅	AN ₄ , AN ₅		
	1	0	AN ₆	AN ₄ to AN ₆		
		1	AN ₇	AN ₄ to AN ₇		

15.2.3 A/D Control Register (ADCR)



ADCR is an 8-bit readable/writable register that enables or disables external triggering of A/D conversion. ADCR is initialized to H'7F by a reset and in standby mode.

Bit 7-Trigger Enable (TRGE): Enables or disables external triggering of A/D conversion.

Bit 7: TRGE	Description	
0	A/D conversion cannot be externally triggered	(Initial value)
1	A/D conversion starts at the falling edge of the external trigger s	ignal (ADTRG)

Bits 6 to 0—Reserved: Read-only bits, always read as 1.

15.3 CPU Interface

ADDRA to ADDRD are 16-bit registers, but they are connected to the CPU by an 8-bit data bus. Therefore, although the upper byte can be be accessed directly by the CPU, the lower byte is read through an 8-bit temporary register (TEMP).

An A/D data register is read as follows. When the upper byte is read, the upper-byte value is transferred directly to the CPU and the lower-byte value is transferred into TEMP. Next, when the lower byte is read, the TEMP contents are transferred to the CPU.

When reading an A/D data register, always read the upper byte before the lower byte. It is possible to read only the upper byte, but if only the lower byte is read, incorrect data may be obtained.

Figure 15.2 shows the data flow for access to an A/D data register.

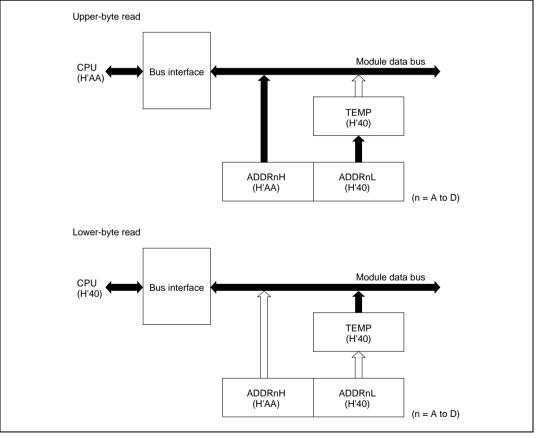


Figure 15.2 A/D Data Register Access Operation (Reading H'AA40)

15.4 Operation

The A/D converter operates by successive approximations with 10-bit resolution. It has two operating modes: single mode and scan mode.

15.4.1 Single Mode (SCAN = 0)

Single mode should be selected when only one A/D conversion on one channel is required. A/D conversion starts when the ADST bit is set to 1 by software, or by external trigger input. The ADST bit remains set to 1 during A/D conversion and is automatically cleared to 0 when conversion ends.

When conversion ends the ADF bit is set to 1. If the ADIE bit is also set to 1, an ADI interrupt is requested at this time. To clear the ADF flag to 0, first read ADCSR, then write 0 in ADF.

When the mode or analog input channel must be switched during analog conversion, to prevent incorrect operation, first clear the ADST bit to 0 in ADCSR to halt A/D conversion. After making the necessary changes, set the ADST bit to 1 to start A/D conversion again. The ADST bit can be set at the same time as the mode or channel is changed.

Typical operations when channel 1 (AN₁) is selected in single mode are described next.

Figure 15.3 shows a timing diagram for this example.

- 1. Single mode is selected (SCAN = 0), input channel AN₁ is selected (CH2 = CH1 = 0, CH0 = 1), the A/D interrupt is enabled (ADIE = 1), and A/D conversion is started (ADST = 1).
- 2. When A/D conversion is completed, the result is transferred into ADDRB. At the same time the ADF flag is set to 1, the ADST bit is cleared to 0, and the A/D converter becomes idle.
- 3. Since ADF = 1 and ADIE = 1, an ADI interrupt is requested.
- 4. The A/D interrupt handling routine starts.
- 5. The routine reads ADCSR, then writes 0 in the ADF flag.
- 6. The routine reads and processes the conversion result (ADDRB).
- Execution of the A/D interrupt handling routine ends. After that, if the ADST bit is set to 1, A/D conversion starts again and steps 2 to 7 are repeated.



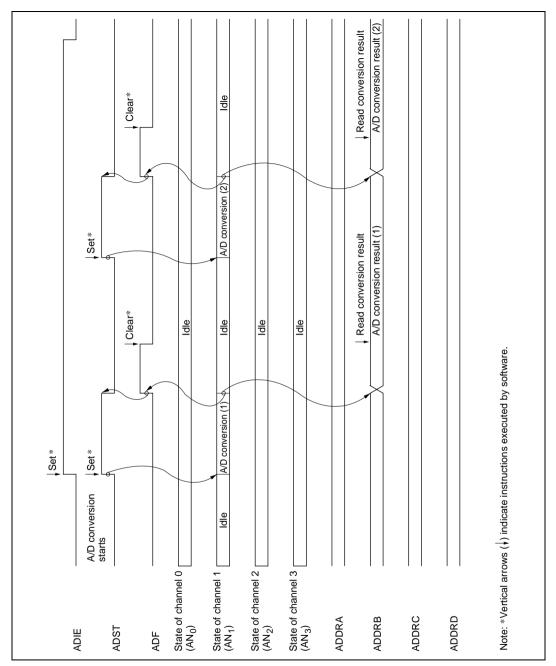


Figure 15.3 Example of A/D Converter Operation (Single Mode, Channel 1 Selected)

15.4.2 Scan Mode (SCAN = 1)

Scan mode is useful for monitoring analog inputs in a group of one or more channels. When the ADST bit is set to 1 by software or external trigger input, A/D conversion starts on the first channel in the group (AN_0 when CH2 = 0, AN_4 when CH2 = 1). When two or more channels are selected, after conversion of the first channel ends, conversion of the second channel (AN_1 or AN_5) starts immediately. A/D conversion continues cyclically on the selected channels until the ADST bit is cleared to 0. The conversion results are transferred for storage into the A/D data registers corresponding to the channels.

When the mode or analog input channel selection must be changed during analog conversion, to prevent incorrect operation, first clear the ADST bit to 0 in ADCSR to halt A/D conversion. After making the necessary changes, set the ADST bit to 1. A/D conversion will start again from the first channel in the group. The ADST bit can be set at the same time as the mode or channel selection is changed.

Typical operations when three channels in group 0 (AN_0 to AN_2) are selected in scan mode are described next. Figure 15.4 shows a timing diagram for this example.

- 1. Scan mode is selected (SCAN = 1), scan group 0 is selected (CH2 = 0), analog input channels AN_0 to AN_2 are selected (CH1 = 1, CH0 = 0), and A/D conversion is started (ADST = 1).
- 2. When A/D conversion of the first channel (AN_0) is completed, the result is transferred into ADDRA. Next, conversion of the second channel (AN_1) starts automatically.
- 3. Conversion proceeds in the same way through the third channel (AN₂).
- 4. When conversion of all selected channels $(AN_0 \text{ to } AN_2)$ is completed, the ADF flag is set to 1 and conversion of the first channel (AN_0) starts again. If the ADIE bit is set to 1, an ADI interrupt is requested at this time.
- 5. Steps 2 to 4 are repeated as long as the ADST bit remains set to 1. When the ADST bit is cleared to 0, A/D conversion stops. After that, if the ADST bit is set to 1, A/D conversion starts again from the first channel (AN_0).



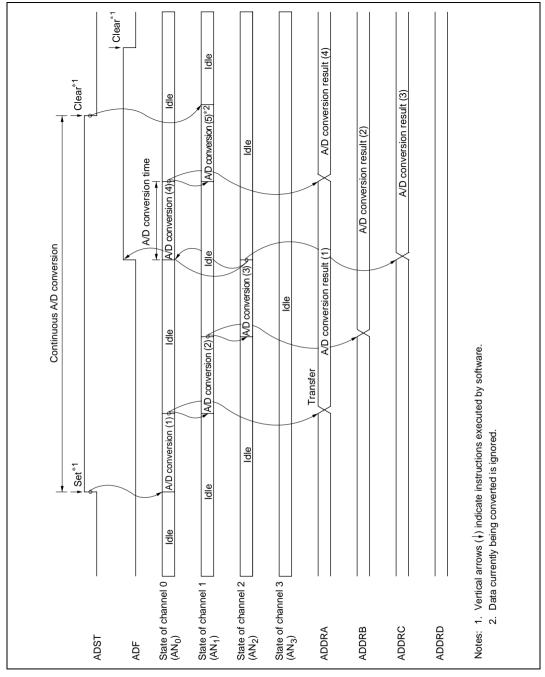


Figure 15.4 Example of A/D Converter Operation (Scan Mode, Channels AN₀ to AN₂ Selected)

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Section 15 A/D Converter

15.4.3 Input Sampling and A/D Conversion Time

The A/D converter has a built-in sample-and-hold circuit. The A/D converter samples the analog input at a time t_D after the ADST bit is set to 1, then starts conversion. Figure 15.5 shows the A/D conversion timing. Table 15.4 indicates the A/D conversion time.

As indicated in figure 15.5, the A/D conversion time includes t_D and the input sampling time. The length of t_D varies depending on the timing of the write access to ADCSR. The total conversion time therefore varies within the ranges indicated in table 15.4.

In scan mode, the values given in table 15.4 apply to the first conversion. In the second and subsequent conversions the conversion time is fixed at 256 states when CKS = 0 or 128 states when CKS = 1.

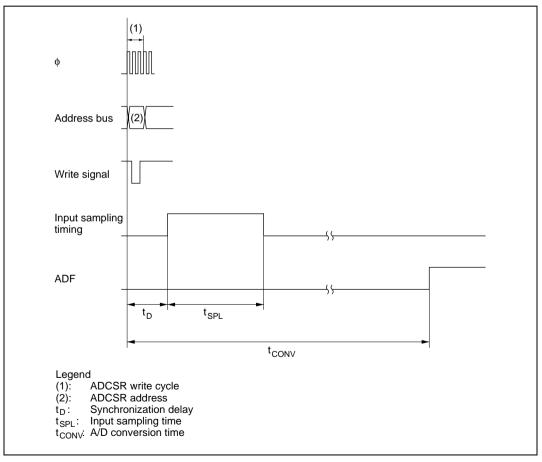


Figure 15.5 A/D Conversion Timing

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		CKS = 0		CKS = 1			
	Symbol	Min	Тур	Max	Min	Тур	Max
Synchronization delay	t _D	10		17	6	_	9
Input sampling time	t _{SPL}	_	63	_	_	31	_
A/D conversion time	t CONV	259	—	266	131	—	134

Table 15.4 A/D Conversion Time (Single Mode)

Note: Values in the table are numbers of states.

15.4.4 External Trigger Input Timing

A/D conversion can be externally triggered. When the TRGE bit is set to 1 in ADCR, external trigger input is enabled at the $\overline{\text{ADTRG}}$ pin. A high-to-low transition at the $\overline{\text{ADTRG}}$ pin sets the ADST bit to 1 in ADCSR, starting A/D conversion. Other operations, in both single and scan modes, are the same as if the ADST bit had been set to 1 by software. Figure 15.6 shows the timing.

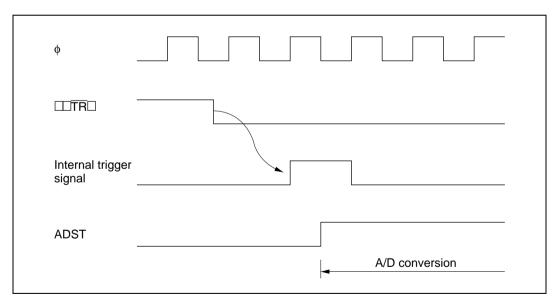


Figure 15.6 External Trigger Input Timing

15.5 Interrupts

The A/D converter generates an interrupt (ADI) at the end of A/D conversion. The ADI interrupt request can be enabled or disabled by the ADIE bit in ADCSR.

15.6 Usage Notes

When using the A/D converter, note the following points:

- 1. Analog Input Voltage Range: During A/D conversion, the voltages input to the analog input pins should be in the range $AV_{SS} \le AN_n \le V_{REF}$.
- 2. Relationships of AV_{CC} and AV_{SS} to V_{CC} and V_{SS}: AV_{CC}, AV_{SS}, V_{CC}, and V_{SS} should be related as follows: $AV_{SS} = V_{SS}$. AV_{CC} and AV_{SS} must not be left open, even if the A/D converter is not used.
- 3. V_{REF} Programming Range: The reference voltage input at the V_{REF} pin should be in the range $V_{REF} \le AV_{CC}$.
- 4. Analog Voltage: When using an A/D converter, make the following voltage settings.
 - a. $V_{CC} \ge AV_{CC} 0.3V$
 - b. $AV_{CC} \ge V_{REF} \ge ANn \ge AV_{SS} = V_{SS}$ (N = 0 to 7)
 - Note: Restriction for the ZTAT version only; The S-mask version of ZTAT, the Flash Memory version and Mask ROM version can be used regularly without restriction.

Failure to observe points 1, 2, 3, and 4 above may degrade chip reliability.

5. Note on Board Design: In board layout, separate the digital circuits from the analog circuits as much as possible. Particularly avoid layouts in which the signal lines of digital circuits cross or closely approach the signal lines of analog circuits. Induction and other effects may cause the analog circuits to operate incorrectly, or may adversely affect the accuracy of A/D conversion. The analog input signals (AN_0 to AN_7), analog reference voltage (V_{REF}), and analog supply voltage (AV_{CC}) must be separated from digital circuits by the analog ground (AV_{SS}). The analog ground (AV_{SS}) should be connected to a stable digital ground (V_{SS}) at one point on the board.

6. Note on Noise: To prevent damage from surges and other abnormal voltages at the analog input pins (AN₀ to AN₇) and analog reference voltage pin (V_{REF}), connect a protection circuit like the one in figure 15.7 between AV_{CC} and AV_{SS}. The bypass capacitors connected to AV_{CC} and V_{REF} and the filter capacitors connected to AN₀ to AN₇ must be connected to AV_{SS}. If filter capacitors like the ones in figure 15.7 are connected, the voltage values input to the analog input pins (AN₀ to AN₇) will be smoothed, which may give rise to error. Error can also occur if A/D conversion is frequently performed in scan mode so that the current that charges and discharges the capacitor in the sample-and-hold circuit of the A/D converter becomes greater than that input to the analog input pins via input impedance Rin. The circuit constants should therefore be selected carefully.

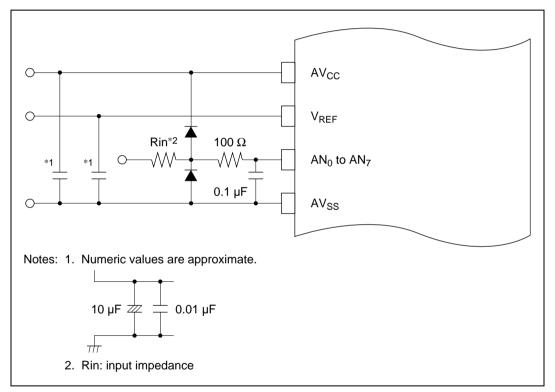


Figure 15.7 Example of Analog Input Protection Circuit

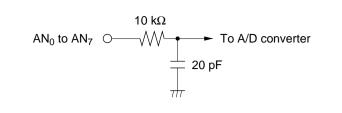




Figure 15.8 Analog Input Pin Equivalent Circuit

Table 15.5 Analog Input Pin Ratings

Item	Min	Max	Unit
Analog input capacitance	—	20	pF
Allowable signal-source impedance	_	10*	kΩ

Note: *When V_{CC} = 4.0 V to 5.5 V and $\varphi \leq$ 12 MHz.

- A/D Conversion Accuracy Definitions: A/D conversion accuracy in the H8/3048 Group is defined as follows:
 - Resolution

Digital output code length of A/D converter

• Offset error

Deviation from ideal A/D conversion characteristic of analog input voltage required to raise digital output from minimum voltage value B'0000000000 to B'0000000001 (figure 15.10)

Full-scale error

Deviation from ideal A/D conversion characteristic of analog input voltage required to raise digital output from B'111111110 to B'111111111 (figure 15.10)

• Quantization error

Intrinsic error of the A/D converter; 1/2 LSB (figure 15.9)

• Nonlinearity error

Deviation from ideal A/D conversion characteristic in range from zero volts to full scale, exclusive of offset error, full-scale error, and quantization error.

Absolute accuracy

Deviation of digital value from analog input value, including offset error, full-scale error, quantization error, and nonlinearity error.

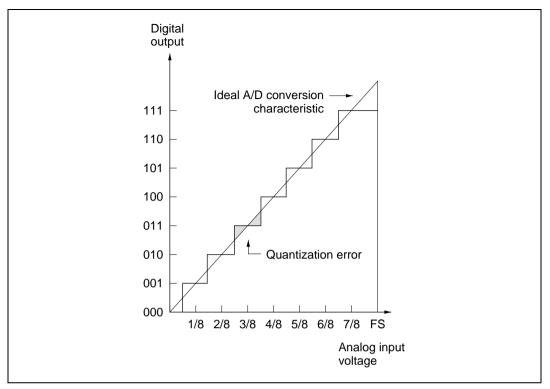


Figure 15.9 A/D Converter Accuracy Definitions (1)

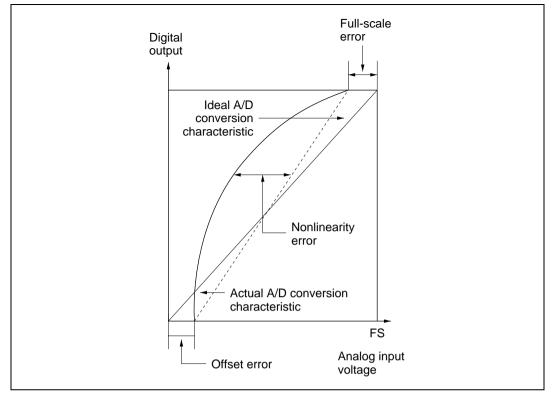


Figure 15.10 A/D Converter Accuracy Definitions (2)

8. Allowable Signal-Source Impedance: The analog inputs of the H8/3048 Group are designed to assure accurate conversion of input signals with a signal-source impedance not exceeding 10 kΩ. The reason for this rating is that it enables the input capacitor in the sample-and-hold circuit in the A/D converter to charge within the sampling time. If the sensor output impedance exceeds 10 kΩ, charging may be inadequate and the accuracy of A/D conversion cannot be guaranteed.

If a large external capacitor is provided in scan mode, then the internal 10-k Ω input resistance becomes the only significant load on the input. In this case the impedance of the signal source is not a problem.

A large external capacitor, however, acts as a low-pass filter. This may make it impossible to track analog signals with high dv/dt (e.g. a variation of 5 mV/ μ s) (figure 15.11). To convert high-speed analog signals or to use scan mode, insert a low-impedance buffer.

 Effect on Absolute Accuracy: Attaching an external capacitor creates a coupling with ground, so if there is noise on the ground line, it may degrade absolute accuracy. The capacitor must be connected to an electrically stable ground, such as AV_{SS}.

If a filter circuit is used, be careful of interference with digital signals on the same board, and make sure the circuit does not act as an antenna.

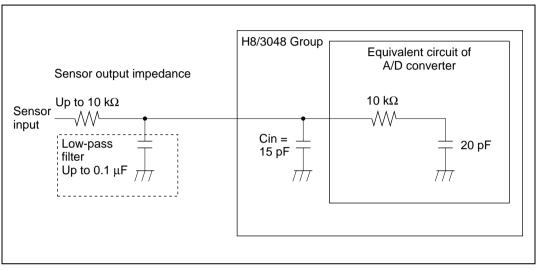


Figure 15.11 Analog Input Circuit (Example)





Section 16 D/A Converter

16.1 Overview

The H8/3048 Group includes a D/A converter with two channels.

16.1.1 Features

D/A converter features are listed below.

- Eight-bit resolution
- Two output channels
- Conversion time: maximum 10 µs (with 20-pF capacitive load)
- Output voltage: 0 V to 255/256 * V_{REF}
- D/A outputs can be sustained in software standby mode

16.1.2 Block Diagram

Figure 16.1 shows a block diagram of the D/A converter.

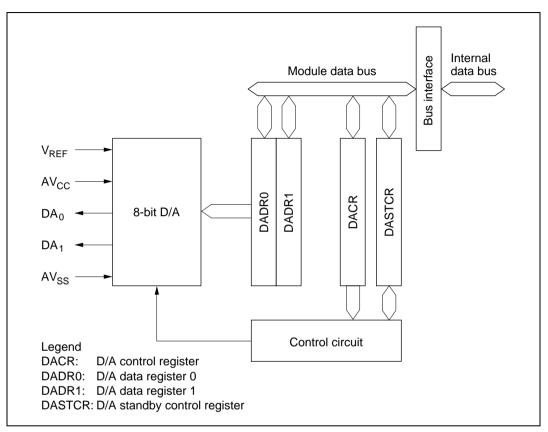


Figure 16.1 D/A Converter Block Diagram



16.1.3 Input/Output Pins

Table 16.1 summarizes the D/A converter's input and output pins.

Table 16.1	D/A Converter Pins
-------------------	---------------------------

Pin Name	Abbreviation	I/O	Function
Analog power supply pin	AV _{CC}	Input	Analog power supply
Analog ground pin	AV _{SS}	Input	Analog ground and reference voltage
Analog output pin 0	DA ₀	Output	Analog output, channel 0
Analog output pin 1	DA ₁	Output	Analog output, channel 1
Reference voltage input pin	V _{REF}	Input	Analog reference voltage

16.1.4 Register Configuration

Table 16.2 summarizes the D/A converter's registers.

Table 16.2 D/A Converter Registers

Address*	Name	Abbreviation	R/W	Initial Value
H'FFDC	D/A data register 0	DADR0	R/W	H'00
H'FFDD	D/A data register 1	DADR1	R/W	H'00
H'FFDE	D/A control register	DACR	R/W	H'1F
H'FF5C	D/A standby control register	DASTCR	R/W	H'FE

Note: * Lower 16 bits of the address

16.2 Register Descriptions

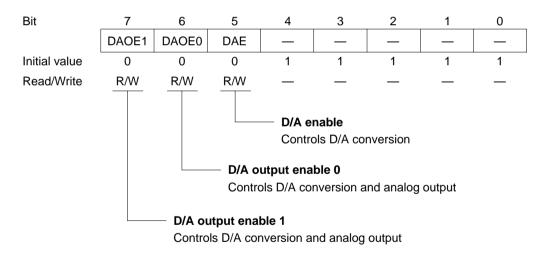
16.2.1 D/A Data Registers 0 and 1 (DADR0/1)

Bit	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

The D/A data registers (DADR0 and DADR1) are 8-bit readable/writable registers that store the data to be converted. When analog output is enabled, the D/A data register values are constantly converted and output at the analog output pins.

The D/A data registers are initialized to H'00 by a reset and in standby mode.

16.2.2 D/A Control Register (DACR)



DACR is an 8-bit readable/writable register that controls the operation of the D/A converter. DACR is initialized to H'1F by a reset and in standby mode.

Bit 7—D/A Output Enable 1 (DAOE1): Controls D/A conversion and analog output.

Bit 7: DAOE1	Description	
0	DA ₁ analog output is disabled	(Initial value)
1	Channel-1 D/A conversion and DA_1 analog output are enabled	

Bit 6—D/A Output Enable 0 (DAOE0): Controls D/A conversion and analog output.

Bit 6: DAOE0	Description	
0	DA ₀ analog output is disabled	(Initial value)
1	Channel-0 D/A conversion and DA_0 analog output are enabled	

Bit 5—D/A Enable (DAE): Controls D/A conversion, together with bits DAOE0 and DAOE1. When the DAE bit is cleared to 0, analog conversion is controlled independently in channels 0 and 1. When the DAE bit is set to 1, analog conversion is controlled together in channels 0 and 1. Output of the conversion results is always controlled independently by DAOE0 and DAOE1.

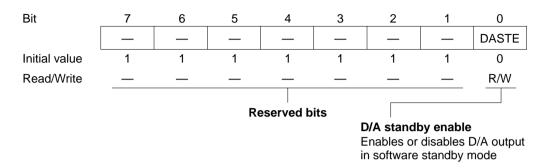
Bit 7: DAOE1	Bit 6: DAOE0	Bit 5: DAE	Description
0	0	_	D/A conversion is disabled in channels 0 and 1
	1	0	D/A conversion is enabled in channel 0
			D/A conversion is disabled in channel 1
		1	D/A conversion is enabled in channels 0 and 1
1	0	0	D/A conversion is disabled in channel 0
			D/A conversion is enabled in channel 1
		1	D/A conversion is enabled in channels 0 and 1
	1	_	D/A conversion is enabled in channels 0 and 1

When the DAE bit is set to 1, even if bits DAOE0 and DAOE1 in DACR and the ADST bit in ADCSR are cleared to 0, the same current is drawn from the analog power supply as during A/D and D/A conversion.

Bits 4 to 0—Reserved: Read-only bits, always read as 1.

16.2.3 D/A Standby Control Register (DASTCR)

DASTCR is an 8-bit readable/writable register that enables or disables D/A output in software standby mode.



DASTCR is initialized to H'FE by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 1—Reserved: Read-only bits, always read as 1.

Bit 0—D/A Standby Enable (DASTE): Enables or disables D/A output in software standby mode.

Bit 0: DASTE	Description	
0	D/A output is disabled in software standby mode	(Initial value)
1	D/A output is enabled in software standby mode	



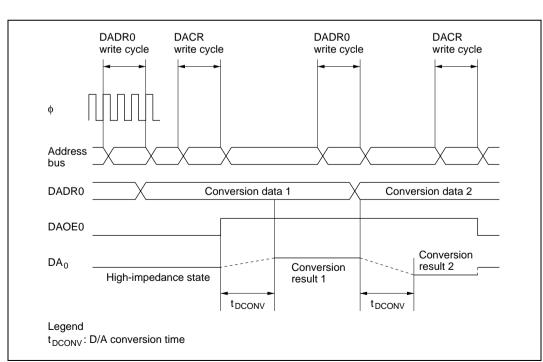
16.3 Operation

The D/A converter has two built-in D/A conversion circuits that can perform conversion independently.

D/A conversion is performed constantly while enabled in DACR. If the DADR0 or DADR1 value is modified, conversion of the new data begins immediately. The conversion results are output when bits DAOE0 and DAOE1 are set to 1.

An example of D/A conversion on channel 0 is given next. Timing is indicated in figure 16.2.

- 1. Data to be converted is written in DADR0.
- 2. Bit DAOE0 is set to 1 in DACR. D/A conversion starts and DA₀ becomes an output pin. The converted result is output after the conversion time. The output value is (DADR0 contents/256) \times V_{REF}. Output of this conversion result continues until the value in DADR0 is modified or the DAOE0 bit is cleared to 0.
- 3. If the DADR0 value is modified, conversion starts immediately, and the result is output after the conversion time.



4. When the DAOE0 bit is cleared to 0, DA_0 becomes an input pin.

Figure 16.2 Example of D/A Converter Operation

16.4 D/A Output Control

In the H8/3048 Group, D/A converter output can be enabled or disabled in software standby mode.

When the DASTE bit is set to 1 in DASTCR, D/A converter output is enabled in software standby mode. The D/A converter registers retain the values they held prior to the transition to software standby mode.

When D/A output is enabled in software standby mode, the reference supply current is the same as during normal operation.

16.5 Usage Notes

When using an D/A converter, note the following.

- 1. $V_{CC} \ge AV_{CC} 0.3V$
- 2. $AV_{CC} \ge V_{REF} \ge ANn \ge AV_{SS} = V_{SS}$ (N = 0 to 7)
- Note: Restriction for the ZTATTM version only; The S Mask version of ZTATTM, the Flash Memory version and Mask ROM version can be used regularly without restriction.



Section 17 RAM

17.1 Overview

The H8/3048 and H8/3047 have 4 kbytes of high-speed static RAM on-chip. The H8/3045 and H8/3044 have 2 kbytes. The RAM is connected to the CPU by a 16-bit data bus. The CPU accesses both byte data and word data in two states, making the RAM useful for rapid data transfer.

The on-chip RAM of the H8/3048 and H8/3047 is assigned to addresses H'FEF10 to H'FFF0F in modes 1, 2, 5, and 7, and to addresses H'FFEF10 to H'FFF0F in modes 3, 4, and 6. The on-chip RAM of the H8/3045 and H8/3044 are assigned to addresses H'FF710 to H'FFF0F in modes 1, 2, 5, and 7, and to addresses H'FFF710 to H'FFF0F in modes 3, 4, and 6. The RAM enable bit (RAME) in the system control register (SYSCR) can enable or disable the on-chip RAM.

17.1.1 Block Diagram

Figure 17.1 shows a block diagram of the on-chip RAM.

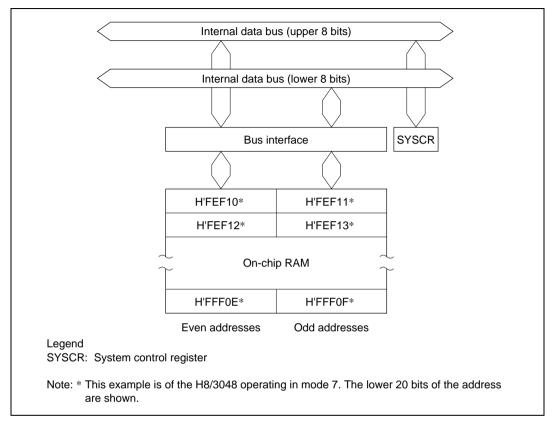


Figure 17.1 RAM Block Diagram

17.1.2 Register Configuration

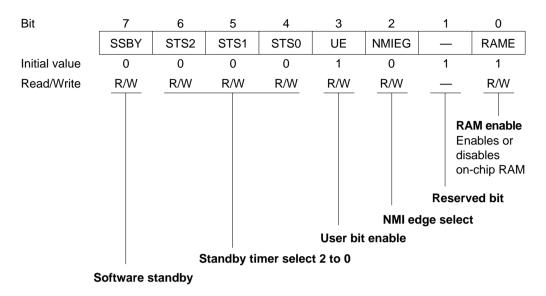
The on-chip RAM is controlled by SYSCR. Table 17.1 gives the address and initial value of SYSCR.

Table 17.1 System Control Register

Address*	Name	Abbreviation	R/W	Initial Value
H'FFF2	System control register	SYSCR	R/W	H'0B
Note: * Lower 16 bits of the address				

Note: * Lower 16 bits of the address.

17.2 System Control Register (SYSCR)



One function of SYSCR is to enable or disable access to the on-chip RAM. The on-chip RAM is enabled or disabled by the RAME bit in SYSCR. For details about the other bits, see section 3.3, System Control Register (SYSCR).

Bit 0—RAM Enable (RAME): Enables or disables the on-chip RAM. The RAME bit is initialized at the rising edge of the input at the $\overline{\text{RES}}$ pin. It is not initialized in software standby mode.

Bit 0: RAME	Description	
0	On-chip RAM is disabled	
1	On-chip RAM is enabled	(Initial value)

17.3 Operation

When the RAME bit is set to 1, the on-chip RAM is enabled. Accesses to addresses H'FEF10 to H'FFF0F in the H8/3048 and H8/3047 in modes 1, 2, 5, and 7, addresses H'FFEF10 to H'FFF0F in the H8/3048 and H8/3047 in modes 3, 4, and 6, addresses H'FF710 to H'FFF0F in the H8/3045 and H8/3044 in modes 1, 2, 5, and 7, and addresses H'FF710 to H'FFF0F in the H8/3045 and H8/3044 in modes 3, 4, and 6 are directed to the on-chip RAM. In modes 1 to 6 (expanded modes), when the RAME bit is cleared to 0, the off-chip address space is accessed. In mode 7 (single-chip mode), when the RAME bit is cleared to 0, the on-chip RAM is not accessed: read access always results in H'FF data, and write access is ignored.

Since the on-chip RAM is connected to the CPU by an internal 16-bit data bus, it can be written and read by word access. It can also be written and read by byte access. Byte data is accessed in two states using the upper 8 bits of the data bus. Word data starting at an even address is accessed in two states using all 16 bits of the data bus.



Section 18 ROM (H8/3048ZTAT and Mask-ROM Versions)

18.1 Overview

The H8/3048 has 128 kbytes of on-chip ROM, the H8/3047 has 96 kbytes, the H8/3045 has 64 kbytes and the H8/3044 has 32 kbytes. The ROM is connected to the CPU by a 16-bit data bus. The CPU accesses both byte data and word data in two states, enabling rapid data transfer.

The mode pins $(MD_2 \text{ to } MD_0)$ can be set to enable or disable the on-chip ROM as indicated in table 18.1.

Table 18.1 Operating Mode and ROM

	I	Mode P	ins	
Mode	MD_2	\mathbf{MD}_1	MD ₀	On-Chip ROM
Mode 1 (1-Mbyte expanded mode with on-chip ROM disabled)	0	0	1	Disabled (external
Mode 2 (1-Mbyte expanded mode with on-chip ROM disabled)	0	1	0	address area)
Mode 3 (16-Mbyte expanded mode with on-chip ROM disabled)	0	1	1	_
Mode 4 (16-Mbyte expanded mode with on-chip ROM disabled)	1	0	0	_
Mode 5 (1-Mbyte expanded mode with on-chip ROM enabled)	1	0	1	Enabled
Mode 6 (16-Mbyte expanded mode with on-chip ROM enabled)	1	1	0	_
Mode 7 (single-chip mode)	1	1	1	

The PROM version (H8/3048ZTAT) can be set to PROM mode and programmed with a generalpurpose PROM programmer.

Note: Care is required when changing from the H8/3048F-ONE to a model with on-chip mask ROM (H8/3048, H8/3047, H8/3045, or H8/3044).
For details, refer to the H8/3048F-ONE Hardware Manual (Rev. 1.0) 1.4.5, Note on Changeover to Mask ROM Version.

18.1.1 Block Diagram

Figure 18.1 shows a block diagram of the ROM.

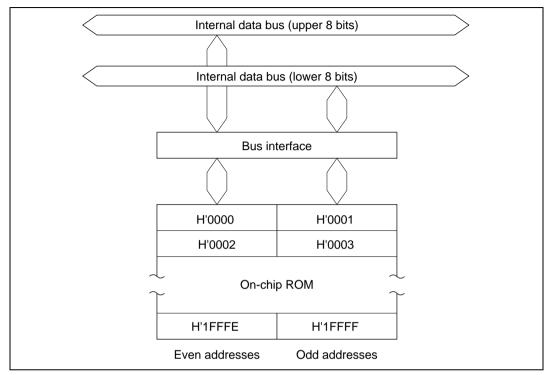


Figure 18.1 ROM Block Diagram (H8/3048, Mode 7)



18.2 PROM Mode

18.2.1 PROM Mode Setting

In PROM mode, the H8/3048 (H8/3048ZTAT) version with on-chip PROM suspends its microcontroller functions, enabling the on-chip PROM to be programmed. The programming method is the same as for the HN27C101, except that page programming is not supported. Table 18.2 indicates how to select PROM mode.

Table 18.2Selecting PROM Mode

Pins	Setting
Three mode pins (MD ₂ , MD ₁ , MD ₀)	Low
STBY pin	
P5 ₁ and P5 ₀	High

18.2.2 Socket Adapter and Memory Map

The PROM is programmed using a general-purpose PROM programmer with a socket adapter to convert to 32 pins. Table 18.3 lists the socket adapter for each package option. Figure 18.2 shows the pin assignments of the socket adapter. Figure 18.3 shows a memory map in PROM mode.

Table 18.3Socket Adapter

Microcontroller	Package	Socket Adapter	
H8/3048	100-pin QFP (FP-100B)	HS3042ESHS1H	
	100-pin TQFP (TFP-100B)	HS3042ESNS1H	

The size of the H8/3048 PROM is 128 kbytes. Figure 18.3 shows a memory map in PROM mode. H'FF data should be specified for unused address areas in the on-chip PROM.

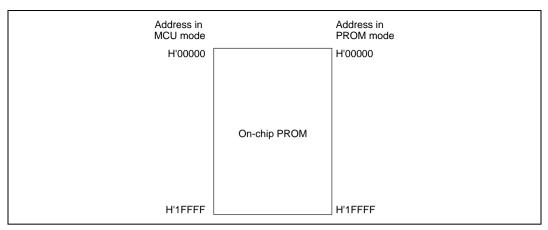
When programming the H8/3048 with a PROM programmer, set the address range to H'00000 to H'1FFFF.

H8/3048 FP-100B, TFP-100B	Pin			Pin	PROM Socket HN27C101 (32 Pins
10	RES	ļ		V _{PP}	1
64	NMI			EA ₉	26
58	P6 ₀			EA ₁₅	3
87	P8 ₀			EA ₁₆	2
88	P8 ₁				31
27					13
	P3 ₀			EO ₀	
28	P3 ₁			EO ₁	14
29	P3 ₂			EO ₂	15
30	P3 ₃			EO3	17
31	P3 ₄			EO ₄	18
32	P3 ₅			EO ₅	19
33	P3 ₆			EO ₆	20
34	P3 ₇			EO ₇	21
36	P1 ₀			EA ₀	12
37	P1 ₁			EA ₁	11
38	P1 ₂	<u> </u>		EA ₂	10
39	P1 ₃			EA ₃	9
40	P1 ₄			EA ₄	8
41	P1 ₅	<u> </u>		EA ₅	7
42	P1 ₆			EA ₆	6
43	P1 ₇			EA ₇	5
45	P2 ₀			EA ₈	27
46					24
	P2 ₁				
47	P2 ₂			EA ₁₀	23
48	P2 ₃			EA ₁₁	25
49	P2 ₄			EA ₁₂	4
50	P25			EA ₁₃	28
51	P2 ₆			EA ₁₄	29
52	P27			ΠĒ	22
53	P5 ₀	1		V _{CC}	32
54	P5 ₁	+ +			
77	V _{REF}	+			
76	AV _{CC}	+			
1	V _{CC}	+			
35	V _{CC}	+			
68	V _{CC}				
73	MD ₀	+		V _{SS}	16
74	MD ₁		Í	50	
75	MD ₂	ļ			
62	STBY				
86	AV _{SS}				
11	V _{SS}		Legend		
22	V _{SS} V _{SS}		V _{PP} :		gramming voltage (12
					ta input/output
44	V _{SS}	Ī			dress input
57	V _{SS}	ſ			tput enable
65	V _{SS}	t t			p enable
92	V _{SS}			Pro	gram

This figure shows pin assignments, and does not show the entire socket adapter circuit. When undertaking a new design, board design (power supply voltage stabilization, noise countermeasures, etc.) as a high-speed CMOS LSI is necessary.

Figure 18.2 Socket Adapter Pin Assignments

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18.3 PROM Programming

Table 18.4 indicates how to select the program, verify, and other modes in PROM mode.

	Pins						
Mode	CE	ŌE	PGM	V _{PP}	Vcc	EO7 to EO0	EA ₁₆ to EA ₀
Program	L	Н	L	V_{PP}	V_{CC}	Data input	Address input
Verify	L	L	Н	V_{PP}	V_{CC}	Data output	Address input
Program inhibited	L	L	L	V_{PP}	V _{CC}	High impedance	Address input
	L	Н	Н				
	Н	L	L				
	Н	Н	Н	_			

Legend

L: Low voltage level

H: High voltage level

V_{PP}: V_{PP} voltage level

V_{CC}: V_{CC} voltage level

Read/write specifications are the same as for the standard HN27C101 EPROM, except that page programming is not supported. Do not select page programming mode. A PROM programmer that supports only page-programming mode cannot be used. When selecting a PROM programmer, check that it supports a byte-at-a-time high-speed programming mode. Be sure to set the address range to H'00000 to H'1FFFF.

18.3.1 Programming and Verification

An efficient, high-speed programming procedure can be used to program and verify PROM data. This procedure programs the chip quickly without subjecting it to voltage stress and without sacrificing data reliability. Unused address areas contain H'FF data. Figure 18.4 shows the basic high-speed programming flowchart. Tables 18.5 and 18.6 list the electrical characteristics of the chip during programming. Figure 18.5 shows a timing chart.

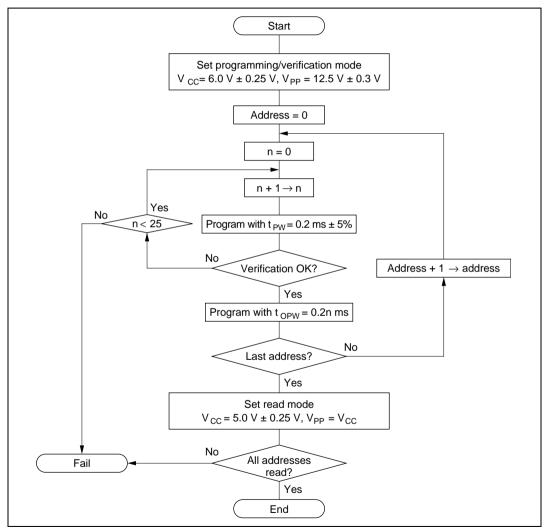


Figure 18.4 High-Speed Programming Flowchart

Table 18.5 DC Characteristics in PROM Mode

(Conditions: $V_{CC} = 6.0 \text{ V} \pm 0.25 \text{ V}$, $V_{PP} = 12.5 \text{ V} \pm 0.3 \text{ V}$, $V_{SS} = 0 \text{ V}$, $T_a = 25^{\circ}C \pm 5^{\circ}C$)

ltem		Symbol	Min	Тур	Мах	Unit	Test Conditions
Input high voltage	$\begin{array}{c} EO_7 \text{ to } EO_0, \\ \\ \hline EA_{16} \text{ to } EA_0, \\ \hline \hline OE, \ \hline CE, \ \hline PGM \end{array}$	VIH	2.4	_	V _{CC} + 0.3	V	
Input low voltage	$\begin{array}{c} EO_7 \text{ to } EO_0, \\ \\ \hline EA_{16} \text{ to } EA_0, \\ \hline \hline OE, \ \hline CE, \ \hline PGM \end{array}$	VIL	-0.3	_	0.8	V	
Output high voltage	EO7 to EO0	V _{OH}	2.4	_	—	V	I _{OH} = -200 μA
Output low voltage	EO7 to EO0	V _{OL}	_	—	0.45	V	I _{OL} = 1.6 mA
Input leakage current	$\begin{array}{c} EO_7 \text{ to } EO_0, \\ \\ \hline EA_{16} \text{ to } EA_0, \\ \hline \hline OE, \ \hline CE, \ \hline PGM \end{array}$	l _u	_	_	2	μA	V _{in} = 5.25 V/0.5 V
V _{CC} current		I _{CC}	—	_	40	mA	
V _{PP} current		I _{PP}	—	—	40	mA	

Note: For details on absolute maximum ratings, see section 22.1.1, Absolute Maximum Ratings. Using an LSI in excess of absolute maximum ratings may result in permanent damage. V_{PP} peak overshoot should not exceed 13 V.

Table 18.6 AC Characteristics in PROM Mode

(Conditions: $V_{CC} = 6.0 \text{ V} \pm 0.25 \text{ V}$, $V_{PP} = 12.5 \text{ V} \pm 0.3 \text{ V}$, $T_a = 25^{\circ}C \pm 5^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Address setup time	t _{AS}	2	_	—	μs	Figure 18.5*1
OE setup time	t _{OES}	2	_	_	μs	_
Data setup time	t _{DS}	2	_	_	μs	_
Address hold time	t _{AH}	0	_	_	μs	_
Data hold time	t _{DH}	2	_	_	μs	_
Data output disable time	t_{DF}^{*2}	_	_	130	ns	_
V _{PP} setup time	t _{VPS}	2	_	_	μs	_
Programming pulse width	t _{PW}	0.19	0.20	0.21	ms	_
PGM pulse width for overwrite programming	t _{OPW} * ³	0.19	_	5.25	ms	_
V _{CC} setup time	t _{vcs}	2	_	_	μs	_
CE setup time	t _{CES}	2	—	_	μs	_
Data output delay time	t _{OE}	0	_	150	ns	_

Notes: 1. Input pulse level: 0.8 V to 2.2 V

Input rise time and fall time \leq 20 ns

Timing reference levels: 1.0 V and 2.0 V for input; 0.8 V and 2.0 V for output

2. t_{DF} is defined at the point where the output is in the open state and the output level cannot be read.

3. t_{OPW} is defined by the value given in the flowchart.



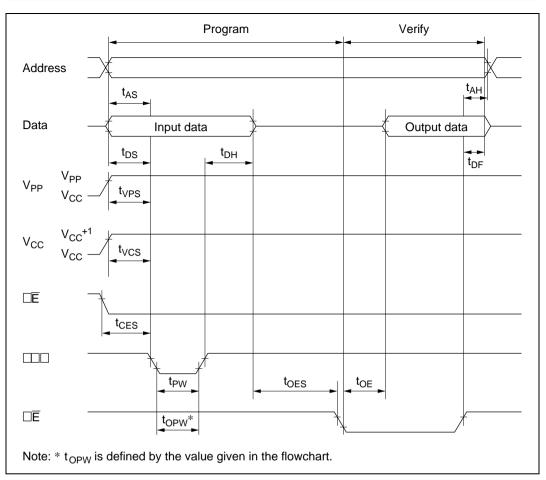


Figure 18.5 PROM Program/Verify Timing

•

18.3.2 Programming Precautions

- Program with the specified voltages and timing. The programming voltage (V_{PP}) in PROM mode is 12.5 V. Applied voltages in excess of the rated values can permanently destroy the chip. Be particularly careful about the PROM programmer's overshoot characteristics. If the PROM programmer is set to Renesas Technology HN27C101 specifications, V_{PP} will be 12.5 V.
- Before programming, check that the chip is correctly mounted in the PROM programmer. Overcurrent damage to the chip can result if the index marks on the PROM programmer, socket adapter, and chip are not correctly aligned.
- Don't touch the socket adapter or chip while programming. Touching either of these can cause contact faults and write errors.
- Select the programming mode carefully. The chip cannot be programmed in page programming mode.
- The H8/3048 PROM size is 128 kbytes. Set the address range to H'00000 to H'1FFFF.



18.3.3 Reliability of Programmed Data

A highly effective way to improve data retention characteristics is to bake the programmed chips at 150°C, then screen them for data errors. This procedure quickly eliminates chips with PROM memory cells prone to early failure.

Figure 18.6 shows the recommended screening procedure.

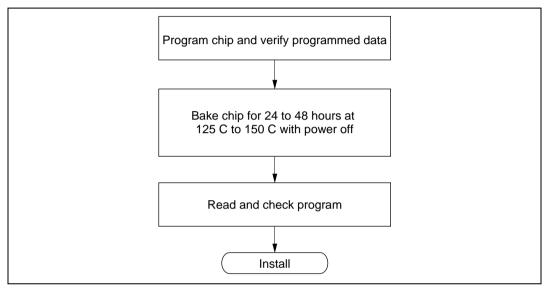


Figure 18.6 Recommended Screening Procedure

If a series of programming errors occurs while the same PROM programmer is in use, stop programming and check the PROM programmer and socket adapter for defects. Please inform Renesas Technology of any abnormal conditions noted during or after programming or in screening of program data after high-temperature baking.

18.4 Notes on Ordering Mask ROM Version Chip

When ordering the H8/3048 Group chips with a mask ROM, note the following.

- When ordering through an EPROM, use a 128-kbyte one.
- Fill all the unused addresses with H'FF as shown in figure 18.7 to make the ROM data size 128 kbytes for all H8/3048 Group chips, which incorporate different sizes of ROM. This applies to ordering through an EPROM and through electrical data transfer.

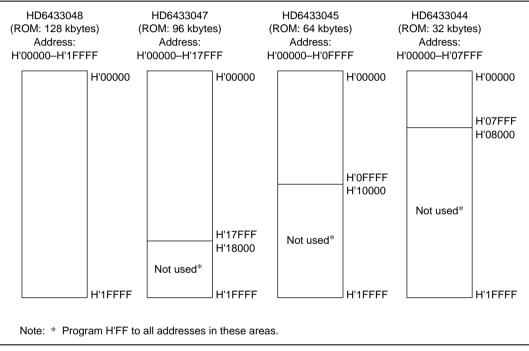


Figure 18.7 Masked ROM Addresses and Data

- The flash memory control registers (FLMCR, EBR1, EBR2, and RAMCR)* for use only by the on-chip flash memory version (H8/3048F (dual-power-supply model)) are not provided in the mask ROM version. Reading a corresponding address will always return a value of 1, and writes to the corresponding addresses are invalid. This point must be noted when switching from a flash memory model to a mask ROM version.
- In the case of the H8/3048F-ONE (single-power-supply model) on-chip flash memory version, the 5 V version has a V_{CL} pin and requires connection of an external capacitor. Care is therefore required with the board design when switching to a mask ROM version. (For details, see section 1.4.5, Notes on Switching to Mask ROM Version, in the H8/3048F-ONE Hardware Manual (First Edition).
- Note: * In the H8/3048F-ONE with on-chip flash memory, the flash memory control registers are FLMCR1, FLMCR2, EBR, and RAMCR. (For details, see appendix B, Internal I/O Registers, in the H8/3048F-ONE Hardware Manual (First Edition)).



Section 19 Flash Memory (H8/3048F: Dual Power Supply ($V_{PP} = 12 \text{ V}$))

19.1 Overview

The H8/3048F has 128 kbytes of on-chip flash memory. The flash memory is connected to the CPU by a 16-bit data bus. The CPU accesses both byte data and word data in two states, enabling rapid data transfer.

The mode pins $(MD_2 \text{ to } MD_0)$ can be set to enable or disable the on-chip ROM as indicated in table 19.1.

Table 19.1 Operating Mode and ROM

	I	Mode P			
Mode	MD_2	\mathbf{MD}_1	MD ₀	On-Chip ROM	
Mode 1 (1-Mbyte expanded mode with on-chip ROM disabled)	0	0	1	Disabled (external	
Mode 2 (1-Mbyte expanded mode with on-chip ROM disabled)	0	1	0	address area)	
Mode 3 (16-Mbyte expanded mode with on-chip ROM disabled)	0	1	1	_	
Mode 4 (16-Mbyte expanded mode with on-chip ROM disabled)	1	0	0	_	
Mode 5 (1-Mbyte expanded mode with on-chip ROM enabled)	1	0	1	Enabled	
Mode 6 (16-Mbyte expanded mode with on-chip ROM enabled)	1	1	0	_	
Mode 7 (single-chip mode)	1	1	1		

The H8/3048F (dual-power supply flash memory version) can be set to PROM mode and programmed with a general-purpose PROM programmer.

19.2 Flash Memory Overview

19.2.1 Flash Memory Operation

Table 19.2 illustrates the principle of operation of the on-chip flash memory of the H8/3048F (dual-power supply).

Like EPROM, flash memory is programmed by applying a high gate-to-drain voltage that draws hot electrons generated in the vicinity of the drain into a floating gate. The threshold voltage of a programmed memory cell is therefore higher than that of an erased cell. Cells are erased by grounding the gate and applying a high voltage to the source, causing the electrons stored in the floating gate to tunnel out. After erasure, the threshold voltage drops. A memory cell is read like an EPROM cell, by driving the gate to the high level and detecting the drain current, which depends on the threshold voltage. Erasing must be done carefully, because if a memory cell is overerased, its threshold voltage may become negative, causing the cell to operate incorrectly.

Section 19.5.6, Erasing Flowchart and Sample Program shows an optimal erase control flowchart and sample program.

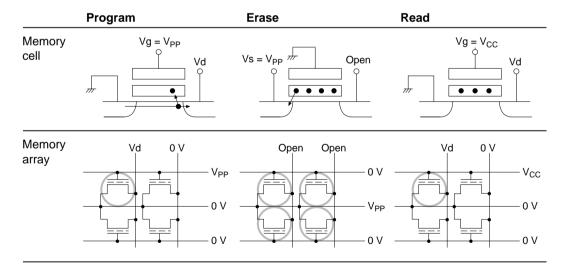


Table 19.2 Principle of Memory Cell Operation

19.2.2 Mode Programming and Flash Memory Address Space

As its on-chip ROM, the H8/3048F has 128 kbytes of flash memory. The flash memory is connected to the CPU by a 16-bit data bus. The CPU accesses both byte data and word data in two states.

The flash memory is assigned to addresses H'00000 to H'1FFFF on the memory map. The mode pins enable either on-chip flash memory or external memory to be selected for this area. Table 19.3 summarizes the mode pin settings and usage of the flash memory area.

		Mode Pin S	Setting	
Mode	MD ₂	MD ₁	MD ₀	Flash Memory Area Usage
Mode 0	0	0	0	Illegal setting
Mode 1	0	0	1	External memory area
Mode 2	0	1	0	External memory area
Mode 3	0	1	1	External memory area
Mode 4	1	0	0	External memory area
Mode 5	1	0	1	On-chip flash memory area
Mode 6	1	1	0	On-chip flash memory area
Mode 7	1	1	1	On-chip flash memory area

Table 19.3 Mode Pin Settings and Flash Memory Area

19.2.3 Features

Features of the flash memory are listed below.

• Five flash memory operating modes

The flash memory has five operating modes: program mode, program-verify mode, erase mode, erase-verify mode, and prewrite-verify mode.

• Block erase designation

Blocks to be erased in the flash memory address space can be selected by bit settings. The address space includes a large-block area (eight blocks with sizes from 12 kbytes to 16 kbytes) and a small-block area (eight 512-byte blocks).

• Program and erase time

Programming one byte of flash memory typically takes 50 μ s. Erasing all blocks (128 kbytes) typically takes 1 s.

• Erase-program cycles

Flash memory contents can be erased and reprogrammed up to 100 times.

On-board programming modes

These modes can be used to program, erase, and verify flash memory contents. There are two modes: boot mode, and user programming mode.

• Automatic bit-rate alignment

In boot-mode data transfer, the H8/3048F aligns its bit rate automatically to the host bit rate (9600 bps, 4800 bps and 2400 bps).

• Flash memory emulation by RAM

Part of the RAM area can be overlapped onto flash memory, to emulate flash memory updates in real time.

• PROM mode

As an alternative to on-board programming, the flash memory can be programmed and erased in PROM mode, using a general-purpose PROM programmer.

• Protect modes

Flash memory can be program-, erase-, and/or verify-protected in hardware and software protect modes.



19.2.4 Block Diagram

Figure 19.1 shows a block diagram of the flash memory.

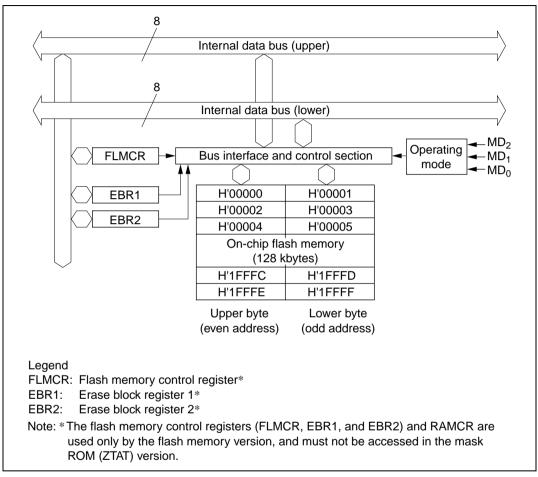


Figure 19.1 Flash Memory Block Diagram

19.2.5 Input/Output Pins

Flash memory is controlled by the pins listed in table 19.4.

Table 19.4Flash Memory Pins

Pin Name	Abbreviation	Input/Output	Function
Programming power	V _{PP}	Power supply	Apply 12.0 V
Mode 2	MD ₂	Input	H8/3048F operating mode programming
Mode 1	MD ₁	Input	H8/3048F operating mode programming
Mode 0	MD ₀	Input	H8/3048F operating mode programming
Transmit data	TXD ₁	Output	Serial transmit data output
Receive data	RXD ₁	Input	Serial receive data input

The transmit data and receive data pins are used in boot mode.

19.2.6 Register Configuration

The flash memory is controlled by the registers listed in table 19.5.

Table 19.5 Flash Memory Registers

Address	Name	Abbreviation	R/W	Initial Value
H'FF40	Flash memory control register*3	FLMCR	R/W* ²	H'00* ¹
H'FF42	Erase block register 1*3	EBR1	R/W* ²	H'00* ¹
H'FF43	Erase block register 2*3	EBR2	R/W* ²	H'00* ¹
H'FF48	RAM control register	RAMCR	R/W	H'70

Notes: 1. The initial value is H'00 in modes 5, 6, and 7 (on-chip flash memory enabled).

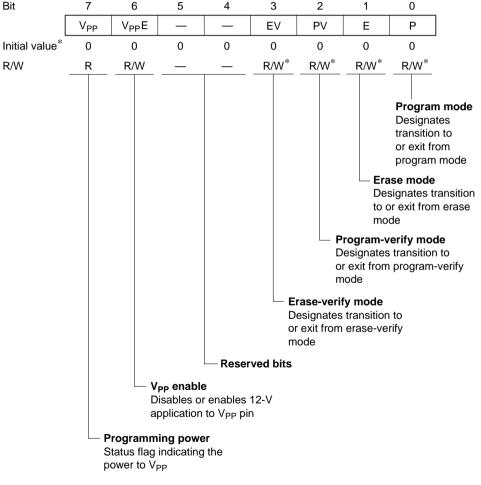
2. In modes 1, 2, 3, and 4 (on-chip flash memory disabled), this register cannot be modified and is always read as H'FF.

 Dedicated registers for controlling flash memory, which are not provided by the mask-ROM and ZTAT versions. Therefore, these registers must not be accessed in the mask-ROM and ZTAT versions. These registers cannot be modified in the mask-ROM and ZTAT versions.

19.3 Flash Memory Register Descriptions

19.3.1 Flash Memory Control Register

The flash memory control register (FLMCR) is an eight-bit register that controls the flash memory operating modes. Transitions to program mode, erase mode, program-verify mode, and erase-verify mode are made by setting bits in this register. FLMCR is initialized to H'00 by a reset, in the standby modes, and when 12 V is not applied to V_{PP} . When 12 V is applied to V_{PP} , a reset or entry to a standby mode initializes FLMCR to H'80.



Note: * The initial value is H'00 in modes 5, 6, and 7 (on-chip flash memory enabled). In modes 1, 2, 3, and 4 (on-chip flash memory disabled), this register cannot be modified and is always read as H'FF.

Bit 7—Programming Power (V_{PP}): Programming power bit (V_{PP}) detects V_{PP}, and level is displayed as "1" or "0." The permissible output currents for impressed high voltage VH are given in 22.2.2, "DC Characteristics." The value of VH ranges from V_{CC} + 2 V to 11.4 V. If a voltage in excess of VH is applied, "1" is displayed; otherwise "0" is displayed.

This bit restricts the hardware protect functions during write and erase operations for the flash memory. For details on hardware protect, see section 19.5.8, "Protect Modes." For notes on VPP usage, see section 19.8, "Flash Memory Programming and Erasing Precautions (Dual-Power Supply)."

Bit 7: V _{PP}	Description	
0	[Clear condition]	(Initial value)
	This is the regular operational mode when a voltage exceedi applied to the V _{PP} pin. The flash memory cannot be written o "Hardware Protect" is displayed.	0
1	[Set condition]	
	This is the operational mode when a voltage exceeding V_H is V_{PP} pin. The flash memory can be written and erased. "Hardy Disabled" is displayed*.	

Note: * For correct write and erase functions, the setting should be V_{PP} = 12.0 V to 0.6 V (11.4 V to 12.6 V).

Bit 6—V_{PP} Enable (V_{PP}E): Disables or enables 12-V application to the V_{PP} pin. After this bit is set, it is necessary to wait for at least 5 μ s for the internal power supply to stabilize; programming and erasing cannot be performed until stabilization is complete. After this bit is cleared, it is necessary to wait for the flash memory read setup time (t_{FRS}) in order to read flash memory.

Bit 6: V _{PP} E	Description	
0	V_{PP} pin 12-V power supply is disabled	(Initial value)
1	V _{PP} pin 12-V supply is enabled	

Note: The power supply system used for the flash memory is switched by means of the VppE bit. After switching, operation is not guaranteed during the period before the power supply system stabilizes. It is therefore prohibited to fetch from flash memory and execute an instruction that sets or resets the VppE bit.

Bits 5 and 4—Reserved: Read-only bits, always read as 0.



Bit 3—Erase-Verify Mode (EV)*1: Selects transition to or exit from erase-verify mode.

Bit 3: EV	Description	
0	Exit from erase-verify mode	(Initial value)
1	Transition to erase-verify mode	

Bit 2—Erase-Verify Mode (PV)*¹: Selects transition to or exit from program-verify mode.

Bit 2: PV	Description	
0	Exit from program-verify mode	(Initial value)
1	Transition to program-verify mode	

Bit 1—Erase Mode (E)*¹*²: Selects transition to or exit from erase mode.

Bit 1: E	Description	
0	Exit from erase mode	(Initial value)
1	Transition to erase mode	

Bit 0—Program Mode (P)*¹*²: Selects transition to or exit from program mode.

Bit 0: P	Description	
0	Exit from program mode	(Initial value)
1	Transition to program mode	

Notes: 1. Do not set two or more of these bits simultaneously. Do not turn off power supply $(V_{CC}-V_{PP})$ while a bit is set.

 For each bit setting procedure, follow the algorithm described in section 19.5, Programming and Erasing Flash Memory. For the notes on programming and erasing, refer to section 19.8, Flash Memory Programming and Erasing Precautions (Dual-Power Supply). Particularly, be sure to set the watchdog timer beforehand to prevent program runaway, when the E or P bit is set.

19.3.2 Erase Block Register 1

Erase block register 1 (EBR1) is an eight-bit register that designates large flash-memory blocks for programming and erasure. EBR1 is initialized to H'00 by a reset, in the standby modes, when 12 V is applied to V_{PP} while the $V_{PP}E$ bit is 0, and when 12 V is not applied to V_{PP} . When a bit in EBR1 is set to 1, the corresponding block is selected and can be programmed and erased. Figure 19.2 shows a block map.

Bit	7	6	5	4	3	2	1	0
	LB7	LB6	LB5	LB4	LB3	LB2	LB1	LB0
Initial value*	0	0	0	0	0	0	0	0
Read/Write	R/W*							

Note: * The initial value is H'00 in modes 5, 6, and 7 (on-chip flash memory enabled). In modes 1, 2, 3, and 4 (on-chip flash memory disabled), this register cannot be modified and is always read as H'FF.

Bits 7 to 0—Large Block 7 to 0 (LB7 to LB0): These bits select large blocks (LB7 to LB0) to be programmed and erased.

Bits 7 to 0: LB7 to LB0	Description	
0	Block LB7 to LB0 is not selected	(Initial value)
1	Block LB7 to LB0 is selected	



19.3.3 Erase Block Register 2

Erase block register 2 (EBR2) is an eight-bit register that designates small flash-memory blocks for programming and erasure. EBR2 is initialized to H'00 by a reset, in the standby modes, when 12 V is applied to V_{PP} while the $V_{PP}E$ bit is 0, and when 12 V is not applied to V_{PP} . When a bit in EBR2 is set to 1, the corresponding block is selected and can be programmed and erased. Figure 19.2 shows a block map.

Bit	7	6	5	4	3	2	1	0
	SB7	SB6	SB5	SB4	SB3	SB2	SB1	SB0
Initial value*	0	0	0	0	0	0	0	0
Read/Write	R/W*							

Note: * The initial value is H'00 in modes 5, 6, and 7 (on-chip flash memory enabled). In modes 1, 2, 3, and 4 (on-chip flash memory disabled), this register cannot be modified and is always read as H'FF.

Bits 7 to 0—Small Block 7 to 0 (SB7 to SB0): These bits select small blocks (SB7 to SB0) to be programmed and erased.

Bits 7 to 0: SB7 to SB0	Description	
0	Block SB7 to SB0 is not selected	(Initial value)
1	Block SB7 to SB0 is selected	

Bit	Addresses					
LB0	H'00000-H'03FFF		H'00000 H'03FFF	16 kbytes		
LB1	H'04000–H'07FFF		H'04000 H'07FFF	16 kbytes		
LB2	H'08000–H'0BFFF		H'08000 H'0BFFF	16 kbytes		
LB3	H'0C000-H'0FFFF	Large block area (124 kbytes)	H'0C000 H'0FFFF	16 kbytes		
LB4	H'10000–H'13FFF		H'10000 H'13FFF	16 kbytes		
LB5	H'14000–H'17FFF		H'14000 H'17FFF	16 kbytes		
LB6	H'18000–H'1BFFF				H'18000 H'1BFFF	16 kbytes
LB7	H'1C000-H'1EFFF		H'1C000 H'1EFFF	12 kbytes		
SB0	H'1F000–H'1F1FF		Ī	H'1F000 H'1F1FF	512 bytes	
SB1	H'1F200–H'1F3FF		H'1F200 H'1F3FF	512 bytes		
SB2	H'1F400–H'1F5FF		H'1F400 H'1F5FF	512 bytes		
SB3	H'1F600–H'1F7FF	Small block area	H'1F600 H'1F7FF	512 bytes		
SB4	H'1F800–H'1F9FF	(4 kbytes)		(4 kbytes)	H'1F800 H'1F9FF	512 bytes
SB5	H'1FA00–H'1FBFF					H'1FA00 H'1FBFF
SB6	H'1FC00–H'1FDFF		H'1FC00 H'1FDFF	512 bytes		
SB7	H'1FE00–H'1FFFF		H'1FE00 H'1FFFF	512 bytes		

Figure 19.2 Erase Block Map

19.3.4 RAM Control Register (RAMCR)

The RAM control register (RAMCR) enables flash-memory updates to be emulated in RAM, and indicates flash memory errors.

Bit	7	6	5	4	3	2	1	0
	FLER		_	_	RAMS	RAM2	RAM1	RAM0
Initial value	0	1	1	1	0	0	0	0
Read/Write	R	_	—	—	R/W	R/W	R/W	R/W

Bit 7—Flash Memory Error (FLER): Indicates that an error occurred while flash memory was being programmed or erased. When bit 7 is set, flash memory is placed in an error-protect mode.*¹

Bit 7: FLER	Description
0	Flash memory is not write/erase-protected (is not in error protect mode ^{*1}) (Initial value)
	[Clearing condition]
	Reset or hardware standby mode
1	Indicates that an error occurred while flash memory was being programmed or erased, and error protection ^{*1} is in effect
	[Setting conditions]
	Flash memory was read ^{*2} while being programmed or erased (including vector or instruction fetch, but not including reading of a RAM area overlapped onto flash memory).
	A hardware exception-handling sequence (other than a reset, trace exception, invalid instruction, trap instruction, or zero-divide exception) was executed just before programming or erasing.
	The SLEEP instruction (for transition to sleep mode or software standby mode) was executed during programming or erasing.
	A bus was released during programming or erasing.

Notes: 1. For details, see section 19.5.8, Protect Modes.

2. The read data has undetermined values.

Bits 6 to 4—Reserved: Read-only bits, always read as 1.

Bit 3—RAM Select (RAMS)*: Is used with bits 2 to 0 to reassign an area to RAM (see table 19.6). When bit 3 is set, all flash-memory blocks are protected from programming and erasing, regardless of the values of bits 2 to 0.

It is initialized by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 2 to 0—RAM2 to RAM0*: These bits are used with bit 3 to reassign an area to RAM (see table 19.6). They are initialized by a reset and in hardware standby mode. They are not initialized in software standby mode.

Note: * These bits can be written to in modes 5, 6, and 7 (on-chip flash memory enabled). In other modes, they are always read as 0 and cannot be modified.

	Bit 3	Bit 2	Bit 1	Bit 0		
RAM Area	RAMS	RAM2	RAM1	RAM0		
H'FFF000 to H'FFF1FF	0	0/1	0/1	0/1		
H'01F000 to H'01F1FF	1	0	0	0		
H'01F200 to H'01F3FF	1	0	0	1		
H'01F400 to H'01F5FF	1	0	1	0		
H'01F600 to H'01F7FF	1	0	1	1		
H'01F800 to H'01F9FF	1	1	0	0		
H'01FA00 to H'01FBFF	1	1	0	1		
H'01FC00 to H'01FDFF	1	1	1	0		
H'01FE00 to H'01FFFF	1	1	1	1		

Table 19.6 RAM Area Reassignment

19.4 On-Board Programming Modes

When an on-board programming mode is selected, the on-chip flash memory can be programmed, erased, and verified. There are two on-board programming modes: boot mode, and user program mode. These modes are selected by inputs at the mode pins (MD_2 to MD_0) and V_{PP} pin. Table 19.7 indicates how to select the on-board programming modes. For information about turning V_{PP} on and off, see note (4) in section 19.8, Flash Memory Programming and Erasing Precautions (Dual-Power Supply).



Mode Selections		V _{PP}	MD ₂	MD ₁	MD ₀	Notes
Boot mode	Mode 5	12 V	12 V	0	1	0: V _{IL}
	Mode 6		12 V	1	0	1: VIH
	Mode 7		12 V	1	1	
User program mode	Mode 5		1	0	1	
	Mode 6		1	1	0	
	Mode 7		1	1	1	

Table 19.7 On-Board Programming Mode Selection

19.4.1 Boot Mode

To use boot mode, a user program for programming and erasing the flash memory must be provided in advance on the host machine (which may be a personal computer). Serial communication interface 1 (SCI1) is used in asynchronous mode (see figure 19.3). If the H8/3048F is placed in boot mode, after it comes out of reset, a built-in boot program is activated. This program starts by measuring the low period of data transmitted from the host and setting the bit rate register (BRR) accordingly. The H8/3048F's built-in serial communication interface (SCI) can then be used to download the user program from the host machine. The user program is stored in on-chip RAM.

After the program has been stored, execution branches to address H'FF300 in modes 5 and 6 and H'FFF300 in mode 7 in the on-chip RAM, and the program stored on RAM is executed to program and erase the flash memory. Figure 19.4 shows the boot-mode execution procedure.

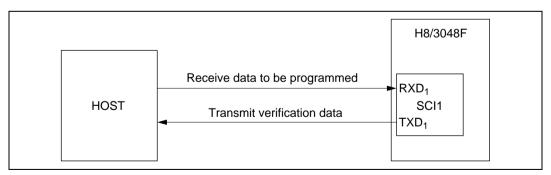
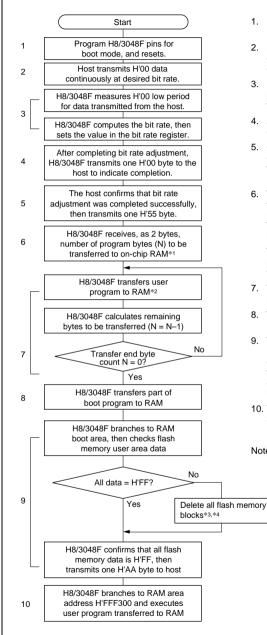


Figure 19.3 Boot-Mode System Configuration

Boot-Mode Execution Procedure: Figure 19.4 shows the boot-mode execution procedure.



- 1. Program the H8/3048F pins for boot mode, and start the H8/3048F from a reset.
- Set the host's data format to 8 bits + 1 stop bit, select the desired bit rate (2400, 4800 or 9600), and transmit H'00 data continuously.
- 3. H8/3048F measures the duration of repeat when the RDX pin is "Low," then computes the bit rate of the serial transmission from the host.
- After H8/3048F completes SCI bit rate adjustment, one byte of H'00 data is transmitted to indicate completion.
- On receiving one byte from H8/3048F to indicate completion of bit rate adjustment, the host confirms regular reception then transmits one byte of H'55. H8/3048F transmits H'AA to indicate regular reception.
- The host transmits the number of user program bytes to be transferred to the H8/3048F. The number of bytes should be sent as two bytes, upper byte followed by lower byte. The host should then sequentially transmit the program set by the user.

The H8/3048F transmits the received byte count and user program sequentially to the host, one byte at a time, as verify data (echo-back).

- The H8/3048F sequentially writes the received user program to on-chip RAM area H'FFF300 to H'FFFEFF.
- 8. The H8/3048F transfers part of the boot program to on-chip RAM area H'FFEF10 to H'FFE2FF.
- The H8/3048F branches to the RAM boot program area (H'FFEF10 to H'FFF2FF) and checks for the presence of data written in the flash memory. If data has been written in the flash memory, the H8/3048F erases all blocks. When erasing ends normally, the H8/3048F transmits one H'AA byte.
- 10. The H8/3048F branches to on-chip RAM address H'FFF300 and executes the user program written in that area.

Notes: 1. The user can use 3072 bytes of RAM. The number of bytes transferred must not exceed 3072 bytes. Be sure to transmit the byte length in two bytes, most significant byte first and least significant byte second. For example, if the byte length of the program to be transferred is 256 bytes, (H'0100), transmit H'01 as the most significant byte, followed by H'00 as the least significant byte.

- 2. The part of the user program that controls the flash memory should be coded according to the flash memory program/erase algorithms given later.
- If a memory cell malfunctions and cannot be erased, the H8/3048F transmits one H'FF byte to report an erase error, halts erasing, and halts further operations.
- 4. The allotted boot program area is H'FFF300 to H'FFFEFF.

Figure 19.4 Boot Mode Flowchart

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Automatic Alignment of SCI Bit Rate

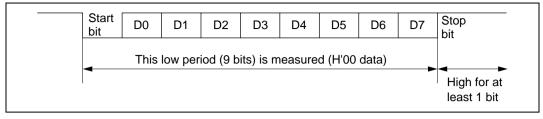


Figure 19.5 Measurement of Low Period in Data Transmitted from Host

When started in boot mode, the H8/3048F measures the low period in asynchronous SCI data transmitted from the host (figure 19.5). The data format is eight data bits, one stop bit, and no parity bit. From the measured low period (nine bits), the H8/3048F computes the host's transmission bit rate. After aligning its own bit rate, the H8/3048F sends the host one byte of H'00 data to indicate that bit-rate alignment is completed. The host should check that this alignment-completed indication is received normally, then transmit one H'55 byte. If the host does not receive a normal alignment-completed indication, the H8/3048F should be reset, then restarted in boot mode to measure the low period again. There may be some alignment error between the host's and H8/3048F's bit rates, depending on the host's bit rate to a value 2400, 4800, or 9600 bps^{*1}. Table 19.8 lists typical host bit rates and indicates the clock-frequency ranges over which the H8/3048F can align its bit rate automatically. Boot mode should be used within these frequency ranges.^{*2}

Host Bit Rate ^{*1}	System Clock Frequencies Permitting Automatic Bit-Rate Alignment by H8/3048F
9600 bps	8 MHz to 16 MHz
4800 bps	4 MHz to 16 MHz
2400 bps	2 MHz to 16 MHz

 Table 19.8
 System Clock Frequencies Permitting Automatic Bit-Rate Alignment by H8/3048F

Notes: 1. Host bit rate settings are 2400, 4800, and 9600 bps; no other settings should be used.

2. Although the H8/3048F may perform automatic bit-rate alignment with combinations of bit rate and system clock other than those shown in table 19.8, there may be a discrepancy between the bit rates of the host and the H8/3048F, preventing subsequent transfer from being performed normally. Boot mode execution should therefore be confined to the range of combinations shown in table 19.8.

RAM Area Allocation in Boot Mode: In boot mode, the H'3F0 bytes from H'FEF10 to H'FF2FF in modes 5 and 7, and from H'FFEF10 to H'FFF2FF in mode 6 are reserved for use by the boot program. The user program is transferred into the area from H'FF300 to H'FFEFF, in modes 5 and 7, and from H'FFF300 to H'FFFEFF in mode 6 (H'C00 bytes). The boot program area is used during the transition to execution of the user program transferred into RAM.

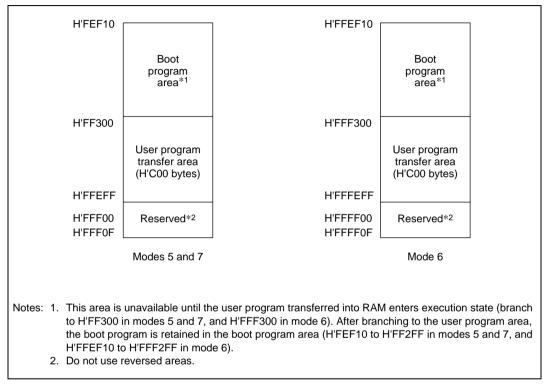


Figure 19.6 RAM Areas in Boot Mode



Notes on Use of Boot Mode

- 1. When the H8/3048F comes out of reset in boot mode, it measures the low period of the input at the SCI1's RXD_1 pin. The reset should end with RXD_1 high. After the reset ends, it takes about 100 states for the H8/3048F to get ready to measure the low period of the RXD_1 input.
- 2. In boot mode, if any data has been programmed into the flash memory (if all data are not H'FF), all flash memory blocks are erased. Boot mode is for use when user program mode is unavailable, e.g. the first time on-board programming is performed, or if the update program activated in user program mode is accidentally erased.
- 3. Interrupts cannot be used while the flash memory is being programmed or erased.
- 4. The RXD_1 and TXD_1 lines should be pulled up on-board.
- 5. Before branching to the user program (at address H'F300 in the RAM area), the H8/3048F terminates transmit and receive operations by the on-chip SCI (channel 1) (by clearing the RE and TE bits in serial control register (SCR) to 0 in channel 1), but the auto-aligned bit rate remains set in bit rate register BRR1. The transmit data pin (TXD₁) is in the high output state (in port 9, the P9₁DDR bit in port 9 data direction register P9DDR and P9₁DR bit in port 9 data register are set to 1).

When the branch to the user program occurs, the contents of general registers in the CPU are undetermined. After the branch, the user program should begin by initializing general registers, especially the stack pointer (SP), which is used implicitly in subroutine calls and at other times. The stack pointer must be set to provide a stack area for use by the user program. The other on-chip registers do not have specific initialization requirements.

- 6. Transition to boot mode are shown in figure 19.7, User Program Mode Operation (Example). This is possible after applying 12 V to pins MD₂ and V_{PP} and restarting. In this case, H8/3048F reset is erased (startup with Low → High) timing^{*1}, mode pin status latches the personal computer internally to maintain boot mode. Boot mode can be erased if the 12 V applied to the MD₂ pin and the V_{PP} pin is erased, then reset is erased^{*1}. However, please note the following.
 - a. When transferring from boot mode to regular mode ($V_{PP} \neq 12 \text{ V}$, $MD_2 \neq 12 \text{ V}$), before transfer the erase must be carried out by the reset input personal computer internal boot mode $\overline{\text{RES}}$ pin. After V_{PP} interrupt, erase reset. The time needed until reset vector lead is flash memory read setup $(t_{FRS})^{*2}$.
 - b. While in boot mode, if the 12 V applied to the MD_2 pin is erased, as long as reset input from the \overline{RES} pin does not occur, the personal computer internal boot mode status will be maintained and boot mode will continue. In boot mode, if watchdog timer reset occur, the personal computer internal boot mode is not erased, and despite mode pin status the internal boot program restarts.
 - c. When transferring to boot mode (reset erase timing) or during boot mode operation, program voltage V_{PP} should be within the range 12 V to 0.6 V. If this range is exceeded,

boot mode will not operate correctly. In addition, during boot program operation or writing and erasing the flash memory, do not interrupt V_{PP}^{*2} .

- 7. During reset (when RES pin input is Low), if MD₂ pin input changes from 0 V to 12 V or vice versa, by instantaneous transfer to 5 V input, the personal computer switches to operation mode. As a result, the address port or bus control output signal (AS, RD, HWR, LWR) status changes, so do not these pins as output signals during reset, as the personal computer internal section needs to be shut down.
- Regarding 12 V application to the V_{PP} and MD₂ pins, insure that peak overshoot does not exceed the maximum rating of 13 V. Also, be sure to connect bypass capacitors to the V_{pp} and MD₂ pins^{*1}.
- Notes: 1. Mode pin input must satisfy the mode programming setup time (t_{MDS}) with respect to the reset release timing. When 12 V is applied to or disconnected from the MD₂ pin, a delay occurs in the fall and rise waveforms due to the influence of the pull-up/pull-down resistor connected to the MD₂ pin, etc. For reset release timing, therefore, this delay must be confirmed with the actual waveform on the board.
 - 2. For notes on applying and cutting V_{PP}, refer to 19.8, note (4) of "Flash Memory Programming and Erasing Precautions (Dual-Power Supply)."

19.4.2 User Program Mode

When set to user program mode, the H8/3048F can erase and program its flash memory by executing a user program. On-board updates of the on-chip flash memory can be carried out by providing on-board circuits for supplying V_{PP} and data, and storing an update program in part of the program area.

To select user program mode, select a mode that enables the on-chip ROM (mode 5, 6, or 7) and apply 12 V to the V_{PP} pin. In this mode, the on-chip peripheral modules operate as they normally would in mode 5, 6, or 7, except for the flash memory. A watchdog timer overflow, however, cannot output a reset signal while 12 V is applied to V_{PP} . The watchdog timer's reset output enable bit (RSTOE) should not be set to 1.

The flash memory cannot be read while being programmed or erased, so the update program must either be stored in external memory, or transferred temporarily to the RAM area and executed in RAM.



User Program Mode Execution Procedure: Figure 19.7 shows the procedure for user program mode execution in RAM.

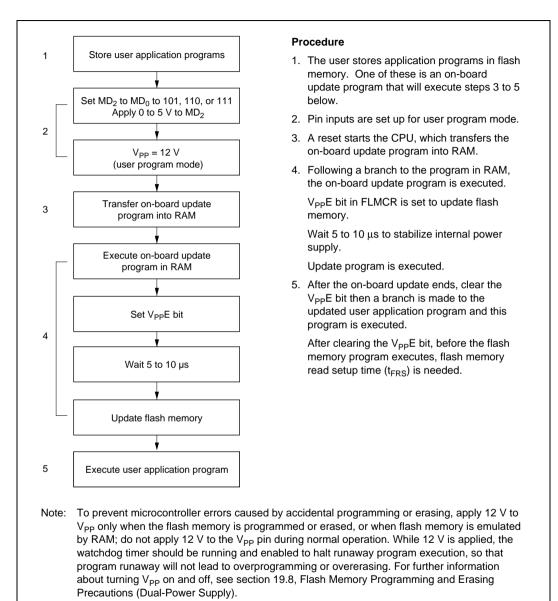


Figure 19.7 User Program Mode Operation (Example)

19.5 Programming and Erasing Flash Memory

The H8/3048F's on-chip flash memory is programmed and erased by software, using the CPU.

The flash memory operating modes and state transition diagram are shown in figure 19.8. Program/erase modes comprise program mode, erase mode, program-verify mode, erase-verify mode, and prewrite-verify mode. Transitions to these modes can be made by setting the P, E, PV, and EV bits in the flash memory control register (FLMCR). Transition to the prewrite-verify mode can also be made by clearing all the bits in FLMCR.

The flash memory cannot be read while being programmed or erased. The program that controls the programming and erasing of the flash memory must be stored and executed in on-chip RAM or in external memory. A description of each mode is given below, with recommended flowcharts and sample programs for programming and erasing. High-reliability programming and erasing algorithms are used, which double the programming or erase processing time for each step. Section 19.8, Flash Memory Programming and Erasing Precautions (Dual-Power Supply), gives further notes on programming and erasing.

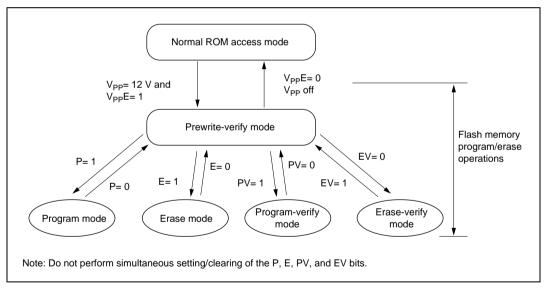


Figure 19.8 Flash Memory Program/Erase Operating Mode State Transition Diagram

19.5.1 Program Mode

To write data into the flash memory, follow the programming algorithm shown in figure 19.9. This programming algorithm can write data without subjecting the device to voltage stress or impairing the reliability of programmed data.

To program data, first set the $V_{PP}E$ bit in FLMCR, wait 5 to 10 μ s, then designate the blocks to be programmed by erase block registers 1 and 2 (EBR1, EBR2), and write the data to the address to be programmed, as in writing to RAM. The flash memory latches the address and data in an address latch and data latch. Next set the P bit in FLMCR, selecting program mode. The programming duration is the time during which the P bit is set. A software timer should be used to provide an initial programming duration of 15.8 μ s or less. Programming for too long a time, due to program runaway for example, can cause device damage. Before selecting program mode, set up the watchdog timer so as to prevent overprogramming.

19.5.2 Program-Verify Mode

In program-verify mode, after data has been programmed in program mode, the data is read to check that it has been programmed correctly.

After the programming time has elapsed, exit programming mode (clear the P bit to 0) and select program-verify mode (set the PV bit to 1). In program-verify mode, a program-verify voltage is applied to the memory cells at the latched address. If the flash memory is read in this state, the data at the latched address will be read. After selecting program-verify mode, wait 4 μ s before reading, then compare the programmed data with the verify data. If they agree, exit program-verify mode and program the next address. If they do not agree, select program mode again and repeat the same program and program-verify sequence. Do not repeat the program and program-verify set a loop counter so that the total programming time will not exceed 1 ms.)

19.5.3 Programming Flowchart and Sample Program

Flowchart for Programming One Byte

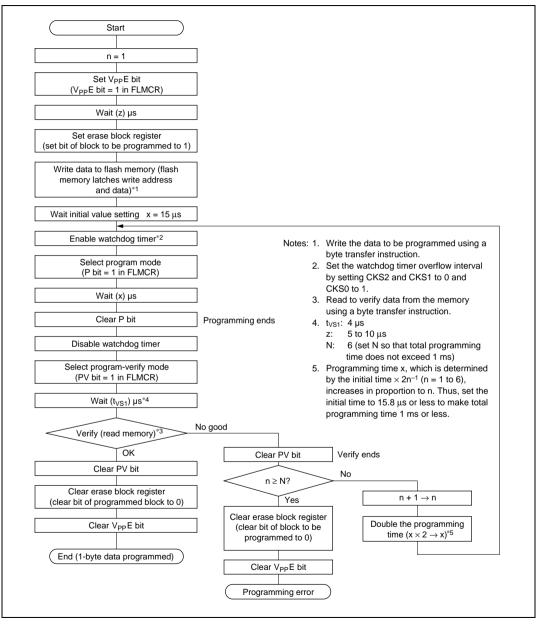


Figure 19.9 Programming Flowchart

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Sample Program for Programming One Byte: This program uses the following registers.

- R0: Program-verify fail counter
- R1: Program-verify timing loop counter
- ER2: Stores the address to be programmed as long word data. Valid addresses are H'00000000 to H'0001FFFF.
- R3H: Stores data to be programmed as byte data
- R4: Sets and clears TCSR and FLMCR
- E4: Stores the initial program loop counter value
- R5: Clears FLMCR
- E5: Stores the program loop counter value

Arbitrary data can be programmed at an arbitrary address by setting the address in ER2 and the data in R3H.

The values of #a, #b, and #g depend on the clock frequency. They can be calculated as indicated under table 19.9.

FLMCR:	.EQU	FFFF40			
EBR1:	.EQU	FFFF42			
EBR2:	.EQU	FFFF43			
TCSR:	.EQU	FFFFA8			
PRGM:	MOV.W	#0001,	RO	;	Program-verify fail count
	MOV.W	#g,	R1	;	Set program loop counter
	MOV.W	#4140,	R4	;	
	MOV.B	R4L,	@FLMCR:8	;	Set V _{PP} E bit
LOOP0:	DEC.W	#1,	Rl	;	
	BPL	LOOP0			
	MOV.B	#**,	ROH	;	
	MOV.B	ROH,	@EBR*:8	;	Set EBR*
	MOV.B	R3H,	@ER2	;	Dummy write
	MOV.W	#a,	E4	;	Set initial program loop counter value
PRGMS:	MOV.W	#A579,	R4	;	Start watchdog timer
	MOV.W	R4,	@TCSR:16	;	
	MOV:W	E4,	E5	;	Set program loop counter
	MOV.W	#4140,	R4	;	
	MOV.B	R4H,	@FLMCR:8	;	Set P bit
LOOP1:	DEC.W	#1,	E5	;	Program
	BPL	LOOP1		;	

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	MOV.B	-	@FLMCR:8		Clear P bit
	MOV.W	#A500,	R4	;	
	MOV.W	R4,	@TCSR:16	;	Stop watchdog timer
	MOV:W	#b ,	R1	;	Set program-verify loop counter
	MOV.B	#44,	R4H	;	
	MOV.B	R4H,	@FLMCR:8	;	Set PV bit
LOOP2:	DEC.W	#1,	R1	;	Wait
	BPL	LOOP2		;	
	MOV.B	@ER2,	R1H	;	Read programmed address
	CMP.B	R3H,	R1H	;	Compare programmed data with read data
	BEQ	PVOK		;	Program-verify decision
PVNG:	MOV.B	#40,	R5H	;	
	MOV.B	R5H,	@FLMCR:8	;	Clear PV bit
	CMP.B	#06,	ROL	;	Program-verify executed 6 times?
	BEQ	NGEND		;	If program-verify executed 6 times, branch to
NGEND					
	INC.B	ROL		;	Program-verify fail count + 1 \rightarrow R0L
	SHLL.W	E4		;	Double program loop counter value
	BRA	PRGMS		;	Program again
PVOK:	MOV.W	#4000,	R5	;	
	MOV.B	R5H,	@FLMCR:8	;	Clear PV bit
	MOV.B	R5L,	@EBR*:8	;	Clear EBR*
	MOV.B	R5L,	@FLMCR:8	;	Clear V _{PP} E bit
					One byte programmed
NGEND:	MOV.W	#4000,	R5	;	
	MOV.B	R5L,	@EBR*:8	;	Clear EBR*
	MOV.B	R5L,	@FLMCR:8	;	Clear V _{PP} E bit
	Programmin	g error			



19.5.4 Erase Mode

To erase the flash memory, follow the erasing algorithm shown in figure 19.10. This erasing algorithm can erase data without subjecting the device to voltage stress or impairing the reliability of programmed data.

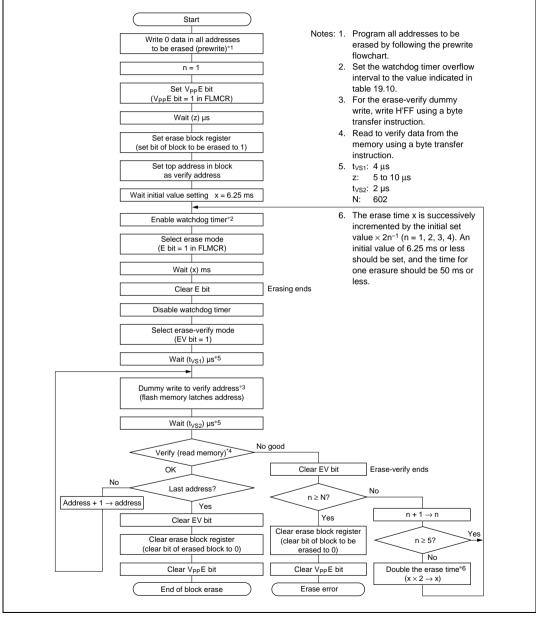
To erase flash memory, before starting to erase, first place all memory data in all blocks to be erased in the programmed state (program all memory data to H'00). If all memory data is not in the programmed state, follow the sequence described later to program the memory data to zero. To select the flash memory areas to be erased, first set the $V_{PP}E$ bit in the flash memory control register (FLMCR), wait 5 to 10 µs, and set up erase block registers 1 and 2 (EBR1 and EBR2). Next set the E bit in FLMCR, selecting erase mode. The erase time is the time during which the E bit is set. To prevent overerasing, use a software timer to divide the erase time. Overerasing, due to program runaway for example, can give memory cells a negative threshold voltage and cause them to operate incorrectly. Before selecting erase mode, set up the watchdog timer so as to prevent overerasing.

19.5.5 Erase-Verify Mode

In program-verify mode, after data has been erased, it is read to check that it has been erased correctly. After the erase time has elapsed, exit erase mode (clear the E bit to 0), select erase-verify mode (set the EV bit to 1), and wait 4 μ s. Before reading data in erase-verify mode, write H'FF dummy data to the address to be read. This dummy write applies an erase-verify voltage to the memory cells at the latched address. If the flash memory is read in this state, the data at the latched address will be read. After the dummy write, wait 2 μ s before reading. If the read data has been successfully erased, perform the dummy write, wait 2 μ s, and erase-verify for the next address. If the read data has not been erased, select erase mode again and repeat the same erase and erase-verify sequence through the last address, until all memory data has been erased to 1. Do not repeat the erase and erase-verify sequence more than 602 times, however.

19.5.6 Erasing Flowchart and Sample Program

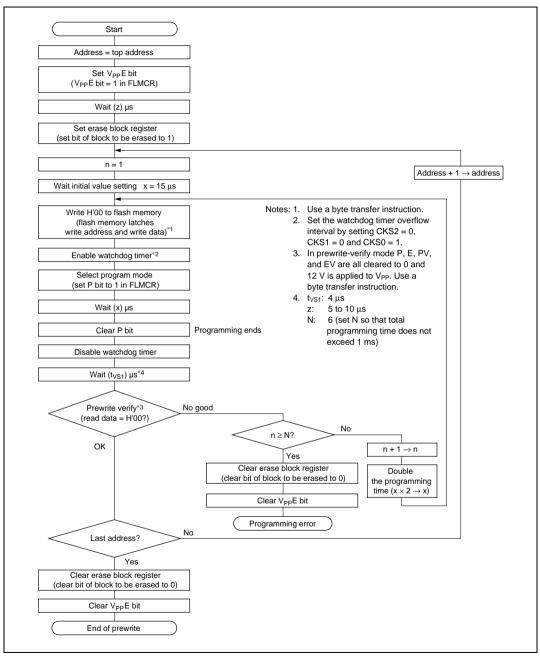
Flowchart for Erasing One Block

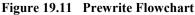




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Prewrite Flowchart





Sample Program for Erasing One Block: This program uses the following registers.

- R0: Prewrite-verify and erase-verify fail counter
- ER1: Stores address used in prewrite
- ER2: Stores address used in prewrite and erase-verify
- ER3: Stores address used in erase-verify
- ER4: Timing loop counter
- R5: Sets appropriate registers
- R6: Sets appropriate registers

The values of #a, #c, #d, #e, #f, #g, and #h, in the program depend on the clock frequency. They can be calculated as indicated in tables 19.9 and 19.10.

FLMCR:	.EQU	FFFF40			
EBR1:	.EQU	FFFF42			
EBR2:	.EQU	FFFF43			
TCSR:	.EQU	FFFFA8			
; #BLKSTI	R is top addres	s of block to b	e erased		
; #BLKEN	D is last addres	ss of block to b	e erased		
	MOV.L	#BLKSTR:	32, ER1	;	ER1: top address of block to be erased
	MOV.L	#BLKEND:	32, ER2	;	ER2: last address of block to be erased
; Execute	prewrite				
PREWRT:	MOV.W	#g,	R4	;	Set wait counter
	MOV.W	#4140,	R6	;	
	MOV.B	R6L,	@FLMCR:8	;	Set V _{PP} E bit
LOOPR0:	DEC.W	#1,	R4	;	
	BPL	LOOPRO		;	
; SET EBR	1 or EBR2 bit	of block to be e	erased		
	MOV.B	#**,	R5H	;	
	MOV.B	R5H,	@EBR*	;	Set EBR*
PREWRN:	SUB.B	ROH,	ROH	;	R0: prewrite-verify fail count
	MOV.W	#a,	E4	;	Set initial prewrite loop counter value
PREWRS:	MOV.B	#00,	R5H	;	Write #00 data
	MOV.B	R5H,	@ER1	;	
	MOV.W	#A579,	R5	;	Start watchdog timer
	MOV.W	R5,	@TCSR:16	;	
	MOV.W	Е4,	R4	;	Set prewrite loop counter
	MOV.W	#4140,	R6	;	

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	MOV.B	R6H,	@FLMCR:8	;	Set P bit
LOOPR1:		#1,	R4		Prewrite
	BPL	LOOPR1		;	
	MOV.B	R6L,	@FLMCR:8	;	Clear P bit
	MOV.W	#A500,	R5		Stop watchdog timer
	MOV.W	R5,	@TCSR:16	;	
	MOV.W	#c ,	R5	;	Set prewrite-verify loop counter
LOOPR2:	DEC.W	#1,	R5	;	Wait
	BPL	LOOPR2		;	
	MOV.B	@ER1,	R5H	;	Read data = H'00?
	BEQ	PWVFOK		;	If read data = H'00, branch to PWVFOK
	CMP.B	#05,	ROH	;	Prewrite-verify executed 6 times?
	BEQ	ABEND1		;	If prewrite-verify executed 6 times, branch to
ABEND1					
	SHLL.W	E4			Double prewrite loop counter value
	INC.B	ROH			Prewrite-verify fail count + 1 \rightarrow R0H
	BRA	PREWRS			Prewrite again
PWVFOK:		ER2,	ER1	;	Last address?
	BEQ	ERASES		;	
	INC.L	#1,	ER1		Address + 1 \rightarrow R1
_	BRA	PREWRN		;	If not last address, prewrite next address
; Execute e		_			
ERASES:		R0,	R0		R0: erase-verify fail count
	MOV.L	#BLKSTR:			ER3: top address of block to be erased
	MOV.W	#d,	E4		Set initial erase loop counter value
ERASE:	CMP.W	#025A,	R0		R0 = H'025A? (erase-verify fail count = 603?)
	BEQ	ABEND2			If $R0 = H'025A$, branch to ABEND2
	INC.W	#1,	R0	;	Erase-verify fail count + 1 \rightarrow R0
	MOV.W	E4,	R4	;	
	MOV.W	#f,	R5		Start watchdog timer
	MOV.W	R5,	@TCSR:16		
	MOV.B	#42,	R5H		
	MOV.B	R5H,	@FLMCR:8	;	
LOOPE:	PUSH.L	ER5			
	POP.L	ER5			

	PUSH.L	ER5			
	POP.L	ER5			
	PUSH.L	ER5			
	POP.L	ER5			
	DEC.W	#1,	R4	;	Erase
	BPL	LOOPE		;	
	MOV.B	#40,	R5H	;	
	MOV.B	R5H,	@FLMCR:8	;	Clear E bit
	MOV.W	#A500,	R5	;	
	MOV.W	R5,	@TCSR:16	;	Stop watchdog timer
; Execute	erase-verify				
	MOV.B	#48,	R5H	;	
	MOV.B	R5H,	@FLMCR:8	;	Set EV bit
	MOV.W	#e ,	R4	;	R4: erase-verify loop counter
LOOPEV:	DEC.W	#1,	R4	;	
	BPL	LOOPEV		;	Wait
EVR2:	MOV.B	#FF,	@ER3	;	Dummy write
	MOV.W	#h,	R4	;	R4: erase-verify loop counter
LOOPDW:	DEC.W	#1,	R4	;	
	BPL	LOOPDW		;	Wait
	MOV.B	@ER3+,	R4H	;	Read
	CMP.B	#FF,	R4H	;	Read data = H'FF?
	BNE	RERASE		;	If read data \neq H'FF, branch to RERASE
	CMP.L	ER2,	ER3	;	Last address in block?
	BGT	EVR2		;	If not last address in block, erase-verify next
address					
	BRA	OKEND,		;	Branch to OKEND
RERASE:	MOV.W	#4000,	R5	;	
	MOV.B	R5H,	@FLMCR:8	;	Clear EV bit
	DEC.L	#1,	ER3	;	Erase-verify address – $1 \rightarrow R3$
	CMP.W	#0004,	R0	;	
	BGE	KEEP		;	Erase executed 4 times?
	SHLL.W	E4		;	Double erase loop counter value
KEEP:	BRA	ERASE		;	Erase again
OKEND:	MOV.W	#4000,	R5	;	

	MOV.B	R5H,	@FLMCR:8	;	Clear EV bit
	MOV.W	#0000,	R5	;	
	MOV.W	R5,	@EBR1:16	;	Clear EBR1 and EBR2
	MOV.B	R5L,	@FLMCR:8	;	Clear $V_{PP}E$ bit
				•	One block erased
ABEND1:	MOV.W	#0000,	R5	;	
	MOV.W	R5,	@EBR1:16	;	Clear EBR1 and EBR2
	MOV.B	R5L,	@FLMCR:8	;	Clear $V_{\mbox{\tiny PP}}E$ bit
	Programming	error			
ABEND2:	MOV.W	#0000,	R5	;	
	MOV.W	R5,	@EBR1:16	;	Clear EBR1 and EBR2
	MOV.B	R5L,	@FLMCR:8	;	Clear $V_{PP}E$ bit
	Erase error				

Flowchart for Erasing Multiple Blocks

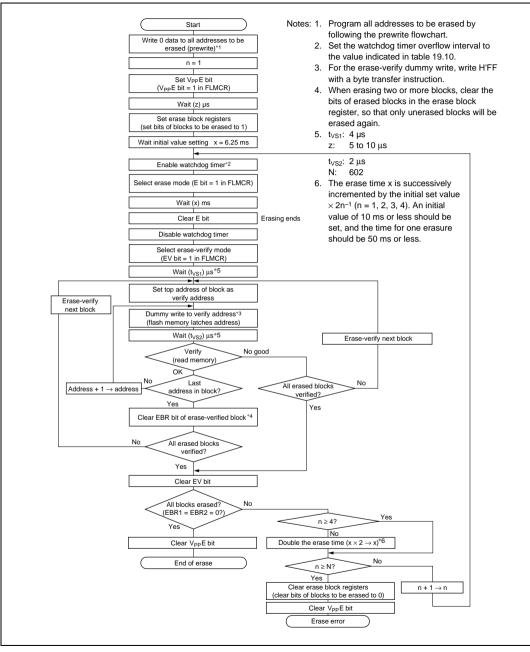


Figure 19.12 Multiple-Block Erase Flowchart

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Sample Program for Erasing Multiple Blocks: This program uses the following registers.

R0, R6: Specifies blocks to be erased (set as explained below)

- R1H: Prewrite-verify fail counter
- R1L: Used to test bits 0 to 15 of R0
- ER2: Specifies address where address used in prewrite and erase-verify is stored
- ER3: Stores address used in prewrite and erase-verify
- ER4: Stores address used in prewrite and erase-verify
- ER5: Sets appropriate registers
- E0, E1: Timing loop counter
- E6: Erase-verify fail counter

Arbitrary blocks can be erased by setting bits in R6.

A bit map of R6 and an example setting for erasing specific blocks are shown next.

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
R6	LB7	LB6	LB5	LB4	LB3	LB2	LB1	LB0	SB7	SB6	SB5	SB4	SB3	SB2	SB1	SB0
	Corresponds to EBR1									Corre	espond	ls to E	BR2			

Example: to erase blocks LB2, SB7, and SB0

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
R6	LB7	LB6	LB5	LB4	LB3	LB2	LB1	LB0	SB7	SB6	SB5	SB4	SB3	SB2	SB1	SB0
		1	Corre	espond	ds to E	BR1	1	1			Corre	espond	ls to E	BR2		
Setting	0	0	0	0	0	1	0	0	1	0	0	0	0	0	0	1

R6 is set as follows:

MOV.W	#0481,	Rб
MOV.W	R6,	@EBR1

The values of #a, #c, #d, #e, #f, #g, and #h in the program depend on the clock frequency. They can be calculated as indicated in tables 19.9 and 19.10.

For #RAMSTR in the program, substitute the starting destination address in RAM, to be used when this program is moved from flash memory into RAM.

FLMCR:		.EQU F	FFF40		
EBR1:			FFF42		
EBR2:		.EQU F			
TCSR:		.EQU F			
; Set R0 v			111110		
	MOV.W	#FFFF,	R6	;	Select blocks to be erased (R6: EBR1/EBR2)
Dinti	MOV.W	_			R0: EBR1/EBR2
	SUB.W	-			R1L: used to test R1-th bit in R0
: #RAMST					rogram is transferred in RAM
	MSTR to eve			n pi	
			:32, ER2	;	Starting transfer destination address
					#RAMSTR + #ERVADR \rightarrow ER2
					ER2: address of data area used in RAM
ספרייפיי:	CMP.B		R1L		
FREIDI	BEQ	ERASES			If finished checking all R0 bits, branch to ERASES
	-	#08,		;	
	BCC	#00, ВСО	КШ	;	
	BTST		DUD	;	
	BNE	PREWRT		;	
	BRA	PWADD1		;	
BC0:	BTST				Test R1-th bit in R0
BCU·	BISI BNE	PREWRT			If R1-th bit in R0 is 1, branch to PREWRT
1 מת משת	INC.B				$R1L + 1 \rightarrow R1L$
PWADDI			ר חיד		
	MOV.L	@ER2+,	ER3	'	Dummy-increment ER2
. Evenute	BRA	PRETST			
; Execute	•	OFF C	ED 2		EP2: prowrite starting address
PREWRT:			ER3		ER3: prewrite starting address
	MOV.L	@ER2,			ER4: top address of next block
	MOV.W	#g,		;	Wait counter
	MOV.W	#4140,	R5	;	
	MOV.B	R5L,			Set V _{PP} E bit
LOOPR0	DEC.W	#1,	E5	;	
	BPL	LOOPR0		;	
	MOV.W	R6,			Set EBR (R6: EBR1/EBR2)
PREW:	MOV.B	#01,	R1H	;	Prewrite-verify fail count

	MOV M	#2	ЕO		Set initial prewrite loop counter value
	MOV.W	#a,			Write #00 data
PREWRS:		#00, DEU	R5H		White #00 Gata
	MOV.B	R5H, #A579,	@ER3	;	
	MOV.W		E5	;	Start watchdag timor
	MOV.W	E5,			Start watchdog timer
	MOV.W	EO,	E1		Set program loop counter
	MOV.W	#4140,	R5	;	Cat D bit
I OODD1 .	MOV.B	R5H,	@FLMCR:8		
LOOPR1:		#1,	E1		Program
	BPL	LOOPR1		;	
	MOV.B	R5L,	@FLMCR:8		Clear P bit
	MOV.W	#A500,	R5	;	
	MOV.W	R5,			Stop watchdog timer
_	MOV.W	#c,	R5		Prewrite-verify loop counter
LOOPR2:		#1,	R5	;	
	BPL	LOOPR2		;	
	MOV.B	@ER3,	R5H	;	Read data = #'00?
	BEQ	PWVFOK		;	If read data = #'00, branch to PWVFOK
PWVFNG:	CMP.B	#06,	R1H	;	Prewrite-verify executed 6 times?
	BEQ	ABEND1		;	If prewrite-verify executed 6 times, branch to
ABEND1	THE D	D111			
	INC.B	R1H			Prewrite-verify fail count + 1 \rightarrow R1H
	SHLL.W	E0			Double prewrite loop counter value
	BRA	PREWRS	_		Prewrite again
PWVFOK:		#1,	ER3		Address + 1 \rightarrow ER3
	CMP.L	ER4,	ER3	;	Last address?
	BEQ	PWADD2		;	
	BRA	PREW		;	
PWADD2:	INC.B	R1L		;	Used to test (R1L + 1)–th bit in R0
	BRA	PRETST		;	Branch to PRETST
; Execute	erase				
ERASES:	MOV.W	R6,	@EBR1:16	;	Set EBR1/EBR2
	SUB.W	Еб,	E6	;	E6: erase-verify fail count
	MOV.W	#d,	ΕO	;	Set initial erase loop counter value
ERASE:	MOV.W	#f ,	R5	;	

Section 19 Flash Memory (H8/3048F: Dual Power Supply (V _{PP} = 12 V	Section 19	ower Supply ($V_{PP} = 12 V$)	Flash Memory
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	MOV.W	R5,	@TCSR:16	;	Start watchdog timer
	MOV.W	ЕΟ,	E1	;	Set erase-loop counter
	MOV.W	#4240,	R5	;	
	MOV.B	R5H,	@FLMCR:8	;	Set E bit
LOOPE:	PUSH.L	ER5			
	POP.L	ER5			
	PUSH.L	ER5			
	POP.L	ER5			
	PUSH.L	ER5			
	POP.L	ER5			
	DEC.W	#1,	E1	;	Erase
	BPL	LOOPE			
	MOV.B	R5L,	@FLMCR:8	;	Clear E bit
	MOV.W	#A500,	R5	;	
	MOV.W	R5,	@TCSR:16	;	Stop watchdog timer
; Execute	erase-verify				
EVR:	MOV.W	R6,	R0	;	R0: EBR1/EBR2
	SUB.W	R1,	R1	;	R1: used to test R1-th bit in R0
; #RAMS1	R is starting c	lestination add	dress to which	ı pr	ogram is transferred in RAM
	MOV.L	#RAMSTR:	32, ER2	;	Starting transfer destination address (RAM)
	ADD.L	#ERVADR:	32, ER2	;	#RAMSTR + #ERVADR \rightarrow ER2
	SUB.L	#START:3	2, ER2	;	ER2: address of data area used in RAM
	MOV.B	#48,	R5H	;	
	MOV.B	R5H,	@FLMCR:8	;	Set EV bit
	MOV.W	#e ,	R5	;	R5: set erase-verify loop counter
LOOPEV:	DEC.W	#1,	R5	;	Program
	BPL	LOOPEV		;	Wait
EBRTST:	CMP.B	#10,	R1L	;	R1L = #10?
	BEQ	HANTEI		;	If finished checking all R0 bits, branch to HANTEI
	CMP.B	#08,	R1L	;	
	BCC	BC1		;	
	BTST	R1L,	R0H	;	Test R1-th bit in R0H (EBR1)
	BNE	ERSEVF		;	
	BRA	ADD01		;	

BC1:	BTST	R1L,	ROL	;	Test R1-th bit in R0L (EBR2)
	BNE	ERSEVF		;	If R1-th bit in R0 is 1, branch to ERSEVF
ADD01:	INC.B	R1L		;	$R1L + 1 \rightarrow R1L$
	MOV.L	@ER2+,	ER3	;	Dummy-increment R2
	BRA	EBRTST		;	
ERSEVF:	MOV.L	@ER2+,	ER3	;	ER3: top address of block to be erase-verified
	MOV.L	@ER2,	ER4	;	ER4: top address of next block
EVR2:	MOV.B	#FF,	R5H	;	
	MOV.B	R5H,	@ER3	;	Dummy write
	MOV.W	#h ,	R5	;	R5: erase-verify loop counter
LOOPDW:	DEC.W	#1,	R5	;	
	BPL	LOOPDW		;	Wait
	MOV.B	@ER3+,	R5L	;	Read
	CMP.B	#FF,	R5L	;	Read data = #FF?
	BNE	ADD02		;	If read data \neq #FF, branch to ADD02
	CMP.L	ER4,	ER3	;	Last address in block?
	BNE	EVR2		;	If not last address in block, branch to EVR2
	CMP.B	#08,	R1L	;	
	BCC	BC2		;	
	BCLR	R1L,	ROH	;	Clear R1L-th bit in R0H (EBR1)
	BRA	ADD02		;	
BC2:	BCLR	R1L,	ROL	;	Clear R1L-th bit in R0L (EBR2)
ADD02:	INC.B	R1L		;	$R1L + 1 \rightarrow R1L$
	BRA	EBRTST		;	Erase-verify next erased block
HANTEI:	MOV.W	#4000,	R5	;	
	MOV.B	R5H,	@FLMCR:8	;	Clear EV bit
	MOV.W	R0,	@EBR1:16	;	Clear bit of erased block to 0
	BEQ	EOWARI		;	If EBR1/EBR2 is all 0, erasing ended normally
	CMP.W	#025A,	E6	;	E6 = 025A? (erase-verify fail count = 602?)
	BEQ	ABEND2		;	If E6 = 025A, branch to ABEND2
	INC.W	#1,	E6	;	Erase-verify fail count + 1 \rightarrow E6
	CMP.W	#0004,	E6	;	
	BGE	KEEP		;	Erase executed 4-times?
	SHLL.W	ΕO		;	Double erase loop counter value
KEEP:	BRA	ERASE		;	Erase again

;	- <block addre<="" p=""></block>	ess table used	in erase-verify	y>-		
	.ALIGN2					
ERVADR:	.DATA.L	00000000		;	#0000	LBO
	.DATA.L	00004000		;	#4000	LB1
	.DATA.L	0008000		;	#8000	LB2
	.DATA.L	0000C000		;	#C000	LB3
	.DATA.L	00010000		;	#10000	LB4
	.DATA.L	00014000		;	#14000	LB5
	.DATA.L	00018000		;	#18000	LB6
	.DATA.L	0001C000		;	#1C000	LB7
	.DATA.L	0001F000		;	#1F000	SBO
	.DATA.L	0001F200		;	#1F200	SB1
	.DATA.L	0001F400		;	#1F400	SB2
	.DATA.L	0001F600		;	#1F600	SB3
	.DATA.L	0001F800		;	#1F800	SB4
	.DATA.L	0001FA00		;	#1FA00	SB5
	.DATA.L	0001FC00		;	#1FC00	SB6
	.DATA.L	0001FE00		;	#1FE00	SB7
	.DATA.L	00020000		;	#20000	FLASH AREA END ADDRESS
EOWARI:	MOV.B	#00,	R5L	;		
	MOV.B	R5L,	@FLMCR:8	;	$Clear\;V_{PP}E$	bit
	Erase end					
ABEND1:	MOV.W	#0000,	R5	;		
	MOV.W	R5,	@EBR1:16	;	Clear EBR	1 and EBR2
	MOV.B	R5L,	@FLMCR:8	;	$Clear\;V_{PP}E$	bit
	Programmin	g error				
ABEND2:	MOV.W	#0000,	R5	;		
	MOV.W	R5,	@EBR1:16	;	Clear EBR	1 and EBR2
	MOV.B	R5L,	@FLMCR:8	;	$Clear V_{PP}E$	bit
	Erase error					

Loop Counter Values in Programs and Watchdog Timer Overflow Interval Settings: The values of a to h in the programs depend on the clock frequency. Table 19.9 indicates the values for 10 MHz. Values for other frequencies can be calculated as shown below, but use the settings in table 19.10 for the value off.

Table 19.9	Loop Counter	Values in	Program	(10 MHz)
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		Variable						
Clock Freq	uency	a (f)	b (f)	C (f)	d (f)	e (f)	g (f)	h (f)
f = 10 MHz	Hexadecimal	H'0019	H'0007	H'0007	H'03B3	H'0007	H'0009	H'0004
	Decimal	25	7	7	947	7	9	4
Comments		Program	t _{∨s1} at write	t _{VS2} at pre-write	Erase	t _{∨S1} at erase	Z	t _{VS2}

Formula:

a (f) to h (f) =
$$\frac{\text{Clock frequency f [MHz]}}{10} \times \{a \text{ (f = 10) to h (f = 10)}\}$$

Examples for 16 MHz:

a (f) =	$\frac{16}{10} \ \times$	25	=	40	*	H'0028
b (f) =	$rac{16}{10}$ $ imes$	7	=	11.2	~	H'000C
c (f) =	$\frac{16}{10}$ ×	7	=	11.2	*	H'000C
d (f) =	$\frac{16}{10}$ ×	947	=	1515.2	*	H'05EC
e (f) =	$\frac{16}{10}$ ×	7	=	11.2	*	H'000C
g (f) =	$rac{16}{10}$ $ imes$	9	=	14.4	*	H'000F
h (f) =	$\frac{16}{10}$ ×	4	=	6.4	*	H'0007

	Variable
Clock Frequency	f
10 MHz \leq frequency \leq 16 MHz	H'A57F
2 MHz \leq frequency < 10 MHz	H'A57E
1 MHz ≤ frequency < 2 MHz	H'A57D

Table 19.10 Watchdog Timer Overflow Interval Settings

Note: The watchdog timer (WDT) set value is calculated based on the number of instructions including write time and erase time from start to stop of WDT operation. In this program example, therefore, no more instructions should be added between the start and stop of WDT operation.

19.5.7 Prewrite-Verify Mode

Prewrite-verify mode is a verify mode used after writing 0 to all bits to equalize their threshold voltages before erasure.

To program all bits, write H'00 in accordance with the algorithm shown in figure 19.11. Use this procedure to set all data in the flash memory to H'00 after programming. After the necessary programming time has elapsed, exit program mode (by clearing the P bit to 0) and select prewrite-verify mode (leave the P, E, PV, and EV bits all cleared to 0). In prewrite-verify mode, a prewrite-verify voltage is applied to the memory cells at the read address. If the flash memory is read in this state, the data at the read address will be read. After selecting prewrite-verify mode, wait 4 μ s before reading.

Note: For a sample prewriting program, see the sample erasing program.



19.5.8 Protect Modes

Flash memory can be protected from programming and erasing by software or hardware methods. These two protection modes are described below.

Software Protection: Prevents transitions to program mode and erase mode even if the P or E bit is set in the flash memory control register (FLMCR). Details are as follows.

			Function						
Protection	Description	Program	Erase	Verify* ¹					
Block protect	Individual blocks can be erase and program-protected by the erase block registers (EBR1 and EBR2). If EBR1 and EBR2 are both set to H'00, all blocks are erase- and program-protected.	Disabled	Disabled	Enabled					
Emulation protect	When the RAMS bit is set in the RAM control register (RAMCR), all blocks are protected from both programming and erasing.	Disabled*2	Disabled* ³	Enabled					
Notes: 1. Th	Notes: 1. Three modes: program-verify, erase-verify, and prewrite-verify.								
2. Ex	cept in RAM areas overlapped onto flash mer	nory.							

3. All blocks are erase-disabled. It is not possible to specify individual blocks.

Hardware Protection: Suspends or disables the programming and erasing of flash memory, and resets the flash memory control register (FLMCR) and erase block registers (EBR1 and EBR2). The error-protect function permits the P and E bits to be set, but prevents transitions to program mode and erase mode. Details of hardware protection are as follows.

			Function	
Protection	Description	Program	Erase	Verify ^{*1}
Programing voltage (V _{PP}) protect	When V_{PP} is not applied, FLMCR, EBR1, and EBR2 are initialized, disabling programming and erasing. To obtain this protection, V_{PP} should not exceed V_{CC} .* ³	Disabled	Disabled*2	Disabled
Reset and standby protect	When a reset occurs (including a watchdog timer reset) or standby mode is entered, FLMCR, EBR1, and EBR2 are initialized, disabling programming and erasing. Note that RES input does not ensure a reset unless the RES pin is held low for at least 20 ms at power-up (to enable the oscillator to settle), or at least 10 system clock cycles (ϕ) during operation.	Disabled	Disabled*2	Disabled
Error protect	If an operational error is detected during programming or erasing of flash memory (FLER = 1), the FLMCR, EBR1, and EBR2 settings are preserved, but programming or erasing is aborted immediately. This type of protection can be cleared only by a reset or hardware standby.	Disabled	Disabled* ²	Enabled

Notes: 1. Program-verify, erase-verify, and prewrite-verify modes.

2. All blocks are erase-disabled. It is not possible to specify individual blocks.

 For details, see section 19.8, Flash Memory Programming and Erasing Precautions (Dual-Power Supply).

Error Protect: This protection mode is entered if one of the error conditions that set the FLER bit in RAMCR is detected while flash memory is being programmed or erased (while the P bit or E bit is set in FLMCR). These conditions can occur if microcontroller operations do not follow the programming or erasing algorithm. Error protect is a flash-memory state. It does not affect other microcontroller operations.

In this state the settings of the flash memory control register (FLMCR) and erase block registers (EBR1 and EBR2) are preserved*, but program mode or erase mode is terminated as soon as the error is detected. While the FLER bit is set, it is not possible to enter program mode or erase

mode, even by setting the P bit or E bit in FLMCR again. The PV and EV bits in FLMCR remain valid, however. Transitions to verify modes are possible in the error-protect state.

The error-protect state can be cleared only by a reset or entry to hardware standby mode.

Note: * It is possible to write to these registers. Note that a transition to software standby mode initializes these registers.

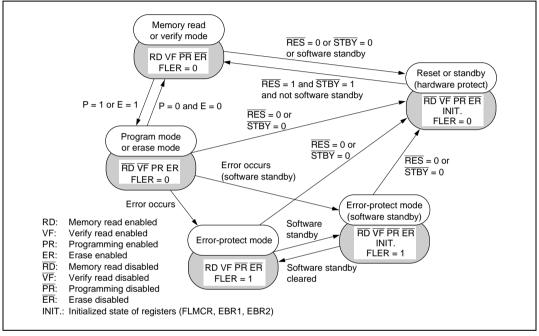


Figure 19.13 Flash Memory State Transitions in Modes 5, 6, and 7 (On-Chip ROM Enabled) when Programming Voltage (V_{PP}) is Applied

The purpose of error-protect mode is to prevent overprogramming or overerasing damage to flash memory by detecting abnormal conditions that occur if the programming or erasing algorithm is not followed, or if a program crashes while the flash memory is being programmed or erased.

This protection function does not cover abnormal conditions other than the setting conditions of the flash memory error bit (FLER), however. Also, if too much time elapses before the errorprotect state is reached, the flash memory may already have been damaged. This function accordingly does not offer foolproof protection from damage to flash memory.

To prevent abnormal operations, when programming voltage (V_{PP}) is applied, follow the programming and erasing algorithms correctly, and keep microcontroller operations under

constant internal and external supervision, using the watchdog timer for example. If a transition to error-protect mode occurs, the flash memory may contain incorrect data due to errors in programming or erasing, or it may contain data that has been insufficiently programmed or erased because of the suspension of these operations. Boot mode should be used to recover to a normal state.

If the memory contains overerased memory cells, boot mode may not operate correctly. This is because the H8/3048F's built-in boot program is located in part of flash memory, and will not read correctly if memory cells have been overerased.

19.5.9 NMI Input Masking

NMI input is disabled when flash memory is being programmed or erased (when the P or E bit is set in FLMCR). NMI input is also disabled while the boot program is executing in boot mode, until the branch to the on-chip RAM area takes place^{*1}. There are three reasons for this.

- NMI input during programming or erasing might cause a violation of the programming or erasing algorithm. Normal operation could not be assured.
- In the NMI exception-handling sequence during programming or erasing, the vector would not be read correctly^{*2}. The result might be a program runaway.
- If NMI input occurred during boot program execution, the normal boot-mode sequence could not be executed.

NMI input is also disabled in the error-protect state while the P or E bit remains set in the flash memory control register (FLMCR).

NMI requests should be disabled externally whenever V_{PP} is applied.

- Notes: 1. The disabled state lasts until the branch to the boot program area in on-chip RAM (addresses H'FFEF10 to H'FFF2FF) that takes place as soon as the transfer of the user program is completed. After the branch to the RAM area, NMI input is enabled except during programming or erasing. NMI interrupt requests must therefore be disabled externally until the user program has completed initial programming (including the vector table and the NMI interrupt-handling program).
 - 2. The vector may not be read correctly for the following two reasons.
 - If flash memory is read while being programmed or erased (while the P or E bit is set in FLMCR), correct read data will not be obtained. Undetermined values are returned.
 - If the NMI entry in the vector table has not been programmed yet, NMI exception handling will not be executed correctly.

19.6 Flash Memory Emulation by RAM

Erasing and programming flash memory takes time, which can make it difficult to tune parameters and other data in real time. If necessary, real-time updates of flash memory can be emulated by overlapping the small-block flash-memory area with part of the RAM (H'FFF000 to H'FFF1FF). This RAM reassignment is performed using bits 3 to 0 of the RAM control register (RAMCR).

After a flash memory area has been overlapped by RAM, it can be accessed from two address areas: the overlapped flash memory area, and the original RAM area (H'FFF000 to H'FFF1FF). Table 19.11 indicates how to reassign RAM.

RAM Control Register (RAMCR)

Bit	7	6	5	4	3	2	1	0
	FLER		—		RAMS	RAM2	RAM1	RAM0
Initial value*	0	1	1	1	0	0	0	0
Read/Write	R	_	_	_	R/W	R/W	R/W	R/W

Note: * Bit 7 and bits 3 to 0 are initialized by a reset and in hardware standby mode. They are not initialized in software standby mode. Bits 3 to 0 can be written to in modes 5, 6, and 7 (onchip flash memory enabled). In other modes, they are always read as 0 and cannot be modified.

Table 19.11 RAM Area Reassignment

	Bit 3	Bit 2	Bit 1	Bit 0
RAM Area	RAMS	RAM2	RAM1	RAM0
H'FFF000 to H'FFF1FF	0	0/1	0/1	0/1
H'01F000 to H'01F1FF	1	0	0	0
H'01F200 to H'01F3FF	1	0	0	1
H'01F400 to H'01F5FF	1	0	1	0
H'01F600 to H'01F7FF	1	0	1	1
H'01F800 to H'01F9FF	1	1	0	0
H'01FA00 to H'01FBFF	1	1	0	1
H'01FC00 to H'01FDFF	1	1	1	0
H'01FE00 to H'01FFFF	1	1	1	1

Example of Emulation of Real-Time Flash-Memory Update

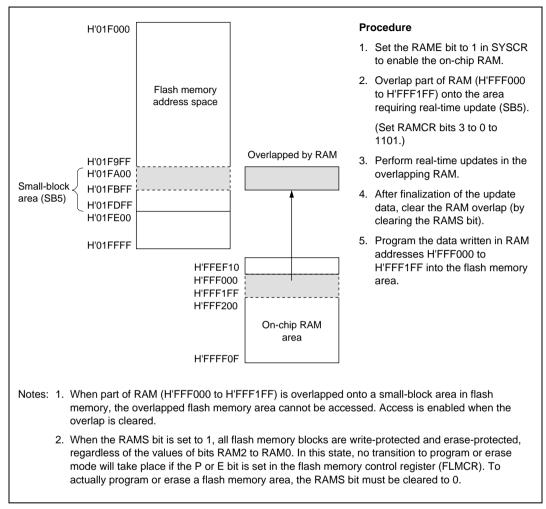


Figure 19.14 Example of RAM Overlap



19.7 Flash Memory PROM Mode

19.7.1 PROM Mode Setting

The on-chip flash memory of the H8/3048F can be programmed and erased not only in the onboard programming modes but also in PROM mode, using a general-purpose PROM programmer. Table 19.12 indicates how to select PROM mode. Be sure to use the indicated table 19.13 socket adapter in PROM mode.

Table 19.12 Selecting PROM Mode

Pins	Setting
Mode pins: MD ₂ , MD ₁ , MD ₀	Low
P8 ₀ , P8 ₁ , and P9 ₂	
STBY and HWR	High
P5 ₀ , P5 ₁ , and P8 ₂	
RES	Power on reset circuit
XTAL and EXTAL	Oscillator circuit

19.7.2 Socket Adapter and Memory Map

Programs can be written and verified by attaching a special 100-pin/32-pin socket adapter to the PROM programmer. Table 19.13 gives ordering information for the socket adapter. Figure 19.15 shows a memory map in PROM mode. Figure 19.16 shows the socket adapter pin interconnections.

Table 19.13 Socket Adapter

Microcontroller	Package	Socket Adapter
HD64F3048F	100-pin plastic QFP (FP-100B)	HS3048ESHF1H
HD64F3048VF		
HD64F3048TF	100-pin plastic TQFP (TFP-100B)	HS3048ESNF1H
HD64F3048VTF		

MCU mode	H8/3048F	PROM mode
H'000000		H'00000
	On-chip ROM area	
H'01FFFF		H'1FFFF



Note: The FP-100B and TFP-100B pin pitch is only 0.5 mm. Use an appropriate tool when inserting the device in the IC socket and removing it. For example, the tool listed in table 19.14 can be used.

Table 19.14

Manufacturer	Part Number
ENPLAS CORPORATION	HP-100 (vacuum pen)

H8/3048F		Cooket Adex :	HN28F101 (32 Pins)		
Pin No.	Pin Name	Socket Adapter			
FP-100B, TFP-100B			Pin Name	Pin No.	
10	RESO	1 	V _{PP}	1	
64	NMI	1	A 9	26	
69	P63		A 16	2	
58	P60	1	A 15	3	
90	P83	1	WE	31	
27	P30	 	I/O ₀	13	
28	P3 ₁	1	I/O ₁	14	
29	P3 ₂	1 	I/O ₂	15	
30	P33	1	I/O ₃	17	
31	P34	 	I/O ₄	18	
32	P35	1	I/O ₅	19	
33	P3 ₆	1	I/O ₆	20	
34	P3 ₇	 	I/O ₇	21	
36	P10		A ₀	12	
37	P11	- 	A 1	11	
38	P12	 	A ₂	10	
39	P13	1	A ₃	9	
40	P14	1 1 1	A ₄	8	
41	P15	1	A 5	7	
42	P1 ₆	1	A ₆	6	
43	P17	 	A ₇	5	
45	P20	1	A ₈	27	
46	P21	1	OE	24	
47	P22	1 	A 10	23	
48	P23	 	A 11	25	
49	P24		A 12	4	
50	P25	 	A 13	28	
51	P2 ₆	1	A 14	29	
52	P27	 	CE	22	
53, 54, 89	P5 ₀ , P5 ₁ , P8 ₂	 •	V _{cc}	32	
62, 71	STBY, HWR	<u> </u>	V _{SS}	16	
73 to 75	MD ₀ , MD ₁ , MD ₂ ,			1	
87, 88, 14	P8 ₀ , P8 ₁ , P9 ₂		Legend	Programming	
76, 77	AV _{CC} , V _{REF}	<u> </u>	1 * PP-	power supply	
1, 35, 68	V _{CC}		I/O_7 to I/O_0 :	Data input/ou	
86	AV _{SS}	<u> </u>	A_{16} to A_0 :		
11, 22, 44	V _{SS}	: 		Output enable Chip enable	
57, 65, 92	* >>		WE:	Write enable	
63	RES	Power-on reset circuit	1		
66, 67	EXTAL, XTAL		1		
Other pins	NC (OPEN)	Oscillator circuit			

Note: This figure shows pin assignments, and does not show the entire socket adapter circuit. When undertaking a new design, board design (power supply voltage stabilization, noise countermeasures, etc.) and operating timing design as a high-speed CMOS LSI are necessary.

Figure 19.16 Wiring of Socket Adapter

19.7.3 Operation in PROM Mode

The program/erase/verify specifications in PROM mode are the same as for the standard HN28F101 flash memory. Table 19.15 indicates how to select the various operating modes. The H8/3048F does not have a device recognition code, so the programmer cannot read the device name automatically.

		Pins						
Mode		V _{PP}	Vcc	CE	ŌĒ	WE	I/O ₇ to I/O ₀	A ₁₆ to A ₀
Read	Read	Vcc	Vcc	L	L	Н	Data output	Address input
	Output disable	V _{CC}	V _{CC}	L	Н	Н	High impedance	
	Standby	V _{CC}	V _{CC}	Н	Х	Х	High impedance	_
Command	Read	V_{PP}	Vcc	L	L	Н	Data output	
write	Output disable	V_{PP}	V _{CC}	L	Н	Н	High impedance	
	Standby	V_{PP}	V _{CC}	Н	Х	Х	High impedance	_
	Write	V_{PP}	V_{CC}	L	Н	L	Data input	

Table 19.15 Operating Mode Selection in PROM Mode

Legend

L: Low level

H: High level

 $V_{\mathsf{PP}} : V_{\mathsf{PP}} \text{ level}$

V_{CC}:V_{CC} level

X: Don't care



		1st Cycle			2nd Cycle			
Command	Cycles	Mode	Address	Data	Mode	Address	Data	
Memory read	1	Write	Х	H'00	Read	RA	Dout	
Erase setup/erase	2	Write	Х	H'20	Write	Х	H'20	
Erase-verify	2	Write	EA	H'A0	Read	Х	EVD	
Auto-erase setup/ auto-erase	2	Write	Х	H'30	Write	Х	H'30	
Program setup/ program	2	Write	Х	H'40	Write	PA	PD	
Program-verify	2	Write	Х	H'C0	Read	Х	PVD	
Reset	2	Write	Х	H'FF	Write	Х	H'FF	

Table 19.16 PROM Mode Commands

PA: Program address

EA: Erase-verify address

RA: Read address

PD: Program data

PVD: Program-verify output data

EVD: Erase-verify output data

High-Speed, High-Reliability Programming: Unused areas of the H8/3048F flash memory contain H'FF data (initial value). The H8/3048F flash memory uses a high-speed, high-reliability programming procedure. This procedure provides enhanced programming speed without subjecting the device to voltage stress and without sacrificing the reliability of programmed data. Figure 19.17 shows the basic high-speed, high-reliability programming flowchart. Tables 19.17 and 19.18 list the electrical characteristics during programming.

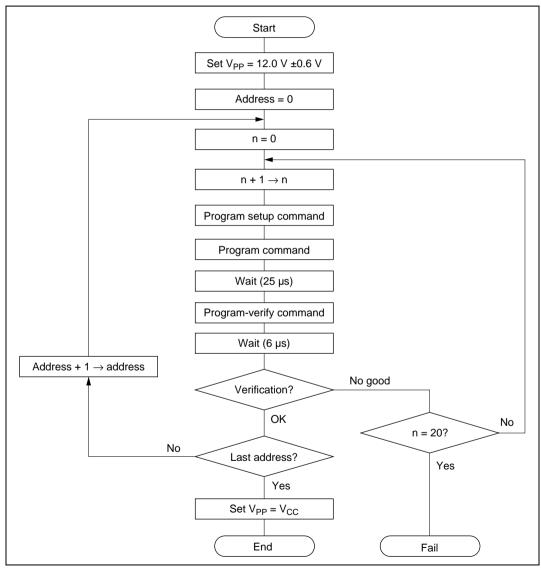


Figure 19.17 High-Speed, High-Reliability Programming

High-Speed, High-Reliability Erasing: The H8/3048F flash memory uses a high-speed, high-reliability erasing procedure. This procedure provides enhanced erasing speed without subjecting the device to voltage stress and without sacrificing data reliability. Figure 19.18 shows the basic high-speed, high-reliability erasing flowchart. Tables 19.17 and 19.18 list the electrical characteristics during programming.

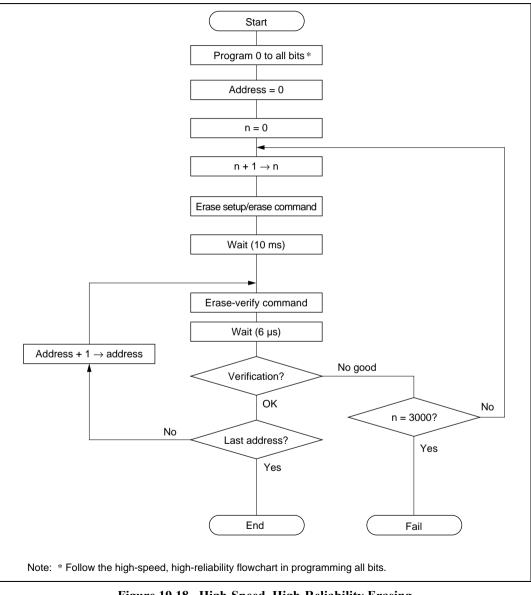


Figure 19.18 High-Speed, High-Reliability Erasing

Table 19.17 DC Characteristics in PROM Mode

(Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{PP} = 12.0 \text{ V} \pm 0.6 \text{ V}$, $V_{SS} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item		Symbol	Min	Тур	Мах	Unit	Test Conditions
Input high voltage	$\begin{array}{c} I/O_7 \text{ to } I/O_0,\\ \underline{A_{16}} \text{ to } A_0,\\ \overline{OE}, \ \overline{CE}, \ \overline{WE} \end{array}$	VIH	2.2	—	V _{CC} + 0.3	V	
Input low voltage	$\begin{array}{c} I/O_7 \text{ to } I/O_0,\\ \underline{A_{16}} \text{ to } A_0,\\ \overline{OE}, \ \overline{CE}, \ \overline{WE} \end{array}$	V _{IL}	-0.3	_	0.8	V	
Output high voltage	I/O ₇ to I/O ₀	V _{OH}	2.4	_	—	V	I _{OH} = -200 μA
Output low voltage	I/O ₇ to I/O ₀	V _{OL}		_	0.45	V	I _{OL} = 1.6 mA
Input leakage current	$\begin{array}{c} I/O_7 \text{ to } I/O_0,\\ \underline{A_{16}} \text{ to } A_0,\\ \overline{OE}, \ \overline{CE}, \ \overline{WE} \end{array}$	ILI	—	—	2	μA	V_{IN} = 0 to V_{CC} V
V _{CC} current	Read	I _{CC}		40	80	mA	
	Program	Icc		40	80	mA	
	Erase	I _{CC}		40	80	mA	
V _{PP} current	Read	I _{PP}	_	_	200	μA	V _{PP} = 5.0 V
			_	10	20	mA	V _{PP} = 12.6 V
	Program	I _{PP}	_	20	40	mA	
	Erase	I _{PP}	—	20	40	mA	

Note: For details on absolute maximum ratings, see section 22.2.1. Using an LSI in excess of absolute maximum ratings may result in permanent damage*.

* V_{PP} peak overshoot should not exceed 13 V.

Table 19.18 AC Characteristics in PROM Mode

(Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{PP} = 12.0 \text{ V} \pm 0.6 \text{ V}$, $V_{SS} = 0 \text{ V}$, $T_a = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

Item	Symbol	Min	Тур	Мах	Unit	Test Conditions
Command write cycle	tcwc	120		—	ns	Figure 19.19
Address setup time	t _{AS}	0		_	ns	Figure 19.20* Figure 19.21
Address hold time	t _{AH}	60	_	_	ns	
Data setup time	t _{DS}	50	_	_	ns	
Data hold time	t _{DH}	10	_	_	ns	
CE setup time	t _{CES}	0	_	_	ns	
CE hold time	t _{CEH}	0	_	_	ns	
V _{PP} setup time	t _{VPS}	100		_	ns	_
V _{PP} hold time	t _{VPH}	100	_	_	ns	
WE programming pulse width	t _{WEP}	70	—	—	ns	_
WE programming pulse high time	t _{WEH}	20	_	_	ns	_
OE setup time before command write	t _{OEWS}	0	_	_	ns	_
OE setup time before verify	t _{OERS}	6		_	μs	_
Verify access time	t _{VA}		_	500	ns	_
OE setup time before status polling	t _{OEPS}	120	_	—	ns	_
Status polling access time	t _{SPA}	_	_	120	ns	_
Program wait time	t _{PPW}	25	_	_	ns	_
Erase wait time	t _{ET}	9	_	11	ms	_
Output disable time	t _{DF}	0	_	40	ns	_
Total auto-erase time	t _{AET}	0.5	—	30	S	_

Note: \overline{CE} , \overline{OE} , and \overline{WE} should be high during transitions of V_{PP} from 5 V to 12 V and from 12 V to 5 V.

* Input pulse level: 0.45 V to 2.4 V
 Input rise time and fall time ≤ 10 ns
 Timing reference levels: 0.8 V and 2.0 V for input; 0.8 V and 2.0 V for output



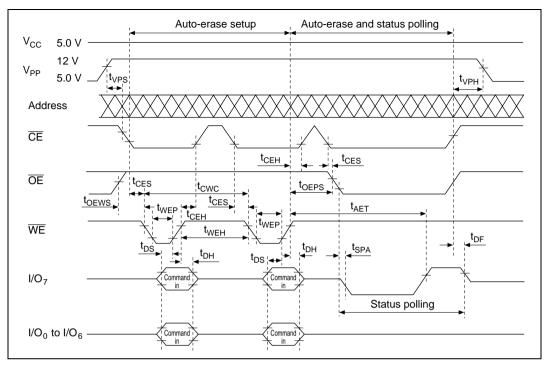


Figure 19.19 Auto-Erase Timing



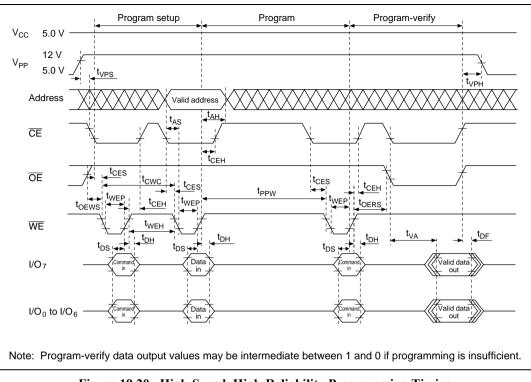


Figure 19.20 High-Speed, High-Reliability Programming Timing



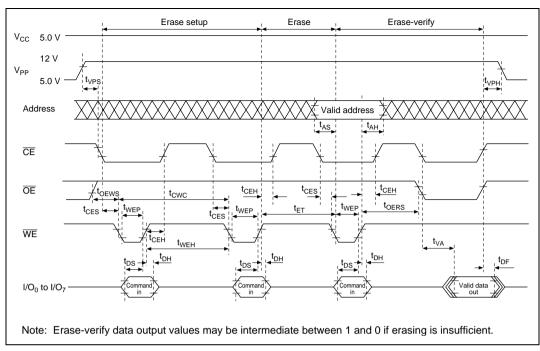


Figure 19.21 Erase Timing



19.8 Flash Memory Programming and Erasing Precautions (Dual-Power Supply)

(1) Program with the specified voltages and timing.

The rated programming voltage (V_{PP}) of the flash memory is 12.0 V.

If the PROM programmer is set to Renesas Technology HN28F101 specifications, V_{PP} will be 12.0 V. Applied voltages in excess of the rating can permanently damage the device. Insure, in particular, that peak overshoot at the Vpp and MD2 pins does not exceed the maximum rating of 13 V. Also, be very careful about PROM programmer overshoot.

(2) Before programming, check that the chip is correctly mounted in the PROM

programmer. Overcurrent damage to the device can result if the index marks on the PROM programmer socket, socket adapter, and chip are not correctly aligned.

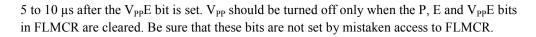
(3) Don't touch the socket adapter or chip while programming. Touching either of these can cause contact faults and write errors.

(4) Precautions in turning the programming voltage (V_{PP}) on and off (see figures 19.22 to 19.24):

• Apply the programming voltage (V_{PP}) after the rise of V_{CC} , when the microcontroller is in a stable condition. Shut off V_{PP} before V_{CC} , again while the microcontroller is in a stable condition. If V_{PP} is turned on or off while V_{CC} is not within its rated voltage range ($V_{CC} = 2.7$ to 5.5 V), since microcontroller operation is unstable and flash memory protection is not functioning, the flash memory may be programmed or erased by mistake. This can occur even if $V_{CC} = 0$ V. The same danger of incorrect programming or erasing exists when V_{CC} is within its rated voltage range ($V_{CC} = 2.7$ to 5.5 V) if the clock oscillator has not stabilized, if the clock oscillator has stopped (except in standby), or if a program runaway has occurred. After V_{CC} power-up, do not apply V_{PP} until the clock oscillator has had time to settle ($t_{OSC1} = 20$ ms min) and the microcontroller is safely in the reset state, or the reset has been cleared.

These power-on and power-off timing requirements should also be satisfied in the event of a power failure and recovery from a power failure. If these requirements are not satisfied, the flash memory may not only be unintentionally programmed or erased; it may be permanently damaged.

• The V_{PP} bit in the flash memory control register (FLMCR) is set or cleared when the $V_{PP}E$ bit in FLMCR is set or cleared while a voltage of 12.0 ± 0.6 V is being applied to the V_{PP} pin. After the $V_{PP}E$ bit is set, it becomes possible to write the erase block registers (EBR1 and EBR2) and the EV, PV, E, and P bits in FLMCR. Accordingly, program or erase flash memory



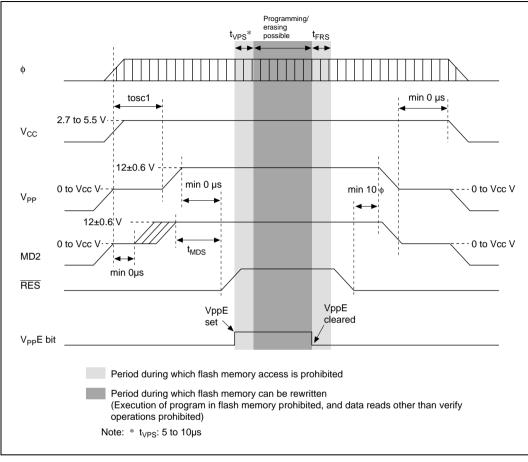


Figure 19.22 Power-On and Power-Off Timing (Boot Mode)



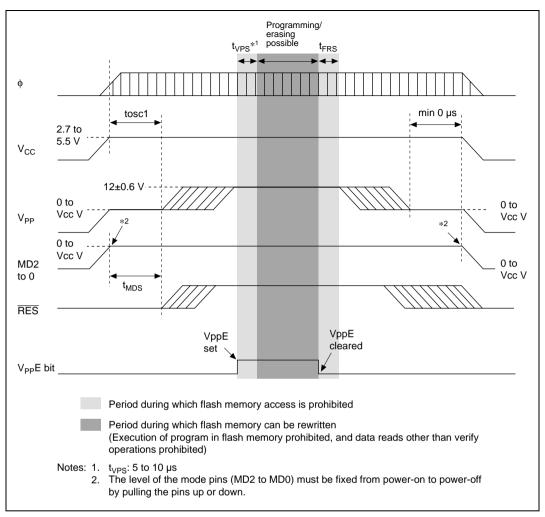


Figure 19.23 Power-On and Power-Off Timing (User Program Mode)



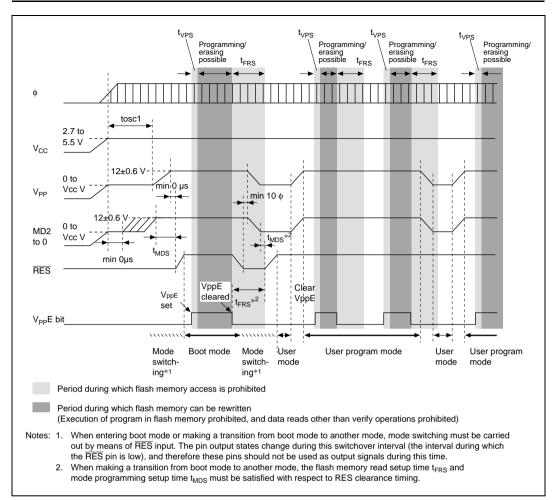


Figure 19.24 Mode Transition Timing (Example: Boot Mode → User Mode ↔ User Program Mode)



(5) Do not apply 12 V to the V_{PP} pin during normal operation. To prevent microcontroller errors caused by accidental programming or erasing, apply 12 V to V_{PP} only when the flash memory is programmed or erased, or when flash memory is emulated by RAM. While 12 V is applied, the watchdog timer should be running and enabled to halt runaway program execution, so that program runaway will not lead to overprogramming or overerasing.

(6) Disable watchdog-timer reset output ($\overline{\text{RESO}}$) while the programming voltage (V_{PP}) is turned on. If 12 V is applied during watchdog timer reset output (while the $\overline{\text{RESO}}$ pin is low), overcurrent flow will permanently destroy the reset output circuit. The watchdog timers reset output enable bit (RSTOE) should not be set to 1.

If a pull-up resistor is externally attached to the V_{PP}/\overline{RESO} pin, a diode is necessary to prevent reverse current from flowing to V_{CC} when V_{PP} is applied (figure 19.25).

(7) If the watchdog timer generates a reset output signal when 12 V is not applied, the rise and fall of the reset output waveform will be delayed by any decoupling capacitors connected to the V_{PP} pin.

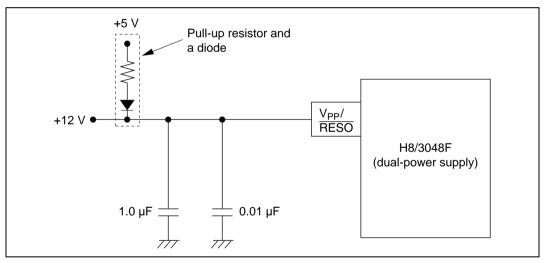


Figure 19.25 V_{PP} Power Supply Circuit Design (Example)

(8) Notes concerning mounting board development—handling of V_{PP} and mode MD2 pins

- The standard 12 V high voltage is applied to the V_{PP} and mode MD2 pins when erasing or programming flash memory. The voltage at these pins also includes overshoot and noise, and the following points should be noted to ensure that the 13 V maximum rated voltage is not exceeded.
 - a. Bypass capacitors should be inserted to eliminate overshoot and noise. These should be positioned as close as possible to the chip's V_{PP} and mode MD2 pins.
 - 1.0 μ F: Stabilizes fluctuations in the low-frequency components, such as power supply ripple.
 - 0.01 µF: Bypasses high-frequency components such as induction noise.
 - b. The V_{PP} and mode MD2 pin wiring should be kept as short as possible to suppress induction noise. When designing a new board, in particular, noise may be increased by jumper wires, etc. In this case too, the power supply waveform should be monitored and measures taken to prevent the maximum rating from being exceeded.
 - c. The maximum rated voltage is based on the potential of the V_{SS} pin. If the potential of this pin oscillates due to current fluctuations, etc., the voltage of the V_{PP} and mode MD2 pins may reciprocally exceed the maximum rated voltage. Careful attention must therefore be paid to stabilizing the reference potential.
 - Note: When the user system's 12 V power supply is connected, attention must be paid to the current capacity. A power supply with a small current capacity will not be able to handle fluctuations in the chip's operating voltage, resulting in voltage drops and rises or oscillation that may make it impossible to obtain the rated operating voltage. If the power supply has a large current capacity, or if the 12 V voltage is turned on abruptly by means of a switch, etc., caution is required since a voltage exceeding the maximum rating may be generated due to the inductance component of the power supply wiring or the power supply characteristics.

Before using the power supply, check the power supply waveform to ensure that the above problems will not arise.

- 2. 12 V is applied to the V_{PP} and mode MD2 pins when programming or erasing flash memory. When these pins are pulled up to the V_{CC} line in normal operation, diodes should be inserted to prevent reverse current from flowing to the V_{CC} line when 12 V is applied.
 - Note: In normal operation, if the mode MD2 pin to which 12 V is applied is to be set to 0, it should be pulled down with a resistor.



A sample circuit is shown figure 19.26.

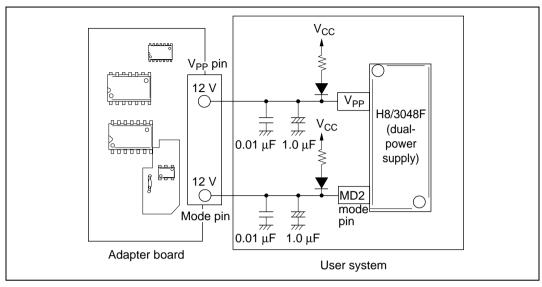


Figure 19.26 Example of Mounting Board Design for the H8/3048F-ZTAT with the Dual-Power Supply

(Connection to Adapter Board—When V_{PP} Pin and Mode Pin Settings Are 1)

(9) Do not set or clear the VppE bit during execution of a program in flash memory.

Flash memory data cannot be read normally when the VppE bit is set or cleared. After the VppE bit is cleared, flash memory data can be rewritten after waiting for the elapse of the Vpp enable setup time (t_{VPS} : 5 10 µs), but flash memory cannot be accessed for purposes other than verification (verification during programming, erasing, or prewriting). After the VppE is cleared, wait for the elapse of the flash memory read setup time before performing program execution and data reading in flash memory.

(10) Do not use interrupts while programming or erasing flash memory.

When Vpp is applied, disable all interrupt requests, including NMI, to give the programming or erase operation (including RAM emulation) the highest priority.

(11) The Vpp flag is set and cleared by a threshold decision on the voltage applied to the Vpp pin. The threshold level is approximately in the range from Vcc +2 V to 11.4 V.

When this flag is set, it becomes possible to write to the flash memory control register (FLMCR) and the erase block registers (EBR1 and EBR2), even though the Vpp voltage may not yet have

reached the programming voltage range of 12.0 V \pm 0.6 V. Do not actually program or erase the flash memory until Vpp has reached the programming voltage range.

The programming voltage range for programming and erasing flash memory is $12.0 \text{ V} \pm 0.6 \text{ V}$ (11.4 V to 12.6 V). Programming and erasing cannot be performed correctly outside this range. When not programming or erasing the flash memory, ensure that the Vpp voltage does not exceed the Vcc voltage. This will prevent unintentional programming and erasing.

(12) After the Vpp enable bit (VppE) is cleared, the flash memory read setup time $(t_{FRS})^*$ must elapse before the flash memory is read.

When switching from boot mode or user program mode to normal mode (Vpp \neq 12 V, MD2 \neq 12 V), this setup time is required as the period from VppE bit clearance until the flash memory is read.

When switching from boot mode to another mode, a mode programming setup time (t_{MDS}) is required with respect to the \overline{RES} release timing.

Note: * The flash memory read setup time stipulates the interval before flash memory is read after the VppE bit is cleared (figure 19.24). Also, when using an external clock (EXTAL input), after powering on and when returning from standby mode, the flash memory read setup time must elapse before the flash memory is read.



19.9 Notes when Converting the F-ZTAT (Dual-Power Supply) Application Software to the Mask-ROM Versions

Please note the following when converting the F-ZTAT (dual-power supply) application software to the mask-ROM versions.

The values read from the internal registers (refer to appendix B, Internal I/O Register, Table B.1) for the flash ROM of the mask-ROM version and F-ZTAT (dual-power supply) version differ as follows.

		St	tatus
Register	Bit	F-ZTAT (Dual-Power Supply) Version	Mask-ROM Version
FLMCR	V_{PP}	0: Application software running 1: Programming	0: Not read out 1: Application software running

Note: This difference applies to all the F-ZTAT (dual-power supply) versions and all the mask-ROM versions that have different ROM size.



Section 20 Clock Pulse Generator

20.1 Overview

The H8/3048 Group has a built-in clock pulse generator (CPG) that generates the system clock (ϕ) and other internal clock signals (ϕ /2 to ϕ /4096). After duty adjustment, a frequency divider divides the clock frequency to generate the system clock (ϕ). The system clock is output at the ϕ pin^{*1} and furnished as a master clock to prescalers that supply clock signals to the on-chip supporting modules. Frequency division ratios of 1/1, 1/2, 1/4, and 1/8 can be selected for the frequency divider by settings in a division control register (DIVCR). Power consumption in the chip is reduced in almost direct proportion to the frequency division ratio^{*2}.

- Notes: 1. Usage of the φ pin differs depending on the chip operating mode and the PSTOP bit setting in the module standby control register (MSTCR). For details, see section 21.7, System Clock Output Disabling Function.
 - 2. The division ratio of the frequency divider can be changed dynamically during operation. The clock output at the ϕ pin also changes when the division ratio is changed. The frequency output at the ϕ pin is shown below.

 $\phi = EXTAL \times n$

where, EXTAL: Frequency of crystal resonator or external clock signal n: Frequency division ratio (n = 1/1, 1/2, 1/4, or 1/8)

20.1.1 Block Diagram

Figure 20.1 shows a block diagram of the clock pulse generator.

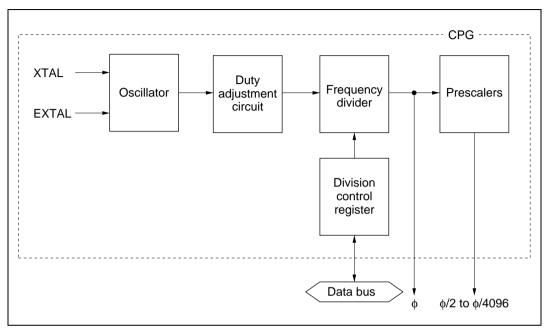


Figure 20.1 Block Diagram of Clock Pulse Generator

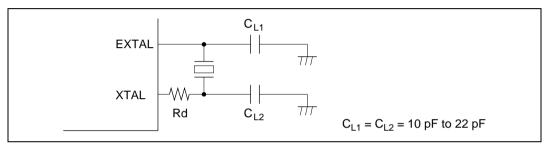


20.2 Oscillator Circuit

Clock pulses can be supplied by connecting a crystal resonator, or by input of an external clock signal.

20.2.1 Connecting a Crystal Resonator

Circuit Configuration: A crystal resonator can be connected as in the example in figure 20.2. The damping resistance Rd should be selected according to table 20.1. An AT-cut parallel-resonance crystal should be used.





In order to improve the accuracy of the oscillation frequency, a thorough study of oscillation matching evaluation, etc., should be carried out when deciding the circuit constants.

Table 20.1 Damping Resistance Value

Dam	ping Resistance			Fi	requency f (l	VIHz)		
Valu		2	2 < f ≤ 4	4 < f ≤ 8	8 < f ≤ 10	10 < f ≤ 13	13 < f ≤ 16	16 < f ≤ 18
Rd (Ω)	For products listed below*	1 k	500	200	0	0	0	0
	H8/3048F	1 k	1 k	500	200	100	0	_

Note: A crystal resonator between 2 MHz and 18 MHz can be used. If the chip is to be operated at less than 2 MHz, the on-chip frequency divider should be used. (A crystal resonator of less than 2 MHz cannot be used.)

* H8/3048ZTAT, H8/3048 mask-ROM, H8/3047 mask-ROM, H8/3045 mask-ROM, H8/3044 mask-ROM

Crystal Resonator: Figure 20.3 shows an equivalent circuit of the crystal resonator. The crystal resonator should have the characteristics listed in table 20.2.

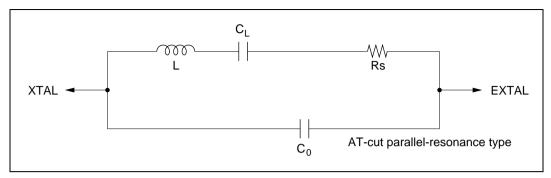


Figure 20.3 Crystal Resonator Equivalent Circuit

Table 20.2 Crystal Resonator Parameters

Frequency (MHz)	2	4	8	10	12	16	18
Rs max (Ω)	500	120	80	70	60	50	40
C₀ max (pF)				7			

Use a crystal resonator with a frequency equal to the system clock frequency (ϕ).

Notes on Board Design: When a crystal resonator is connected, the following points should be noted:

Other signal lines should be routed away from the oscillator circuit to prevent induction from interfering with correct oscillation. See figure 20.4.

When the board is designed, the crystal resonator and its load capacitors should be placed as close as possible to the XTAL and EXTAL pins.



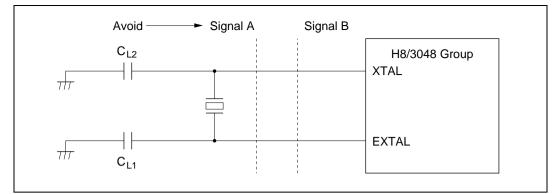
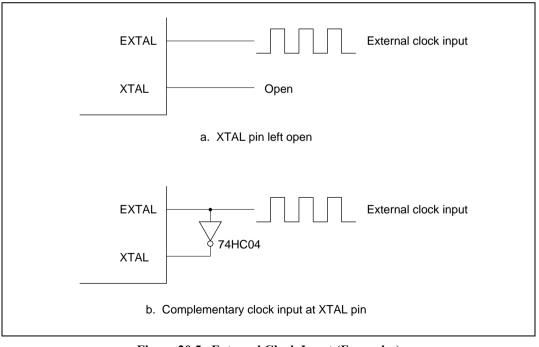


Figure 20.4 Example of Incorrect Board Design

20.2.2 External Clock Input

Circuit Configuration: An external clock signal can be input as shown in the examples in figure 20.5. The external clock is input from the EXTAL pin. If the XTAL pin is left open, the stray capacitance should not exceed 10 pF. If the stray capacitance at the XTAL pin exceeds 10 pF in configuration a, use configuration b instead and hold the clock high in standby mode.



External Clock: The external clock frequency should be equal to the system clock frequency (ϕ) when not divided by the on-chip frequency divider. Table 20.3, figures 20.6 and 20.7 indicate the clock timing.

When the appropriate external clock is input via the EXTAL pin, its waveform is corrected by the on-chip oscillator and duty adjustment circuit. The resulting stable clock is output to external devices after the external clock settling time (t_{DEXT}) has passed after the clock input. The system must remain reset with the reset signal low during t_{DEXT} , while the clock output is unstable.

			/ _{cc} = ′ to 5.5 V		V _{cc} = V ± 10%			
ltem	Symbol	Min	Max	Min	Max	Unit	Test Condit	tions
External clock input low pulse width	t _{EXL}	40	_	20	_	ns	Figure 20.6	
External clock input high pulse width	t _{EXH}	40	—	20	—	ns	_	
External clock rise time	t _{EXr}	—	10		5	ns	_	
External clock fall time	t_{EXf}	—	10	_	5	ns	_	
Clock low pulse	t _{CL}	0.4	0.6	0.4	0.6	t _{cyc}	$\varphi \geq 5 \ MHz$	Figure
width		80	—	80	—	ns	ϕ < 5 MHz	22.7
Clock high pulse width	igh pulse t _{CH}	0.4	0.6	0.4	0.6	t _{cyc}	$\varphi \geq 5 \ MHz$	_
		80		80	_	ns	ϕ < 5 MHz	_
External clock output settling delay time	t _{DEXT} *	500		500		μs	Figure 20.7	

Table 20.3 Clock Timing

Note: * t_{DEXT} includes 10 t_{cyc} of \overline{RES} (t_{RESW}).

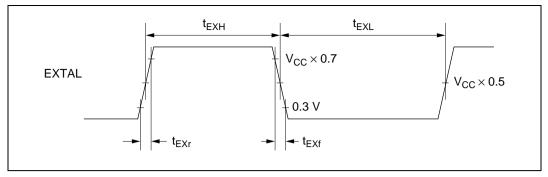


Figure 20.6 External Clock Input Timing

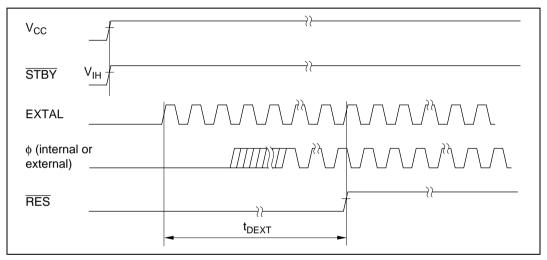


Figure 20.7 External Clock Output Settling Delay Timing

20.3 Duty Adjustment Circuit

When the oscillator frequency is 5 MHz or higher, the duty adjustment circuit adjusts the duty cycle of the clock signal from the oscillator to generate the signal that becomes the system clock.

20.4 Prescalers

The prescalers divide the system clock (ϕ) to generate internal clocks (ϕ /2 to ϕ /4096).

20.5 Frequency Divider

The frequency divider divides the duty-adjusted clock signal to generate the system clock (ϕ). The frequency division ratio can be changed dynamically by modifying the value in DIVCR, as described below. Power consumption in the chip is reduced in almost direct proportion to the frequency division ratio. The system clock generated by the frequency divider can be output at the ϕ pin.

20.5.1 Register Configuration

Table 20.4 summarizes the frequency division register.

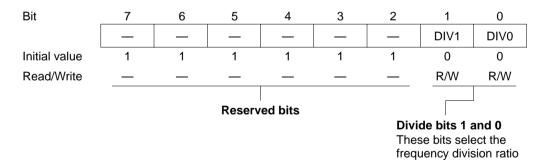
Table 20.4 Frequency Division Register

Address*	Name	Abbreviation	R/W	Initial Value			
H'FF5D	Division control register	DIVCR	R/W	H'FC			

Note: * The lower 16 bits of the address are shown.

20.5.2 Division Control Register (DIVCR)

DIVCR is an 8-bit readable/writable register that selects the division ratio of the frequency divider.



DIVCR is initialized to H'FC by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bits 7 to 2—Reserved: Read-only bits, always read as 1.



Bit 1: DIV1	Bit 0: DIV0	Frequency Division Ratio	
0	0	1/1	(Initial value)
	1	1/2	
1	0	1/4	
	1	1/8	

Bits 1 and 0—Divide (DIV1 and DIV0): These bits select the frequency division ratio, as follows.

20.5.3 Usage Notes

The DIVCR setting changes the ϕ frequency, so note the following points.

• Select a frequency division ratio that stays within the assured operation range specified for the clock cycle time t_{cyc} in the AC electrical characteristics. Note that ϕ_{MIN} must be in the lower limit of the clock frequency range. Avoid settings that give system clock frequencies less than the lower limit.

Table 20.5 shows the comparison with the clock frequency range for each version.

 Table 20.5
 Comparison with the Clock Frequency Ranges in the H8/3048 Group

ROM type F-ZTAT ZTAT Mask ROM		ROM				
Product type)	H8/3048F	H8/3048	8 Mask ROM Mask ROM Mask ROM Mas		H8/3044 Mask ROM Version
Guaranteed 4.5–5.5 V clock 3.15–5.5 V		1–16 MHz	1–18 MHz	1–18 MHz		
		_	1–13 MHz	1–13 MHz		
frequency range	2.7–5.5 V	1–8 MHz	1–8 MHz	1–8 MHz		
Crystal oscil	lation range	2–16 MHz	2–18 MHz	Hz 2–18 MHz		

• All on-chip module operations are based on ϕ . Note that the timing of timer operations, serial communication, and other time-dependent processing differs before and after any change in the division ratio. The waiting time for exit from software standby mode also changes when the division ratio is changed. For details, see section 21.4.3, Selection of Waiting Time for Exit from Software Standby Mode.



Section 21 Power-Down State

21.1 Overview

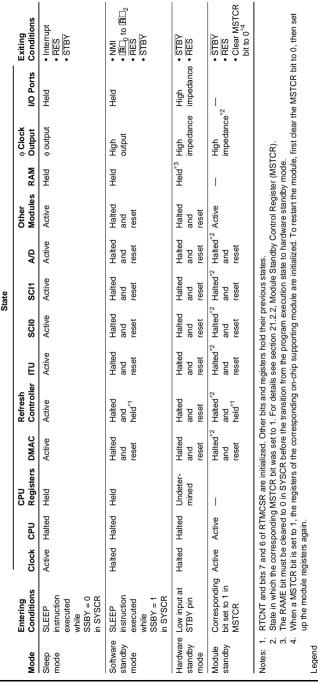
The H8/3048 Group has a power-down state that greatly reduces power consumption by halting the CPU, and a module standby function that reduces power consumption by selectively halting on-chip modules.

The power-down state includes the following three modes:

- Sleep mode
- Software standby mode
- Hardware standby mode

The module standby function can halt on-chip supporting modules independently of the powerdown state. The modules that can be halted are the ITU, SCI0, SCI1, DMAC, refresh controller, and A/D converter.

Table 21.1 indicates the methods of entering and exiting the power-down modes and module standby mode, and gives the status of the CPU and on-chip supporting modules in each mode.



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Renesas

SSBY: Software standby bit MSTCR: Module standby control register

System control register

SYSCR:

 Table 21.1
 Power-Down State and Module Standby Function

21.2 Register Configuration

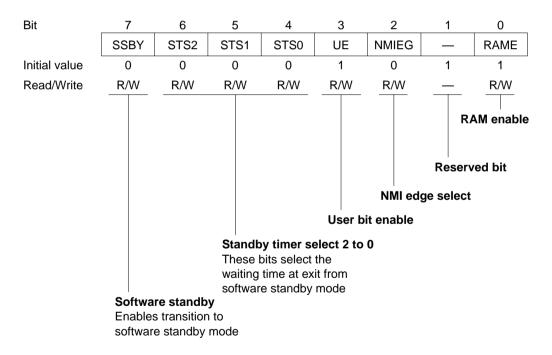
The H8/3048 Group has a system control register (SYSCR) that controls the power-down state, and a module standby control register (MSTCR) that controls the module standby function. Table 21.2 summarizes these registers.

Table 21.2 Control Register

Address*	Name	Abbreviation	R/W	Initial Value
H'FFF2	System control register	SYSCR	R/W	H'0B
H'FF5E	Module standby control register	MSTCR	R/W	H'40
N. 1				

Note: * Lower 16 bits of the address.

21.2.1 System Control Register (SYSCR)



SYSCR is an 8-bit readable/writable register. Bit 7 (SSBY) and bits 6 to 4 (STS2 to STS0) control the power-down state. For information on the other SYSCR bits, see section 3.3, System Control Register (SYSCR).

Bit 7—Software Standby (SSBY): Enables transition to software standby mode. When software standby mode is exited by an external interrupt, this bit remains set to 1 after the return to normal operation. To clear this bit, write 0.

Bit 7: SSBY	Description	
0	SLEEP instruction causes transition to sleep mode	(Initial value)
1	SLEEP instruction causes transition to software standby mode	

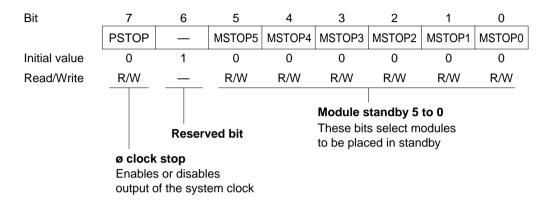
Bits 6 to 4—Standby Timer Select (STS2 to STS0): These bits select the length of time the CPU and on-chip supporting modules wait for the clock to settle when software standby mode is exited by an external interrupt. If the clock is generated by a crystal resonator, set these bits according to the clock frequency so that the waiting time will be at least 7 ms. See table 21.3. If an external clock is used, any value may be selected.

Bit 6: STS2	Bit 5: STS1	Bit 4: STS0	Description	
0	0	0	Waiting time = 8,192 states	(Initial value)
		1	Waiting time = 16,384 states	
	1	0	Waiting time = 32,768 states	
		1	Waiting time = 65,536 states	
1	0	0	Waiting time = 131,072 states	
		1	Waiting time = 1,024 states	
	1	_	Illegal setting	



21.2.2 Module Standby Control Register (MSTCR)

MSTCR is an 8-bit readable/writable register that controls output of the system clock (ϕ). It also controls the module standby function, which places individual on-chip supporting modules in the standby state. Module standby can be designated for the ITU, SCI0, SCI1, DMAC, refresh controller, and A/D converter modules.



MSTCR is initialized to H'40 by a reset and in hardware standby mode. It is not initialized in software standby mode.

Bit 7—\phi Clock Stop (PSTOP): Enables or disables output of the system clock (ϕ).

Bit 1: PSTOP	Description	
0	System clock output is enabled	(Initial value)
1	System clock output is disabled	

Bit 6—Reserved: Read-only bit, always read as 1.

Bit 5—Module Standby 5 (MSTOP5): Selects whether to place the ITU in standby.

Bit 5: MSTOP5	Description	
0	ITU operates normally	(Initial value)
1	ITU is in standby state	

Bit 4—Module Standby 4 (MSTOP4): Selects whether to place SCI0 in standby.

Bit 4: MSTOP4	Description	
0	SCI0 operates normally	(Initial value)
1	SCI0 is in standby state	

Bit 3—Module Standby 3 (MSTOP3): Selects whether to place SCI1 in standby.

Bit 3: MSTOP3	Description	
0	SCI1 operates normally	(Initial value)
1	SCI1 is in standby state	

Bit 2-Module Standby 2 (MSTOP2): Selects whether to place the DMAC in standby.

Bit 2: MSTOP2	Description	
0	DMAC operates normally	(Initial value)
1	DMAC is in standby state	

Bit 1-Module Standby 1 (MSTOP1): Selects whether to place the refresh controller in standby.

Bit 1: MSTOP1	Description	
0	Refresh controller operates normally	(Initial value)
1	Refresh controller is in standby state	

Bit 0—Module Standby 0 (MSTOP0): Selects whether to place the A/D converter in standby.

Bit 0: MSTOP0	Description	
0	A/D converter operates normally	(Initial value)
1	A/D converter is in standby state	



21.3 Sleep Mode

21.3.1 Transition to Sleep Mode

When the SSBY bit is cleared to 0 in SYSCR, execution of the SLEEP instruction causes a transition from the program execution state to sleep mode. Immediately after executing the SLEEP instruction the CPU halts, but the contents of its internal registers are retained. The DMA controller (DMAC), refresh controller, and on-chip supporting modules do not halt in sleep mode. Modules which have been placed in standby by the module standby function, however, remain halted.

21.3.2 Exit from Sleep Mode

Sleep mode is exited by an interrupt, or by input at the $\overline{\text{RES}}$ or $\overline{\text{STBY}}$ pin.

Exit by Interrupt: An interrupt terminates sleep mode and causes a transition to the interrupt exception handling state. Sleep mode is not exited by an interrupt source in an on-chip supporting module if the interrupt is disabled in the on-chip supporting module. Sleep mode is not exited by an interrupt other than NMI if the interrupt is masked by the I and UI bits in CCR and IPR.

Exit by RES Input: Low input at the RES pin exits from sleep mode to the reset state.

Exit by STBY Input: Low input at the STBY pin exits from sleep mode to hardware standby mode.

21.4 Software Standby Mode

21.4.1 Transition to Software Standby Mode

To enter software standby mode, execute the SLEEP instruction while the SSBY bit is set to 1 in SYSCR.

In software standby mode, current dissipation is reduced to an extremely low level because the CPU, clock, and on-chip supporting modules all halt. The DMAC and on-chip supporting modules are reset. As long as the specified voltage is supplied, however, CPU register contents and on-chip RAM data are retained. The settings of the I/O ports and refresh controller* are also held.

Note: * RTCNT and bits 7 and 6 of RTMCSR are initialized. Other bits and registers hold their previous states.

When the WDT is used as a watchdog timer (WT/ \overline{IT} = 1), the TME bit must be cleared to 0 before setting SSBY. Also, when setting TME to 1, SSBY should be cleared to 0.

Clear the BRLE bit in BRCR (inhibiting bus release) before making a transition to software standby mode.

21.4.2 Exit from Software Standby Mode

Software standby mode can be exited by input of an external interrupt at the NMI, \overline{IRQ}_0 , \overline{IRQ}_1 , or \overline{IRQ}_2 pin, or by input at the \overline{RES} or \overline{STBY} pin.

Exit by Interrupt: When an NMI, IRQ_0 , IRQ_1 , or IRQ_2 interrupt request signal is received, the clock oscillator begins operating. After the oscillator settling time selected by bits STS2 to STS0 in SYSCR, stable clock signals are supplied to the entire chip, software standby mode ends, and interrupt exception handling begins. Software standby mode is not exited if the interrupt enable bits of interrupts IRQ_0 , IRQ_1 , and IRQ_2 are cleared to 0, or if these interrupts are masked in the CPU.

Exit by RES Input: When the RES input goes low, the clock oscillator starts and clock pulses are supplied immediately to the entire chip. The RES signal must be held low long enough for the clock oscillator to stabilize. When RES goes high, the CPU starts reset exception handling.

Exit by **STBY** Input: Low input at the **STBY** pin causes a transition to hardware standby mode.

21.4.3 Selection of Waiting Time for Exit from Software Standby Mode

Bits STS2 to STS0 in SYSCR and bits DIV1 and DIV0 in DIVCR should be set as follows.

Crystal Resonator: Set STS2 to STS0, DIV1, and DIV0 so that the waiting time (for the clock to stabilize) is at least 7 ms. Table 21.3 indicates the waiting times that are selected by STS2 to STS0, DIV1, and DIV0 settings at various system clock frequencies. Refer to table 21.3 for the operating frequency and the waiting time needed for the oscillator to settle.

External Clock: Any values may be set.



0		0	0	0100 states										
_	۱		•	8192 states	0.46	0.51	0.65	0.8	1.0	1.3	2.0	4.1	8.2*	ms
0	,	0	1	16384 states	0.91	1.0	1.3	1.6	2.0	2.7	4.1	8.2*	16.4	
0)	1	0	32768 states	1.8	2.0	2.7	3.3	4.1	5.5	8.2*	16.4	32.8	
0)	1	1	65536 states	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4	32.8	65.5	
1		0	0	131072 states	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	
1		0	1	1024 states	0.057	0.064	0.085	0.10	0.13	0.17	0.26	0.51	1.0	-
1		1	_					llleg	al settin	g				-
0)	0	0	8192 states	0.91	1.02	1.4	1.6	2.0	2.7	4.0	8.2*	16.4*	ms
0)	0	1	16384 states	1.8	2.0	2.7	3.3	4.1	5.5	8.2*	16.4	32.8	
0)	1	0	32768 states	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4	32.8	65.5	•
0)	1	1	65536 states	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	
1		0	0	131072 states	14.6	16.4	21.8	26.2	32.8	43.7	65.5	131.1	262.1	
1		0	1	1024 states	0.11	0.13	0.17	0.20	0.26	0.34	0.51	1.0	2.0	
1		1	_					llleg	al settin	g				
0)	0	0	8192 states	1.8	2.0	2.7	3.3	4.1	5.5	8.2*	16.4*	32.8*	ms
0)	0	1	16384 states	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4	32.8	65.5	
0)	1	0	32768 states	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	
0)	1	1	65536 states	14.6	16.4	21.8	26.2	32.8	43.7	65.5	131.1	262.1	-
1		0	0	131072 states	29.1	32.8	43.7	52.4	65.5	87.4	131.1	262.1	524.3	-
1		0	1	1024 states	0.23	0.26	0.34	0.41	0.51	0.68	1.02	2.0	4.1	
1		1	_					llleg	al settin	g				-
0)	0	0	8192 states	3.6	4.1	5.5	6.6	8.2*	10.9*	16.4*	32.8*	65.5	ms
0)	0	1	16384 states	7.3*	8.2*	10.9*	13.1*	16.4	21.8	32.8	65.5	131.1	
0)	1	0	32768 states	14.6	16.4	21.8	26.2	32.8	43.7	65.5	131.1	262.1	•
0)	1	1	65536 states	29.1	32.8	43.7	52.4	65.5	87.4	131.1	262.1	524.3	
1		0	0	131072 states	58.3	65.5	87.4	104.9	131.1	174.8	262.1	524.3	1048.6	•
1		0	1	1024 states	0.46	0.51	0.68	0.82	1.0	1.4	2.0	4.1	8.2	•
1		1	_					llleg	al settin	g				
		1 1 0 0 0 0 1 1 1 1 0 1	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	1 0 1 1024 states 0.057 0.064 0.085 0.10 0.13 0.17 0.26 0.51 1.0 1 1 Illegal setting 0 0 8192 states 0.91 1.02 1.4 1.6 2.0 2.7 4.0 8.2* 16.4* 0 0 1 16384 states 1.8 2.0 2.7 3.3 4.1 5.5 8.2* 16.4 32.8 0 1 0 32768 states 3.6 4.1 5.5 6.6 8.2* 10.9* 16.4 21.8 32.8 65.5 131.1 1 0 0 131072 states 14.6 16.4 21.8 26.2 32.8 43.7 65.5 131.1 26.1 1 0 1 1024 states 0.11 0.13 0.17 0.20 0.26 0.34 0.51 1.0 2.0 1 1 Illegal setting						

 Table 21.3
 Clock Frequency and Waiting Time for Clock to Settle

DIV1 DIV0 STS2 STS1 STS0 Waiting Time 18 MHz 16 MHz 12 MHz 10 MHz 8 MHz 6 MHz 4 MHz 2 MHz 1 MHz Unit

*: Recommended setting

21.4.4 Sample Application of Software Standby Mode

Figure 21.1 shows an example in which software standby mode is entered at the fall of NMI and exited at the rise of NMI.

With the NMI edge select bit (NMIEG) cleared to 0 in SYSCR (selecting the falling edge), an NMI interrupt occurs. Next the NMIEG bit is set to 1 (selecting the rising edge) and the SSBY bit is set to 1; then the SLEEP instruction is executed to enter software standby mode.

Software standby mode is exited at the next rising edge of the NMI signal.

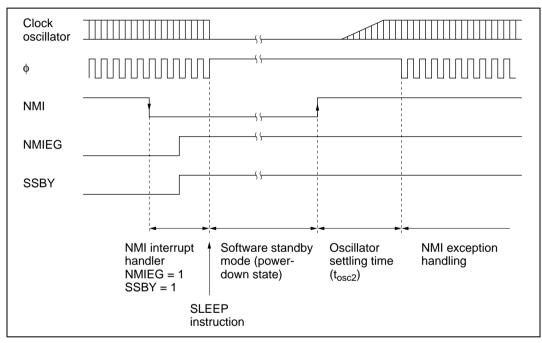


Figure 21.1 NMI Timing for Software Standby Mode (Example)

21.4.5 Note

The I/O ports retain their existing states in software standby mode. If a port is in the high output state, its output current is not reduced.



21.5 Hardware Standby Mode

21.5.1 Transition to Hardware Standby Mode

Regardless of its current state, the chip enters hardware standby mode whenever the STBY pin goes low. Hardware standby mode reduces power consumption drastically by halting all functions of the CPU, DMAC, refresh controller, and on-chip supporting modules. All modules are reset except the on-chip RAM. As long as the specified voltage is supplied, on-chip RAM data is retained. I/O ports are placed in the high-impedance state.

Clear the RAME bit to 0 in SYSCR before STBY goes low to retain on-chip RAM data.

The inputs at the mode pins (MD2 to MD0) should not be changed during hardware standby mode.

21.5.2 Exit from Hardware Standby Mode

Hardware standby mode is exited by inputs at the $\overline{\text{STBY}}$ and $\overline{\text{RES}}$ pins. While $\overline{\text{RES}}$ is low, when $\overline{\text{STBY}}$ goes high, the clock oscillator starts running. $\overline{\text{RES}}$ should be held low long enough for the clock oscillator to settle. When $\overline{\text{RES}}$ goes high, reset exception handling begins, followed by a transition to the program execution state.

21.5.3 Timing for Hardware Standby Mode

Figure 21.2 shows the timing relationships for hardware standby mode. To enter hardware standby mode, first drive $\overline{\text{RES}}$ low, then drive $\overline{\text{STBY}}$ low. To exit hardware standby mode, first drive $\overline{\text{STBY}}$ high, wait for the clock to settle, then bring $\overline{\text{RES}}$ from low to high.

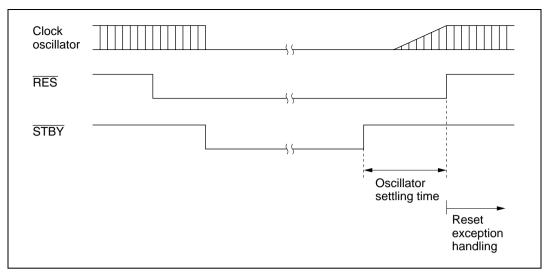


Figure 21.2 Hardware Standby Mode Timing

21.6 Module Standby Function

21.6.1 Module Standby Timing

The module standby function can halt several of the on-chip supporting modules (the ITU, SCI0, SCI1, DMAC, refresh controller, and A/D converter) independently of the power-down state. This standby function is controlled by bits MSTOP5 to MSTOP0 in MSTCR. When one of these bits is set to 1, the corresponding on-chip supporting module is placed in standby and halts at the beginning of the next bus cycle after the MSTCR write cycle.

21.6.2 Read/Write in Module Standby

When an on-chip supporting module is in module standby, read/write access to its registers is disabled. Read access always results in H'FF data. Write access is ignored.



21.6.3 Usage Notes

When using the module standby function, note the following points.

DMAC and Refresh Controller: When setting bit MSTOP2 or MSTOP1 to 1 to place the DMAC or refresh controller in module standby, make sure that the DMAC or refresh controller is not currently requesting the bus right. If bit MSTOP2 or MSTOP1 is set to 1 when a bus request is present, operation of the bus arbiter becomes ambiguous and a malfunction may occur.

Internal Peripheral Module Interrupt: When MSTCR is set to "1", prevent module interrupt in advance. When an on-chip supporting module is placed in standby by the module standby function, its registers, including the interrupt flag, are initialized.

Pin States: Pins used by an on-chip supporting module lose their module functions when the module is placed in module standby. What happens after that depends on the particular pin. For details, see section 9, I/O Ports. Pins that change from the input to the output state require special care. For example, if SCI1 is placed in module standby, the receive data pin loses its receive data function and becomes a generic I/O pin. If its data direction bit is set to 1, the pin becomes a data output pin, and its output may collide with external serial data. Data collisions should be prevented by clearing the data direction bit to 0 or taking other appropriate action.

Register Resetting: When an on-chip supporting module is halted by the module standby function, all its registers are initialized. To restart the module, after its MSTCR bit is cleared to 0, its registers must be set up again. It is not possible to write to the registers while the MSTCR bit is set to 1.

MSTCR Access from DMAC Disabled: To prevent malfunctions, MSTCR can only be accessed from the CPU. It can be read by the DMAC, but it cannot be written by the DMAC.

21.7 System Clock Output Disabling Function

Output of the system clock (ϕ) can be controlled by the PSTOP bit in MSTCR. When the PSTOP bit is set to 1, output of the system clock halts and the ϕ pin is placed in the high-impedance state. Figure 21.3 shows the timing of the stopping and starting of system clock output. When the PSTOP bit is cleared to 0, output of the system clock is enabled. Table 21.4 indicates the state of the ϕ pin in various operating states.

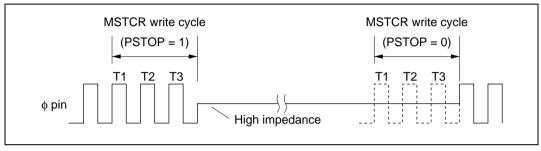


Figure 21.3 Starting and Stopping of System Clock Output

Table 21.4	φ Pin State in	Various O	perating States
	• • • • • • • • • • • • • • • • • • •		per anna seates

Operating State	PSTOP = 0	PSTOP = 1
Hardware standby	High impedance	High impedance
Software standby	Always high	High impedance
Sleep mode	System clock output	High impedance
Normal operation	System clock output	High impedance



Section 22 Electrical Characteristics

Table 22.1 shows the electrical characteristics of the various products in the H8/3048 Group.

Table 22.1	Electrical Characteristics of H8/3048 Group Products
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	ltem	Symbol	Unit	H8/3048 F-ZTAT (Dual Power Supply)	H8/3048 H8/3047 H8/3045 H8/3044	H8/3048 ZTAT	H8/3048 F-ONE (Single Power Supply) ^{∗5}
Operating	$V_{\rm CC}$ = 4.5 to 5.5 V		MHz	1 to 16	1 to 18	1 to 18	2 to 25
range	$V_{\rm CC}$ = 3.15 to 5.5 V			—	1 to 13	1 to 13	—
	V_{CC} = 2.7 to 5.5 V			1 to 8	1 to 8	1 to 8	_
	$V_{\rm CC}$ = 3.0 to 3.6 V			—	—		2 to 25
Operating temperature	Regular specifications	T _{opr}	°C	-20 to +75	-20 to +75	-20 to +75	-20 to +75*1
range	Wide-range specifications			-40 to +85	-40 to +85	-40 to +85	-40 to +85 ^{*1}
Absolute	V _{PP} pin rating	Vin		Yes	—	Yes	—
maximum	FWE pin rating			—	—		Yes
ratings	V _{CL} pin			_	_	_	Cannot be connected to power supply ^{*2} (5 V operation model only)
	Power supply voltage	V _{in}	V	-0.3 to +7.0	-0.3 to +7.0	-0.3 to +7.0	-0.3 to +7.0 (5 V operation model) -0.3 to +4.6 (3 V operation model)
DC charac- teristics	RESO pin specification			Yes	Yes	Yes	—
	FWE pin specification				_	-	Yes
	Determination level for applying high voltage (12 V)			Yes	_		-
	Standby current $(T_a \le 50^{\circ}C)$	I _{CC} * ³	μA	Max 5	Max 5	Max 5	Max 10
	Standby current (50°C < T _a)			Max 20	Max 20	Max 20	Max 80



Section 22 Electrical Characteristics

	Item	Symbol	Unit	H8/3048 F-ZTAT (Dual Power Supply)	H8/3048 H8/3047 H8/3045 H8/3044	H8/3048 ZTAT	H8/3048 F-ONE (Single Power Supply)* ⁵
AC charac-	Clock cycle time	t _{cyc}	ns	Max 1000	Max 1000	Max 1000	Max 500
teristics	RES pulse width	t _{RESW}	t _{cyc}	Min 10	Min 10	Min 10	Min 20
	RESO output delay time	t _{RESD}	ns	Max 100	Max 100	Max 100	—
	RESO output pulse width	t _{RESOW}	t _{cyc}	Min 132	Min 132	Min 132	_
Flash memory charac- teristics* ⁴	Other wait times			See table 22.20	_	—	See table 21.11

Notes: 1. The operating temperature range for flash memory programming/erasing is 0°C to +75°.

2. Connect an external capacitor between the V_{CL} pin and GND.

3. See the DC Characteristics table for current dissipation during operation.

4. Refer to the program/erase algorithms for details of flash memory characteristics.

5. Refer to the H8/3048F-ONE Hardware Manual (Rev. 1.0) for details.



22.1 Electrical Characteristics for H8/3048 ZTAT (PROM) and On-Chip Mask ROM Versions

Target product types:H8/3048 ZTAT, H8/3048 mask-ROM, H8/3047 mask-ROM,
H8/3045 mask-ROM, H8/3044 mask-ROM

22.1.1 Absolute Maximum Ratings

Table 22.2 lists the absolute maximum ratings.

Table 22.2 Absolute Maximum Ratings

Item	Symbol	Value	Unit
Power supply voltage	V _{CC}	-0.3 to +7.0	V
Programming voltage (H8/3048 ZTAT)	V _{PP}	–0.3 to +13.5	V
Input voltage (except for port 7)	Vin	–0.3 to V _{CC} + 0.3	V
Input voltage (port 7)	Vin	–0.3 to AV _{CC} + 0.3	V
Reference voltage	V_{REF}	–0.3 to AV _{CC} + 0.3	V
Analog power supply voltage	AV _{CC}	-0.3 to +7.0	V
Analog input voltage	V _{AN}	–0.3 to AV _{CC} + 0.3	V
Operating temperature	T _{opr}	Regular specifications: -20 to +75	°C
		Wide-range specifications: -40 to +85	°C
Storage temperature	T _{stg}	–55 to +125	°C

Caution: Permanent damage to the chip may result if absolute maximum ratings are exceeded. Particularly, insure that peak overshoot at the V_{PP} pin does not exceed 13 V.

22.1.2 DC Characteristics

Table 22.3 lists the DC characteristics. Table 22.4 lists the permissible output currents.

Table 22.3 DC Characteristics (1)

Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}^{*1}$, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt trigger input	Port A, P8 ₂ to P8 ₀ ,	V _T -	1.0	_	_	V	
voltages	PB ₃ to PB ₀	V_{T}^{+}	_	_	$V_{CC} \times 0.7$	V	-
		$V_T^+ - V_T^-$	0.4	_	_	V	_
Input high voltage	RES, STBY, NMI,	V _{IH}	$V_{CC} - 0.7$	_	V _{CC} + 0.3	V	
	EXTAL	_	$V_{CC} \times 0.7$	_	V _{CC} + 0.3	V	_
	Port 7	_	2.0	_	AV _{CC} + 0.3	V	_
	Ports 1 to 6, 9, P8 ₃ , P8 ₄ , PB ₄	_	2.0	—	V _{CC} + 0.3	V	_
Input low voltage	RES, STBY, MD ₂ to MD ₀	V _{IL}	-0.3	—	0.5	V	
	NMI, EXTAL, ports 1 to 7, 9,	_	-0.3	—	0.8	V	_
Output high voltage	All output pins (except RESO)	V _{OH}	$V_{CC}-0.5$	—		V	I _{OH} = -200 μA
			3.5	—	—	V	$I_{OH} = -1 \text{ mA}$
Output low voltage	All output pins (except RESO)	V _{OL}	_	—	0.4	V	I _{OL} = 1.6 mA
	Ports 1, 2, 5, and B	_	_	_	1.0	V	I _{OL} = 10 mA
	RESO	_		_	0.4	V	I _{OL} = 2.6 mA
Input leakage	<u>STBY</u> , NMI, RES,	I _{IN}	_	_	1.0	μA	V_{IN} = 0.5 to V_{CC} - 0.5 V
current	Port 7		_	_	1.0	μA	V_{IN} = 0.5 to AV _{CC} - 0.5 V

ltem		Symbol	Min	Тур	Max	Unit	Test Conditions
Three-state leakage	Ports 1 to 6, 8 to B	I _{TS1}	_	_	1.0	μA	V_{IN} = 0.5 to V_{CC} - 0.5 V
current (off state)	RESO	_	_	_	10.0	μA	
Input pull-up current	Ports 2, 4, and 5	— _P	50	_	300	μA	V _{IN} = 0 V
Input	NMI	C _{IN}	_	_	50	pF	V _{IN} = 0 V
capacitance	All input pins	_	_	_	15	pF	f = 1 MHz
	except NMI						T _a = 25°C
Current	Normal	I _{CC}	_	50	65	mA	f = 16 MHz
dissipation*2	operation		_	55	75	mA	f = 18 MHz
	Sleep mode	_	_	35	50	mA	f = 16 MHz
			_	40	55	mA	f = 18 MHz
	Module standby mode ^{*4}	-	_	20	25	mA	f = 16 MHz
			_	25	27	mA	f = 18 MHz
	Standby mode ^{*3}	_	_	0.01	5.0	μA	$T_a \leq 50^\circ C$
			_	_	20.0	μA	50°C < T _a
Analog power	During A/D conversion	Al _{CC}	_	1.2	2.0	mA	
supply current	During A/D and D/A conversion	_	_	1.2	2.0	mA	-
	Idle	-	_	0.01	5.0	μA	DASTE = 0
Reference current	During A/D conversion	AI _{CC}	_	0.3	0.6	mA	V _{REF} = 5.0 V
	During A/D and D/A conversion	_	_	1.3	3.0	mA	-
	Idle	_	_	0.01	5.0	μA	DASTE = 0
RAM standby	v voltage	V _{RAM}	2.0	_	_	V	

Notes: 1. If the A/D and D/A converters are not used, do not leave the AV_{CC}, AV_{SS}, and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC}, and connect AV_{SS} to V_{SS}.

2. Current dissipation values are for V_{IHmin} = V_{CC} - 0.5 V and V_{ILmax} = 0.5 V with all output pins unloaded and the on-chip pull-up transistors in the off state.

3. The values are for $V_{RAM} \leq V_{CC}$ < 4.5 V, V_{IHmin} = $V_{CC} \times$ 0.9, and V_{ILmax} = 0.3 V.

4. Module standby current values apply in sleep mode with all modules halted.

Table 22.2DC Characteristics (2)

Conditions: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{AV}_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{V}_{REF} = 2.7 \text{ V to } \text{AV}_{CC},$ $V_{SS} = \text{AV}_{SS} = 0 \text{ V}^{*1}, \text{ T}_{a} = -20^{\circ}\text{C} \text{ to } +75^{\circ}\text{C} \text{ (regular specifications)},$ $T_{a} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C} \text{ (wide-range specifications)}$

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt	Port A,	V _T -	$V_{CC} \times 0.2$	_	_	V	
trigger input voltages	P82 to P80, PB3 to PB0	V _T +	_	_	$V_{CC}\!\times\!0.7$	V	_
voltages		$V_T^+ - V_T^-$	V _{CC} × 0.07	_	—	V	-
Input high voltage	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	VIH	$V_{CC} imes 0.9$	—	V _{CC} + 0.3	V	
	EXTAL	-	$V_{CC} \times 0.7$	_	V _{CC} + 0.3	V	-
	Port 7	-	$V_{CC} \times 0.7$	_	AV _{CC} + 0.3	V	-
	Ports 1 to 6, 9, P8 ₄ , P8 ₃ , PB ₇ to PB ₄	-	$V_{CC} imes 0.7$	_	V _{CC} + 0.3	V	-
Input low voltage	$\overline{\text{RES}}, \overline{\text{STBY}}, \\ \text{MD}_2 \text{ to } \text{MD}_0$	V _{IL}	-0.3	—	$V_{CC} \times 0.1$	V	
	NMI, EXTAL, ports 1 to 7, 9,	-	-0.3	—	$V_{CC} \times 0.2$	V	V _{CC} < 4.0 V
	P8 ₃ , P8 ₄ PB ₄ to PB ₇				0.8	V	V _{CC} = 4.0 V to 5.5 V
Output high	All output pins	V _{OH}	$V_{\text{CC}}-0.5$	_	_	V	I _{OH} = –200 μA
voltage	(except RESO)		V _{CC} – 1.0	_	_	V	I _{ОН} = –1 mA
Output low voltage	All output pins (except RESO)	V _{OL}	—	_	0.4	V	I _{OL} = 1.6 mA
	Ports 1, 2, 5, and B	-	_	_	1.0	V	$\label{eq:V_CC} \begin{array}{l} V_{CC} \leq 4 \ V \\ I_{OL} = 5 \ mA, \\ 4 \ V < V_{CC} \leq 5.5 \ V \\ I_{OL} = 10 \ mA \end{array}$
	RESO	-	_		0.4	V	I _{OL} = 1.6 mA
Input leakage current	$\begin{tabular}{l} \hline \hline STBY, NMI, \\ \hline RES, \\ MD_2 to MD_0 \end{tabular}$	I _{IN}	—	_	1.0	μA	V_{IN} = 0.5 to V_{CC} - 0.5 V
	Port 7	-	_	—	1.0	μA	V_{IN} = 0.5 to AV _{CC} - 0.5 V

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ltem		Symbol	Min	Тур	Max	Unit	Test Conditions
Three-state leakage	Ports 1 to 6, 8 to B	_{TS1}	_		1.0	μA	$V_{IN} = 0.5 \text{ to}$ $V_{CC} - 0.5 \text{ V}$
current (off state)	RESO	-	_	_	10.0	μA	-
Input pull-up current	Ports 2, 4, and 5	— _P	10	—	300	μA	V_{CC} = 2.7 V to 5.5 V, V _{IN} = 0 V
Input	NMI	C _{IN}	_		50	pF	V _{IN} = 0 V
capacitance	All input pins	-	_		15	_	f = 1 MHz
	except NMI						T _a = 25°C
Current dissipation ^{*2}	Normal operation	I _{CC} *4	—	12 (3.0 V)	35 (5.5 V)	mA	f = 8 MHz
			_	20	55	mA	f = 13 MHz
				(3.3 V)	(5.5 V)		(V _{CC} = 3.15 V to 5.5 V)
	Sleep mode	_	—	8	25	mA	f = 8 MHz
				(3.0 V)	(5.5 V)		
			—	12	40 (5.5 V)	mA	f = 13 MHz
				(3.3 V)	(5.5 V)		(V _{CC} = 3.15 V to 5.5 V)
	Module standby mode ^{*5}	-	_	5 (3.0 V)	14 (5.5 V)	mA	f = 8 MHz
			—	7 (3.3 V)	20 (5.5 V)	mA	13 MHz (V _{CC} = 3.15 V to 5.5 V)
	Standby	-	_	0.01	5.0	μA	$T_a \leq 50^\circ C$
	mode ^{*3}		_		20.0	μA	50°C < T _a
Analog	During A/D	Al _{CC}	_	0.4	1.0	mA	AV _{CC} = 3.0 V
power supply	conversion		_	1.2		mA	AV _{CC} = 5.0 V
current	During A/D and	=	_	0.4	1.0	mA	AV _{CC} = 3.0 V
	D/A conversion		_	1.2		mA	AV _{CC} = 5.0 V
	Idle	=	_	0.01	5.0	μA	DASTE = 0
Reference	During A/D	Alcc	_	0.2	0.4	mA	V _{REF} = 3.0 V
current	conversion		_	0.3		mA	V _{REF} = 5.0 V
	During A/D and	_	—	0.8	2.0	mA	V _{REF} = 3.0 V
	D/A conversion		_	1.3	_	mA	V _{REF} = 5.0 V
	Idle	_	_	0.01	5.0	μA	DASTE = 0
RAM standby	voltage	V_{RAM}	2.0			V	

- Notes: 1. If the A/D and D/A converters are not used, do not leave the AV_{CC}, AV_{SS}, and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC}, and connect AV_{SS} to V_{SS}.
 - 2. Current dissipation values are for $V_{IHmin} = V_{CC} 0.5 V$ and $V_{ILmax} = 0.5 V$ with all output pins unloaded and the on-chip pull-up transistors in the off state.
 - 3. The values are for $V_{\text{RAM}} \leq V_{\text{CC}}$ < 2.7 V, V_{IHmin} = $V_{\text{CC}} \times 0.9,$ and V_{ILmax} = 0.3 V.
 - 4. I_{CC} depends on V_{CC} and f as follows: $I_{CCmax} = 3.0 (mA) + 0.75 (mA/MHz \cdot V) \times V_{CC} \times f$ [normal mode] $I_{CCmax} = 3.0 (mA) + 0.55 (mA/MHz \cdot V) \times V_{CC} \times f$ [sleep mode] $I_{CCmax} = 3.0 (mA) + 0.25 (mA/MHz \cdot V) \times V_{CC} \times f$ [module standby mode]
 - 5. Module standby current values apply in sleep mode with all modules halted.

Table 22.4 Permissible Output Currents

Conditions: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications),

 $T_a = -40^{\circ}C$ to $+85^{\circ}C$ (wide-range specifications)

Item		Symbol	Min	Тур	Мах	Unit
Permissible output	Ports 1, 2, 5, and B	I _{OL}		_	10	mA
low current (per pin)	Other output pins		_		2.0	mA
Permissible output low current (total)	Total of 28 pins in ports 1, 2, 5, and B	ΣI_{OL}	_	_	80	mA
	Total of all output pins, including the above		_	_	120	mA
Permissible output high current (per pin)	All output pins	I _{ОН}	_	_	2.0	mA
Permissible output high current (total)	Total of all output pins	ΣI_{OH}	—	—	40	mA

Notes: 1. To protect chip reliability, do not exceed the output current values in table 22.4.

2. When driving a darlington pair or LED, always insert a current-limiting resistor in the output line, as shown in figures 22.1 and 22.2.



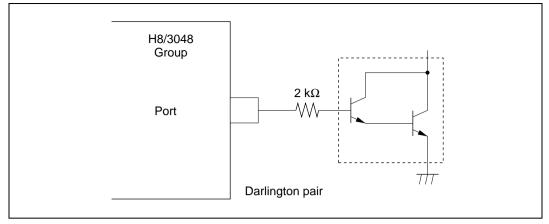


Figure 22.1 Darlington Pair Drive Circuit (Example)

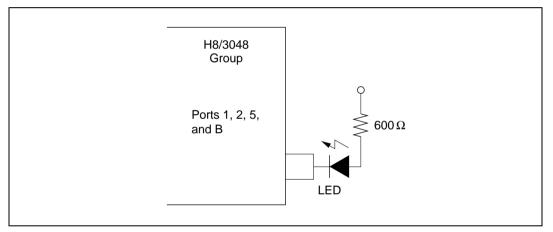


Figure 22.2 LED Drive Circuit (Example)

22.1.3 AC Characteristics

Bus timing parameters are listed in table 22.5. Refresh controller bus timing parameters are listed in table 22.6. Control signal timing parameters are listed in table 22.7. Timing parameters of the on-chip supporting modules are listed in table 22.8.

Table 22.5 Bus Timing

Condition A:	$V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} ,
	$V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 8 MHz, $T_a = -20^{\circ}$ C to $+75^{\circ}$ C (regular
	specifications), $T_a = -40^{\circ}C$ to +85°C (wide-range specifications)

Condition B:	$V_{CC} = 3.15$ V to 5.5 V, $AV_{CC} = 3.15$ V to 5.5 V, $V_{REF} = 3.15$ V to AV_{CC} ,
	$V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 13 MHz, $T_a = -20^{\circ}$ C to $+75^{\circ}$ C (regular
	specifications), $T_a = -40^{\circ}$ C to $+85^{\circ}$ C (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1$ MHz to 18 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

			dition A		dition B			dition C			
		8	MHz	13	13 MHz		16 MHz		18 MHz		Test
Item	Symbol	Min	Max	Min	Мах	Min	Мах	Min	Мах	Unit	Conditions
Clock cycle time	t _{CYC}	125	1000	76.9	1000	62.5	1000	55.5	1000	ns	Figure 22.7,
Clock pulse low width	t _{CL}	40	—	20	—	20	—	17	—	-	Figure 22.8
Clock pulse high width	t _{CH}	40	—	20	_	20	—	17	—	-	
Clock rise time	t _{CR}	_	20	—	15	_	10	—	10	-	
Clock fall time	t _{CF}	_	20	—	15	_	10	—	10	-	
Address delay time	t _{AD}	_	60	—	50		30	_	25	-	
Address hold time	t _{AH}	25	_	20	_	10	_	10	_	-	
Address strobe delay time	t _{ASD}	_	60	_	50	—	30	_	25	-	
Write strobe delay time	t _{WSD}	_	60	_	50		30	_	25	-	
Strobe delay time	t _{SD}	_	60	—	50		30	_	25	-	
Write data strobe pulse width 1	t _{wsw1∗}	85	_	40	_	35	_	32	_	-	
Write data strobe pulse width 2	t _{WSW2*}	150	—	90	—	65	_	62	_	-	
Address setup time 1	t _{AS1}	20	—	15	—	10	—	10	—	-	
Address setup time 2	t _{AS2}	80	—	45	—	40	—	38	—	-	

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			dition A		dition B			dition C			
		8	MHz	13	MHz	16 MHz		18 MHz		-	Test
Item	Symbol	Min	Max	Min	Max	Min	Max	Min	Мах	Unit	Conditions
Read data setup time	t _{RDS}	50	—	30		20	—	15	—	ns	Figure 22.7,
Read data hold time	t _{RDH}	0	—	0		0	_	0	_	-	Figure 22.8
Write data delay time	\mathbf{t}_{WDD}	_	75	—	75	—	60		55	-	
Write data setup time 1	t _{WDS1}	60	—	20		15	_	10	_	-	
Write data setup time 2	t _{WDS2}	5	—	-10		-5	_	-10	_	-	
Write data hold time	\mathbf{t}_{WDH}	25	—	15	—	20	—	20	—	-	
Read data access time 1	t _{ACC1*}	_	120	—	60	_	60	_	50	-	
Read data access time 2	t _{ACC2*}	_	240	—	140	—	120		105	-	
Read data access time 3	t _{ACC3*}	_	70	—	30	—	30		20	-	
Read data access time 4	t _{ACC4*}	_	180	—	100	—	95	_	80	-	
Precharge time	t _{PCH*}	85	—	55		45	_	40	—	-	
Wait setup time	t _{wts}	40	_	40	_	25	_	25	_	ns	Figure 22.9
Wait hold time	t _{wth}	10	—	10	—	5	—	5	—	-	
Bus request setup ime	t _{BRQS}	40	—	40	—	40	—	40	—	ns	Figure 22.21
Bus acknowledge delay time 1	t _{BACD1}	_	60	_	50	_	30	_	30	-	
Bus acknowledge delay time 2	t _{BACD2}	_	60	—	50	—	30	_	30	-	
Bus-floating time	t _{BZD}	_	70		70	—	40		40	-	

Note: * At 8 MHz, the times below depend as indicated on the clock cycle time.

$t_{ACC1} = 1.5 \times t_{CYC} - 68 \text{ (ns)}$	$t_{WSW1} = 1.0 \times t_{CYC} - 40 \text{ (ns)}$
t_{ACC2} = 2.5 $ imes$ t_{CYC} – 73 (ns)	t_{WSW2} = 1.5 \times t_{CYC} – 38 (ns)
t_{ACC3} = 1.0 × t_{CYC} – 55 (ns)	t_{PCH} = 1.0 \times t_{CYC} – 40 (ns)
t_{ACC4} = 2.0 × t_{CYC} – 70 (ns)	

At 13 MHz, the times below depend as indicated on the clock cycle time.

$t_{ACC1} = 1.5 \times t_{CYC} - 56$ (ns)	$t_{WSW1} = 1.0 \times t_{CYC} - 37$ (ns)
$t_{ACC2} = 2.5 \times t_{CYC} - 53$ (ns)	$t_{WSW2} = 1.5 \times t_{CYC} - 26$ (ns)
$t_{ACC3} = 1.0 \times t_{CYC} - 47$ (ns)	t_{PCH} = 1.0 × t_{CYC} – 32 (ns)
t_{ACC4} = 2.0 × t_{CYC} – 54 (ns)	

At 16 MHz, the times below depend as indicated on the clock cycle time.

t_{ACC1} = 1.5 × t_{CYC} – 34 (ns)	t_{WSW1} = 1.0 × t_{CYC} – 28 (ns)
t_{ACC2} = 2.5 × t_{CYC} – 37 (ns)	t_{WSW2} = 1.5 × t_{CYC} – 29 (ns)
t_{ACC3} = 1.0 × t_{CYC} – 33 (ns)	t_{PCH} = 1.0 $ imes$ t_{CYC} – 28 (ns)
$t_{ACC4} = 2.0 \times t_{CYC} - 30$ (ns)	

At 18 MHz, the times below depend as indicated on the clock cycle time.

 $\begin{array}{ll} t_{ACC1} = 1.5 \times t_{CYC} - 34 \ (ns) & t_{WSW1} = 1.0 \times t_{CYC} - 24 \ (ns) \\ t_{ACC2} = 2.5 \times t_{CYC} - 34 \ (ns) & t_{WSW2} = 1.5 \times t_{CYC} - 22 \ (ns) \\ t_{ACC3} = 1.0 \times t_{CYC} - 36 \ (ns) & t_{PCH} = 1.0 \times t_{CYC} - 21 \ (ns) \\ t_{ACC4} = 2.0 \times t_{CYC} - 31 \ (ns) \end{array}$

Table 22.6 Refresh Controller Bus Timing

- Condition A: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 8 MHz, $T_a = -20^{\circ}\text{C}$ to +75°C (regular specifications), $T_a = -40^{\circ}\text{C}$ to +85°C (wide-range specifications)
- Condition B: $V_{CC} = 3.15$ V to 5.5 V, $AV_{CC} = 3.15$ V to 5.5 V, $V_{REF} = 3.15$ V to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 13 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)
- Condition C: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 18 MHz, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)

			dition A		dition B			dition C			
		8 MF	lz	13 M	Hz	16 M	Hz	18 M	Hz	-	Test
Item	Symbol	Min	Мах	Min	Мах	Min	Мах	Min	Мах	Unit	Conditions
RAS delay time 1	t _{RAD1}	_	60	—	50	—	30		30	ns	Figure 22.10
RAS delay time 2	t _{RAD2}	_	60	—	50	—	30		30	_	to Figure 22.16
RAS delay time 3	t _{RAD3}	_	60	—	50	—	30		30	_	1 19410 22.10
Row address hold time*	t _{RAH}	25	—	20		15	_	15	_	_	
RAS precharge time*	t _{RP}	85	—	55		45	_	40	_	_	
CAS to RAS precharge time*	t _{CRP}	85	_	55	_	45	_	40	-	-	
CAS pulse width	t _{CAS}	100	_	55	—	40	—	35	_	-	
RAS access time*	t _{RAC}	_	160	—	80	—	85	_	70	_	
Address access time	t _{AA}	_	105	—	45	—	55		45	_	
CAS access time*	t _{CAC}	_	50	—	30	—	30		25	_	
Write data setup time 3	t _{WDS3}	50	—	20		15	_	10	_	_	
CAS setup time*	t _{CSR}	20	_	10		15	_	10	_	_	
Read strobe delay time	t _{RSD}	_	60	_	50	_	30		30		

Note: * At 8 MHz, the times below depend as indicated on the clock cycle time.

 $t_{RAH} = 0.5 \times t_{CYC} - 38$ (ns)

 $t_{CAC} = 1.0 \times t_{CYC} - 75$ (ns)

 $t_{RAC} = 2.0 \times t_{CYC} - 90$ (ns) $t_{CSR} = 0.5 \times t_{CYC} - 43$ (ns) $t_{RP} = t_{CRP} = 1.0 \times t_{CYC} - 40$ (ns) At 13 MHz, the times below depend as indicated on the clock cycle time. $t_{RAH} = 0.5 \times t_{CYC} - 19$ (ns) $t_{CAC} = 1.0 \times t_{CYC} - 47$ (ns) $t_{RAC} = 2.0 \times t_{CYC} - 74$ (ns) $t_{CSR} = 0.5 \times t_{CYC} - 29$ (ns) $t_{RP} = t_{CRP} = 1.0 \times t_{CYC} - 22$ (ns) At 16 MHz, the times below depend as indicated on the clock cycle time.

 $t_{RAH} = 0.5 \times t_{CYC} - 17$ (ns) $t_{CAC} = 1.0 \times t_{CYC} - 33$ (ns) $t_{RAC} = 2.0 \times t_{CYC} - 40$ (ns) $t_{CSR} = 0.5 \times t_{CYC} - 17$ (ns) $t_{RP} = t_{CRP} = 1.0 \times t_{CYC} - 18$ (ns)

At 18 MHz, the times below depend as indicated on the clock cycle time.

 $t_{RAH} = 0.5 \times t_{CYC} - 13$ (ns) $t_{CAC} = 1.0 \times t_{CYC} - 31$ (ns) $t_{RAC} = 2.0 \times t_{CYC} - 41$ (ns) $t_{CSR} = 0.5 \times t_{CYC} - 18$ (ns) $t_{RP} = t_{CRP} = 1.0 \times t_{CYC} - 16$ (ns)

Table 22.7 Control Signal Timing

Condition A: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 8 MHz, $T_a = -20^{\circ}\text{C}$ to +75°C (regular specifications), $T_a = -40^{\circ}\text{C}$ to +85°C (wide-range specifications)

Condition B: $V_{CC} = 3.15$ V to 5.5 V, $AV_{CC} = 3.15$ V to 5.5 V, $V_{REF} = 3.15$ V to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 13 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1 MHz$ to 18 MHz, $T_a = -20^{\circ}C$ to +75°C (regular specifications), $T_a = -40^{\circ}C$ to +85°C (wide-range specifications)

			dition A		dition B			dition C			
		8 MH	lz	13 M	Hz	16 M	Hz	18 M	Hz	-	Test
Item	Symbol	Min	Max	Min	Мах	Min	Мах	Min	Max	Unit	Conditions
RES setup time	t _{RESS}	200	_	200	_	200	_	200	_	ns	Figure 22.18
RES pulse width	\mathbf{t}_{RESW}	10	_	10		10		10	_	\mathbf{t}_{CYC}	_
Mode programming setup time	t _{MDS}	200	—	200	—	200	_	200	—	ns	-
RESO output delay time	t _{RESD}	—	100	_	100	_	100	_	100	ns	Figure 22.19
RESO output pulse width	\mathbf{t}_{RESOW}	132	—	132	_	132	—	132	—	\mathbf{t}_{CYC}	
NMI setup time (NMI, \overline{IRQ}_5 to \overline{IRQ}_0)	t _{NMIS}	200	_	200	—	150	—	150	—	ns	Figure 22.20
NMI hold time (NMI, IRQ₅ to IRQ₀)	t _{NMIH}	10	—	10	—	10	—	10	—	_	
Interrupt pulse width (NMI, \overline{IRQ}_2 to \overline{IRQ}_0 when exiting software standby mode)	t _{NMIW}	200	_	200	_	200	_	200	_	_	
Clock oscillator settling time at reset (crystal)	t _{osc1}	20	_	20	_	20	_	20	_	ms	Figure 22.22
Clock oscillator settling time in software standby (crystal)	t _{osc2}	7	—	7	_	7	—	7	—	ms	Figure 21.1

Table 22.8 Timing of On-Chip Supporting Modules

- Condition A: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 8 MHz, $T_a = -20^{\circ}\text{C}$ to +75°C (regular specifications), $T_a = -40^{\circ}\text{C}$ to +85°C (wide-range specifications)
- Condition B: $V_{CC} = 3.15$ V to 5.5 V, $AV_{CC} = 3.15$ V to 5.5 V, $V_{REF} = 3.15$ V to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 13 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)
- $\begin{array}{ll} \mbox{Condition C:} & V_{CC} = 5.0 \ V \pm 10\%, \ AV_{CC} = 5.0 \ V \pm 10\%, \ V_{REF} = 4.5 \ V \ to \ AV_{CC}, \\ & V_{SS} = AV_{SS} = 0 \ V, \ \varphi = 1 \ MHz \ to \ 18 \ MHz, \ T_a = -20^{\circ}\ C \ to \ +75^{\circ}\ C \ (regular \ specifications), \ T_a = -40^{\circ}\ C \ to \ +85^{\circ}\ C \ (wide-range \ specifications) \end{array}$

					dition A		dition B			dition C			
				8 M⊦	lz	13 M	IHz	16 M	IHz	18 M	lHz	_	Test
Item			Symbol	Min	Max	Min	Max	Min	Мах	Min	Мах	Unit	Conditions
DMAC	DREQ time	setup	t _{DRQS}	40	-	40	_	30	_	30	—	ns	Figure 22.30
	DREQ time	hold	t _{DRQH}	10	—	10	—	10	—	10	—	_	
	TEND time 1	delay	t_{TED1}	_	100	—	100	—	50		50	_	Figure 22.28, Figure 22.29
	TEND time 2	delay	\mathbf{t}_{TED2}	—	100	—	100	—	50	_	50	_	
ITU	Timer delay t		t _{TOCD}	_	100	—	100	—	100	_	100	ns	Figure 22.24
	Timer setup f		t _{TICS}	50	—	50	_	50	—	50	_	_	
	Timer input s	clock etup time	t _{TCKS}	50	_	50	_	50	—	50	—	_	Figure 22.25
	Timer clock	Single edge	t _{тскwн}	1.5	—	1.5	_	1.5	—	1.5	_	t _{CYC}	_
	pulse width	Both edges	t _{TCKWL}	2.5	—	2.5		2.5	_	2.5	_	_	
SCI	Input clock	Asyn- chronous	t _{scyc}	4	—	4		4		4		$\mathbf{t}_{\mathrm{CYC}}$	Figure 22.26
	cycle	Syn- chronous	t _{scyc}	6	—	6	_	6	_	6	_	_	
	Input c time	lock rise	t _{SCKr}	—	1.5	—	1.5	—	1.5	_	1.5	_	
	Input c time	lock fall	t _{SCKf}	_	1.5	—	1.5	—	1.5	_	1.5	_	
	Input o pulse v		t _{scкw}	0.4	0.6	0.4	0.6	0.4	0.6	0.4	0.6	t _{scyc}	-

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					dition A		dition B			dition C		_	
				8 MH	lz	13 M	Hz	16 M	Hz	18 M	Hz		Test
ltem			Symbol	Min	Max	Min	Max	Min	Max	Min	Мах	Unit	Conditions
SCI	Transmit o delay time		t_{TXD}	_	100	—	100	—	100	—	100	ns	Figure 22.27
	Receive d setup time (synchron)	t _{RXS}	100	—	100	—	100	—	100	-	_	
	Receive data	Clock input	t _{RXH}	100	—	100	_	100	—	100	—		
	hold time (synchro- nous)	Clock output	_	0	—	0	_	0	_	0	_	_	
Ports and	Output da delay time		t _{PWD}	_	100		100	_	100	—	100	ns	Figure 22.23
TPC	Input data setup time		t _{PRS}	50	—	50	—	50	—	50	_	_	
	Input data hold time		t _{PRH}	50	—	50	—	50	_	50		_	

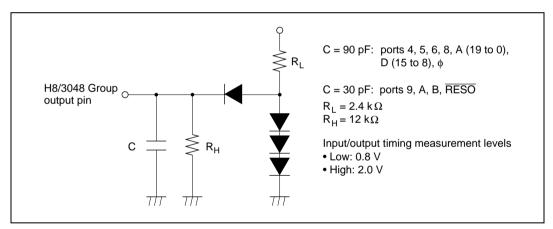


Figure 22.3 Output Load Circuit

22.1.4 A/D Conversion Characteristics

Table 22.9 lists the A/D conversion characteristics.

Table 22.9 A/D Converter Characteristics

- Condition A: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 8 MHz, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)
- Condition B: $V_{CC} = 3.15$ V to 5.5 V, $AV_{CC} = 3.15$ V to 5.5 V, $V_{REF} = 3.15$ V to AV_{CC} , $V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 13 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)
- Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1$ MHz to 18 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

	Co	nditio	n A	Condition B Condition C										
		8 MHz	:		13 MHz			16 MH	z		18 MHz			
Item	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
Resolution	10	10	10	10	10	10	10	10	10	10	10	10	bits	
Conversion time	16.75	—	—	10.31	—	_	8.375	—	_	7.45	—	_	μs	
Analog input capacitance	_	_	20	_	_	20	_	_	20	_	_	20	pF	
Permissible	_	_	10 ^{*1}	_	_	10 ^{*1}	_	_	10 ^{*3}	_	_	10 ^{*3}	kΩ	
signal-source impedance	-	_	5 ^{*2}	—	—	5 ^{*2}	_	—	5 ^{*4}	—	—	5 ^{*4}	-	
Nonlinearity error	—	—	±6.0	_	—	±6.0	_	_	±3.0	_	—	±3.0	LSB	
Offset error	—	—	±4.0	—	—	±4.0	_	—	±2.0	—	—	±2.0	LSB	
Full-scale error	_	_	±4.0	_	_	±4.0	_	_	±2.0	_	_	±2.0	LSB	
Quantization error	—	_	±0.5	_	—	±0.5	_	_	±0.5	—	-	±0.5	LSB	
Absolute accuracy	_	—	±8.0	_	—	±8.0	_	_	±4.0	_	—	±4.0	LSB	

Notes: 1. The value is for $4.0 \le AV_{CC} \le 5.5$.

2. The value is for $2.7 \le AV_{CC} \le 4.0$.

3. The value is for $\phi \leq$ 12 MHz.

4. The value is for $\phi > 12$ MHz.

22.1.5 D/A Conversion Characteristics

Table 22.10 lists the D/A conversion characteristics.

Table 22.10 D/A Converter Characteristics

Condition A:	$V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} ,
	$V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 8 MHz, $T_a = -20^{\circ}$ C to $+75^{\circ}$ C (regular
	specifications), $T_a = -40^{\circ}C$ to +85°C (wide-range specifications)

Condition B: $V_{CC} = 3.15 \text{ V}$ to 5.5 V, $AV_{CC} = 3.15 \text{ V}$ to 5.5 V, $V_{REF} = 3.15 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 13 MHz, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1$ MHz to 18 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

	Condition A			Condition B			Condition C							
		8 MHz		13 MHz		16 MHz		18 MHz			-	Test		
ltem	Min	Тур	Мах	Min	Тур	Мах	Min	Тур	Max	Min	Тур	Мах	Unit	Conditions
Resolution	8	8	8	8	8	8	8	8	8	8	8	8	Bits	
Conversion time	_	_	10	_	_	10	_	_	10	_	—	10	μs	20-pF capacitive load
Absolute accuracy	_	±2.0	±3.0	_	±2.0	±3.0	_	±1.0	±1.5	_	±1.0	±1.5	LSB	2-MΩ resistive load
	_	_	±2.0	_	_	±2.0	_	_	±1.0	_	_	±1.0	LSB	4-MΩ resistive load



22.2 Electrical Characteristics of H8/3048F (Dual-Power Supply)

22.2.1 Absolute Maximum Ratings

Table 22.11 lists the absolute maximum ratings.

Table 22.11	Absolute	Maximum	Ratings
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Item	Symbol	Value	Unit
Power supply voltage	V _{CC}	-0.3 to +7.0	V
Programming voltage	V _{PP}	-0.3 to +13.0	V
Input voltage (except for MD_2 and port 7	Vin	-0.3 to V _{CC} + 0.3	V
Input voltage (MD ₂)	Vin	-0.3 to +13.0	V
Input voltage (port 7)	Vin	-0.3 to AV _{CC} + 0.3	V
Reference voltage	V_{REF}	-0.3 to AV _{CC} + 0.3	V
Analog power supply voltage	AV _{CC}	-0.3 to +7.0	V
Analog input voltage	V _{AN}	-0.3 to AV _{CC} + 0.3	V
Operating temperature	T _{opr}	Regular specifications: -20 to +75	°C
		Wide-range specifications: -40 to +85	°C
Storage temperature	T _{stg}	–55 to +125	°C

Caution: Permanent damage to the chip may result if absolute maximum ratings are exceeded. Particularly, insure that peak overshoot at the V_{PP} and MD2 pins does not exceed 13 V.

22.2.2 DC Characteristics

Table 22.12 lists the DC characteristics. Table 22.13 lists the permissible output currents.

Table 22.12 DC Characteristics (1)

Conditions: $V_{CC} = 5.0 \text{ V} \pm 10\%$, $AV_{CC} = 5.0 \text{ V} \pm 10\%$, $V_{REF} = 4.5 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}^{*1}$, $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ (regular specifications), $T_a = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ (wide-range specifications)

Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt	Port A,	V _T -	1.0	_	_	V	
trigger input voltages	P82 to P80, PB3 to PB0	V _T +	_	_	$V_{CC} \times 0.7$	V	-
	1 03 10 1 00	$V_T{}^+ - V_T{}^-$	0.4	_	_	V	-
Input high voltage	RES, STBY, NMI, MD ₂ to MD ₀	V _{IH}	V _{CC} – 0.7	_	V _{CC} + 0.3	V	
	EXTAL	=	$V_{\text{CC}} \times 0.7$	_	V _{CC} + 0.3	V	-
	Port 7	-	2.0	_	AV _{CC} + 0.3	V	_
	Ports 1 to 6, 9, P8 ₄ , P8 ₃ , PB ₇ to PB ₄	-	2.0	_	V _{CC} + 0.3	V	-
Input low voltage	$\overline{\text{RES}}, \overline{\text{STBY}}, \\ \text{MD}_2 \text{ to } \text{MD}_0$	VIL	-0.3	_	0.5	V	
	NMI, EXTAL, ports 1 to 7, 9, P84, P8 ₃ , PB ₇ to PB ₄	-	-0.3	_	0.8	V	-
Output high	All output pins	V _{OH}	$V_{\text{CC}}-0.5$	_	_	V	I _{OH} = –200 µА
voltage			3.5	_	_	V	I _{OH} = -1 mA
Output low voltage	All output pins (except RESO)	V _{OL}	_	—	0.4	V	I _{OL} = 1.6 mA
	Ports 1, 2, 5, and B	-	_	_	1.0	V	I _{OL} = 10 mA
	RESO	_	_		0.4	V	I _{OL} = 2.6 mA
High voltage (12 V) application criterion level ^{*5}	RESO/V _{PP} MD2	V _H	V _{CC} + 2.0	_	11.4	V	V _{CC} = 4.5 V to 5.5 V

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Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Input leakage	STBY, NMI, RES, MD ₁ , MD ₀	I _{in}	_	—	1.0	μA	V_{in} = 0.5 to V_{CC} – 0.5 V
current	MD ₂	-	_	—	10.0	μA	V _{in} = 0.5 to V _{CC} + 0.5 V
	MD ₂	-	_	—	50.0	μA	V _{in} = V _{CC} + 0.5 to 12.6 V
	Port 7	-	_	—	1.0	μA	V_{in} = 0.5 to AV _{CC} - 0.5 V
Three-state leakage	Ports 1 to 6, 8 to B	I _{TSI}		—	1.0	μA	V_{in} = 0.5 to V_{CC} - 0.5 V
current (off state)	RESO/V _{PP}	-	_	—	20.0	mA	$\begin{array}{l} V_{CC} \text{ to 5 V <} \\ V_{in} \leq 12.6 \text{ V} \end{array}$
			_	—	10.0	μA	$\begin{array}{l} 0.5 \ V \leq V_{in} \leq \\ V_{CC} \ to \ 0.5 \ V \end{array}$
Input pull-up current	Ports 2, 4, and 5	—I P	50	—	300	μA	V _{in} = 0 V
Input capacitance	NMI	Cin	_	_	50	pF	V _{IN} = 0 V
	All input pins	-	_	_	15	pF	f = 1 MHz
	except NMI						T _a = 25°C
Current dissipation*2	Normal operation	Icc	_	50	65	mA	f = 16 MHz
	Sleep mode	-	_	35	50	mA	f = 16 MHz
	Module standby mode ^{*4}	-	_	20	25	mA	f = 16 MHz
	Standby	-		0.01	5.0	μA	$T_a \leq 50^\circ C$
	mode ^{*3}		_	_	20.0	μA	50°C < T _a
Analog power	During A/D conversion	Alcc	—	1.2	2.0	mA	
supply current	During A/D and D/A conversion	-	_	1.2	2.0	mA	-
	Idle	-		0.01	5.0	μA	DASTE = 0
Reference current	During A/D conversion	Alcc	_	0.3	0.6	mA	V _{REF} = 5.0 V
	During A/D and D/A conversion	-	_	1.3	3.0	mA	-
	Idle	-	_	0.01	5.0	μA	DASTE = 0

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Item		Symbol	Min	Тур	Мах	Unit	Test Conditions
V_{PP} pin	Read output	IPP	_		10	μA	V _{PP} = 5.0 V
current			_	10	20	mA	V _{PP} = 12.6 V
	Program execution		_	20	40	mA	-
	Erase		_	20	40	mA	_
RAM stand	dby voltage	V _{RAM}	2.0	—		V	

Notes: 1. If the A/D and D/A converters are not used, do not leave the AV_{CC}, AV_{SS}, and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC}, and connect AV_{SS} to V_{SS}.

2. Current dissipation values are for $V_{IHmin} = V_{CC} - 0.5 V$ and $V_{ILmax} = 0.5 V$ with all output pins unloaded and the on-chip pull-up transistors in the off state.

- 3. The values are for $V_{RAM} \leq V_{CC}$ < 4.5 V, V_{IHmin} = $V_{CC} \times$ 0.9, and V_{ILmax} = 0.3 V.
- 4. Module standby current values apply in sleep mode with all modules halted.
- 5. The high-voltage application criterion level is as shown above. However, in boot mode and during flash memory write and erase it should be set at 12.0 V \pm 0.6 V.



Table 22.12 DC Characteristics (2)

Conditions: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{AV}_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{V}_{REF} = 2.7 \text{ V to } \text{AV}_{CC},$ $V_{SS} = \text{AV}_{SS} = 0 \text{ V}^{*1}, \text{ T}_a = -20^{\circ}\text{C} \text{ to } +75^{\circ}\text{C} \text{ (regular specifications)},$ $T_a = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C} \text{ (wide-range specifications)}$

ltem		Symbol	Min	Тур	Max	Unit	Test Conditions
Schmitt	Port A,	V _T -	$V_{\text{CC}} \times 0.2$	_	_	V	
trigger input voltages	P82 to P80, PB3 to PB0	V _T +	_		$V_{\text{CC}} \times 0.7$	V	-
vollages		$V_T^+ - V_T^-$	V _{CC} × 0.07	_	_	V	-
Input high voltage	$\frac{\text{RES}}{\text{NMI}}, \frac{\text{STBY}}{\text{MD}_2} \text{ to } \text{MD}_0$	VIH	$V_{CC} imes 0.9$	_	V _{CC} + 0.3	V	
	EXTAL	-	$V_{CC} \times 0.7$	—	V _{CC} + 0.3	V	-
	Port 7	-	$V_{CC} \times 0.7$	_	AV _{CC} + 0.3	V	-
	Ports 1 to 6, 9, P8 ₄ , P8 ₃ , PB ₇ to PB ₄	-	$V_{CC} \times 0.7$		V _{CC} + 0.3	V	-
Input low voltage	RES, STBY, MD ₂ to MD ₀	V _{IL}	-0.3	_	$V_{CC} imes 0.1$	V	
	NMI, EXTAL,	-	-0.3	—	$V_{CC} \times 0.2$	V	V _{CC} < 4.0 V
	ports 1 to 7, 9, P8 ₄ , P8 ₃ , PB ₇ to PB ₄				0.8	V	V _{CC} = 4.0 V to 5.5 V
Output high	All output pins	V _{OH}	$V_{\text{CC}}-0.5$	_	_	V	I _{OH} = -200 μA
voltage			V _{CC} – 1.0		_	V	I _{ОН} = –1 mA
Output low voltage	All output pins (except RESO)	V _{OL}	—	_	0.4	V	I _{OL} = 1.6 mA
	Ports 1, 2, 5, and B	-	_	_	1.0	V	$\label{eq:VCC} \begin{array}{l} V_{CC} \leq 4 \ V \\ I_{OL} = 5 \ mA, \\ 4 \ V < V_{CC} \leq 5.5 \ V \\ I_{OL} = 10 \ mA \end{array}$
	RESO	-	_		0.4	V	I _{OL} = 1.6 mA
High voltage (12 V) application criterion level ^{*6}	RESO/V _{PP} MD2	V _H	V _{CC} + 2.0	_	11.4	V	V _{CC} = 2.7 V to 5.5 V

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Item		Symbol	Min	Тур	Max	Unit	Test Conditions
Input leakage	$\frac{\overline{\text{STBY}}, \text{ NMI},}{\overline{\text{RES}}, \text{ MD}_1, \text{ MD}_0}$	I _{in}	_	—	1.0	μA	$V_{in} = 0.5 \text{ to}$ $V_{CC} - 0.5 \text{ V}$
current	MD ₂	-	—	—	10.0	μA	$V_{in} = 0.5 \text{ to}$ $V_{CC} + 0.5 \text{ V}$
	MD ₂	-	_	_	50.0	μA	V _{in} = V _{CC} + 0.5 to 12.6 V
	Port 7	-	_	_	1.0	μA	V_{in} = 0.5 to AV _{CC} - 0.5 V
Three-state leakage	Ports 1 to 6, 8 to B	I _{TSI}	_	_	1.0	μA	V_{in} = 0.5 to V_{CC} - 0.5 V
current (off state)	RESO/V _{PP}	-	_	_	20.0	mA	$V_{CC} + 0.5 < V_{in}$ ≤ 12.6
			_	—	10.0	μA	$\begin{array}{l} 0.5 \leq V_{in} \leq V_{CC} \\ \textbf{+0.5V} \end{array}$
Input pull-up current	Ports 2, 4, and 5	–I P	10	_	300	μA	V_{CC} = 2.7 V to 5.5 V, V _{in} = 0 V
Input capacitance	NMI	C _{in}	_	_	50	pF	V _{in} = 0 V
	All input pins except NMI	-	_	_	15		f = 1 MHz T _a = 25°C
Current dissipation*2	Normal operation	I _{CC} *4		12 (3.0 V)	35 (5.5 V)	mA	f = 8 MHz
	Sleep mode	-	_	8 (3.0 V)	25 (5.5 V)	mA	f = 8 MHz
	Module standby mode ^{*5}	-	_	5 (3.0 V)	14 (5.5 V)	mA	f = 8 MHz
	Standby	-	_	0.01	5.0	μA	$T_a \leq 50^\circ C$
	mode ^{*3}		_	_	20.0	μA	50°C < T _a
Analog	During A/D	Al _{CC}	_	0.4	1.0	mA	AV_{CC} = 3.0 V
power supply	conversion		_	1.2		mA	AV_{CC} = 5.0 V
current	During A/D and	-	_	0.4	1.0	mA	AV _{CC} = 3.0 V
	D/A conversion		_	1.2		mA	AV_{CC} = 5.0 V
	Idle	-	_	0.01	5.0	μA	DASTE = 0
Reference	During A/D	Alcc	_	0.2	0.4	mA	V _{REF} = 3.0 V
current	conversion			0.3	_	mA	V _{REF} = 5.0 V
	During A/D and	-		0.8	2.0	mA	V _{REF} = 3.0 V
	D/A conversion			1.3	_	mA	V _{REF} = 5.0 V
	Idle	<u>-</u> .		0.01	5.0	μA	DASTE = 0

Item		Symbol	Min	Тур	Мах	Unit	Test Conditions
V _{PP} pin Read output current	Read output	I _{PP}	_	—	10	μA	V _{PP} = 5.0 V
			_	10	20	mA	_
	Program execution		_	20	40	mA	V _{PP} = 12.6 V
	Erase		_	20	40	mA	_
RAM stand	dby voltage	VRAM	2.0	—	_	V	

Notes: 1. If the A/D and D/A converters are not used, do not leave the AV_{CC}, AV_{SS}, and V_{REF} pins open. Connect AV_{CC} and V_{REF} to V_{CC}, and connect AV_{SS} to V_{SS}.

- 3. The values are for $V_{RAM} \leq V_{CC}$ < 2.7 V, V_{IHmin} = $V_{CC} \times$ 0.9, and V_{ILmax} = 0.3 V.
- 4. I_{CC} depends on V_{CC} and f as follows: $I_{CCmax} = 3.0 \text{ (mA)} + 0.75 \text{ (mA/MHz · V)} \times V_{CC} \times f$ [normal mode] $I_{CCmax} = 3.0 \text{ (mA)} + 0.55 \text{ (mA/MHz · V)} \times V_{CC} \times f$ [sleep mode] $I_{CCmax} = 3.0 \text{ (mA)} + 0.25 \text{ (mA/MHz · V)} \times V_{CC} \times f$ [module standby mode]
- 5. Module standby current values apply in sleep mode with all modules halted.
- 6. The high-voltage application criterion level is as shown above. However, in boot mode and during flash memory write and erase it should be set at $12.0 \text{ V} \pm 0.6 \text{ V}$.

Table 22.13 Permissible Output Currents

Conditions: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} ,

 $V_{SS} = AV_{SS} = 0$ V, $T_a = -20^{\circ}$ C to +75°C (regular specifications),

 $T_a = -40^{\circ}C$ to $+85^{\circ}C$ (wide-range specifications)

Item		Symbol	Min	Тур	Мах	Unit
Permissible output low current (per pin)	Ports 1, 2, 5, and B	I _{OL}	_		10	mA
	Other output pins		_		2.0	mA
Permissible output low current (total)			_	_	80	mA
	Total of all output pins, including the above		_	_	120	mA
Permissible output high current (per pin)	All output pins	I _{ОН}	—	_	2.0	mA
Permissible output high current (total)	Total of all output pins	ΣI_{OH}	_	_	40	mA

Notes: 1. To protect chip reliability, do not exceed the output current values in table 22.13.

2. When driving a darlington pair or LED, always insert a current-limiting resistor in the output line, as shown in figures 22.4 and 22.5.

^{2.} Current dissipation values are for V_{IHmin} = V_{CC} - 0.5 V and V_{ILmax} = 0.5 V with all output pins unloaded and the on-chip pull-up transistors in the off state.

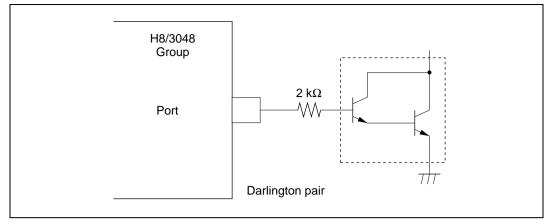


Figure 22.4 Darlington Pair Drive Circuit (Example)

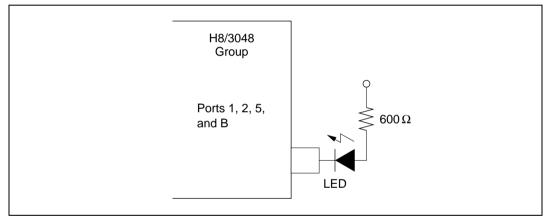


Figure 22.5 LED Drive Circuit (Example)



22.2.3 AC Characteristics

Bus timing parameters are listed in table 22.14. Refresh controller bus timing parameters are listed in table 22.15. Control signal timing parameters are listed in table 22.16. Timing parameters of the on-chip supporting modules are listed in table 22.17.

Table 22.14 Bus Timing

Condition A:	$V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} ,
	$V_{SS} = AV_{SS} = 0$ V, $\phi = 1$ MHz to 8 MHz, $T_a = -20^{\circ}$ C to $+75^{\circ}$ C (regular
	specifications), $T_a = -40^{\circ}C$ to $+85^{\circ}C$ (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1 MHz$ to 16 MHz, $T_a = -20^{\circ}C$ to +75°C (regular specifications), $T_a = -40^{\circ}C$ to +85°C (wide-range specifications)

		Condition A 8 MHz		Condition C				
				1	16 MHz		Test	
Item	Symbol	Min	Max	Min	Max	Unit	Conditions	
Clock cycle time	t _{CYC}	125	1000	62.5	1000	ns	Figure 22.7,	
Clock pulse low width	t _{CL}	40		20	_		Figure 22.8	
Clock pulse high width	t _{сн}	40		20	_			
Clock rise time	t _{CR}	_	20		10			
Clock fall time	t _{CF}	_	20		10			
Address delay time	t _{AD}	_	60		30			
Address hold time	t _{AH}	25	_	10	_			
Address strobe delay time	t _{ASD}	_	60	_	30			
Write strobe delay time	t _{WSD}	_	60	_	30			
Strobe delay time	t _{sD}	_	60		30	_		
Write data strobe pulse width 1	t _{wsw1*}	85		35				
Write data strobe pulse width 2	t _{wsw2*}	150		65	_			
Address setup time 1	t _{AS1}	20		10	_	_		
Address setup time 2	t _{AS2}	80	_	40	_	_		
Read data setup time	t _{RDS}	50	_	20	_	_		
Read data hold time	t _{RDH}	0	_	0	_			

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		Cor	ndition A	Cor	ndition C		
		8	8 MHz 16 MHz		_	Test	
Item	Symbol	Min	Max	Min	Max	Unit	Conditions
Write data delay time	t _{WDD}	_	75	_	60	ns	Figure 22.7,
Write data setup time 1	t _{WDS1}	60	_	15			Figure 22.8
Write data setup time 2	t _{WDS2}	5	_	-5			
Write data hold time	t _{WDH}	25	_	20			
Read data access time 1	t _{ACC1*}	_	120	_	60		
Read data access time 2	t _{ACC2*}	_	240	_	120		
Read data access time 3	t _{ACC3*}	_	70	_	30		
Read data access time 4	t _{ACC4*}	_	180	_	95		
Precharge time	t _{PCH*}	85	_	45		_	
Wait setup time	t _{wts}	40	_	25		ns	Figure 22.9
Wait hold time	t _{WTH}	10	_	5			
Bus request setup time	t _{BRQS}	40	_	40		ns	Figure 22.21
Bus acknowledge delay time 1	t _{BACD1}	_	60	_	30		
Bus acknowledge delay time 2	t _{BACD2}	_	60	_	30	_	
Bus-floating time	t _{BZD}	—	70	_	40	_	

Note: * At 8 MHz, the times below depend as indicated on the clock cycle time.

$$\begin{split} t_{ACC1} &= 1.5 \times t_{CYC} - 68 \; (ns) \\ t_{ACC2} &= 2.5 \times t_{CYC} - 73 \; (ns) \\ t_{ACC3} &= 1.0 \times t_{CYC} - 55 \; (ns) \\ t_{ACC4} &= 2.0 \times t_{CYC} - 70 \; (ns) \end{split}$$

 $t_{WSW1} = 1.0 \times t_{CYC} - 40 \text{ (ns)}$ $t_{WSW2} = 1.5 \times t_{CYC} - 38 \text{ (ns)}$ $t_{PCH} = 1.0 \times t_{CYC} - 40 \text{ (ns)}$

At 16 MHz, the times below depend as indicated on the clock cycle time.

t_{ACC1} = 1.5 × t_{CYC} – 34 (ns)	t_{WSW1} = 1.0 \times t_{CYC} – 28 (ns)
t_{ACC2} = 2.5 × t_{CYC} – 37 (ns)	t_{WSW2} = 1.5 \times t_{CYC} – 29 (ns)
t_{ACC3} = 1.0 × t_{CYC} – 33 (ns)	t_{PCH} = 1.0 \times t_{CYC} – 28 (ns)
t_{ACC4} = 2.0 × t_{CYC} – 30 (ns)	

Table 22.15 Refresh Controller Bus Timing

Condition A: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 8 MHz, $T_a = -20^{\circ}\text{C}$ to +75°C (regular specifications), $T_a = -40^{\circ}\text{C}$ to +85°C (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1$ MHz to 16 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

		Condition A		Cor	Condition C			
			3 MHz	1	16 MHz		Test	
Item	Symbol	Min	Max	Min	Max	Unit	Conditions	
RAS delay time 1	t _{RAD1}	_	60	_	30	ns	Figure 22.10	
RAS delay time 2	t _{RAD2}	_	60	—	30		to Figure 22.16	
RAS delay time 3	t _{RAD3}	_	60	—	30			
Row address hold time*	t _{RAH}	25		15	_			
RAS precharge time*	t _{RP}	85		45				
CAS to RAS precharge time*	t _{CRP}	85		45	_			
CAS pulse width	t _{CAS}	100	_	40	—			
RAS access time*	t _{RAC}	_	160	_	85			
Address access time	t _{AA}	_	105	_	55			
CAS access time*	t _{CAC}	_	50	_	30			
Write data setup time 3	t _{WDS3}	50	_	15	—			
CAS setup time*	t _{CSR}	20		15				
Read strobe delay time	t _{RSD}	_	60	_	30			

Note: * At 8 MHz, the times below depend as indicated on the clock cycle time.

 $\begin{array}{ll} t_{\text{RAH}} = 0.5 \times t_{\text{CYC}} - 38 \ (\text{ns}) & t_{\text{CAC}} = 1.0 \times t_{\text{CYC}} - 75 \ (\text{ns}) \\ t_{\text{RAC}} = 2.0 \times t_{\text{CYC}} - 90 \ (\text{ns}) & t_{\text{CSR}} = 0.5 \times t_{\text{CYC}} - 43 \ (\text{ns}) \\ t_{\text{RP}} = t_{\text{CRP}} = 1.0 \times t_{\text{CYC}} - 40 \ (\text{ns}) \end{array}$

At 16 MHz, the times below depend as indicated on the clock cycle time.

$$\begin{split} t_{\text{RAH}} &= 0.5 \times t_{\text{CYC}} - 17 \text{ (ns)} \\ t_{\text{RAC}} &= 2.0 \times t_{\text{CYC}} - 40 \text{ (ns)} \\ t_{\text{CRC}} &= 1.0 \times t_{\text{CYC}} - 33 \text{ (ns)} \\ t_{\text{CSR}} &= 0.5 \times t_{\text{CYC}} - 17 \text{ (ns)} \\ t_{\text{RP}} &= t_{\text{CRP}} = 1.0 \times t_{\text{CYC}} - 18 \text{ (ns)} \end{split}$$

Table 22.16 Control Signal Timing

Condition A: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 8 MHz, $T_a = -20^{\circ}\text{C}$ to +75°C (regular specifications), $T_a = -40^{\circ}\text{C}$ to +85°C (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1$ MHz to 16 MHz, $T_a = -20^{\circ}$ C to $+75^{\circ}$ C (regular specifications), $T_a = -40^{\circ}$ C to $+85^{\circ}$ C (wide-range specifications)

		Condition A		Condition C			
		8	3 MHz	1	6 MHz	_	
Item	Symbol	Min	Мах	Min	Мах	Unit	Test Conditions
RES setup time	t _{RESS}	200		200	_	ns	Figure 22.18
RES pulse width	t _{RESW}	10		10	_	t _{CYC}	
Mode programming setup time	t _{MDS}	200		200	_	ns	
RESO output delay time	t _{RESD}	_	100	_	100	ns	Figure 22.19
RESO output pulse width	t _{RESOW}	132		132	_	t _{CYC}	
NMI setup time (NMI, \overline{IRQ}_5 to \overline{IRQ}_0)	t _{NMIS}	200	_	150	_	ns	Figure 22.20
NMI hold time (NMI, \overline{IRQ}_5 to \overline{IRQ}_0)	t _{NMIH}	10	—	10	—		
Interrupt pulse width (NMI, \overline{IRQ}_2 to \overline{IRQ}_0 when exiting software standby mode)	t _{NMIW}	200	_	200	_		
Clock oscillator settling time at reset (crystal)	t _{osc1}	20	—	20	—	ms	Figure 22.22
Clock oscillator settling time in software standby (crystal)	t _{osc2}	7	_	7	_	ms	Figure 21.1

Table 22.17 Timing of On-Chip Supporting Modules

Condition A: $V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 \text{ V}$, $\phi = 1 \text{ MHz}$ to 8 MHz, $T_a = -20^{\circ}\text{C}$ to +75°C (regular specifications), $T_a = -40^{\circ}\text{C}$ to +85°C (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1$ MHz to 16 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

				Con	dition A	Con	dition C		
				8	MHz	16	6 MHz	_	Test
Item			Symbol	Min	Мах	Min	Мах	Unit	Conditions
DMAC	DREQ setup	time	t _{DRQS}	40	_	30	_	ns	Figure 22.30
	DREQ hold t	ime	t _{DRQH}	10		10	_	_	
	TEND delay	time 1	t _{TED1}	—	100	_	50		Figure 22.28
	TEND delay	time 2	t _{TED2}	—	100		50		Figure 22.29
ITU	Timer output	delay time	t _{TOCD}	_	100	_	100	ns	Figure 22.24
	Timer input s	setup time	t _{TICS}	50	_	50	_	_	
	Timer clock i	input setup time	t _{TCKS}	50	_	50	_	_	Figure 22.25
	Timer clock	Single edge	t _{тскwн}	1.5	_	1.5	_	t _{CYC}	
	pulse width	Both edges	t _{TCKWL}	2.5	_	2.5	_	_	
SCI	Input clock	Asynchronous	t _{scyc}	4	_	4	_	t _{CYC}	Figure 22.26
	cycle	Synchronous	t _{scyc}	6	—	6	—	_	
	Input clock ri	ise time	t _{SCKr}	—	1.5	—	1.5	_	
	Input clock fa	all time	t _{SCKf}	—	1.5	—	1.5		
	Input clock p	ulse width	t _{scкw}	0.4	0.6	0.4	0.6	t _{scyc}	
SCI	Transmit dat	a delay time	t _{TXD}	—	100	—	100	ns	Figure 22.27
	Receive data (synchronou	•	t _{RXS}	100	_	100	—		
	Receive data hold	Clock input	t _{RXH}	100	—	100	_		
	time (syn- chronous)	Clock output	t _{RXH}	0		0	_	_	
Ports	Output data	delay time	t _{PWD}	—	100	—	100	ns	Figure 22.23
and TPC	Input data se	etup time	t _{PRS}	50		50			
	Input data ho	old time	t _{PRH}	50	_	50	_	_	

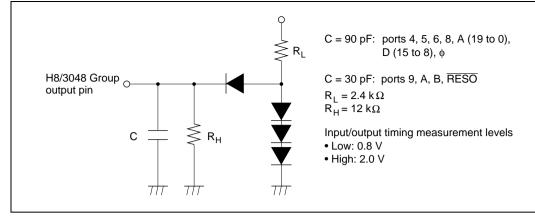


Figure 22.6 Output Load Circuit



22.2.4 A/D Conversion Characteristics

Table 22.18 lists the A/D conversion characteristics.

Table 22.18 A/D Converter Characteristics

- Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{AV}_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{V}_{REF} = 2.7 \text{ V to } \text{AV}_{CC},$ $V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \phi = 1 \text{ MHz to } 8 \text{ MHz}, \text{T}_a = -20^{\circ}\text{C} \text{ to } +75^{\circ}\text{C} \text{ (regular specifications)}, \text{T}_a = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C} \text{ (wide-range specifications)}$
- Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1 MHz$ to 16 MHz, $T_a = -20^{\circ}C$ to $+75^{\circ}C$ (regular specifications), $T_a = -40^{\circ}C$ to $+85^{\circ}C$ (wide-range specifications)

		Conditio	on A				
		8 MH	Z		16 MH	Iz	
Item	Min	Тур	Мах	Min	Тур	Мах	Unit
Resolution	10	10	10	10	10	10	bits
Conversion time	16.75	_	_	8.375	_	_	μs
Analog input capacitance		_	20	_	_	20	pF
Permissible signal-source		_	10 ^{*1}	_	_	10 ^{*3}	kΩ
impedance	_	_	5 ^{*2}	_	_	5 ^{*4}	
Nonlinearity error		_	±6.0	_	_	±3.0	LSB
Offset error		_	±4.0	_	_	±2.0	LSB
Full-scale error		_	±4.0	_	_	±2.0	LSB
Quantization error	_	_	±0.5	_	_	±0.5	LSB
Absolute accuracy		_	±8.0	_	_	±4.0	LSB

Notes: 1. The value is for $4.0 \le AV_{CC} \le 5.5$.

2. The value is for $2.7 \le AV_{CC} < 4.0$.

3. The value is for $\phi \leq$ 12 MHz.

4. The value is for $\phi > 12$ MHz.

22.2.5 D/A Conversion Characteristics

Table 22.19 lists the D/A conversion characteristics.

Table 22.19 D/A Converter Characteristics

Condition A: $V_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{ AV}_{CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{ V}_{REF} = 2.7 \text{ V to } \text{AV}_{CC},$ $V_{SS} = \text{AV}_{SS} = 0 \text{ V}, \phi = 1 \text{ MHz to } 8 \text{ MHz}, \text{ T}_a = -20^{\circ}\text{C} \text{ to } +75^{\circ}\text{C} \text{ (regular specifications)}, \text{ T}_a = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C} \text{ (wide-range specifications)}$

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $\phi = 1$ MHz to 16 MHz, $T_a = -20^{\circ}$ C to +75°C (regular specifications), $T_a = -40^{\circ}$ C to +85°C (wide-range specifications)

		Conditio	on A		Conditio	on C		
		8 MH:	z		16 MH	lz	_	
Item	Min	Тур	Мах	Min	Тур	Max	Unit	Test Conditions
Resolution	8	8	8	8	8	8	Bits	
Conversion time	—	_	10	_	_	10	μs	20-pF capacitive load
Absolute accuracy	—	±2.0	±3.0	_	±1.0	±1.5	LSB	2-M Ω resistive load
	_	_	±2.0	_	—	±1.0	LSB	4-M Ω resistive load



22.2.6 Flash Memory Characteristics

Table 22.20 lists the flash memory characteristics.

Table 22.20 Flash Memory

Condition A:	$V_{CC} = 2.7 \text{ V}$ to 5.5 V, $AV_{CC} = 2.7 \text{ V}$ to 5.5 V, $V_{REF} = 2.7 \text{ V}$ to AV_{CC} ,
	$V_{SS} = AV_{SS} = 0$ V, $V_{PP} = 12$ V ± 0.6 V, $\phi = 1$ MHz to 8 MHz, $T_a = -20^{\circ}$ C to $+75^{\circ}$ C
	(regular specifications), $T_a = -40^{\circ}C$ to $+85^{\circ}C$ (wide-range specifications)

Condition C: $V_{CC} = 5.0 V \pm 10\%$, $AV_{CC} = 5.0 V \pm 10\%$, $V_{REF} = 4.5 V$ to AV_{CC} , $V_{SS} = AV_{SS} = 0 V$, $V_{PP} = 12 V \pm 0.6 V$, $\phi = 1$ MHz to 16 MHz, $T_a = -20^{\circ}C$ to $+75^{\circ}C$ (regular specifications), $T_a = -40^{\circ}C$ to $+85^{\circ}C$ (wide-range specifications)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Programming time*1	t _P	_	50	1000	μs	
Erase time ^{*1}	t⊨	_	1	30	S	
Erase-program cycle	N _{WEC}	_		100	time	
Verify setup time 1*1	t _{VS1}	4	—	_	μs	
Verify setup time 2*1	t _{VS2}	2		_	μs	
Flash memory read	t _{FRS}	50		_	μs	$V_{CC} \geq 4.5 \ V$
setup time*2		100	_	_	μs	V _{CC} < 4.5 V

Notes: 1. To specify each time, follow the appropriate algorithm.

2. Before reading the flash memory, wait at least for the read setup time after clearing the $V_{PP}E$ bit; lowering the voltage supplied to V_{PP} from 12 V to 0–5 V; turning on the power when the external clock is used; or returning from standby mode. When the V_{PP} voltage is cut off, t_{FRS} indicates the time from when the V_{PP} falls below V_{CC} + 2 V to when the flash memory is read.

22.3 Operational Timing

This section shows timing diagrams.

22.3.1 Bus Timing

Bus timing is shown as follows:

- Basic bus cycle: two-state access Figure 22.7 shows the timing of the external two-state access cycle.
- Basic bus cycle: three-state access Figure 22.8 shows the timing of the external three-state access cycle.
- Basic bus cycle: three-state access with one wait state Figure 22.9 shows the timing of the external three-state access cycle with one wait state inserted.



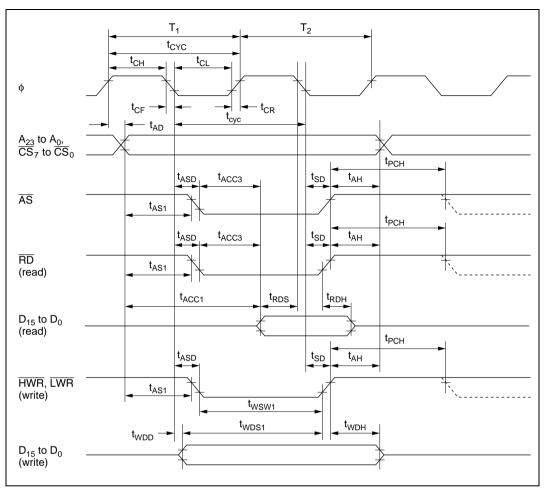


Figure 22.7 Basic Bus Cycle: Two-State Access



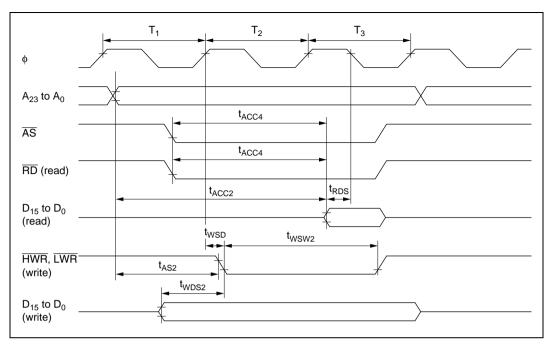


Figure 22.8 Basic Bus Cycle: Three-State Access



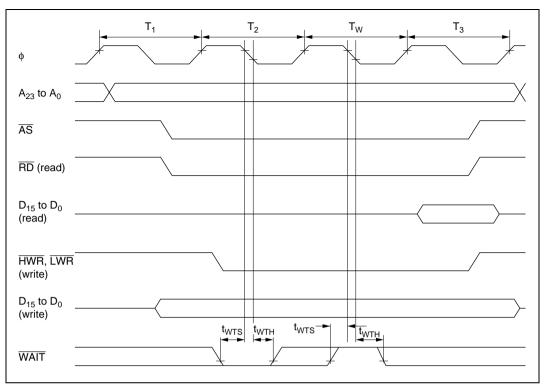


Figure 22.9 Basic Bus Cycle: Three-State Access with One Wait State



22.3.2 Refresh Controller Bus Timing

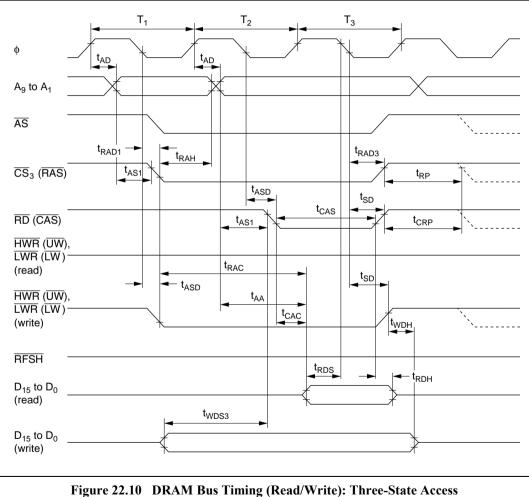
Refresh controller bus timing is shown as follows:

• DRAM bus timing

Figures 22.10 to 22.15 show the DRAM bus timing in each operating mode.

• PSRAM bus timing

Figures 22.16 and 22.17 show the pseudo-static RAM bus timing in each operating mode.



- 2 WE Mode -

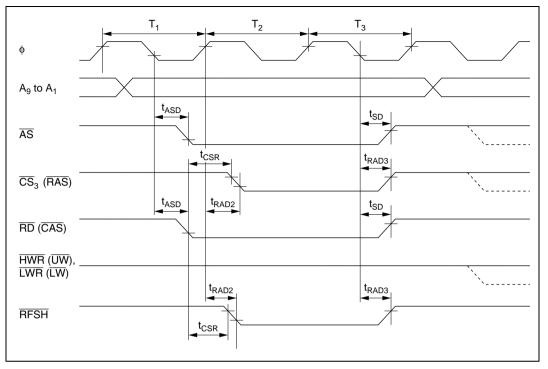


Figure 22.11 DRAM Bus Timing (Refresh Cycle): Three-State Access — 2WE Mode —

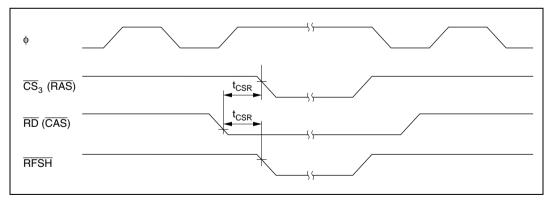


Figure 22.12 DRAM Bus Timing (Self-Refresh Mode) — 2WE Mode —

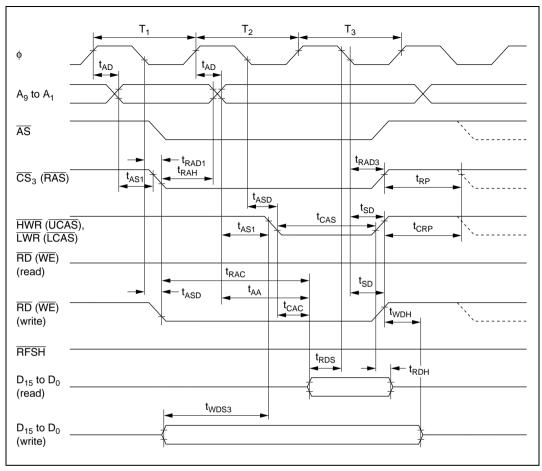


Figure 22.13 DRAM Bus Timing (Read/Write): Three-State Access — 2CAS Mode —



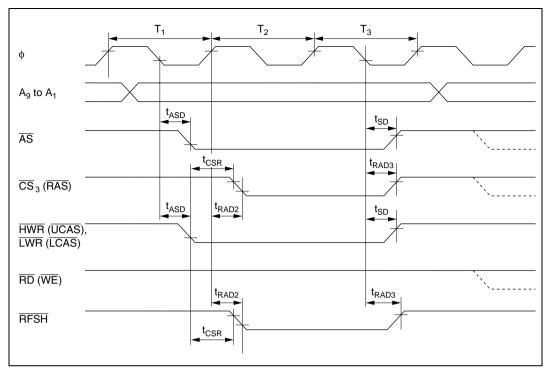


Figure 22.14 DRAM Bus Timing (Refresh Cycle): Three-State Access — 2CAS Mode —

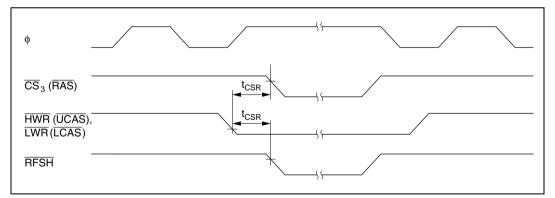


Figure 22.15 DRAM Bus Timing (Self-Refresh Mode) — 2CAS Mode —



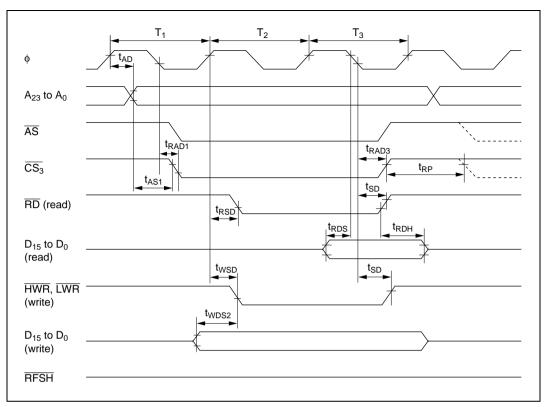


Figure 22.16 PSRAM Bus Timing (Read/Write): Three-State Access

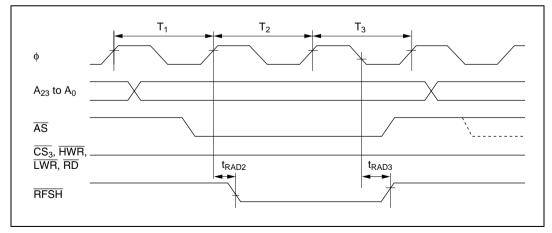


Figure 22.17 PSRAM Bus Timing (Refresh Cycle): Three-State Access

22.3.3 Control Signal Timing

Control signal timing is shown as follows:

• Reset input timing

Figure 22.18 shows the reset input timing.

- Reset output timing Figure 22.19 shows the reset output timing.
- Interrupt input timing Figure 22.20 shows the input timing for NMI and IRQ₅ to IRQ₀.
- Bus-release mode timing

Figure 22.21 shows the bus-release mode timing.

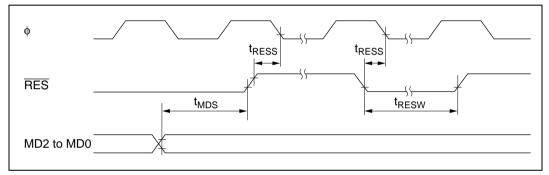


Figure 22.18 Reset Input Timing

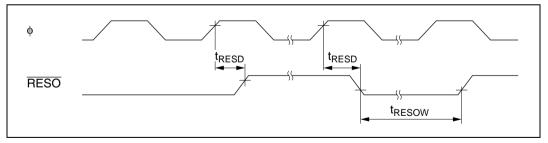
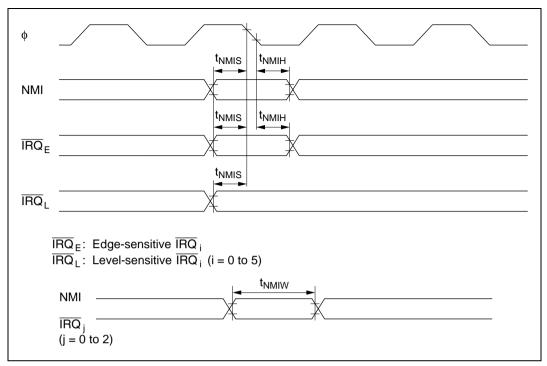
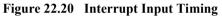


Figure 22.19 Reset Output Timing*

Note: * This is a function for models with on-chip mask ROM (H8/3048, H8/3047, H8/3045, and H8/3044), PROM (H8/3048ZTAT), and on-chip flash memory with a dual power supply (H8/3048F). The function does not exist in the product with on-chip flash memory with a single power supply (H8/3048F-ONE).





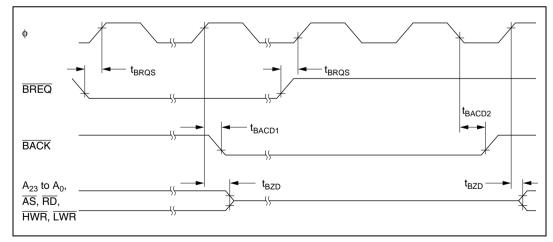


Figure 22.21 Bus-Release Mode Timing

22.3.4 Clock Timing

Clock timing is shown as follows:

• Oscillator settling timing

Figure 22.22 shows the oscillator settling timing.

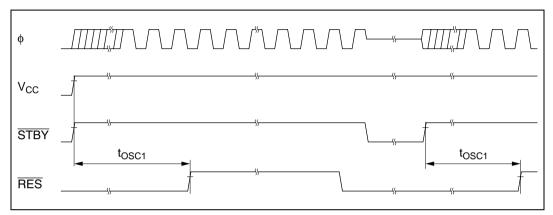


Figure 22.22 Oscillator Settling Timing

22.3.5 TPC and I/O Port Timing

Figure 22.23 shows the TPC and I/O port timing.

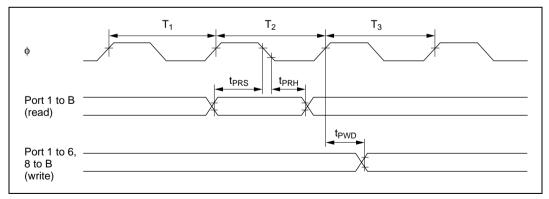
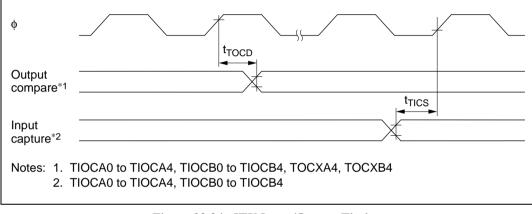


Figure 22.23 TPC and I/O Port Input/Output Timing

22.3.6 ITU Timing

ITU timing is shown as follows:

- ITU input/output timing Figure 22.24 shows the ITU input/output timing.
- ITU external clock input timing Figure 22.25 shows the ITU external clock input timing.





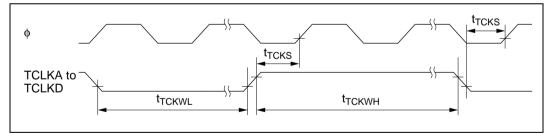


Figure 22.25 ITU External Clock Input Timing

22.3.7 SCI Input/Output Timing

SCI timing is shown as follows:

- SCI input clock timing Figure 22.26 shows the SCK input clock timing.
- SCI input/output timing (synchronous mode) Figure 22.27 shows the SCI input/output timing in synchronous mode.

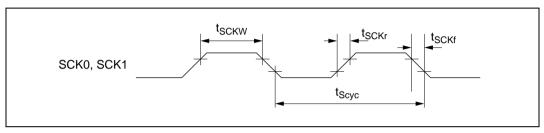


Figure 22.26 SCK Input Clock Timing

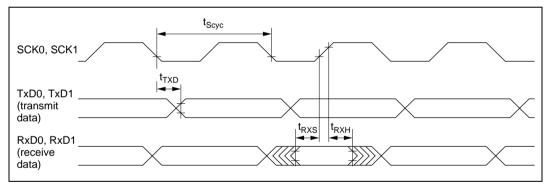


Figure 22.27 SCI Input/Output Timing in Synchronous Mode

22.3.8 DMAC Timing

DMAC timing is shown as follows.

- DMAC TEND output timing for 2 state access Figure 22.28 shows the DMAC TEND output timing for 2 state access.
- DMAC TEND output timing for 3 state access
 Figure 22.29 shows the DMAC TEND output timing for 3 state access.
- DMAC DREQ input timing Figure 22.30 shows DMAC DREQ input timing.

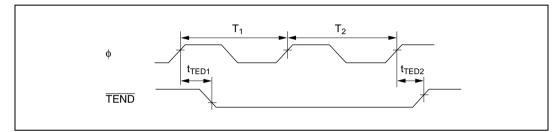


Figure 22.28 DMAC TEND Output Timing for 2 State Access

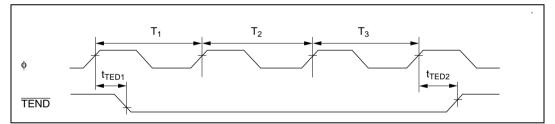


Figure 22.29 DMAC TEND Output Timing for 3 State Access

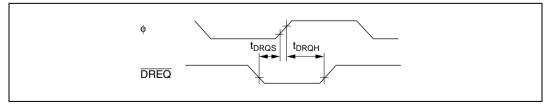


Figure 22.30 DMAC DREQ Input Timing

Appendix A Instruction Set

A.1 Instruction List

Operand Notation

Symbol	Description
Rd	General destination register
Rs	General source register
Rn	General register
ERd	General destination register (address register or 32-bit register)
ERs	General source register (address register or 32-bit register)
ERn	General register (32-bit register)
(EAd)	Destination operand
(EAs)	Source operand
PC	Program counter
SP	Stack pointer
CCR	Condition code register
Ν	N (negative) flag in CCR
Z	Z (zero) flag in CCR
V	V (overflow) flag in CCR
С	C (carry) flag in CCR
disp	Displacement
\rightarrow	Transfer from the operand on the left to the operand on the right, or transition from the state on the left to the state on the right
+	Addition of the operands on both sides
-	Subtraction of the operand on the right from the operand on the left
X	Multiplication of the operands on both sides
÷	Division of the operand on the left by the operand on the right
^	Logical AND of the operands on both sides
V	Logical OR of the operands on both sides
\oplus	Exclusive logical OR of the operands on both sides
٦	NOT (logical complement)
(), < >	Contents of operand
	ral registers include 8-bit registers (R0H to R7H and R0L to R7L) and 16-bit registers R7 and E0 to E7).

Condition Code Notation

Symbol	Description
\updownarrow	Changed according to execution result
*	Undetermined (no guaranteed value)
0	Cleared to 0
1	Set to 1
_	Not affected by execution of the instruction
Δ	Varies depending on conditions, described in notes



Table A.1Instruction Set

1. Data transfer instructions

		Addressing Mode and Instruction Length (bytes)																			
Mnemonic	Operand Size	Operation	#xx	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@ aa	@(d, PC)	0 0 aa		1	Con	ditio	n Co	v	с	Normal	Advanced		
MOV.B #xx:8, Rd	-	#xx:8 → Rd8	+ F	-	•	•					-	-	-	N ↓	2 1	0		~			
MOV.B Rs, Rd	В	$Rs8 \rightarrow Rd8$	-	2								_	_	↓	1	0	_	2			
MOV.B @ERs, Rd	В	$@ERs \rightarrow Rd8$		-	2							_	_	↓	1	0	_				
MOV.B @(d:16, ERs), Rd	В	$@(d:16, ERs) \rightarrow Rd8$				4						_	_	↓	1	0	_	E	}		
MOV.B @(d:24, ERs), Rd	В	$@(d:24, ERs) \rightarrow Rd8$				8						_	_	\$	1	0	_	1	0		
MOV.B @ERs+, Rd	В	@ERs → Rd8 ERs32+1 → ERs32					2					—	—	\$	\$	0	—	e	3		
MOV.B @aa:8, Rd	В	@aa:8 → Rd8						2				_	_	\$	\$	0	_	4	ļ.		
MOV.B @aa:16, Rd	В	@aa:16 → Rd8						4				_	—	\$	\$	0	—	e	6		
MOV.B @aa:24, Rd	В	@aa:24 → Rd8						6				_	—	\$	\$	0	—	8	3		
MOV.B Rs, @ERd	В	$Rs8 \rightarrow @ERd$			2							_	—	\$	\$	0	-	2	ļ		
MOV.B Rs, @(d:16, ERd)	В	$Rs8 \rightarrow @(d:16, ERd)$				4						-	—	\$	\$	0	—	6	6		
MOV.B Rs, @(d:24, ERd)	В	$Rs8 \rightarrow @(d:24, ERd)$				8						-	—	\$	\$	0	—	1	0		
MOV.B Rs, @-ERd	В	$\begin{array}{l} ERd32-1 \rightarrow ERd32 \\ Rs8 \rightarrow @ERd \end{array}$					2					_	_	\$	\$	0	_	6	6		
MOV.B Rs, @aa:8	В	Rs8 → @aa:8						2				-	—	\$	\$	0	-	2	ł		
MOV.B Rs, @aa:16	В	Rs8 → @aa:16						4				—	—	\$	\$	0	—	e	6		
MOV.B Rs, @aa:24	В	$Rs8 \rightarrow @aa:24$						6				—	—	\$	\$	0	—	5	3		
MOV.W #xx:16, Rd	W	#xx:16 → Rd16	4									—	—	↕	\$	0	—	4	ł		
MOV.W Rs, Rd	W	$\text{Rs16} \rightarrow \text{Rd16}$		2								—	—	↕	\$	0	—	2	2		
MOV.W @ERs, Rd	W	$@ERs \to Rd16$			2							—	—	\updownarrow	\$	0	—	4	ļ		
MOV.W @(d:16, ERs), Rd	W	$@(d:16, ERs) \rightarrow Rd16$				4						—	—	\updownarrow	\$	0	—	6	6		
MOV.W @(d:24, ERs), Rd	W	$@(d:24, ERs) \rightarrow Rd16$				8						—	—	\updownarrow	\$	0	—	1	0		
MOV.W @ERs+, Rd	w	@ERs → Rd16 ERs32+2 → @ERd32					2					-	_	\$	\$	0	_	6	6		
MOV.W @aa:16, Rd	W	@aa:16 → Rd16						4				-	-	\$	\$	0	-	6	6		
MOV.W @aa:24, Rd	W	@aa:24 → Rd16						6				-	-	\$	\$	0	-	ε	3		
MOV.W Rs, @ERd	W	$Rs16 \rightarrow @ERd$			2							_	_	\$	\$	0	_	2	ļ		
MOV.W Rs, @(d:16, ERd)	W	$Rs16 \rightarrow @(d:16, ERd)$				4						_	_	↕	\$	0	_	6	5		
MOV.W Rs, @(d:24, ERd)	W	$Rs16 \rightarrow @(d:24, ERd)$				8						_	_	↕	\$	0	_	1	0		

			essi tion	•			nd /tes)							No. Stat	. of es ^{*1}			
Mnemonic	Operand Size	Operation	xx#	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	0 0 aa			Con			1	•	Normal	Advanced
MOV.W Rs, @-ERd	-	$ERd32-2 \rightarrow ERd32$	#	Ľ.			2				1	 -	н —	N ↓	z ≎	v 0	с —	2	
		$Rs16 \rightarrow @ERd$																	
MOV.W Rs, @aa:16	W	$Rs16 \rightarrow @aa:16$						4				-	-	\$	\$	0	—	6	3
MOV.W Rs, @aa:24	W	$Rs16 \rightarrow @aa:24$						6				—	—	\$	\$	0	—	8	3
MOV.L #xx:32, Rd	L	#xx:32 → Rd32	6									-	-	\$	\$	0	-	e	5
MOV.L ERs, ERd	L	$ERs32 \rightarrow ERd32$		2								-	-	\$	\$	0	-	2	2
MOV.L @ERs, ERd	L	@ERs \rightarrow ERd32			4							-	-	\$	\$	0	—	8	3
MOV.L @(d:16, ERs), ERd	L	@(d:16, ERs) → ERd32				6						-	—	\$	\$	0	-	1	0
MOV.L @(d:24, ERs), ERd	L	@(d:24, ERs) → ERd32				10						-	-	\$	\$	0	-	1	4
MOV.L @ERs+, ERd	L	@ERs → ERd32 ERs32+4 → ERs32					4					-	-	\$	\$	0	-	1	0
MOV.L @aa:16, ERd	L	@aa:16 → ERd32										-	-	\$	1	0	—	1	0
MOV.L @aa:24, ERd	L	@aa:24 → ERd32						6				-	-	1	1	0	—	1	2
MOV.L ERs, @ERd	L	$ERs32 \rightarrow @ERd$			4			8				_	_	1	1	0	_	8	3
MOV.L ERs, @(d:16, ERd)	L	ERs32 \rightarrow @(d:16, ERd)				6						-	_	\$	\$	0	—	1	0
MOV.L ERs, @(d:24, ERd)	L	$ERs32 \rightarrow @(d:24, ERd)$				10						-	_	\$	\$	0	—	1	4
MOV.L ERs, @-ERd	L	$ERd32-4 \rightarrow ERd32$ $ERs32 \rightarrow @ERd$					4					-	-	\$	\$	0	-	1	0
MOV.L ERs, @aa:16	L	ERs32 → @aa:16										-	-	\$	\$	0	_	1	0
MOV.L ERs, @aa:24	L	ERs32 \rightarrow @aa:24						6				-	_	\$	\$	0	_	1	2
POP.W Rn	w	$@SP \rightarrow Rn16$ SP+2 $\rightarrow SP$						8			2	-	-	\$	\$	0	-	6	3
POP.L ERn	L	$\begin{array}{l} @SP \to ERn32 \\ SP+4 \to SP \end{array}$									4	-	-	\$	\$	0	-	1	0
PUSH.W Rn	w	$SP-2 \rightarrow SP$ Rn16 $\rightarrow @SP$									2	-	-	\$	\$	0	-	6	3
PUSH.L ERn	L	$SP-4 \rightarrow SP$ ERn32 $\rightarrow @SP$									4	-	-	\$	\$	0	-	1	0
MOVFPE @aa:16, Rd	в	Cannot be used in the H8/3048 Group						4					annc e H8						
MOVTPE Rs, @aa:16	в	Cannot be used in the H8/3048 Group						4					annc e H8						

2. Arithmetic instructions

		Addressing Mode and Instruction Length (bytes)																No. Stat	. of es ^{*1}
Mnemonic	Operand Size	Operation	×	×		@(d, ERn)	@-ERn/@ERn+	aa	@ (d, PC)	@aa			Con	ditio	n Co	ode		Normal	Advanced
	-		XX#	Rn	@ERn	0	0	0	8	0		I	н	N	z	v	С		
ADD.B #xx:8, Rd		$Rd8+#xx:8 \rightarrow Rd8$	2									-	\$	\$	\$	\$	\$	2	
ADD.B Rs, Rd		$Rd8+Rs8 \rightarrow Rd8$		2								-	\$	\$	\$	\$	\$	2	
ADD.W #xx:16, Rd	W	$Rd16+#xx:16 \rightarrow Rd16$	4									-	(1)	€	\$	€	\$		4
ADD.W Rs, Rd	W	$Rd16+Rs16 \rightarrow Rd16$		2								-	(1)	€	1	€	€	2	2
ADD.L #xx:32, ERd	L	ERd32+#xx:32 → ERd32	6									-	(2)	\$	1	\$	\$	e	6
ADD.L ERs, ERd	L	ERd32+ERs32 → ERd32		2								-	(2)	\$	\$	\$	\$	2	2
ADDX.B #xx:8, Rd	В	Rd8+#xx:8 +C \rightarrow Rd8	2									—	\$	\$	(3)	\$	\$	2	2
ADDX.B Rs, Rd	В	Rd8+Rs8 +C \rightarrow Rd8		2								—	\$	\$	(3)	\$	\$	2	2
ADDS.L #1, ERd	L	ERd32+1 \rightarrow ERd32		2								—	—	-	-	_	—	2	2
ADDS.L #2, ERd	L	ERd32+2 \rightarrow ERd32		2								—	—	_	-	_	—	2	2
ADDS.L #4, ERd	L	$ERd32+4 \rightarrow ERd32$		2								-	—	_	-	_	—	2	2
INC.B Rd	В	$Rd8+1 \rightarrow Rd8$		2								-	—	\$	\$	\$	—	2	2
INC.W #1, Rd	W	Rd16+1 → Rd16		2								-	—	\$	\$	\$	—	2	2
INC.W #2, Rd	W	Rd16+2 → Rd16		2								—	—	\$	\$	\$	—	2	2
INC.L #1, ERd	L	ERd32+1 \rightarrow ERd32		2								-	—	\$	\$	\$	—	2	2
INC.L #2, ERd	L	$ERd32+2 \rightarrow ERd32$		2								—	—	\$	\$	\$	—	2	2
DAA Rd	В	Rd8 decimal adjust \rightarrow Rd8		2								-	*	\$	\$	*	-	2	2
SUB.B Rs, Rd	В	$Rd8-Rs8 \rightarrow Rd8$		2								_	\$	\$	1	1	1	2	2
SUB.W #xx:16, Rd	w	Rd16–#xx:16 → Rd16	4									-	(1)	1	1	1	\$	4	4
SUB.W Rs, Rd	w	Rd16–Rs16 \rightarrow Rd16		2								-	(1)	\$	1	\$	\$	2	2
SUB.L #xx:32, ERd	L	ERd32–#xx:32 \rightarrow ERd32	6									_	(2)	\$	1	\$	\$	e	6
SUB.L ERs, ERd	L	ERd32–ERs32 \rightarrow ERd32		2								-	(2)	\$	\$	\$	\$	2	2
SUBX.B #xx:8, Rd	В	Rd8–#xx:8–C \rightarrow Rd8	2									-	\$	\$	(3)	\$	\$	2	2
SUBX.B Rs, Rd	В	Rd8–Rs8–C \rightarrow Rd8		2								-	\$	\$	(3)	\$	\$	2	2
SUBS.L #1, ERd	L	ERd32–1 \rightarrow ERd32		2								-	_	_	_	_	-	2	2
SUBS.L #2, ERd	L	ERd32–2 \rightarrow ERd32		2								-	_	_	-	_	-	2	2
SUBS.L #4, ERd	L	ERd32–4 \rightarrow ERd32		2								-	_	_	-	_	-	2	2
DEC.B Rd	В	Rd8–1 \rightarrow Rd8		2								-	_	\$	\$	\$	-	2	2
DEC.W #1, Rd	w	Rd16–1 → Rd16		2								-	_	\$	\$	\$	-	2	2
DEC.W #2, Rd	W	Rd16–2 → Rd16		2								-	_	\$	\$	\$	-	2	2

		Addressing Mode and Instruction Length (bytes)																No. Stat	. of es ^{*1}
Mnemonic	Operation Size	#xx Rn @ERn @(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@aa		Condition Cod			ode	_	Normal	Advanced					
	g		XX#	R	0	0	ġ	0	0	0		I	н	N	z	v	c	Ŷ	Ad
DEC.L #1, ERd	L	$ERd32-1 \rightarrow ERd32$		2								-	_	\$	\$	\$	-	2	2
DEC.L #2, ERd	L	$ERd32-2 \rightarrow ERd32$		2								-	_	\$	\$	\$	-	2	2
DAS.Rd	В	Rd8 decimal adjust \rightarrow Rd8		2								-	*	\$	\$	*	-	2	2
MULXU. B Rs, Rd	В	$Rd8 \times Rs8 \rightarrow Rd16$ (unsigned multiplication)		2								_	-	-	-	-	_	1	4
MULXU. W Rs, ERd	W	$Rd16 \times Rs16 \rightarrow ERd32$ (unsigned multiplication)		2								-	-	-	-	-	-	2	2
MULXS. B Rs, Rd	В	$Rd8 \times Rs8 \rightarrow Rd16$ (signed multiplication)		4								-	-	\$	\$	-	-	1	6
MULXS. W Rs, ERd	W	$Rd16 \times Rs16 \rightarrow ERd32$ (signed multiplication)		4								-	-	\$	\$	-	-	2	4
DIVXU. B Rs, Rd	В	Rd16 ÷ Rs8 → Rd16 (RdH: remainder, RdL: quotient) (unsigned division)		2								_	_	(6)	(7)	_	_	1	4
DIVXU. W Rs, ERd	W	ERd32 ÷ Rs16 → ERd32 (Ed: remainder, Rd: quotient) (unsigned division)		2								_	_	(6)	(7)	_	_	2	2
DIVXS. B Rs, Rd	В	Rd16 ÷ Rs8 → Rd16 (RdH: remainder, RdL: quotient) (signed division)		4								_	_	(8)	(7)	_	_	1	6
DIVXS. W Rs, ERd	W	$ERd32 \div Rs16 \rightarrow ERd32$ (Ed: remainder, Rd: quotient) (signed division)		4								_	_	(8)	(7)	_	_	2	4
CMP.B #xx:8, Rd	В	Rd8–#xx:8	2									_	\$	\$	\$	\$	\uparrow	2	2
CMP.B Rs, Rd	В	Rd8–Rs8		2								_	€	€	€	€	€	2	2
CMP.W #xx:16, Rd	W	Rd16–#xx:16	4									-	(1)	\$	\$	\$	€	4	4
CMP.W Rs, Rd	W	Rd16–Rs16		2								_	(1)	€	€	€	€	2	2
CMP.L #xx:32, ERd	L	ERd32-#xx:32	6									-	(2)	\uparrow	\uparrow	\uparrow	\uparrow	4	4
CMP.L ERs, ERd	L	ERd32–ERs32		2									(2)	1	1	1	1	2	2

									le a n (by)								. of es ^{*1}
Mnemonic	Operand Size	Operation	×		@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@aa			Con	ditic	on Co	ode		Normal	Advanced
	g		XX#	R	0	0	6	0	0	0	1	Т	н	N	z	v	С	Ž	Ad
NEG.B Rd	В	$0-Rd8 \rightarrow Rd8$		2								—	\$	\$	\$	\$	\$	2	2
NEG.W Rd	W	$0-Rd16 \rightarrow Rd16$		2								-	\$	\$	\$	\$	\$	2	2
NEG.L ERd	L	$0-ERd32 \rightarrow ERd32$		2								-	\$	\$	\$	\$	\$	2	2
EXTU.W Rd	W	$0 \rightarrow (\text{} \text{ of Rd16})$		2								-	_	0	\$	0	_	2	2
EXTU.L ERd	L	$0 \rightarrow$ (<bits 16="" 31="" to=""> of ERd32)</bits>		2								-	-	0	\$	0	-	2	2
EXTS.W Rd	W	(<bit 7=""> of Rd16) \rightarrow (<bits 15="" 8="" to=""> of Rd16)</bits></bit>		2								-	—	\$	\$	0	—	2	2
EXTS.L ERd	L	(<bit 15=""> of ERd32) \rightarrow (<bits 16="" 31="" to=""> of ERd32)</bits></bit>		2								_	_	\$	\$	0	_		2

3. Logic instructions

								Mod		nd /tes)								. of es ^{*1}
Mnemonic	Operand Size	Operation	×	_	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@aa			Con	ditic	n Co	ode		Normal	Advanced
	ō		XX#	R	8	0	0	0	8	0		Т	н	N	z	v	С	ž	¥
AND.B #xx:8, Rd	В	$Rd8 \land \#xx:8 \rightarrow Rd8$	2									-	-	\$	\$	0	-	2	2
AND.B Rs, Rd	В	$Rd8 \land Rs8 \rightarrow Rd8$		2								-	-	\$	\$	0	-	2	2
AND.W #xx:16, Rd	W	$Rd16 \land \#xx:16 \rightarrow Rd16$	4									-	—	\$	\$	0	—	4	4
AND.W Rs, Rd	W	$Rd16 \land Rs16 \rightarrow Rd16$		2								-	—	\$	\$	0	—		2
AND.L #xx:32, ERd	L	$ERd32 \land \#xx:32 \rightarrow ERd32$	6									-	-	\$	\$	0	-	(6
AND.L ERs, ERd	L	$ERd32 \land ERs32 \to ERd32$		4								-	-	\$	\$	0	-	4	4
OR.B #xx:8, Rd	В	$Rd8 \lor \#xx:8 \rightarrow Rd8$	2									—	—	\$	\$	0	-	2	2
OR.B Rs, Rd	В	$Rd8 \lor Rs8 \rightarrow Rd8$		2								-	—	\$	\$	0	-	2	2
OR.W #xx:16, Rd	W	Rd16∨#xx:16 → Rd16	4									-	—	\$	\$	0	-	4	4
OR.W Rs, Rd	W	$Rd16 \lor Rs16 \rightarrow Rd16$		2								-	—	\$	\$	0	-	2	2
OR.L #xx:32, ERd	L	$ERd32 \lor \#xx:32 \rightarrow ERd32$	6									-	—	\$	\$	0	—	(6
OR.L ERs, ERd	L	$ERd32{\vee}ERs32\rightarrowERd32$		4								-	—	\$	\$	0	—	4	4
XOR.B #xx:8, Rd	В	Rd8⊕#xx:8 → Rd8	2									-	—	\$	\$	0	—	2	2
XOR.B Rs, Rd	В	Rd8⊕Rs8 → Rd8		2								-	—	\$	\$	0	—	2	2
XOR.W #xx:16, Rd	W	Rd16⊕#xx:16 → Rd16	4									-	—	\$	\$	0	-	4	4
XOR.W Rs, Rd	W	Rd16⊕Rs16 → Rd16		2								-	—	\$	\$	0	-	2	2
XOR.L #xx:32, ERd	L	$ERd32 \oplus \#xx:32 \to ERd32$	6									-	—	\$	\$	0	—	6	6
XOR.L ERs, ERd	L	$ERd32{\oplus}ERs32 \to ERd32$		4								—	—	\$	\$	0	-	4	4
NOT.B Rd	В	¬ Rd8 → Rd8		2								—	—	\$	\$	0	-	2	2
NOT.W Rd	W	¬ Rd16 → Rd16		2								-	-	\$	\$	0	-	2	2
NOT.L ERd	L	$\neg \text{ Rd32} \rightarrow \text{ Rd32}$		2								-	-	\$	\$	0	-		2



4. Shift instructions

					ddro ruc					nd /tes)							No Stat	. of es ^{*1}
Mnemonic	Operand Size	Operation	×		@ERn	@(d, ERn)	@-ERn/@ERn+	aa	@(d, PC)	@aa			Con	ditio	n Co	ode		Normal	Advanced
	Q		XX#	Rn	0	0	6	@ aa	0	0	1	I	н	N	z	v	с	Ž	Ρq
SHAL.B Rd	В			2								—	—	\$	\$	\$	\$	2	2
SHAL.W Rd	W			2								—	—	\uparrow	\$	\$	\uparrow	2	2
SHAL.L ERd	L	MSB LSB		2								—	—	\uparrow	\$	\$	\$	2	2
SHAR.B Rd	В	r≠ C		2								-	—	\$	\$	0	\$	2	2
SHAR.W Rd	W			2								-	—	\$	\$	0	\$	2	2
SHAR.L ERd	L	MSB LSB		2								—	—	\uparrow	\$	0	\$	2	2
SHLL.B Rd	В			2								—	—	\$	\$	0	\uparrow	2	2
SHLL.W Rd	W			2								-	—	\$	\$	0	\$	2	2
SHLL.L ERd	L	MSB LSB		2								—	—	\uparrow	\$	0	\$	2	2
SHLR.B Rd	В			2								—	—	\uparrow	\$	0	\$	2	2
SHLR.W Rd	W			2								—	—	\uparrow	\$	0	\$	2	2
SHLR.L ERd	L	MSB LSB		2								—	—	\uparrow	\$	0	\uparrow	2	2
ROTXL.B Rd	В			2								—	—	\uparrow	\$	0	\$	2	2
ROTXL.W Rd	W	⊂C-		2								—	—	\$	\$	0	\$	2	2
ROTXL.L ERd	L	MSB 🗕 LSB		2								—	—	\uparrow	\$	0	\$	2	2
ROTXR.B Rd	В			2								—	—	\uparrow	\$	0	\$	2	2
ROTXR.W Rd	W			2								—	—	\$	\$	0	\$	2	2
ROTXR.L ERd	L	MSB ──► LSB		2								—	—	\$	\$	0	\$	2	2
ROTL.B Rd	В			2								-	—	\$	\$	0	\$	2	2
ROTL.W Rd	W			2								_	_	\$	\$	0	\$	2	2
ROTL.L ERd	L	MSB 🗕 LSB		2								_	_	↕	\$	0	€	2	2
ROTR.B Rd	В			2								_	_	\$	\$	0	\$	2	2
ROTR.W Rd	W	►FC		2								_	_	↕	\$	0	€	2	2
ROTR.L ERd	L	MSB		2								-	_	\$	\$	0	\$	2	2

5. Bit manipulation instructions

					ddro)							No. Stat	
Mnemonic	Operand Size	Operation	XX#	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@ @ aa	I	1	Con H	ditic	n Co	v	С	Normal	Advanced
BSET #xx:3, Rd	в	(#xx:3 of Rd8) ← 1		2								-	_	-	-	_	-	2	2
BSET #xx:3, @ERd	в	(#xx:3 of @ERd) ← 1			4							—	_	—	—	_	—	8	3
BSET #xx:3, @aa:8	в	(#xx:3 of @aa:8) ← 1						4				—	_	-	-	_	—	8	3
BSET Rn, Rd	в	(Rn8 of Rd8) ← 1		2								—	_	-	—	_	—	2	2
BSET Rn, @ERd	В	(Rn8 of @ERd) ← 1			4							-	_	-	-	_	—	6	3
BSET Rn, @aa:8	В	(Rn8 of @aa:8) ← 1						4				-	_	-	-	_	-	8	3
BCLR #xx:3, Rd	В	(#xx:3 of Rd8) ← 0		2								-	-	-	-	-	-	2	2
BCLR #xx:3, @ERd	в	(#xx:3 of @ERd) ← 0			4							—	_	—	—	_	—	8	3
BCLR #xx:3, @aa:8	в	(#xx:3 of @aa:8) ← 0						4				—	_	-	—	_	—	8	3
BCLR Rn, Rd	в	(Rn8 of Rd8) ← 0		2								—	_	—	-	_	—	2	2
BCLR Rn, @ERd	В	(Rn8 of @ERd) ← 0			4							-	_	-	-	_	—	6	3
BCLR Rn, @aa:8	В	(Rn8 of @aa:8) ← 0						4				-	_	-	-	_	—	6	3
BNOT #xx:3, Rd	В	(#xx:3 of Rd8) ← ¬ (#xx:3 of Rd8)		2								-	-	-	-	-	-	2	2
BNOT #xx:3, @ERd	В	(#xx:3 of @ERd) ← ¬ (#xx:3 of @ERd)			4							-	-	-	-	-	-	8	3
BNOT #xx:3, @aa:8	В	(#xx:3 of @aa:8) ← ¬ (#xx:3 of @aa:8)						4				-	-	-	-	-	-	8	3
BNOT Rn, Rd	В	(Rn8 of Rd8) ← ¬ (Rn8 of Rd8)		2								-	-	-	-	-	-	2	>
BNOT Rn, @ERd	В	(Rn8 of @ERd) ← ¬ (Rn8 of @ERd)			4							-	-	-	-	-	-	8	}
BNOT Rn, @aa:8	В	(Rn8 of @aa:8) ← ¬ (Rn8 of @aa:8)						4				-	-	-	-	-	-	8	}
BTST #xx:3, Rd	В	¬ (#xx:3 of Rd8) → Z		2								-	-	-	\$	-	-	2	2
BTST #xx:3, @ERd	В	¬ (#xx:3 of @ERd) → Z			4							-	-	-	\$	-	-	6	;
BTST #xx:3, @aa:8	В	¬ (#xx:3 of @aa:8) → Z						4				-	-	-	\$	-	-	e	;
BTST Rn, Rd	В	¬ (Rn8 of @Rd8) → Z		2								-	-	-	\$	-	-	2	2
BTST Rn, @ERd	В	¬ (Rn8 of @ERd) → Z			4							-	-	-	\$	-	-	e	;
BTST Rn, @aa:8	В	¬ (Rn8 of @aa:8) → Z						4				-	-	-	\$	-	-	e	;
BLD #xx:3, Rd	в	(#xx:3 of Rd8) \rightarrow C		2								—	_	-	-	_	\$	2	2

Renesas

							ng l Ler)							No. Stat	· · ·
Mnemonic	Operand Size	Operation	×	-	@ERn	@(d, ERn)	@-ERn/@ERn+	@ aa	@(d, PC)	@aa			Con	ditio	n Co	ode	I	Normal	Advanced
	ō		XX#	R	8	0	8	0	0	0		I	н	N	z	v	С	ž	¥
BLD #xx:3, @ERd	В	(#xx:3 of @ERd) \rightarrow C			4							-	_	-	-	-	€	6	3
BLD #xx:3, @aa:8	В	(#xx:3 of @aa:8) \rightarrow C						4				-	—	—	—	—	\$	6	3
BILD #xx:3, Rd	В	¬ (#xx:3 of Rd8) → C		2								-	—	-	-	-	\uparrow	2	2
BILD #xx:3, @ERd	В	¬ (#xx:3 of @ERd) → C			4							-	—	-	-	-	\$	6	3
BILD #xx:3, @aa:8	В	¬ (#xx:3 of @aa:8) → C						4				-	—	-	-	-	\$	6	3
BST #xx:3, Rd	В	$C \rightarrow (\#xx:3 \text{ of } Rd8)$		2								-	—	-	-	-	—	2	2
BST #xx:3, @ERd	В	$C \rightarrow (\#xx:3 \text{ of } @ERd24)$			4							—	—	—	—	—	—	8	3
BST #xx:3, @aa:8	В	$C \rightarrow (\#xx:3 \text{ of } @aa:8)$						4				-	—	—	—	—	—	8	3
BIST #xx:3, Rd	В	\neg C \rightarrow (#xx:3 of Rd8)		2								-	—	-	-	-	—	2	2
BIST #xx:3, @ERd	В	\neg C \rightarrow (#xx:3 of @ERd24)			4							-	-	-	-	-	-	6	3
BIST #xx:3, @aa:8	В	$\neg C \rightarrow (\#xx:3 \text{ of } @aa:8)$						4				-	—	-	—	-	—	8	3
BAND #xx:3, Rd	В	$C \land (\#xx:3 \text{ of } Rd8) \rightarrow C$		2								—	—	—	—	—	\$	2	2
BAND #xx:3, @ERd	В	C∧(#xx:3 of @ERd24) → C			4							—	—	—	—	—	\$	6	3
BAND #xx:3, @aa:8	В	C∧(#xx:3 of @aa:8) → C						4				-	—	-	-	-	\$	6	3
BIAND #xx:3, Rd	В	$C \land \neg$ (#xx:3 of Rd8) $\rightarrow C$		2								-	—	-	-	-	\$	2	2
BIAND #xx:3, @ERd	В	$C \land \neg$ (#xx:3 of @ERd24) $\rightarrow C$			4							-	—	-	-	-	\$	6	3
BIAND #xx:3, @aa:8	В	C∧ ¬ (#xx:3 of @aa:8) → C						4				-	—	-	-	-	\$	6	3
BOR #xx:3, Rd	В	$C \lor (\#xx:3 \text{ of } Rd8) \rightarrow C$		2								-	—	—	—	-	\$	2	2
BOR #xx:3, @ERd	В	$C \lor (\#xx:3 \text{ of } @ERd24) \rightarrow C$			4							-	—	—	—	-	\$	e	3
BOR #xx:3, @aa:8	В	$C \lor (\#xx:3 \text{ of } @aa:8) \rightarrow C$						4				-	—	-	-	-	\$	6	3
BIOR #xx:3, Rd	В	$C \lor \neg$ (#xx:3 of Rd8) $\rightarrow C$		2								_	—	—	-	-	\$	2	2
BIOR #xx:3, @ERd	В	$C \lor \neg$ (#xx:3 of @ERd24) $\rightarrow C$			4							_	—	-	—	-	\$	6	3
BIOR #xx:3, @aa:8	В	C∨ ¬ (#xx:3 of @aa:8) → C						4				_	—	-	-	-	\$	6	3
BXOR #xx:3, Rd	В	C⊕(#xx:3 of Rd8) \rightarrow C		2								-	-	-	-	-	\$	2	2
BXOR #xx:3, @ERd	В	C⊕(#xx:3 of @ERd24) → C			4							-	-	-	-	-	\$	6	3
BXOR #xx:3, @aa:8	В	C⊕(#xx:3 of @aa:8) → C						4				_	-	-	-	-	\$	6	3
BIXOR #xx:3, Rd	В	C⊕ ¬ (#xx:3 of Rd8) → C		2								_	-	-	_	_	\$	2	2
BIXOR #xx:3, @ERd	в	C⊕ ¬ (#xx:3 of @ERd24) → C			4							_	-	-	_	-	\$	6	3
BIXOR #xx:3, @aa:8	в	C⊕ ¬ (#xx:3 of @aa:8) → C						4				-	-	-	-	-	\$	6	3

6. Branching instructions

									Mod ngth)							No. Stat	
Mnemonic	Operand Size	Oper	ation			Rn	@(d, ERn)	@-ERn/@ERn+	6	@(d, PC)	@aa			Con	ditic	on Co	ode		Normal	Advanced
	do		Branch Condition	XX#	Rn	@ERn	0	8	@ aa	0	0	I	I	н	N	z	v	с	Nor	Adv
BRA d:8 (BT d:8)	—	If condition	Always							2			—	—	—	—	—	—	4	1
BRA d:16 (BT d:16)	—	is true then								4			-	-	-	-	-	-	e	5
BRN d:8 (BF d:8)	_	$PC \leftarrow PC+d$	Never							2			_	-	-	—	-	-	4	4
BRN d:16 (BF d:16)	—	else next;								4			—	—	—	—	_	—	E	5
BHI d:8	—		$C \lor Z = 0$							2			—	—	—	—	_	—	2	4
BHI d:16	—									4			—	—	—	—	_	—	E	5
BLS d:8	—		C ∨ Z = 1							2			—	—	—	—	_	—	2	4
BLS d:16	—									4			—	—	—	—	_	—	E	5
BCC d:8 (BHS d:8)	_		C = 0							2			-	-	-	-	-	-	4	4
BCC d:16 (BHS d:16)	_	-								4			_	—	—	—	—	—	F	6
BCS d:8 (BLO d:8)	—		C = 1							2			-	—	—	—	_	-	4	4
BCS d:16 (BLO d:16)	—									4			-	—	-	—	_	-	6	3
BNE d:8	_	-	Z = 0							2			_	—	—	—	—	—	4	4
BNE d:16	_	-								4			_	—	—	—	—	—	e	3
BEQ d:8	_		Z = 1							2			-	-	-	-	-	-	4	4
BEQ d:16	_									4			-	-	-	-	-	-	e	3
BVC d:8	_		V = 0							2			-	-	-	-	-	-	4	4
BVC d:16	_									4			-	-	-	-	-	-	e	6
BVS d:8	_		V = 1							2			-	-	-	-	-	-	4	4
BVS d:16	_									4			-	-	-	-	-	-	e	6
BPL d:8	—		N = 0							2			-	—	-	—	_	-	4	4
BPL d:16	—									4			-	—	-	—	_	—	e	6
BMI d:8	_		N = 1							2			-	-	-	-	-	-	4	4
BMI d:16	—									4			-	—	-	—	_	-	F	6
BGE d:8	1_	-	N⊕V = 0							2			-	-	-	-	_	_	4	4
BGE d:16	1_	-								4			-	-	-	-	_	_	6	3
BLT d:8	1_	-	N⊕V = 1							2			-	-	-	-	_	-	4	4
BLT d:16	1_	-								4			-	-	-	-	_	-	F	6
BGT d:8	1_	1	$Z \vee (N \oplus V) = 0$							2			-	-	-	-	-	-	2	4
BGT d:16	1_	1								4			-	-	-	-	-	-	6	3
BLE d:8	1_	1	$Z \lor (N \oplus V) = 1$							2			-	-	-	-	_	-	2	4
BLE d:16	1_	-								4			-	-	-	-	-	-	F	5

					ddro ruc					nd /tes)							No Stat	. of es ^{*1}
Mnemonic	Operand Size	Operation	×		@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@aa			Con	ditic	on Co	ode		Normal	Advanced
	ő		XX#	R	0	0	ġ	0	0	0		T	н	N	z	v	с	ž	Ρq
JMP @ERn	—	$PC \gets ERn$			2							-	_	—	—	-	-	4	1
JMP @aa:24	_	PC ← aa:24						4				-	_	—	-	-	-	6	6
JMP @@aa:8	_	PC ← @aa:8								2		-	_	-	-	-	-	8	10
BSR d:8	-	$PC \rightarrow @-SP$ $PC \leftarrow PC+d:8$							2			-	—	-	-	-	-	6	8
BSR d:16	-	$PC \rightarrow @-SP$ $PC \leftarrow PC+d:16$							4			-	—	-	-	-	-	8	10
JSR @ERn	-	$PC \rightarrow @-SP$ $PC \leftarrow @ERn$			2							-	—	-	-	-	-	6	8
JSR @aa:24	-	$PC \rightarrow @-SP$ $PC \leftarrow @aa:24$						4				-	—	-	-	-	-	8	10
JSR @@aa:8	-	$PC \rightarrow @-SP$ $PC \leftarrow @aa:8$								2		-	—	-	-	-	-	8	12
RTS	—	$PC \gets @SP+$									2	—	_	-	—	—	—	8	10

7. System control instructions

						essi tion				nd /tes)							No Stat	. of es ^{*1}
Mnemonic	Operand Size	Operation	×		@ERn	@(d, ERn)	@-ERn/@ERn+	@ aa	@(d, PC)	@ aa			Con	ditic	n Co	ode		Normal	Advanced
	ŏ		XX#	R	0	0	ġ	0	0	0	Ι	Т	н	N	z	v	с	ž	Ad
TRAPA #x:2	-	$PC \rightarrow @-SP$ $CCR \rightarrow @-SP$ $ \rightarrow PC$									2	1	-	-		_	_	14	16
RTE	-	$CCR \leftarrow @SP+$ PC $\leftarrow @SP+$										\$	\$	\$	\$	\$	\$	1	0
SLEEP	-	Transition to power- down state										-	-	-	-	-	-	2	2
LDC #xx:8, CCR	В	#xx:8 → CCR	2									\$	\$	\$	\$	\$	\$	2	2
LDC Rs, CCR	в	$Rs8 \rightarrow CCR$		2								\$	\$	\$	\$	\$	\$	2	2
LDC @ERs, CCR	w	@ERs → CCR			4							\$	\$	\$	\$	\$	\$	6	6
LDC @(d:16, ERs), CCR	w	@(d:16, ERs) → CCR				6						\$	\$	\$	\$	\$	\$	8	3
LDC @(d:24, ERs), CCR	W	@(d:24, ERs) → CCR				10						\$	\$	\$	\$	\$	\$	1	2
LDC @ERs+, CCR	W	@ERs → CCR ERs32+2 → ERs32					4					↓ ↓	↓ ↓	\$ \$	↓ ↓	↓ ↓	↓ ↓	8	3
LDC @aa:16, CCR	w	@aa:16 → CCR						6				\$	\$	\$	\$	\$	\$	8	3
LDC @aa:24, CCR	w	@aa:24 \rightarrow CCR						8				\$	\$	\$	\$	\$	\$	1	0
STC CCR, Rd	в	$CCR \rightarrow Rd8$		2								—	_	-	_	_	-	2	2
STC CCR, @ERd	w	$CCR \rightarrow @ERd$			4							—	-	-	_	-	—	6	6
STC CCR, @(d:16, ERd)	w	$CCR \rightarrow @(d:16, ERd)$				6						—	-	-	-	-	—	8	3
STC CCR, @(d:24, ERd)	w	$CCR \rightarrow @(d:24, ERd)$				10						—	-	-	-	-	—	1	2
STC CCR, @-ERd	W	$\begin{array}{l} ERd32-2 \rightarrow ERd32 \\ CCR \rightarrow @ERd \end{array}$					4					-	-	-	-	-	-	8	3
STC CCR, @aa:16	w	CCR → @aa:16						6				—	—	-	-	-	—	8	3
STC CCR, @aa:24	w	$CCR \rightarrow @aa:24$						8				-	—	-	-	-	-	1	0
ANDC #xx:8, CCR	В	$CCR \land \#xx:8 \rightarrow CCR$	2									\$	\$	\$	\$	\$	\$	2	2
ORC #xx:8, CCR	В	$CCR \lor \#xx:8 \rightarrow CCR$	2									\$	\$	\$	\$	\$	\$	2	2
XORC #xx:8, CCR	В	$CCR \oplus \#xx:8 \rightarrow CCR$	2									\$	≎	\$	\$	\$	\$	2	2
NOP	-	$PC \leftarrow PC+2$									2	—	—	-	_	_	—	2	2

8. Block transfer instructions

						essi tion)							No Stat	. of es ^{*1}
Mnemonic	Operand Size	Operation	×	-	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@ @aa			Con	ditio	n Co	ode		Normal	Advanced
	ō		XX#	Rn	8	0	0	8	0	8		I	н	N	z	۷	С	ž	Ă
EEPMOV. B		$\begin{array}{l} \text{if } R4L \neq 0 \text{ then} \\ \text{repeat} @R5 \rightarrow @R6 \\ & R5+1 \rightarrow R5 \\ & R6+1 \rightarrow R6 \\ & R4L-1 \rightarrow R4L \\ \text{until} \qquad R4L=0 \\ \text{else next} \end{array}$									4				_	_		8+ 4n ^{*2}	
EEPMOV. W		$\begin{array}{l} \text{if } R4 \neq 0 \text{ then} \\ \text{repeat} @R5 \rightarrow @R6 \\ &R5+1 \rightarrow R5 \\ &R6+1 \rightarrow R6 \\ &R4-1 \rightarrow R4 \\ \text{until} &R4=0 \\ \text{else next} \end{array}$									4							8+ 4n ^{*2}	

Notes: 1. The number of states is the number of states required for execution when the instruction and its operands are located in on-chip memory. For other cases see section A.3, Number of States Required for Execution.

- 2. n is the value set in register R4L or R4.
- (1) Set to 1 when a carry or borrow occurs at bit 11; otherwise cleared to 0.
- (2) Set to 1 when a carry or borrow occurs at bit 27; otherwise cleared to 0.
- (3) Retains its previous value when the result is zero; otherwise cleared to 0.
- (4) Set to 1 when the adjustment produces a carry; otherwise retains its previous value.
- (5) The number of states required for execution of an instruction that transfers data in synchronization with the E clock is variable.
- (6) Set to 1 when the divisor is negative; otherwise cleared to 0.
- (7) Set to 1 when the divisor is zero; otherwise cleared to 0.
- (8) Set to 1 when the quotient is negative; otherwise cleared to 0.

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A.2 Operation Code Map

Table A.2 Operation Code Map

							1		, I								
	Ŀ	Table A-2 (2)	Table A-2 (2)			BLE											
	ш	ADDX	SUBX			BGT	JSR		Table A-2 (3)								
	٥	MOV	CMP			ВLТ			Table (3								
BH is 0 BH is 1	U	W	C			BGE	BSR	NOV									
t bit of] t bit of]	æ	Table A-2 Table A-2 (2) (2)	Table A-2 (2)			BMI		W	EEPMOV								
 Instruction when most significant bit of BH is 0. Instruction when most significant bit of BH is 1. 	A	Table A-2 (2)	Table A-2 Table A-2 (2) (2)			BPL	ЧМГ		Table A-2 Table A-2 EEPMOV (2) (2)								
nost sig nost sig	6	0				BVS			Table A-2 (2)								
when n when n	80	ADD	SUB			BVC	Table A-2 (2)		MOV								
ruction	~	LDC	Table A-2 (2)		MOV.B	BEQ	TRAPA	BST BIST	BLD BLD	ADD	ADDX	CMP	SUBX	OR	XOR	AND	MOV
 Instruction when most significant bit of BH is 0. Instruction when most significant bit of BH is 1. 	9	ANDC	AND.B			BNE	RTE	AND	BAND BIAND								
	2	XORC	XOR.B			BCS	BSR		BXOR BIXOR								
byte BL	4	ORC	OR.B			BCC	RTS	OR	BOR BIOR								
2nd byte BH BL	т	LDC	Table A-2 (2)			BLS	DIVXU	10	BISI								
1st byte AH AL	2	STC	Table A-2 Table A-2 Table A-2 Table A-2 Column A-2 <thcolumn a-2<="" th=""> <thcolumn a-2<="" t<="" td=""><td></td><td></td><td>ВНІ</td><td>MULXU</td><td>i i</td><td>BCLR</td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></thcolumn></thcolumn>			ВНІ	MULXU	i i	BCLR								
	-	Table A-2 (2)	Table A-2 (2)			BRN	DIVXU	Long	BNOT								
tion cod	0	NOP	Table A-2 (2)			BRA	МИГХИ		BSET								
Instruction code:	AHAL	0	-	2	ю	4	5	9	7	8	6	A	В	ပ	D	ш	Ľ

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ш	Table A-2 (3)		INC						EXTS		DEC		BLE		
ш													BGT		
۵	Table A-2 Table A-2 (3) (3)		INC						EXTS		DEC		BLT		
U	Table A-2 (3)	ADD		MOV						SUB		CMP	BGE		
ш		AL		W	SHAL	SHAR	ROTL	ROTR	NEG	ร		C	BMI		
A													BPL		
6			ADDS		SHAL	SHAR	ROTL	ROTR	NEG		SUB		BVS		
œ	SLEEP		ADI		SH	SH	RO	RO	Ÿ		ns		BVC		
7			INC						ЕХТИ		DEC		BEQ		
9													BNE	AND	AND
5			INC						ЕХТИ		DEC		BCS	XOR	XOR
4	LDC/STC												BCC	OR	OR
3					SHLL	SHLR	ROTXL	ROTXR	NOT				BLS	SUB	SUB
2													BHI	CMP	CMP
-					SHLL	SHLR	ROTXL	ROTXR	NOT				BRN	ADD	ADD
0	MOV	INC	ADDS	DAA	ST	HS	RO	RO	ž	DEC	SUBS	DAS	BRA	MOV	MOV
AH AL	01	ΡO	OB	OF	10	11	12	13	17	1A	1B	1F	58	29	ΤA

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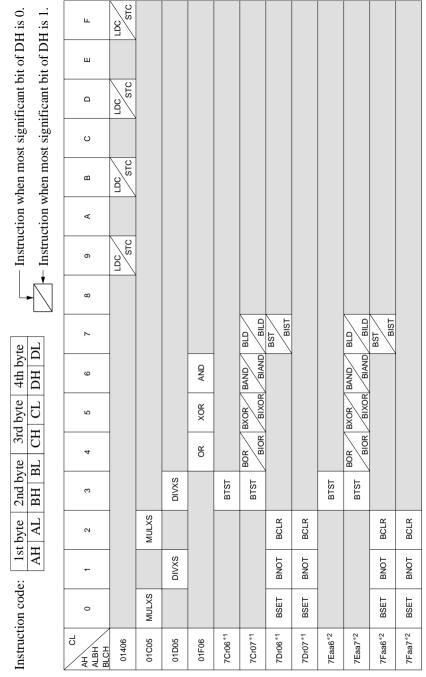
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Instruction code:

BH AL

BL

2nd byte 1st byte AH



Notes: 1. r is the register designation field. 2. aa is the absolute address field.

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A.3 Number of States Required for Execution

The tables in this section can be used to calculate the number of states required for instruction execution by the H8/300H CPU. Table A.4 indicates the number of instruction fetch, data read/write, and other cycles occurring in each instruction. Table A.3 indicates the number of states required per cycle according to the bus size. The number of states required for execution of an instruction can be calculated from these two tables as follows:

Number of states = $I \times S_I + J \times S_J + K \times S_K + L \times S_L + M \times S_M + N \times S_N$

Examples of Calculation of Number of States Required for Execution

Examples: Advanced mode, stack located in external address space, on-chip supporting modules accessed with 8-bit bus width, external devices accessed in three states with one wait state and 16-bit bus width.

BSET #0, @FFFFC7:8

From table A.4, I = L = 2 and J = K = M = N = 0From table A.3, $S_I = 4$ and $S_L = 3$ Number of states $= 2 \times 4 + 2 \times 3 = 14$

JSR @@30

From table A.4, I = J = K = 2 and L = M = N = 0From table A.3, $S_I = S_J = S_K = 4$ Number of states = $2 \times 4 + 2 \times 4 + 2 \times 4 = 24$

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				Α	ccess Con	ditions		
				-Chip		Extern	al Device	
			•	porting odule	8-B	it Bus	16-B	it Bus
Cycle		On-Chip Memory	8-Bit Bus	16-Bit Bus	2-State Access	3-State Access	2-State Access	3-State Access
Instruction fetch	Sı	2	6	3	4	6 + 2m	2	3 + m
Branch address read	$S_{ m J}$							
Stack operation	Sκ							
Byte data access	S_{L}		3		2	3 + m		
Word data access	SM		6		4	6 + 2m		
Internal operation	S_{N}	1	1	1	1	1	1	1

Table A.3Number of States per Cycle

Legend

m: Number of wait states inserted into external device access



Instruction	n Mnemonic	Instruction Fetch I	Branch Addr. Read J	Stack Operation K	-	Word Data Access M	Internal Operation N
ADD	ADD.B #xx:8, Rd	1					
	ADD.B Rs, Rd	1					
	ADD.W #xx:16, Rd	2					
	ADD.W Rs, Rd	1					
	ADD.L #xx:32, ERd	3					
	ADD.L ERs, ERd	1					
ADDS	ADDS #1/2/4, ERd	1					
ADDX	ADDX #xx:8, Rd	1					
	ADDX Rs, Rd	1					
AND	AND.B #xx:8, Rd	1					
	AND.B Rs, Rd	1					
	AND.W #xx:16, Rd	2					
	AND.W Rs, Rd	1					
	AND.L #xx:32, ERd	3					
	AND.L ERs, ERd	2					
ANDC	ANDC #xx:8, CCR	1					
BAND	BAND #xx:3, Rd	1					
	BAND #xx:3, @ERd	2			1		
	BAND #xx:3, @aa:8	2			1		
Bcc	BRA d:8 (BT d:8)	2					
	BRN d:8 (BF d:8)	2					
	BHI d:8	2					
	BLS d:8	2					
	BCC d:8 (BHS d:8)	2					
	BCS d:8 (BLO d:8)	2					
	BNE d:8	2					
	BEQ d:8	2					
	BVC d:8	2					
	BVS d:8	2					
	BPL d:8	2					
	BMI d:8	2					
	BGE d:8	2					
	BLT d:8	2					

Table A.4 Number of Cycles per Instruction

Appendix A Instruction Set

I		Instruction Fetch	Addr. Read		Access	Word Data Access	Operation
	Mnemonic	1	J	К	L	М	N
Bcc	BGT d:8	2					
	BLE d:8	2					_
	BRA d:16 (BT d:16)	2					2
	BRN d:16 (BF d:16)	2					2
	BHI d:16	2					2
	BLS d:16	2					2
	BCC d:16 (BHS d:16)	2					2
	BCS d:16 (BLO d:16)	2					2
	BNE d:16	2					2
	BEQ d:16	2					2
	BVC d:16	2					2
	BVS d:16	2					2
	BPL d:16	2					2
	BMI d:16	2					2
	BGE d:16	2					2
	BLT d:16	2					2
	BGT d:16	2					2
	BLE d:16	2					2
BCLR	BCLR #xx:3, Rd	1					
	BCLR #xx:3, @ERd	2			2		
	BCLR #xx:3, @aa:8	2			2		
	BCLR Rn, Rd	1					
	BCLR Rn, @ERd	2			2		
	BCLR Rn, @aa:8	2			2		
BIAND	BIAND #xx:3, Rd	1					
	BIAND #xx:3, @ERd	2			1		
	BIAND #xx:3, @aa:8	2			1		
BILD	BILD #xx:3, Rd	1					
	BILD #xx:3, @ERd	2			1		
	BILD #xx:3, @aa:8	2			1		
BIOR	BIOR #xx:8, Rd	1					
	BIOR #xx:8, @ERd	2			1		
	BIOR #xx:8, @aa:8	2			1		
BIST	BIST #xx:3, Rd	1					
-	BIST #xx:3, @ERd	2			2		
	BIST #xx:3, @aa:8	2			2		

Inchrychia	Masaaais		Instruction Fetch	Addr. Read	-	Access	Word Data Access	Operation
BIXOR	n Mnemonic	2 D4	1 1	J	К	L	М	N
DIAUR	BIXOR #xx:					1		
	BIXOR #xx: BIXOR #xx:	-	2 2			1		
BLD	BLD #xx:3, 1		1			I		
BLD	BLD #xx:3,		2			1		
	BLD #xx.3, (BLD #xx:3, (-				1		
DNOT		-	2			I		
BNOT	BNOT #xx:3 BNOT #xx:3		1			2		
			2			2		
	BNOT #xx:3	-	2 1			2		
	BNOT Rn, Rd BNOT Rn, @ERd BNOT Rn, @aa:8 BOR BOR #xx:3, Rd BOR #xx:3, @ERd		2			2		
			2			2		
BOP			2			2		
DOIX			2			1		
	BOR #xx:3, BOR #xx:3,	-	2			1		
BSET	BSET #xx:3	-	1			1		
DOLI	BSET #xx:3		2			2		
	BSET #xx:3	. 0	2			2		
	BSET Rn, R	-	2			2		
	BSET Rn, @		2			2		
	BSET Rn, @		2			2		
BSR	BSR d:8	Normal ^{*1}	2		1	2		
2011	Derraie	Advanced	2		2			
	BSR d:16	Normal ^{*1}	2		1			2
	Derrano	Advanced	2		2			2
BST	BST #xx:3,		1		-			-
	BST #xx:3,		2			2		
	BST #xx:3,	-	2			2		
BTST	BTST #xx:3	-	1			_		
	BTST #xx:3	,	2			1		
	BTST #xx:3		2			1		
	BTST Rn, R		1					
	BTST Rn, @		2			1		
	BTST Rn, @		2			1		
	, e	-						

Appendix A Instruction Set

Instruction Mnemonic			Instruction Fetch I	Branch Addr. Read J	Stack Operation K	-	Word Data Access M	Internal Operation N
BXOR	BXOR #xx:3, R	٨d	1					
	BXOR #xx:3, @	DERd	2			1		
	BXOR #xx:3, @	Daa:8	2			1		
CMP	CMP.B #xx:8, I	Rd	1					
	CMP.B Rs, Rd		1					
	CMP.W #xx:16	, Rd	2					
	CMP.W Rs, Rd	ł	1					
	CMP.L #xx:32,	ERd	3					
	CMP.L ERs, El	Rd	1					
DAA	DAA Rd		1					
DAS	DAS Rd		1					
DEC	DEC.B Rd		1					
	DEC.W #1/2, F	Rd	1					
	DEC.L #1/2, ERd		1					
DIVXS	DIVXS.B Rs, R	Rd	2					12
	DIVXS.W Rs, E	ERd	2					20
DIVXU	DIVXU.B Rs, R	Rd	1					12
	DIVXU.W Rs, E	ERd	1					20
EEPMOV	EEPMOV.B		2			2n + 2 ^{*2}		
	EEPMOV.W		2			2n + 2 ^{*2}		
EXTS	EXTS.W Rd		1					
	EXTS.L ERd		1					
EXTU	EXTU.W Rd		1					
	EXTU.L ERd		1					
INC	INC.B Rd		1					
	INC.W #1/2, R	d	1					
	INC.L #1/2, ER	Rd	1					
JMP	JMP @ERn		2					
	JMP @aa:24		2					2
	JMP @@aa:8	Normal ^{*1}	2	1				2
		Advanced	2	2				2

Instruction	on Mnemonic		Instruction Fetch I	Branch Addr. Read J	Stack Operation K	-	Word Data Access M	Internal Operation N
JSR	JSR @ERn	Normal*1	2		1			
		Advanced	2		2			
	JSR @aa:24	Normal*1	2		1			2
		Advanced	2		2			2
	JSR @@aa:8	Normal*1	2	1	1			
		Advanced	2	2	2			
LDC	LDC #xx:8, CC	LDC #xx:8, CCR						
	LDC Rs, CCR		1					
	LDC @ERs, C	CR	2				1	
	LDC @(d:16, E	ERs), CCR	3				1	
	LDC @(d:24, E	ERs), CCR	5				1	
	LDC @ERs+,	CCR	2				1	2
	LDC @aa:16, CCR		3				1	
LDC @aa:24, CCI		CCR	4				1	
MOV	MOV.B #xx:8,	Rd	1					
	MOV.B Rs, Rd		1					
	MOV.B @ERs	, Rd	1			1		
	MOV.B @(d:16	6, ERs), Rd	2			1		
	MOV.B @(d:24	4, ERs), Rd	4			1		
	MOV.B @ERs	+, Rd	1			1		2
	MOV.B @aa:8	, Rd	1			1		
	MOV.B @aa:1	6, Rd	2			1		
	MOV.B @aa:2	4, Rd	3			1		
	MOV.B Rs, @	ERd	1			1		
	MOV.B Rs, @	(d:16, ERd)	2			1		
	MOV.B Rs, @	(d:24, ERd)	4			1		
	MOV.B Rs, @-	–ERd	1			1		2
	MOV.B Rs, @a	aa:8	1			1		
	MOV.B Rs, @a	aa:16	2			1		
	MOV.B Rs, @a	aa:24	3			1		
	MOV.W #xx:16	6, Rd	2					
			1					
	MOV.W @ERs	s, Rd	1				1	
	MOV.W @(d:1	6, ERs), Rd	2				1	

Appendix A Instruction Set

Instruction	Mnomonia	Instruction Fetch	Addr. Read	-	Access	Word Data Access	Operation
MOV	Mnemonic MOV.W @(d:24, ERs), Rd	1	J	К	L	M 1	N
NOV	MOV.W @(d.24, ERS), Rd	4				1	2
	MOV.W @ERS+, Rd MOV.W @aa:16, Rd	2				1	2
	MOV.W @aa:24, Rd	3				1	
	MOV.W Rs, @ERd	1				1	
	MOV.W Rs, @ERd MOV.W Rs, @(d:16, ERd)					1	
	MOV.W Rs, @(d:10, ERd)					1	
	MOV.W Rs, @–ERd	1				1	2
	MOV.W Rs, @aa:16	2				1	2
	MOV.W Rs, @aa:24	3				1	
	MOV.L #xx:32, ERd	3				I	
	MOV.L ERs, ERd	1					
	MOV.L @ERs, ERd	2				2	
	MOV.L @(d:16, ERs), ERd					2	
	MOV.L @(d:10, ERS), ERd					2	
	MOV.L @ERs+, ERd	2				2	2
	MOV.L @aa:16, ERd	3				2	2
	MOV.L @aa:24, ERd	4				2	
	MOV.L ERs, @ERd	2				2	
	MOV.L ERs, @(d:16, ERd)					2	
	MOV.L ERs, @(d:24, ERd)					2	
	MOV.L ERs, @-ERd	2				2	2
	MOV.L ERs, @aa:16	3				2	-
	MOV.L ERs, @aa:24	4				2	
MOVFPE	MOVFPE @aa:16, Rd*1	2			1	_	
MOVTPE	MOVTPE Rs, @aa:16 ^{*1}	2			1		
MULXS	MULXS.B Rs, Rd	2					12
	MULXS.W Rs, ERd	2					20
MULXU	MULXU.B Rs, Rd	1					12
	MULXU.W Rs, ERd	1					20
NEG	NEG.B Rd	1					
-	NEG.W Rd	1					
	NEG.L ERd	1					
NOP	NOP	1					

Instruction	Mnemonic		Instruction Fetch I	Branch Addr. Read J	Stack Operation K	Word Data Access M	Internal Operation N
NOT	NOT.B Rd		1				
	NOT.W Rd		1				
	NOT.L ERd		1				
OR	OR.B #xx:8, Rd		1				
	OR.B Rs, Rd		1				
	OR.W #xx:16	6, Rd	2				
	OR.W Rs, Ro	Ł	1				
	OR.L #xx:32,	ERd	3				
	OR.L ERs, E	Rd	2				
ORC	ORC #xx:8, 0	CCR	1				
POP	POP.W Rn		1			1	2
	POP.L ERn		2			2	2
PUSH	PUSH.W Rn		1			1	2
	PUSH.L ERn		2			2	2
ROTL	ROTL.B Rd		1				
	ROTL.W Rd		1				
	ROTL.L ERd		1				
ROTR	ROTR.B Rd		1				
	ROTR.W Rd		1				
	ROTR.L ERd	l	1				
ROTXL	ROTXL.B Rd		1				
	ROTXL.W Ro	t	1				
	ROTXL.L ER	d	1				
ROTXR	ROTXR.B Ro	i	1				
	ROTXR.W R	d	1				
	ROTXR.L ER	Rd	1				
RTE	RTE		2		2		2
RTS	RTS	Normal ^{*1}	2		1		2
		Advanced	2		2		2
SHAL	SHAL.B Rd		1				
	SHAL.W Rd		1				
	SHAL.L ERd		1				
SHAR	SHAR.B Rd		1			 	
	SHAR.W Rd		1				
	SHAR.L ERd		1				

Appendix A Instruction Set

Instruction	Mnemonic		Instruction Fetch I	Branch Addr. Read J	Stack Operation K	-	Word Data Access M	Internal Operation N
SHLL	SHLL.B Rd		1					
	SHLL.W Rd		1					
	SHLL.L ERd		1					
SHLR	SHLR.B Rd		1					
	SHLR.W Rd		1					
SHLR.L ERd			1					
SLEEP	SLEEP		1					
STC	STC CCR, Rd		1					
	STC CCR, @)ERd	2				1	
	STC CCR, @)(d:16, ERd)	3				1	
	STC CCR, @)(d:24, ERd)	5				1	
	STC CCR, @)–ERd	2				1	2
	STC CCR, @)aa:16	3				1	
	STC CCR, @)aa:24	4				1	
SUB	SUB.B Rs, R	d	1					
	SUB.W #xx:1	6, Rd	2					
	SUB.W Rs, R	Rd	1					
	SUB.L #xx:32	2, ERd	3					
	SUB.L ERs, E	ERd	1					
SUBS	SUBS #1/2/4	, ERd	1					
SUBX	SUBX #xx:8,	Rd	1					
	SUBX Rs, Ro	Ł	1					
TRAPA	TRAPA #x:2	Normal ^{*1}	2	1	2			4
		Advanced	2	2	2			4
XOR	XOR.B #xx:8	, Rd	1					
	XOR.B Rs, R	d	1					
	XOR.W #xx:1	16, Rd	2					
	XOR.W Rs, F	۶d	1					
	XOR.L #xx:32	XOR.L #xx:32, ERd						
	XOR.L ERs, I	ERd	2					
XORC	DRC XORC #xx:8, CCR							

Notes: 1. Not available in the H8/3048 Group.

2. n is the value set in register R4L or R4. The source and destination are accessed n + 1 times each.

Appendix B Internal I/O Register

Table B.1 Comparison of H8/3048 Group Internal I/O Register Specifications

Address (Low)	H8/3048 ZTAT	H8/3048 Mask ROM Version, H8/3047 Mask ROM Version, H8/3045 Mask ROM Version, H8/3044 Mask ROM Version	H8/3048F	Module
H'FF40	—	—	FLMCR	Flash memory
H'FF41	—	—	—	
H'FF42	_	—	EBR1	_
H'FF43	—	-	EBR2	
H'FF47	—	_	—	
H'FF48	_	—	RAMCR	

Note: A dash ("—") indicates that access is prohibited. Normal operation is not guaranteed if these addresses are accessed.

B.1 Addresses

		Data									
Address (low)	Register Name	Bus Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module Name
H'1C											
H'1D	-										
H'1E	-										
H'1F	-										
H'20	MAR0AR	8									DMAC
H'21	MAR0AE	8									channel 0A
H'22	MAR0AH	8									
H'23	MAR0AL	8									
H'24	ETCR0AH	8									
H'25	ETCR0AL	8									_
H'26	IOAR0A	8									_
H'27	DTCR0A	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode
			DTE	DTSZ	SAID	SAIDE	DTIE	DTS2A	DTS1A	DTS0A	Full address mode
H'28	MAR0BR	8									DMAC channel 0B
H'29	MAR0BE	8									_
H'2A	MAR0BH	8									
H'2B	MAR0BL	8									
H'2C	ETCR0BH	8									
H'2D	ETCR0BL	8									
H'2E	IOAR0B	8									
H'2F	DTCR0B	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode
			DTME	_	DAID	DAIDE	TMS	DTS2B	DTS1B	DTS0B	Full address mode

A alalaa a a	Deviator	Data	Data Bit Names									
(low)	Register Name	Bus Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	- Module Name	
H'30	MAR1AR	8									DMAC	
H'31	MAR1AE	8									channel 1A	
H'32	MAR1AH	8									_	
H'33	MAR1AL	8									_	
H'34	ETCR1AH	8									_	
H'35	ETCR1AL	8									_	
H'36	IOAR1A	8										
H'37	DTCR1A	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode	
			DTE	DTSZ	SAID	SAIDE	DTIE	DTS2A	DTS1A	DTS0A	Full address mode	
H'38	MAR1BR	8									DMAC	
H'39	MAR1BE	8									- channel 1B	
H'3A	MAR1BH	8										
H'3B	MAR1BL	8									_	
H'3C	ETCR1BH	8									_	
H'3D	ETCR1BL	8									_	
H'3E	IOAR1B	8										
H'3F	DTCR1B	8	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0	Short address mode	
			DTME	_	DAID	DAIDE	TMS	DTS2B	DTS1B	DTS0B	Full address mode	
H'40	FLMCR	8	VPP	VPPE	_	_	EV	PV	E	Р	Flash	
H'41	_	—	—	_	_	_	_	_	_	_	memory	
H'42	EBR1	8	LB7	LB6	LB5	LB4	LB3	LB2	LB1	LB0	_	
H'43	EBR2	8	SB7	SB6	SB5	SB4	SB3	SB2	SB1	SB0	_	
H'44	_	_	_	_	_	_	_	_	_			
H'45	_	_	_	_	_	_	_	_	_	_		
H'46	_	_	_	_	_	_	_	_	_	_		
H'47	_	_	_	_	_	_	_	_	_	_		
H'48	RAMCR	8	FLER	_	_	_	RAMS	RAM2	RAM1	RAM0		
H'49	_	_	_	_	_	_	_	_	_	_		
H'4A	_	_	_	_	_	_	_	_	_	_	_	
H'4B	_	—	—	_	_	_	_	_	_	_	_	
H'4C	_	_	_	_	_	_	_	_	_	_	_	
H'4D	_	-	_	_	_	_	_	_	_	_	_	

Appendix B Internal I/O Register

Address	Pagistar	Data Bus				Bit N	ames				- Module
(low)	Name	Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Name
H'4E	_	_	_	_	_	_	_	_		_	
H'4F	_	—	—	_	—	_	_	_	_	—	-
H'50	_	_	_	—	—	_	_	_	_	_	-
H'51	_	_	_	—	—	_	_	_	_	_	-
H'52	_	_	—	_	—	_	_	_		_	-
H'53	_	_	_	—	—	_	_	_	_	_	-
H'54	_	_	_	—	—	_	_	_	_	_	-
H'55	_	_	—	—	—	—	_	_	_	_	-
H'56	_	_	_	_	_	_	_		_	_	-
H'57	_	_	_	_	_	_	_		_	_	-
H'58	_	_	_	_	_	_	_	_	_	_	-
H'59	_	_	_	_	_	_	_	_	_	_	-
H'5A	_	_	_	_	_	_	_	_	_	_	-
H'5B	_	_	_	_	_	_	_		_	_	-
H'5C	DASTCR	8	—	_	_	_	_	_	_	DASTE	D/A converter
H'5D	DIVCR	8	_	_	_	_	_	_	DIV1	DIV0	System
H'5E	MSTCR	8	PSTOP	_	MSTOP5	MSTOP4	MSTOP3	MSTOP2	MSTOP1	MSTOP0	control
H'5F	CSCR	8	CS7E	CS6E	CS5E	CS4E	_		_	_	Bus controller
H'60	TSTR	8	_	_	_	STR4	STR3	STR2	STR1	STR0	ITU
H'61	TSNC	8	_	_	_	SYNC4	SYNC3	SYNC2	SYNC1	SYNC0	(all channels)
H'62	TMDR	8		MDF	FDIR	PWM4	PWM3	PWM2	PWM1	PWM0	-
H'63	TFCR	8	_	_	CMD1	CMD0	BFB4	BFA4	BFB3	BFA3	-
H'64	TCR0	8	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	ITU
H'65	TIOR0	8	_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	channel 0
H'66	TIER0	8	—	_	_	_	_	OVIE	IMIEB	IMIEA	-
H'67	TSR0	8	_	_	_	_	_	OVF	IMFB	IMFA	-
H'68	TCNT0H	16									-
H'69	TCNT0L	-									-
H'6A	GRA0H	16									-
H'6B	GRA0L	-									-
H'6C	GRB0H	16									-
H'6D	GRB0L	-									-
H'6E	TCR1	8	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	ITU
											channel 1

Address	Register Name	Data Bus	Bit Names										
(low)		Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module Name		
H'70	TIER1	8	_	_	_	_	_	OVIE	IMIEB	IMIEA	ITU channel 1		
H'71	TSR1	8	—	_		_	_	OVF	IMFB	IMFA	_		
H'72	TCNT1H	16									_		
H'73	TCNT1L	_											
H'74	GRA1H	16									_		
H'75	GRA1L	_									_		
H'76	GRB1H	16											
H'77	GRB1L	_									_		
H'78	TCR2	8	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	ITU channel 2		
H'79	TIOR2	8	_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0			
H'7A	TIER2	8	—	_		_	_	OVIE	IMIEB	IMIEA	_		
H'7B	TSR2	8	_	_	_	_	_	OVF	IMFB	IMFA	_		
H'7C	TCNT2H	16									_		
H'7D	TCNT2L	_									_		
H'7E	GRA2H	16									_		
H'7F	GRA2L	_									_		
H'80	GRB2H	16									_		
H'81	GRB2L	_									-		
H'82	TCR3	8	—	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	ITU channel 3		
H'83	TIOR3	8	_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	_		
H'84	TIER3	8	-	_	—	—	_	OVIE	IMIEB	IMIEA	_		
H'85	TSR3	8	-	_	—	—	_	OVF	IMFB	IMFA	_		
H'86	TCNT3H	16									_		
H'87	TCNT3L	_									-		
H'88	GRA3H	16									-		
H'89	GRA3L	_									-		
H'8A	GRB3H	16											
H'8B	GRB3L												
H'8C	BRA3H	16											
H'8D	BRA3L	_											
H'8E	BRB3H	16											
H'8F	BRB3L	_											

Appendix B Internal I/O Register

Addrose	Register Name	Data Bus											
(low)		Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module Name		
H'90	TOER	8	_	_	EXB4	EXA4	EB3	EB4	EA4	EA3	ITU (all		
H'91	TOCR	8	_	_	_	XTGD	_	_	OLS4	OLS3	channels)		
H'92	TCR4	8	_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0	ITU channel		
H'93	TIOR4	8	_	IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0	-		
H'94	TIER4	8	_	_	_	_	_	OVIE	IMIEB	IMIEA	-		
H'95	TSR4	8	_	_	_	_	_	OVF	IMFB	IMFA	-		
H'96	TCNT4H	16									-		
H'97	TCNT4L	_									-		
H'98	GRA4H	16									-		
H'99	GRA4L	_									-		
H'9A	GRB4H	16									-		
H'9B	GRB4L	-									-		
H'9C	BRA4H	16									-		
H'9D	BRA4L	-									-		
H'9E	BRB4H	16									-		
H'9F	BRB4L	-									-		
H'A0	TPMR	8	_	_	_	_	G3NOV	G2NOV	G1NOV	G0NOV	TPC		
H'A1	TPCR	8	G3CMS1	G3CMS0	G2CMS1	G2CMS0	G1CMS1	G1CMS0	G0CMS1	G0CMS0	-		
H'A2	NDERB	8	NDER15	NDER14	NDER13	NDER12	NDER11	NDER10	NDER9	NDER8	-		
H'A3	NDERA	8	NDER7	NDER6	NDER5	NDER4	NDER3	NDER2	NDER1	NDER0	-		
H'A4	NDRB ^{*1}	8	NDR15	NDR14	NDR13	NDR12	NDR11	NDR10	NDR9	NDR8	-		
		8	NDR15	NDR14	NDR13	NDR12	—	_	_	_	-		
H'A5	NDRA ^{*1}	8	NDR7	NDR6	NDR5	NDR4	NDR3	NDR2	NDR1	NDR0	-		
		8	NDR7	NDR6	NDR5	NDR4	—	—	_	—	-		
H'A6	NDRB ^{*1}	8	_	_	_	_	_	_	_	_	-		
		8	_	_	_	_	NDR11	NDR10	NDR9	NDR8	-		
H'A7	NDRA ^{*1}	8	_	_	—	_	—	—	_	—	-		
		8	_	_	_	_	NDR3	NDR2	NDR1	NDR0	-		
H'A8	TCSR*2	8	OVF	WT/ĪT	TME	_	_	CKS2	CKS1	CKS0	WDT		
H'A9	TCNT*2	8									-		
H'AA	_		_	_	_	_	_	_	_	_	-		
H'AB	RSTCSR*3	8	WRST	RSTOE	_	_	_	_	_	_	-		
H'AC	RFSHCR	8	SRFMD	PSRAME	DRAME	CAS/WE	M9/M8	RFSHE	_	RCYCE	Refresh		
H'AD	RTMCSR	8	CMF	CMIE	CKS2	CKS1	CKS0	_	_	_	controller		
H'AE	RTCNT	8									-		
H'AF	RTCOR	8									-		

A	Register Name	Data	Bit Names									
(low)		•	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module Name	
H'B0	SMR	8	C/Ā/GM	CHR	PE	O/E	STOP	MP	CKS1	CKS0	SCI channel 0	
H'B1	BRR	8									-	
H'B2	SCR	8	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	-	
H'B3	TDR	8									=	
H'B4	SSR	8	TDRE	RDRF	ORER	FER/ ERS	PER	TEND	MPB	MPBT	-	
H'B5	RDR	8									=	
H'B6	SCMR	8	_	_	_	_	SDIR	SINV	_	SMIF	-	
H'B7											-	
H'B8	SMR	8	C/A	CHR	PE	O/Ē	STOP	MP	CKS1	CKS0	SCI channel 1	
H'B9	BRR	8									=	
H'BA	SCR	8	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0	-	
H'BB	TDR	8									-	
H'BC	SSR	8	TDRE	RDRF	ORER	FER	PER	TEND	MPB	MPBT	-	
H'BD	RDR	8									-	
H'BE	_		_	_	_	_	_	_	_	_	-	
H'BF											-	
H'C0	P1DDR	8	P17DDR	P1 ₆ DDR	P1₅DDR	P1₄DDR	P1₃DDR	P1 ₂ DDR	P1 ₁ DDR	P1₀DDR	Port 1	
H'C1	P2DDR	8	P27DDR	P2 ₆ DDR	P2₅DDR	P2 ₄ DDR	P2₃DDR	P22DDR	P2 ₁ DDR	P2₀DDR	Port 2	
H'C2	P1DR	8	P17	P1 ₆	P1₅	P14	P1 ₃	P1 ₂	P1 ₁	P10	Port 1	
H'C3	P2DR	8	P2 ₇	P2 ₆	P2 ₅	P2 ₄	P2 ₃	P2 ₂	P2 ₁	P2 ₀	Port 2	
H'C4	P3DDR	8	P37DDR	P3 ₆ DDR	P3₅DDR	P3 ₄ DDR	P3₃DDR	P3 ₂ DDR	P3 ₁ DDR	P3₀DDR	Port 3	
H'C5	P4DDR	8	P47DDR	P4 ₆ DDR	P4₅DDR	P4 ₄ DDR	P4 ₃ DDR	P4 ₂ DDR	P4 ₁ DDR	P4₀DDR	Port 4	
H'C6	P3DR	8	P37	P36	P35	P34	P33	P32	P31	P30	Port 3	
H'C7	P4DR	8	P47	P4 ₆	P4 ₅	P4 ₄	P4 ₃	P4 ₂	P4 ₁	P4 ₀	Port 4	
H'C8	P5DDR	8	_	_	_	_	P5₃DDR	P52DDR	P51DDR	P5₀DDR	Port 5	
H'C9	P6DDR	8	_	P6 ₆ DDR	P6₅DDR	P6 ₄ DDR	P6₃DDR	P6 ₂ DDR	P61DDR	P6₀DDR	Port 6	
H'CA	P5DR	8	_	_	_	_	P53	P5 ₂	P5 ₁	P50	Port 5	
H'CB	P6DR	8	_	P6 ₆	P65	P64	P63	P6 ₂	P61	P60	Port 6	
H'CC	_		_	_	_	_	_	_	_	_		
H'CD	P8DDR	8	_	_	_	P8 ₄ DDR	P8₃DDR	P8 ₂ DDR	P8 ₁ DDR	P8₀DDR	Port 8	
H'CE	P7DR	8	P77	P7 ₆	P75	P74	P73	P72	P7 ₁	P70	Port 7	
H'CF	P8DR	8	_	_	_	P84	P83	P8 ₂	P8 ₁	P8 ₀	Port 8	

Appendix B Internal I/O Register

		Data				Bit N	lames				
Address (low)	Register Name	Bus Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module Name
H'D0	P9DDR	8	_	_	P9₅DDR	P9₄DDR	P9₃DDR	P92DDR	P91DDR	P9₀DDR	Port 9
H'D1	PADDR	8	PA7DDR	PA ₆ DDR	PA ₅ DDR	PA ₄ DDR	PA ₃ DDR	PA ₂ DDR	PA ₁ DDR	PA ₀ DDR	Port A
H'D2	P9DR	8	—	_	P95	P94	P93	P92	P91	P90	Port 9
H'D3	PADR	8	PA ₇	PA ₆	PA ₅	PA ₄	PA ₃	PA ₂	PA ₁	PA ₀	Port A
H'D4	PBDDR	8	PB7DDR	PB ₆ DDR	PB₅DDR	PB₄DDR	PB₃DDR	PB ₂ DDR	PB₁DDR	PB₀DDR	Port B
H'D5	_	_	_	_	_	_	_	_	_	_	_
H'D6	PBDR	8	PB ₇	PB_6	PB₅	PB_4	PB_3	PB ₂	PB_1	PB ₀	Port B
H'D7	_	_	—	_	_	_	_	—	_	_	_
H'D8	P2PCR		P27PCR	P2 ₆ PCR	P2₅PCR	P2₄PCR	P2 ₃ PCR	P2 ₂ PCR	P2 ₁ PCR	P2 ₀ PCR	Port 2
H'D9	—		_	_	_	_	_	_	_	_	
H'DA	P4PCR	8	P47PCR	P4 ₆ PCR	P4₅PCR	P4 ₄ PCR	P4 ₃ PCR	P4 ₂ PCR	P4 ₁ PCR	P4 ₀ PCR	Port 4
H'DB	P5PCR	8	_	_	_	_	P5₃PCR	P5 ₂ PCR	P5 ₁ PCR	P5₀PCR	Port 5
H'DC	DADR0	8									D/A converter
H'DD	DADR1	8									-
H'DE	DACR	8	DAOE1	DAOE0	DAE	_	_	_	_	_	-
H'DF			_	_	_	_	_	_	_	_	-
H'E0	ADDRAH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	A/D converter
H'E1	ADDRAL	8	AD1	AD0	_	_	_	—	_	_	-
H'E2	ADDRBH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	-
H'E3	ADDRBL	8	AD1	AD0	_	_	_	_	_	_	-
H'E4	ADDRCH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	-
H'E5	ADDRCL	8	AD1	AD0	—	_	_	_	_	_	-
H'E6	ADDRDH	8	AD9	AD8	AD7	AD6	AD5	AD4	AD3	AD2	=
H'E7	ADDRDL	8	AD1	AD0	—	_	_	—	_	_	-
H'E8	ADCSR	8	ADF	ADIE	ADST	SCAN	CKS	CH2	CH1	CH0	-
H'E9	ADCR	8	TRGE	_		_	_	_	_	_	-
H'EA	_		_	_	_	_	_	_	_	_	
H'EB	_		_	_	_	_	_	_	_	_	-
H'EC	ABWCR	8	ABW7	ABW6	ABW5	ABW4	ABW3	ABW2	ABW1	ABW0	Bus controller
H'ED	ASTCR	8	AST7	AST6	AST5	AST4	AST3	AST2	AST1	AST0	-
H'EE	WCR	8	_	_	_	_	WMS1	WMS0	WC1	WC0	-
H'EF	WCER	8	WCE7	WCE6	WCE5	WCE4	WCE3	WCE2	WCE1	WCE0	-

		Data				Bit N	lames				
Address (low)	Register Name	Bus Width	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Module Name
H'F0	_		_	_	_	_	_	_	_	_	
H'F1	MDCR	8	—	—	—	—	—	MDS2	MDS1	MDS0	System
H'F2	SYSCR	8	SSBY	STS2	STS1	STS0	UE	NMIEG	_	RAME	control
H'F3	BRCR	8	A23E	A22E	A21E	_	_	_	_	BRLE	Bus controller
H'F4	ISCR	8	—		IRQ5SC	IRQ4SC	IRQ3SC	IRQ2SC	IRQ1SC	IRQ0SC	Interrupt
H'F5	IER	8	_	_	IRQ5E	IRQ4E	IRQ3E	IRQ2E	IRQ1E	IRQ0E	controller
H'F6	ISR	8	_	—	IRQ5F	IRQ4F	IRQ3F	IRQ2F	IRQ1F	IRQ0F	-
H'F7	_		—			_	—	—	—	_	-
H'F8	IPRA	8	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0	-
H'F9	IPRB	8	IPRB7	IPRB6	IPRB5	_	IPRB3	IPRB2	IPRB1	_	-
H'FA	_		—	—	—	—	—	—	—	_	
H'FB	_		_	_	_	_	_	_	_	_	-
H'FC											_
H'FD	_		—	—	—	—	—	—	—	_	-
H'FE	_		_	_	_	_	_	_	_	_	-
H'FF	—		—	—	—	—	—	—	—	_	_

Notes: 1. The address depends on the output trigger setting.

2. For write access to TCSR and TCNT, see section 12.2.4, Notes on Register Access.

3. For write access to RSTCSR, see section 12.2.4, Notes on Register Access.

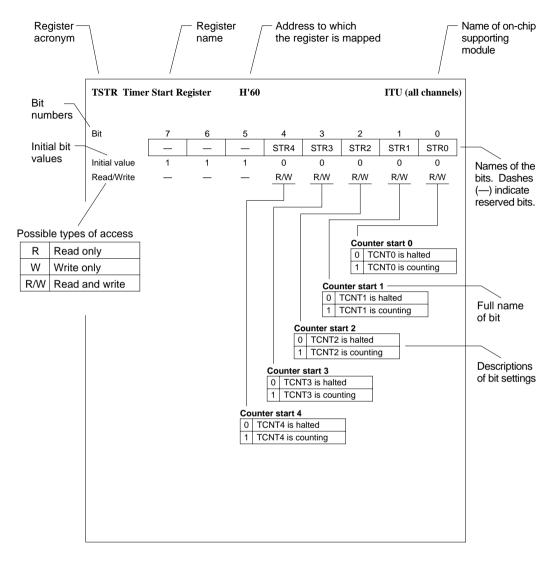
Legend

DMAC: DMA controller

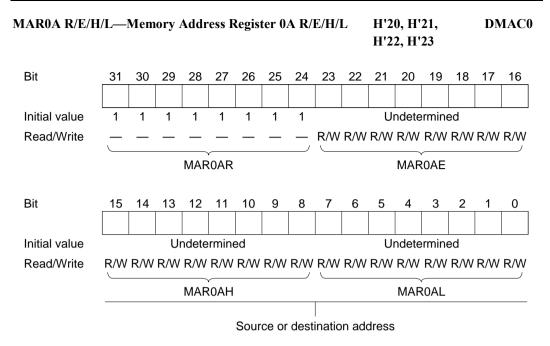
- ITU: 16-bit integrated timer unit
- TPC: Programmable timing pattern controller
- SCI: Serial communication interface
- WDT: Watchdog timer

Renesas

B.2 Function







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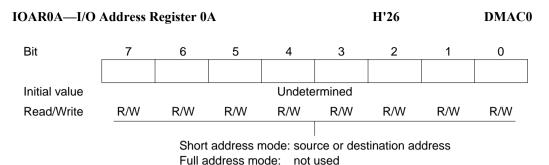
ETCR0A H/L—Execute Transfer Count Register 0A H/L H'24, H'25 **DMAC0** Short address mode • - I/O mode and idle mode Bit 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 Undetermined Initial value Read/Write Transfer counter - Repeat mode Bit 7 4 2 0 6 5 3 1 Initial value Undetermined Read/Write R/W R/W R/W R/W R/W R/W R/W R/W ETCR0AH Transfer counter Bit 7 5 2 6 4 3 1 0 Initial value Undetermined Read/Write R/W R/W R/W R/W R/W R/W R/W R/W **ETCR0AL**

RENESAS

Initial count

ETCR0A H/L-	-Execute (cont)	Transfer	Count R		Н'2	4, H'	DMAC0							
Full address mode														
— Normal n	node													
Bit	15 14	13 12	11 10	9 8	8 7	6	5	4	3	2	1	0		
Initial value	Undetermined													
Read/Write	R/W													
	Transfer counter													
— Block tra	nsfer mod	e												
Bit	7	6	5	4		3		2		1		D		
Initial value				Unde	etermin	ed								
Read/Write	R/W	R/W	R/W	R/W	R	/W	R/	W	R	R/W R/W				
				ET	CR0AH	4								
				Block	ize co	unter								
Bit	7	6	5	4		3	2	2		1	()		
Initial value				Unde	termin	ed								
Read/Write	R/W R/W R/W R/W R/W R/W							/W	R/W					
				ET	CR0AI	-								
				Initial	 block (ozizo								

Initial block size





DTCR0A—Data Transfer Control Register 0A

H'27 DMAC0

• Short address mode

it	7		6	5	4	3	2	1	0
	DTE	= I	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS
itial value	0	I	0	0	0	0	0	0	0
ead/Write	R/V	v	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Data tr	ransfe	r selec	t					
	Bit 2	Bit 1	Bit 0						
	DTS2	DTS1	DTS0	Data Trans	sfer Activat	ion Source			
	0	0	0	Compare I	match/inpu	t capture A	interrupt fro	m ITU char	nnel 0
			1			t capture A			
		1	0			t capture A			
			1	•		t capture A		m ITU char	nnel 3
	1	0	0			mpty interru	pt		
		4	1		ve-data-ful				
		1	0			ss mode (ch	,		
			1	Transfer In	i full addres	ss mode (ch	iannel A)		
D	ata tran	sfer ir	nterrup	ot enable					
	Interru	ıpt requ	lested b	y DTE bit is	disabled				
	Interru	ipt requ	lested b	y DTE bit is	enabled				
Rep	eat ena	ble							
RP		-	ription						
0	0	I/O m	node						
	1								
1	0	Repe	eat mod	е					
	1	Idle r	node						
Data tr	ansfor i	ncrom	ont/de	ecrement					
				MAR is incl	remented h	v 1 after ea	ch transfer		
				MAR is inc					
1 Dec	remente	d: If DT	SZ = 0,	MAR is dec	cremented	by 1 after ea	ach transfei		
		וטזו	32 = 1,	MAR is dec	remented	by 2 arter ea	ach transfei		
Data tran	sfer siz	е							
0 Byte-s	ze transf	er							
1 Word-s	size trans	sfer							
ata transfe	r enabl	е							

- Data transfer enable
- 0 Data transfer is disabled
- 1 Data transfer is enabled

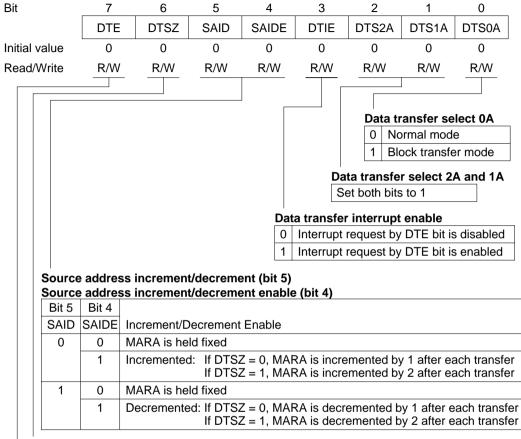
Renesas

DTCR0A—Data Transfer Control Register 0A (cont)

DMAC0

H'27

Full address mode



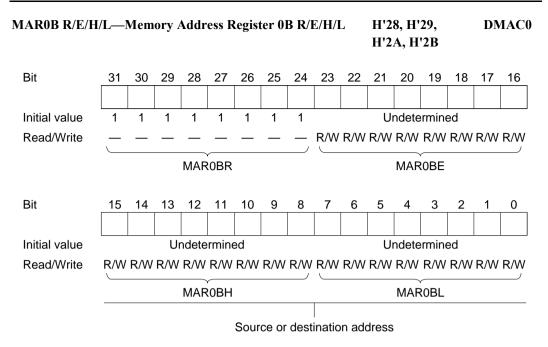
Data transfer size

- 0 Byte-size transfer
- 1 Word-size transfer

Data transfer enable

- 0 Data transfer is disabled
- 1 Data transfer is enabled





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ETCR0B H/L—Execute Transfer Count Register 0B H/L H'2C, H'2D **DMAC0** Short address mode • - I/O mode and idle mode Bit 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 Undetermined Initial value Read/Write Not used - Repeat mode Bit 7 4 2 0 6 5 3 1 Initial value Undetermined Read/Write R/W R/W R/W R/W R/W R/W R/W R/W ETCR0BH Transfer counter Bit 7 5 2 6 4 3 1 0 Initial value Undetermined Read/Write R/W R/W R/W R/W R/W R/W R/W R/W **ETCR0BL**

Initial count

Renesas

ETCR0B H/L-	–Execute (cont)	Transfer	Coui	nt Re	giste	r 0B	H/L		Н'2	С, Н	'2D		DN	1AC0
• Full address	mode													
— Normal r	node													
Bit	15 14	13 12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value							ermine							
Read/Write	R/W R/W	R/W R/W	/ R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
						Not	used							
— Block tra	nsfer mod	e												
Bit	15 14	13 12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	LI				U	ndete	ermine	ed						
Read/Write	R/W R/W	R/W R/W	/ R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				E	Block	trans	sfer c	ounte	er					
IOAR0B—I/O	Address F	Register 0	B						H'2	Е			DN	IAC0
Bit	7	6		5		4		3	2	2		1	()
Initial value		1			Uı	ndete	ermine	ed						
Read/Write	R/W	R/W	R	/W	R/	W/	R/	W	R/	W	R	/W	R/	W
			hort a						destir	natior	add	ress		

Full address mode: not used

DTCR0B—Data Transfer Control Register 0B

• Short address mode

Bit		7	•	6	5	4	3	2	1	0
		DT	E	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0
Initial va	alue	C)	0	0	0	0	0	0	0
Read/W	/rite	R/	W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Γ									
		Data tr								
		Bit 2	Bit 1	Bit 0	Data Ta					
		DTS2	DTS1	DTS0		ansfer Activ				
		0	0	0						U channel 0
				1						U channel 1
			1	0					•	U channel 2
				1					ipt from 11	U channel 3
		1	0	0		nsmit-data				
				1		ceive-data-		ipt		
			1	0	-	edge of DR				
				1	Low leve	el of DREC	2 input			
	Da	ata tran	sfer int	errupt	enable					
	0	Interr	upt requ	uested b	by DTE bit	t is disable	d			
	1					t is enable				
		An int	errupt r	request	is issued	to the CPL	J when the	DTE bit =	= 0	
	Repe	eat enab	ble							
	RPE			cription						
	0	0	I/O I	node						
		1								
	1	0	Rep	eat mod	de					
		1	Idle	mode						
Dat	ta tra	ansfer i	ncreme	ent/deci	rement					
0	Incr	emente	d: If D	TSZ = C), MAR is	incremente	ed by 1 af	ter each tra	ansfer	
						incremente				
1	Dec	crement				decrement				
			lf D	ISZ = 1	, MAR IS	decrement	ted by 2 a	iter each ti	ranster	
		fer size		1						
		ize tran								
1 W	Vord-	size trai	nsfer]						
Data tra			-							
0 Data	a tran	sfer is c	disabled	1						



DTCR0B—Data Transfer Control Register 0B (cont)

H'2F DMAC0

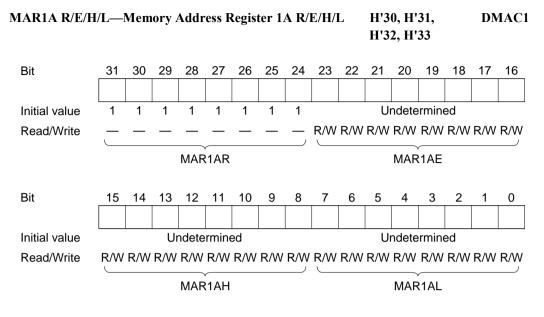
• Full address mode

Bit		7	6	5	4	:	3	2	1	0			
		DTME	_	DAID	DAIDE	TN	ЛS	DTS2B	DTS1B	DTS0B			
nitial valu	le 🗌	0	0	0	0	()	0	0	0			
Read/Writ	te	R/W	R/W	R/W	R/W	R/	W	R/W	R/W	R/W			
			10,11										
]								
]						
	Data ti	ransfer	select 2	2B to 0B									
	Bit 2	Bit 1	Bit 0		Data Trans	fer A	ctiva	tion Source	е				
	DTS2E	BDTS1B	DTS0B	Normal Mo	de		Blo	ck Transfe	r Mode				
	0	0	0	Auto-reque (burst mode			Cor A fr	npare mat om ITU ch	ch/input ca annel 0	apture			
			1	Not availab	le		Compare ma A from ITU c			apture			
		1	0	Auto-reque (cycle-steal				npare mat om ITU ch		apture			
			1	Not availab				npare mat om ITU ch		apture			
	1	0	0	Not availab	le		Not	available					
			1	Not availab	le		Not	available					
		1	0	Falling edg	e of DREC	<u></u>	Fall	ing edge c	f DREQ				
			1	Low level input at DREQ Not available									
Tra	nsfer r	node se	lect										
0	Destir	nation is	the bloc	k area in blo	ock transfe	r moo	de						
1	Sourc	e is the b	olock ar	ck area in block transfer mode									
Destin	ation a	ddress	increm	ent/decreme	ent (bit 5)								
Destina	ation a	ddress	ess increment/decrement enable (bit 4)										
Bit 5	Bit 4												
DAID	DAIDE	Increm	ent/De	crement Ena	ble								
0	0	MARB	is held	fixed									
	1	Increm	nented:	If DTSZ = 0 If DTSZ = 1									
1	0	MARB	is held	fixed									
	1	Decrer	mented	If DTSZ = 0	, MARB is , MARB is								

Data transfer master enable

- 0 Data transfer is disabled
- 1 Data transfer is enabled

Renesas



Note: Bit functions are the same as for DMAC0.



ETCR1A H/L-	-Exe	cute	Tran	sfer	Cou	nt Re	giste	r 1A	H/L		H'3	4, H'	35		DN	IAC1
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value							U	ndete	ermine	ed						
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Bit	7	7		6		5		4	3	3	2	2		1	()
Initial value			1				U	ndete	rmine	əd						
Read/Write	R/	W	R	/W	R	/W	R/	W/	R/	W	R/	W	R/	W/	R/	Ŵ
								ETC	, R1A⊢	ł						
Bit	7	7		6	:	5	4	4	3	3	2	2		1	()
Initial value							U	ndete	rmine	ed						
Read/Write	R/	W	R	/W	R	/W	R/	W/	R/	W	R/	W	R/	W/	R/	Ŵ
								ETC	R1AL	-						_

Note: Bit functions are the same as for DMAC0.

IOAR1A—I/O	Address H	Register 1	A			Н'36		DMAC1	
Bit	7	6	5	4	3	2	1	0	
Initial value				Undete	regio o d				
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	

Note: Bit functions are the same as for DMAC0.

DTCR1A—Data Transfer Control Register 1A

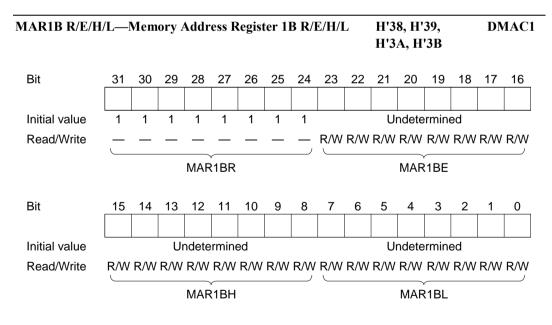
• Short address mode

Bit	7	6	5	4	3	2	1	0
	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Full address mode

Bit	7	6	5	4	3	2	1	0
	DTE	DTSZ	SAID	SAIDE	DTIE	DTS2A	DTS1A	DTS0A
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Note: Bit functions are the same as for DMAC0.



Note: Bit functions are the same as for DMAC0.

RENESAS

H'37

ETCR1B H/L-	–Exe	cute	Tran	sfer	Cou	nt Re	giste	r 1B	H/L		Н'3	С, Н	'3D		DN	IAC1
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value		•					U	ndete	ermine	ed						
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	' R/W	R/W
Bit		7		6		5		4	3	3		2		1	()
Initial value							U	ndete	rmine	ed			1			
Read/Write	R	/W	R	/W	R	/W	R/	W/	R/	W	R/	W	R/	W/	R/	Ŵ
	-							ETC	R1B⊦	ł						_
Bit		7	I	6	1	5	4	4	3	3	2	2		1	()
Initial value								ndete	ermine	-d						
Read/Write	R	/W	R	/W	R	/W	-	W	R/		R/	W	R/	W/W	R/	Ŵ
								ETCI	R1BL	-						

Note: Bit functions are the same as for DMAC0.

IOAR1B—I/O	Address H	Register 1	В			H'3E		DMAC	1
Bit	7	6	5	4	3	2	1	0	1
Initial value					ermined]
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	

Note: Bit functions are the same as for DMAC0.

DTCR1B—Data Transfer Control Register 1B

DMAC1

H'3F

• Short address mode

Read/Write

Bit	7	6	5	4	3	2	1	0
	DTE	DTSZ	DTID	RPE	DTIE	DTS2	DTS1	DTS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
 Full address i 	mode							
Bit	7	6	5	4	3	2	1	0
Dit	1	0	-		-	_	•	-
	DTME	—	DAID	DAIDE	TMS	DTS2B	DTS1B	DTS0B
Initial value	0	0	0	0	0	0	0	0

R/W

R/W

R/W

R/W

R/W

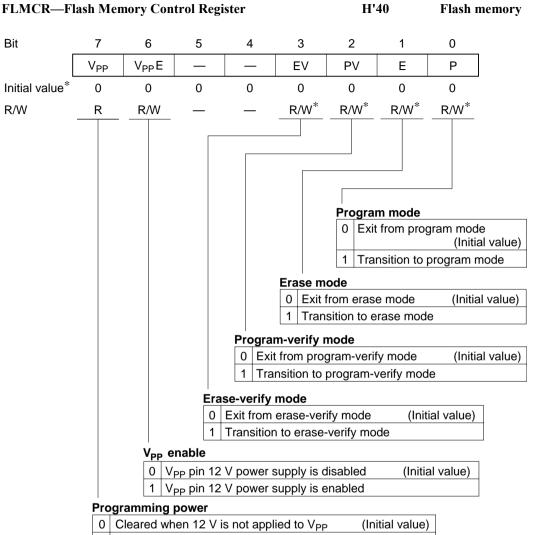
Note: Bit functions are the same as for DMAC0.

R/W

R/W

R/W





- 1 Set when 12 V is applied to V_{PP}
- Note: * The initial value is H'00 in modes 5, 6, and 7 (on-chip flash memory enabled). In modes 1, 2, 3, and 4 (on-chip flash memory disabled), this register cannot be modified and is always read as H'FF.

H8/3048F	Include this register
H8/3048ZTAT H8/3048 mask ROM version H8/3047 mask ROM version H8/3045 mask ROM version H8/3044 mask ROM version	Not include this register

EBR1—Erase	Block R	egister 1				Н'42	2	Flash memory
Bit	7	6	5	4	3	2	1	0
	LB7	LB6	LB5	LB4	LB3	LB2	LB1	LB0
Initial value*	0	0	0	0	0	0	0	0
R/W	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*	R/W*
			Large	e block 7	to 0			
	0 Block LB7 to LB0 is not selected (Initial value)							ial value)
	1 Block LB7 to LB0 is selected							

Note: * The initial value is H'00 in modes 5, 6, and 7 (on-chip flash memory enabled). In modes 1, 2, 3, and 4 (on-chip flash memory disabled), this register cannot be modified and is always read as H'FF.

H8/3048F	Include this register
H8/3048ZTAT H8/3048 mask ROM version H8/3047 mask ROM version H8/3045 mask ROM version H8/3044 mask ROM version	Not include this register



EBR2—Erase	Block	Register	2
------------	-------	----------	---

Bit	7	6	5	4	3	2	1	0
	SB7	SB6	SB5	SB4	SB3	SB2	SB1	SB0
Initial value*	0	0	0	0	0	0	0	0
R/W	R/W^*	R/W*	R/W^*	R/W*	R/W^*	R/W*	R/W*	R/W*
			Smal	l block 7	to 0			
			0 E	Block SB7	to SB0 is	not selec	ted (Init	tial value)
			1 E	Block SB7	to SB0 is	selected		

Note: * The initial value is H'00 in modes 5, 6, and 7 (on-chip flash memory enabled). In modes 1, 2, 3, and 4 (on-chip flash memory disabled), this register cannot be modified and is always read as H'FF.

H8/3048F	Include this register
H8/3048ZTAT H8/3048 mask ROM version H8/3047 mask ROM version H8/3045 mask ROM version H8/3044 mask ROM version	Not include this register

RAMCR—RAM Control Register

Flash
Flash

H'48

Flash memory

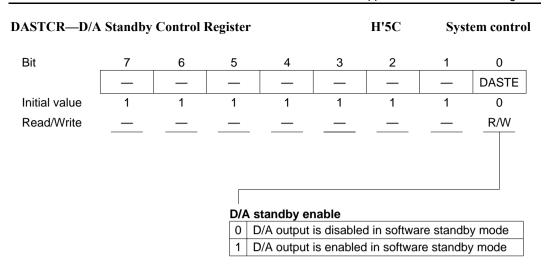
Bit	7	6	5	4	3	2	1	0	_
	FLER			—	RAMS	RAM2	RAM1	RAM0]
Initial value	0	1	1	1	0	0	0	0	-
R/W	R	_	_	_	R/W	R/W	R/W	R/W	
			RAM se	lect, RA	M 2 to R	AM 0			
			Bit 3	Bit 2	Bit 1	Bit 0			
			RAMS	RAM 2	RAM 1	RAM 0	RAM Area	a	
			0	1/0	1/0	1/0	H'FFF000	to H'FFF	1FF
			1	0	0	0	H'01F000	to H'01F	1FF
						1	H'01F200	to H'01F	3FF
					1	0	H'01F400	to H'01F	5FF
						1	H'01F600	to H'01F	7FF
				1	0	0	H'01F800	to H'01F	9FF
						1	H'01FA00) to H'01F	BFF
					1	0	H'01FC00) to H'01F	DFF
						1	H'01FE00) to H'01F	FFF

Flash memory error

0	Flash memory is not write/erase-protected	(Initial value)
	(is not in error protect mode)	
1	Flash memory is write/erase-protected	
	(is in error protect mode)	

H8/3048F	Include this register
H8/3048ZTAT H8/3048 mask ROM version H8/3047 mask ROM version H8/3045 mask ROM version H8/3044 mask ROM version	Not include this register





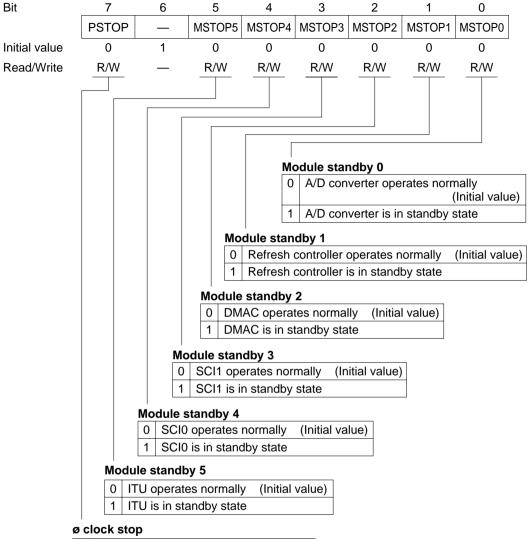
DIVCR—Divisi	on Contr	ol Registe	r			H'5D	Syste	em control
Bit	7	6	5	7	3	2	1	0
	—	—	—	—		_	DIV1	DIV0
Initial value	1	1	1	1	1	1	0	0
Read/Write							R/W	R/W

Bit 1	Bit 0	_
	DILU	Frequency
DIV1	DIV0	Division Ratio
0	0	1/1
	1	1/2
1	0	1/4
	1	1/8

MSTCR—Module Standby Control Register

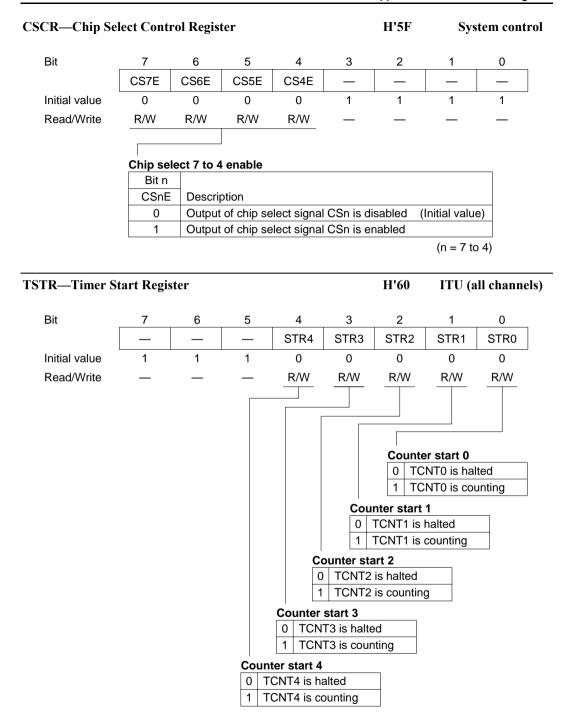






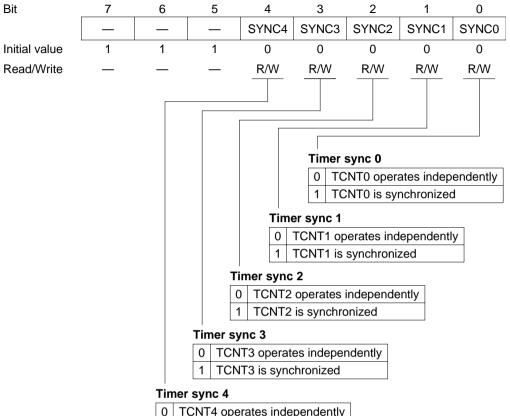
0	ø clock output is enabled	(Initial value)
---	---------------------------	-----------------

1 ø clock output is disabled



TSNC—Timer Synchro Register



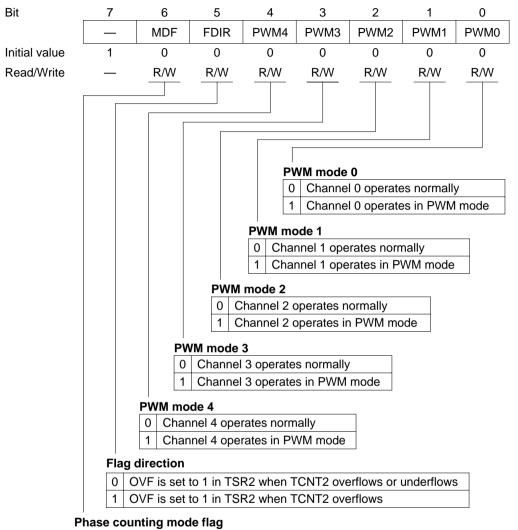


0	rontri i oporacoo inaoponac
1	TCNT4 is synchronized



TMDR—Timer Mode Register

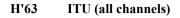
H'62 ITU (all channels)

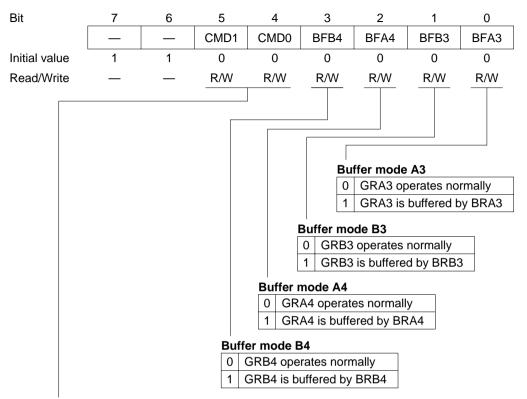


0 Channel 2 operates normally

1 Channel 2 operates in phase counting mode

TFCR—Timer Function Control Register





Combination mode 1 and 0

Bit 5	Bit 4	
CMD1	CMD0	Operating Mode of Channels 3 and 4
0	0	Channels 3 and 4 operate normally
	1	
1	0	Channels 3 and 4 operate together in complementary PWM mode
	1	Channels 3 and 4 operate together in reset-synchronized PWM mode

TCR0—Timer Control Register 0

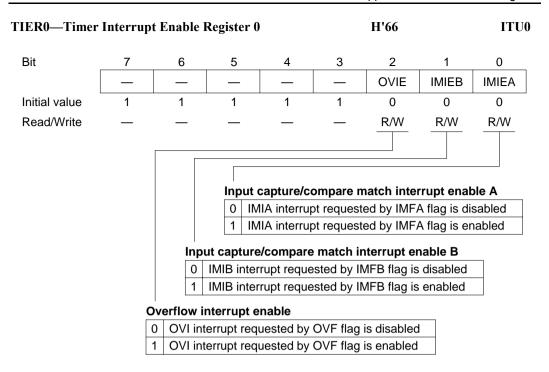
7	6	5	4	3	2	1	0						
_	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0						
1	0	0	0	0	0	0	0						
_	R/W	R/W	R/W	R/W	R/W	R/W	R/W						
Γ													
	Timer	r prescaler 2 to 0											
	Bit 2	Bit 1	Bit 0										
	TPSC	2 TPSC1	TPSC0	TCNT Cloc	ck Source								
	0	0	0	Internal clo	ock: ø								
			1										
		1	0										
	1	0											
		1											
						•							
			•	External of	000 0. 10								
						_							
				. –									
CK					hal Clock	_							
						-							
			<u> </u>			-							
			euges c	ounted									
		and 0											
				~~									
	-				noare mate	ch or input	capture						
1				-									
	1	Synchror	nous clea	ar: TCNT is	cleared in								
	1 	− CCLR1 1 0 − R/W Timer Bit 2 TPSC 0 1 1 0 1 1 0 1 1 0 0 0 0 1 1 0 0 0 1 1 0 0 1 1 1 0 1 1 0 0 1 0 1 0 1 1	CCLR1 CCLR0 1 0 0 - R/W R/W Timer prescale Bit 2 Bit 1 TPSC2 TPSC1 0 0 0 1 1 0 0 1 1 0 1 0 0 1 1 1 1 0 0 Bit 4 Bit 3 CKEG1CKEG0 Courter clear 1 and 0 Bit 4 Bit 5 CCLR1 CCLR0 CCLR1 CCLR0 TCNT clear 0 0 TCNT is 1 0 TCNT is 1 0 TCNT is 1 0 TCNT is	CCLR1 CCLR0 CKEG1 1 0 0 0 - R/W R/W R/W Timer prescaler 2 to 0 Bit 2 Bit 1 Bit 0 TPSC2 TPSC1 TPSC0 0 0 0 0 0 1 1 1 0 0 1 1 1 0 0 1 1 1 0 0 1 1 1 0 0 1 1 1 0 0 1 1 1 0 0 1 1 1 0 0 1 1 1 0 0 1 1 1 0 Rising edges 1 1 1 1 - Both edges c 1 - Both edges c 1 - Bit 5 CCLR1 CCLR0 TCNT Clear Sour 0 0	CCLR1 CCLR0 CKEG1 CKEG0 1 0 0 0 0 R/W R/W R/W R/W R/W Timer prescaler 2 to 0 Bit 2 Bit 1 Bit 0 TCNT Close 0 0 0 0 Internal close 1 Internal close 0 0 0 Internal close 1 Internal close Internal close 1 Internal close Intexternal close Internal close	CCLR1 CCLR0 CKEG1 CKEG0 TPSC2 1 0 0 0 0 0 R/W R/W R/W R/W R/W R/W Timer prescaler 2 to 0 Bit 2 Bit 1 Bit 0 TCNT Clock Source 0 0 Internal clock: \$\phi\$ 0 0 0 Internal clock: \$\phi\$ 1 Internal clock: \$\phi\$ 1 1 0 Internal clock: \$\phi\$ 1 Internal clock: \$\phi\$ 1 1 0 Internal clock: \$\phi\$ 1 Internal clock C: \$\phi\$ 1 1 0 External clock B: TC 1 External clock B: TC 1 1 0 External clock C: TC 1 External clock D: TC 1 1 0 External clock D: TC 1 External clock D: TC 1 0 External clock D: TC 1 External clock D: TC 1 0 Rising edges counted 1 Internal clock D: TC 0 0	CCLR1 CCLR0 CKEG1 CKEG0 TPSC2 TPSC1 1 0 0 0 0 0 0 0 - R/W R/W						

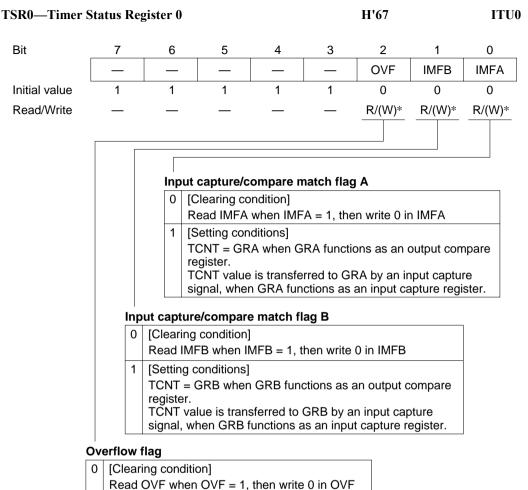
7	6	5	4	3	2	1	0
_	IOB2	IOB1	IOB0	—	IOA2	IOA1	IOA0
1	0	0	0	1	0	0	0
_	R/W	R/W	R/W	_	R/W	R/W	R/W
	7 — 1 —	- IOB2 1 0	IOB2 IOB1 1 0 0	IOB2 IOB1 IOB0 1 0 0 0	IOB2 IOB1 IOB0 1 0 0 0 1	IOB2 IOB1 IOB0 IOA2 1 0 0 0 1 0	IOB2 IOB1 IOB0 IOA2 IOA1 1 0 0 0 1 0 0

Bit 2	Bit 1	Bit 0		
IOA2	IOA1	IOA0	GRA Function	
0	0	0	GRA is an output	No output at compare match
		1	compare register	0 output at GRA compare match
	1	0		1 output at GRA compare match
		1		Output toggles at GRA compare match
1	0	0	GRA is an input	GRA captures rising edge of input
		1	capture register	GRA captures falling edge of input
	1	0		GRA captures both edges of input
		1		

I/O control B2 to B0

-				
Bit 6	Bit 5	Bit 4		
IOB2	IOB1	IOB0	GRB Function	
0	0	0	GRB is an output	No output at compare match
		1	compare register	0 output at GRB compare match
	1	0		1 output at GRB compare match
		1		Output toggles at GRB compare match
1	0	0	GRB is an input	GRB captures rising edge of input
		1	capture register	GRB captures falling edge of input
	1	0		GRB captures both edges of input
		1		

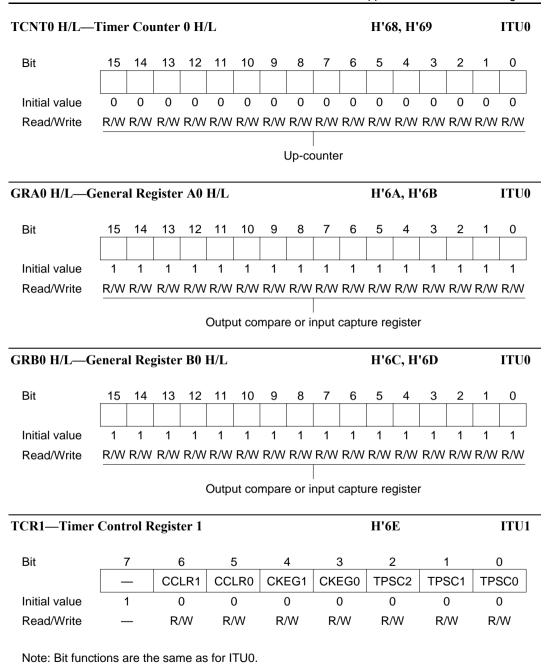




1 [Setting condition] TCNT overflowed from H'FFFF to H'0000 or underflowed from H'0000 to H'FFFF

Note: * Only 0 can be written, to clear the flag.





TIOR1—Timer	· I/O	Cont	rol R	H'6F							ITU1							
Bit	7	7	(6	!	5	4	4	3	3		2		1	()		
	_	_	IO	B2	IO	B1	10	B0	_	_	10	A2	IO	A1	IO	A0		
Initial value		1	(0	(0	(0		1	0			0)		
Read/Write	-	_	R/	W	R	/W	R	/W	-	_	R/	W	R	/W	R/W			
Note: Bit functions are the same as for ITU0.																		
TIER1—Timer Interrupt Enable Register 1 H'70																ITU1		
Bit		7		6		5	4	4		3		2		1	()		
	-	_	-	_	-	_	-	_	-	_	0\	/IE	IM	IEB	IMI	EA		
Initial value		1		1		1		1		1	. ()		0	. ()		
Read/Write													— R/W R/W					
Note: Bit functions are the same as for ITU0. TSR1—Timer Status Register 1 H'71															ITU1			
Bit		7	(6	5		4		3		2		1		0			
	-	_	_	_	-	_	-			_	OVF		IMFB		IMFA			
Initial value		1		1		1		1		1	. ()		0	()		
Read/Write	-	_	-	_	-		-	_	-	-	R/(W)*	R/(W)*	R/(W)*		
Notes: Bit func * Only																		
TCNT1 H/L—7	lime	r Cou	inter			H'7	2, H'	73			ITU1							
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		

GRA1 H/L—G	GRA1 H/L—General Register A1 H/L															ITU1
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	/ R/W	R/W	' R/W	R/W	/ R/W	R/W	R/W	R/W	R/W	R/W	/ R/W	R/W
Note: Bit functions are the same as for ITU0.																
GRB1 H/L—G	enera	l Re	gister	• B1	H/L						H'7	6, H'	77			ITU1
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	/ R/W	R/W	' R/W	R/W	/ R/W	R/W	' R/W	R/W	R/W	R/W	/ R/W	R/W
Note: Bit funct	ions a	are th	e sar	ne as	s for l	TU0.										
TCR2—Timer	Cont	rol R	legist	er 2							H'7	8				ITU2
Bit	7		6		5		4		3		2		1		0	
			CCL	R1	CCL	R0	CKE	G1	CKE	G0	TPS	C2	TPS	C1	TPS	C0
Initial value	1		0		0		0		0		0		0		0	
Read/Write			R/V	V	R/V	V	R/V	V	R/V	V	R/V	V	R/V	V	R/\	V

Notes: 1. Bit functions are the same as for ITU0.

2. When channel 2 is used in phase counting mode, the counter clock source selection by bits TPSC2 to TPSC0 is ignored.

TIOR2—Timer	r I/O Con	trol Regis	ter 2			H'79		ITU2							
Bit	7	6	5	4	3	2	1	0							
	_	IOB2	IOB1	IOB0		IOA2	IOA1	IOA0							
Initial value	1	0	0	0	1	0	0	0							
Read/Write	—	R/W	R/W	R/W	_	R/W	R/W	R/W							
Note: Bit funct	ions are th	ne same as	s for ITU0.												
TIER2—Timer	TIER2—Timer Interrupt Enable Register 2 H'7A IT														
Bit	7	6	5	4	3	2	1	0							
				_		OVIE	IMIEB	IMIEA							
Initial value	1	1	1	1	1	0	0	0							
Read/Write	—	—	—	_	—	R/W	R/W	R/W							
TSR2—Timer	Status Re	gister 2				H'7B		ITU2							
Bit	7	6	5	4	3	2	1	0							
	—	—	_		_	OVF	IMFB	IMFA							
Initial value	1	1	1	1	1	0	0	0							
Read/Write	_	—	_	—	—	R/(W)*	R/(W)*	R/(W)*							
Notes: Bit functions are the same as for ITU0. * Only 0 can be written, to clear the flag. The function is the same as ITU0. Overflow flag															
			0 [Cl	earing con	dition]	4. 44 47 5									
			1 [Se The	etting cond e TCNT va	lition] alue overfl	= 1, then v lows (from 0000 to H'l	H'FFFF to								

TCNT2 H/L	ГСNT2 H/L—Timer Counter 2 H/L															ITU2
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	' R/W
Phase counting mode: up/down counter Other modes: up-counter																
GRA2 H/L—G	GRA2 H/L—General Register A2 H/L H'7E, H'7F															ITU2
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	•	•	•	-	-	•	-	-	•	-	-	•	•	•	•	•
	Read/Write R/W															
GRB2 H/L—G	enera	l Reg	gister	r B2	H/L						Н'8	0, H'	81			ITU2
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Note: Bit functions are the same as for ITU0.

TCR3—Timer	H'82			ITU3						
Bit	7	6	5	4	3	2	1	0		
		CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0		
Initial value	1	0	0	0	0	0	0	0		
Read/Write	—	R/W								
Note: Bit functions are the same as for ITU0.										
TIOR3—Timer I/O Control Register 3						ITU3				
Bit	7	6	5	4	3	2	1	0		
		IOB2	IOB1	IOB0	_	IOA2	IOA1	IOA0		
Initial value	1	0	0	0	1	0	0	0		
Read/Write	—	R/W	R/W	R/W	—	R/W	R/W	R/W		
Note: Bit functions are the same as for ITU0.										
TIER3—Timer	H'84			ITU3						
Bit	7	6	5	4	3	2	1	0		
				_		OVIE	IMIEB	IMIEA		
Initial value	1	1	1	1	1	0	0	0		

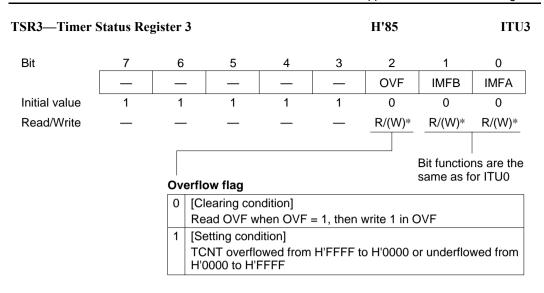
R/W R/W

R/W

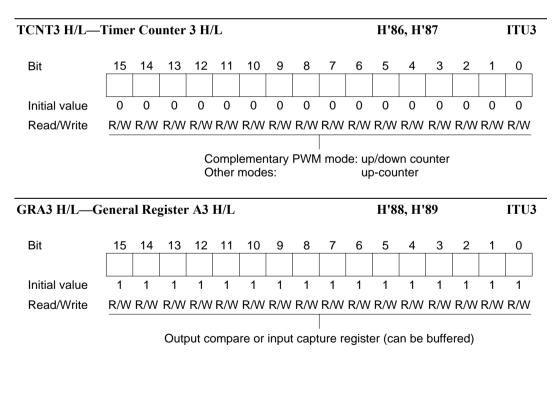
Note: Bit functions are the same as for ITU0.

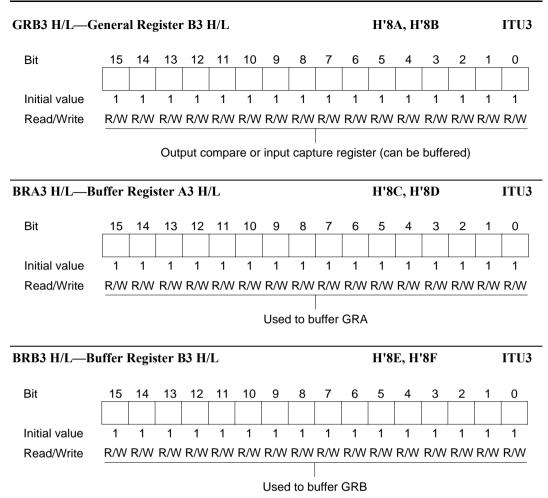
Read/Write



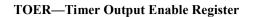


Note: * Only 0 can be written, to clear the flag.



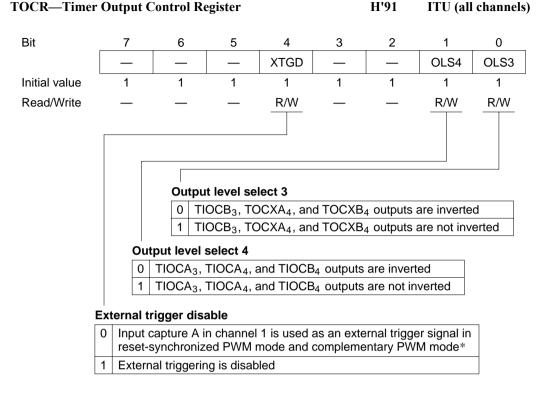






Bit	7	6	5	4	3	2	1	0	
	_	_	EXB4	EXA4	EB3	EB4	EA4	EA3	
Initial value	1	1	1	1	1	1	1	1	
Read/Write	_	_	R/W	R/W	R/W	R/W	R/W	R/W	
	Master en		-						
	0 TIOCA ₃ output is disabled regardless of TIOR3, TMDR, and TFCR settings								
1 TIOCA ₃ is enabled for output according to TIOR3, TMDR, and TFCR settings									
Master enable TIOCA4									
0 TIOCA ₄ output is disabled regardless of TIOR4, TMDR, and TFCR settings									
1 TIOCA ₄ is enabled for output according to TIOR4, TMDR, and TFCR settings									
Master enable TIOCB4									
			hled reas	rdless of T	IOR/ and	TECR sot	tings		
 0 TIOCB₄ output is disabled regardless of TIOR4 and TFCR settings 1 TIOCB₄ is enabled for output according to TIOR4 and TFCR settings 									
			i ouipui ai				settings		
	enable TIC								
	CB ₃ outpu								
1 TIC	DCB ₃ is ena	abled for o	utput acco	ording to TI	OR3 and	TFCR sett	ings		
Master er	nable TOCX	(A4							
	KA ₄ output i	s disabled	regardles	s of TFCR	settings				
1 TOC	KA ₄ is enabl	led for out	put accord	ling to TFC	CR setting	5			
	·			-					
Master enab			aordiooc		ttingo				
	₁ output is d	isableu le	yaruless 0		ungs				

- 0 TOCXB₄ output is disabled regardless of TFCR settings
- 1 TOCXB₄ is enabled for output according to TFCR settings



Note: * When an external trigger occurs, bits 5 to 0 in TOER are cleared to 0, disabling ITU output.



								0
TCR4—Timer	Control F	Register 4				Н'92		ITU4
Bit	7	6	5	4	3	2	1	0
		CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0
Initial value	1	0	0	0	0	0	0	0
Read/Write	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Note: Bit functi	ons are th	ne same as	s for ITU0.					
ГIOR4—Timer	I/O Con	trol Regis	ter 4			Н'93		ITU4
Bit	7	6	5	4	3	2	1	0
		IOB2	IOB1	IOB0		IOA2	IOA1	IOA0
Initial value	1	0	0	0	1	0	0	0
Read/Write	—	R/W	R/W	R/W	—	R/W	R/W	R/W
Note: Bit functi	ons are th	ne same as	s for ITU0.					
ГIER4—Timer	Interrup	t Enable l	Register 4	ļ		Н'94		ITU4
Bit	7	6	5	4	3	2	1	0
		_		_	_	OVIE	IMIEB	IMIEA
Initial value	1	1	1	1	1	0	0	0
Read/Write	—		—	—	—	R/W	R/W	R/W
Note: Bit functi	ons are th	ie same as	s for ITU0.					
ГSR4—Timer S	Status Re	gister 4				Н'95		ITU4
Bit	7	6	5	4	3	2	1	0
					_	OVF	IMFB	IMFA
Initial value	1	1	1	1	1	0	0	0
Read/Write	—	—	—	—	—	R/(W)*	R/(W)*	R/(W)*

Notes: Bit functions are the same as for ITU0.

* Only 0 can be written, to clear the flag.

TCNT4 H/L-7	Fime	r Cou	inter	• 4 H/	/L						Н'9	6, H'	97			ITU4
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Note: Bit funct	ions a	are th	e sar	ne as	s for l	TU3.										
GRA4 H/L—G	enera	al Re	giste	r A4	H/L						H'9	8, H'	99			ITU4
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Note: Bit funct	ions a	are th	e sar	ne as	s for I	TU3.										
GRB4 H/L—G	enera	l Re	gister	r B4	H/L						Н'9	A, H	'9B			ITU4
GRB4 H/L—G	enera	ıl Reş	gistei	r B 4	H/L						Н'9	A, H	'9B			ITU4
GRB4 H/L—G	enera 15	l Reg 14	gister 13	r B4	H/L 11	10	9	8	7	6	H'9 5	A, H	'9 B 3	2	1	ITU4 0
			13	12	11						5	4	3	2		
Bit Initial value	15	14	13	12	11	1	1	1	1	1	5	4	3	1	1	0
Bit	15	14	13	12	11	1	1	1	1	1	5	4	3	1	1	0
Bit Initial value	15 1 R/W	14 1 R/W	13 1 R/W	12 1 7 R/W	11 1 7 R/W	1 R/W	1	1	1	1	5	4	3	1	1	0
Bit Initial value Read/Write	15 1 R/W	14 1 R/W are th	13 1 R/W e sar	12 1 7 R/W	11 1 7 R/W	1 R/W	1	1	1	1	5 1 R/W	4	3 1 R/W	1	1	0
Bit Initial value Read/Write Note: Bit funct	15 1 R/W	14 1 R/W are th	13 1 R/W e sar	12 1 7 R/W	11 1 7 R/W	1 R/W	1	1	1	1	5 1 R/W	4 1 R/W	3 1 R/W	1	1	0 1 R/W
Bit Initial value Read/Write Note: Bit funct BRA4 H/L—Bu	15 1 R/W ions a	14 1 R/W are th Regis	13 1 R/W e sar	12 1 7 R/W me as	11 1 7 R/W s for I	1 R/W TU3.	1 R/W	1 R/W	1 R/W	1 R/W	5 1 R/W H'9	4 1 R/W	3 1 R/W	1 R/W	1 1 R/W	0 1 R/W ITU4
Bit Initial value Read/Write Note: Bit funct BRA4 H/L—Bu	15 1 R/W ions a	14 1 R/W are th Regis	13 1 R/W e sar	12 1 7 R/W me as	11 1 7 R/W s for I	1 R/W TU3.	1 R/W	1 R/W	1 R/W	1 R/W	5 1 R/W H'9	4 1 R/W	3 1 R/W	1 R/W	1 1 R/W	0 1 R/W ITU4
Bit Initial value Read/Write Note: Bit funct BRA4 H/L—Bu Bit	15 1 R/W ions a uffer 15	14 1 R/W are th Regis	13 1 R/W e sar 13 1	12 1 7 R/W ne as A4 H 12	11 1 7 R/W 8 for I 7/L 11	1 R/W TU3. 10	1 R/W 9	1 R/W 8 1	1 R/W 7 1	1 R/W 6 1	5 1 R/W H'9 5 1	4 1 R/W C, H 4 1	3 1 R/W '9D 3 1	1 R/W 2 1	1 1 R/W	0 1 R/W ITU4 0 1

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BRB4 H/L—B	uffer Regi	ster B4 H	/L					H'9	E, H'	'9F			ITU4
Bit	15 14	13 12	11 10	9	8	7	6	5	4	3	2	1	0
Initial value	1 1	1 1	1 1	1	1	1	1	1	1	1	1	1	1
Read/Write Note: Bit funct		R/W R/W			R/W	′ R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
TPMR—TPC	Output M	ode Regis	ter					H'A	.0				TPC
Bit	7	6	5	4	4	3	3	2	2	,	1	()
	_	_	—	-	_	G3N	IOV	G2N	IOV	G1N	VOV	GON	VOV
Initial value	1	1	1		1	()	()	(C	()
Read/Write	—	—	—	-	_	R/	W	_R/	W	R/	W_	R/	W
	0No1No3AGroup 1 n0NormaOutpu1Non-o	al TPC outp t values ch verlapping B in the se	butput in g change a ing TPC c e selected p but in grou ange at co TPC outp	ip 1 output of 1 ompa	in grou	roup (nel atch <i>A</i>), cor A in tł	ntrolle ne se	ed by	comp d ITU	oare i I chai	matcl	
0	Normal T Output va Non-over	PC output llues chang lapping TP n the selec	ge at comp C output i	pare r n gro	up 2,							I	
	3 non-ov ormal TPC utput value	output in g s change a	at compare]	
1 No A a	on-overlapp and B in th	oing TPC c e selected	utput in g ITU chan	roup (nel	3, co	ntrolle	ed by	com	oare	matc	h		



Bit	7	6	5	4	3	2	1	0
	G3CMS1	G3CMS0	G2CMS1	G2CMS0	G1CMS1	G1CMS0	G0CMS1	G0CMS0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

H'A1

TPC

 ITU Channel Selected as Output Trigger TPC output group 0 (TP₃ to TP₀) is triggered by compare match in ITU channel 0
TPC output group 0 (TP ₃ to TP ₀) is triggered by compare match in ITU channel 0
TPC output group 0 (TP ₃ to TP ₀) is triggered by compare match in ITU channel 1
TPC output group 0 (TP ₃ to TP ₀) is triggered by compare match in ITU channel 2
TPC output group 0 (TP ₃ to TP ₀) is triggered by compare match in ITU channel 3
-

Group 1 compare match select 1 and 0

Bit 3	Bit 2	
G1CMS1	G1CMS0	ITU Channel Selected as Output Trigger
0	0	TPC output group 1 (TP $_7$ to TP $_4$) is triggered by compare match in ITU channel 0
	1	TPC output group 1 (TP ₇ to TP ₄) is triggered by compare match in ITU channel 1
1	0	TPC output group 1 (TP $_7$ to TP $_4$) is triggered by compare match in ITU channel 2
	1	TPC output group 1 (TP $_7$ to TP $_4$) is triggered by compare match in ITU channel 3

Group 2 compare match select 1 and 0

	Bit 5	Bit 4	
G	2CMS1	G2CMS0	ITU Channel Selected as Output Trigger
	0	0	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in ITU channel 0
		1	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in ITU channel 1
	1	0	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in ITU channel 2
		1	TPC output group 2 (TP ₁₁ to TP ₈) is triggered by compare match in ITU channel 3

Group 3 compare match select 1 and 0

Bit 7	Bit 6	
G3CMS1	G3CMS0	ITU Channel Selected as Output Trigger
0	0	TPC output group 3 (TP ₁₅ to TP ₁₂) is triggered by compare match in ITU channel 0
	1	TPC output group 3 (TP ₁₅ to TP ₁₂) is triggered by compare match in ITU channel 1
1	0	TPC output group 3 (TP ₁₅ to TP ₁₂) is triggered by compare match in ITU channel 2
	1	TPC output group 3 (TP $_{15}$ to TP $_{12}$) is triggered by compare match in ITU channel 3

NDERB—Next	Data Ena	ble Regis	ter B			H'A2		TPC
Bit	7	6	5	4	3	2	1	0
	NDER15	NDER14	NDER13	NDER12	NDER11	NDER10	NDER9	NDER8
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Bit	ta enable s 7 to 0 5 to NDEF 0	R8 Descri	outputs TP		are disable		
		1	TPC o	outputs TP	15 to TP ₈	ransferred are enable sferred to I	d	
NDERA—Next	Data Ena	ble Regis	ter A			H'A3		ТРС

Bit	7	6	5	4	3	2	1	0
	NDER7	NDER6	NDER5	NDER4	NDER3	NDER2	NDER1	NDER0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W							

Next data enable 7 to 0

Bits 7 to 0	
NDER7 to NDER0	Description
0	TPC outputs TP ₇ to TP ₀ are disabled (NDR7 to NDR0 are not transferred to PA ₇ to PA ₀)
1	TPC outputs TP ₇ to TP ₀ are enabled (NDR7 to NDR0 are transferred to PA_7 to PA_0)

NDRB—Next Data Register B

• Same trigger for TPC output groups 2 and 3

Bit	7	6	5	4	3	2	1	0
	NDR15	NDR14	NDR13	NDR12	NDR11	NDR10	NDR9	NDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		re the next C output gi		ata for		e the next o output gro		a for
— Address H	I'FFA6							
Bit	7	6	5	4	3	2	1	0
	_	_	_	_	_	_	_	_
Initial value	1	1	1	1	1	1	1	1
Read/Write	—	—	—	—	—	—		
Different trigg	-	PC output	groups 2	and 3				
Bit	-	6	5	4	3	2	4	
DIL	7	0	0		0	~	1	0
DIL	/ NDR15	NDR14	NDR13	NDR12	_		1	0
Bit Initial value		-	-		1	2 — 1	1 	0 — 1
	NDR15	NDR14	NDR13	NDR12			—	
Initial value	NDR15 0 R/W Stor	NDR14 0	NDR13 0 R/W output dat	NDR12 0 R/W			—	
Initial value	NDR15 0 R/W Stor TPC	NDR14 0 R/W e the next	NDR13 0 R/W output dat	NDR12 0 R/W			—	
Initial value Read/Write	NDR15 0 R/W Stor TPC	NDR14 0 R/W e the next	NDR13 0 R/W output dat	NDR12 0 R/W			—	
Initial value Read/Write — Address H	NDR15 0 R/W Stor TPC	NDR14 0 R/W e the next output gro	NDR13 0 R/W output dat pup 3	NDR12 0 R/W a for	1	1	1 	1
Initial value Read/Write — Address H	NDR15 0 R/W Stor TPC	NDR14 0 R/W e the next output gro	NDR13 0 R/W output dat pup 3	NDR12 0 R/W a for	 1 3	 1 2	 1 1	 1 0

H'A4/H'A6

TPC

NDRA—Next Data Register A

H'A5/H'A7 TPC

Same trigger for TPC output groups 0 and 1 •

— Address H'FFA5

7	6	5	4	3	2	1	0
NDR7	NDR6	NDR5	NDR4	NDR3	NDR2	NDR1	NDR0
0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	0	0 0	0 0 0	0 0 0 0	0 0 0 0 0	0 0 0 0 0 0	0 0 0 0 0 0 0

Store the next output data for TPC output group 1

Store the next output data for TPC output group 0

- Address H'FFA7

Bit	7	6	5	4	3	2	1	0
	—	—	—	—	—	—	—	—
Initial value	1	1	1	1	1	1	1	1
Read/Write	_	_	_		_	_	_	_

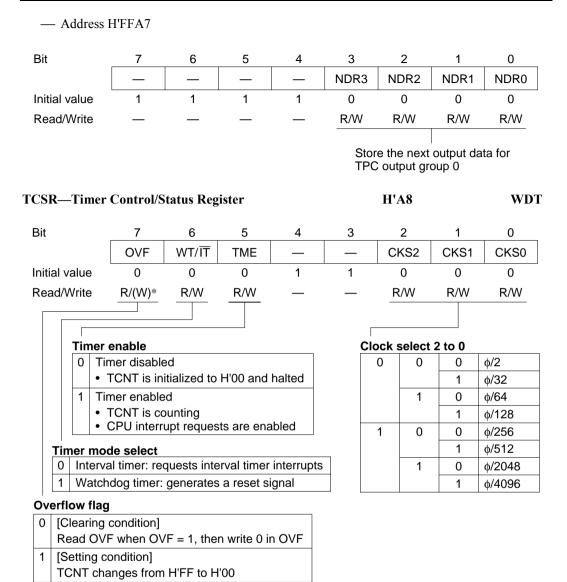
Different triggers for TPC output groups 0 and 1 •

- Address H'FFA5

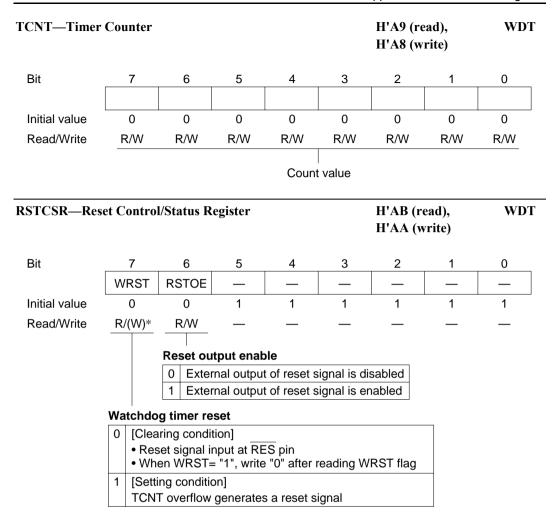
_ . .

Bit	7	6	5	4	3	2	1	0	_
	NDR7	NDR6	NDR5	NDR4	—	—	—		
Initial value	0	0	0	0	1	1	1	1	
Read/Write	R/W	R/W	R/W	R/W	—	—	—	—	

Store the next output data for TPC output group 1



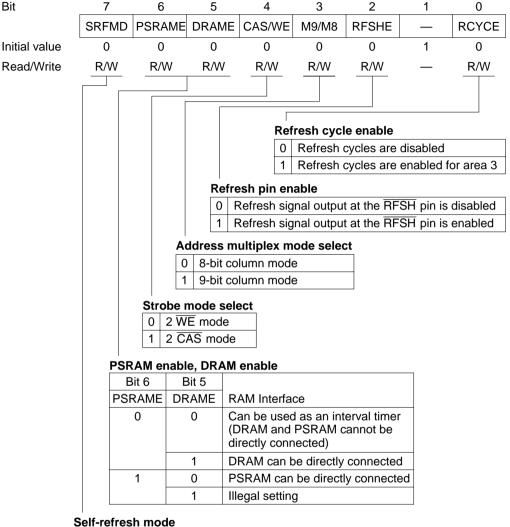
Note: * Only 0 can be written, to clear the flag.



Note: * Only 0 can be written in bit 7, to clear the flag.

RFSHCR—Refresh Control Register





0	DRAM or PSRAM self-refresh is disabled in software standby mode
1	DRAM or PSRAM self-refresh is enabled in software standby mode

RTMCSR—Refresh Timer Control/Status Register

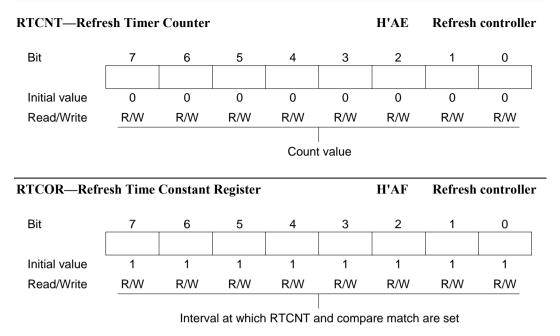
H'AD Refresh controller

Bit	7	6	5		4	3	2	1	0
	CMF	CMIE	CKS	S2 0	KS1	CKS0	—	—	_
Initial value	0	0	0		0	0	1	1	1
Read/Write	R/(W)*	R/W	R/V	V	R/W	R/W	—	—	—
			(Clock	select 2	2 to 0			
				Bit 5	Bit 4	Bit 3			
				CKS2	CKS1	CKS0	Counter Cl	ock Sourc	е
				0	0	0	Clock input	t is disable	d
						1	ф/2		
					1	0	φ/8		
						1	ф/32		
				1	0	0	ф/128		
						1	φ/ 5 12		
					1	0	ф/2048		
						1	ф/4096		
		Comp	are ma	atch in	terrupt	enable			
							/ CMF is dis	abled	
						-	CMF is en		
					prioqu				
	Comp	are match	flag						
	0 [C	learing co	ndition]					
	R	ead CMF v	vhen C	CMF = 1	l, then v	write 0 ir	n CMF		

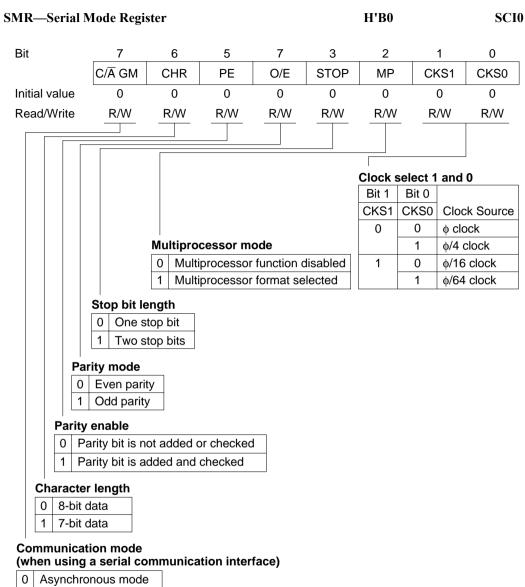
1 [Setting condition]

RTCNT = RTCOR

Note: * Only 0 can be written, to clear the flag.



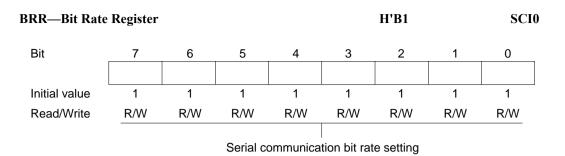




1 Synchronous mode

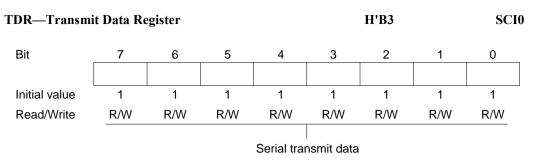
GSM mode (when using a smart card interface)

- 0 Regular smart card interface operation
- 1 GSM mode smart card interface operation

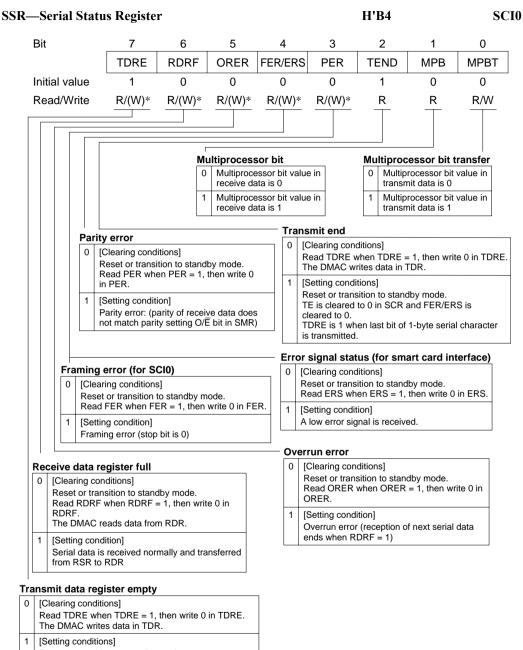




H'B2 SCR—Serial Control Register SCI0 Bit 5 3 2 0 7 6 4 1 TIE RIE ΤE RE MPIE TEIE CKE1 CKE0 Initial value 0 0 0 0 0 0 0 0 Read/Write R/W R/W R/W R/W R/W R/W R/W R/W Clock enable 1 and 0 Bit 1 Bit 0 CKE1 CKE0 Clock Selection and Output 0 0 Asynchronous mode Internal clock, SCK pin available for generic I/O Synchronous mode Internal clock, SCK pin used for serial clock output 1 Asynchronous mode Internal clock, SCK pin used for clock output Internal clock, SCK pin used for serial clock output Synchronous mode 1 0 Asynchronous mode External clock, SCK pin used for clock input Synchronous mode External clock, SCK pin used for serial clock input 1 External clock, SCK pin used for clock input Asynchronous mode Synchronous mode External clock. SCK pin used for serial clock input Transmit-end interrupt enable Transmit-end interrupt requests (TEI) are disabled 0 1 Transmit-end interrupt requests (TEI) are enabled Multiprocessor interrupt enable 0 Multiprocessor interrupts are disabled (normal receive operation) Multiprocessor interrupts are enabled 1 **Receive enable** Transmit enable Receiving is disabled 0 0 Transmitting is disabled 1 Receiving is enabled 1 Transmitting is enabled **Receive interrupt enable** Receive-data-full (RXI) and receive-error (ERI) interrupt requests are disabled 0 1 Receive-data-full (RXI) and receive-error (ERI) interrupt requests are enabled Transmit interrupt enable 0 Transmit-data-empty interrupt request (TXI) is disabled Transmit-data-empty interrupt request (TXI) is enabled 1

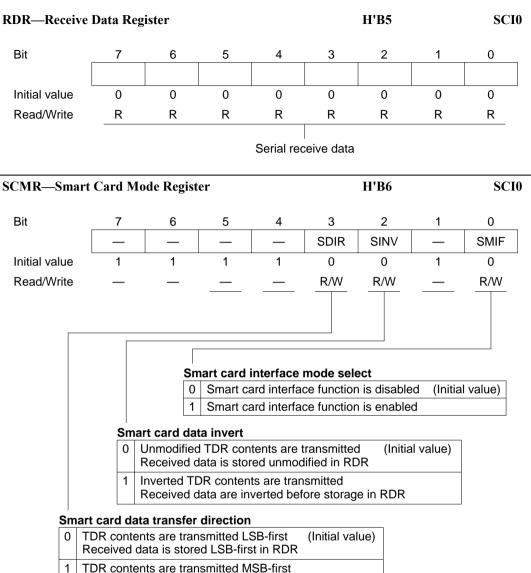






- Reset or transition to standby mode.
- TE is 0 in SCR Data is transferred from TDR to TSR, enabling new
- data to be written in TDR.

Note: * Only 0 can be written, to clear the flag.



Received data is stored MSB-first in RDR



SMR—Serial M	lode Regi	ster				H'B8		SCI1
Bit	7	6	5	4	3	2	1	0
	C/A	CHR	PE	O/E	STOP	MP	CKS1	CKS0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Note: Bit functi	ons are th	e same as	s for SCI0.					
BRR—Bit Rate	Register					H'B9		SCI1
Bit	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Note: Bit functi	ons are th	e same as	s for SCI0.					
SCR—Serial Co	ontrol Reg	gister				H'BA		SCI1
Bit	7	6	5	4	3	2	1	0
	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Note: Bit functions are the same as for SCI0.

TDR—Transm						H'BB		SCI
		8-500						501
Bit	7	6	5	4	3	2	1	0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Note: Bit funct	ions are th	e same as	ofor SCI0.					
SSR—Serial St	atus Regis	ster				H'BC		SCI
Bit	7	6	5	4	3	2	1	0
	TDRE	RDRF	ORER	FER	PER	TEND	MPB	MPBT
Initial value	1	0	0	0	0	1	0	0
Read/Write	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R	R	R/W
Notes: Bit fund * Only	ctions are t 0 can be w							
RDR—Receive	Data Reg	ister				H'BD		SCI
Bit	7	6	5	4	3	2	1	0

Note: Bit functions are the same as for SCI0.

0

R

0

R

0

R

0

R

0

R

0

R

0

R

0

R

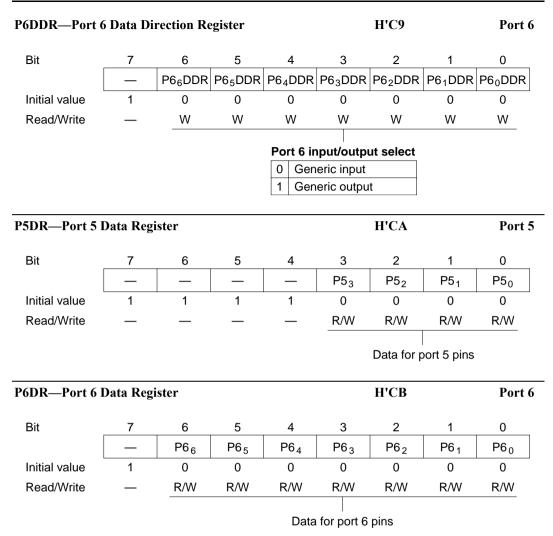
Initial value

Read/Write

P1DDI	R—Port 1	Data Dire	ection Reg	ister		l	H'C0		Port 1
Bit		7	6	5	4	3	2	1	0
		P17DDR	P1 ₆ DDR	P1 ₅ DDR	P1 ₄ DDR	P1 ₃ DDR	P1 ₂ DDR	P1 ₁ DDR	P10DDR
Modes	Initial valu	e 1	1	1	1	1	1	1	1
1 to 4	Read/Writ	ie —	_	_	_	—	_	_	—
Modes	Initial valu	e 0	0	0	0	0	0	0	0
5 to 7	Read/Writ	e W	W	W	W	W	W	W	W
				Po	rt 1 input/ Generic	output se	elect		
				1		output pin			
P2DDI	R—Port 2	Data Dire	ection Reg	ister			H'C1		Port 2
Bit		7	6	5	4	3	2	1	0
		P27DDR	P2 ₆ DDR	P25 DDR	P2 ₄ DDR	P2 ₃ DDR	P2 ₂ DDR	P21 DDR	P20DDR
Modes	Initial valu	e 1	1	1	1	1	1	1	1
1 to 4	Read/Writ	e —	—	_	—	—	—	_	_
Modes	Initial valu	e 0	0	0	0	0	0	0	0
5 to 7	Read/Writ	e W	W	W	W	W	W	W	W
				Po 0 1	Generic	foutput se input pin output pin	lect		
P1DR-	—Port 1 D	ata Regis	ter]	H'C2		Port 1
Bit		7	6	5	4	3	2	1	0
		P17	P1 ₆	P1 ₅	P14	P1 ₃	P12	P1 ₁	P10
Initia	l value	0	0	0	0	0	0	0	0
Read	I/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				[Data for po	ort 1 pins			

P2DR—Port 2	Data Regi	ster				Н'СЗ		Port 2
Bit	7	6	5	4	3	2	1	0
	P27	P2 ₆	P2 ₅	P24	P23	P22	P2 ₁	P20
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				Data for p	oort 2 pins			
P3DDR—Port	3 Data Dii	rection Ro	egister			H'C4		Port 3
Bit	7	6	5	4	3	2	1	0
	P37DDR	P3 ₆ DDR	P3 ₅ DDR	P3 ₄ DDR	P3 ₃ DDR	P3 ₂ DDR	P31DDR	P3 ₀ DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W
			Po 0 1	Generic	output se input pin output pin	lect		
P4DDR—Port	4 Data Dii	rection Re	egister			H'C5		Port 4
Bit	7	6	5	4	3	2	1	0
	P47DDR	P4 ₆ DDR	P45DDR	P4 ₄ DDR	P4 ₃ DDR	P4 ₂ DDR	P41DDR	P40DDR
Initial value	0	0	0	0	0	0	0	0
Read/Write	W	W	W	W	W	W	W	W
			Po 0 1	Generic	output se input pin output pin	lect		

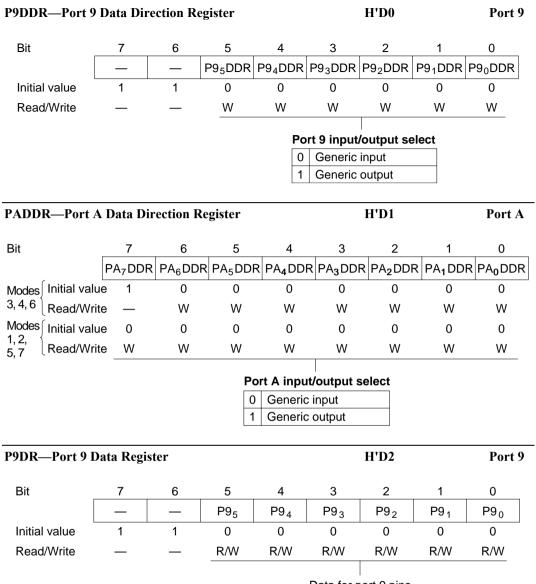
P3DR—Port 3 D	ata Regi	ster]	H'C6		Port 3
Bit	7	6	5	4	3	2	1	0
	P37	P3 ₆	P3 ₅	P34	P33	P32	P3 ₁	P3 ₀
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				Data for p	oort 3 pins			
P4DR—Port 4 D	ata Regi	ster]	H'C7		Port 4
Bit	7	6	5	4	3	2	1	0
	P47	P4 ₆	P4 5	P44	P43	P42	P4 1	P40
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				Data for p	oort 4 pins			
P5DDR—Port 5	Data Dir	ection Re	gister]	H'C8		Port 5
Bit	7	6	5	4	3	2	1	0
		_		_	P5₃DDR	P5 ₂ DDR	P51DDR	P50DDR
Modes∫ Initial valu	e 1	1	1	1	1	1	1	1
1 to 4 Read/Writ	e —	—	_	—	—	—	—	—
Modes Initial valu	e 1	1	1	1	0	0	0	0
5 to 7 Read/Writ	ie —	—	—	—	W	W	W	W
					Ро	rt 5 input/	/output se	lect
					0	Generic		
					1	Generic	output	



P8DDR—Port 8	Data Dir	ection Reg	gister]	H'CD		Port 8
Bit	7	6	5	4	3	2	1	0
		_		P8 ₄ DDR	P83DDR	P82DDR	P81DDR	P8 ₀ DDR
Modes∫ Initial valu	ie 1	1	1	1	0	0	0	0
^{1 to 4} Read/Writ	ie —	—	—	W	W	W	W	W
Modes∫ Initial valu	ie 1	1	1	0	0	0	0	0
5 to 7 Read/Writ	ie —	—	—	W	W	W	W	W
			0 Ger	n put/outpu neric input output	It select	0 Ge	input/out eneric inpu eneric outp	
P7DR—Port 7 D	ata Regis	ster]	H'CE		Port 7
Bit	7	6	5	4	3	2	1	0
	P7 ₇	P7 ₆	P7 ₅	P74	P73	P72	P7 ₁	P7 ₀
Initial value	*	*	*	*	*	*	*	*
Read/Write	R	R	R	R	R	R	R	R
			Read	d the pin lev	vels for po	rt 7		

Note: * Determined by pins $P7_7$ to $P7_0$.

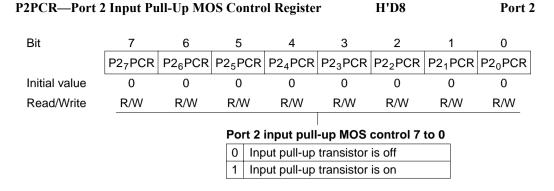
8DR—Port 8 E	Data Regi	ster			H'CF				
Bit	7	6	5	4	3	2	1	0	
	_	—	—	P84	P83	P82	P8 ₁	P8 ₀	
Initial value	1	1	1	0	0	0	0	0	
Read/Write			_	R/W	R/W	R/W	R/W	R/W	



Data for port 9 pins

PADR—Port A Data Register						H'D3			
Bit	7	6	5	4	3	2	1	0	
	PA ₇	PA ₆	PA ₅	PA ₄	PA ₃	PA ₂	PA ₁	PA ₀	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
				Data for p	ort A pins				
PBDDR—Port	B Data Di	rection R	egister			H'D4		Port B	
Bit	7	6	5	4	3	2	1	0	
	PB7DDR	PB ₆ DDR	PB ₅ DDR	PB ₄ DDR	PB ₃ DDR	PB ₂ DDR	PB ₁ DDR	PB ₀ DDR	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	W	W	W	W	W	W	W	W	
			Po	rt B input/	output se	lect			
			0	Generic i	nput				
			1	Generic o	output				
PBDR—Port B	Data Reg	ister				H'D6		Port B	
Bit	7	6	5	4	3	2	1	0	
	P27PCR	P26PCR	P25PCR	P2 ₄ PCR	P2 ₃ PCR	P2 ₂ PCR	P2 ₁ PCR	P20PCR	
Initial value	0	0	0	0	0	0	0	0	
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
			0 Inp	input pull out pull-up out pull-up	transistor	is off	to 0		

Note: Valid when the corresponding P2DDR bit is cleared to 0 (designating generic input).

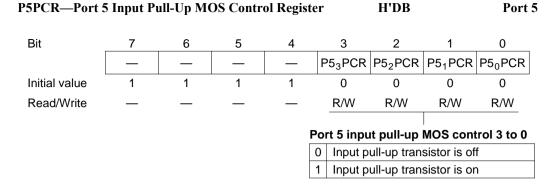


Note: Valid when the corresponding P2DDR bit is cleared to 0 (designating generic input).

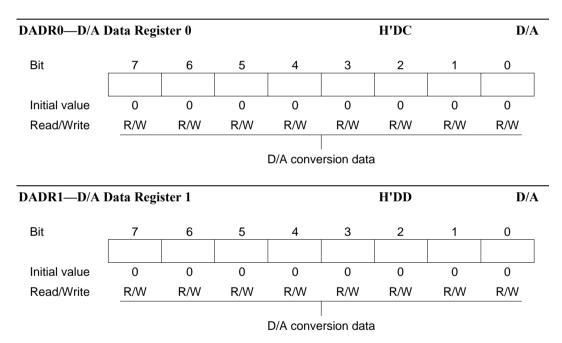
P4PCR—Port 4	4 Input Pu	ill-Up MC	OS Contro	ol Registe	r	H'DA		Port 4
Bit	7	6	5	4	3	2	1	0
	P47PCR	P4 ₆ PCR	P45PCR	P4 ₄ PCR	P4 ₃ PCR	P4 ₂ PCR	P41PCR	P4 ₀ PCR
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Port 4 input pull-up MOS control 7 to 00Input pull-up transistor is off1Input pull-up transistor is on								

Note: Valid when the corresponding P4DDR bit is cleared to 0 (designating generic input).





Note: Valid when the corresponding P5DDR bit is cleared to 0 (designating generic input).



DACR—D/A Control Register

Bit	7		6	5	4	3	2	1	0		
	DAOE	1 DA	OE0	DAE			_	_			
Initial value	0		0	0	1	1	1	1	1		
Read/Write	R/W	R	2/W	R/W	—	—	—	_	—		
	D/A ena	able									
	Bit 7	Bit 6	Bit 5								
	DAOE1	DAOE0	DAE	Descrip	otion						
	0	0	_	D/A co	D/A conversion is disabled in channels 0 and 1						
		1	0				in channel	-			
	D/A conversion is disabled in channel 1 1 D/A conversion is enabled in channels 0 and 1							_			
	1	0	0 D/A conversion is disabled in channel 0								
				D/A co	nversion is	enabled	in channel	1			
			1	D/A co	nversion is	enabled	in channel	s 0 and 1			
		1			oversion is	enabled	in channel	s 0 and 1			

D/A output enable 0

0 DA₀ analog output is disabled

1 Channel-0 D/A conversion and DA₀ analog output are enabled

D/A output enable 1

- 0 DA₁ analog output is disabled
- 1 Channel-1 D/A conversion and DA₁ analog output are enabled

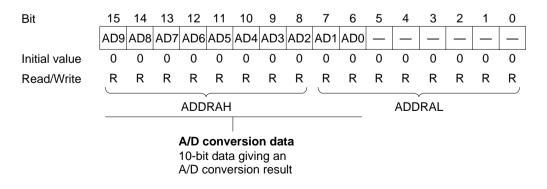
ADDRA H/L—A/D Data Register A H/L

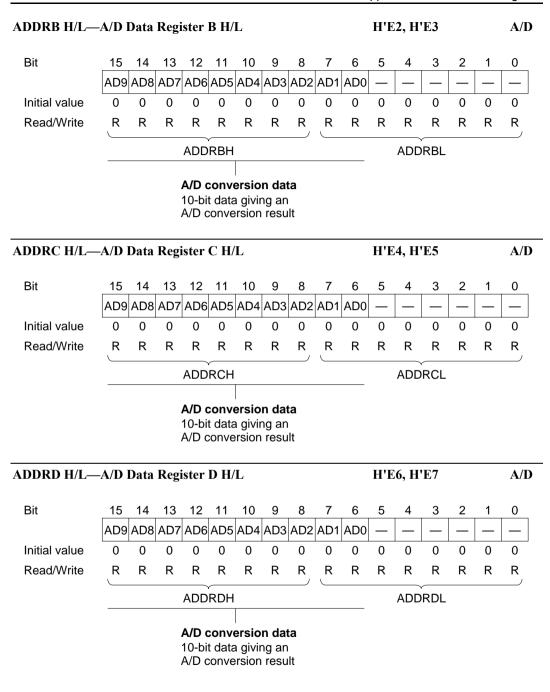
H'E0, H'E1

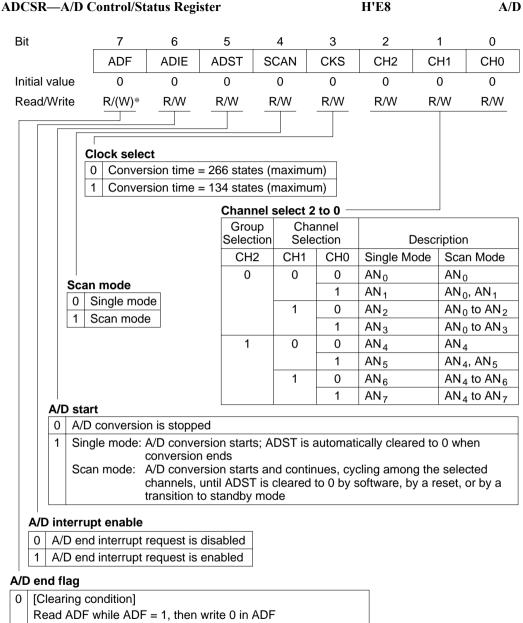
H'DE

A/D

D/A







 I
 [Setting conditions]

 Single mode: A/D conversion ends
 Scan mode: A/D conversion ends in all selected channels

Note: * Only 0 can be written, to clear flag.



					-			
ADCR—A/D C	ontrol Reg	gister				Н'Е9		A/D
Bit	7	6	5	4	3	2	1	0
	TRGE	_	_	—	_	—	_	_
Initial value	0	1	1	1	1	1	1	1
Read/Write	R/W	—	—	—	—	—	—	—
	Trigger	enable						
	0 A/D	conversio	on cannot	be extern	ally trigger	ed		
	1 A/D	conversio	on starts a	t the fall o	f the exter	nal trigger	signal (Al	DTRG)
ABWCR—Bus	Width Co	ntrol Reg	ister			H'EC	Bus	controller
Bit	7	6	5	4	3	2	1	0
	ABW7	ABW6	ABW5	ABW4	ABW3	ABW2	ABW1	ABW0
Initial Mode 1,3	3,5,6 1	1	1	1	1	1	1	1
value Mode 2,4		0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
				_				
			dth contro	ol				
		7 to 0 to ABW0	Bus Wi	dth of Acc	ess Area			
		0		Bus Width of Access Area Areas 7 to 0 are 16-bit access areas				
		1	Areas 7 to 0 are 8-bit access areas					
ASTCR—Acces	ss State Co	ontrol Reg	gister			H'ED	Bus	controller
Bit	7	6	5	4	3	2	1	0
	AST7	AST6	AST5	AST4	AST3	AST2	AST1	AST0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
	Area 7 to 0	access s	state cont	rol				
	Bits 7							
	AST7 to	AST0	Number	of States i	n Access	Cycle		
	0		Areas 7 t	o 0 are tw	o-state ac	cess areas	6	

1

Areas 7 to 0 are three-state access areas

WCR—Wait Control Register

Bit	7	6	5	4	3	2	1	0
	—		_	_	WMS1	WMS0	WC1	WC0
Initial value	1	1	1	1	0	0	1	1
Read/Write	_	_	_	_	R/W	R/W	R/W	R/W

Γ

Wait mode select 1 and 0

Bit 3	Bit 2	
WMS1	WMS0	Wait Mode
0	0	Programmable wait mode
	1	No wait states inserted by wait-state controller
1	0	Pin wait mode 1
	1	Pin auto-wait mode

Wait count 1 and 0

H'EE

Bit 1	Bit 0	
WC1	WC0	Number of Wait States
0	0	No wait states inserted by wait-state controller
	1	1 state inserted
1	0	2 states inserted
	1	3 states inserted

H'EF

WCER—Wait-State Controller Enable Register

Bus controller

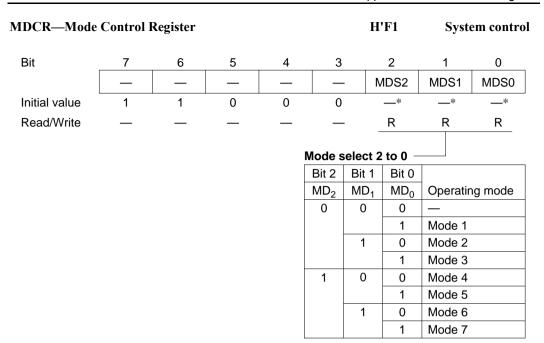
Bus controller

Bit	7	6	5	4	3	2	1	0
	WCE7	WCE6	WCE5	WCE4	WCE3	WCE2	WCE1	WCE0
Initial value	1	1	1	1	1	1	1	1
Read/Write	R/W							

Wait-state controller enable 7 to 0

0 Wait-state control is disabled (pin wait mode 0)1 Wait-state control is enabled



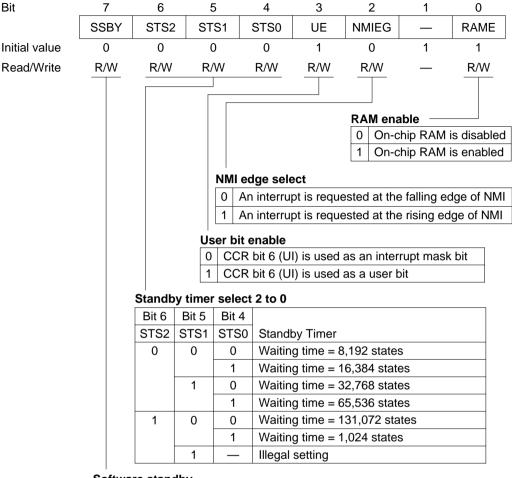


Note: * Determined by the state of the mode pins (MD_2 to MD_0).

SYSCR—System Control Register

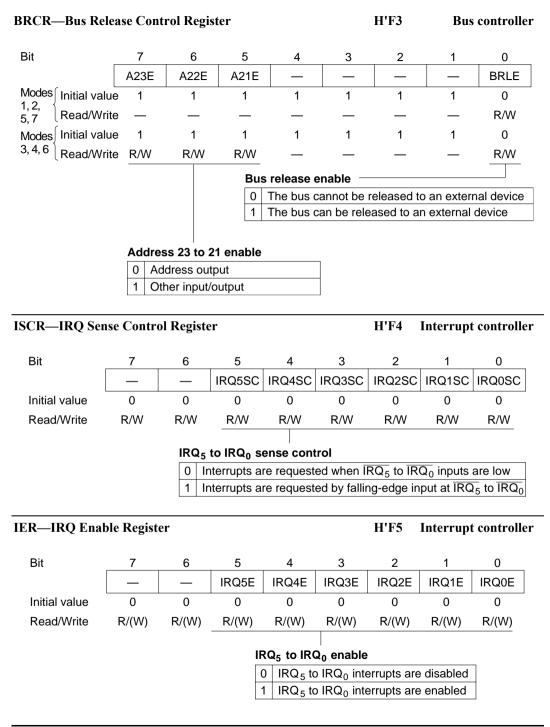






Software standby

0	SLEEP instruction causes transition to sleep mode
1	SLEEP instruction causes transition to software standby mode



ISR—IRQ Status Register

H'F6 Interrupt controller

Bit	7	6	5	4	3	2	1	0
	—	—	IRQ5F	IRQ4F	IRQ3F	IRQ2F	IRQ1F	IRQ0F
Initial value	0	0	0	0	0	0	0	0
Read/Write	—	—	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*	R/(W)*

IRQ₅ to IRQ₀ flags

integ to integ hags	
Bits 5 to 0	
IRQ5F to IRQ0F	Setting and Clearing Conditions
0	[Clearing conditions]
	Read IRQnF when IRQnF = 1, then write 0 in IRQnF. IRQnSC = 0, IRQn input is high, and interrupt exception handling is carried out. IRQnSC = 1 and IRQn interrupt exception handling is carried out.
1	[Setting conditions] IRQnSC = 0 and \overline{IRQn} input is low. IRQnSC = 1 and a falling edge is generated in the \overline{IRQn} input.

(n = 5 to 0)

Note: * Only 0 can be written, to clear the flag.



H'F8 Interrupt controller

Bit	7	6	5	4	3	2	1	0
	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
			_			_		
	Priority level A7 to A0							
			0	Priority	level 0 (lov	w priority)		
			1	Priority	level 1 (hi	gh priority)		

• Interrupt sources controlled by each bit

	Bit 7:	Bit 6:	Bit 5:	Bit 4:	Bit 3:	Bit 2:	Bit 1:	Bit 0:
	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0
Interrupt source	IRQ₀	IRQ₁	IRQ2, IRQ3	IRQ₄, IRQ₅	WDT, Refresh Controller	channel	ITU channel 1	ITU channel 2

IPRB—Interrupt Priority Register B

H'F9 Interrupt controller

Bit	7	6	5	4	3	2	1	0
	IPRB7	IPRB6	IPRB5	_	IPRB3	IPRB2	IPRB1	—
Initial value	0	0	0	0	0	0	0	0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
			Priority	/ level B7	to B5, B3	to B 1		
			0 Pri	ority level	0 (low pric	ority)		

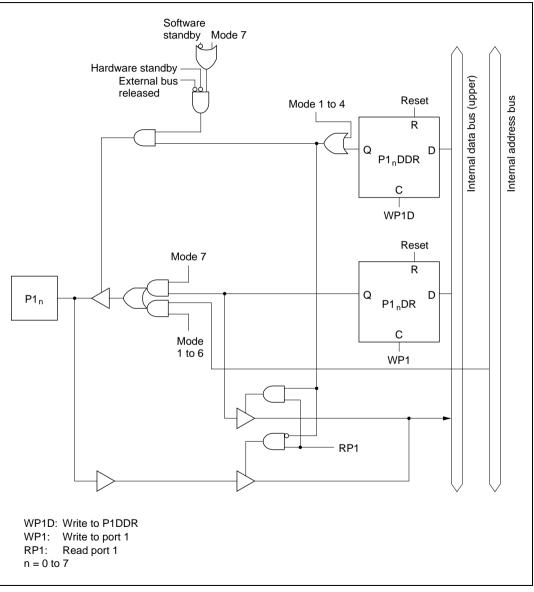
1 Priority level 1 (high priority)

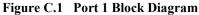
• Interrupt sources controlled by each bit

_		Bit 6: IPRB6			Bit 3: IPRB3	 Bit 1: IPRB1	
	ITU channel 3		DMAC	—		 A/D converter	

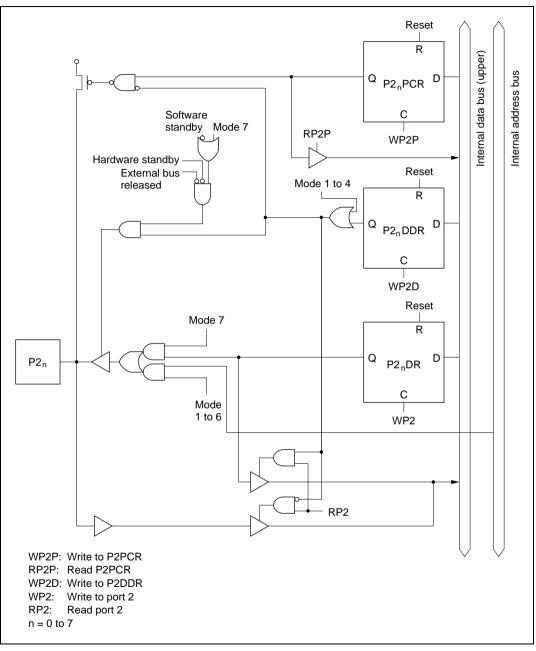
Appendix C I/O Port Block Diagrams

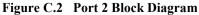
C.1 Port 1 Block Diagram





C.2 Port 2 Block Diagram





C.3 Port 3 Block Diagram

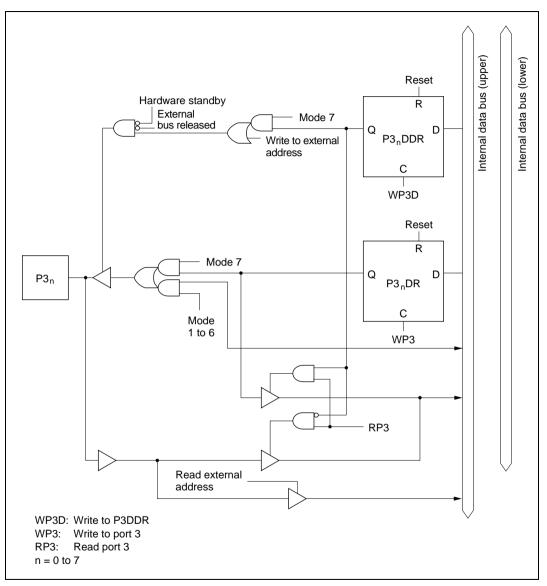
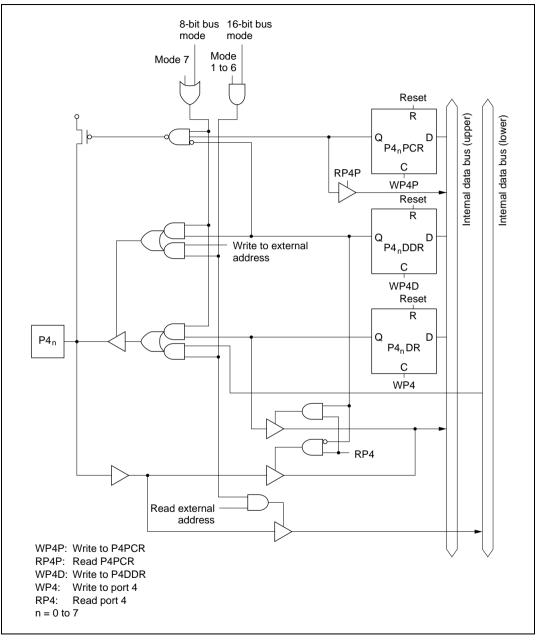
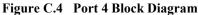


Figure C.3 Port 3 Block Diagram

C.4 Port 4 Block Diagram





C.5 Port 5 Block Diagram

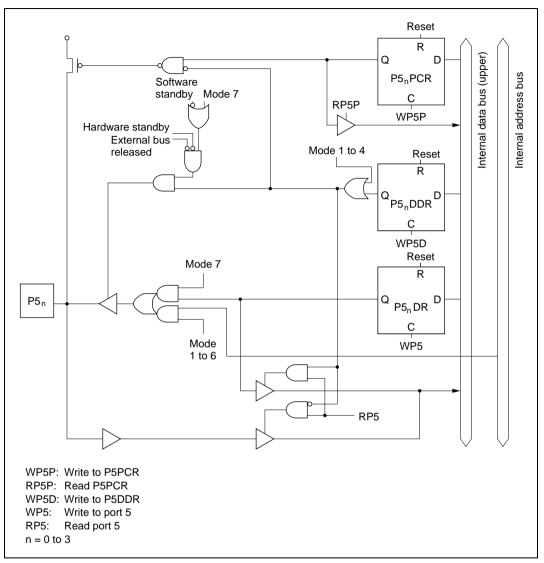


Figure C.5 Port 5 Block Diagram

C.6 Port 6 Block Diagrams

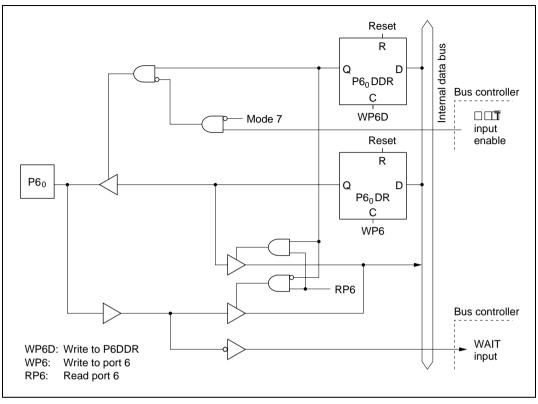


Figure C.6 (a) Port 6 Block Diagram (Pin P6₀)

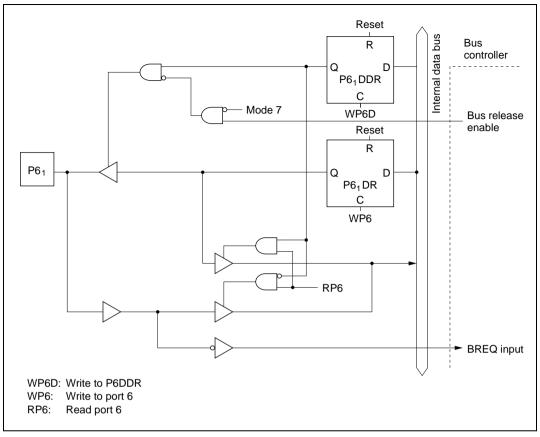


Figure C.6 (b) Port 6 Block Diagram (Pin P6₁)



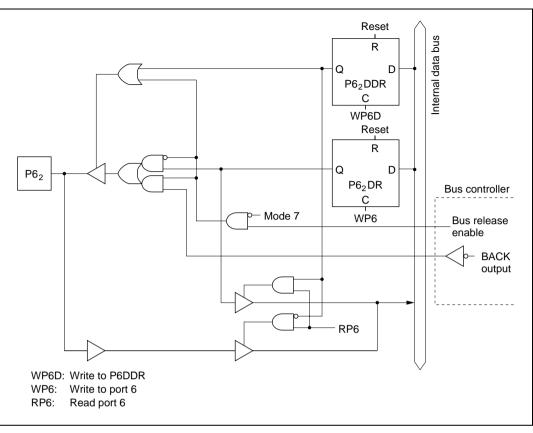


Figure C.6 (c) Port 6 Block Diagram (Pin P6₂)



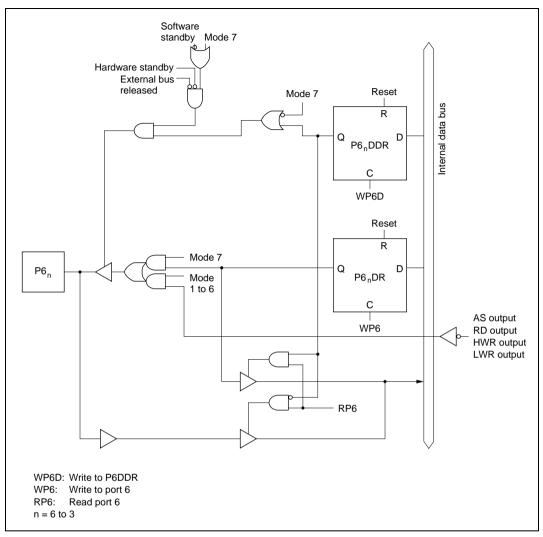


Figure C.6 (d) Port 6 Block Diagram (Pins P6₆ to P6₃)

C.7 Port 7 Block Diagrams

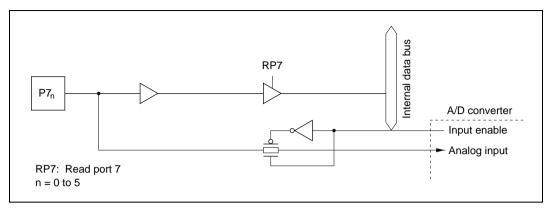


Figure C.7 (a) Port 7 Block Diagram (Pins P7₀ to P7₅)

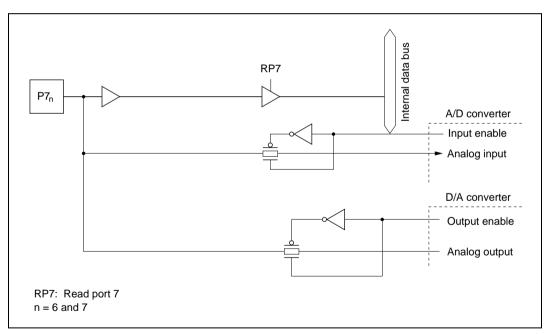


Figure C.7 (b) Port 7 Block Diagram (Pins P7₆ and P7₇)

C.8 Port 8 Block Diagrams

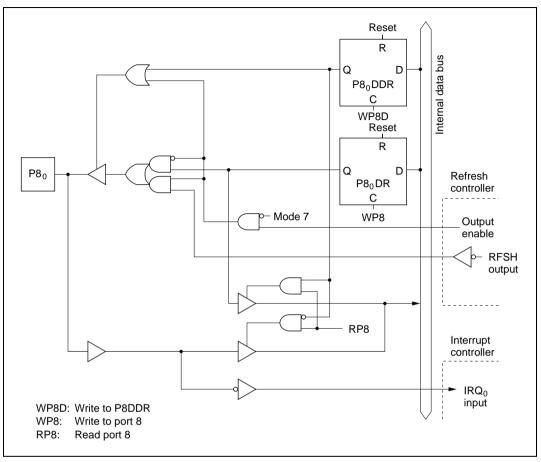


Figure C.8 (a) Port 8 Block Diagram (Pin P8₀)



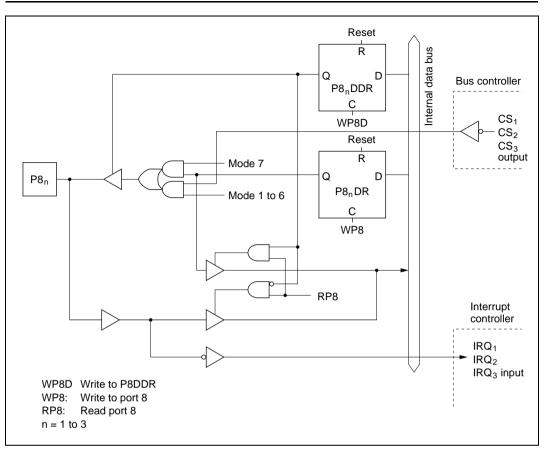


Figure C.8 (b) Port 8 Block Diagram (Pins P8₁ to P8₃)

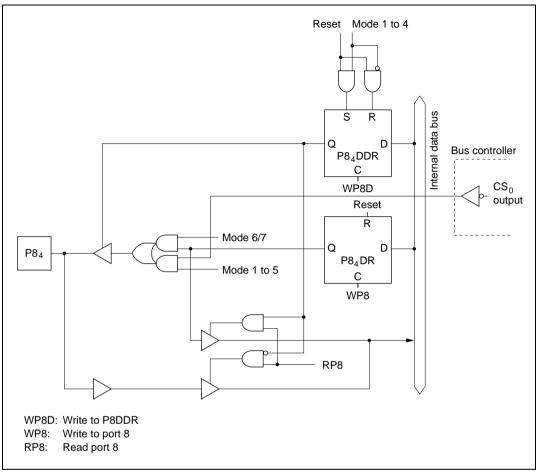


Figure C.8 (c) Port 8 Block Diagram (Pin P84)

C.9 Port 9 Block Diagrams

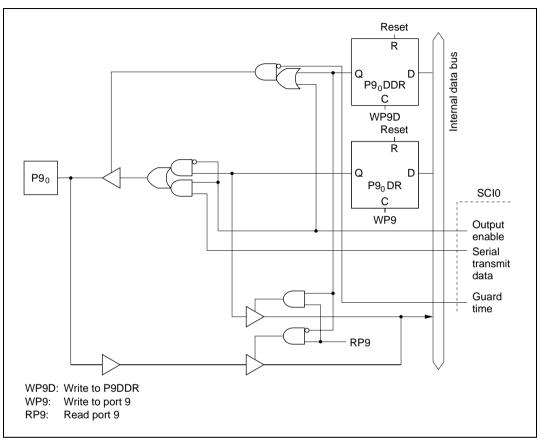


Figure C.9 (a) Port 9 Block Diagram (Pin P9₀)

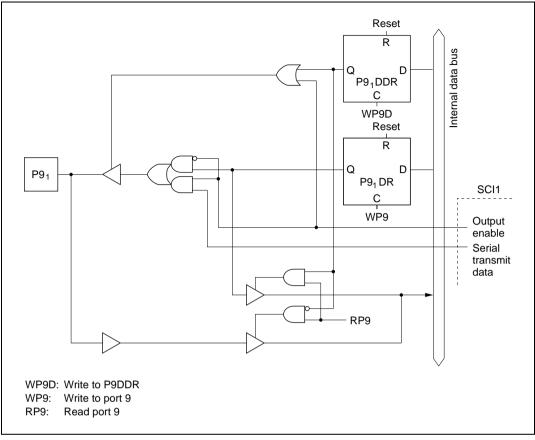


Figure C.9 (b) Port 9 Block Diagram (Pin P9₁)



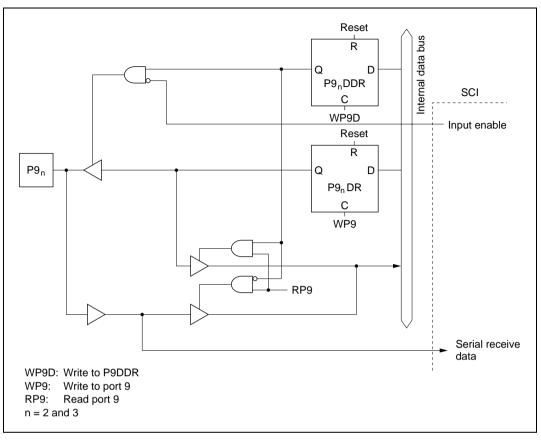


Figure C.9 (c) Port 9 Block Diagram (Pins P9₂ and P9₃)

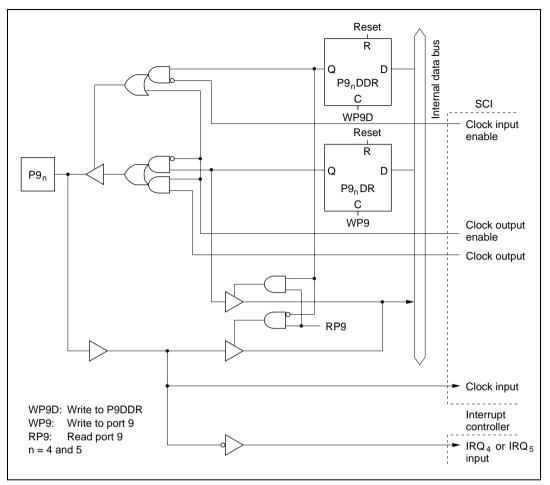


Figure C.9 (d) Port 9 Block Diagram (Pins P9₄ and P9₅)

C.10 Port A Block Diagrams

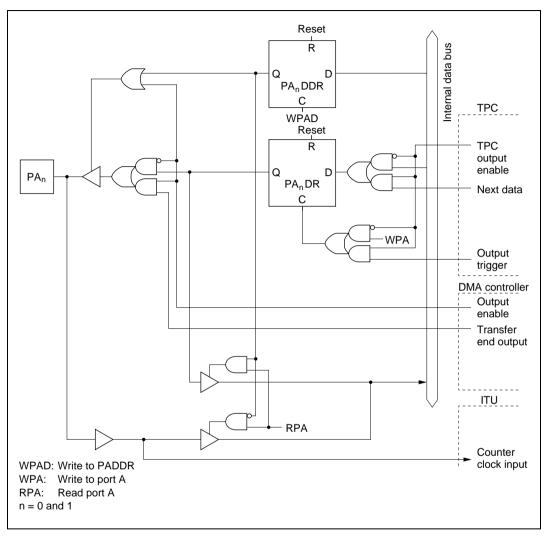


Figure C.10 (a) Port A Block Diagram (Pins PA₀ and PA₁)

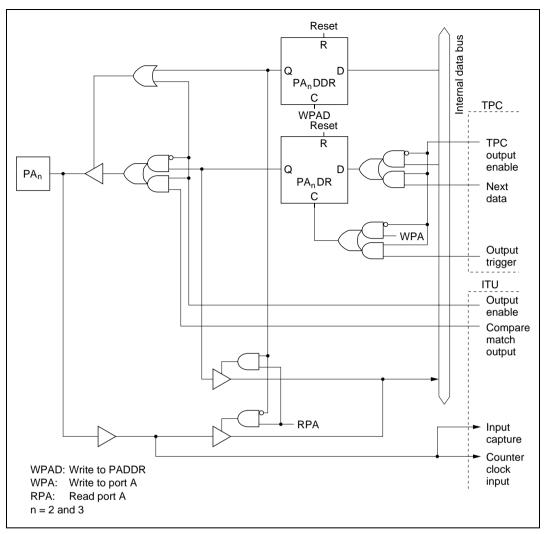


Figure C.10 (b) Port A Block Diagram (Pins PA₂ and PA₃)

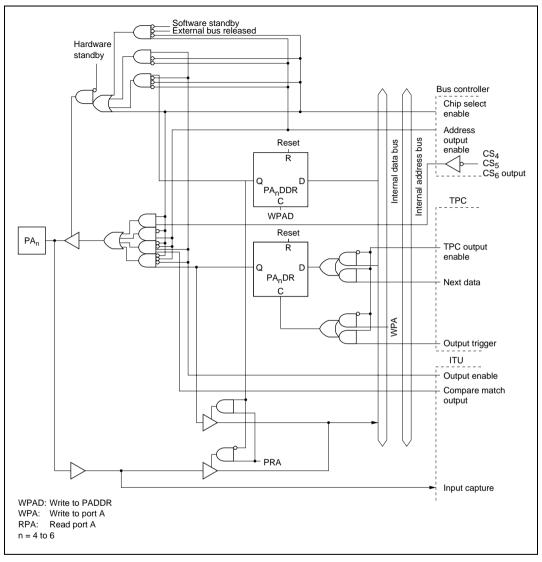


Figure C.10 (c) Port A Block Diagram (Pins PA₄ to PA₆)

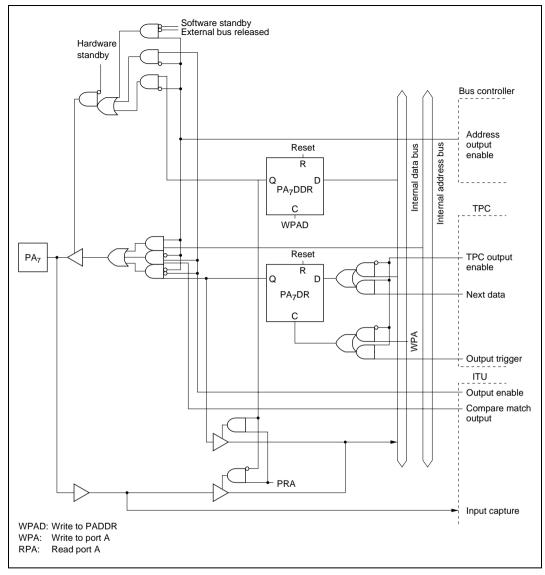


Figure C.10 (d) Port A Block Diagram (Pin PA₇)



C.11 Port B Block Diagrams

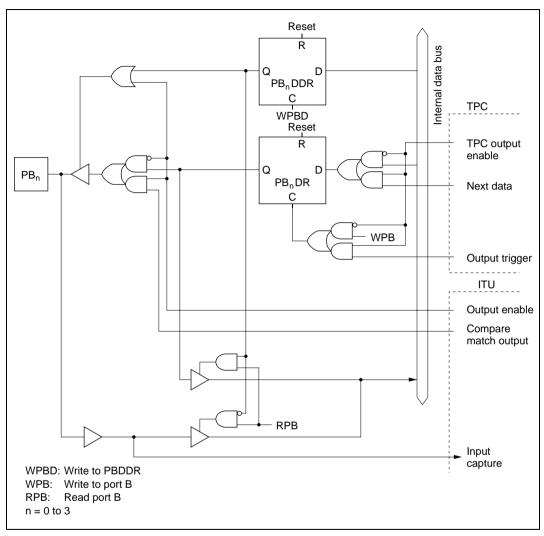


Figure C.11 (a) Port B Block Diagram (Pins PB₀ to PB₃)

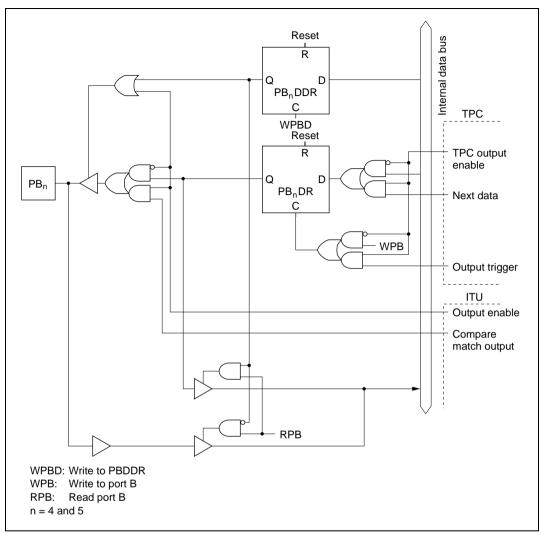


Figure C.11 (b) Port B Block Diagram (Pins PB₄ and PB₅)

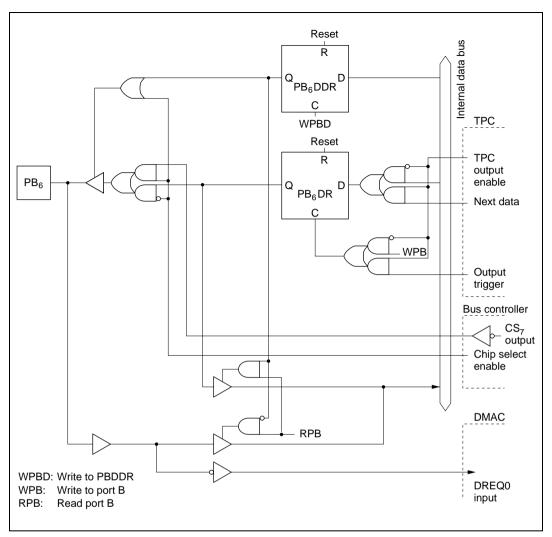


Figure C.11 (c) Port B Block Diagram (Pin PB₆)

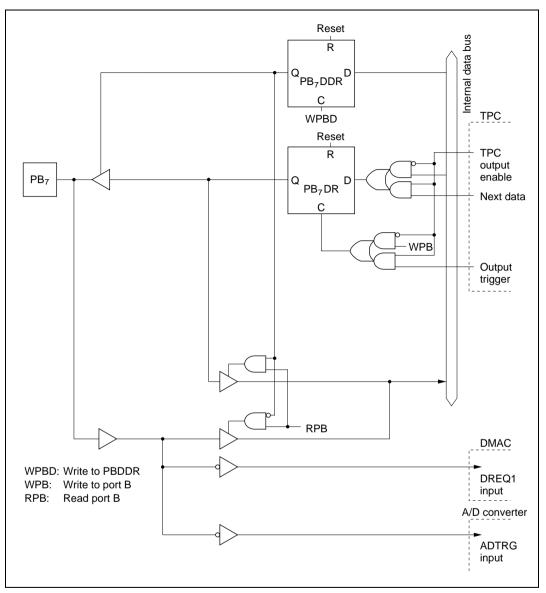


Figure C.11 (d) Port B Block Diagram (Pin PB₇)

Appendix D Pin States

D.1 Port States in Each Mode

Table D.1 Port States

Pin Name	Mode		Reset	Hardware Standby Mode	Software Standby Mode	Bus- Released Mode	Program Execution, Sleep Mode
φ	_		Clock output	Т	Н	Clock output	Clock output
RESO*2			T* ²	Т	Т	Т	RESO
$P1_7$ to $P1_0$	1 to 4		L	Т	Т	Т	A ₇ to A ₀
	5, 6		Т	Т	keep	Т	Input port (DDR = 0)
					Т	Т	A ₇ to A ₀ (DDR = 1)
	7		Т	Т	keep	_	I/O port
P27 to P20	1 to 4		L	Т	Т	Т	A ₁₅ to A ₈
	5, 6		Т	Т	keep	Т	Input port (DDR = 0)
					Т	Т	A ₁₅ to A ₈ (DDR = 1)
	7		Т	Т	keep	_	I/O port
P37 to P30	1 to 6		Т	Т	Т	Т	D ₁₅ to D ₈
	7		Т	Т	keep	_	I/O port
P47 to P40	1 to 6	8-bit bus	Т	Т	keep	keep	I/O port
		16-bit bus	Т	Т	Т	Т	D ₇ to D ₀
	7		Т	Т	keep	_	I/O port
$P5_3$ to $P5_0$	1 to 4		L	Т	Т	Т	A ₁₉ to A ₁₆
	5, 6		Т	Т	keep	Т	Input port (DDR = 0)
					Т	Т	A ₁₉ to A ₁₆ (DDR = 1)
	7		Т	Т	keep	_	I/O port

Appendix D Pin States

Pin Name	Mode	Reset	Hardware Standby Mode	Software Standby Mode	Bus- Released Mode	Program Execution, Sleep Mode
P6 ₀	1 to 6	Т	Т	keep	keep	I/O port WAIT
	7	Т	Т	keep	_	I/O port
P6 ₁	1 to 6	Т	Т	keep (BRLE = 0) T (BRLE = 1)	Т	I/O port BREQ
	7	Т	Т	keep	_	I/O port
P6 ₂	1 to 6	Т	Т	keep (BRLE = 0) H (BRLE = 1)	L	I/O port (BRLE = 0) or BACK (BRLE = 1)
	7	Т	Т	keep	_	I/O port
P6 ₆ to P6 ₃	1 to 6	H* ³	Т	Т	Т	AS, RD, HWR, LWR
	7	Т	Т	keep	_	I/O port
P77 to P70	1 to 7	Т	Т	Т	T* ¹	Input port
P8 ₀	1 to 6	Т	Т	RFSH	keep (RFSHE = 0) H (RFSHE = 1)	I/O port (RFSHE = 0) or RFSH (RFSHE = 1)
	7	Т	Т	keep	_	I/O port
P8 ₃ to P8 ₁	1 to 6	Т	Т	T (DDR = 0) H (DDR = 1)	keep (DDR = 0) H (DDR = 1)	Input port (DDR = 0) or \overline{CS}_3 to \overline{CS}_1 (DDR = 1)
	7	Т	Т	keep	_	I/O port
P84	1 to 6	L	Т	T (DDR = 0) L (DDR = 1)	keep (DDR = 0) H (DDR = 1)	Input port (DDR = 0) or \overline{CS}_0 (DDR = 1)
	7	Т	Т	keep	_	I/O port
P95 to P90	1 to 7	Т	Т	keep	keep*1	I/O port

Pin Name	Mode	Reset	Hardware Standby Mode	Software Standby Mode	Bus- Released Mode	Program Execution, Sleep Mode
PA ₃ to PA ₀	1 to 7	Т	Т	keep	keep*1	I/O port
PA ₆ to PA ₄	3, 4, 6	T* ⁴	Т	H (CS output)	H (CS output)	\overline{CS}_6 to \overline{CS}_4 (\overline{CS} output)
				T (address output)	T (address output)	A23 to A21 (address
				keep	keep	output)
				(otherwise)	(otherwise)	I/O port (otherwise)
	1, 2, 5, 7	T* ⁴	Т	keep	keep*1	I/O port
PA ₇	3, 4, 6	L^{*4}	Т	Т	Т	A ₂₀
	1, 2, 5, 7	T* ⁴	Т	keep	keep*1	I/O port
PB ₇ , PB₅ to PB₀	1 to 7	Т	Т	keep	keep*1	I/O port
PB ₆	3, 4, 6	Т	Т	Н	Н	CS ₇
				(CS output)	(CS output)	(CS output)
				keep (otherwise)	keep (otherwise)	I/O port (otherwise)
	1, 2, 5, 7	Т	Т	keep	keep*1	I/O port

Legend

H: High

L: Low

T: High-impedance state

keep: Input pins are in the high-impedance state; output pins maintain their previous state.

DDR: Data direction register bit

Notes: 1. The bus cannot be released in mode 7.

- Output is low only for reset by WDT overflow. This RESO output function is only for the mask ROM, ZTAT, and flash memory (dual power supply).
- 3. During direct power supply, oscillation damping time is "H" or "T".
- 4. During direct power supply, oscillation damping time differs between "H", "L" and "T".

D.2 Pin States at Reset

Reset in T1 State: Figure D.1 is a timing diagram for the case in which $\overline{\text{RES}}$ goes low during the T1 state of an external memory access cycle. As soon as $\overline{\text{RES}}$ goes low, all ports are initialized to the input state. $\overline{\text{AS}}$, $\overline{\text{RD}}$, $\overline{\text{HWR}}$, and $\overline{\text{LWR}}$ go high, and the data bus goes to the high-impedance state. The address bus is initialized to the low output level 0.5 state after the low level of $\overline{\text{RES}}$ is sampled. Sampling of $\overline{\text{RES}}$ takes place at the fall of the system clock (ϕ).

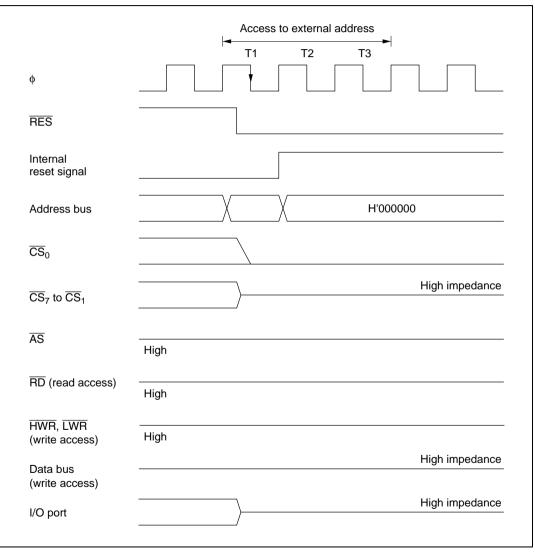


Figure D.1 Reset during Memory Access (Reset during T1 State)

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Reset in T2 State: Figure D.2 is a timing diagram for the case in which $\overline{\text{RES}}$ goes low during the T2 state of an external memory access cycle. As soon as $\overline{\text{RES}}$ goes low, all ports are initialized to the input state. $\overline{\text{AS}}$, $\overline{\text{RD}}$, $\overline{\text{HWR}}$, and $\overline{\text{LWR}}$ go high, and the data bus goes to the high-impedance state. The address bus is initialized to the low output level 0.5 state after the low level of $\overline{\text{RES}}$ is sampled. The same timing applies when a reset occurs during a wait state (T_w).

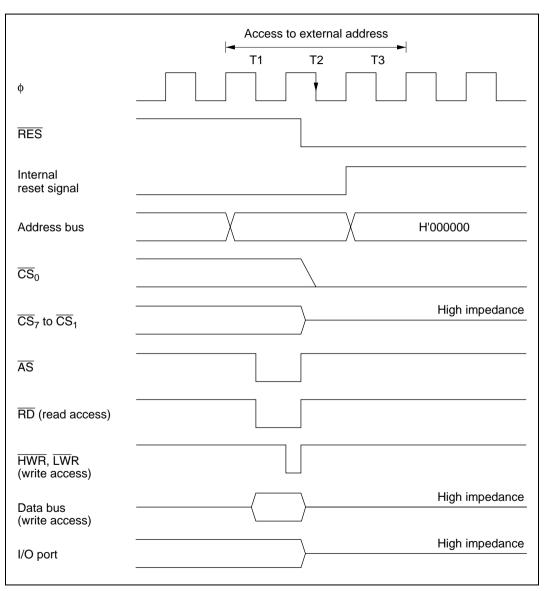


Figure D.2 Reset during Memory Access (Reset during T2 State)

Reset in T3 State: Figure D.3 is a timing diagram for the case in which $\overline{\text{RES}}$ goes low during the T3 state of an external memory access cycle. As soon as $\overline{\text{RES}}$ goes low, all ports are initialized to the input state. $\overline{\text{AS}}$, $\overline{\text{RD}}$, $\overline{\text{HWR}}$, and $\overline{\text{LWR}}$ go high, and the data bus goes to the high-impedance state. The address bus outputs are held during the T3 state. The same timing applies when a reset occurs in the T2 state of an access cycle to a two-state-access area.

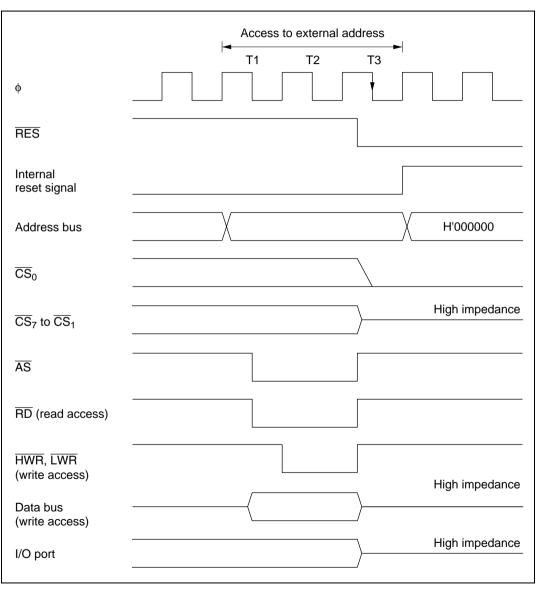


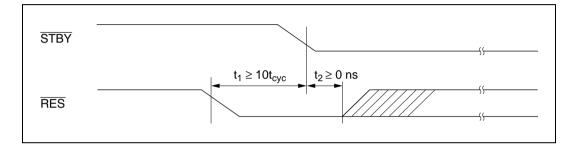
Figure D.3 Reset during Memory Access (Reset during T3 State)



Appendix E Timing of Transition to and Recovery from Hardware Standby Mode

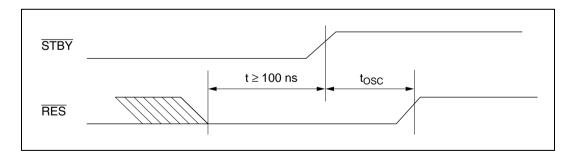
Timing of Transition to Hardware Standby Mode

(1) To retain RAM contents with the RAME bit set to 1 in SYSCR, drive the RES signal low 10 system clock cycles before the STBY signal goes low, as shown below. RES must remain low until STBY goes low (minimum delay from STBY low to RES high: 0 ns).



(2) To retain RAM contents with the RAME bit cleared to 0 in SYSCR, or when RAM contents do not need to be retained, $\overline{\text{RES}}$ does not have to be driven low as in (1).

Timing of Recovery from Hardware Standby Mode: Drive the $\overline{\text{RES}}$ signal low approximately 100 ns before $\overline{\text{STBY}}$ goes high.



Renesas

Appendix F Product Code Lineup

Table F.1 H8/3048 Group Product Code Lineup

Class	sification o	f Products			Deskawa
Product Type	Type of ROM	Power Supply Specifications	Product Code	Mark Code	Package (Package Code)
H8/3048F	Flash	5 V version	HD64F3048TF	HD64F3048TF	100-pin TQFP (TFP-100B)
	memory version		HD64F3048F	HD64F3048F	100-pin QFP (FP-100B)
	(dual	3 V version	HD64F3048VTF	HD64F3048VTF	100-pin TQFP (TFP-100B)
	power supply)		HD64F3048VF	HD64F3048VF	100-pin QFP (FP-100B)
H8/3048	PROM	5 V version	HD6473048TF	HD6473048TF	100-pin TQFP (TFP-100B)
ZTAT	version		HD6473048F	HD6473048F	100-pin QFP (FP-100B)
		3 V version	HD6473048VTF	HD6473048VTF	100-pin TQFP (TFP-100B)
			HD6473048VF	HD6473048VF	100-pin QFP (FP-100B)
H8/3048		5 V version	HD6433048TF	HD6433048(***)TF	100-pin TQFP (TFP-100B)
	ROM version		HD6433048F	HD6433048(***)F	100-pin QFP (FP-100B)
	Version	3 V version	HD6433048VTF	HD6433048(***)VTF	100-pin TQFP (TFP-100B)
			HD6433048VF	HD6433048(***)VF	100-pin QFP (FP-100B)
H8/3047	Mask	5 V version	HD6433047TF	HD6433047(***)TF	100-pin TQFP (TFP-100B)
	ROM version		HD6433047F	HD6433047(***)F	100-pin QFP (FP-100B)
	10131011	3 V version	HD6433047VTF	HD6433047(***)VTF	100-pin TQFP (TFP-100B)
			HD6433047VF	HD6433047(***)VF	100-pin QFP (FP-100B)
H8/3045	Mask	5 V version	HD6433045TF	HD6433045(***)TF	100-pin TQFP (TFP-100B)
	ROM version		HD6433045F	HD6433045(***)F	100-pin QFP (FP-100B)
	Version	3 V version	HD6433045VTF	HD6433045(***)VTF	100-pin TQFP (TFP-100B)
			HD6433045VF	HD6433045(***)VF	100-pin QFP (FP-100B)
H8/3044	Mask	5 V version	HD6433044TF	HD6433044(***)TF	100-pin TQFP (TFP-100B)
	ROM version		HD6433044F	HD6433044(***)F	100-pin QFP (FP-100B)
		3 V version	HD6433044VTF	HD6433044(***)VTF	100-pin TQFP (TFP-100B)
			HD6433044VF	HD6433044(***)VF	100-pin QFP (FP-100B)

Note: (***) in mask ROM versions is the ROM code.

Appendix G Package Dimensions

Figure G.1 shows the FP-100B package dimensions of the H8/3048 Group. Figure G.2 shows the TFP-100B package dimensions.

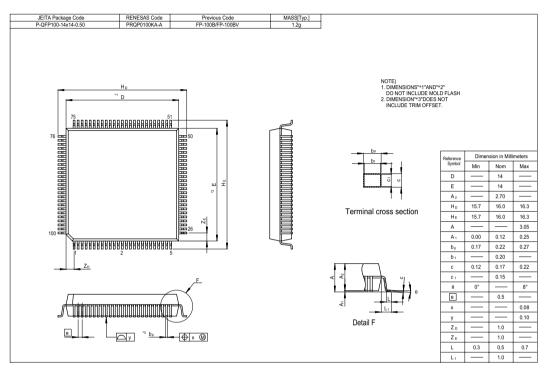


Figure G.1 Package Dimensions (FP-100B)

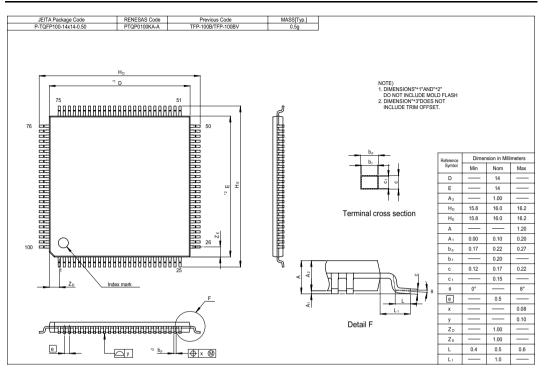


Figure G.2 Package Dimensions (TFP-100B)



Renesas 16-Bit Single-Chip Microcomputer Hardware Manual H8/3048 Group, H8/3048 F-ZTAT™

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Sales Strategic Planning Div.
Renesas Technology Corp.
Customer Support Department
Global Strategic Communication Div.
Renesas Solutions Corp.

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